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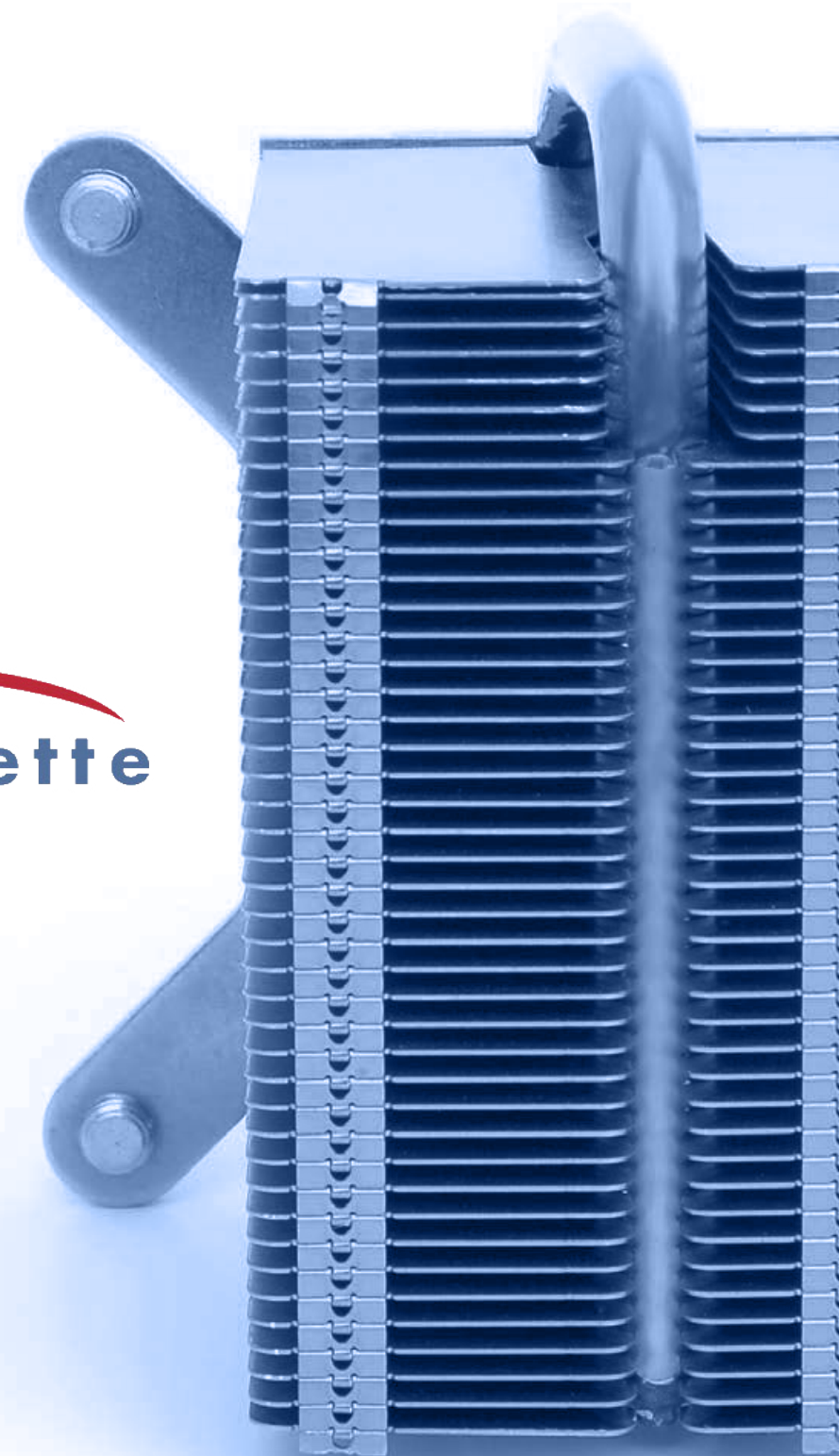
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For 75 years, Richardson Electronics has been your industry-leading global provider of engineered solutions. We are an authorized distributor that provides specialized technical expertise and engineered solutions based on our core engineering and manufacturing capabilities. We provide solutions and add value through design-in support, systems integration, prototype design and manufacturing, testing, logistics, and aftermarket technical service and repair—all through our existing global infrastructure.

We are proud to announce our new partnerships with manufacturers of leading edge and disruptive technologies. These technologies drive the latest innovations for our customers.

  
**wakefield-vette**  
[wakefield-vette.com](http://wakefield-vette.com)

**Corporate Headquarters:**  
 Wakefield Engineering Inc.\*  
 33 Bridge Street, Pelham, NH 03076  
 Tel: 603-635-2800 • Fax: 603-635-1900  
 \* ISO 9001:2015 REGISTERED



  
**wakefield-vette**

**THERMAL MANAGEMENT**  
 Standard Product Catalog

**2018**

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Wakefield-Vette believes that information provided in this product catalog is accurate as of publication date. Product testing for proper performance in customer applications is recommended for all component designs and adhesives. Obtain mechanical samples of all assembly components and test to determine suitability. The physical properties reported herein are representative of performance values obtained by standard predictive and testing methods and exclude the interface resistance of any adhesive or other interface material in heat sink data. Wakefield-Vette is a manufacturer of heat dissipation products and reserves the right to make changes to its products without notice to improve the design or performance characteristics.

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All specifications subject to change without notice. © 2018

## ABOUT WAKEFIELD-VETTE

### SINCE 1952

**Wakefield-Vette** has been in continuous operations since 1952, providing thermal solutions across multiple industries, from international Fortune 50 companies to small and medium sized businesses. Industries served include *Power Conversion, Information Technology, Renewable Energy, Telecommunications, Transportation, Aerospace/Defense, LED Lighting, Factory Automation, Consumer, and Medical.*

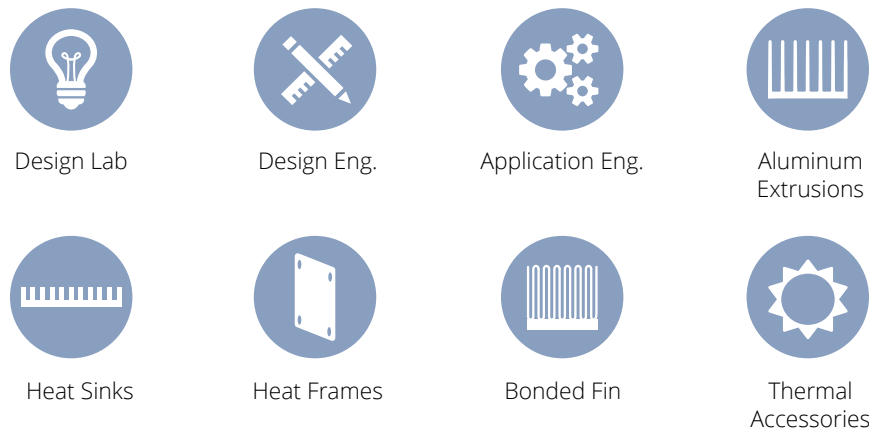
The thermal solutions Wakefield-Vette manufactures comprise a wide array of products, including *thermal extrusions, LED heat sinks, heat frames and pipes, fans, heat exchangers, coolant distribution units, liquid cold plates, etc.*, making Wakefield-Vette unique in its ability to deliver the increasingly complex **thermal solutions** required to meet the thermal engineering challenges of today's ever-higher electronics packaging densities.

Wakefield-Vette is a **700-employee strong company** with 500,000 square feet of global manufacturing capacity with facilities located in New Hampshire, North Carolina, and Wisconsin.



### PELHAM, NH

*US Headquarters Production – Thermal Management, Extrusions*



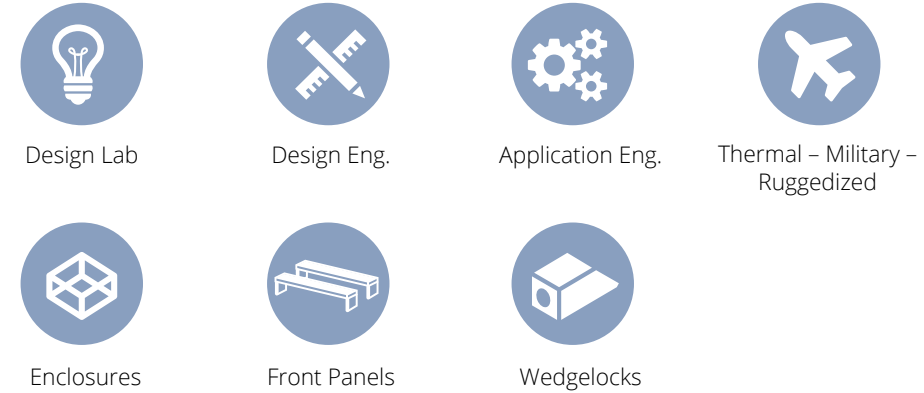
**33 Bridge Street  
Pelham, NH 03076**  
**Phone:** (603) 635-2800  
**Fax:** (603) 635-1900

210 Employees  
240,000 ft<sup>2</sup>

## LOCATION OVERVIEW

### RALEIGH, NC

*Production – Ruggedized & Electronic Packaging, Hi-end Complex Mfg, Military*



**2910 Industrial Drive  
Raleigh, NC 27609**  
**Phone:** (919) 831-9950

65 Employees  
50,000 ft<sup>2</sup>

### WITHEE, WI

*Production – Extrusions, Fabrications*

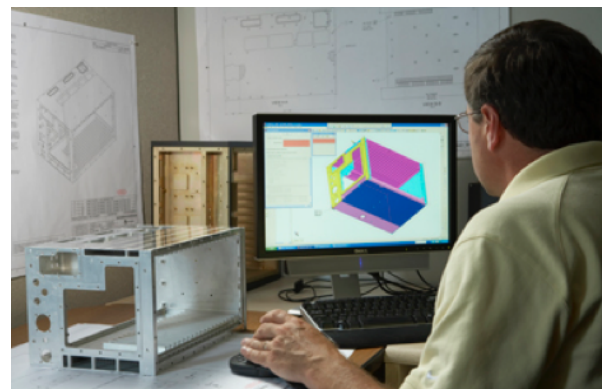
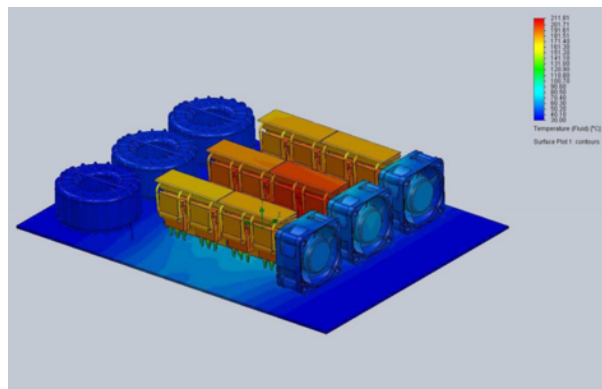


**511 Progress Street  
Withee, WI 54498**  
**Phone:** (715) 229-9200  
**Fax:** (715) 229-9202

60 Employees  
55,000 ft<sup>2</sup>

# DESIGN SERVICES

## THERMAL SOLUTIONS



Wakefield-Vette also offers a **wide range of engineering design services** along with our standard and custom products. In many cases, our customers need to make small changes to our standard products. Wakefield-Vette's application engineers are ready to modify drawings and give feedback on requested changes to support your efforts to make the product you purchase work as intended in your application. When even more design assistance is needed, Wakefield-Vette has a world class team of engineers to work with you. We excel at collaboration with **engineering teams** to share drawings, design ideas, analysis and manufacturing understanding. Wakefield-Vette uses SolidWorks solid models and drawings and Ansys IcePak for Computational Fluid Dynamics (CFD) analysis.

Even if you do not have a thermal solution in mind, bring your applications to us and we can support ground-up design efforts with options for **liquid, natural and forced air convection cooling solutions**. Wakefield-Vette can also give insight into the use of thermal products like heat pipes, vapor chambers, liquid cold plates and many other technologies to bring to bear on your application as well as accessory items such as thermal interface materials, fans and attach methods. Wakefield-Vette can truly be your one-stop-shop for thermal solutions from start to finish.

# NOTES

Lined area for taking notes.

# THERMAL MANAGEMENT SOLUTIONS & THERMAL INTERFACE

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## BGA THERMAL SOLUTIONS MATRIX

The following table represents Wakefield-Vette's recommendations for a variety of standard BGA sizes. However, this is by no means a complete list of components that can be used with these heat sinks. To determine suitability for your particular component, request a BGA heat sink evaluation kit.

BGA Sizes (mm)	Heat Sink Footprint (mm)	Heat Sink Height (inches)	Recommended Series #	Attachment Method
17	17 x 17	.40	D10650	Adhesive
19	19 x 19	1.00	602	Adhesive
21	21 x 21	.40	D10850	Adhesive
21	21 x 21	.25 .35 .45 .60	624	Adhesive
23	22 x 22	.40 .60	604	Adhesive
23	22 x 22	.75	605	Adhesive
25	25 x 25	.25 .35 .45 .60	625	Adhesive
27	28 x 28	.25 .35 .45 .60	658	Adhesive
29	30 x 30	.77	606	Adhesive
31	31 x 28	.65	607	Adhesive
31	31 x 31	.80	611	Adhesive
33	32 x 32	.35 .40	610	Adhesive
35	35 x 35	.65	612	Adhesive
35	35 x 35	.25 .35 .45 .60	642	Adhesive
35	35 x 35	.25 .35 .45 .60	630	Adhesive
37.5	37 x 37	.50	613	Adhesive
37.5	37 x 37	.65	659	Adhesive
45.7 x 35.5	37 x 47	.80	617	Adhesive
40	38 x 38	.30 .50 1.00	614	Adhesive
37.5	38 x 38	.29	660	Adhesive
40	40 x 28	.35	643	Clip
40	40 x 40	.26 .53	655	Adhesive
42.5	41 x 41	.41	615	Adhesive
45	43 x 43	.20 .25 .35 .45 .60	628	Adhesive
45	43 x 43	.15	662	Adhesive
47.5	47 x 47	.80	616	Adhesive
50	50 x 50	.40 .65 .80 1.00	698	Adhesive
50	51 x 51	.20 1.00	618	Adhesive
50	52 x 51	.80	622	Adhesive
50	53 x 47	.40 .65 .80 1.00	798	Adhesive
50	64 x 51	.24	620	Adhesive
up to 45	73 x 50	.50 1.00	609	Clip
up to 45	73 x 50	.95	619	Clip

### RoHS COMPLIANCE

Please note that Wakefield-Vette part numbers designated with an "E" in this catalog denote new parts in compliance with the RoHS initiative, with the exception of our Precision Clamps. Wakefield-Vette will still continue to offer non-RoHS compliant versions of these parts. Please be aware that many Wakefield-Vette Standard parts have always been compliant since their design inception and therefore will not carry the "E" designation.

Wakefield-Vette requests that you refer to the RoHS compliance tool on our website at [www.wakefield-vette.com](http://www.wakefield-vette.com) to verify RoHS compliance. If you require further clarification or information regarding RoHS, please contact the factory.

## THERMAL INTERFACE MATERIAL PART NUMBER GUIDE

All of the heat sinks shown in this catalog are available with any of the following thermal tape and interface materials, pre-applied at the factory. Use the “T” series, thermally enhanced, pressure sensitive adhesives to attach the heat sink to the electronic package and provide a good thermal link to the heat sink. Specify these materials in applications where the heat sink will be fixed to the electronic package by some mechanical means other than a tape. Please note that none of these materials are for use in applications requiring electrical isolation from the electronic device. All options other than -T1 and -T4 are RoHS compliant.

**Note:** To obtain the estimated thermal resistance of the interface material in your application, divide the thermal impedance value by the area of the pad in square inches. For example, a 2” x 2” piece of T4 has a resistance of 1.10 C-in<sup>2</sup>/W ÷ 4 in<sup>2</sup>=0.275 C/W

### “T” Series Thermally Enhanced Pressure Sensitive Adhesives

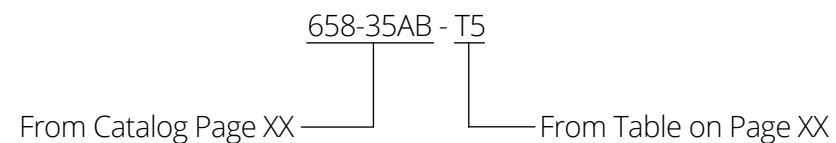
Suffix	Manufacturer Product	Thermal Impedance C-in <sup>2</sup> /W	Thickness, Inches	Package Surface, Comments
-T1	Chomerics, T405	0.47	0.006	Metal/ceramic; aluminum carrier
-T1E	Chomerics, T405R	0.47	0.006	RoHS-compliant version of -T1
-T3	Chomerics, T412	0.25	0.009	Metal/ceramic; very good performance and conformity
-T4	Chomerics, T410	1.10	0.007	Plastic
-T4E	Chomerics, T410R	1.10	0.007	RoHS-compliant version of -T4
-T5	Chomerics, T411	1.00	0.011	Plastic; conforms to out-of-flat packages
-T6	3M, 8810	0.88	0.010	Metal/ceramic; very good adhesion and conformity
-T7	Bergquist, BP 108	1.28	0.008	Metal/ceramic; electrically insulating

### ORDERING INFORMATION

Once you have chosen heat sink and thermal interface material that meets your thermal & mechanical requirements it is easy to designate the part number. Simply add the interface material suffix referenced on the chart above to the base part number for the heat sink. The base part number already includes information regarding its size and finish.

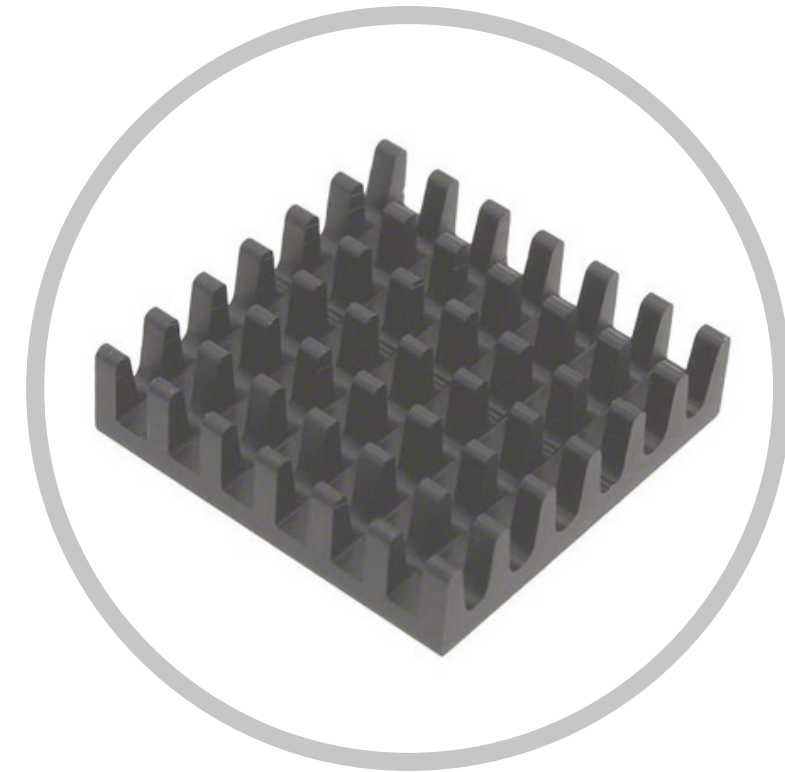
Example:

To order the 658 Series heat sink at .350” tall with the T5 thermal interface material, specify part number:



# INTEGRATED CIRCUIT COOLING HEAT SINKS

<i>Heat Sinks For BGAs, Super BGAs, &amp; FPBGAs .....</i>	<i>12-27</i>
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*With the increase in heat dissipation from microelectronics devices and the reduction in overall form factors, thermal management becomes a more important element of electronic product design.*

*Both the performance reliability and life expectancy of electronic equipment are inversely related to the component temperature of the equipment. The relationship between the reliability and the operating temperature of a typical silicon semi-conductor device shows that a reduction in the temperature corresponds to an exponential increase in the reliability and life expectancy of the device. Therefore, long life and reliable performance of a component may be achieved by effectively controlling the device operating temperature within the limits set by the device design engineers.*

*Heat sinks are devices that enhance heat dissipation from a hot surface, usually the case of a heat generating component, to a cooler ambient, usually air. For the following discussions, air is assumed to be the cooling fluid. In most situations, heat transfer across the interface between the solid surface and the coolant air is the least efficient within the system, and the solid-air interface represents the greatest barrier for heat dissipation. A heat sink lowers this barrier mainly by increasing the surface area that is in direct contact with the coolant. This allows more heat to be dissipated and/or lowers the device operating temperature. The primary purpose of a heat sink is to maintain the device temperature below the maximum allowable temperature specified by the device manufacturers.*

## HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, & FPBGAs

### 624 SERIES OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs



The **624 Series** is an omnidirectional pin fin heat sink for both natural and forced-convection applications.

Applications include network routers and switches, high-resolution printers, digital cameras, consumer video games, digital video disks (DVD) and global positioning systems (GPS).

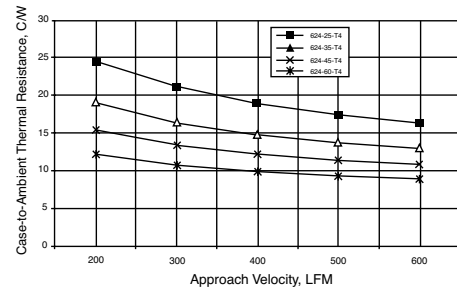
Standard P/N	Base Dimensions in. Sq.	Fin Height "A" in. (mm)	Typical Applications	Weight lbs. (grams)
624-25AB	.827 (21)	.250 (6.4)	21mm BGA	.009 (4.09)
624-35AB	.827 (21)	.350 (8.9)	21mm BGA	.011 (4.99)
624-45AB	.827 (21)	.450 (11.4)	21mm BGA	.015 (6.81)
624-60AB	.827 (21)	.600 (15.2)	21mm BGA	.026 (11.80)

**Material:** Aluminum, Black Anodized

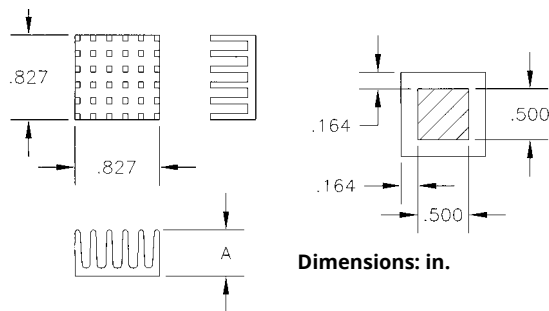
#### PRODUCT FEATURES

- Available in four standard heights, .25 inch, .35 inch, .45 inch, and .60 inch.
- Available with pressure sensitive adhesives for quick and easy mounting. See Page 8.

#### 624 THERMAL PERFORMANCE



#### MECHANICAL DIMENSIONS



### OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs **625 SERIES**

#### PRODUCT FEATURES

- Available in four standard heights, .25 inch, .35 inch, .45 inch, and .60 inch.
- Available with pressure sensitive adhesives for quick and easy mounting. See Page 8.

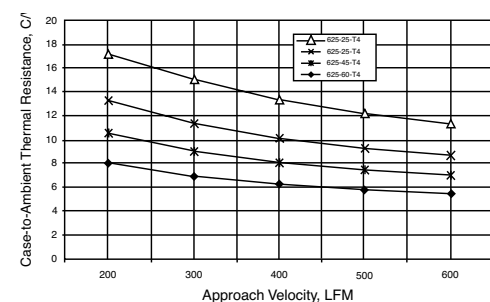
The **625 Series** is an omnidirectional pin fin heat sink for both natural and forced-convection applications.

Applications include network routers and switches, high-resolution printers, digital cameras, consumer video games, digital video disks (DVD) and global positioning systems (GPS).

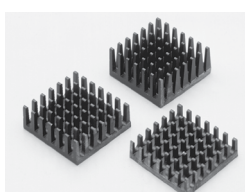
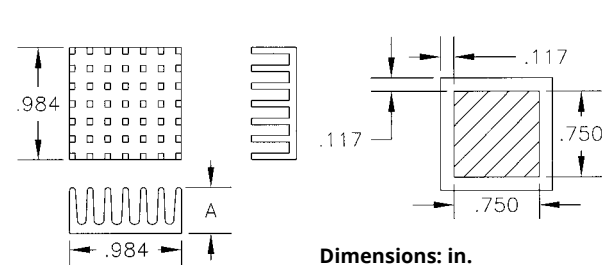
Standard P/N	Base Dimensions in. Sq.	Fin Height "A" in. (mm)	Typical Applications	Weight lbs. (grams)
625-25AB	.984 (25)	0.250 (6.4)	25 mm BGA	.012 (5.45)
625-35AB	.984 (25)	0.350 (8.9)	25 mm BGA	.014 (6.36)
625-45AB	.984 (25)	0.450 (11.4)	25 mm BGA	.018 (8.17)
625-60AB	.984 (25)	0.600 (15.2)	25 mm BGA	.030 (13.62)

**Material:** Aluminum, Black Anodized

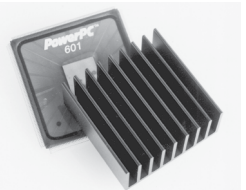
#### 625 THERMAL PERFORMANCE



#### MECHANICAL DIMENSIONS



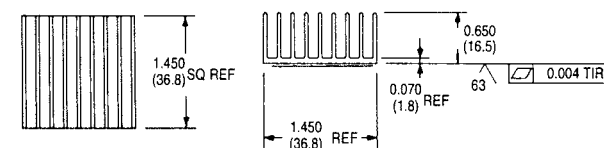
### UNIDIRECTIONAL FIN HEAT SINK FOR BGAs **659 SERIES**



Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Typical Application	Heat Sink Finish	Weight lbs. (grams)
659-65AB	1.45 (36.8) sq	.650 (16.5)	37mm BGA	Black Anodized	0.050 (22.68)

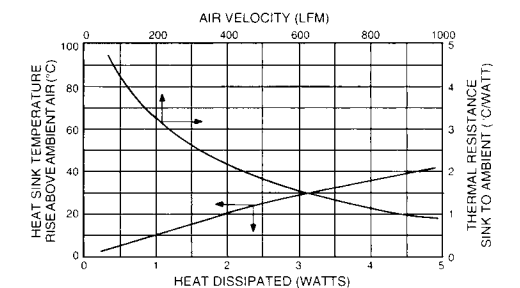
**Notes:** 1. Optional factory pre-applied pressure-sensitive adhesive. See Page 8.

#### MECHANICAL DIMENSIONS

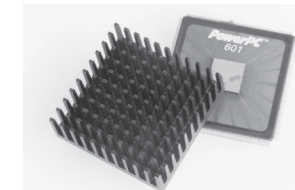


Dimensions: in. (mm)

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



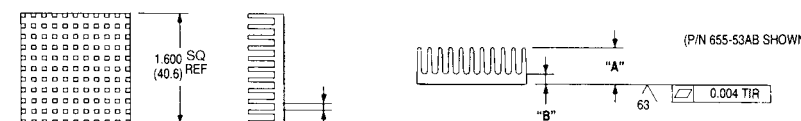
### OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs AND POWERPC™ **655 SERIES**



Standard P/N	Base Dimensions in. (mm)	Dimension "A" in. (mm)	Dimension "B" in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
655-26AB	1.600 (40.6) sq	0.260 (6.6)	0.125 (3.2)	40mm BGA	Black Anodized	0.038 (17.01)
655-53AB	1.600 (40.6) sq	0.525 (13.3)	0.145 (3.7)	40mm BGA	Black Anodized	0.050 (22.68)

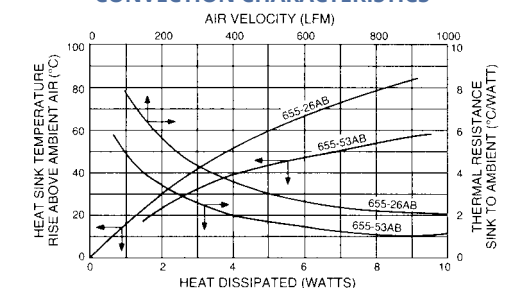
**Notes:** 1. Optional factory pre-applied pressure-sensitive adhesive. See Page 8.

#### MECHANICAL DIMENSIONS

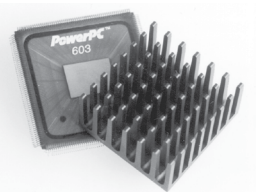


Dimensions: in. (mm)

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



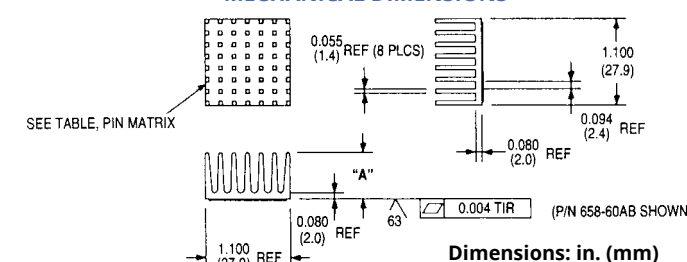
### OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs AND POWERPC™ **658 SERIES**



Standard P/N	Base Dimensions in. (mm)	Dimension "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
658-25AB	1.100 (27.9) sq	0.250 (6.4)	27mm BGA	Black Anodized	0.013 (5.67)
658-35AB	1.100 (27.9) sq	0.350 (8.9)	27mm BGA	Black Anodized	0.015 (6.70)
658-45AB	1.100 (27.9) sq	0.450 (11.4)	27mm BGA	Black Anodized	0.019 (8.50)
658-60AB	1.100 (27.9) sq	0.600 (15.2)	27mm BGA	Black Anodized	0.031 (14.17)

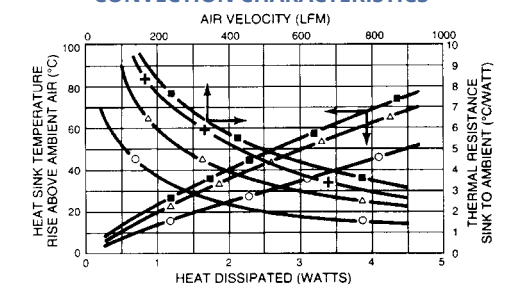
**Notes:** 1. Optional factory pre-applied pressure-sensitive adhesive. See Page 8.

#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



KEY:  
 ■ 658-25AB  
 + 658-35AB  
 △ 658-45AB  
 ○ 658-60AB



## HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, & FPBGAs

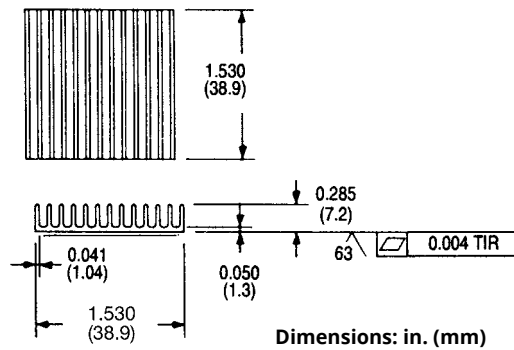
### 660 SERIES

UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

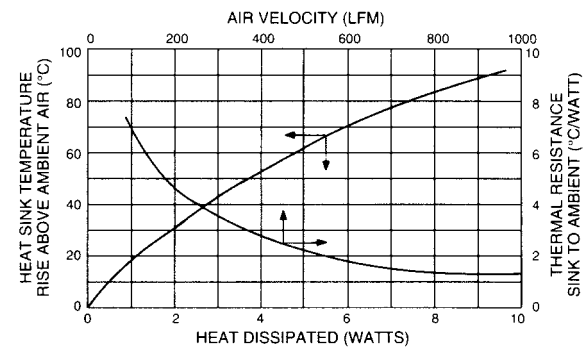
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Typical Application	Heat Sink Finish	Weight lbs. (grams)
660-29AB	1.530SQ. (38.9)SQ.	0.285 (7.2)	37mm BGA	Black Anodized	0.031 (14.17)

Notes: 1. Optional factory pre-applied pressure-sensitive adhesive. See Page 8.

#### MECHANICAL DIMENSIONS



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



### UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

### 642 SERIES

#### PRODUCT FEATURES

- Available in four standard heights, .25 inch, .35 inch, .45 inch, and .60 inch.
- Available with pressure sensitive adhesives for quick and easy mounting. See Page 8.

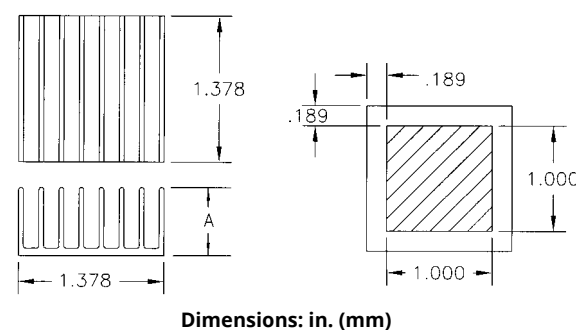
The **642 Series** is an unidirectional pin fin heat sink for both natural and forced-convection applications.

Applications include network routers and switches, high-resolution printers, digital cameras, consumer video games, digital video disks (DVD) and global positioning systems (GPS).

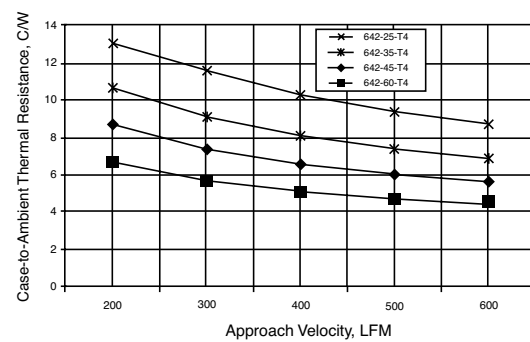
Standard P/N	Base Dimensions in. Sq.	Fin Height "A" in. (mm)	Typical Applications	Weight lbs. (grams)
642-25AB	1.378 (35)	.250 (6.4)	35 mm BGA	.022 (9.99)
642-35AB	1.378 (35)	.350 (8.9)	35 mm BGA	.027 (12.26)
642-45AB	1.378 (35)	.450 (11.4)	35 mm BGA	.031 (14.07)
642-60AB	1.378 (35)	.600 (15.2)	35 mm BGA	.039 (17.71)

Material: Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



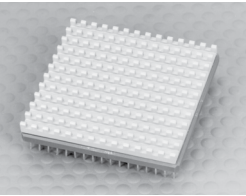
#### 642 THERMAL PERFORMANCE



Performance shown is with T4 thermal adhesive applied.

### OMNIDIRECTIONAL PIN FIN HEAT SINK FOR LIMITED HEIGHT BGAs

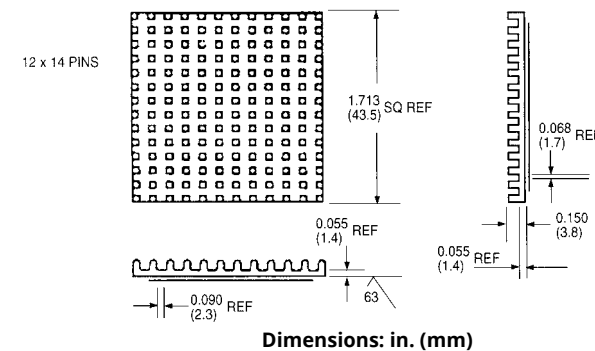
### 662 SERIES



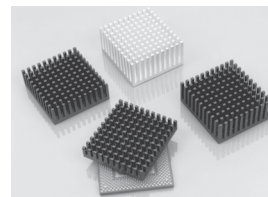
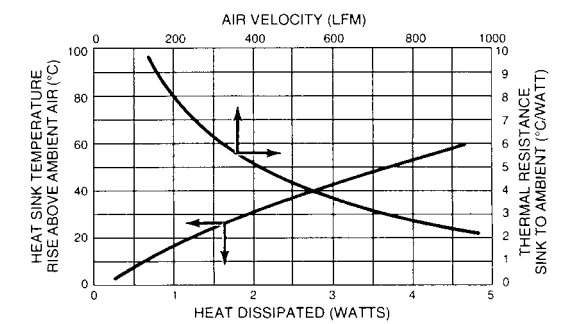
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
662-15AG	1.713 (43.5) sq	0.150 (3.8)	45mm BGA	Gold Iridite	0.019 (8.50)
662-15AB	1.713 (43.5) sq	0.150 (3.8)	45mm BGA	Black Anodized	0.019 (8.50)

Notes: 1. Optional factory pre-applied pressure-sensitive adhesive. See Page 8.

#### MECHANICAL DIMENSIONS



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



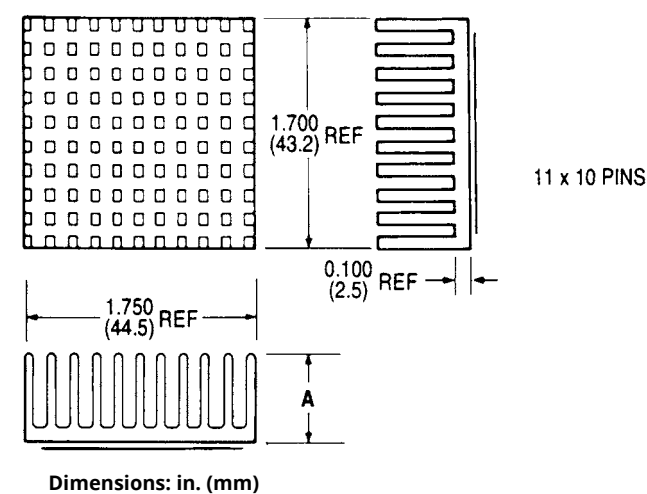
### 628 SERIES

OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs

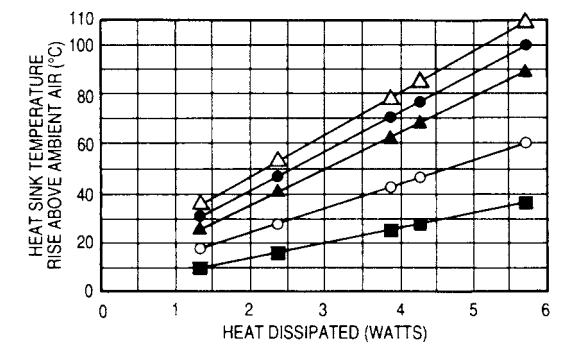
Standard P/N	Base Dimensions in. (mm)	Dimensions "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
628-20AB	1.750 (44.5) x 1.700 (43.2)	0.200 (5.1)	45mm BGA	Black Anodized	0.031 (14.17)
628-25AB	1.750 (44.5) x 1.700 (43.2)	0.250 (6.4)	45mm BGA	Black Anodized	0.038 (17.01)
628-35AB	1.750 (44.5) x 1.700 (43.2)	0.350 (8.9)	45mm BGA	Black Anodized	0.044 (19.84)
628-40AB	1.750 (44.5) x 1.700 (43.2)	0.400 (10.2)	45mm BGA	Black Anodized	0.050 (22.68)
628-65AB	1.750 (44.5) x 1.700 (43.2)	0.650 (16.5)	45mm BGA	Black Anodized	0.056 (25.51)

Notes: 1. Optional factory pre-applied pressure-sensitive adhesive. See Page 8.

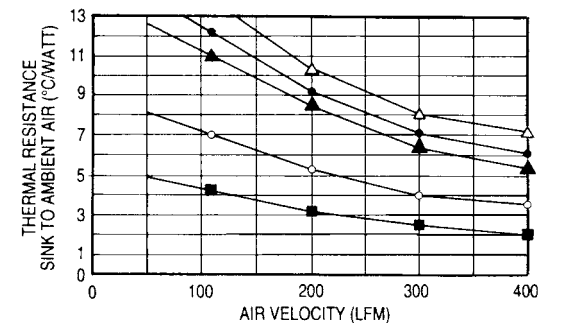
#### MECHANICAL DIMENSIONS



#### NATURAL CONVECTION CHARACTERISTICS



#### FORCED CONVECTION CHARACTERISTICS



KEY:  
 △ 628-20AB  
 ● 628-25AB  
 ▲ 628-35AB  
 ○ 628-40AB  
 ■ 628-65AB

## HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, & FPBGAs

### 630 SERIES OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs

The **630 Series** is an omnidirectional pin fin heat sink for both natural and forced-convection applications.

Applications include network routers and switches, high-resolution printers, digital cameras, consumer video games, digital video disks (DVD) and global positioning systems (GPS).

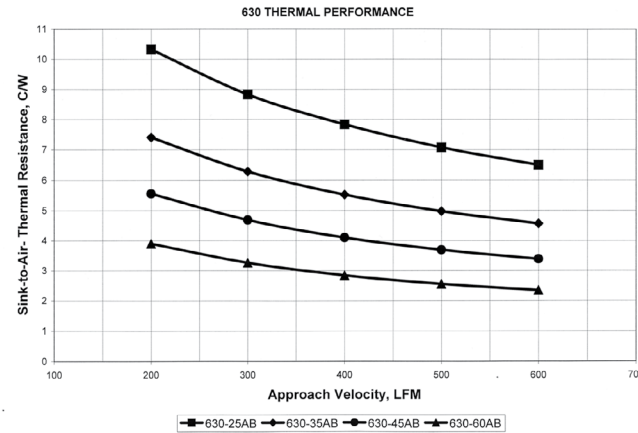
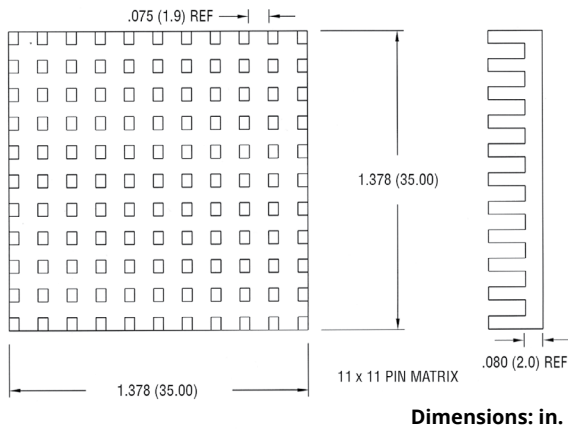
Standard P/N	Base Dimensions in. Sq.	Fin Height "A" in. (mm)	Typical Applications	Weight lbs. (grams)
630-25AB	1.378 (35)	.250 (6.4)	35mm BGA	.009 (4.09)
630-35AB	1.378 (35)	.350 (8.9)	35mm BGA	.011 (4.99)
630-45AB	1.378 (35)	.450 (11.4)	35mm BGA	.015 (6.81)
630-60AB	1.378 (35)	.600 (15.2)	35mm BGA	.026 (11.80)

**Material:** Aluminum, Black Anodized

#### PRODUCT FEATURES

- Available in four standard heights, .25 inch, .35 inch, .45 inch, and .60 inch.
- Available with pressure sensitive adhesives for quick and easy mounting. See Page 8.

#### MECHANICAL DIMENSIONS

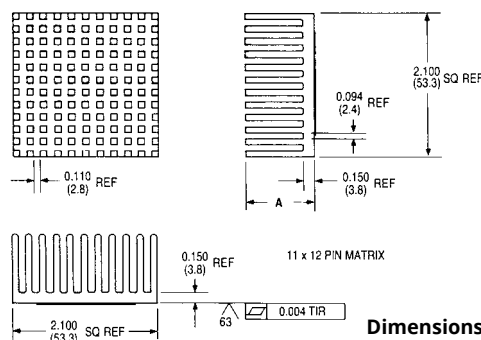


### OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs 698 SERIES

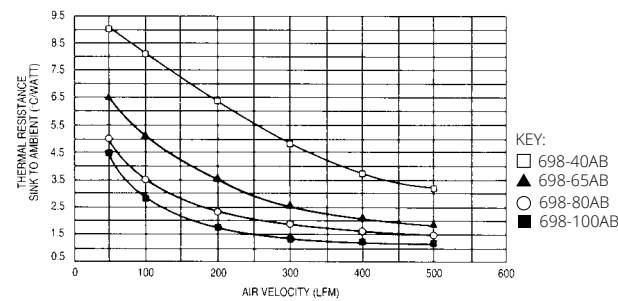
Standard P/N	Base Dimensions in. (mm)	Dimensions "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
698-40AB	2.100 (53.3) sq.	0.400 (10.2) sq.	45mm BGA	Black Anodized	0.075 (34.02)
698-65AB	2.100 (53.3) sq.	0.650 (16.5) sq.	45mm BGA	Black Anodized	0.119 (53.86)
698-80AB	2.100 (53.3) sq.	0.800 (20.3) sq.	45mm BGA	Black Anodized	0.125 (56.70)
698-100AB	2.100 (53.3) sq.	1.000 (25.4) sq.	45mm BGA	Black Anodized	0.144 (65.20)

**Notes:** 1. Optional factory preapplied pressure-sensitive adhesive. See Page 8.

#### MECHANICAL DIMENSIONS

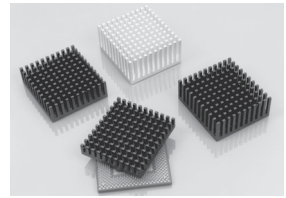


#### FORCED CONVECTION THERMAL PERFORMANCE DATA (FLOW PARALLEL TO EXTRUSION DIRECTION)

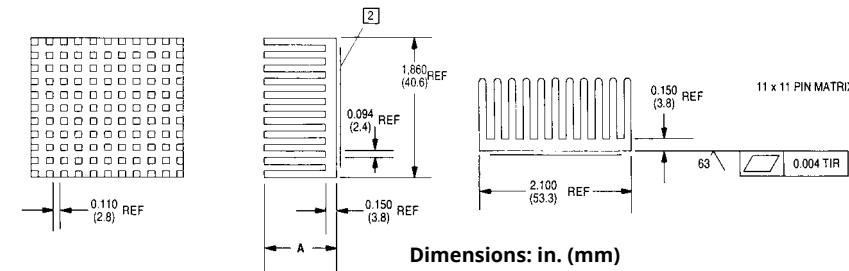


### PIN FIN HEAT SINK FOR BGAs 798 SERIES

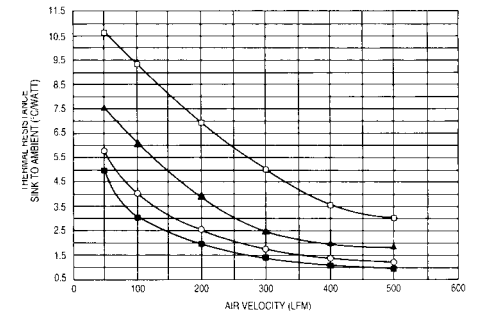
Standard P/N	Base Dimensions in. (mm)	Dimensions "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
798-40AB	2.100 (53.3) x 1.860 (47.2)	0.400 (10.2)	45mm BGA	Black Anodized	0.063 (28.35)
798-65AB	2.100 (53.3) x 1.860 (47.2)	0.650 (16.5)	45mm BGA	Black Anodized	0.106 (48.19)
798-80AB	2.100 (53.3) x 1.860 (47.2)	0.800 (20.3)	45mm BGA	Black Anodized	0.113 (51.03)
798-100AB	2.100 (53.3) x 1.860 (47.2)	1.000 (25.4)	45mm BGA	Black Anodized	0.131 (59.53)



#### MECHANICAL DIMENSIONS



#### FORCED CONVECTION THERMAL PERFORMANCE DATA (FLOW PARALLEL TO EXTRUSION DIRECTION)

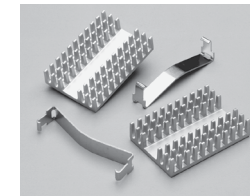


#### NOTES:

1. Heat sink mounting surface flatness: 0.004" TIR
2. Optional factory pre-applied pressure-sensitive adhesive. See Page 8.

KEY: □ 798-40AB ▲ 798-65AB ○ 798-80AB ■ 798-100AB

### 643 SERIES OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs



The **Series 643-35AP** is an omnidirectional pin fin heat sink for both natural and forced-convection applications designed to fit a 40 mm BGA.

Applications include network routers and switches, high-resolution printers, digital cameras, consumer video games, digital video disks (DVD) and global positioning systems (GPS).

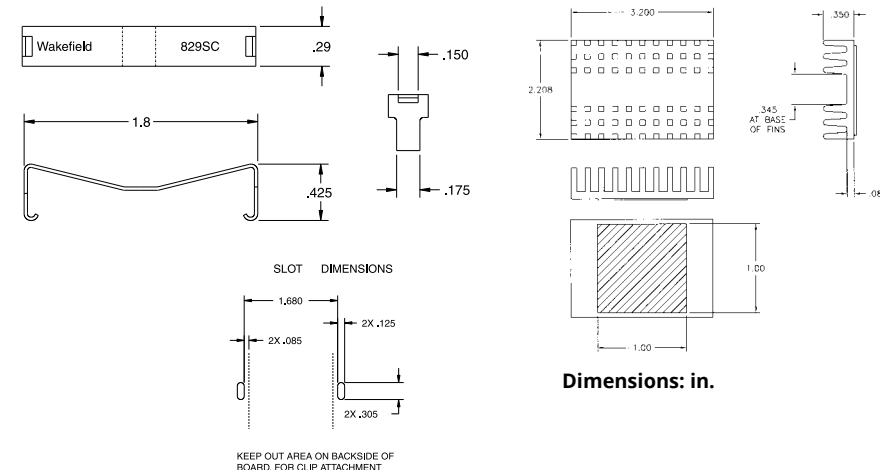
#### PRODUCT FEATURES

- Available with pressure sensitive adhesives to ensure good thermal performance. See page 8.
- Can be ordered with the **829SC clip**. Order clip separately. (Clip cannot be purchased without heat sink)

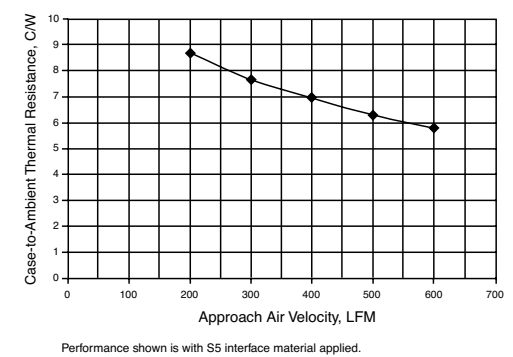
Standard P/N	Base Dimensions in. (mm)	Fin Height in. (mm)	Typical Applications	Weight lbs. (grams)
643-35AP	1.60 (40.64) x 1.10 (27.94)	0.350 (8.89)	40 mm BGA	.070 (31.78)

**Material:** Aluminum, Plain Finish

#### MECHANICAL DIMENSIONS

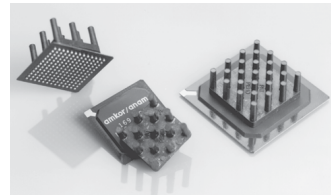


#### 643 THERMAL PERFORMANCE



Performance shown is with S5 interface material applied.

## DELTEM™ COMPOSITE HEAT SINKS FOR BGAs



### DELTEM™ D10650-40 PIN FIN HEAT SINK

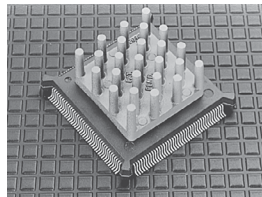
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Weight lbs. (grams)
D10650-40	0.650 (16.5) sq	0.400 (10.2)	0.004 (1.91)

**Notes:** Available with pressure sensitive adhesives for quick and easy mounting. See Page 8.

### PIN FIN HEAT SINK DELTEM™ D10850-40

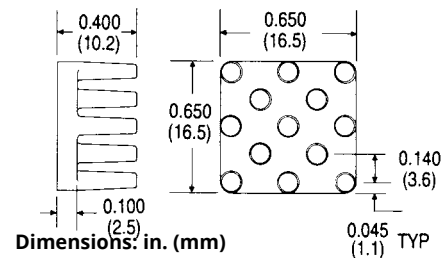
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Typical Applications	Weight lbs. (grams)
D10850-40	0.850 (21.6) sq	0.400 (10.2)	21mm BGA	0.006 (3.9)

**Notes:** Available with pressure sensitive adhesives for quick and easy mounting. See Page 8.

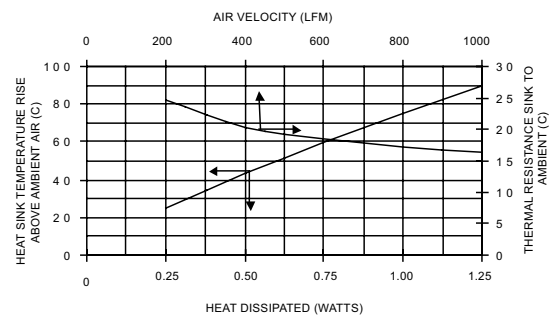


#### MECHANICAL DIMENSIONS

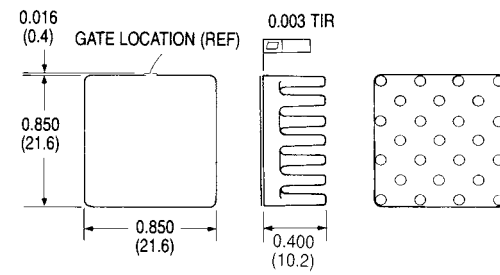
##### DELTEM™ D10650-40 PIN FIN HEAT SINK



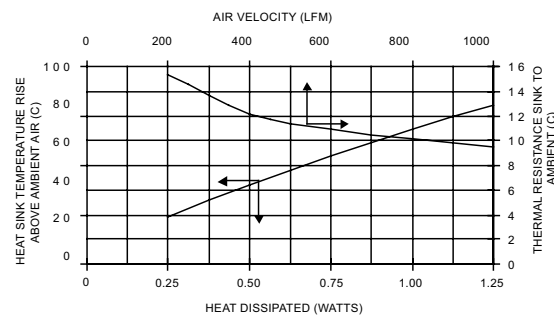
#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



##### DELTEM™ D10850-40 PIN FIN HEAT SINK



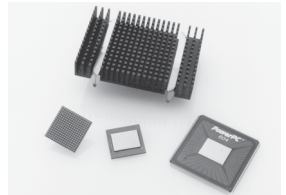
#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, & FPBGAs

### PIN FIN HEAT SINK FOR BGAs HEAT SINK/CLIP ASSEMBLY FOR BGAs AND POWERPC™ PACKAGES

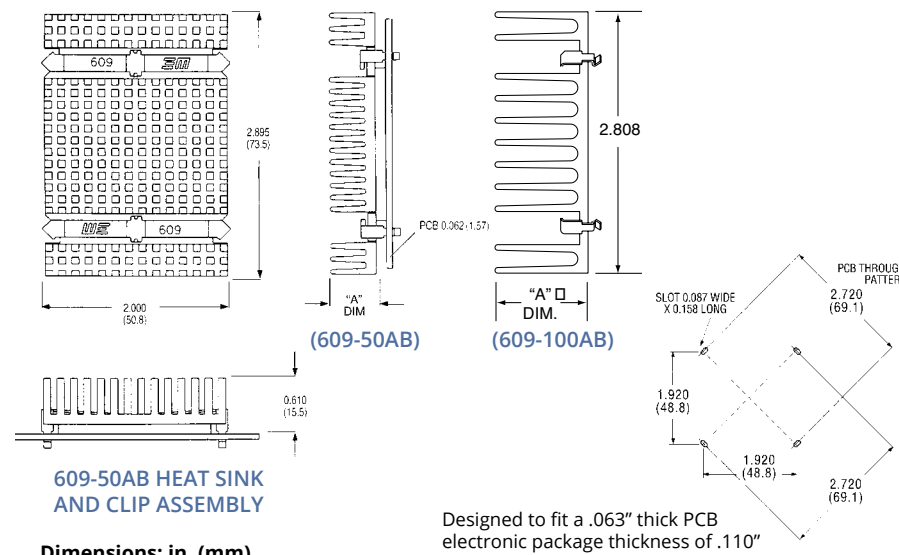
### 609 SERIES



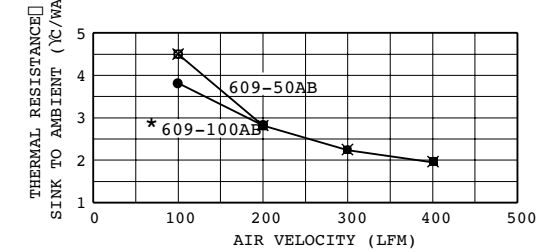
Standard P/N	Base Dimensions in. (mm)	Dimensions "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
609-50AB	2.895 (73.5) x 2.000 (50.8)	0.500 (12.7)	40&45mm BGA	Black Anodized	0.094 (42.5)
609-100AB	2.808 (71.32) x 1.700 (43.2)	1.00 (25.4)	40&45mm BGA	Black Anodized	0.130 (59.0)

**Note:** Optional factory pre-applied thermal interface material.  
S3 (Bergquist Q-Pad 3, 0.14 °C in<sup>2</sup>/w)  
S4 (Bergquist Softface, 0.07 °C in<sup>2</sup>/w)

#### MECHANICAL DIMENSIONS

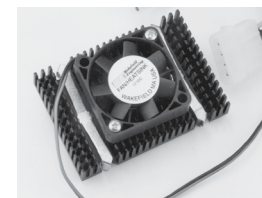


#### FORCED CONVECTION THERMAL PERFORMANCE DATA (LOW PARALLEL TO EXTRUSION DIRECTION)



#### 609-50AB HEAT SINK AND CLIP ASSEMBLY

Dimensions: in. (mm)



### 619 SERIES FAN HEAT SINK FOR BGA AND POWERPC™ PACKAGES

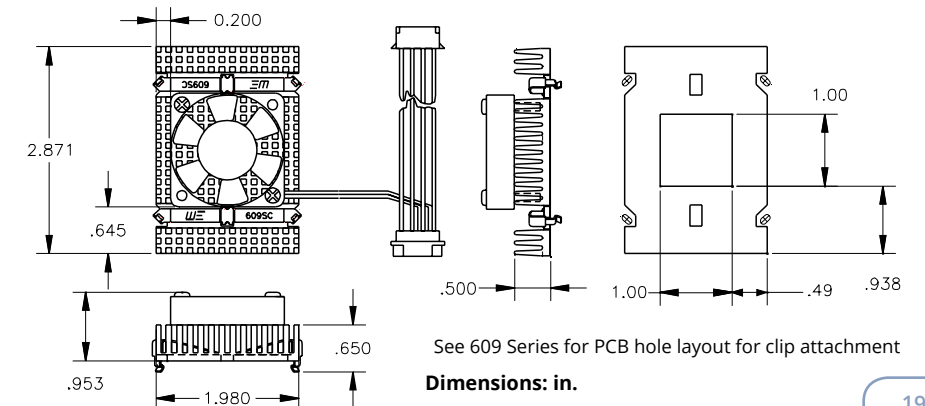
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Typical Applications	Heat Sink Finish	Thermal Performance	Weight lbs.(grams)
61995AB124D1	2.871 (72.92) x 1.98 (50.29)	0.953 (24.21)	40&45mm BGA	Black Anodized	1.2° C/W	.150 (68.10)
61995AB054D1	2.871 (72.92) x 1.98 (50.29)	0.953 (24.21)	40&45mm BGA	Black Anodized	1.2° C/W	.150 (68.10)

**Note:** Optional factory pre-applied thermal interface material. See 609 series.

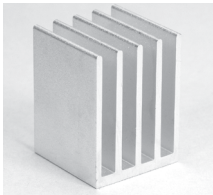
#### FEATURES AND BENEFITS

- Captivated clips for ease of assembly.
- Low acoustic noise.
- Impingement air flow.
- Accommodates BGA packages up to 45 mm in size.

#### MECHANICAL DIMENSIONS



## HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, & FPBGAs

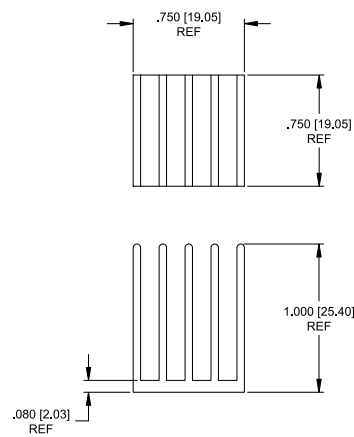


### 602 SERIES

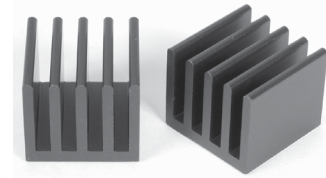
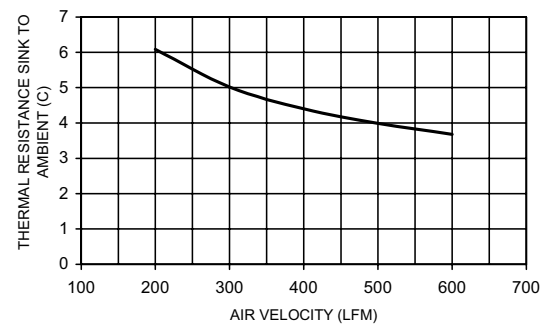
UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
602-100AP	.750 (19.1) sq	1.000 (25.4)	Plain	.021 (9.59)
<b>Material:</b> Aluminum, Plain Finish				

#### MECHANICAL DIMENSIONS



#### 602 THERMAL PERFORMANCE

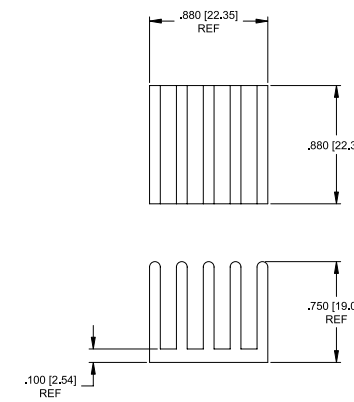


UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

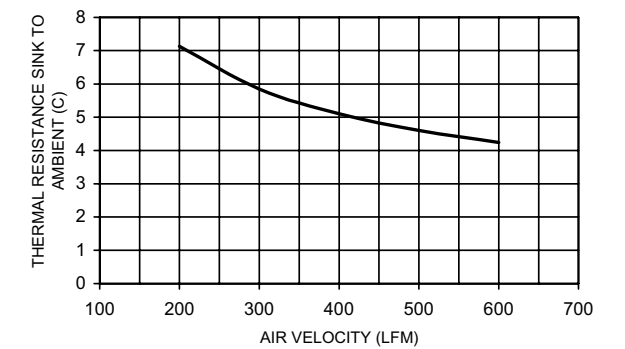
### 605 SERIES

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
605-75AB	.880 (22.4) sq	.750 (19.1)	Black Anodized	.030 (13.5)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS

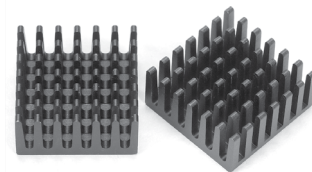


#### 605 THERMAL PERFORMANCE



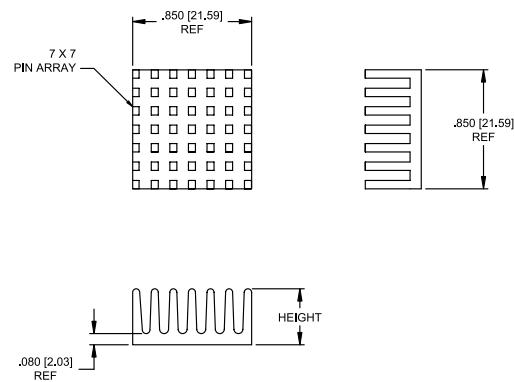
OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs

### 604 SERIES

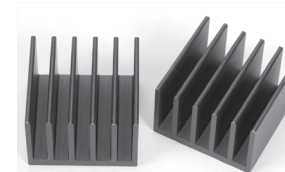
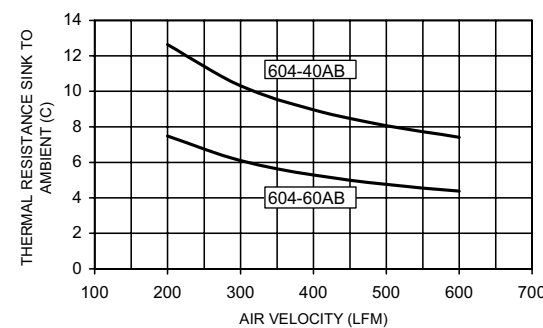


Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
604-40AB	.850 (21.6) sq	.400 (10.2)	Black Anodized	.012 (5.60)
604-60AB	.850 (21.6) sq	.600 (15.2)	Black Anodized	.016 (7.47)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS



#### 604 THERMAL PERFORMANCE

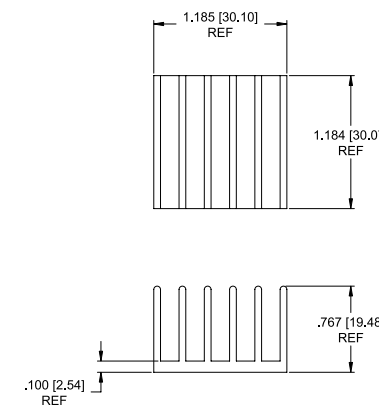


### 606 SERIES

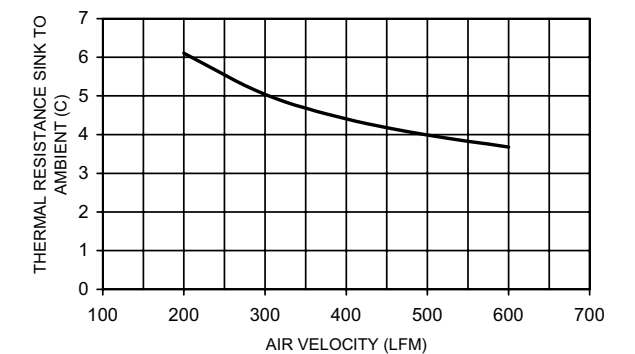
UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
606-77AB	1.185 (30.1) sq	.767 (19.5)	Black Anodized	.041 (18.7)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS



#### 606 THERMAL PERFORMANCE



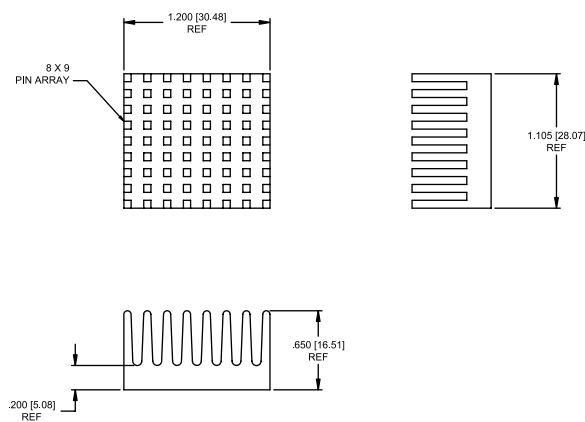
## HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, & FPBGAs

### 607 SERIES

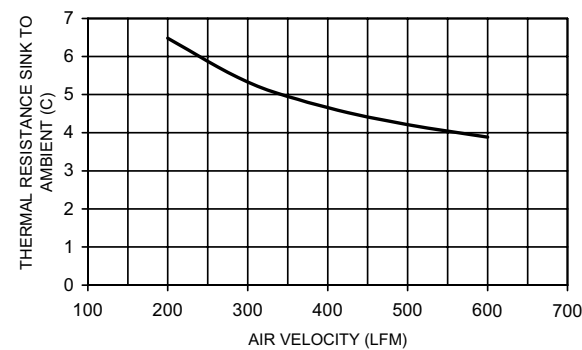
UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
607-65AB	1.200 (30.5) x 1.105 (28.1)	.650 (16.5)	Black Anodized	.041 (18.7)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS



#### 607 THERMAL PERFORMANCE

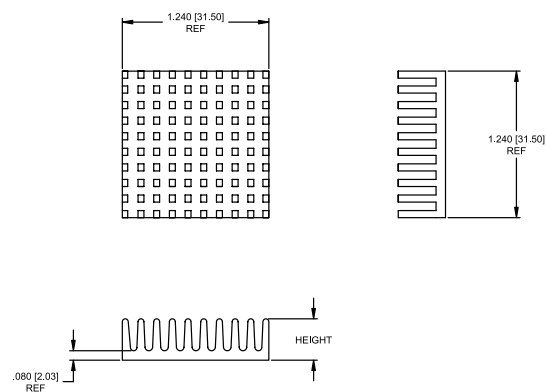


### OMNIDIRECTIONAL PIN FIN HEAT SINK FOR BGAs

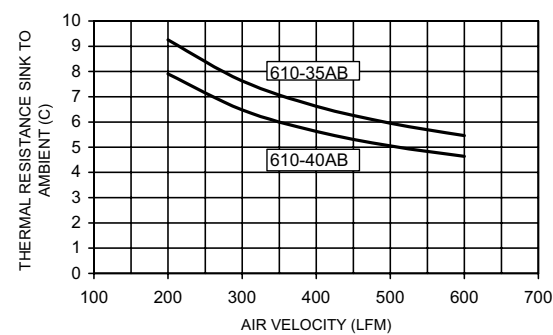
### 610 SERIES

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
610-35AB	1.240 (31.5) sq	.350 (8.9)	Black Anodized	.022 (10.0)
610-40AB	1.240 (31.5) sq	.400 (10.2)	Black Anodized	.024 (10.8)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS



#### 610 THERMAL PERFORMANCE

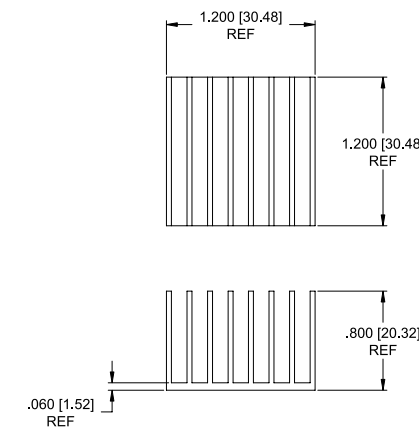


### UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

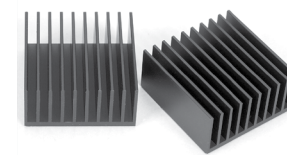
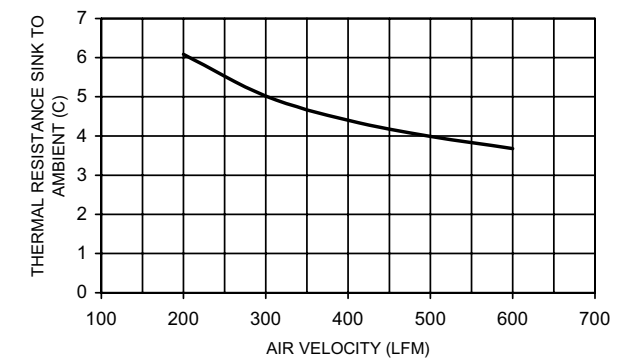
### 611 SERIES

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
611-80AB	1.200 (30.5) sq	.800 (20.3)	Black Anodized	.036 (16.3)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS



#### 611 THERMAL PERFORMANCE

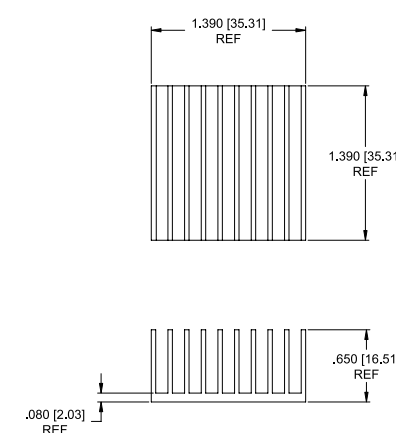


### 612 SERIES

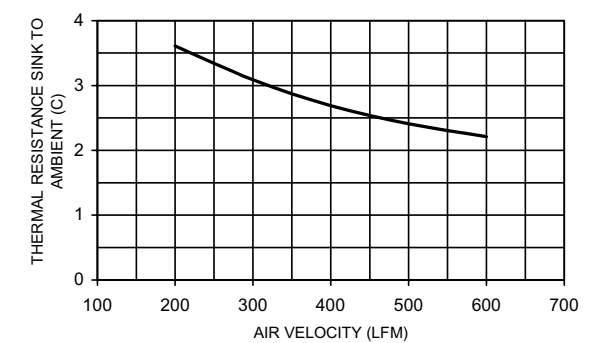
UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
612-65AB	1.390 (35.3) sq	.650 (16.5)	Black Anodized	.054 (24.5)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS



#### 612 THERMAL PERFORMANCE



## HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, & FPBGAs

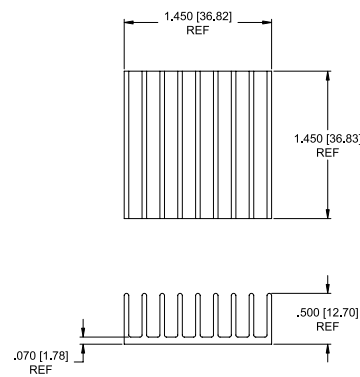
### 613 SERIES

UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

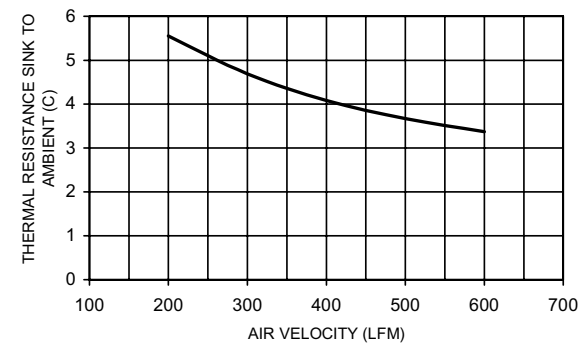
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
613-50AB	1.450 (36.8) sq	.500 (12.7)	Black Anodized	.046 (20.8)

**Material:** Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



#### 613 THERMAL PERFORMANCE



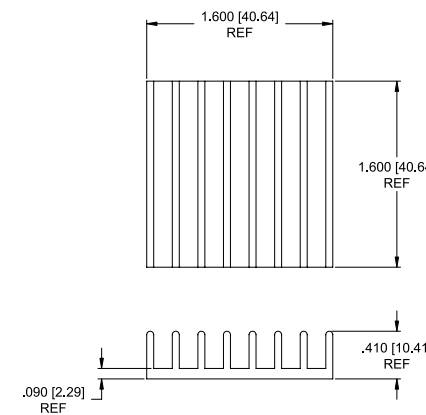
UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

### 615 SERIES

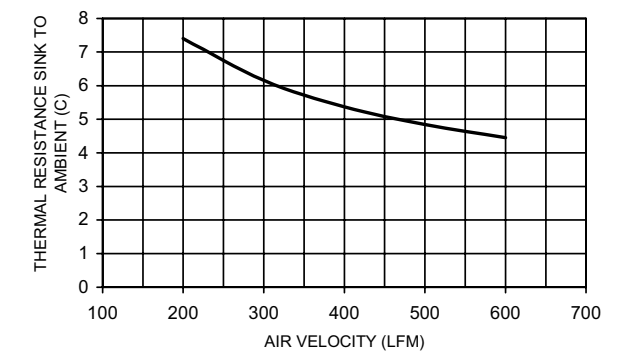
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
615-41AB	1.600 (40.6) sq	.410 (10.4)	Black Anodized	.046 (21.0)

**Material:** Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



#### 615 THERMAL PERFORMANCE



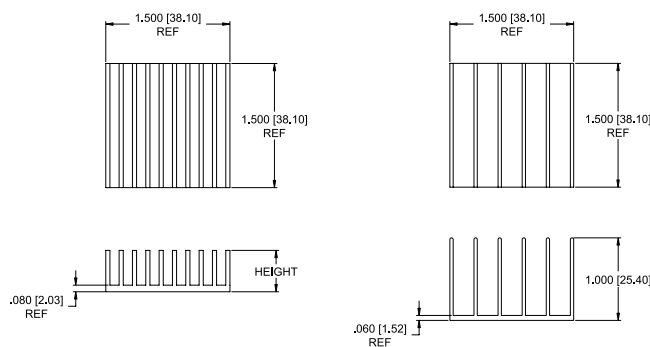
UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

### 614 SERIES

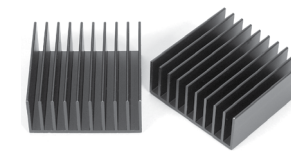
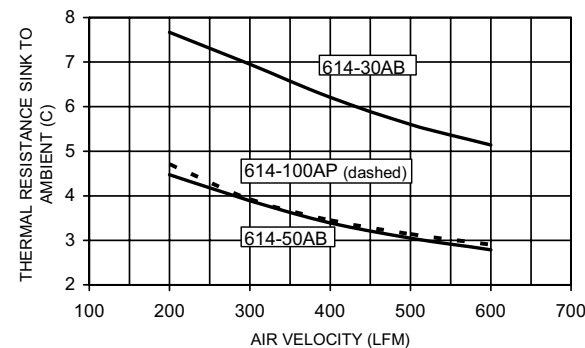
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
614-30AB	1.500 (38.1) sq	.300 (7.6)	Black Anodized	.030 (13.8)
614-50AB	1.500 (38.1) sq	.500 (12.7)	Black Anodized	.048 (21.8)
614-100AP	1.500 (38.1) sq	1.000 (25.4)	Plain	.046 (20.9)

**Material:** Aluminum, Black Anodized or Plain

#### MECHANICAL DIMENSIONS



#### 614 THERMAL PERFORMANCE



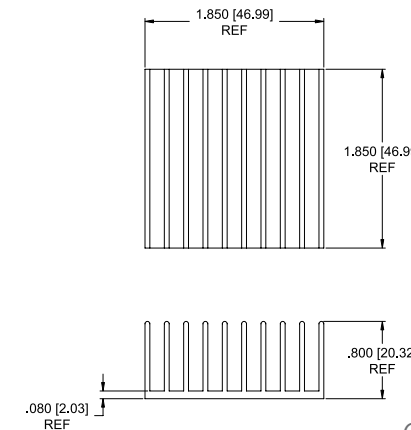
### 616 SERIES

UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

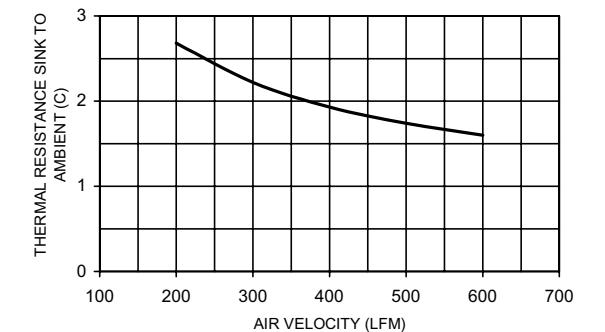
Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
616-80AB	1.85 (47.0) sq	.800 (20.3)	Black Anodized	.054 (24.5)

**Material:** Aluminum, Black Anodized

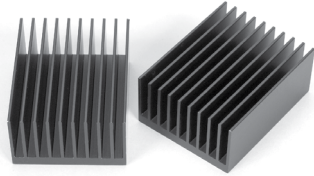
#### MECHANICAL DIMENSIONS



#### 616 THERMAL PERFORMANCE



## HEAT SINKS FOR BGAs, SUPER BGAs, PBGAs, & FPBGAs

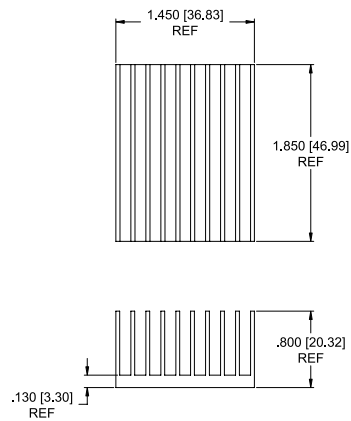


### 617 SERIES

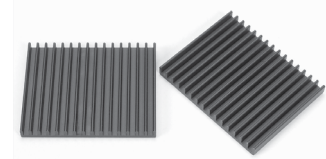
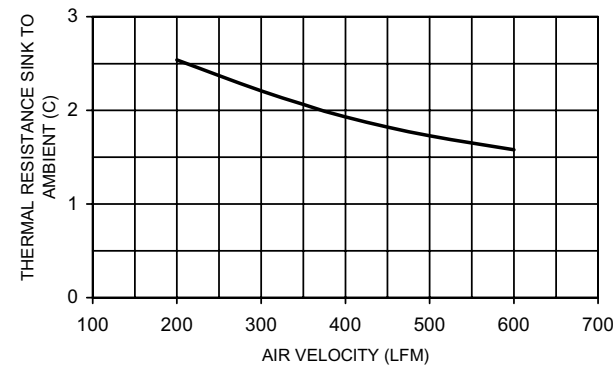
UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
617-80AB	1.450 (36.8) x 1.850 (47.0)	.800 (20.3)	Black Anodized	.082 (37.2)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS



#### 617 THERMAL PERFORMANCE

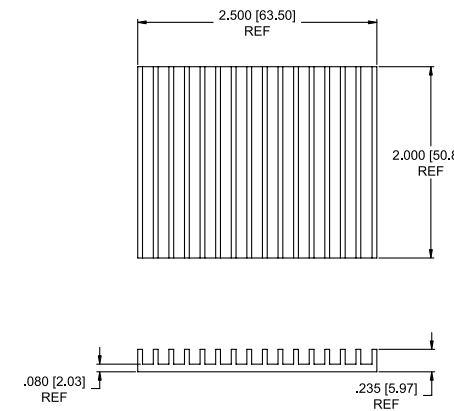


UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

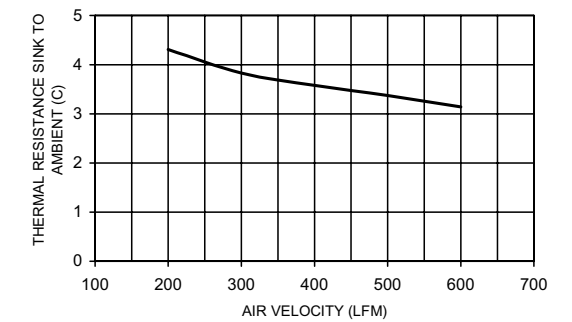
### 620 SERIES

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
620-24AB	2.500 (63.5) x 2.000 (50.8)	.235 (6.0)	Black Anodized	.063 (28.6)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS

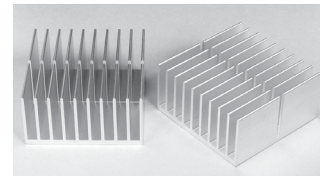


#### 620 THERMAL PERFORMANCE



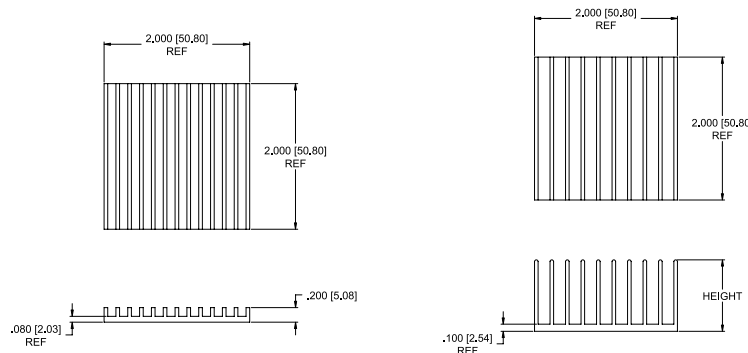
UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

### 618 SERIES

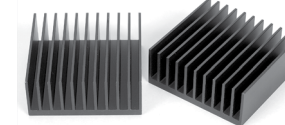
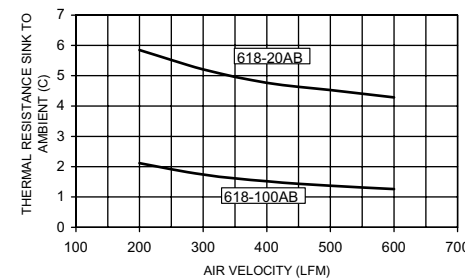


Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
618-20AB	2.00 (50.8) sq	.200 (5.1)	Black Anodized	.046 (21.0)
618-100AP	2.00 (80.8) sq	1.000 (25.4)	Plain	.122 (55.5)
<b>Material:</b> Aluminum, Black Anodized or Plain				

#### MECHANICAL DIMENSIONS



#### 618 THERMAL PERFORMANCE

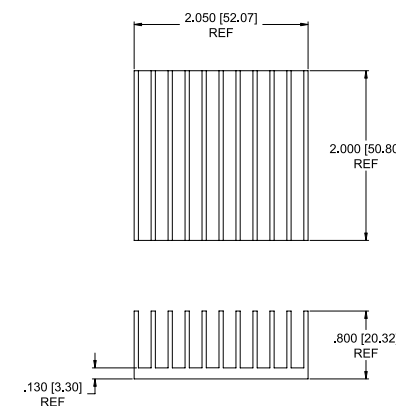


### 622 SERIES

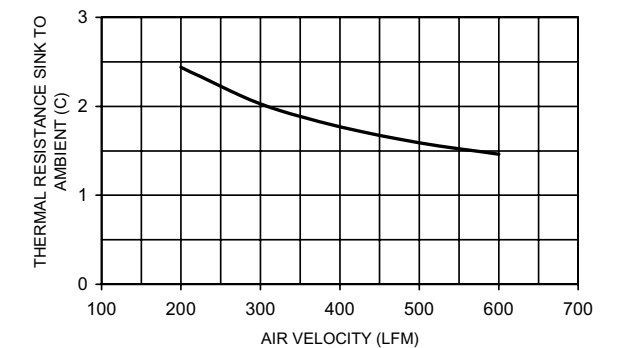
UNIDIRECTIONAL FIN HEAT SINK FOR BGAs

Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Heat Sink Finish	Weight lbs. (grams)
622-80AB	2.050 (52.1) x 2.000 (50.8)	.800 (20.3)	Black Anodized	.123 (56.0)
<b>Material:</b> Aluminum, Black Anodized				

#### MECHANICAL DIMENSIONS



#### 622 THERMAL PERFORMANCE



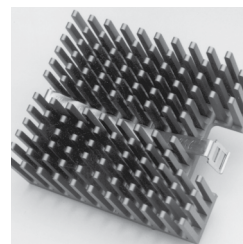
## HEAT SINKS FOR MICROPROCESSORS & ASICs

### 569, 579, 589, 599 SERIES

HEAT SINKS & CLIP FOR INTEL'S PENTIUM, PENTIUM MMX, AMD'S K6 & K62,  
CYRIX'S 6X86 & MEDIA GX, CENTAUR/IDT'S WINCHIP C6

#### PRODUCT FEATURES

- Compact design heat sinks can comfortably fit a variety of Robust Socket 7-based PC boxes.
- Robust clip attachments.
- Clips are not captive to sink.
- To order heat sink with optional interface material pre-applied at the factory, add S4 or S5 suffix to the part number. (See Product Designation)

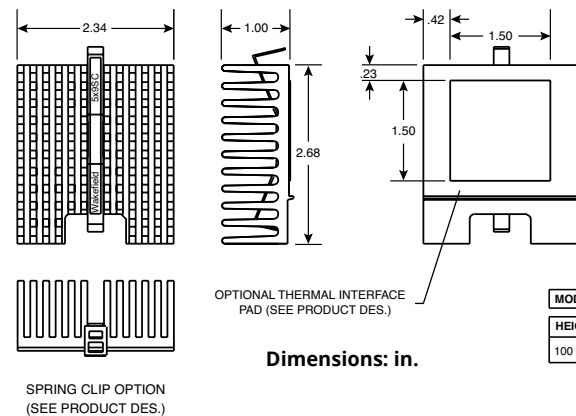


569-100AK SERIES

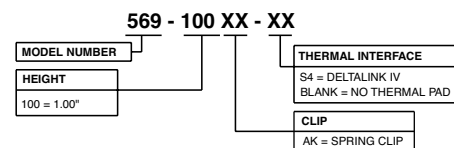
Standard P/N	Base Dimensions in. (mm)	Fin Height in. (mm)	Thermal Resistance at 200 LFM (°C/W)	Interface Material Options
569-100AK	2.34 (59.44) x 2.68 (67.95)	1.00 (25.4)	1.7	Pages 74-76
579-150AK	2.15 (54.71) x 1.95 (49.53)	1.50 (38.10)	1.6	Pages 74-76
589-150AK	2.15 (54.71) x 3.10 (78.74)	1.50 (38.10)	1.5	Pages 74-76
599X-100AB	1.96 (49.78) x 2.67 (67.95)	1.00 (25.4)	1.9	Pages 74-76

**Material:** Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



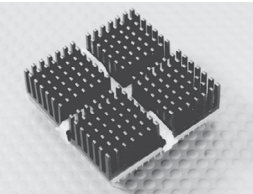
#### PRODUCT DESIGNATION



#### 18 x 18 PGA

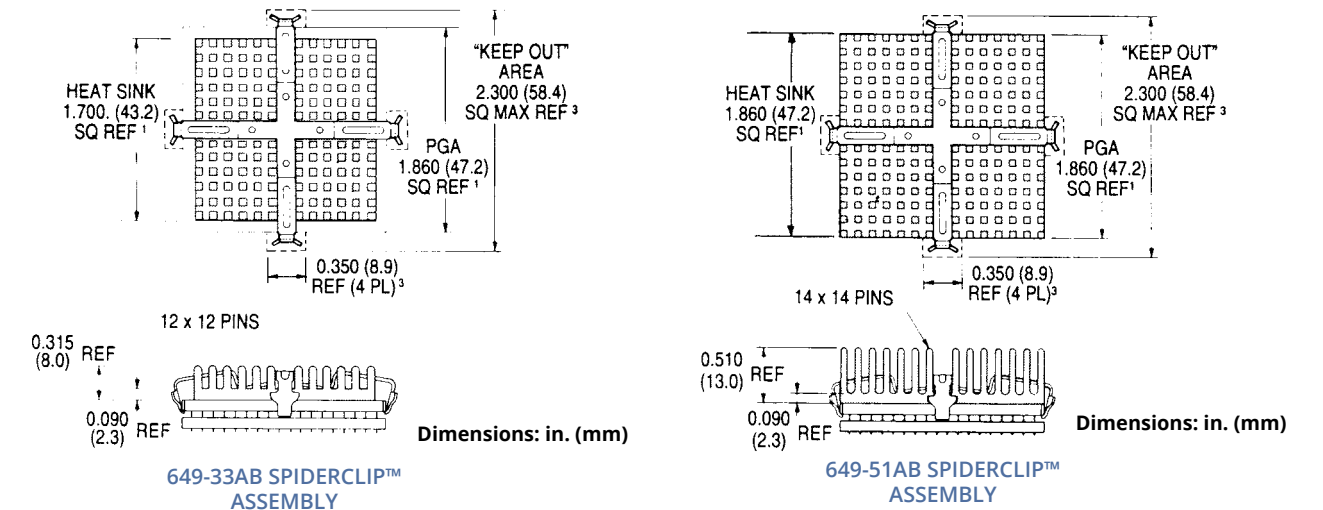
SPIDERCLIP™ HEAT SINK ASSEMBLY  
FOR MOTOROLA MC68040™, MC68060

### 649 SERIES

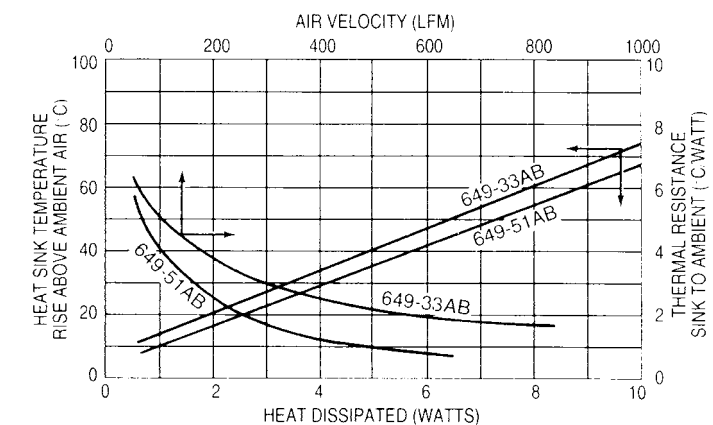


Standard P/N	Base Dimensions in. (mm)	Height in. (mm)	Base Thickness in. (mm)	Clip Color	Heat Sink Finish	Weight lbs. (grams)
649-33AB	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	Gray	Black Anodized	0.044 (19.84)
649-51AB	1.86 (47.2) sq	0.510 (13.0)	0.090 (2.3)	Gray	Black Anodized	0.056 (25.51)

#### MECHANICAL DIMENSIONS



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS

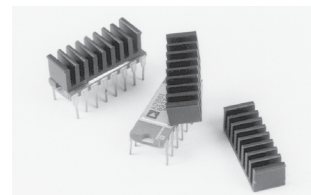


### LOW-COST HEAT SINKS FOR DIPs AND SRAMs

### 650 & 651 SERIES

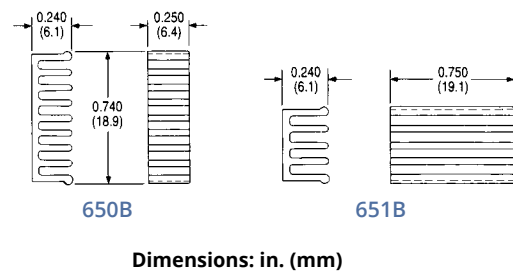
#### 14-16 Pin DIPs

These extruded heat sinks serve as low-cost heat dissipation solutions for DIPs with pin counts from 14 to 16. Use an epoxy such as Wakefield-Vette Engineering DeltaBond™ 152 or 155, or use Wakefield-Vette 2-part DeltaBond™ 156 modified acrylic adhesive. The 650 and 651 are also available in natural aluminum finish. They can be ordered as 650P or 651P.

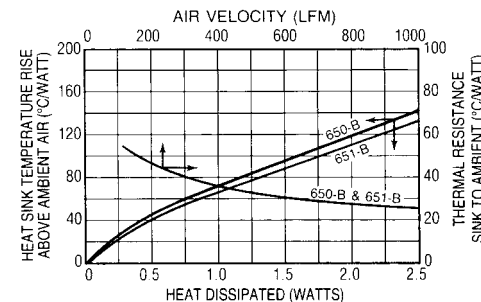


Standard P/N	Length in. (mm)	Width in. (mm)	Height in. (mm)	Typical Applications	Weight lbs. (grams)
650B	0.250 (6.4)	0.740 (18.9)	0.240 (6.1)	14-Pin, 16-Pin DIP	0.003 (1.36)
651B	0.750 (19.1)	0.415 (10.5)	0.240 (6.1)	14-Pin, 16-Pin DIP	0.005 (2.27)

#### MECHANICAL DIMENSIONS



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



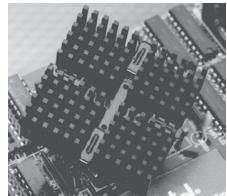
#### NOTES:

1. Finish: black anodize
2. TIR: Total Indicator Reading. This is a measure of flatness across the greatest dimension of a surface.



## HEAT SINKS FOR MICROPROCESSORS & ASICs

## PIN FIN HEAT SINK



### 669 SERIES

SPIDERCLIP™ HEAT SINK ASSEMBLY FOR INTEL DX4™, AMD AM486DX2, AND AM486DX4

17 x 17 SPGA

### 661 SERIES

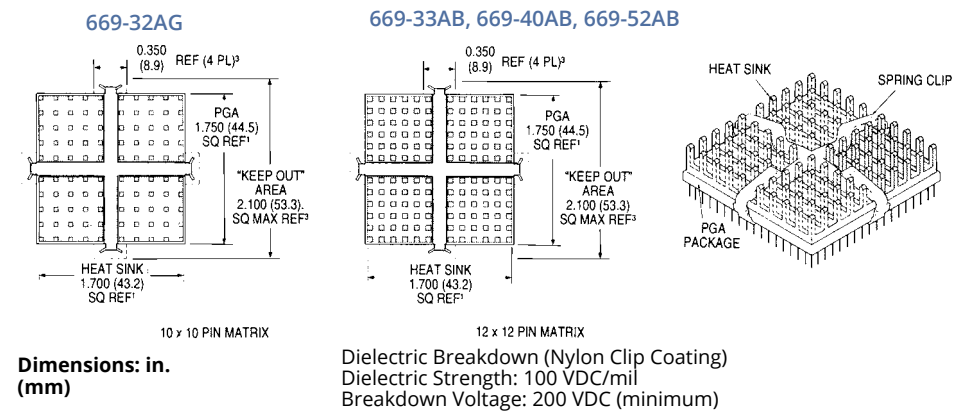
HEAT SINK WITHOUT CLIP

669 Series SpiderClip™ Heat Sink Assemblies may be applied to the following:

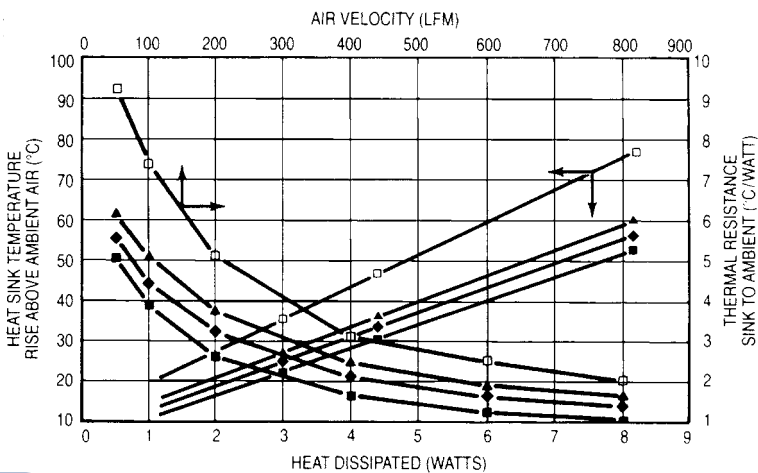
- Intel 80486DX and 80486DX2™ (168 PGA)
- Intel DX4™ (168 PGA)
- Intel 80486SX (168 PGA) and I860XR (208 PGA)
- AMD Am 486 Microprocessors AM486DX2, AM486DX4
- Intel 82495 Cache Controller
- AMD Am 29000 Microcontrollers
- Intel I960CA, I960CF Embedded Controllers

Standard P/N	Base Dimensions in. (mm)	Dimensions "A" Height in. (mm)	Base Thickness in. (mm)	Clip Color	Standard Finish	Weight lbs. (grams)
669-32AG	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	Black	Gold Iridite	0.044 (19.84)
669-33AB	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	Black	Black Anodized	0.044 (19.84)
669-40AB	1.70 (43.2) sq	0.400 (10.2)	0.090 (2.3)	Black	Black Anodized	0.044 (19.84)
669-52AB	1.70 (43.2) sq	0.520 (13.2)	0.090 (2.3)	Black	Black Anodized	0.050 (22.68)
661-32AG	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	N/A	Gold Iridite	0.044 (19.84)
661-33AB	1.70 (43.2) sq	0.315 (8.0)	0.090 (2.3)	N/A	Black Anodized	0.044 (19.84)
661-40AB	1.70 (43.2) sq	0.400 (10.2)	0.090 (2.3)	N/A	Black Anodized	0.044 (19.84)
661-52AB	1.70 (43.2) sq	0.520 (13.2)	0.090 (2.3)	N/A	Black Anodized	0.050 (22.68)

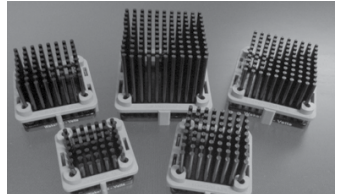
### MECHANICAL DIMENSIONS



### NATURAL AND FORCED CONVECTION CHARACTERISTICS



### 900 SERIES



Wakefield-Vette's **900 Series** Heat Sinks for Chipset can match up to devices from Intel, Xilinx, TI, Motorola, ATI, AMD, Nvidia, Vishay, Powerex, Infineon, Microsemi, and many more.

These heat sinks are designed for air flow applications in the Telecom, Data Center, Networking, Cloud Computing, and many more Industries.

Series	Height	Chip Size	Natural Convection	Forced Convection			Series	Height	Chip Size	Natural Convection	Forced Convection		
				200 LFM	400 LFM	600 LFM					200 LFM	400 LFM	600 LFM
901	12	19mm	12.74 C/W	6.6 C/W	4.79 C/W	4.16 C/W	906	12	31mm	10.71 C/W	3.49 C/W	2.28 C/W	1.69 C/W
	15	19mm	12.05 C/W	6.3 C/W	4.51 C/W	3.86 C/W		15	31mm	10.14 C/W	3.18 C/W	2.03 C/W	1.5 C/W
	18	19mm	11.35 C/W	5.97 C/W	4.16 C/W	3.47 C/W		18	31mm	9.57 C/W	2.93 C/W	1.86 C/W	1.33 C/W
	21	19mm	10.66 C/W	5.66 C/W	3.89 C/W	3.21 C/W		21	31mm	9.01 C/W	2.72 C/W	1.69 C/W	1.2 C/W
	23	19mm	10.55 C/W	5.36 C/W	3.64 C/W	2.99 C/W		23	31mm	8.88 C/W	2.5 C/W	1.54 C/W	1.07 C/W
	28	19mm	10.27 C/W	4.91 C/W	3.36 C/W	2.71 C/W		28	31mm	8.56 C/W	2.26 C/W	1.38 C/W	.96 C/W
902	33	19mm	9.99 C/W	4.52 C/W	3.07 C/W	2.49 C/W	33	31mm	8.24 C/W	2.09 C/W	1.27 C/W	.88 C/W	
	12	21mm	12.4 C/W	6.61 C/W	4.37 C/W	3.7 C/W	907	12	33mm	10.37 C/W	3.32 C/W	2.18 C/W	1.62 C/W
	15	21mm	11.73 C/W	5.84 C/W	4.09 C/W	3.42 C/W		15	33mm	9.82 C/W	3.14 C/W	1.99 C/W	1.45 C/W
	18	21mm	11.06 C/W	5.51 C/W	3.76 C/W	3.07 C/W		18	33mm	9.28 C/W	2.89 C/W	1.78 C/W	1.3 C/W
	21	21mm	10.38 C/W	5.20 C/W	3.49 C/W	2.84 C/W		21	33mm	8.73 C/W	2.67 C/W	1.60 C/W	1.13 C/W
	23	21mm	10.27 C/W	4.9 C/W	3.26 C/W	2.62 C/W		23	33mm	8.60 C/W	2.45 C/W	1.43 C/W	.99 C/W
28	21mm	9.98 C/W	4.55 C/W	2.98 C/W	2.42 C/W	28		33mm	8.27 C/W	2.24 C/W	1.28 C/W	.87 C/W	
903	33	21mm	9.7 C/W	4.18 C/W	2.73 C/W	2.21 C/W	33	33mm	7.94 C/W	2.03 C/W	1.15 C/W	.77 C/W	
	12	23mm	12.06 C/W	5.72 C/W	3.95 C/W	3.24 C/W	908	12	35mm	10.03 C/W	3.06 C/W	1.97 C/W	1.49 C/W
	15	23mm	11.41 C/W	5.39 C/W	3.67 C/W	2.99 C/W		15	35mm	9.5 C/W	2.85 C/W	1.81 C/W	1.34 C/W
	18	23mm	10.76 C/W	5.05 C/W	3.35 C/W	2.67 C/W		18	35mm	8.98 C/W	2.6 C/W	1.64 C/W	1.19 C/W
	21	23mm	10.11 C/W	4.74 C/W	3.1 C/W	2.46 C/W		21	35mm	8.46 C/W	2.4 C/W	1.5 C/W	1.07 C/W
	23	23mm	9.99 C/W	4.44 C/W	2.87 C/W	2.31 C/W		23	35mm	8.32 C/W	2.19 C/W	1.34 C/W	.97 C/W
28	23mm	9.70 C/W	4.09 C/W	2.62 C/W	2.12 C/W	28		35mm	7.99 C/W	1.97 C/W	1.19 C/W	.83 C/W	
904	33	23mm	9.41 C/W	3.83 C/W	2.43 C/W	1.96 C/W	33	35mm	7.65 C/W	1.82 C/W	1.06 C/W	.7 C/W	
	12	27mm	11.38 C/W	4.84 C/W	3.11 C/W	2.32 C/W	909	12	37.5mm	9.60 C/W	2.93 C/W	1.90 C/W	1.36 C/W
	15	27mm	10.78 C/W	4.48 C/W	2.84 C/W	2.12 C/W		15	37.5mm	9.11 C/W	2.71 C/W	1.72 C/W	1.19 C/W
	18	27mm	10.17 C/W	4.13 C/W	2.56 C/W	1.88 C/W		18	37.5mm	8.61 C/W	2.52 C/W	1.53 C/W	1.05 C/W
	21	27mm	9.56 C/W	3.82 C/W	2.32 C/W	1.72 C/W		21	37.5mm	8.11 C/W	2.25 C/W	1.36 C/W	.88 C/W
	23	27mm	9.44 C/W	3.51 C/W	2.11 C/W	1.6 C/W		23	37.5mm	7.98 C/W	2.04 C/W	1.2 C/W	.75 C/W
28	27mm	9.13 C/W	3.26 C/W	1.97 C/W	1.49 C/W	28		37.5mm	7.63 C/W	1.82 C/W	1.01 C/W	.63 C/W	
905	33	27mm	8.82 C/W	3.07 C/W	1.82 C/W	1.39 C/W	33	37.5mm	7.29 C/W	1.6 C/W	.87 C/W	.52 C/W	
	12	29mm	11.04 C/W	4.08 C/W	2.55 C/W	1.98 C/W	910	12	40mm	9.18 C/W	2.84 C/W	1.86 C/W	1.36 C/W
	15	29mm	10.46 C/W	3.82 C/W	2.32 C/W	1.78 C/W		15	40mm	8.71 C/W	2.64 C/W	1.65 C/W	1.18 C/W
	18	29mm	9.87 C/W	3.58 C/W	2.14 C/W	1.58 C/W		18	40mm	8.24 C/W	2.4 C/W	1.44 C/W	.98 C/W
	21	29mm	9.28 C/W	3.33 C/W	1.96 C/W	1.44 C/W		21	40mm	7.77 C/W	2.21 C/W	1.27 C/W	.86 C/W
	23	29mm	9.16 C/W	3.13 C/W	1.82 C/W	1.34 C/W		23	40mm	7.63 C/W	2 C/W	1.15 C/W	.73 C/W
28	29mm	8.84 C/W	2.82 C/W	1.64 C/W	1.2 C/W	28		40mm	7.27 C/W	1.77 C/W	.99 C/W	.62 C/W	

Material: AL 6063  
Finish: Black Anodize

Series	Chip Size	Construction	Height	Chip Height	Finish	Interface
901	19-	2= Pin Fin	12= 11.6 15= 14.6 18= 17.6 21= 20.6 23= 22.6 28= 27.6 33= 32.6	1= .9-2.1 2= 2.2-3.4	B= BLK ANO	0= None 1= T725
	21					
	23					
	27					
	29					
	31					
	33					
	35					
	37.5					

Refer to Page 33 for  
Installation Instructions

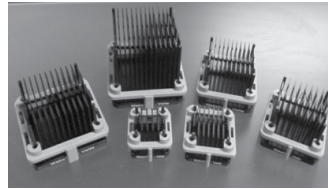
## ELLIPTICAL FIN HEAT SINK

### 900 SERIES



Wakefield-Vette's **900 Series** Heat Sinks for Chipset can match up to devices from Intel, Xilinx, TI, Motorola, ATI, AMD, Nvidia, Vishay, Powerex, Infineon, Microsemi, and many more.

These heat sinks are designed for air flow applications in the Telecom, Data Center, Networking, Cloud Computing, and many more Industries.



Series	Height	Chip Size	Natural Convection	Forced Convection			Series	Height	Chip Size	Natural Convection	Forced Convection		
				200 LFM	400 LFM	600 LFM					200 LFM	400 LFM	600 LFM
901	12	19mm	12.74 C/W	6.6 C/W	4.79 C/W	4.16 C/W	906	12	31mm	10.71 C/W	3.49 C/W	2.28 C/W	1.69 C/W
	15	19mm	12.05 C/W	6.3 C/W	4.51 C/W	3.86 C/W		15	31mm	10.14 C/W	3.18 C/W	2.03 C/W	1.5 C/W
	18	19mm	11.35 C/W	5.97 C/W	4.16 C/W	3.47 C/W		18	31mm	9.57 C/W	2.93 C/W	1.86 C/W	1.33 C/W
	21	19mm	10.66 C/W	5.66 C/W	3.89 C/W	3.21 C/W		21	31mm	9.01 C/W	2.72 C/W	1.69 C/W	1.2 C/W
	23	19mm	10.55 C/W	5.36 C/W	3.64 C/W	2.99 C/W		23	31mm	8.88 C/W	2.5 C/W	1.54 C/W	1.07 C/W
	28	19mm	10.27 C/W	4.91 C/W	3.36 C/W	2.71 C/W		28	31mm	8.56 C/W	2.26 C/W	1.38 C/W	.96 C/W
	33	19mm	9.99 C/W	4.52 C/W	3.07 C/W	2.49 C/W	33	31mm	8.24 C/W	2.09 C/W	1.27 C/W	.88 C/W	
902	12	21mm	12.4 C/W	6.61 C/W	4.37 C/W	3.7 C/W	907	12	33mm	10.37 C/W	3.32 C/W	2.18 C/W	1.62 C/W
	15	21mm	11.73 C/W	5.84 C/W	4.09 C/W	3.42 C/W		15	33mm	9.82 C/W	3.14 C/W	1.99 C/W	1.45 C/W
	18	21mm	11.06 C/W	5.51 C/W	3.76 C/W	3.07 C/W		18	33mm	9.28 C/W	2.89 C/W	1.78 C/W	1.3 C/W
	21	21mm	10.38 C/W	5.20 C/W	3.49 C/W	2.84 C/W		21	33mm	8.73 C/W	2.67 C/W	1.60 C/W	1.13 C/W
	23	21mm	10.27 C/W	4.9 C/W	3.26 C/W	2.62 C/W		23	33mm	8.60 C/W	2.45 C/W	1.43 C/W	.99 C/W
	28	21mm	9.98 C/W	4.55 C/W	2.98 C/W	2.42 C/W		28	33mm	8.27 C/W	2.24 C/W	1.28 C/W	.87 C/W
	33	21mm	9.7 C/W	4.18 C/W	2.73 C/W	2.21 C/W	33	33mm	7.94 C/W	2.03 C/W	1.15 C/W	.77 C/W	
903	12	23mm	12.06 C/W	5.72 C/W	3.95 C/W	3.24 C/W	908	12	35mm	10.03 C/W	3.06 C/W	1.97 C/W	1.49 C/W
	15	23mm	11.41 C/W	5.39 C/W	3.67 C/W	2.99 C/W		15	35mm	9.5 C/W	2.85 C/W	1.81 C/W	1.34 C/W
	18	23mm	10.76 C/W	5.05 C/W	3.35 C/W	2.67 C/W		18	35mm	8.98 C/W	2.6 C/W	1.64 C/W	1.19 C/W
	21	23mm	10.11 C/W	4.74 C/W	3.1 C/W	2.46 C/W		21	35mm	8.46 C/W	2.4 C/W	1.5 C/W	1.07 C/W
	23	23mm	9.99 C/W	4.44 C/W	2.87 C/W	2.31 C/W		23	35mm	8.32 C/W	2.19 C/W	1.34 C/W	.97 C/W
	28	23mm	9.70 C/W	4.09 C/W	2.62 C/W	2.12 C/W		28	35mm	7.99 C/W	1.97 C/W	1.19 C/W	.83 C/W
	33	23mm	9.41 C/W	3.83 C/W	2.43 C/W	1.96 C/W	33	35mm	7.65 C/W	1.82 C/W	1.06 C/W	.7 C/W	
904	12	27mm	11.38 C/W	4.84 C/W	3.11 C/W	2.32 C/W	909	12	37.5mm	9.60 C/W	2.93 C/W	1.90 C/W	1.36 C/W
	15	27mm	10.78 C/W	4.48 C/W	2.84 C/W	2.12 C/W		15	37.5mm	9.11 C/W	2.71 C/W	1.72 C/W	1.19 C/W
	18	27mm	10.17 C/W	4.13 C/W	2.56 C/W	1.88 C/W		18	37.5mm	8.61 C/W	2.52 C/W	1.53 C/W	1.05 C/W
	21	27mm	9.56 C/W	3.82 C/W	2.32 C/W	1.72 C/W		21	37.5mm	8.11 C/W	2.25 C/W	1.36 C/W	.88 C/W
	23	27mm	9.44 C/W	3.51 C/W	2.11 C/W	1.6 C/W		23	37.5mm	7.98 C/W	2.04 C/W	1.2 C/W	.75 C/W
	28	27mm	9.13 C/W	3.26 C/W	1.97 C/W	1.49 C/W		28	37.5mm	7.63 C/W	1.82 C/W	1.01 C/W	.63 C/W
	33	27mm	8.82 C/W	3.07 C/W	1.82 C/W	1.39 C/W	33	37.5mm	7.29 C/W	1.6 C/W	.87 C/W	.52 C/W	
905	12	29mm	11.04 C/W	4.08 C/W	2.55 C/W	1.98 C/W	910	12	40mm	9.18 C/W	2.84 C/W	1.86 C/W	1.36 C/W
	15	29mm	10.46 C/W	3.82 C/W	2.32 C/W	1.78 C/W		15	40mm	8.71 C/W	2.64 C/W	1.65 C/W	1.18 C/W
	18	29mm	9.87 C/W	3.58 C/W	2.14 C/W	1.58 C/W		18	40mm	8.24 C/W	2.4 C/W	1.44 C/W	.98 C/W
	21	29mm	9.28 C/W	3.33 C/W	1.96 C/W	1.44 C/W		21	40mm	7.77 C/W	2.21 C/W	1.27 C/W	.86 C/W
	23	29mm	9.16 C/W	3.13 C/W	1.82 C/W	1.34 C/W		23	40mm	7.63 C/W	2 C/W	1.15 C/W	.73 C/W
	28	29mm	8.84 C/W	2.82 C/W	1.64 C/W	1.2 C/W		28	40mm	7.27 C/W	1.77 C/W	.99 C/W	.62 C/W
	33	29mm	8.53 C/W	2.59 C/W	1.47 C/W	1.07 C/W	33	40mm	6.92 C/W	1.58 C/W	.85 C/W	.51 C/W	

Material: AL 6063  
Finish: Black Anodize

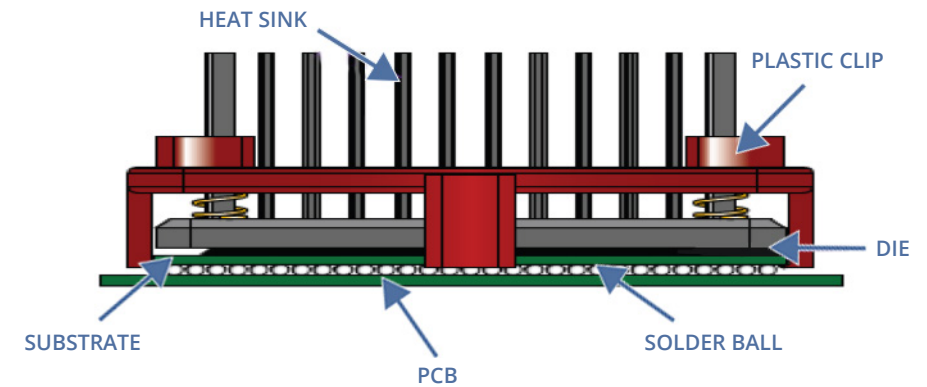
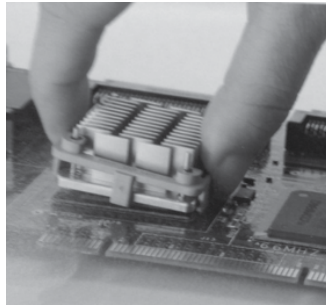
Series	Chip Size	Construction	Height	Chip Height	Finish	Interface
901-	19-	1-	12-	1-	B-	1
XXX	XX	X	XX	X	X	X
901	19	1= Elliptical Fin	12 = 11.6	1 = .9-2.1	B = BLK ANO	0 = None
902	21	2= Pin Fin	15 = 14.6	2 = 2.2-3.4		1 = T725
903	23		18 = 17.6			
904	27		21 = 20.6			
905	29		23 = 22.6			
906	31		28 = 27.6			
907	33		33 = 32.6			
908	35					
909	37.5					
910	40					

Refer to Page 33 for  
Installation Instructions

## PIN FIN & ELLIPTICAL FIN HEAT SINK

### 900 SERIES

Wakefield-Vette's heat sink assembles onto chip set using the space that is between the PCB and the substrate of the solder balls. The solder balls provide a minimal gap of .5mm to .7mm. Attachment feature is below .4mm thickness. The clipping system will not interfere or damage chip. Contact area is the edge of chip.



### ASSEMBLY INSTRUCTIONS:

**Step 1**  
Hook the clip under one side of the BGA chip set.

**Step 2**  
Rotate assembly down until opposite side clip engages substrate edge of BGA chip set.

**Step 3**  
Make sure the solder rods are clearing from edges of BGA chip set.

**Step 4**  
Press firmly down to make sure clips fully engage edges of chip set. Heat Sink should not move around easily.

### RANDOM VIBRATION TEST

Frequency: 5 Hz to 500 Hz  
Acceleration: 3.13 grms  
P.S.D: 0.01 g<sup>2</sup>/HZ (5 Hz)  
0.02 g<sup>2</sup>/HZ (20 Hz to 500 Hz)  
Test Axis: X, Y, Z axis  
Test Time: 10 mins (Each axis)  
Total Test Time: 30 mins

### SHOCK TEST SPECIFICATION:

Wave Form: Half sine wave  
Acceleration: 50 g  
Duration Time: 11 ms  
No. of Shock: Each axis 3 times  
Shock Direction: ±X, ±Y, ±Z axis  
Reliability & Communication Testing Instruments

## CERAMIC HEAT SINK FOR TO DEVICES W/ omniKlip



### CE-OMNI-38 HEAT SINK



Wakefield-Vette introduces heat sinks made from alumina and aluminum nitride for thermal management of high-power/ voltage electronics, photovoltaic, LED, power resistors and other applications. While electrically insulating and thermally conducting, the ceramic heat sink is an effective combination for the circuit board and heat sink reliability of cooling thermally sensitive components and circuits. The power chip dies can be directly bonded onto ceramic heat sink as a module substrate to eliminate the thermal barriers to quickly dissipate the generated heat. These heat sinks extend component life and enhance performance.

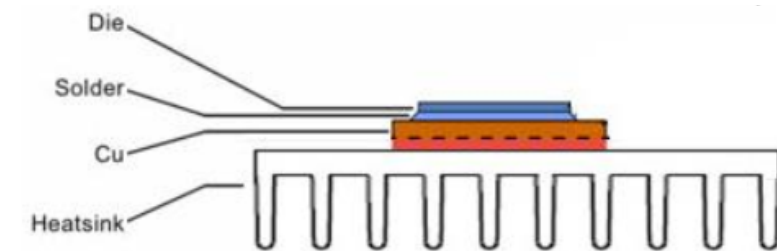
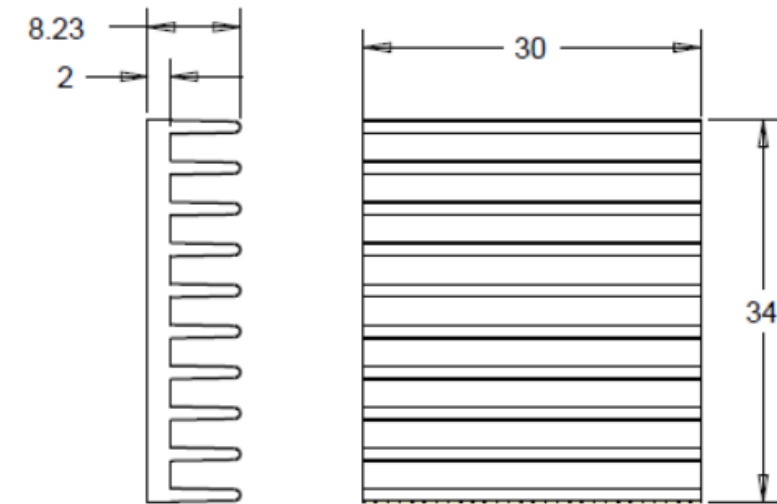
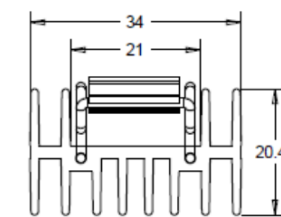
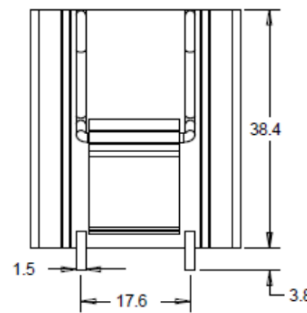
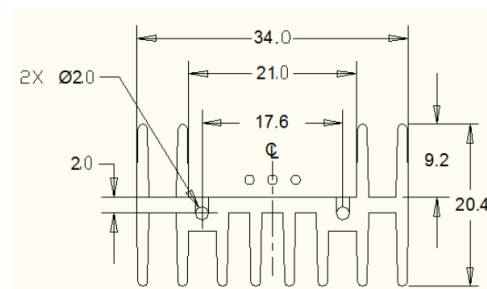
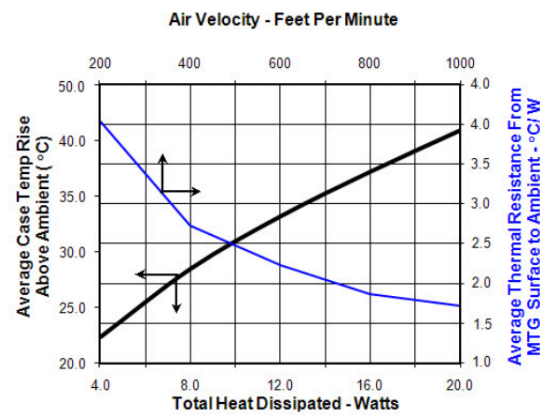
omniKlip™

#### FEATURES

- An innovative ceramic (Patent Pending) heat sink with unique design combines the tin plated solderable integral omniKlip spring with a molded aluminum oxide (Al<sub>2</sub>O<sub>3</sub>) or aluminum nitride (AlN) heat sink body to be mountable onto the PCB directly with no other fasteners needed. Unlike any others, this type of heat sink provides ease of assembly and an all-in-one solution (one part does all). It can be used with different package devices, such as TO-220, TO-247, TO-264 and TO-218 package, etc. series power devices with either natural or forced convection cooling.

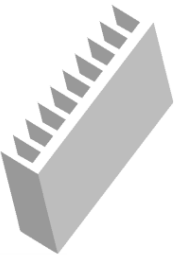
WkV Part Number	Description	Package Cooled	Attachment Method	Length	Width	Height Off Base (Fin Height)	Thermal Resistance @ Forced Air Flow	Thermal Resistance @ Natural
CE-OMNI-38	Ceramic Heat Sink for TO Devices w/omniKlip	TO-220, TO-247	Solderable Feet	38.4mm	34mm	9.2mm	3.8°C/W @ 200 LFM	7.0°C/W @ 200 LFM

Material: 95% Al<sub>2</sub>O<sub>3</sub>, Surface Area: 11,408mm<sup>2</sup>, Weight: 22 g  
RoHS Compliant



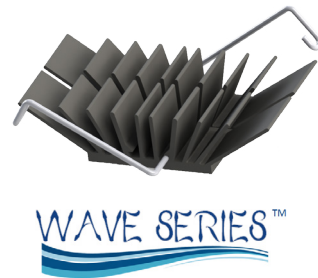
Material: 95% Al<sub>2</sub>O<sub>3</sub>, Surface Area: 5,979mm<sup>2</sup>, Weight: 15 g

Common Ceramic Heat sinks are a rectangular or square shape ceramic as commonly seen in an extrusion heat sink that provides the most common use in cooling. It can be used as Chip-on-heat-sink (on the metalized surface) and makes it possible to achieve an extremely compact design for the entire cooling system. Using ceramic as the material for a heat sink ensures outstanding thermal conductivity and electrical insulation; the closer it is used to a source of heat, the greater the cooling advantage it offers.



Additional Configurations & Custom Ceramic Heat Sinks  
Contact Wakefield-Vette for more information or visit [www.wakefield-vette.com](http://www.wakefield-vette.com)

# WAVE SERIES HEAT SINK WITH INTEGRATED CLIP ASSEMBLY



## WAVE SERIES BGA HEAT SINKS



The Wakefield-Vette **Wave Series Heat Sink Series** are a superior choice for cooling BGA applications in which limited height/footprint while achieving maximum surface area. The Wave Series Heat Sinks include a unique clipping mechanism that allows for superior heat transfer while securing the heat sink to the BGA itself. The clipping mechanism allows for easy installation in high production assembly.

### FEATURES AND BENEFITS

- Approximately 12% better thermal performance than traditional footprint heat sinks.
- Height- A low profile design allows for more surface area in a height restricted application.
- Clipping mechanism included with heat sink.
- Surface Area - Fin array allows for more surface area for forced convection.
- Easily customizable.
- Easily compatible with major BGA device manufacturers components such as: Motorola, Freescale, TI, Intel, etc.

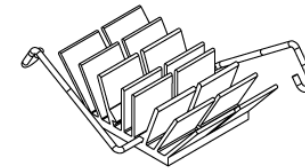
WkV Part Number	Description	Attachment Method	Mechanical Dimensions (mm)						Thermal Resistance - Forced Conv. @ 200 LFM
			Length	Width	Fin Width	Height	Surface Area (sq mm)	Height Off Base (Fin Height)	
WAVE-23-125	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	23	23	40	12.5	6055.1	10.5	6.76
WAVE-23-165	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	23	23	46.5	16.5	7634.6	14.5	5.08
WAVE-26-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	26	26	52.9	12	8305.2	10	5.21
WAVE-29-127	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	29	29	61.4	12.7	11810.5	10.7	4.08
WAVE-32-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	32	32	50.2	12	10957.5	10	4.64
WAVE-34-21	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	34	34	70	21	21268.4	19	2.19
WAVE-35-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	35	35	62	12	15180.8	10	3.83
WAVE-35-125	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	35	35	63.3	12.5	15792.6	10.5	3.63
WAVE-35-15	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	35	35	58.1	15	15612.7	13	3.15
WAVE-35-21	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	35	35	74.6	21	21721.8	19	2.11
WAVE-366-175	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	36.6	36.6	63.6	17.5	18637.8	15.5	2.55
WAVE-40-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	40	40	66.9	12	17689.4	10	3.36
WAVE-40-125	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	40	40	68.3	12.5	18410.1	10.5	3.16
WAVE-425-117	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	42.5	42.5	67.4	11.7	21668.3	9.3	3.40
WAVE-45-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	45	45	72	12	22303.7	10	2.96

**Material Specifications:** Heat Sink: Aluminum Alloy 6063-T5 with black anodized finish. Spring Clip: 304 Stainless Steel, 1.2mm [0.47"] DIA  
RoHS Compliant

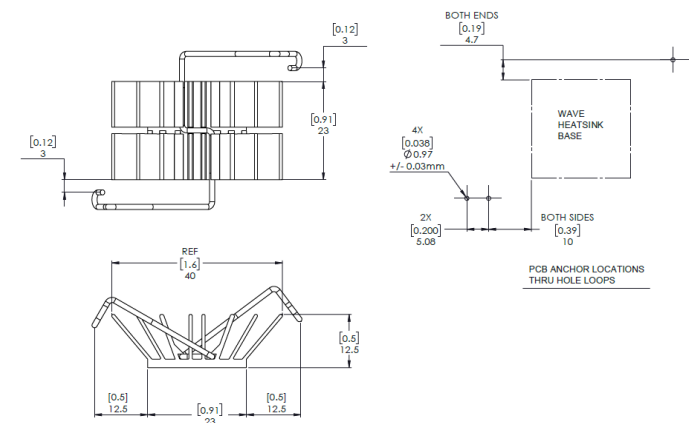
## BGA HEAT SINKS WAVE 2X SERIES

WkV Part Number	Description	Attachment Method	Mechanical Dimensions (mm)						Thermal Resistance - Forced Conv. @ 200 LFM
			Length	Width	Fin Width	Height	Surface Area (sq mm)	Height Off Base (Fin Height)	
WAVE-23-125	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	23	23	40	12.5	6055.1	10.5	6.76
WAVE-23-165	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	23	23	46.5	16.5	7634.6	14.5	5.08

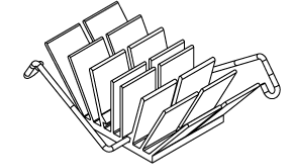
### WAVE-23-125



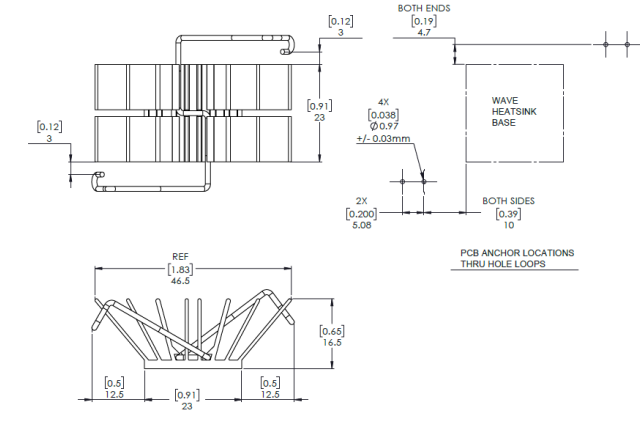
#### MECHANICAL DIMENSIONS



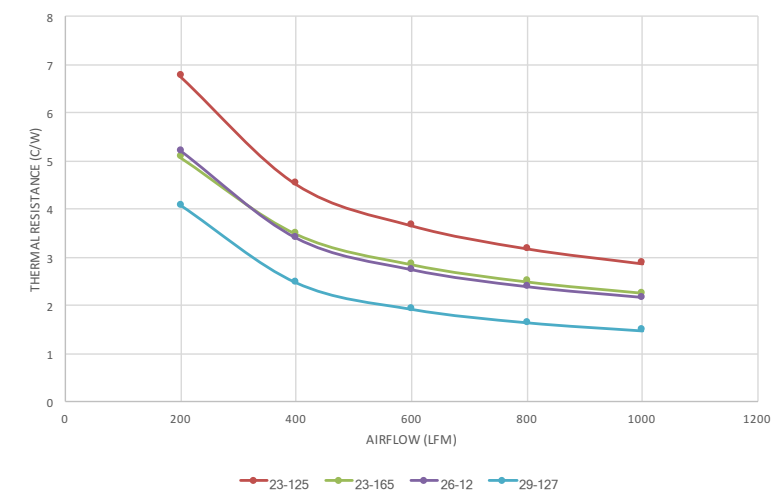
### WAVE-23-165



#### MECHANICAL DIMENSIONS



Wave 2X



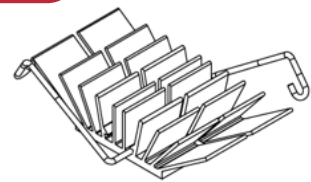
# WAVE SERIES HEAT SINK WITH INTEGRATED CLIP ASSEMBLY

## WAVE 2X SERIES

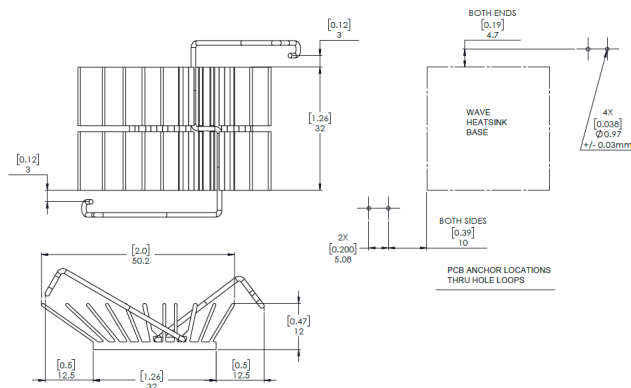
BGA HEAT SINKS

WkV Part Number	Description	Attachment Method	Mechanical Dimensions (mm)							Thermal Resistance - Forced Conv. @ 200 LFM
			Length	Width	Fin Width	Height	Surface Area (sq mm)	Height Off Base (Fin Height)		
WAVE-26-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	26	26	52.9	12	8305.2	10	5.21	
WAVE-29-127	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	29	29	61.4	12.7	11810.5	10.7	4.08	

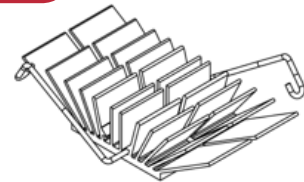
### WAVE-26-12



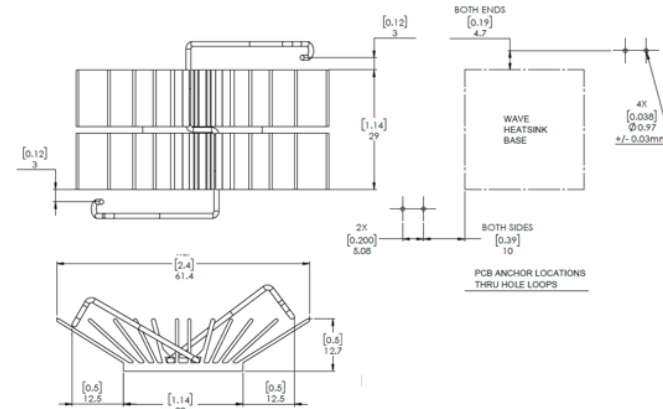
MECHANICAL DIMENSIONS



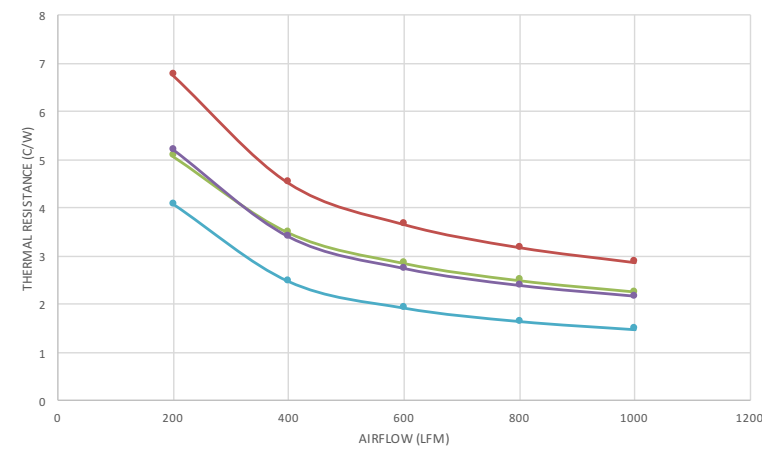
### WAVE-29-127



MECHANICAL DIMENSIONS



Wave 2X



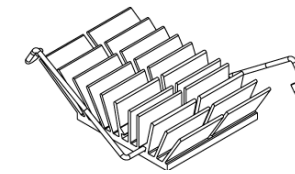
— 23-125 — 23-165 — 26-12 — 29-127

BGA HEAT SINKS

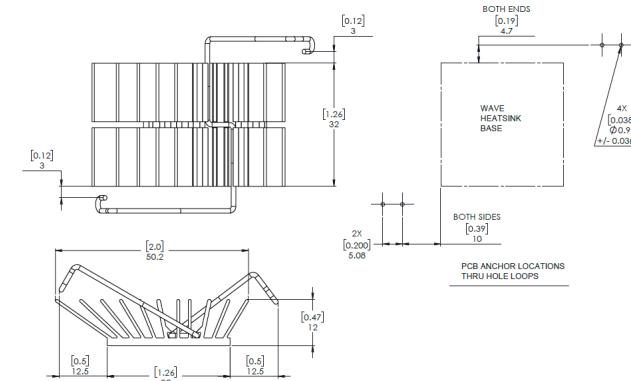
## WAVE 3X SERIES

WkV Part Number	Description	Attachment Method	Mechanical Dimensions (mm)							Thermal Resistance - Forced Conv. @ 200 LFM
			Length	Width	Fin Width	Height	Surface Area (sq mm)	Height Off Base (Fin Height)		
WAVE-32-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	32	32	50.2	12	10957.5	10	4.64	
WAVE-34-21	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	34	34	70	21	21268.4	19	2.19	

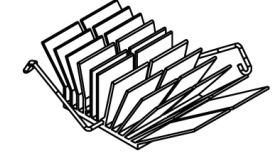
### WAVE-32-12



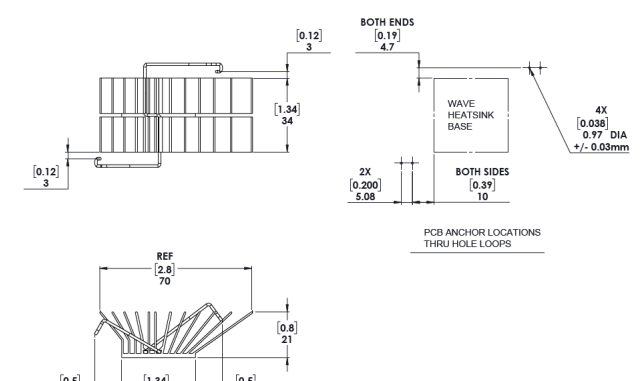
MECHANICAL DIMENSIONS



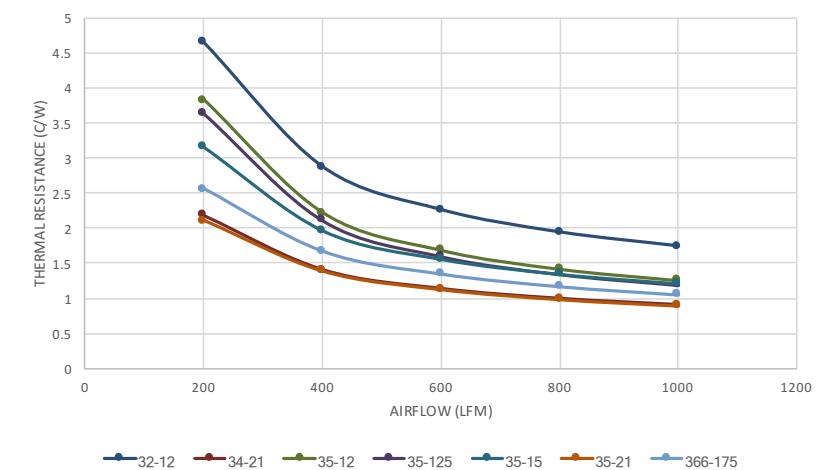
### WAVE-34-21



MECHANICAL DIMENSIONS



Wave 3X



— 32-12 — 34-21 — 35-12 — 35-125 — 35-15 — 35-21 — 366-175

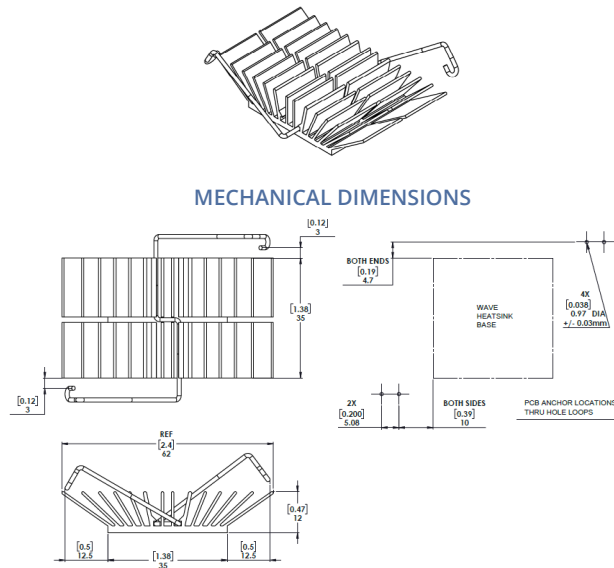
# WAVE SERIES HEAT SINK WITH INTEGRATED CLIP ASSEMBLY

## WAVE 3X SERIES

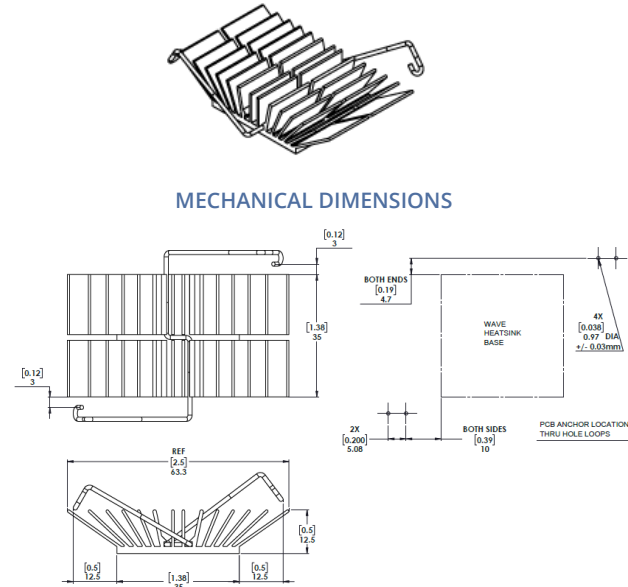
### BGA HEAT SINKS

WkV Part Number	Description	Attachment Method	Mechanical Dimensions (mm)						Thermal Resistance - Forced Conv. @ 200 LFM
			Length	Width	Fin Width	Height	Surface Area (sq mm)	Height Off Base (Fin Height)	
WAVE-35-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	35	35	62	12	15180.8	10	3.83
WAVE-35-125	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	35	35	63.3	12.5	15792.6	10.5	3.63

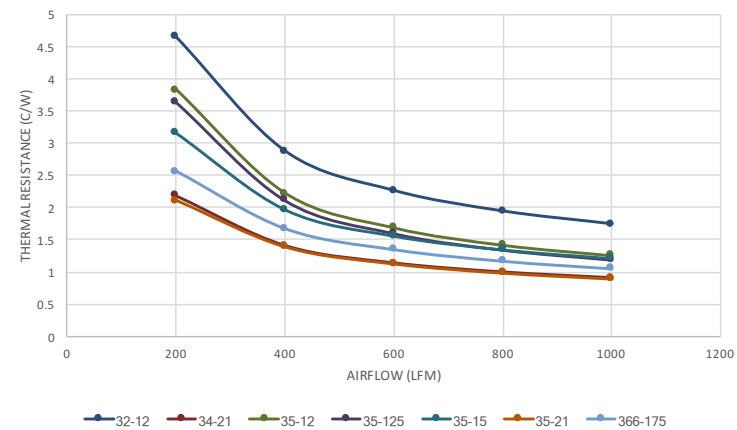
#### WAVE-35-12



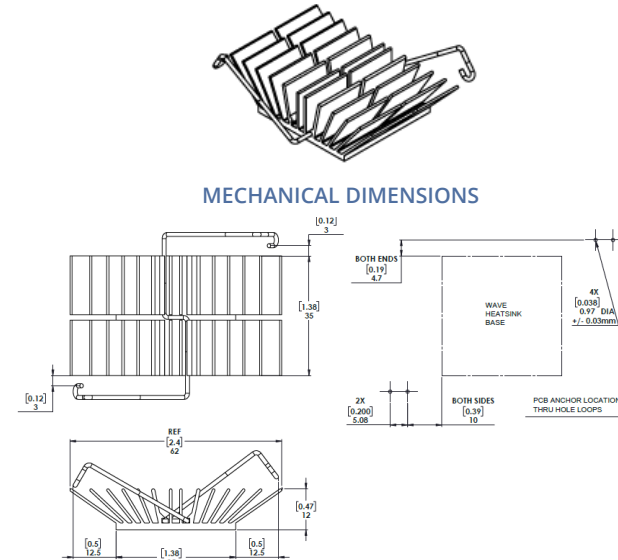
#### WAVE-35-125



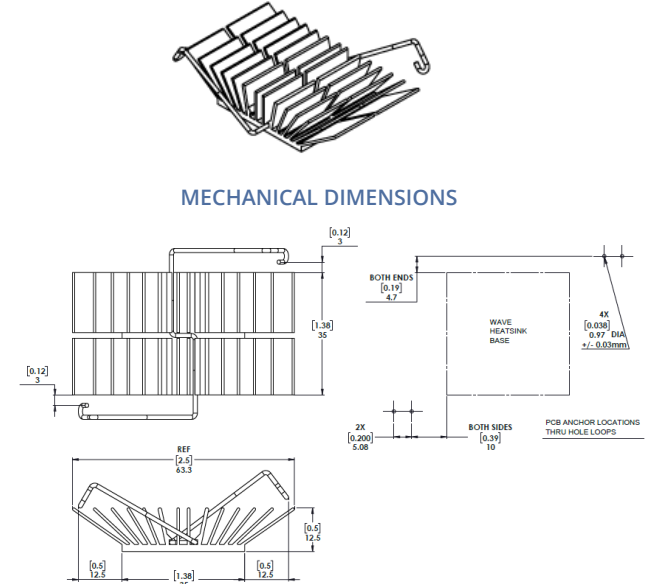
Wave 3X



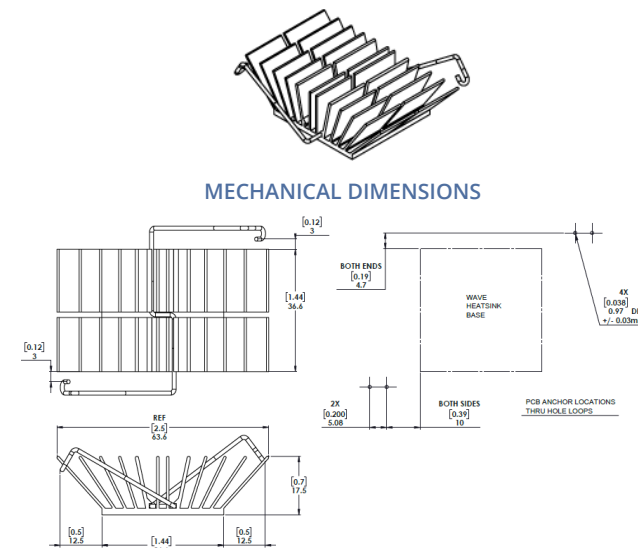
#### WAVE-35-15



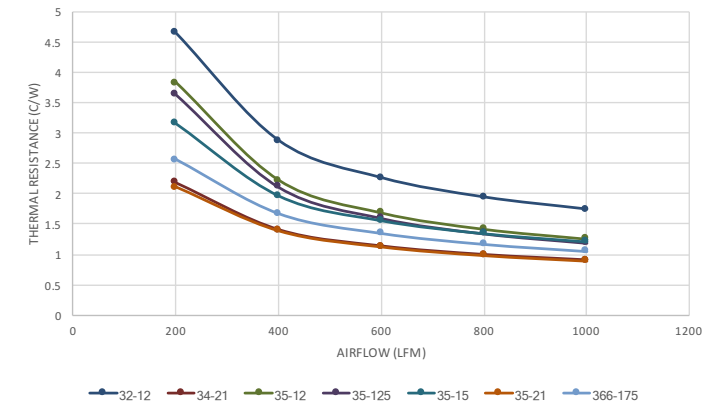
#### WAVE-35-21



#### WAVE-366-175



Wave 3X



# WAVE SERIES HEAT SINK WITH INTEGRATED CLIP ASSEMBLY

## WAVE 4X SERIES

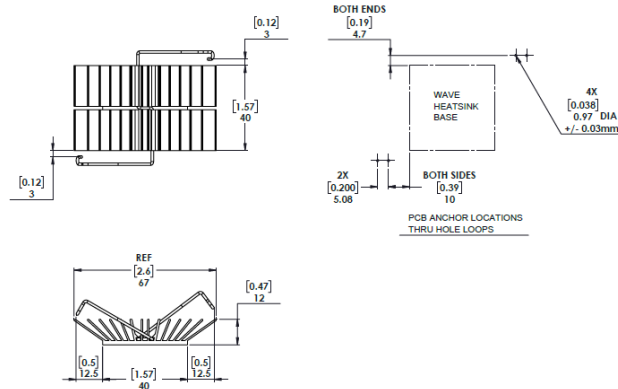
BGA HEAT SINKS

WkV Part Number	Description	Attachment Method	Mechanical Dimensions (mm)						Thermal Resistance - Forced Conv. @ 200 LFM
			Length	Width	Fin Width	Height	Surface Area (sq mm)	Height Off Base (Fin Height)	
WAVE-40-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	40	40	66.9	12	17689.4	10	3.36
WAVE-40-125	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	40	40	68.3	12.5	18410.1	10.5	3.16
WAVE-425-117	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	42.5	42.5	67.4	11.7	21668.3	9.3	3.40
WAVE-45-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	45	45	72	12	22303.7	10	2.96

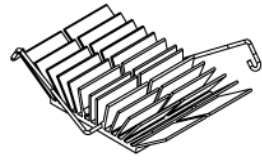
### WAVE-40-12



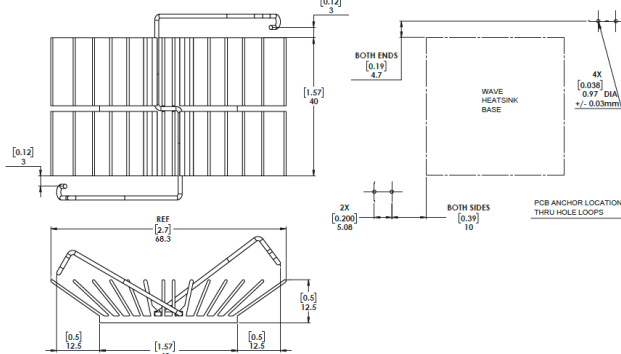
#### MECHANICAL DIMENSIONS



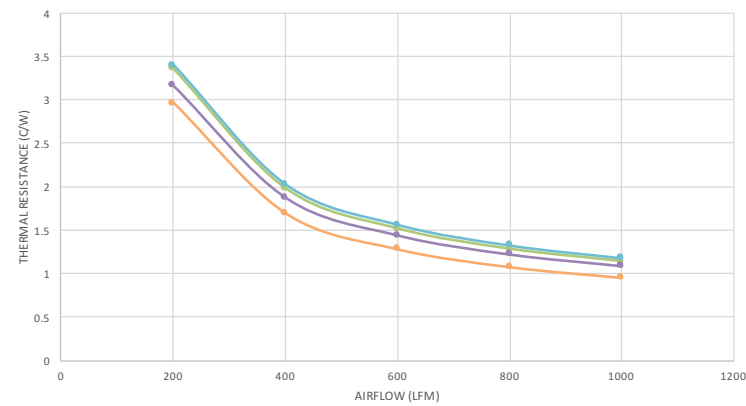
### WAVE-40-125



#### MECHANICAL DIMENSIONS



Wave 4X



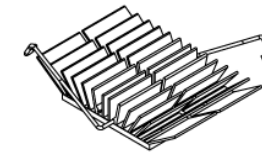
— 40-12 — 40-125 — 425-117 — 45-12

BGA HEAT SINKS

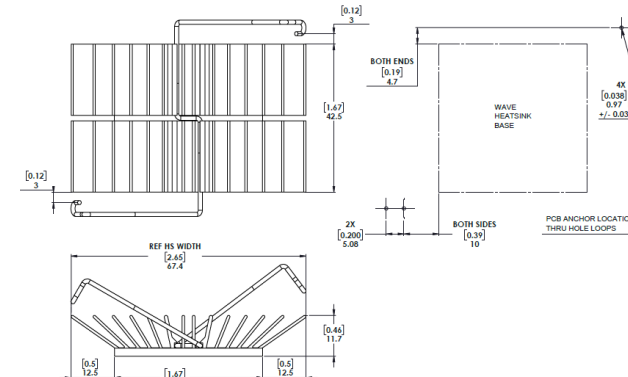
## WAVE 4X SERIES

WkV Part Number	Description	Attachment Method	Mechanical Dimensions (mm)						Thermal Resistance - Forced Conv. @ 200 LFM
			Length	Width	Fin Width	Height	Surface Area (sq mm)	Height Off Base (Fin Height)	
WAVE-40-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	40	40	66.9	12	17689.4	10	3.36
WAVE-40-125	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	40	40	68.3	12.5	18410.1	10.5	3.16
WAVE-425-117	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	42.5	42.5	67.4	11.7	21668.3	9.3	3.40
WAVE-45-12	Wave Heat Sink BGA Chipset Aluminum Top Mount	Spring-Anchor	45	45	72	12	22303.7	10	2.96

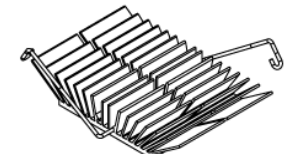
### WAVE-425-117



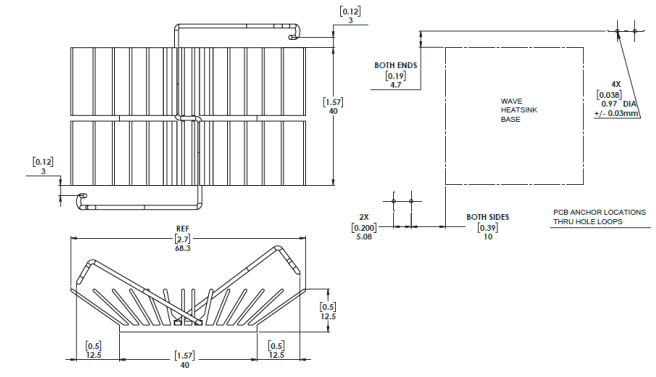
#### MECHANICAL DIMENSIONS



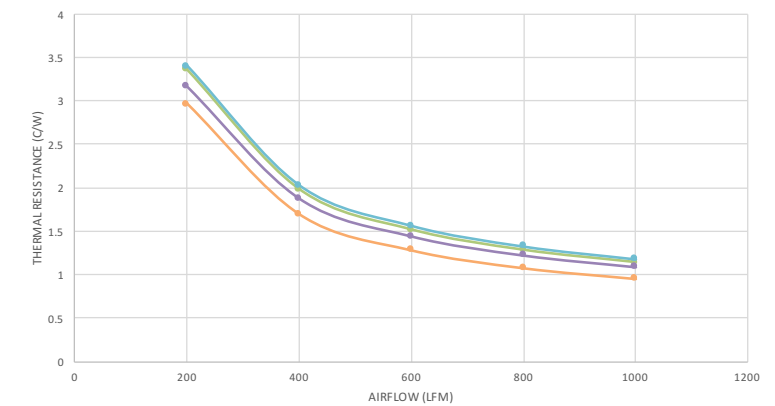
### WAVE-45-12



#### MECHANICAL DIMENSIONS



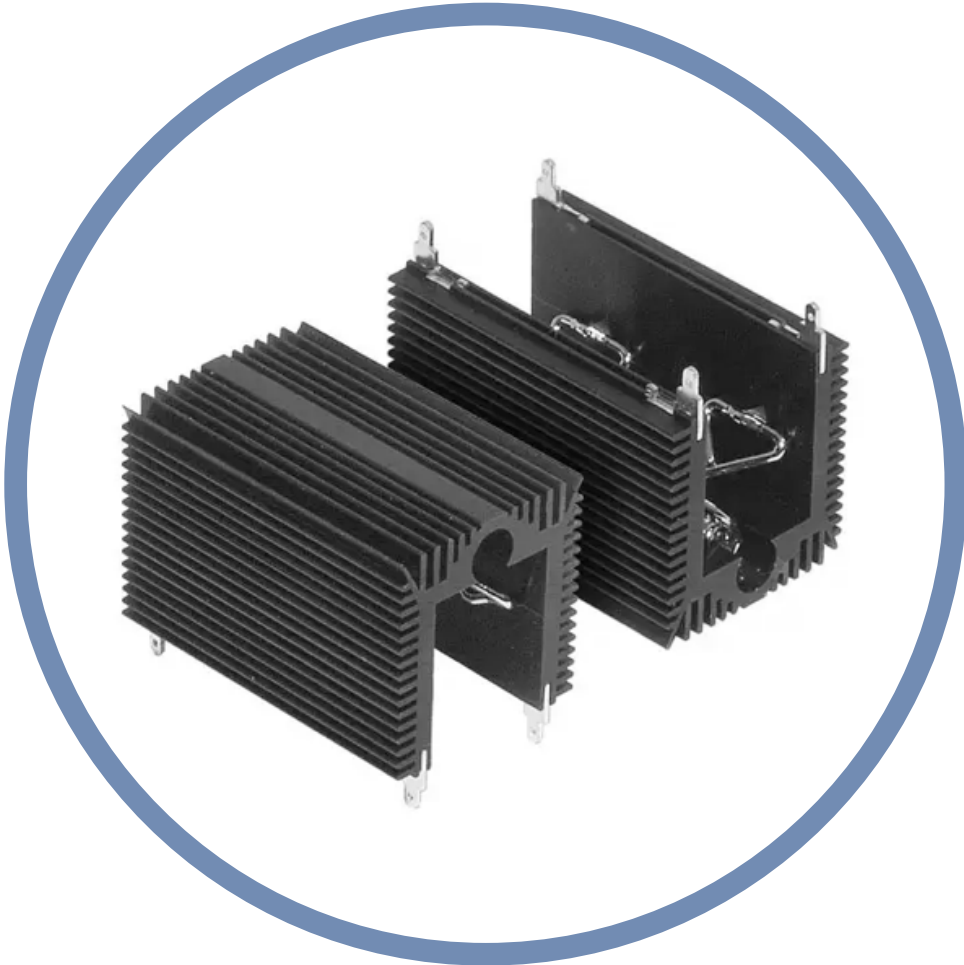
Wave 4X



— 40-12 — 40-125 — 425-117 — 45-12

# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

<i>Board Level Power Semiconductor Heat Sinks</i> .....	46-76
<i>219 Series Heat Sinks for TO-263 Devices</i> .....	48-49
<i>Board Level Heat Sinks for TO-220, TO-218 &amp; Multiwatt™ Components</i> .....	59-61
<i>Universal 678 Series Vertical Heat Sink for Power Devices</i> .....	77
<i>One Heat Sink for all Packages</i> .....	78
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<i>omniKlip™ Series Heat Sink w/ Clip(s) for TO-Devices</i> .....	81-83
<i>Additional Configurations</i> .....	84



*A wide variety of heat dissipators with various attachment mechanisms for surface mount and thru-hole power semiconductors packaged in industry standard plastic, ceramic, and metal cases such as D2Pak, TO-220, TO-3 to TO-247, DO-4 to DO-11, multiwatt, hex-type, and stud mount devices.*



# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

## 217 SERIES

### SURFACE MOUNT HEAT SINKS

D2PAK; TO-220; SOT-223; SOL-20

Compatible with surface mount technology (SMT) automated production techniques for ease of assembly and a variety of soldering methods, these heat sinks allow greater packaging densities and reduction in PC-board area, increasing the power dissipation of surface mount devices (SMDs) while maintaining and improving manufacturers' component thermal specifications.

#### FEATURES AND BENEFITS

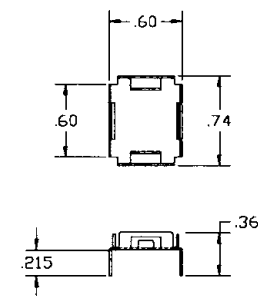
- No interface material is needed
- Copper with matte tin plating for improved solderability and assembly
- Both the component and the heat sink are installed on the PC-board utilizing standard SMT assembly equipment for "Tape & Reel" and "Tube" formats
- EIA standards and ESD protection are specified
- Can be used with water soluble or no clean SMT solder creams or other pastes

Footprint Standard P/N	Height Above PC Board in. (mm)	Dimensions in. (mm)	Package Format	Package Quantity	Thermal Performance at Typical Load	
					Natural Convection	Forced Convection
217-36CTE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Bulk	1	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTTE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tube	20	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTRE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tape & Reel	250	55°C @ 1W	16.0°C/W @ 200 LFM

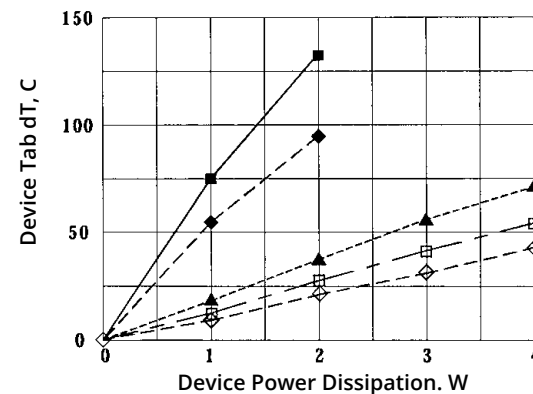
Material: Copper, Matte Tin Plated

#### MECHANICAL DIMENSIONS

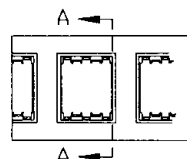
#### THERMAL PERFORMANCE 6 LAYER BOARD, D' PAK 125°C LEAD, 40°C AMBIENT



217-36CT6

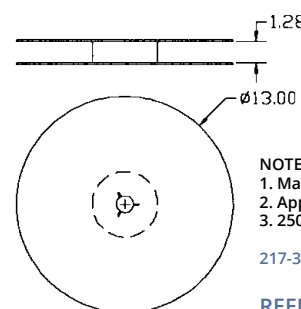


KEY: ■ Device only, NC ◆ Device + HS, NC ▲ Device + HS, 100 lfm □ Device + HS, 200 lfm ◇ Device + HS, 300 lfm



SECTION A-A

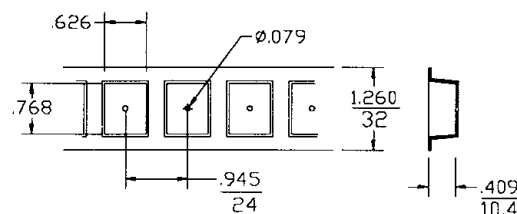
Dimensions: in.



NOTES  
1. Material to be "ESD"  
2. Approximately 6 Meters per Reel  
3. 250 Pieces per Reel.

217-36CTR6

#### REEL DETAILS



#### TAPE DETAILS

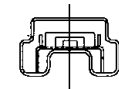
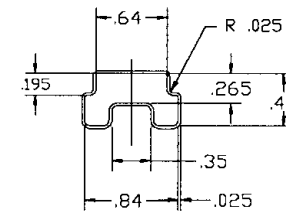
D2PAK; TO-220; SOL-20

## SURFACE MOUNT HEAT SINKS

## 217 SERIES

#### MECHANICAL DIMENSIONS

##### TUBE DETAILS

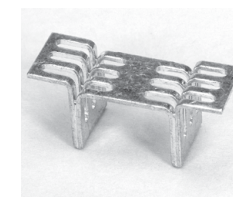
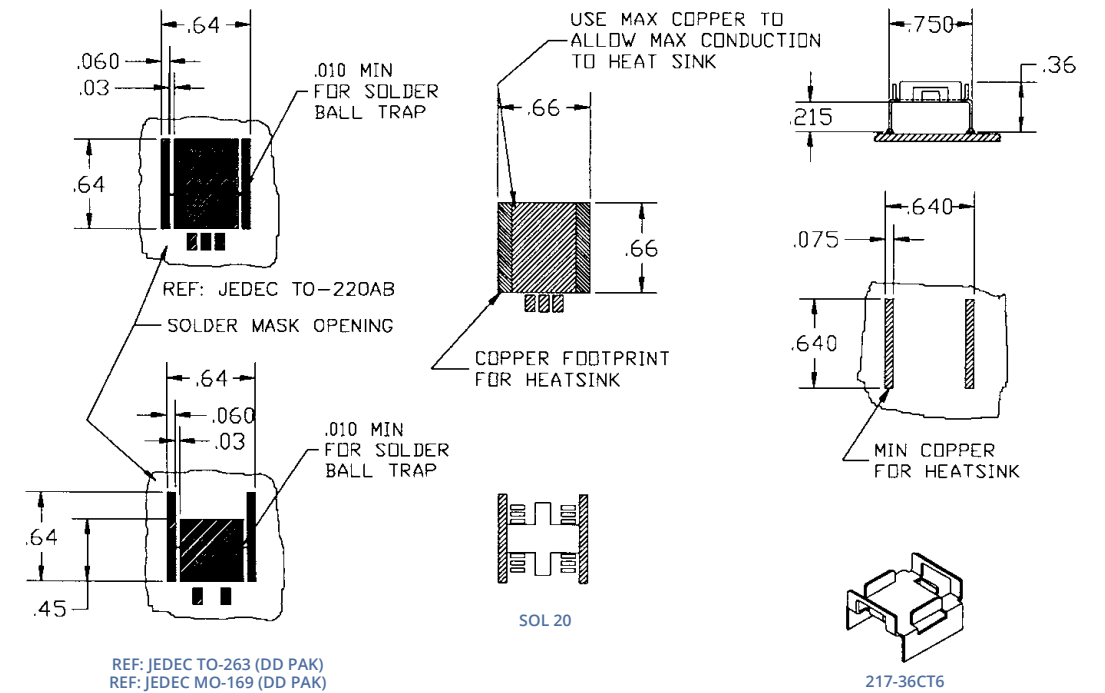


Tube: 16.25 Inches Long, Min. esd Material with Nail Stops  
20 Pieces per Tube

217-36CT6

Dimensions: in.

#### BOARD LAYOUT RECOMMENDATIONS



## 218 SERIES

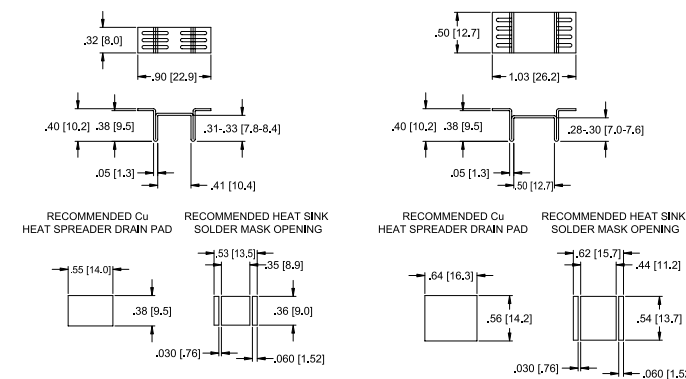
### SURFACE MOUNT HEAT SINK

SMT Devices

Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
218-40CTE3	.40 (10.2)	.90 (22.9) x .315 (8.0)	62°C rise @ 2W	21°C/W @ 200LFM
218-40CTE5	.40 (10.2)	1.03 (26.2) x .50 (12.7)	62°C rise @ 2W	21°C/W @ 200LFM

Material: Copper, Matte Tin Plated

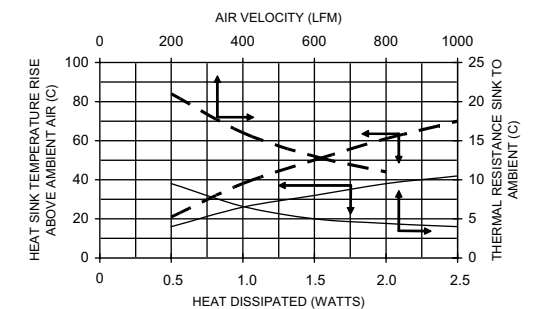
#### MECHANICAL DIMENSIONS



218-40CT3

218-40CT5

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## 219 SERIES HEAT SINKS FOR TO-263 DEVICES

### 219-263A HEAT SINK FOR TO-263 DEVICES



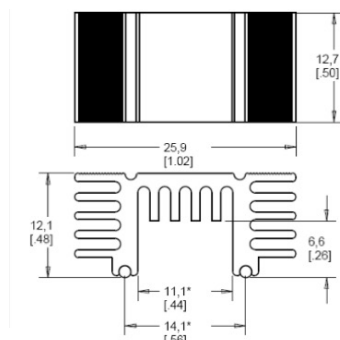
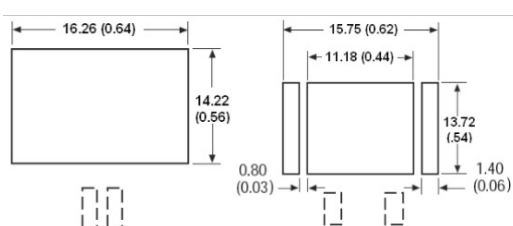
Innovation in SMT compatible heat sinks to meet the needs of newer higher power SMT semiconductors. The 219 Series heat sinks unique design (Patent Pending) combines the technology of automatically assembling the tin plated solderable wires/rods with that of extruded aluminum anodized heat sink body to configure these SMT heat sinks. Rods/wires named "Rollers" are mated mechanically to the heat sink body by forging to reduce the interface thermal resistance between the drains & heat dissipation body.

#### FEATURES AND BENEFITS

- Increased thermal performance up to 30% over bright copper heat sinks from improved radiation of the black finish.
- Increased surface areas by 3 times therefore thermal performance up to 300% over the aluminum stamped heat sinks on markets.
- Light weight aluminum construction allows faster pick and place assembly reducing the manufacturing cycle time.
- Radius mounted "Rollers" are designed for maximizing heat transfer from component and to avoid "bottle neck" heat transfer like the Aluminum stamped heat sinks.
- Available in bulk packaging or Tape & Reel.

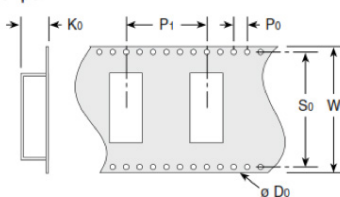
Part Number	Description	Attachment	Length	Width	Height Off Base (Height Of Fin)	Power Dissipation @ Temperature Rise	Thermal Resistance @ Forced Air Flow	Package Type
219-263A	TO-263 SMD HEAT SINK ANODZD	Solderable Feet	0.500" (12.70mm)	1.020" (25.91mm)	0.480" (12.19mm)	2W @ 30°C	8°C/W @ 500 LFM	Bulk

#### MECHANICAL DIMENSIONS



#### TAPE AND REEL INFORMATION

Reel diameter: 13.00" (330.00mm)  
250 pcs. per

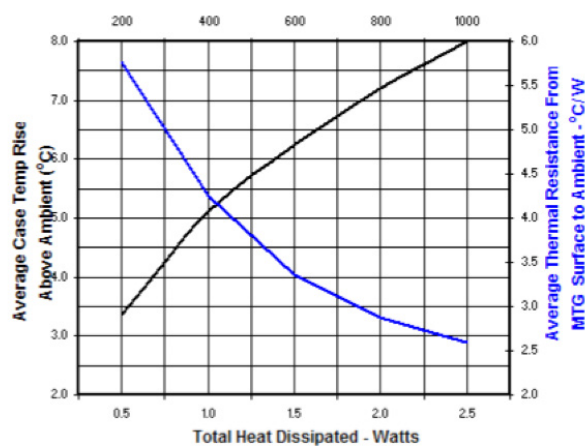


	Style 10	Style 20	Style 30
Do	1.55mm	1.5mm	1.5mm
Ko	10.5mm	12.20mm	11.50mm
Po	4mm	4.0mm	4.0mm
P1	24mm	24mm	24.0mm
So	40.4mm	40.4mm	52.4mm
W	44mm	44mm	56mm

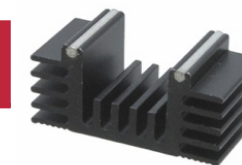
#### TAPE DETAILS

#### THERMAL RESISTANCE

Air Velocity - Feet Per Minute



### HEAT SINK FOR TO-263 DEVICES 219-263A-TR



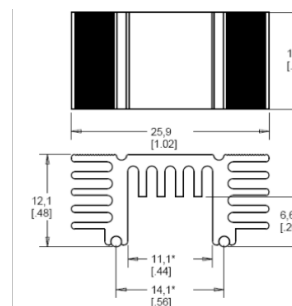
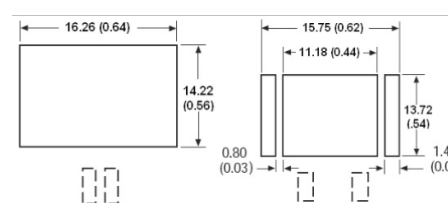
Innovation in SMT compatible heat sinks to meet the needs of newer higher power SMT semiconductors. The 219 Series heat sinks unique design (Patent Pending) combines the technology of automatically assembling the tin plated solderable wires/rods with that of extruded aluminum anodized heat sink body to configure these SMT heat sinks. Rods/wires named "Rollers" are mated mechanically to the heat sink body by forging to reduce the interface thermal resistance between the drains & heat dissipation body.

#### FEATURES AND BENEFITS

- Increased thermal performance up to 30% over bright copper heat sinks from improved radiation of the black finish.
- Increased surface areas by 3 times therefore thermal performance up to 300% over the aluminum stamped heat sinks on markets.
- Light weight aluminum construction allows faster pick and place assembly reducing the manufacturing cycle time.
- Radius mounted "Rollers" are designed for maximizing heat transfer from component and to avoid "bottle neck" heat transfer like the Aluminum stamped heat sinks.
- Available in bulk packaging or Tape & Reel.

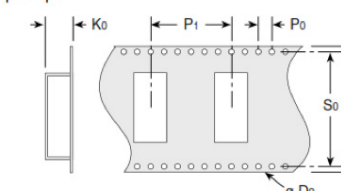
Part Number	Description	Attachment	Length	Width	Height Off Base (Height Of Fin)	Power Dissipation @ Temperature Rise	Thermal Resistance @ Forced Air Flow	Package Type
219-263A-TR	TO-263 SMD HEAT SINK ANODZD	Solderable Feet	0.500" (12.70mm)	1.020" (25.91mm)	0.480" (12.19mm)	2W @ 30°C	8°C/W @ 500 LFM	Tape & Reel

#### MECHANICAL DIMENSIONS



#### TAPE AND REEL INFORMATION

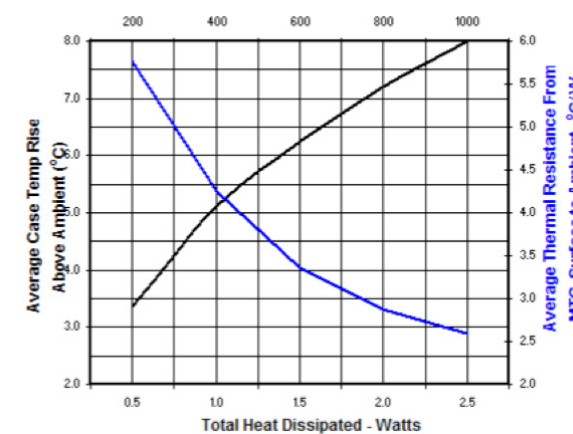
Reel diameter: 13.00" (330.00mm)  
250 pcs. per



	Style 10	Style 20	Style 30
Do	1.55mm	1.5mm	1.5mm
Ko	10.5mm	12.20mm	11.50mm
Po	4mm	4.0mm	4.0mm
P1	24mm	24mm	24.0mm
So	40.4mm	40.4mm	52.4mm
W	44mm	44mm	56mm

#### THERMAL RESISTANCE

Air Velocity - Feet Per Minute



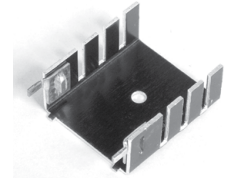
Contact us: (603) 635-2800

# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

## 206 SERIES

VERTICAL MOUNT HEAT SINK

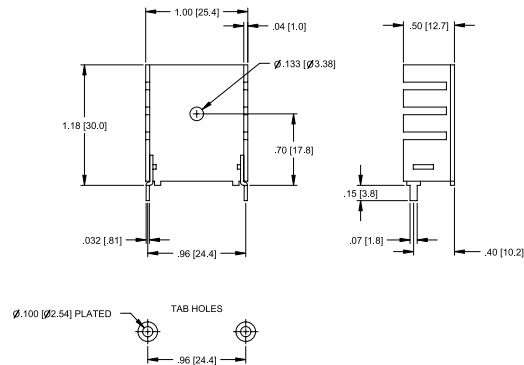
TO-220



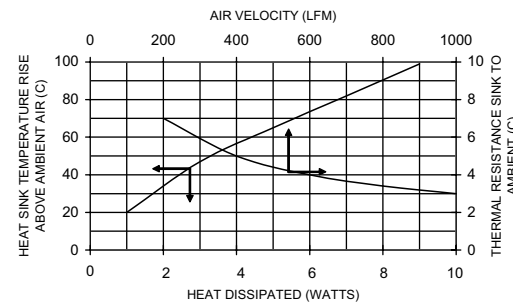
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
206-1PABEH	1.18 (30.0)	1.00 (25.4) x .50 (12.7)	56°C rise @ 4W	7.3°C/W @ 200LFM

**Material:** Aluminum, Black Anodized

### MECHANICAL DIMENSIONS



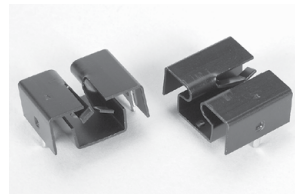
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



TO-220

HORIZONTAL MOUNT HEAT SINK

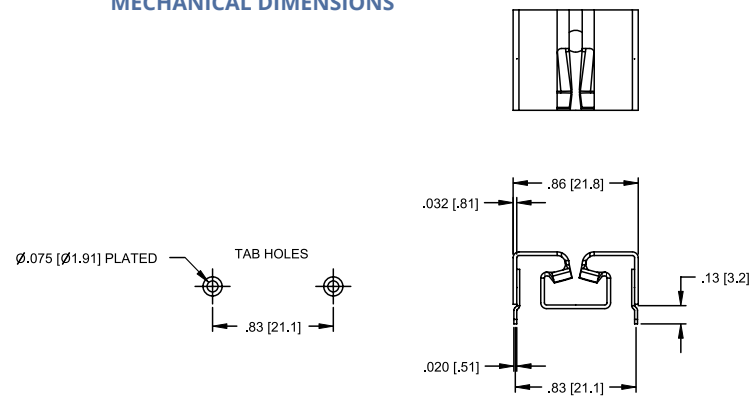
## 241 SERIES



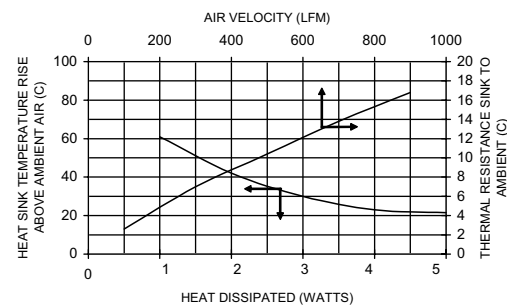
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
241-69ABE-03	.39 (9.9)	.86 (21.8) x .69 (17.5)	77°C rise @ 4W	12°C/W @ 200LFM

**Material:** Aluminum, Black Anodized

### MECHANICAL DIMENSIONS



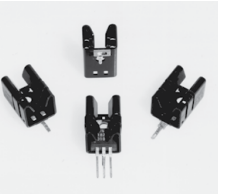
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



COMPACT, WAVE-SOLDERABLE LOW-PROFILE SELF-LOCKING HEAT SINKS

## 230 & 234 SERIES

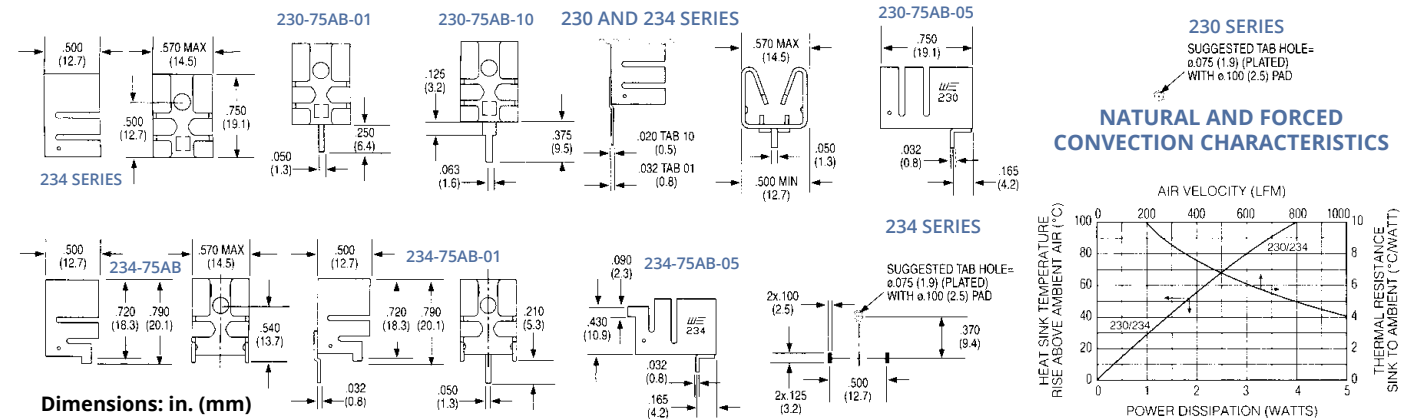
TO-220



Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Option	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
230-75AB	.750 (19.1)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
230-75ABE-01	.750 (19.1)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
230-75ABE-05	.500 (12.7)	.750 (19.1) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
230-75ABE-10	.875 (22.2)	.570 (14.5) x .500 (12.7)	Vertical	10	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
234-75AB	.790 (20.0)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
234-75ABE-01	.790 (20.0)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
234-75ABE-05	.500 (12.7)	.790 (20.0) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM

**Material:** Aluminum, Black Anodized

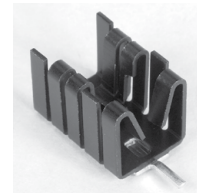
### MECHANICAL DIMENSIONS



## 262 SERIES

HORIZONTAL AND VERTICAL MOUNT HEAT SINK

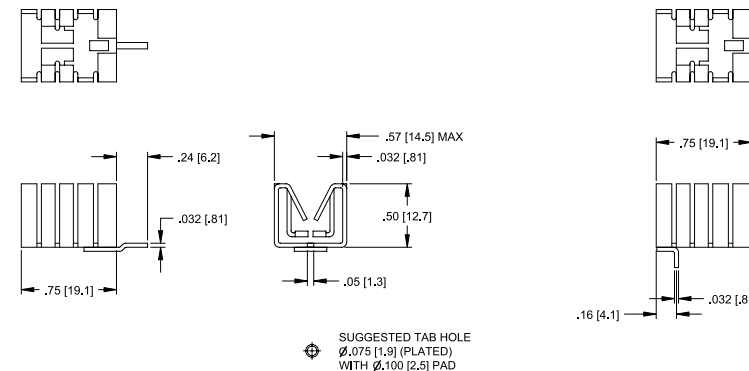
TO-220



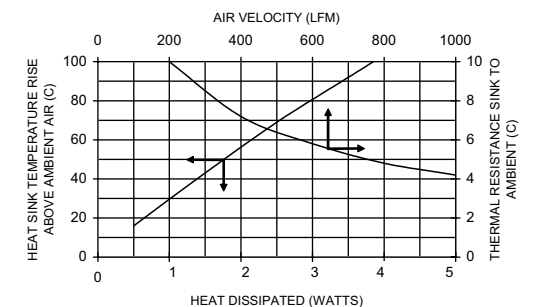
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
262-75ABE-05	.53 (13.4)	.75 (19.1) x .50 (12.78)	80°C rise @ 2W	10°C/W @ 200LFM
262-75ABE-01	.75 (19.1)	.53 (13.4) x .50 (12.7)	80°C rise @ 2W	10°C/W @ 200LFM

**Material:** Aluminum, Black Anodized

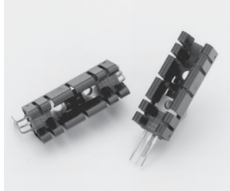
### MECHANICAL DIMENSIONS



### NATURAL AND FORCED CONVECTION CHARACTERISTICS



# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



## 233 & 236 SERIES

SELF-LOCKING WAVE-SOLDERABLE HEAT SINKS

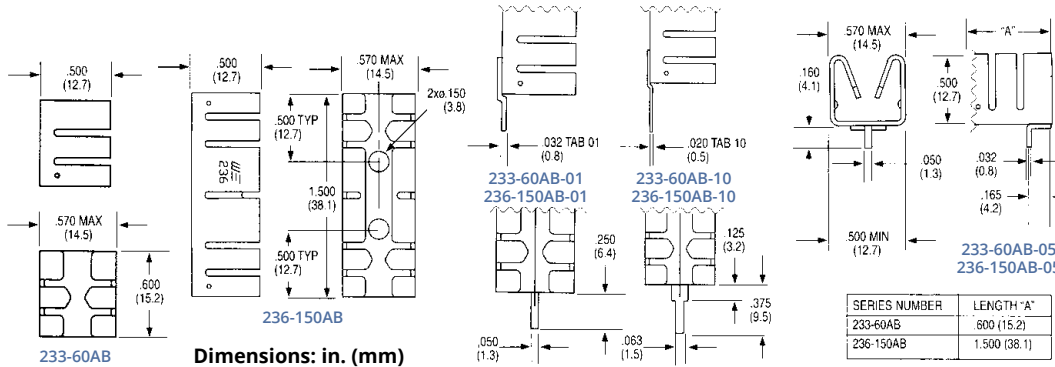
TO-220

PATENT  
PENDING

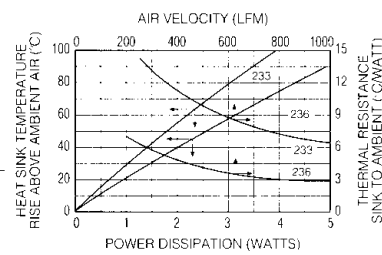
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
233-60AB	.600(15.2)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
233-60ABE-01	.600(15.2)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
233-60ABE-05	.500(12.7)	.600 (15.2) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
233-60ABE-10	.725(18.4)	.570 (14.5) x .500 (12.7)	Vertical	10	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
236-150AB	1.500(38.1)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	40°C @ 2W	4.80°C/W @ 400 LFM
236-150ABE-01	1.500(38.1)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	40°C @ 2W	4.80°C/W @ 400 LFM
236-150ABE-05	.500(12.7)	1.500 (38.1) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	40°C @ 2W	4.80°C/W @ 400 LFM
236-150ABE-10	1.625(41.3)	.570 (14.5) x .570 (12.7)	Vertical	10	Clip/Mtg Hole	40°C @ 2W	4.80°C/W @ 400 LFM

Material: Aluminum, Black Anodized

### MECHANICAL DIMENSIONS



### NATURAL AND FORCED CONVECTION CHARACTERISTICS



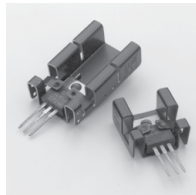
SERIES NUMBER	LENGTH "A"
233-60AB	.600 (15.2)
236-150AB	1.500 (38.1)

SUGGESTED TAB HOLE =  $\phi$ 0.075 (1.9) (PLATED) WITH  $\phi$ 0.100 (2.5) PAD

COMPACT, STRESS-FREE LABOR-SAVING  
LOCKING-TAB HEAT SINKS

## 275 & 231 SERIES

TO-220



PATENT  
5381041

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
275-75AB	.750 (19.1)	.835 (21.2) x .400 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	44 C @ 2W	7.9°C/W @ 400 LFM
275-75ABE-01	.750 (19.1)	.835 (21.2) x .400 (12.7)	Vertical	01	Clip/Mtg Hole	44°C @ 2W	7.9°C/W @ 400 LFM
275-75ABE-10	.875 (12.7)	.835 (21.2) x .400 (14.5)	Vertical	10	Clip/Mtg Hole	44°C @ 2W	7.9°C/W @ 400 LFM
231-69PAB	.690 (18.4)	.835 (21.2) x .400 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	45°C @ 2W	8°C/W @ 400 LFM
231-69PABE	.400 (10.1)	.690 (17.5) x .835 (12.7)	Horizontal	13H	Clip/Mtg Hole	45°C @ 2W	8°C/W @ 400 LFM
231-69PABE-XXX	.690 (17.5)	.835 (21.2) x .400 (12.7)	Vertical	13V, 14V, 15V	Clip/Mtg Hole	45°C @ 2W	8°C/W @ 400 LFM
231-75PAB	.750 (19.1)	.835 (21.2) x .400 (14.5)	Vert./Horiz.	No Tab	Clip/Mtg Hole	43°C @ 2W	7.9°C/W @ 400 LFM
231-75PABE	.400 (10.1)	.750 (19.1) x .835 (12.7)	Horizontal	13H	Clip/Mtg Hole	43°C @ 2W	7.9°C/W @ 400 LFM
231-75PABE-XXX	.750 (19.1)	.835 (21.2) x .400 (12.7)	Vertical	13V, 14V, 15V	Clip/Mtg Hole	43°C @ 2W	7.9°C/W @ 400 LFM
231-137PAB	1.375 (35)	.835 (21.2) x .400 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	32°C @ 2W	5.9°C/W @ 400 LFM
231-137PABE	.400 (10.2)	1.375 (34.9) x .835 (12.7)	Horizontal	13H	Clip/Mtg Hole	32°C @ 2W	5.9°C/W @ 400 LFM
231-137PABE-XXX	1.375 (35)	.835 (21.2) x .400 (12.7)	Vertical	13V, 14V, 15V	Clip/Mtg Hole	32°C @ 2W	5.9°C/W @ 400 LFM

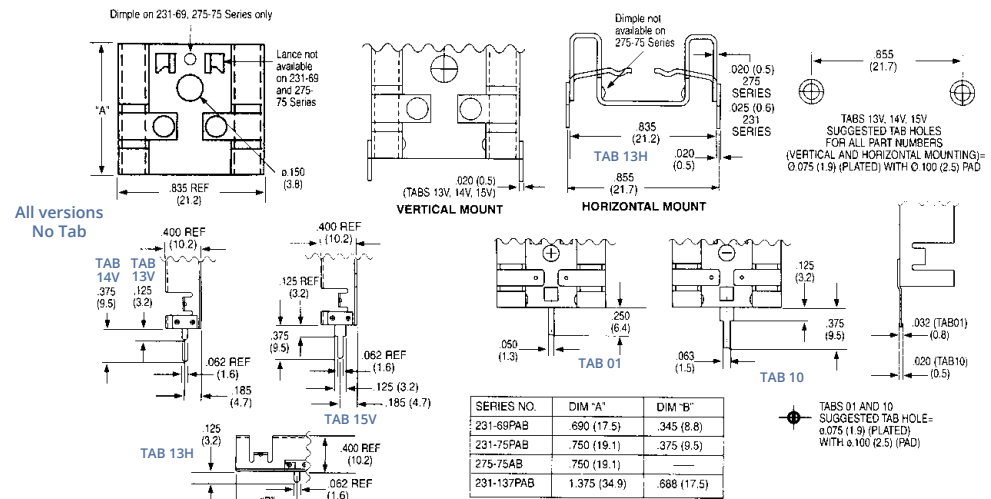
Material: Aluminum, Pre-anodized Black (PAB), Anodized Black (AB)

TO-220

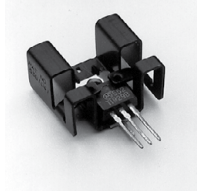
COMPACT, STRESS-FREE LABOR-SAVING  
LOCKING-TAB HEAT SINKS

## 275 & 231 SERIES

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)



## 235 SERIES

COMPACT, STRESS-FREE LABOR-SAVING  
LOCKING-TAB HEAT SINKS

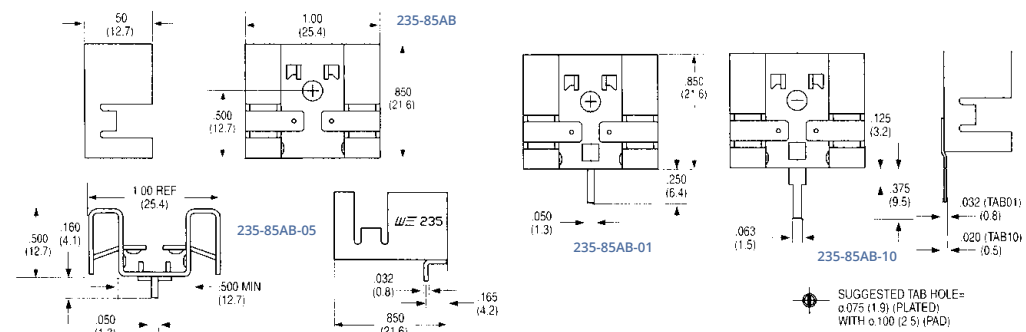
TO-220

PATENT  
5381041

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
235-85AB	.850 (21.6)	1.000 (25.4) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM
235-85ABE-01	.850 (21.6)	1.000 (25.4) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM
235-85ABE-05	.500 (12.7)	.850 (21.6) x 1.000 (25.4)	Horizontal	05	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM
235-85ABE-10	.975 (24.8)	1.000 (25.4) x .500 (12.7)	Vertical	10	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM

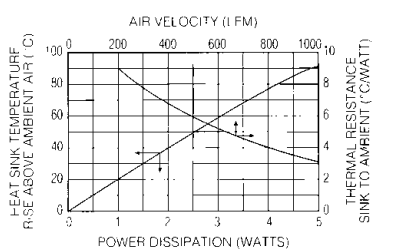
Material: Aluminum, Black Anodized

### MECHANICAL DIMENSIONS

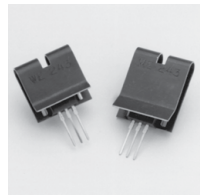


Dimensions: in. (mm)

### NATURAL AND FORCED CONVECTION CHARACTERISTICS



# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



## 243 SERIES

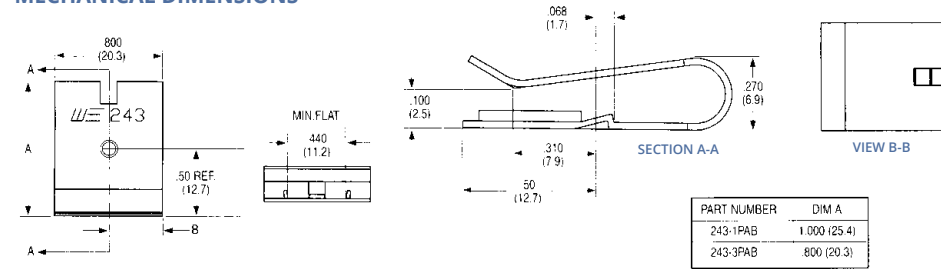
LABOR-SAVING CLIP-ON HEAT SINKS

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
243-1PAB	1.000 (25.4)	.800 (20.3) x .270 (6.9)	Vert./Horiz.	No Tab	Clip	50°C@ 2W	4.5°C/W @ 400 LFM
243-3PAB	.800 (20.3)	.800 (20.3) x .270 (6.9)	Verl./Horiz.	No Tab	Clip	78°C@ 2W	8.2°C/W @ 400 LFM

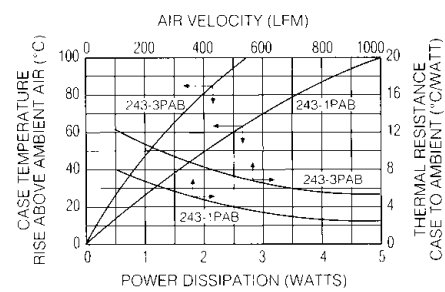
**Material:** Aluminum, Pre-anodized Black

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

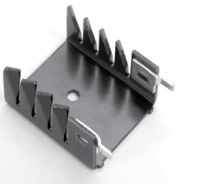
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



TO-220

VERTICAL MOUNT HEAT SINK

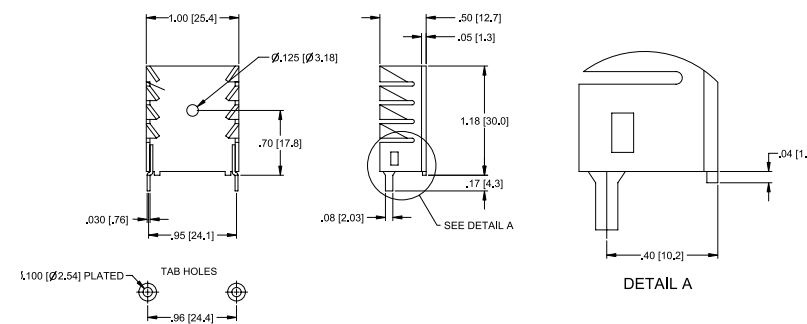
## 265 SERIES



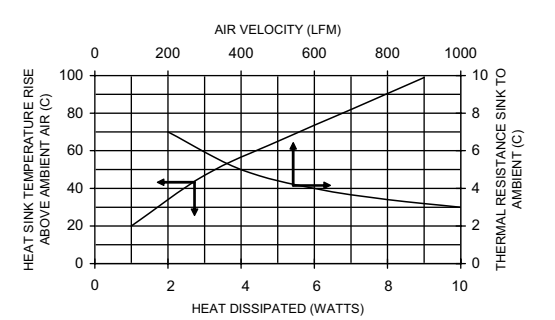
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
265-118ABHE-22	1.18 (30.0)	1.00 (25.4) x .50 (12.7)	56°C rise @ 4W	7.0°C/W @ 200LFM

**Material:** Aluminum, Black Anodized

### MECHANICAL DIMENSIONS



### NATURAL AND FORCED CONVECTION CHARACTERISTICS



TO-220

SNAP-DOWN SELF-LOCKING HEAT SINKS

## 239 SERIES

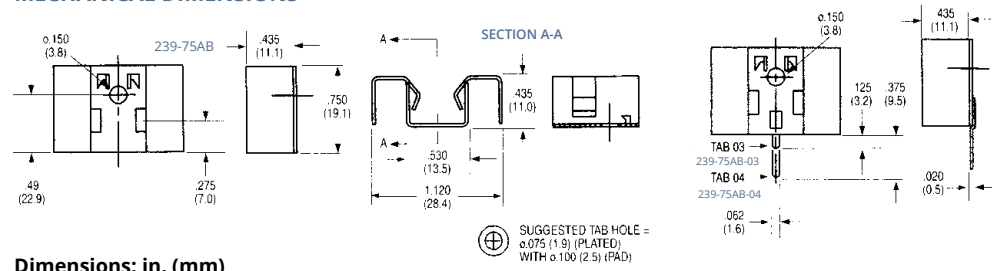


PATENT PENDING

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
239-75AB	.750 (19.1)	1.120 (28.4) x .435 (11.0)	Vert./Horiz.	No Tab	Clip/Mtg Hole	38°C @ 2W	6°C/W @ 400 LFM
239-75ABE-03	.750 (19.1)	1.120 (28.4) x .435 (11.0)	Vertical	03	Clip/Mtg Hole	38°C @ 2W	6°C/W @ 400 LFM
239-75ABE-04	.750 (19.1)	1.120 (28.4) x .435 (11.0)	Vertical	04	Clip/Mtg Hole	38°C @ 2W	6°C/W @ 400 LFM

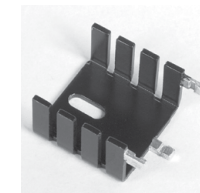
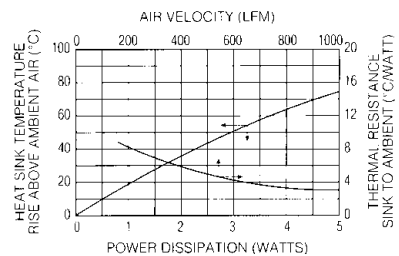
**Material:** Aluminum, Black Anodized

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## 286DB SERIES

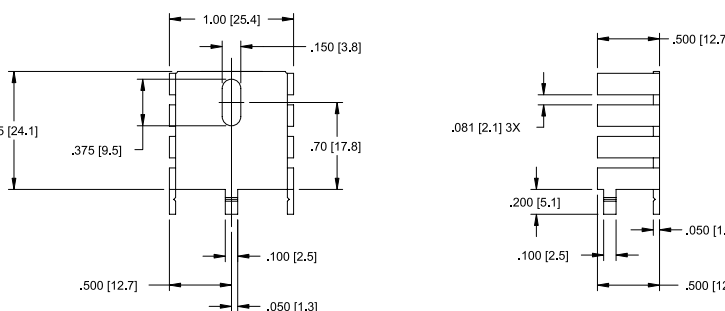
VERTICAL MOUNT HEAT SINK

TO-220

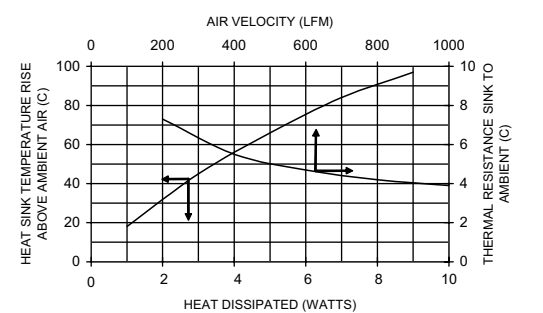
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
286DBE	.95 (24.1)	1.00 (25.4) x .50 (12.7)	65°C rise @ 4W	9.0°C/W @ 200LFM

**Material:** Aluminum, Black Anodized

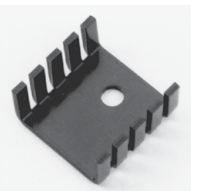
### MECHANICAL DIMENSIONS



### NATURAL AND FORCED CONVECTION CHARACTERISTICS



# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



## 273 SERIES

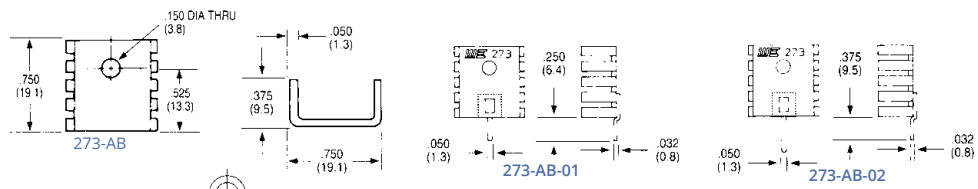
LOW-COST, LOW-HEIGHT WAVE-SOLDERABLE  
HEAT SINKS

TO-220 and TO-218

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
273-AB	.375 (9.5)	.750 (19.1) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	49°C @ 2W	7.2°C/W @ 400 LFM
273-ABE-01	.375 (9.5)	.750 (19.1) x .750 (19.1)	Vertical	01	Mtg Hole	49°C @ 2W	7.2°C/W @ 400 LFM
273-ABE-02	.375 (9.5)	.750 (19.1) x .750 (19.1)	Vertical	02	Mtg Hole	49°C @ 2W	7.2°C/W @ 400 LFM

Material: Aluminum, Black Anodized

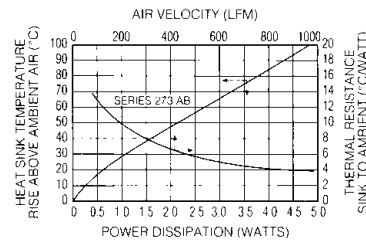
### MECHANICAL DIMENSIONS



Note:  
1. Suggested Tab Hole = ø.075 (1.9) (Plated) with ø.100 (2.5) pad

Dimensions: in. (mm)

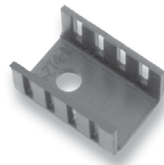
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## LOW-COST, LOW-HEIGHT WAVE-SOLDERABLE HEAT SINKS

## 274 & 281 SERIES

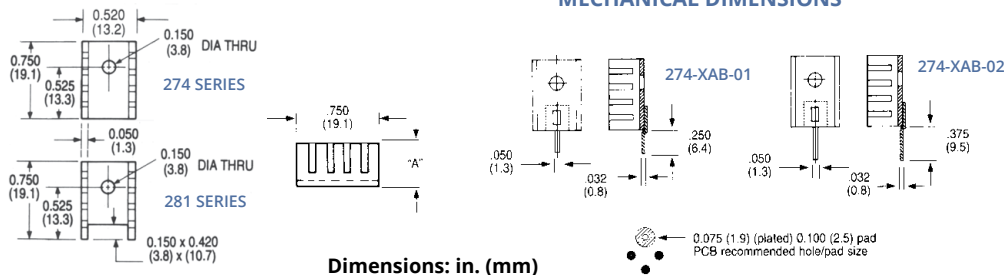
TO-220



Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
274-1AB	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
274-1ABE-01	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vertical	01	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
274-1ABE-02	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vertical	02	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
274-2AB	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM
274-2ABE-01	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vertical	01	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM
274-2ABE-02	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vertical	02	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM
274-3AB	.250 (6.4)	.520 (13.2) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	62°C @ 2W	9.0°C/W @ 400 LFM
274-3ABE-01	.250 (6.4)	.520 (13.2) x .750 (19.1)	Vertical	01	Mtg Hole	62°C @ 2W	9.0°C/W @ 400 LFM
274-3ABE-02	.250 (6.4)	.520 (13.2) x .750 (19.1)	Vertical	02	Mtg Hole	62°C @ 2W	9.0°C/W @ 400 LFM
281-1AB	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vertical	No Tab	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
281-2AB	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vertical	No Tab	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM

Material: Aluminum, Black Anodized

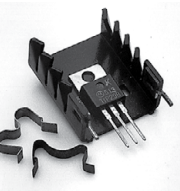
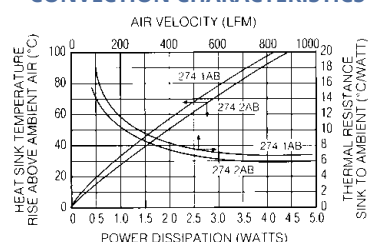
### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

• ø.075 (1.9) (plated) ø.100 (2.5) pad  
PCB recommended hole/pad size

### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## 240 SERIES

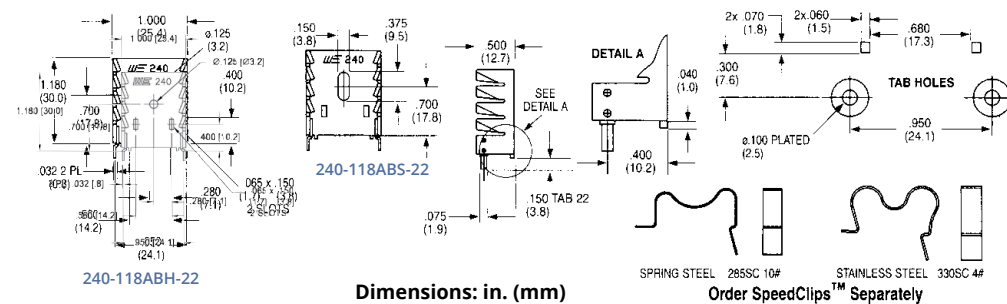
LABOR-SAVING TWISTED FIN HEAT SINKS

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
240-118ABEH-22	1.180 (30.0)	1.000 (25.4) x .500 (12.7)	Vertical	22	Clip/Mtg Hole	55°C @ 4W	5.3°C/W @ 400 LFM
240-118ABES-22	1.180 (30.0)	1.000 (25.4) x .500 (12.7)	Vertical	22	Clip/Mtg Slot	55°C @ 4W	5.3°C/W @ 400 LFM

Material: Aluminum, Black Anodized

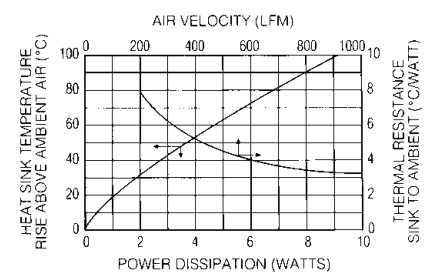
### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

Order SpeedClips™ Separately

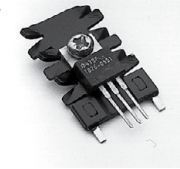
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## 242 SERIES

LOW-COST, LOW-HEIGHT WAVE-SOLDERABLE HEAT SINKS

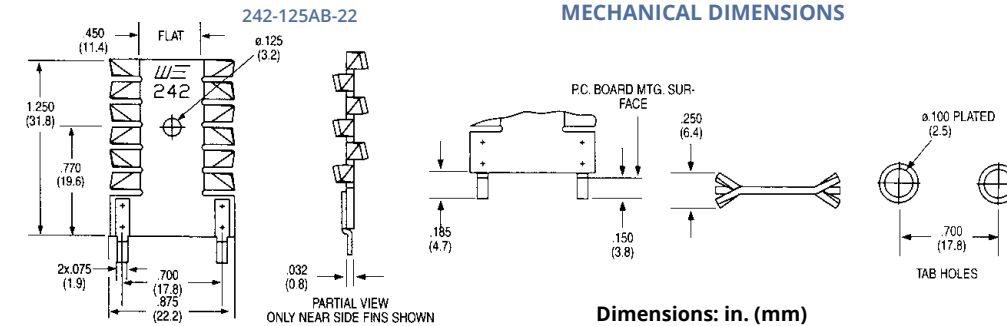
TO-220



Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
242-125ABE-22	1.285 (32.6)	.875 (22.2) x .250 (6.4)	Vertical	22	Mtg Hole	48°C @ 2W	6.2°C/W @ 400 LFM

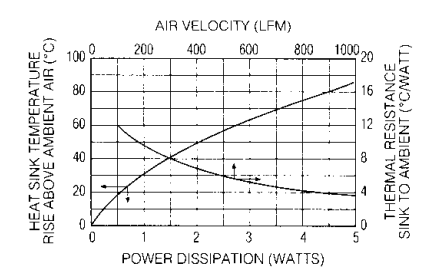
Material: Aluminum, Black Anodized

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

## BOARD LEVEL HEAT SINKS FOR TO-220, TO-218 & MULTIWATT™ COMPONENTS

### 232 & 238 SERIES

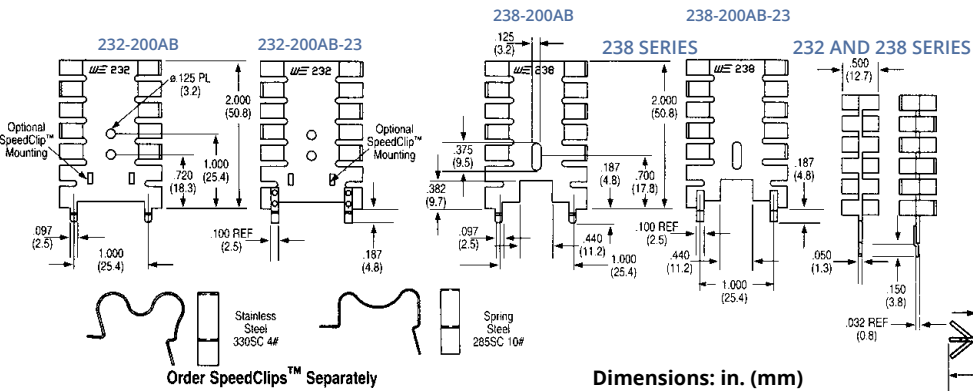
STAGGERED FIN HEAT SINKS FOR  
VERTICAL MOUNTING

TO-220 and TO-202

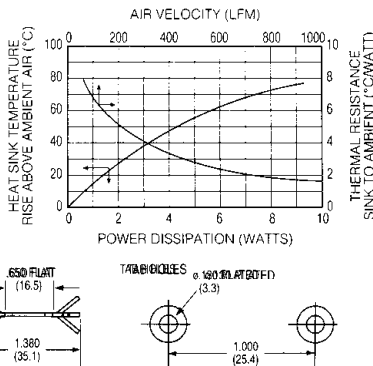
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
232-200AB	2.000 (50.8)	1.380 (35.1) x .500 (12.7)	Vertical	2, Twisted	Clip/Mtg Hole	48°C @ 4W	3.3°C/W @ 400 LFM
232-200ABE-23	2.000 (50.8)	1.380 (35.1) x .500 (12.7)	Vertical	2, Solderable	Clip/Mtg Hole	48°C @ 4W	3.3°C/W @ 400 LFM
238-200AB	2.000 (50.8)	1.380 (35.1) x .500 (12.7)	Vertical	2, Twisted	Mtg Slot	48°C @ 4W	3.3°C/W @ 400 LFM
238-200ABE-23	2.000 (50.8)	1.380 (35.1) x .500 (12.7)	Vertical	2, Solderable	Mtg Slot	48°C @ 4W	3.3°C/W @ 400 LFM

**Material:** Aluminum, Black Anodized

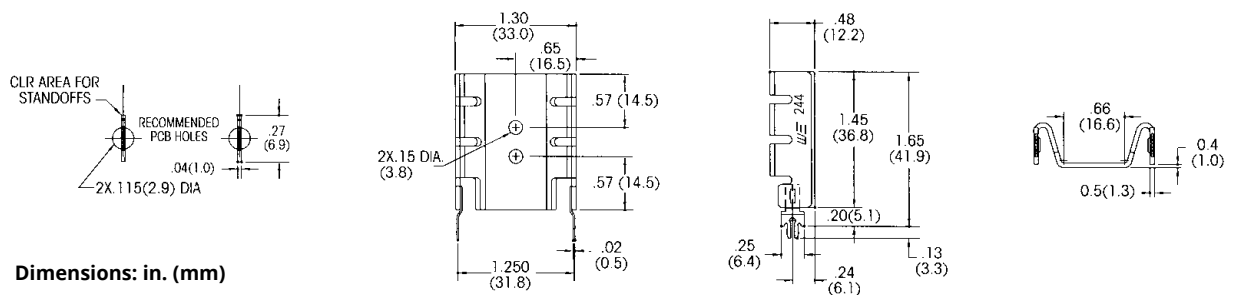
#### MECHANICAL DIMENSIONS



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)



### 245 SERIES

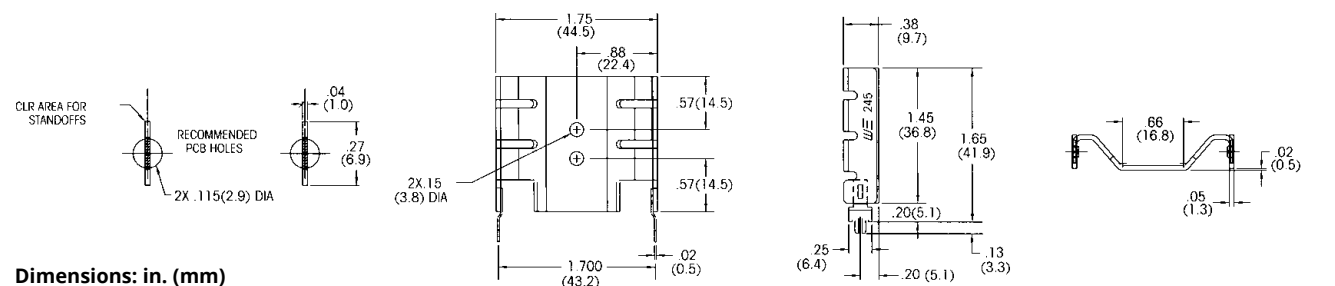
LOW HEIGHT, SLIM PROFILE WAVE-SOLDERABLE  
FOLDED FIN HEAT SINKS

Multiwatt

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
245-145AB	1.450 (36.8)	1.750 (44.5) x .380 (9.7)	Vert./Horiz.	No Tab	38°C @ 4W	3.2°C/W @ 400 LFM	.0160 (7.25)
245-145ABE-50	1.650 (41.9)	1.750 (44.5) x .380 (9.7)	Vertical	50	38°C @ 4W	3.2°C/W @ 400 LFM	.0170 (7.20)

**Material:** Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

### SLIM-PROFILE HEAT SINKS WITH INTEGRAL CLIPS

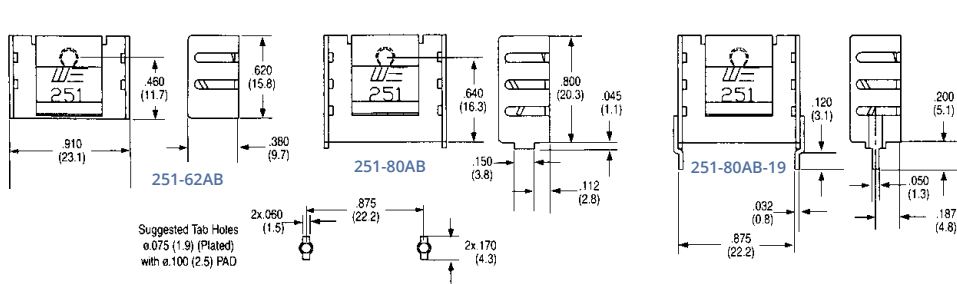
### 251 SERIES

15 Lead Multiwatt

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
251-62AB	.620 (15.7)	.910 (23.1) x .380 (9.7)	Vert./Horiz.	No Tab	Clip	66°C @ 3W	66°C/W @ 400 LFM
251-80AB	.845 (21.5)	.910 (23.1) x .380 (9.7)	Vert./Horiz.	No Tab	Clip	64°C @ 3W	66°C/W @ 400 LFM
251-80ABE-19	.875 (22.2)	.910 (23.1) x .380 (9.7)	Vertical	19	Clip	64°C @ 3W	66°C/W @ 400 LFM

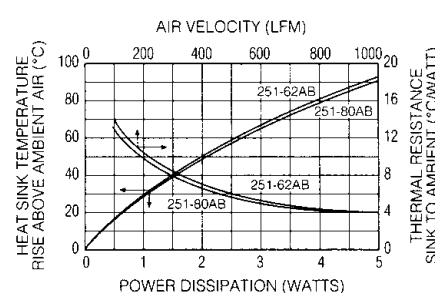
**Material:** Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## BOARD LEVEL HEAT SINKS FOR TO-220, TO-218 & MULTIWATT™ COMPONENTS



### 246 SERIES

MEDIUM HEIGHT, SLIM PROFILE WAVE-SOLDERABLE FOLDED FIN HEAT SINKS

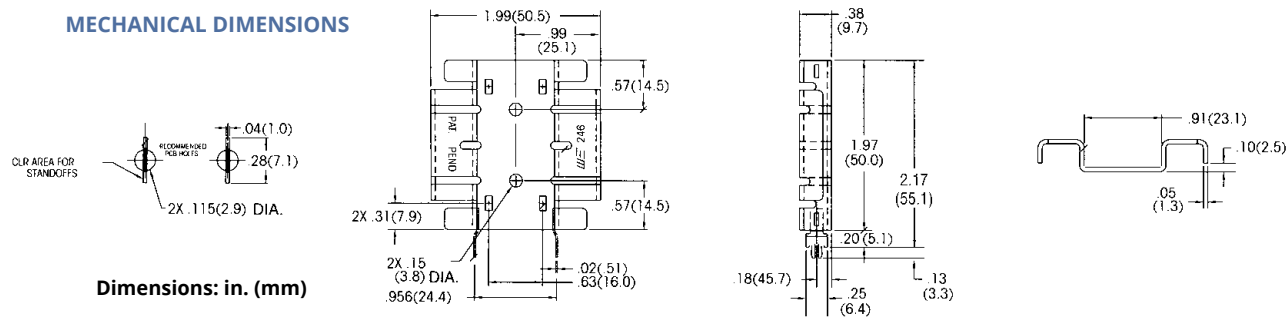
Multiwatt

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
246-197AB	1.968 (50.0)	1.986 (50.4) x 3.75 (9.5)	Vert./Horiz.	No Tab	35°C @ 4W	2.8°C/W @ 400 LFM	.0240 (10.90)
246-197ABE-50	2.168 (55.1)	1.986 (50.4) x 3.75 (9.5)	Vertical	50	35°C @ 4W	2.8°C/W @ 400 LFM	.0250 (11.40)

Order SpeedClip™ 285SC or 330SC separately. (See 248 Series section).

Material: Aluminum, Black Anodized

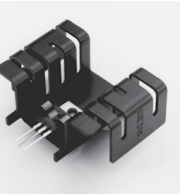
#### MECHANICAL DIMENSIONS



LOW HEIGHT, MEDIUM PROFILE WAVE-SOLDERABLE FOLDED FIN HEAT SINKS

Multiwatt

### 248 SERIES

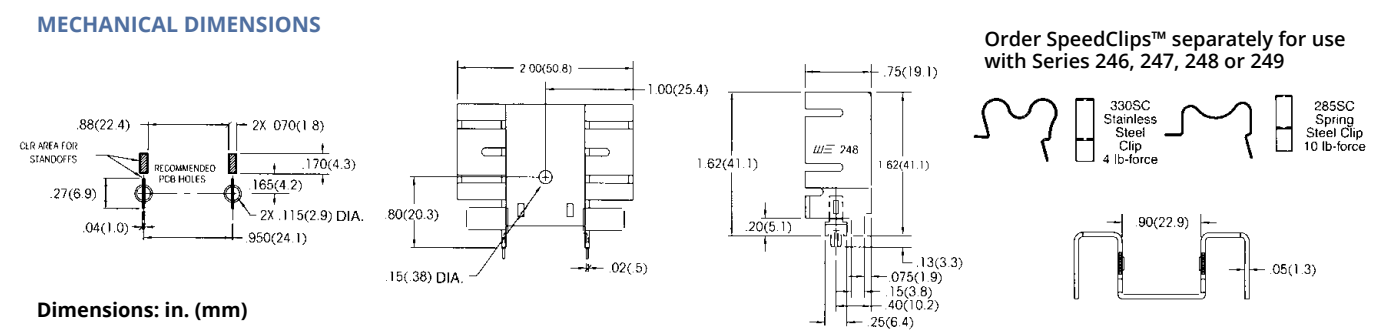


Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
248-162AB	1.620 (41.1)	2.000 (50.8) x .750 (19.1)	Vert./Horiz.	No Tab	35°C @ 4W	2.5°C/W @ 400 LFM	.026 (11.60)
248-162ABE-50	1.620 (41.1)	2.000 (50.8) x .750 (19.1)	Vertical	50	35°C @ 4W	2.5°C/W @ 400 LFM	.027 (12.20)

Order SpeedClip™ 285SC or 330SC separately.

Material: Aluminum, Black Anodized

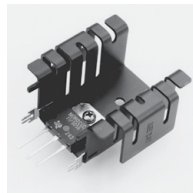
#### MECHANICAL DIMENSIONS



MEDIUM HEIGHT, DEEP PROFILE WAVE-SOLDERABLE FOLDED FIN HEAT SINKS

Multiwatt

### 247 SERIES

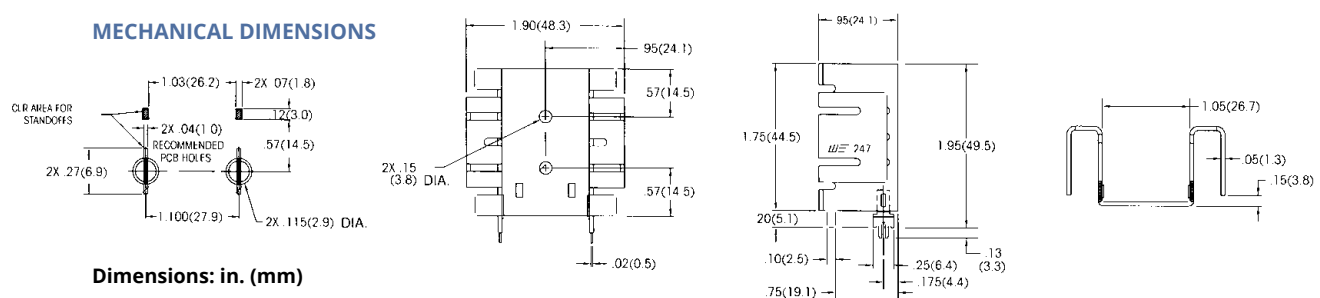


Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
247-195AB	1.950 (49.5)	1.900 (48.3) x .950 (24.1)	Vert./Horiz.	No Tab	25°C @ 4W	2.4°C/W @ 400 LFM	.0330 (15.10)
247-195ABE-50	1.950 (49.5)	1.900 (48.3) x .950 (24.1)	Vertical	50	25°C @ 4W	2.4°C/W @ 400 LFM	.0340 (15.60)

Order SpeedClip™ 285SC or 330SC separately. (See 248 Series section).

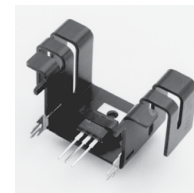
Material: Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



MEDIUM HEIGHT, DEEP PROFILE WAVE-SOLDERABLE FOLDED FIN HEAT SINKS

### 249 SERIES



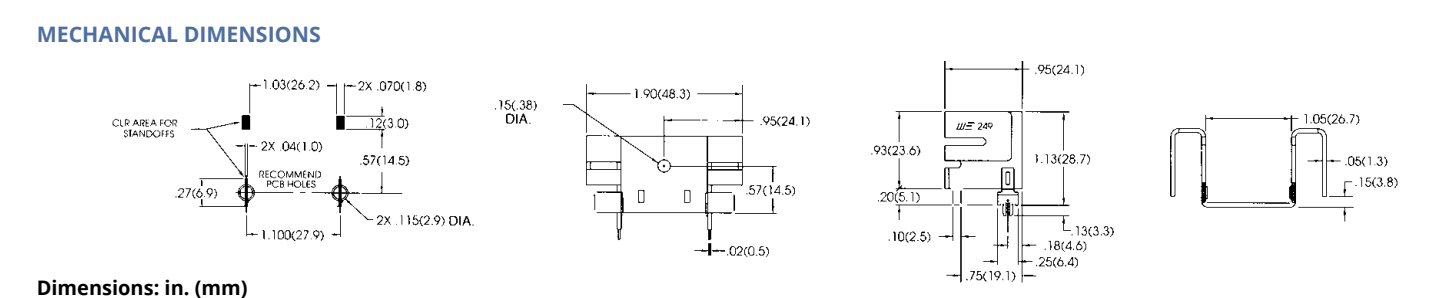
Multiwatt

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
249-113AB	1.130 (28.7)	1.900 (48.3) x .950 (24.1)	Vert./Horiz.	No Tab	35°C @ 4W	3.29°C/W @ 400 LFM	.020 (8.90)
249-113ABE-50	1.130 (28.7)	1.900 (48.3) x .950 (24.1)	Vertical	50	35°C @ 4W	3.29°C/W @ 400 LFM	.021 (9.40)

Order SpeedClip™ 285SC or 330SC separately. (See 248 Series section).

Material: Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS





## BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



### 288 SERIES

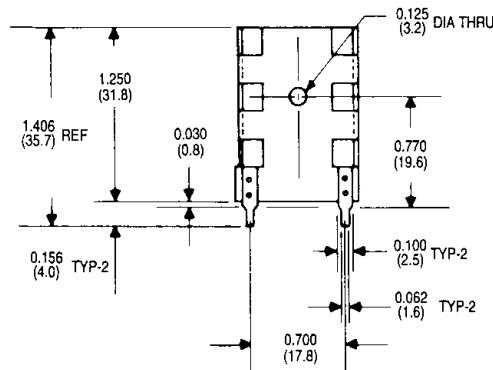
COMPACT WAVE-SOLDERABLE LOW-COST HEAT SINKS

TO-220 and TO-202

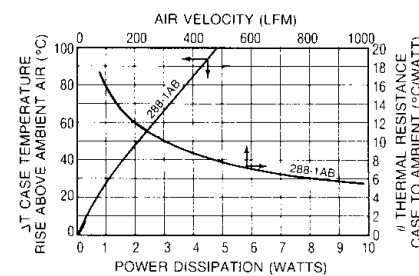
Mounting tabs are pre-tinned to ensure excellent wave-solder bond and good electrical connections for vertical mounting of TO-220 and TO-202 semiconductor packages. These heat sinks are designed for use where minimum PC board space is available. The 288-1AB is a stamped aluminum heat sink, black anodized, designed for applications requiring good heat dissipation from a heat sink occupying minimum space, available at minimum cost.

Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
288-1ABE	1.250 (31.8)	0.875 (22.2) x 0.215 (5.5)	85°C @ 4W	12°C/W @ 200 LFM	0.0057 (2.59)

#### MECHANICAL DIMENSIONS



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS

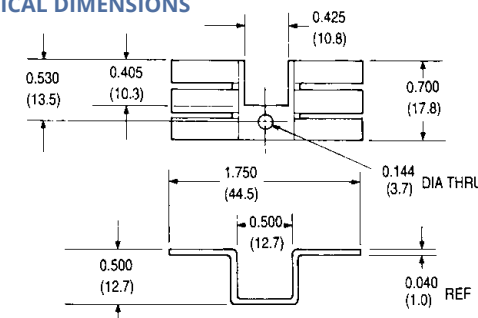


## TOP-MOUNT BOOSTER HEAT SINKS FOR USE WITH 270/272/280 SERIES

### 271 SERIES

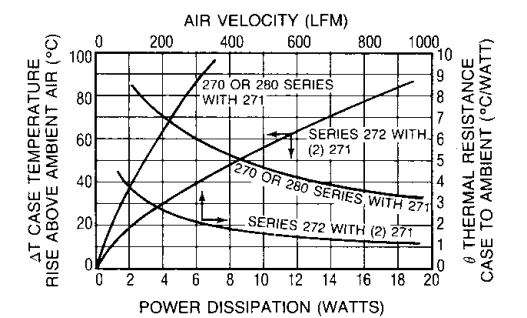
TO-220

#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

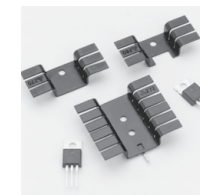
#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



### 270, 272, & 280 SERIES

SMALL FOOTPRINT LOW-COST HEAT SINKS

TO-220 and TO-202



These exceptionally low-cost heat sinks can be mounted horizontally under a TO-220 or TO-202 case style with a maximum height of only 0.375 in. (9.4). For added performance, a 271 Series heat sink can also be used for double-sided heat dissipation. The 270-AB and 280-AB accept one power semiconductor; the 272-AB is designed for two power semiconductors. Specify solderable tab options for the **272 Series** by the addition of suffix "01" or "02" to the standard part number (i.e. 272-AB01 or 272-AB02).

Standard P/N	Height Above PC Board in. (mm)	Horizontal Mounting Maximum Footing in. (mm)	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
270-AB	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0052 (2.36)
272-AB	0.375 (9.4)	1.750 (44.5) x 1.450 (36.8)	01,02	42°C @ 4W	3.6°C/W @ 400 LFM	0.0105 (5.72)
280-AB	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0048 (2.18)

Material: Aluminum, Black Anodized

## TOP-MOUNT BOOSTER HEAT SINKS FOR USE WITH 270/272/280 SERIES

TO-220

### 271 SERIES

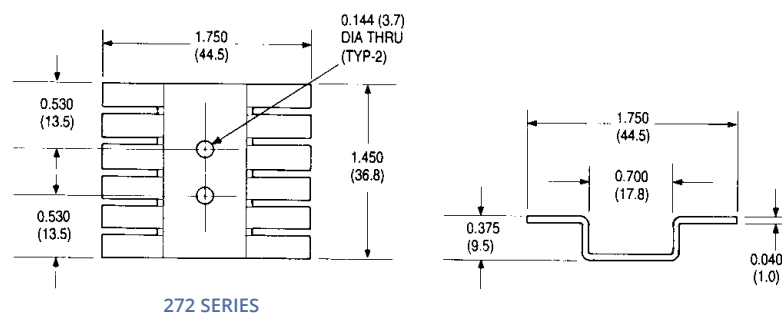
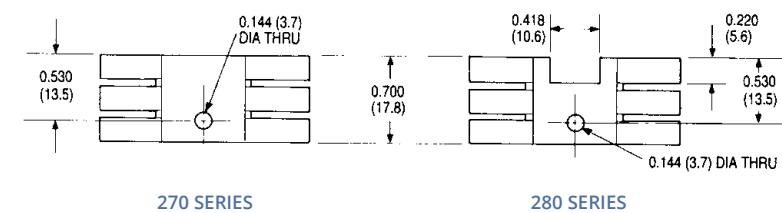
This top-hat style booster heat sink can be added to any of the 270, 272, or 280 Series for improved performance. NOTE A: Thermal resistance with one 271-AB. NOTE B: Thermal resistance (total) as shown with (2) 271-AB types added to (1) 272-AB type.



Standard P/N	Height Above Semiconductor Case in. (mm)	Horizontal Mounting Footprint Dimensions in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
271-AB	0.500 (12.7)	1.750 (44.5) x 0.700 (17.8)	62°C @ 4W (NOTE A) 31°C @ 4W (NOTE B)	5.1°C/W @ 400 LFM 1.8°C/W 400 LFM (NOTE B)	0.0052 (2.36)

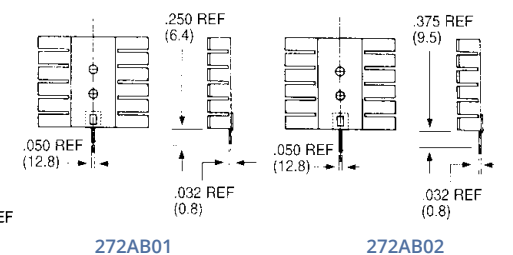
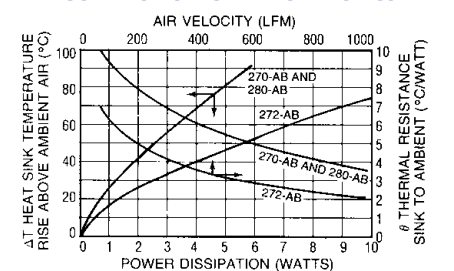
Material: Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



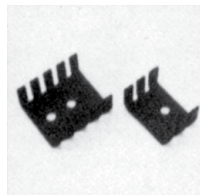
Dimensions: in. (mm)

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



Note:  
1. Suggested Tab Hole = 0.075 ±0.003 plated with 0.100 pad

## BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



### 289 & 290 SERIES

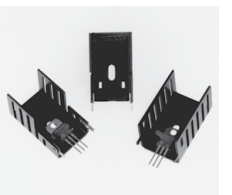
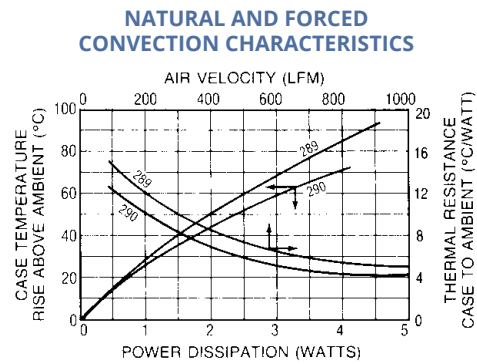
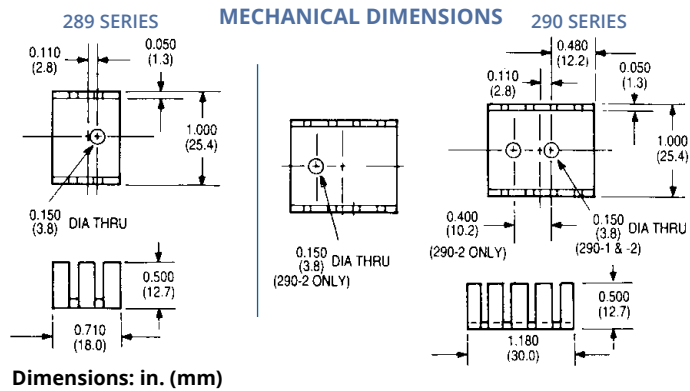
LOW-COST SINGLE OR DUAL PACKAGE  
HEAT SINKS

TO-218; TO-202; TO-220

Low in cost and compact in overall dimensions, one **289 Series** heat sink can accommodate one semiconductor; the **289 Series** is available with a black anodized finish (289-AB) or with no finish (289-AP). Two semiconductors can be mounted to the 290-2AB style.

Standard P/N	Height Above PC Board in. (mm)	Horizontal Mounting Maximum Footing in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
289-AB	0.500 (12.7)	1.000 (25.4) x 0.710 (18.1)	50°C @ 2W	9.0 C/W @ 400 LFM	0.0055 (2.49)
289-AP	0.500 (12.7)	1.000 (25.4) x 0.710 (18.1)	50°C @ 2W	9.0 C/W @ 400 LFM	0.0055 (2.49)
290-1AB	0.500 (12.7)	1.000 (25.4) x 1.180 (30.0)	44°C @ 2W	7.0 C/W @ 400 LFM	0.0082 (3.72)
290-2AB	0.500 (12.7)	1.000 (25.4) x 1.180 (30.0)	44°C @ 2W	7.0 C/W @ 400 LFM	0.0081 (3.67)

**Material:** Aluminum, Black Anodized



HIGH-PERFORMANCE, HIGH-POWER VERTICAL  
MOUNT HEAT SINKS

### 237 & 252 SERIES

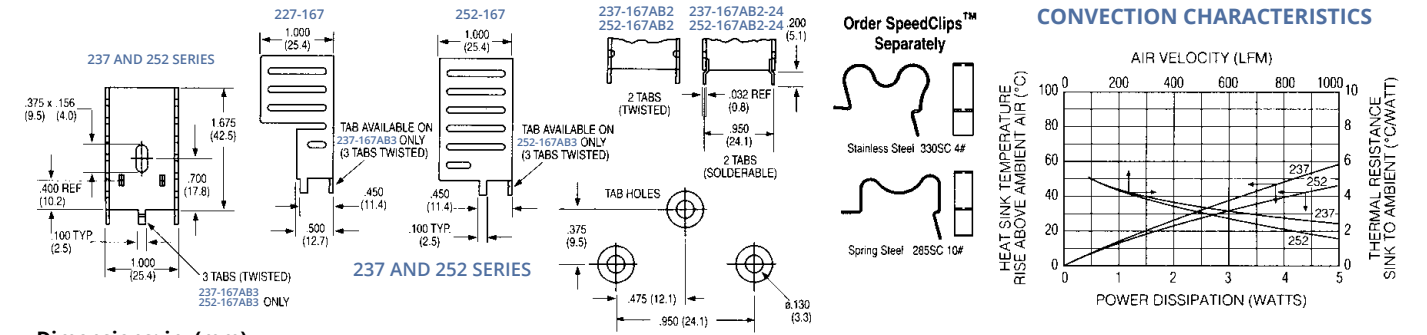
TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
237-167AB2	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Twisted	Clip/Mtg	Slot46°C @ 4W	4.5°C/W @ 200 LFM
237-167AB3	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	3, Twisted	Clip/Mtg	Slot46°C @ 4W	4.5°C/W @ 200 LFM
237-167ABE2-24	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Solderable	Clip/Mtg	Slot46°C @ 4W	4.5°C/W @ 200 LFM
252-167AB2	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Twisted	Clip/Mtg	Slot40°C @ 4W	4.5°C/W @ 200 LFM
252-167AB3	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	3, Twisted	Clip/Mtg	Slot40°C @ 4W	4.5°C/W @ 200 LFM
252-167ABE2-24	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Solderable	Clip/Mtg	Slot40°C @ 4W	4.5°C/W @ 200 LFM

Order SpeedClips™ 2855C or 3305C separately for rapid component installation, lowering manufacturing costs.

**Material:** Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS

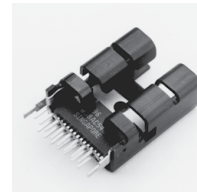


**Dimensions: in. (mm)**

HIGH-PERFORMANCE SLIM PROFILE HEAT SINKS  
WITH INTEGRAL CLIPS

Multiwatt

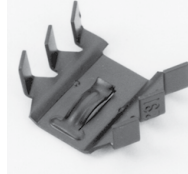
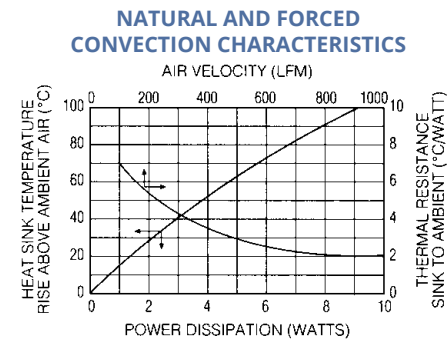
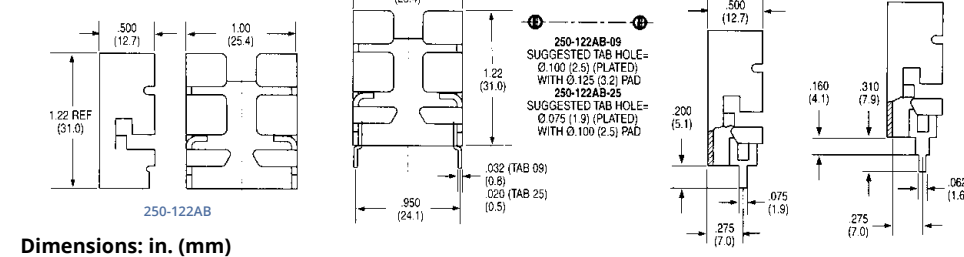
### 250 SERIES



Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
250-122AB	1.220 (31.0)	1.000 (25.4) x .500 (12.7)	Vert./Horiz.	No Tab	Clip	50°C @ 4W	3.7°C/W @ 400 LFM
250-122ABE-09	1.220 (31.0)	1.000 (25.4) x .500 (12.7)	Vertical	09	Clip	50°C @ 4W	3.7°C/W @ 400 LFM
250-122ABE-25	1.380 (35.1)	1.000 (25.4) x .500 (12.7)	Vertical	25	Clip	50°C @ 4W	3.7°C/W @ 400 LFM

**Material:** Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



### 291 SERIES

LABOR-SAVING CLIP-ON HEAT SINKS

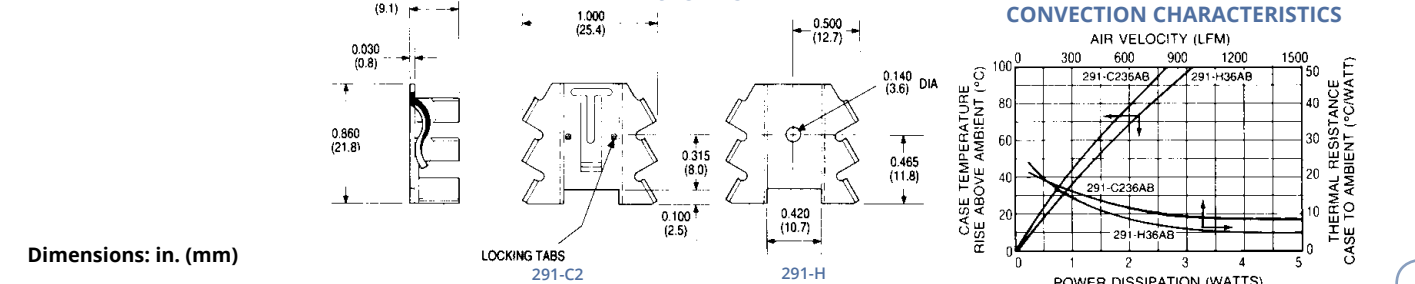
TO-220

Designed for mounting horizontally or vertically on a circuit board, **291 Series** heat sinks employ a unique clip for attachment of TO-220 case styles. One type is available with a locking clip and one with a 0.140 in. (3.6) diameter mounting hole only.

Standard P/N	Vertical Height Above PC Board in. (mm)	Mounting Footprint Dimensions in. (mm)	Mounting Style	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
291-C236AB	0.860 (21.9)	1.100 (27.0) x 0.360 (9.1)	TO-220 (Clip)	80°C @ 2W	24°C/W @ 600 LFM	0.0026 (1.18)
291-H36AB	0.860 (21.9)	1.100 (27.0) x 0.360 (9.1)	TO-220 (Mtg. Hole)	68°C @ 2W	16°C/W @ 600 LFM	0.0026 (1.18)

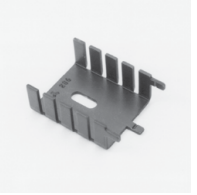
**Material:** Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS



**Dimensions: in. (mm)**

# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



## 286 SERIES

ALUMINUM AND COPPER LOW-COST WAVE-SOLDERABLE HEAT SINKS

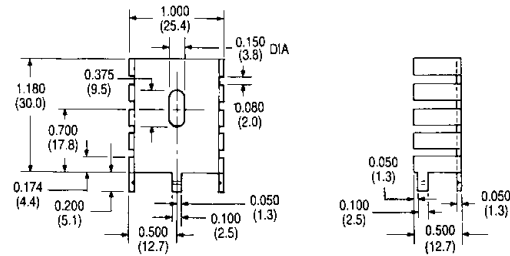
TO-220

Efficient heat removal at low cost can be achieved by inserting the **286 Series** directly into pre-drilled circuit boards; scored mounting tabs may be bent after insertion to provide added stability. The **286 Series** can be wave-soldered directly to the board. See also 286DB Series on page 55.

Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Material	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
286-AB	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Aluminum, Anodized	58°C @ 4W	7.4°C/W @ 200 LFM	0.0085 (3.86)
286-CBTE	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Copper, Black	58°C @ 4W	7.4°C/W @ 200 LFM	0.0250 (11.34)
286-CTE	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Copper, Tinned	58°C @ 4W	7.4°C/W @ 200 LFM	0.0250 (11.34)

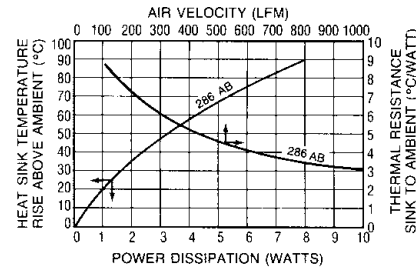
**Material:** 286-AB style (aluminum, black anodized), 286-CBT style (copper, black paint tin tabs), and 286-CT style (copper, tinned).

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

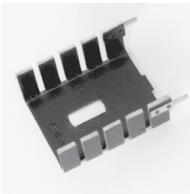
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## WAVE-SOLDERABLE LOW-COST HEAT SINKS

## 287 SERIES

TO-220

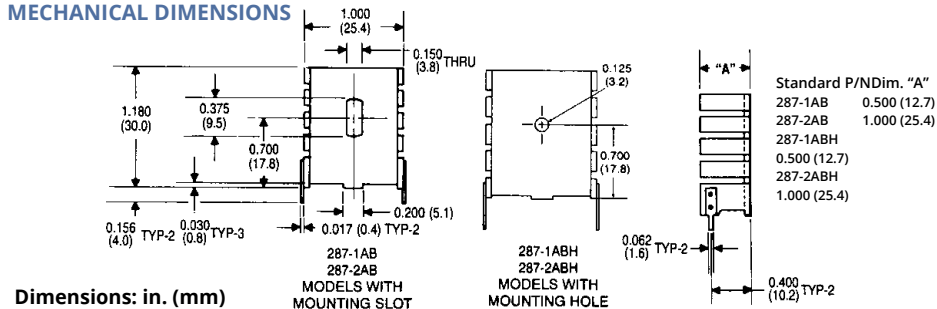


Mount these cost-effective TO-220 heat sinks vertically into pre-drilled printed circuit boards. Soldered, pre-tinned tabs can be wavesoldered directly to the board. A 0.375 in. (9.5 mm) mounting slot allows for correct positioning of TO-220 and similar semiconductor packages.

Standard P/N		Height Above PC Board in. (mm)	Maximum Footprint "A" in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
Mounting Slot	Mounting Hole			Natural Convection	Forced Convection	
287-1ABE	287-1ABH	1.180 (30.0)	1.000 (25.4) x 0.500 (12.7)	65°C @ 4W	7.8°C/W @ 200 LFM	0.0090 (4.08)
287-2ABE	287-2ABH	1.180 (30.0)	1.000 (25.4) x 1.000 (25.4)	55°C @ 4W	6.4°C/W @ 200 LFM	0.0140 (6.35)

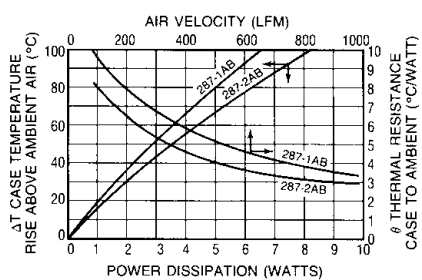
**Material:** Aluminum, Black Anodized

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## 285 SC AND 330 SC SPEEDCLIPS™

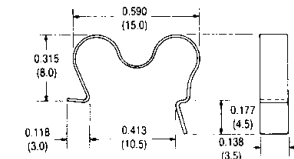
## 285 & 330 SERIES



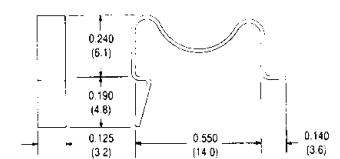
SpeedClips™ employ a locking safety tab for mounting. Must be ordered separately for these heat sink series. Use these SpeedClips™ with our 237, 240, and 252 Series heat sinks for the lowest production assembly time and cost. Order one SpeedClip™ for each heat sink purchased. Must be purchased with heat sinks.

Standard P/N	Nominal Installed Loading Force	For Use With Series	Material	Weight lbs. (grams)
285 SC	10 lbs	232, 237, 240, 252, 667	Carbon Steel	0.00053 (0.24)
330 SC	4 lbs	232, 237, 240, 252, 667	Stainless Steel	0.00074 (0.34)

### MECHANICAL DIMENSIONS



Speed Clip  
330 SC  
4 lb (17.8N)  
Nominal Force Installed



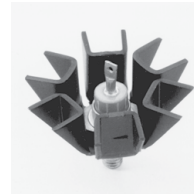
Speed Clip  
285 SC  
10 lb (44.5N)  
Nominal Force Installed

Dimensions: in. (mm)

## 695 SERIES

SPACE-SAVING HEAT SINKS FOR SMALL STUD-MOUNTED DIODES

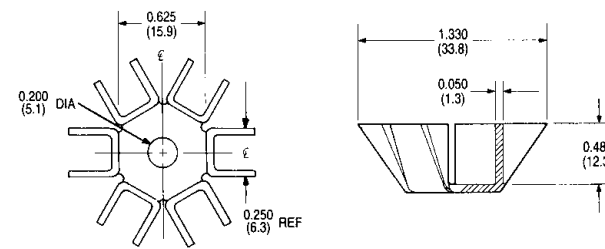
Stud-Mount



Mount and effectively heat sink small stud-mounted diodes with the **695 Series** space-saving heat sink type. Each unit is black anodized aluminum with an 0.200 in. (5.1) dia. mounting hole centered in the base. The folded fin design provides good heat dissipation for use where height is limited above the printed circuit board or base plate.

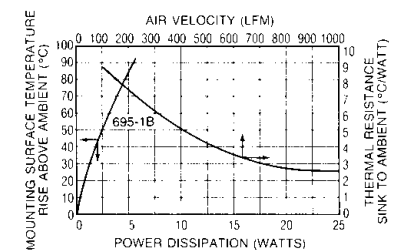
Standard P/N	Maximum Width in. (mm)	Height in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
695-1B	1.330 (33.8)	0.530 (13.7)	72°C @ 4.0W	5.2°C/W @ 400 LFM	0.008 (4.0)

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

### NATURAL AND FORCED CONVECTION CHARACTERISTICS



# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

## 260 SERIES

CUP CLIPS FOR TO-5 CASE STYLE SEMICONDUCTORS

TO-5

Characteristics	TO-5
Thermal Resistance – Epoxy Insulated	14° C/W
Breakdown Voltage – Epoxy Type (VAC), 60 Hz	500
Recommended Operating Voltage, AC or DC	
Clean Conditions: % Hipot Rating	50
Dusty Conditions: % Hipot Rating	30
Dirty Conditions: % Hipot Rating	10 to 20
Temperature Range — Continuous (C°)	-73/+149

Model	Depth of Tapped Base
260-4T5E	0.093 (2.36)
260-4TH5E	0.125 (3.18)

Thread Size:	Base Style:
4 = #4-40 UNC	H = hex
6 = #6-32 UNC	Semiconductor
Mounting Style:	Case Style:
T = tapped	5 = TO-5
S = stud	Insulation E = epoxy
P = plain	

Standard P/N	Outline Dimension Insulation Type	L x W x I.D. in. (mm)	Weight lbs. (grams)	Case Style
260-4T5E	Epoxy Insulated	0.370 (9.4) x 0.380 (9.7) dia. x 0.290 (7.4)	0.0024 (1.09)	TO-5
260-4TH5E	Epoxy Insulated	0.400 (10.2) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0031 (1.41)	TO-5
260-6SH5E	Epoxy Insulated	0.557 (14.1) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0037 (1.68)	TO-5

**Materials and Finish:** Cups – beryllium copper, black ebonol "C"; Bases – brass, black ebonol "C"

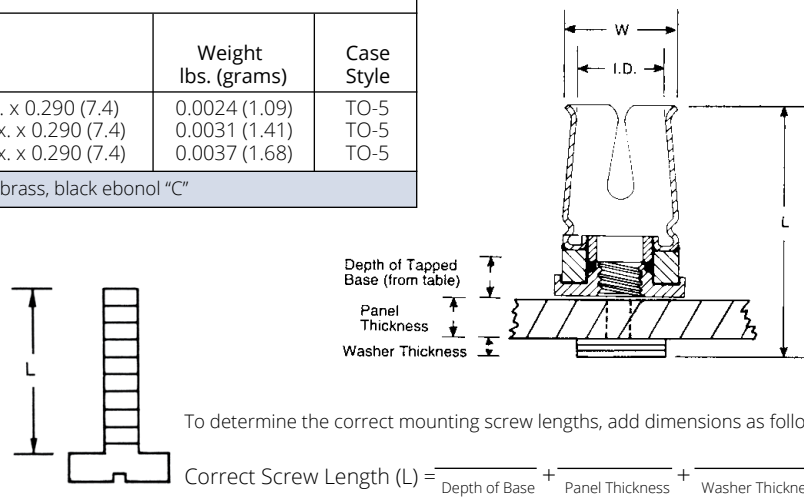
### Base Mounting Configurations — TO-5

**Plain Type** — Epoxy bonded, or used with #4 pan head screws.

**Tapped Base** — #4-40 UNC screw (not supplied) fits tapped hole. Care should be taken not to use too long a screw, which could short against the semiconductor case. For correct screw lengths:

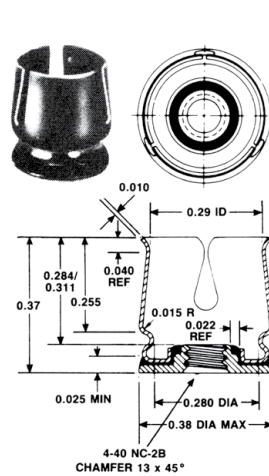
$$\text{Correct Screw Length (L)} = \text{Depth of Base} + \text{Panel Thickness} + \text{Washer Thickness}$$

**Stud Mounting Base.** #6-32 UNC. Nuts and washers not supplied. Stud hole must be slightly countersunk to ensure flat mounting.

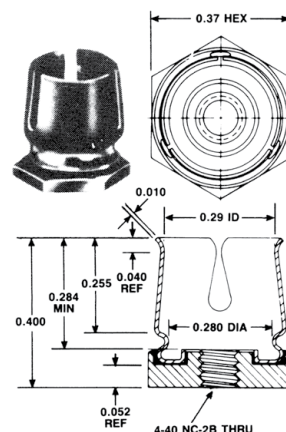


## EPOXY INSULATED FOR TO-5

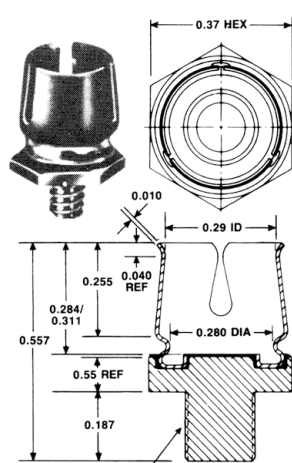
## 260 SERIES



260-4T5E



260-4TH5E



260-6SH5E

Diodes

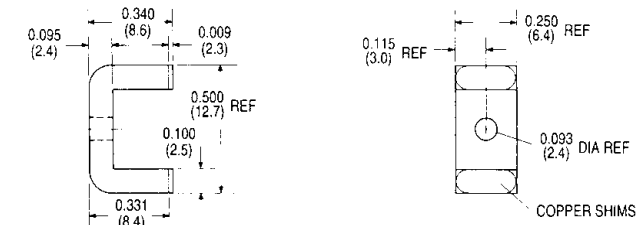
THERMAL LINKS FOR FUSED GLASS DIODES

## 258 SERIES

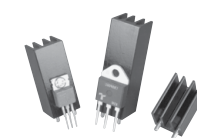
The thermal resistance from diode leads to chassis or heat sink is 12°C/watt, when unit is mounted with TYPE 120 joint Compound. If a 10°C/watt chassis or sink to ambient impedance is available, the thermal resistance from the diode leads to ambient is reduced from about 150°C/watt to 22°C/watt.

Standard P/N	Dimensions in. (mm)	Material	Finish	Weight lbs. (grams)
258	0.500 (12.7) x 0.250 (6.4) x 0.340 (8.6)	Aluminum	DeltaCoate™ 151 on all surfaces except solder pads and base	0.0018 (0.82)

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)



## 634 SERIES

SLIM PROFILE UNIDIRECTIONAL FIN VERTICAL MOUNT HEAT SINK

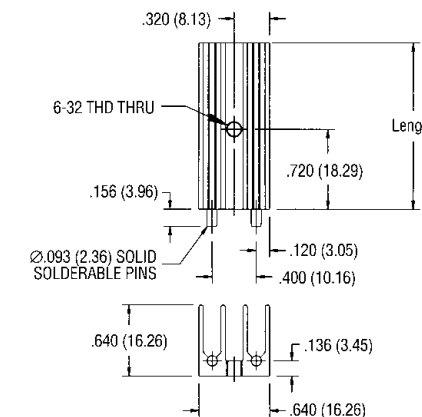
TO-220 and TO-218

These slim profile unidirectional fin heat sinks offer users two assembly alternatives for vertically mounting TO-220 and TO-218 components. Models are available with or without wave-solderable pins on 0.40 in. (10.2) centers, making them ideal for a variety of applications where quick assembly is needed and space is at a premium.

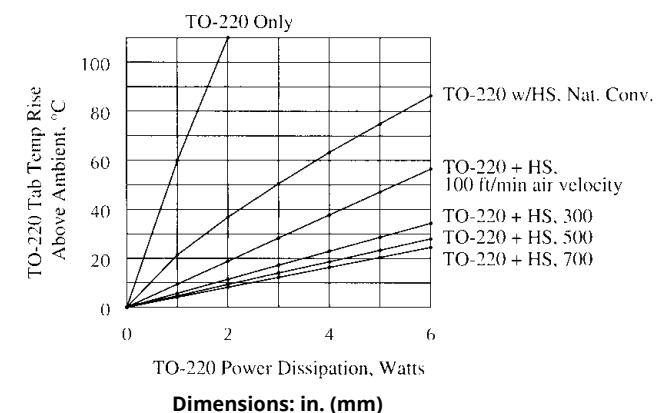
Standard P/N		Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Weight lbs. (grams)
Plain Pin	Without Pin			
634-10ABEP	634-10AB	1.000 (25.4)	0.640 (16.26) x 0.640 (16.26)	0.016 (7.48)
634-15ABEP	634-15AB	1.500 (38.1)	0.640 (16.26) x 0.640 (16.26)	0.025 (11.21)
634-20ABEP	634-20AB	2.000 (50.8)	0.640 (16.26) x 0.640 (16.26)	0.033 (14.95)

**Material:** Aluminum, Black Anodized.

### MECHANICAL DIMENSIONS



### TYPICAL THERMAL PERFORMANCE FOR 634-15ABP



### NOTES:

1. Thermal compound is assumed between device and heat sink.
2. Tab temp with longer heat sink (634-20ABP) will typically be about 15% cooler. Tab temp with shorter heat sink (634-10ABP) will typically be about 25% higher.

## BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

### 292 SERIES HEAT SINK FOR SINGLE TO-92

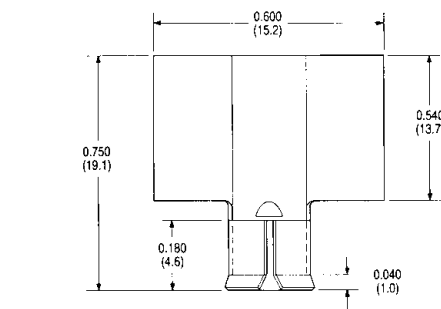
TO-92

Power semiconductors packaged in a TO-92 style plastic case can be cooled effectively at little additional cost with the addition of the 292-AB heat sink. The 292-AB is effective over the typical power range of such devices.

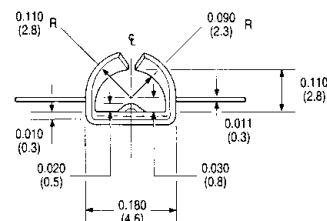
Standard P/N	Height Above PC Board in. (mm)	Overall Fin Width in. (mm)	Thermal Performance Natural Convection	Finish	Weight lbs. (grams)
292-AB	0.750 (19.1)	0.600 (15.3)	0.225°C/W @ 0.250 W	Black Anodized	0.00049 (0.22)

**Material:** Aluminum, Black Anodized

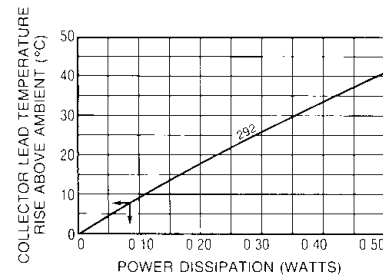
#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



### HIGH-EFFICIENCY HEAT SINKS FOR VERTICAL BOARD MOUNTING

TO-220

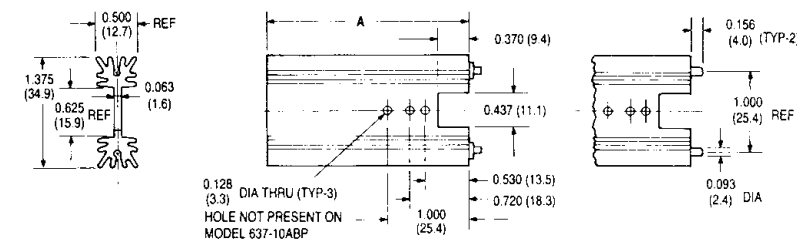
### 637 SERIES

Wave-solderable pins on 1 in. centers for vertical mounting on printed circuit boards. Maximum semiconductor package width 0.625 in. (15.9). Use this heat sink where weight and board space occupied must be minimized. Refer to the Accessory products section for thermal interface materials, thermal compounds, and other accessories products.

Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
637-10ABEP	1.000 (25.4)	1.375 (34.9) x 0.500 (12.7)	76°C @ 6W	5.8°C/W @ 200 LFM	0.023 (10.43)
637-15ABEP	1.500 (38.1)	1.375 (34.9) x 0.500 (12.7)	65°C @ 6W	5.5°C/W @ 200 LFM	0.035 (15.88)
637-20ABEP	2.000 (50.8)	1.375 (34.9) x 0.500 (12.7)	55°C @ 6W	4.7°C/W @ 200 LFM	0.050 (22.68)
637-25ABEP	2.500 (63.5)	1.375 (34.9) x 0.500 (12.7)	48°C @ 6W	4.2°C/W @ 200 LFM	0.062 (28.12)

**Material:** Aluminum, Black Anodized

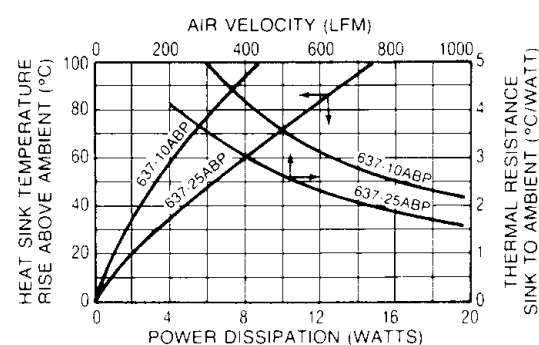
#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

#### 637 SERIES (EXTRUSION PROFILE 5183)

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



### LABOR-SAVING SPEEDCLIP™ HEAT SINKS FOR VERTICAL BOARD MOUNTING

TO-220

### 667 SERIES

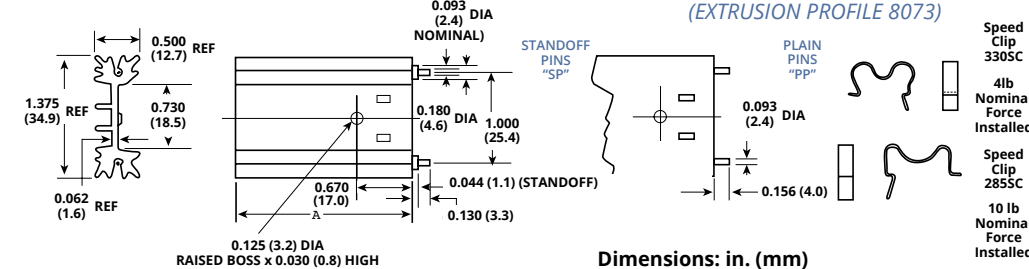
Excellent performance, choice of wave-solderable plain pins (PP-Type) or wave-solderable hex-shaped standoff pins (SP-Type), and reduced assembly cost.

Standard P/N Standoff Pin	Standard P/N Plain Pin	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
667-10ABESP	667-10ABPP	1.000 (25.4)	1.375 (34.9) x 0.500 (12.7)	76°C @ 6W	5.8°C/W @ 200 LFM	0.0240 (11.0)
667-15ABESP	667-15ABPP	1.500 (38.1)	1.375 (34.9) x 0.500 (12.7)	66°C @ 6W	5.5°C/W @ 200 LFM	0.0340 (15.6)
667-20ABESP	667-20ABPP	2.000 (50.8)	1.375 (34.9) x 0.500 (12.7)	58°C @ 6W	4.7°C/W @ 200 LFM	0.0460 (21.0)
667-25ABESP	667-25ABPP	2.500 (63.5)	1.375 (34.9) x 0.500 (12.7)	48°C @ 6W	4.2°C/W @ 200 LFM	0.0580 (26.2)

Order 330 SC or 285 SC SpeedClip™ separately.

Wave-solderable pins. Material: Aluminum, Black Anodized

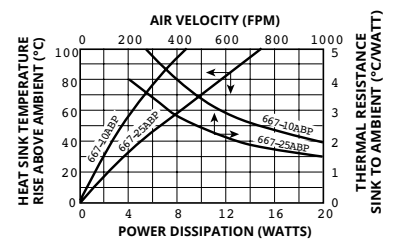
#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

#### 667 SERIES (EXTRUSION PROFILE 8073)

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



### 626 & 627 SERIES

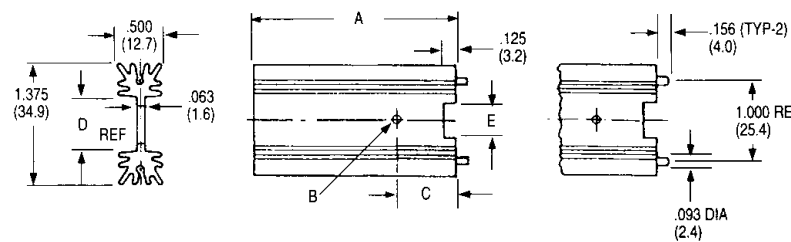
### HIGH-EFFICIENCY HEAT SINKS FOR VERTICAL BOARD MOUNTING

TO-220 and TO-218

Standard P/N	Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
				Natural Convection	Forced Convection
626-10ABEP	627-10ABP	1.000 (25.4)	1.375 (34.9) x .500 (12.7)	76°C @ 6W	5.8°C/W @ 200 LFM
626-15ABEP	627-15ABP	1.500 (38.1)	1.375 (34.9) x .500 (12.7)	65°C @ 6W	5.5°C/W @ 200 LFM
626-20ABEP	627-20ABP	2.000 (50.8)	1.375 (34.9) x .500 (12.7)	55°C @ 6W	4.7°C/W @ 200 LFM
626-25ABEP	627-25ABP	2.500 (63.5)	1.375 (34.9) x .500 (12.7)	48°C @ 6W	4.2°C/W @ 200 LFM

**Wave-solderable pins. Material:** Aluminum, Black Anodized

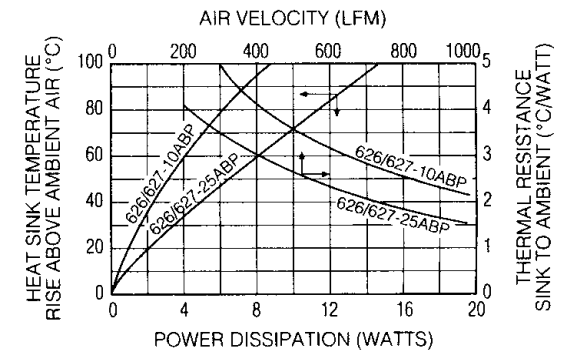
#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

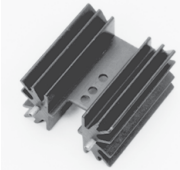
#### 626 AND 627 SERIES

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



Series	Type Device	Hole Diameter "B"	Hole Height "C"	Webb Width "D"	Notch Width "E"	Extrusion Profile
626	TO-218	.144 (3.7)	.850 (21.6)	.660 (16.8)	.540 (13.7)	8420
627	TO-220	.128 (3.3)	.720 (18.3)	.625 (15.9)	.437 (11.1)	5183

## BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



### 647 SERIES

HIGH-PERFORMANCE HEAT SINKS FOR VERTICAL BOARD MOUNTING

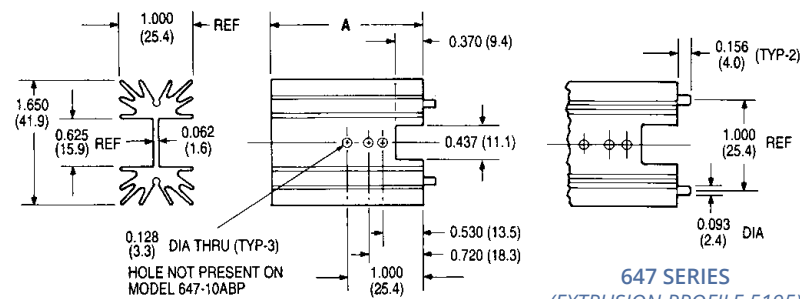
TO-220

Wave-solderable pins on 1 in. centers for vertical mounting of larger devices on printed circuit boards. Maximum semiconductor package width: 0.625 (15.9). Refer to the Accessory Products section for thermal interface materials, 126 Series silicone-free thermal compounds, and other accessories products.

Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
647-10ABEP	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	42°C @ 6W	3.8°C/W @ 200 LFM	0.055 (24.95)
647-15ABEP	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	37°C @ 6W	3.5°C/W @ 200 LFM	0.075 (34.02)
647-175ABEP	1.750 (44.5)	1.650 (41.9) x 1.000 (25.4)	34°C @ 6W	3.3°C/W @ 200 LFM	0.090 (40.82)
647-20ABEP	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	31°C @ 6W	3.1°C/W @ 200 LFM	0.104 (47.17)
647-25ABEP	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	25°C @ 6W	2.8°C/W @ 200 LFM	0.125 (56.70)

**Material:** Aluminum, Black Anodized

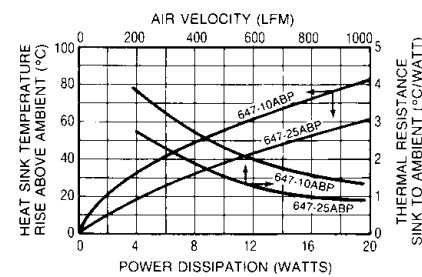
#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

647 SERIES  
(EXTRUSION PROFILE 5195)

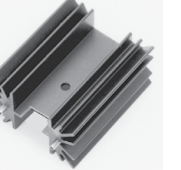
#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## HIGH-PERFORMANCE NOTCHED HEAT SINKS FOR VERTICAL BOARD MOUNTING

TO-218; TO-247; TO-220

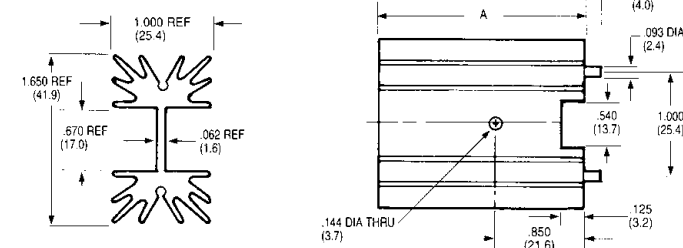
### 657 SERIES



Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
657-10ABEPN	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	41°C @ 6W	3.7°C/W @ 200 LFM
657-15ABEPN	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	38°C @ 6W	3.3°C/W @ 200 LFM
657-20ABEPN	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	32°C @ 6W	2.9°C/W @ 200 LFM
657-25ABEPN	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	25°C @ 6W	2.7°C/W @ 200 LFM

**Wave-solderable pins. Material:** Aluminum, Black Anodized

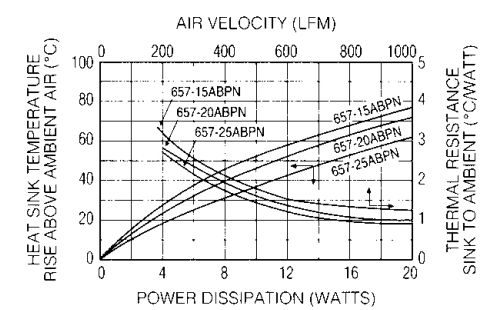
#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

657 SERIES  
(EXTRUSION PROFILE 6533)

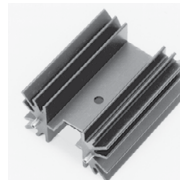
#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## HIGH-PERFORMANCE HEAT SINKS FOR VERTICAL BOARD MOUNTING

TO-218; TO-247; TO-220

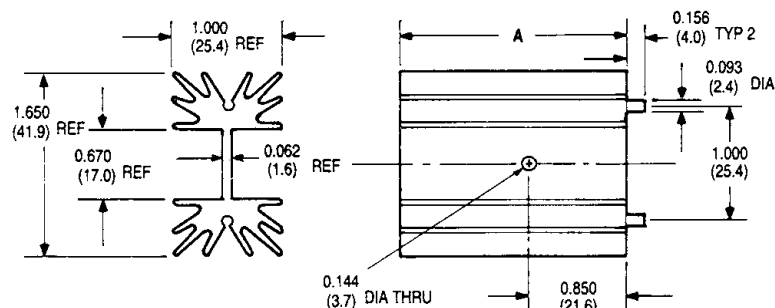
### 657 SERIES



Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs (grams)
			Natural Convection	Forced Convection	
657-10ABEP	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	41°C @ 6W	3.7°C/W @ 200 LFM	0.0515 (23.36)
657-15ABEP	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	38°C @ 6W	3.3°C/W @ 200 LFM	0.0760 (34.60)
657-20ABEP	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	32°C @ 6W	2.9°C/W @ 200 LFM	0.1030 (47.00)
657-25ABEP	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	25°C @ 6W	2.7°C/W @ 200 LFM	0.1250 (57.00)

**Wave-solderable pins. Material:** Aluminum, Black Anodized

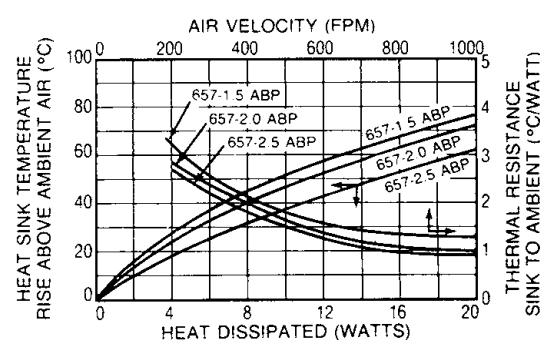
#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

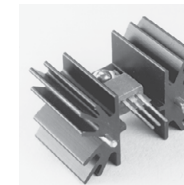
657 SERIES  
(EXTRUSION PROFILE 6533)

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## HIGH-PERFORMANCE HEAT SINKS WITH SPEEDCLIPS™ FOR VERTICAL BOARD MOUNTING

TO-218; TO-247; TO-220

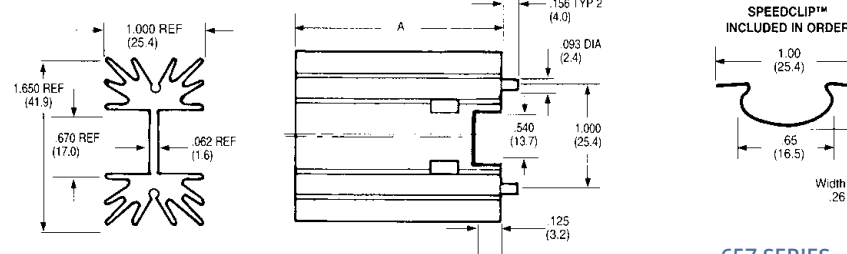


### 657 SERIES

Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
657-10ABEPSC	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	41°C @ 6W	3.7°C/W @ 200 LFM
657-15ABEPSC	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	38°C @ 6W	3.3°C/W @ 200 LFM
657-20ABEPSC	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	32°C @ 6W	2.9°C/W @ 200 LFM
657-25ABEPSC	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	25°C @ 6W	2.7°C/W @ 200 LFM

**Wave-solderable pins. Material:** Aluminum, Black Anodized

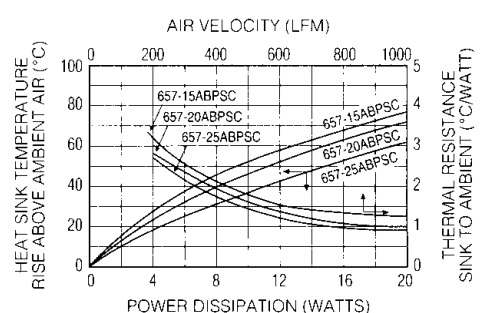
#### MECHANICAL DIMENSIONS



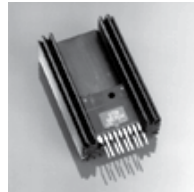
Dimensions: in. (mm)

657 SERIES  
(EXTRUSION PROFILE 6533)

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



## 677 SERIES

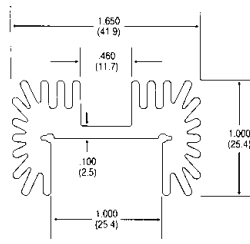
HIGH-PERFORMANCE, HIGH-POWER HEAT SINKS FOR VERTICAL BOARD MOUNTING

TO-218; TO-220; TO-247;  
15-Lead Multiwatt

Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
677-10ABEP	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	52°C @ 6W	3.1°C/W @ 200 LFM
677-15ABEP	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	46°C @ 6W	2.8°C/W @ 200 LFM
677-20ABEP	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	40°C @ 6W	2.5°C/W @ 200 LFM
677-25ABEP	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	35°C @ 6W	2.2°C/W @ 200 LFM

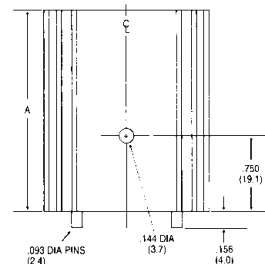
Wave-solderable pins. Material: Aluminum, Black Anodized

### MECHANICAL DIMENSIONS

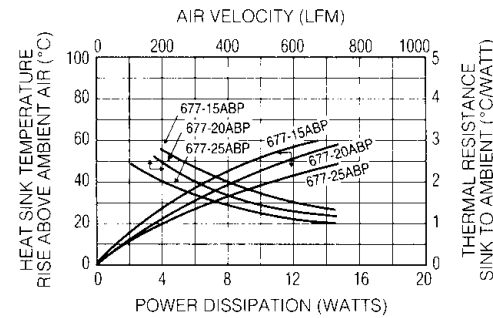


Dimensions: in. (mm)

677 SERIES  
(EXTRUSION  
PROFILE 8719)



### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## HIGHEST EFFICIENCY/LOWEST UNIT COST HEAT SINKS

TO-3; TO-66; TO-220

## 690 SERIES

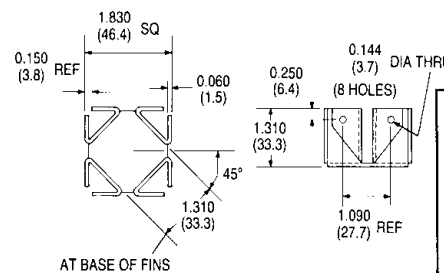
These low-cost heat sinks provide the most power dissipation at the lowest unit cost and are available in three standard types to mount and cool one TO-3 or TO-66 metal power semiconductor type or two plastic package TO-220 power semiconductor types. For higher power semiconductors, the 690 Series can dissipate up to 20 watts while maintaining a mounting surface temperature rise above ambient air temperature of no more than 91°C.



Standard P/N	Height Above PC Board in. (mm)	Outline Dimensions in. (mm)	Thermal Performance at Typical Load		Semiconductor Mounting Hole Pattern	Weight lbs. (grams)
			Natural Convection	Forced Convection		
690-3B	1.310 (33.3)	1.860 (47.2)-sq	44°C @ 7.5W	2.0°C/W @ 400 LFM	(1) TO-3	0.0700 (31.75)
690-66B	1.310 (33.3)	1.860 (47.2)-sq	44°C @ 7.5W	2.0°C/W @ 400 LFM	(1) TO-66	0.0700 (31.75)
690-220B	1.310 (33.3)	1.860 (47.2)-sq	44°C @ 7.5W	2.0°C/W @ 400 LFM	(2) TO-220	0.0700 (31.75)

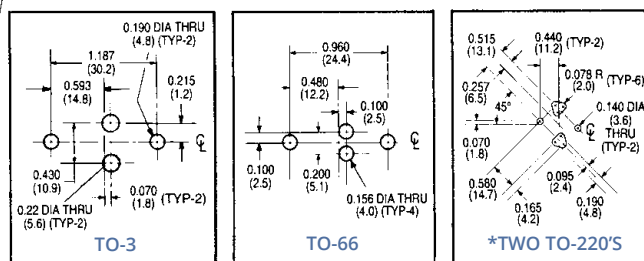
Material: Aluminum, Black Anodized

### MECHANICAL DIMENSIONS

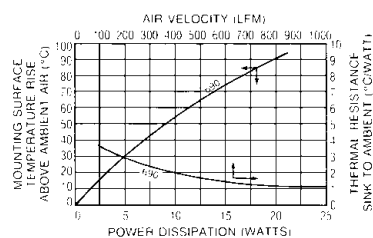


Dimensions: in. (mm)

### SEMICONDUCTOR MOUNTING HOLES



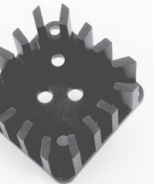
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



TO-3; TO-220

## MAXIMUM EFFICIENCY OMNIDIRECTIONAL HEAT SINKS

## 680 SERIES

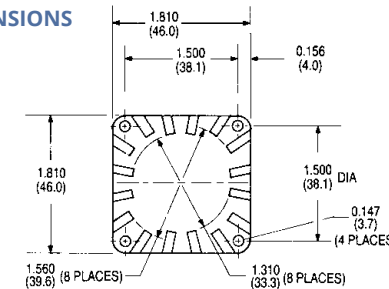


Achieve optimum natural convection cooling per unit volume occupied above the printed circuit board for TO-3 (one semiconductor package per heat sink) or for two TO-220 style cases, when this low-cost heat sink is used. Any mounting attitude will provide free circulation of air in natural convection applications. These 680 Series heat sinks can also be specified without any semiconductor mounting hole pattern by specifying suffix "K" (Example: 680-5K).

Standard P/N	Height Above PC Board "A" in. (mm)	Horizontal Mounting Footprint Dimensions in. (mm)	Thermal Performance at Typical Load		Semiconductor Mounting Hole Pattern	Weight lbs. (grams)
			Natural Convection	Forced Convection		
680-5A	0.500 (12.7)	1.810 (46.0)-sq	70°C @ 7.5W	3.0°C/W @ 400 LFM	(1) TO-3	0.0700 (31.75)
680-75A	0.750 (19.1)	1.810 (46.0)-sq	58°C @ 7.5W	2.4°C/W @ 400 LFM	(1) TO-3	0.0900 (40.82)
680-10A	1.000 (25.4)	1.810 (46.0)-sq	52°C @ 7.5W	2.0°C/W @ 400 LFM	(1) TO-3	0.0980 (44.45)
680-125A	1.250 (31.8)	1.810 (46.0)-sq	45°C @ 7.5W	1.5°C/W @ 400 LFM	(1) TO-3	0.1100 (49.90)
680-5220	0.500 (12.7)	1.810 (46.0)-sq	70°C @ 7.5W	3.0°C/W @ 400 LFM	(2) TO-220	0.0700 (31.75)
680-75220	0.750 (19.1)	1.810 (46.0)-sq	58°C @ 7.5W	2.4°C/W @ 400 LFM	(2) TO-220	0.0900 (40.82)
680-10220	1.000 (25.4)	1.810 (46.0)-sq	52°C @ 7.5W	2.0°C/W @ 400 LFM	(2) TO-220	0.0980 (44.45)
680-125220	1.250 (31.8)	1.810 (46.0)-sq	45°C @ 7.5W	1.5°C/W @ 400 LFM	(2) TO-220	0.1100 (49.90)

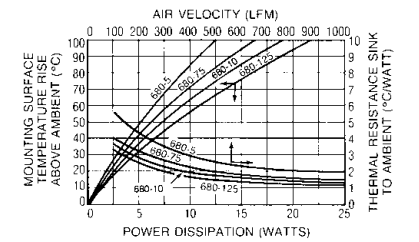
Material: Aluminum, Black Anodized

### MECHANICAL DIMENSIONS

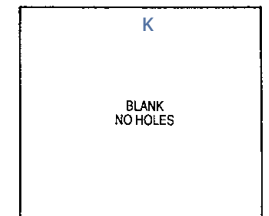
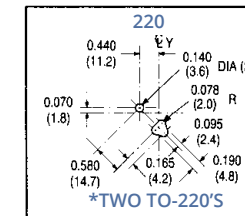
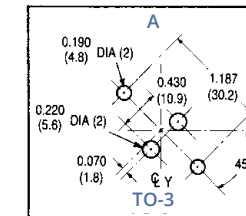


Dimensions: in. (mm)

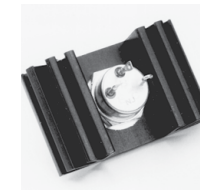
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



### SEMICONDUCTOR MOUNTING HOLES



\*Only one hole pattern of two is shown. Hole patterns are symmetrical about the center lines.



## 601 & 603 SERIES

LOW-HEIGHT HEAT SINKS

DO-4/DO-5 Diodes

Use these low-height heat sinks on printed circuit board applications for TO-66 power semiconductors and DO-4 and DO-5 diodes, where close board-to-board spacing and efficient heat dissipation are required. The 601 and 603 Series may also be attached to enclosure panels or brackets using isolation hardware where necessary.

Standard P/N	Footprint Dimensions in. (mm)	Height in. (mm)	Mounting Hole Dia. in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
601E	2.000 (50.8) x 1.250 (31.8)	0.562 (14.3)	0.200 (5.1)	52°C @ 5.0W	4.5°C/W @ 175 LFM	0.0500 (22.68)
601F	2.000 (50.8) x 1.250 (31.8)	0.562 (14.3)	0.270 (6.9)	52°C @ 5.0W	4.5°C/W @ 175 LFM	0.0500 (22.68)
601K	2.000 (50.8) x 1.250 (31.8)	0.562 (14.3)	None	52°C @ 5.0W	4.5°C/W @ 175 LFM	0.0500 (22.68)
603K	2.000 (50.8) x 2.000 (50.8)	0.562 (14.3)	None	41°C @ 5.0W	4.0°C/W @ 175 LFM	0.0810 (36.74)

Material: Aluminum Alloy, Black Anodized

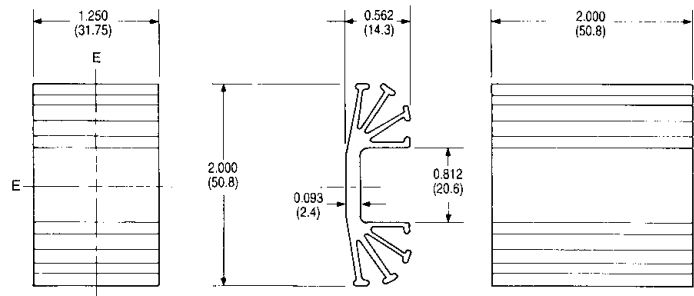
## BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

### 601 & 603 SERIES

LOW-HEIGHT HEAT SINKS

DO-4/DO-5 Diodes

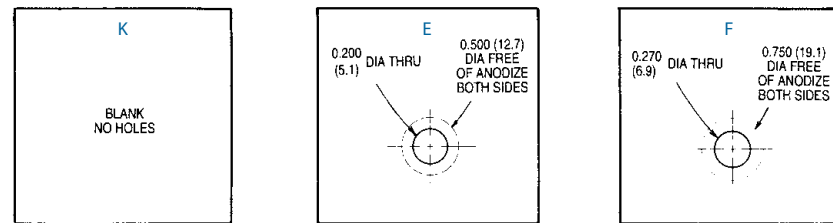
#### MECHANICAL DIMENSIONS



**601 SERIES**  
(EXTRUSION PROFILE 1284)

**603 SERIES**  
(EXTRUSION PROFILE 1284)

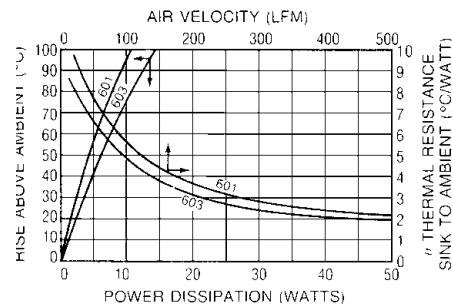
#### SEMICONDUCTOR MOUNTING HOLES



Dimensions: in. (mm)

E&F available on 601 Series only as a standard product.

#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



### MAXIMUM PERFORMANCE NATURAL CONVECTION HEAT SINK FOR ALL METAL-CASE SEMICONDUCTORS

TO-3

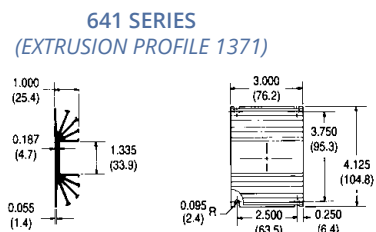
### 641 SERIES

Available with a standard TO-3 mounting hole pattern predrilled for cost-effective mounting in limited-height applications, the **641 Series** provides maximum performance in natural convection with an optimized heat sink surface area. The 641K type with an open channel area of 1.300 in. (33.0) and no predrilled mounting holes can be adapted to meet mounting requirements for most metal case power semiconductor types.

Standard P/N	Outline Dimensions in. (mm)	Height in. (mm)	Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
641A	4.125 (104.8) x 3.000 (76.2)	1.000 (25.4)	(1) TO-3	36°C @ 15W	0.9°C/W @ 250 LFM	0.2900 (131.54)
641K	4.125 (104.8) x 3.000 (76.2)	1.000 (25.4)	None	36°C @ 15W	0.9°C/W @ 250 LFM	0.2900 (131.54)

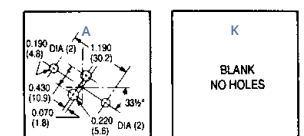
Material: Aluminum Alloy, Black Anodized.

#### MECHANICAL DIMENSIONS

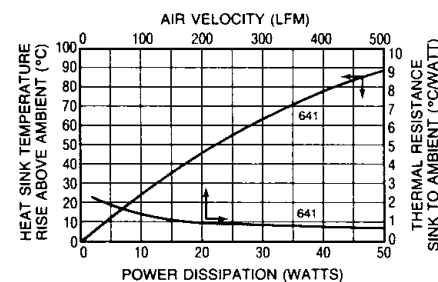


Dimensions: in. (mm)

#### SEMICONDUCTOR MOUNTING HOLES



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## UNIVERSAL 678 SERIES VERTICAL HEAT SINK FOR POWER DEVICES

### 678-39-S & 678-39-C



Wakefield-Vette introduces **Universal 678 series**, high performance, low cost and versatile heat sink with screw or clip for all kinds of standard packages. This type of heat sink provides both vertical and horizontal mounting options on PCB to accommodate natural and forced convection cooling method.

#### SPECIFICATIONS

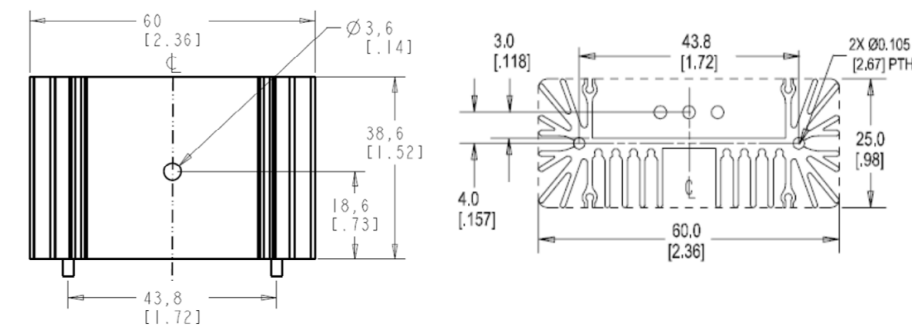
- Heat Sink:** Aluminum Alloy 6063-T5 or Equivalent with either degreased or black anodized finish
- Spring Clip:** Music Wire, Per ASTM A228 with bright nickel plating
- Solder Foot:** Cold-rolled Steel, Per ASTM A-366 with pure tin over copper strike. RoHS compliant.
- Insulator (Optional):** t-Global H48-1, L37-3F and H48-6S. The thickness of the insulating material not to exceed 10 mil (0.01").

#### FEATURES AND BENEFITS

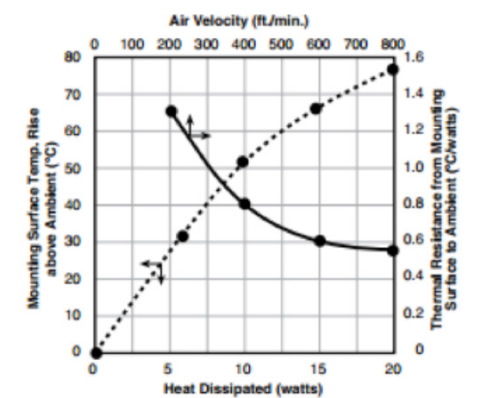
- Minimum assembly cost and labor** - Spring Clips make the mounting holes and fasteners obsolete in assembly operations & reduce costs.
- Design Flexibility** - Universal mountable and "one fits all" give designers total freedom to fit their packaging designs with ideal device pack style and to orient the heat sink to meet their power dissipations with optimized cooling method. (see page 7 of data sheet).

Part Number	Description	Length	Width	Thermal Resistance @ Forced Air Flow
678-39-S	Universal Heat Sink for TO Devices w/Screw Hole, Black Anodize	1.520" (38.61mm)	2.362" (60.00mm)	0.6°C/W @ 600 LFM
678-39-C	Universal Heat Sink for TO Devices w/ Clip, Black Anodize	1.520" (38.61mm)	2.362" (60.00mm)	0.6°C/W @ 600 LFM

#### MECHANICAL DIMENSIONS

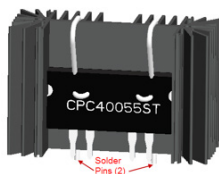


#### THERMAL PERFORMANCE





## ONE HEAT SINK FOR ALL PACKAGES

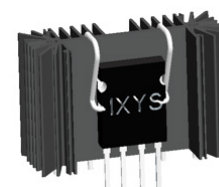
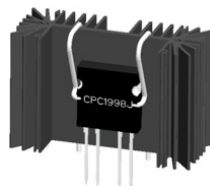


### CPC40055ST PACKAGE

Board level – 2 solder pins    Natural convection – Vertical    Spring Clip

### CPC1998J PACKAGE

Board level – 2 solder pins    Natural convection – Vertical    Spring Clip

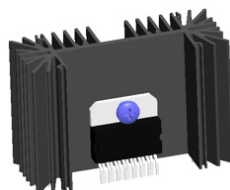


### CPC1968 AND TO-264 PACKAGE

Board level – 2 solder pins    Natural convection – Vertical    Spring Clip

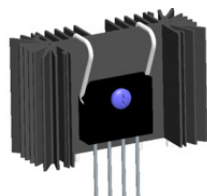
### L4970A PACKAGE

Board level – 2 solder pins    Natural convection – Vertical    Screw attachment



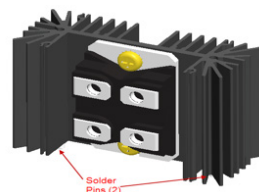
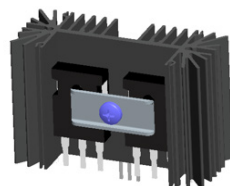
### KBU PACKAGE

Board level – 2 solder pins    Natural convection – Vertical    Spring Clip



### TO-247 AND TO-220 PACKAGE

Board level – 2 solder pins    Natural convection – Vertical    Screw attachment or Spring Clip



### SOT-227 PACKAGE

System level – 2 screws    Natural convection – Vertical

## MOUNTAIN SERIES HEAT SINKS FOR TO-264, TO-247 DEVICES

### MTN-264-27



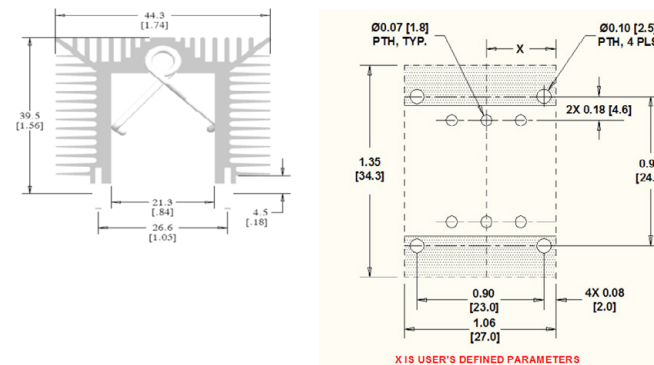
Wakefield-Vette's **Mountain Series Heat Sinks** are high performance, low cost, configurable, scalable and compact with a matrix clip system for TO220, TO-247, TO-264 and other standard packages. This type powerful heat sink provides easiest assembly, largest surface areas, smallest space occupation and all-in-one solution. The power dissipations can be easily increased simply by extending the fin height on each side of the heat sink, while keeping the heat sink height and PCB layout the same. It is the ideal type of heat sink for high power density and small size (1U or 2U) electronic packaging with forced convention cooling.

#### FEATURES AND BENEFITS

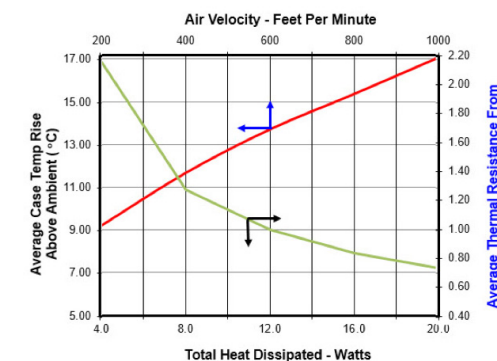
- **Minimum assembly cost and labor** - Spring Clips make the mounting holes and fasteners obsolete in assembly operations and reduce costs.
- **Maximum Repeatability** - Constant spring force over repeated assembly/disassembly.
- **Maximum Reliability** - Resilient spring action locks electronic component in place. Fewer parts in assembly and no fasteners and washers required. Prevent short circuit by eliminating metal particles generated from hardware or thread tapping.
- **Maximum Thermal Transfer** - Maximum surface area per unit volume, efficient cooling fins & consistent mounting force reduces thermal resistance.

Part Number	Description	Type	Package Cooled	Attachment Method	Length	Width	Height Off Base (Height of Fin)	Thermal Resistance @ Forced Air Flow	Material	Material Finish
MTN-264-27	Heat Sink w/ Two Clips for TO-247 TO-264	Top Mount	TO-247 and TO-264	Clip and PC Pin	1.06" (27mm)	1.740" (44.3mm)	1.56" (39.5mm)	5.5°C/W @ 18 Watts	Aluminum	Black Anodized

#### MECHANICAL DIMENSIONS



#### THERMAL RESISTANCE



## MOUNTAIN SERIES HEAT SINKS FOR TO-264, TO-247 DEVICES



### MTN-264-55

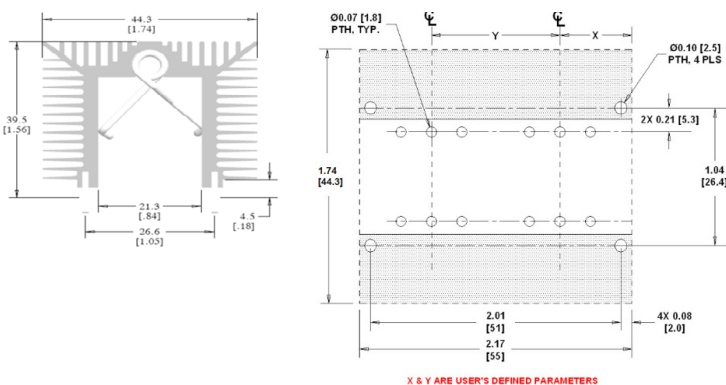
Wakefield-Vette's **Mountain Series Heat Sinks** are high performance, low cost, configurable, scalable and compact with a matrix clip system for TO220, TO-247, TO-264 and other standard packages. This type powerful heat sink provides easiest assembly, largest surface areas, smallest space occupation and all-in-one solution. The power dissipations can be easily increased simply by extending the fin height on each side of the heat sink, while keeping the heat sink height and PCB layout the same. It is the ideal type of heat sink for high power density and small size (1U or 2U) electronic packaging with forced convection cooling.

#### FEATURES AND BENEFITS

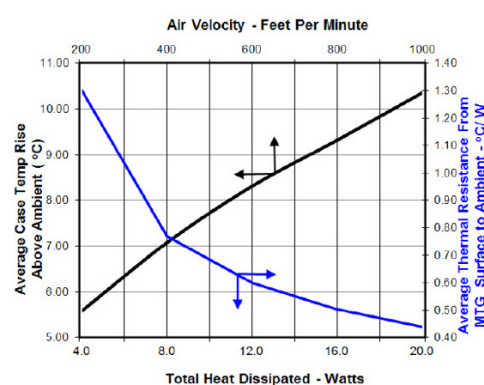
- **Minimum assembly cost and labor** - Spring Clips make the mounting holes and fasteners obsolete in assembly operations and reduce costs.
- **Maximum Thermal Transfer** - Maximum surface area per unit volume, efficient cooling fins & consistent mounting force reduces thermal resistance.
- **Maximum Repeatability** - Constant spring force over repeated assembly/disassembly.
- **Maximum Reliability** - Resilient spring action locks electronic component in place. Fewer parts in assembly and no fasteners and washers required. Prevent short circuit by eliminating metal particles generated from hardware or thread tapping.

Part Number	Description	Type	Package Cooled	Attachment Method	Length	Width	Height Off Base (Height of Fin)	Thermal Resistance @ Forced Air Flow	Material	Material Finish
MTN-264-55	Heat Sink w/ Two Clips for TO-247 TO-264	Top Mount	TO-247 and TO-264	Clip and PC Pin	2.17" (55.11mm)	1.740" (44.3mm)	1.56" (39.5mm)	3.7°C/W @ 18 Watts	Aluminum	Black Anodized

#### MECHANICAL DIMENSIONS



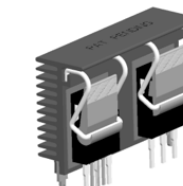
#### THERMAL RESISTANCE



## omniKLIP™ SERIES HEAT SINK W/ CLIP(S) FOR TO-DEVICES



### HEAT SINKS OMNI-CLIP-18-L SERIES



omniKlip™

The Wakefield- Vette **omniKlip Heat Sink Series** are a configurable and patented (Pat. Pending) high performance, low cost and compact solutions for TO-220, TO-247 and TO-264 , or similar packages. This powerful heat sink provides tool and fixture free assembly operation, largest surface areas and smallest space occupation. It is the ideal type of heat sink for high power density and small size (1U or 2U) electronic packaging with forced convection cooling.

#### SPECIFICATIONS

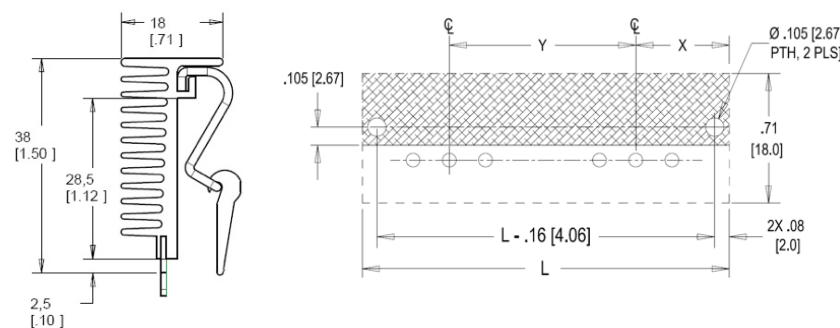
- **Heat Sink:** Aluminum Alloy 6063-T5 or Equivalent with black anodized finish.
- **Spring Clip:** Music Wire, Per ASTM A228 with bright nickel plating
- **Solder Foot:** Cold-rolled Steel, Per ASTM A-366 with pure tin over copper strike. RoHS compliant.

#### FEATURES AND BENEFITS

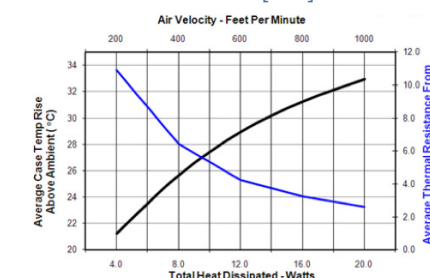
- **Minimum assembly cost and labor** - Spring Clips make the mounting holes, fasteners, tools and fixtures obsolete in assembly operations & reduce costs.
- **Maximum Repeatability** - Constant spring force over repeated assembly/disassembly
- **Maximum Reliability** - Resilient spring action locks electronic component in place. Fewer parts in assembly and no fasteners and washers required. Prevent short circuit by eliminating metal particles generated from hardware or thread tapping
- **Design Flexibility** - Maximum flexibility for dynamic device locations and power up grading. "Configure-to-Fit" gives designers total freedom to configure heat sink needed to fit their dynamic design environments.

WkV Part Number	Description	Related Clip	Package Cooled	Length	Width	Height Off Base (Height of Fin)
OMNI-UNI-18-25	OmniKlip Heat Sink, 18mm wide, 25mm long, black anodized for TO-247 & TO-264	OMNI-UC	TO-247, TO-264	0.984" (25.00mm)	1.500" (38.10mm)	0.710" (18.03mm)
OMNI-UNI-18-50	OmniKlip Heat Sink, 18mm wide, 50mm long, black anodized for TO-247 & TO-264	OMNI-UC	TO-247, TO-264	1.969" (50.00mm)	1.500" (38.10mm)	0.710" (18.03mm)
OMNI-UNI-18-75	OmniKlip Heat Sink, 18mm wide, 75mm long, black anodized for TO-247 & TO-264	OMNI-UC	TO-247, TO-264	2.95" (75.00mm)	1.500" (38.10mm)	0.710" (18.03mm)
OMNI-220-18-25-1C	OmniKlip Heat Sink w/1 clip, 18mm wide, 25mm long, black anodized for TO-220		TO-220	0.984" (25.00mm)	1.500" (38.10mm)	0.710" (18.03mm)
OMNI-220-18-50-2C	OmniKlip Heat Sink w/2 clips, 18mm wide, 50mm long, black anodized for TO-220		TO-220	1.969" (50.00mm)	1.500" (38.10mm)	0.710" (18.03mm)
OMNI-220-18-75-3C	OmniKlip Heat Sink w/3 clips, 18mm wide, 75mm long, black anodized for TO-220		TO-220	2.95" (75.00mm)	1.500" (38.10mm)	0.710" (18.03mm)

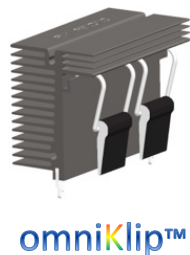
#### MECHANICAL DIMENSIONS



#### THERMAL PERFORMANCE (OMNI-UNI-18) TWO TO-247 DEVICES WITH SIL-PAD 900s L = 500mm[2.0"]



## OmniKLIP™ SERIES HEAT SINK W/ CLIP(S) FOR TO-DEVICES

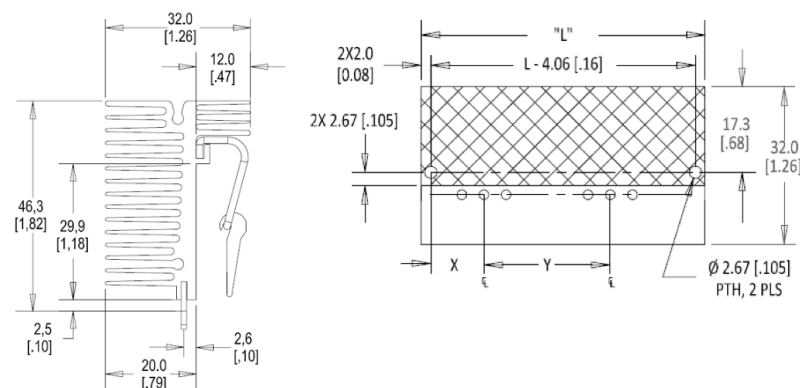


### OMNI-UNI-32-L SERIES HEAT SINKS

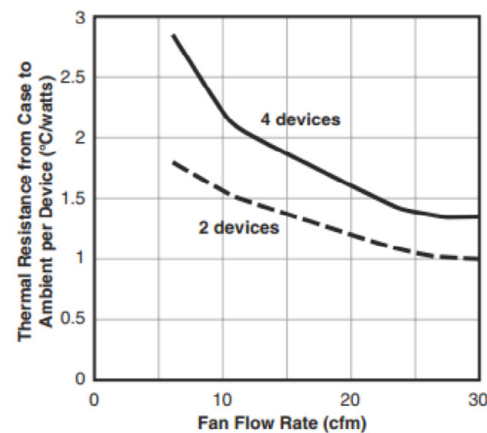


WkV Part Number	Description	Related Cross Sell Part	Package Cooled	Shape	Length	Width	Height Off Base (Height of Fin)
OMNI-UNI-32-58	OmniKlip Heat Sink for 2 universal 2 clips, 32mm wide, 58mm long, black anodized for any TO except TO-220	OMNI-UC, OMNI-220C	TO-247, TO-264	Rectangular, Fins	2.28" (58mm)	1.25" (32mm)	1.62" (46.3mm)

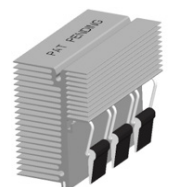
#### MECHANICAL DIMENSIONS



#### THERMAL PERFORMANCE

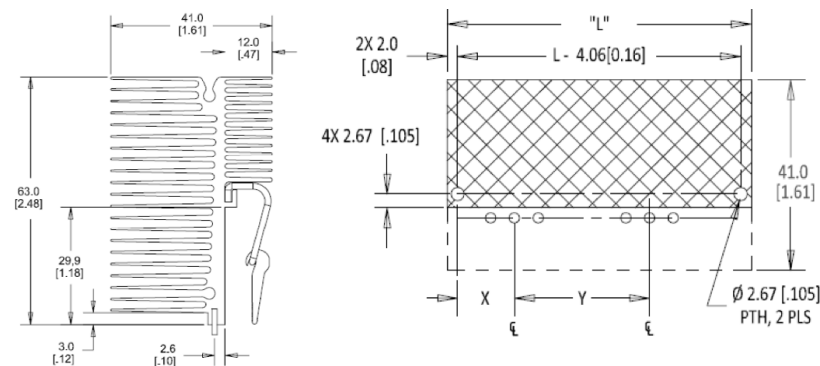


### HEAT SINKS OMNI-UNI-41-L SERIES

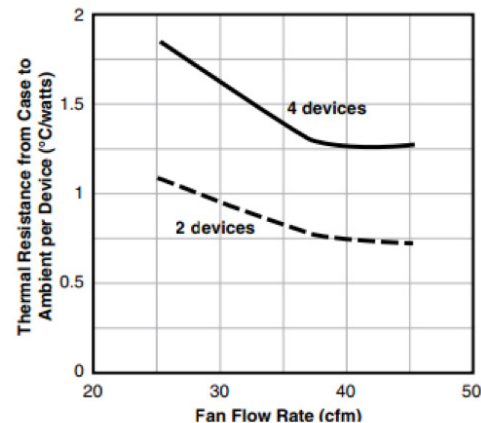


WkV Part Number	Description	Related Cross Sell Part	Package Cooled	Shape	Length	Width	Height Off Base (Height of Fin)
OMNI-UNI-41-75	OmniKlip Heat Sink for 2 universal 2 clips, 41mm wide, 75mm long, black anodized for any TO except TO-220	OMNI-UC, OMNI-220C	TO-247, TO-264	Rectangular, Fins	2.95" (75mm)	1.61" (41mm)	1.62" (46.3mm)

#### MECHANICAL DIMENSIONS



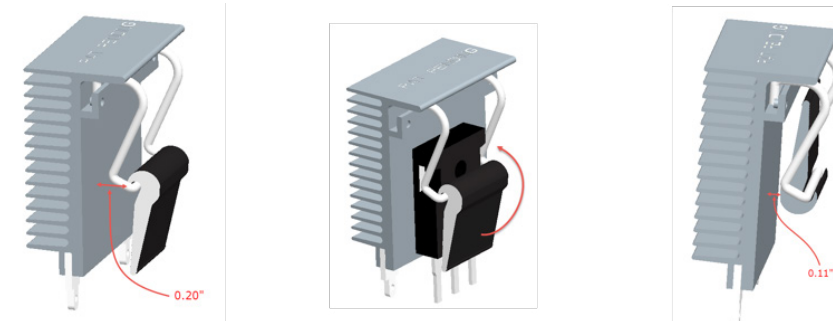
#### THERMAL PERFORMANCE



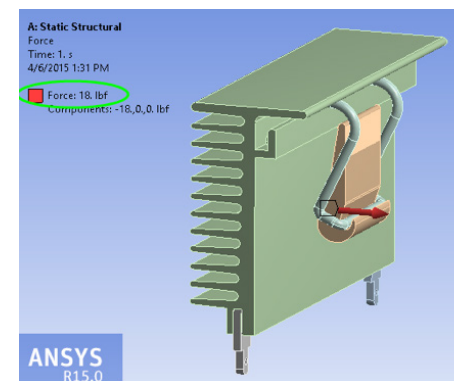
### OMNIKLIPS™



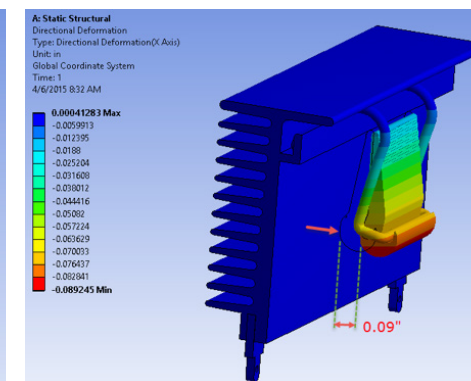
Part Number	Description
OMNI-UC	Universal Clip for omniKlip Heat Sink for any TO except TO220
OMNI-220C	Clip for omniKlip Heat Sink for TO 220



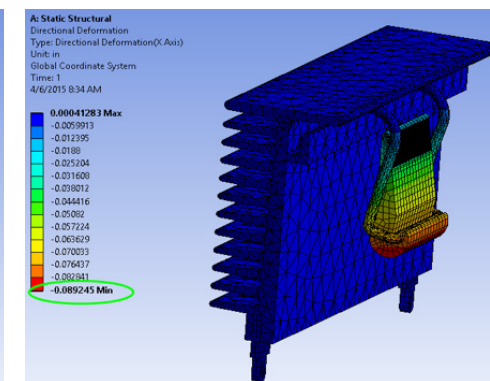
Universal Clip mechanism is rotating the bar by 180°. The eccentric circle will raise 0.09". This deformation will exert the force on the components.



omniKlip assembly model in ANSYS, with 18 lbf load applied to the clip



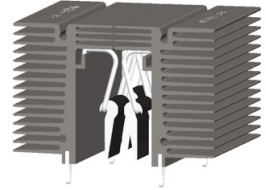
Under the 18 lbf, the clip deformed 0.09" from its original position to the final



Directional deformation plot as shown.

With the FEA analysis and simulation, the force applied to the TO-series components will be at least 18 lbs.

## ADDITIONAL CONFIGURATIONS

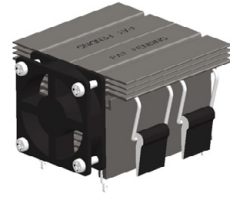


**OMNI-UNI-32-L SERIES** FACE TO FACE MOUNTING (SPACE SAVER)

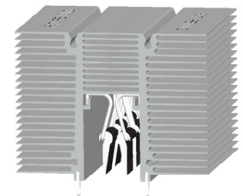
omniKlip™

BACK TO BACK MOUNTING WITH 40MM FAN

**OMNI-UNI-32-L SERIES**



omniKlip™

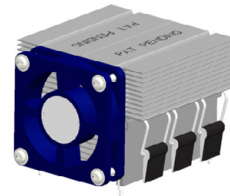


**OMNI-UNI-41-L SERIES** FACE TO FACE MOUNTING (SPACE SAVER)

omniKlip™

BACK TO BACK MOUNTING WITH 60MM FAN

**OMNI-UNI-41-L SERIES**



omniKlip™

# EXTRUDED SERIES HEAT SINKS

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*Extruded Heat Sinks For Power Semiconductors* ..... 88-92

*Performance, Low Profile Heat Sinks For Power Modules & IGBT's* ..... 93

*Extruded Heat Sinks For DC/DC Converters* ..... 94-96

*Mounting Hardware For Extruded Heat Sinks* ..... 95



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*For cooling single and multiple high power devices packaged in industry standard semiconductor case styles: TO-3 to TO-247, DO-4 to DO-30, hex-type, and stud mount; press pack devices; power modules; SCRs, IGBTs; I/O devices; and other isolated flat base devices in both natural and forced convection.*

### EXTRUDED HEAT SINKS FOR POWER SEMICONDUCTORS

#### 621 & 623 SERIES

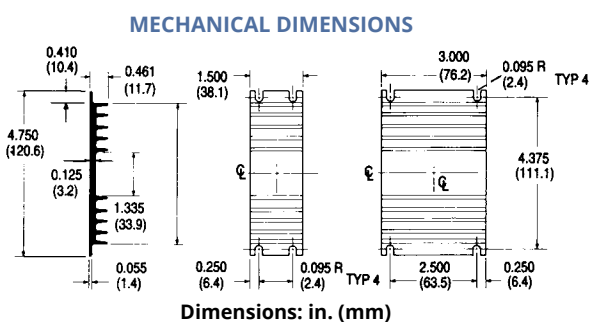
LOW-PROFILE HEAT SINKS FOR ALL METAL-CASE POWER SEMICONDUCTORS

TO-3

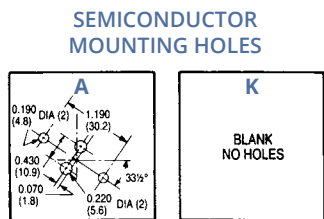
A general purpose yet efficient heat dissipator for TO-3 and virtually all other styles of metal case power semiconductor package types, the **621 and 623 Series** low-profile flat back heat sinks find a wide variety of applications. The central channel between fins measures 1.300 in. (33.0) (min.) in width, accommodating many types of packages. Mounting hole pattern "A" is pre-drilled for the standard TO-3 package.

Standard P/N	Footprint Dimensions in. (mm)	Height in. (mm)	Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
621A	4.750 (120.6) x 1.500 (38.1)	0.461 (11.7)	(1) TO-3	75°C @ 15W	2.0°C/W @ 250 LFM	0.1000 (45.36)
621K	4.750 (120.6) x 1.500 (38.1)	0.461 (11.7)	None	75°C @ 15W	2.0°C/W @ 250 LFM	0.1000 (45.36)
623A	4.750 (120.6) x 3.000 (76.2)	0.461 (11.7)	(1) TO-3	52°C @ 15W	1.5°C/W @ 250 LFM	0.2100 (95.26)
623K	4.750 (120.6) x 3.000 (76.2)	0.461 (11.7)	None	52°C @ 15W	1.5°C/W @ 250 LFM	0.2100 (95.26)

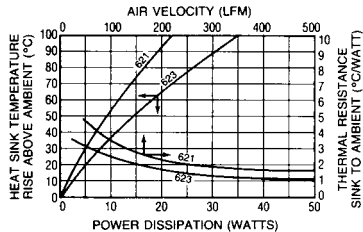
Material: Aluminum Alloy, Black Anodized.



(EXTRUSION PROFILE 1327)



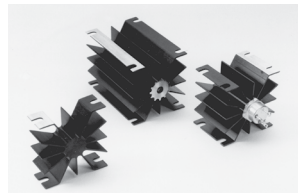
NATURAL AND FORCED CONVECTION CHARACTERISTICS



#### Stud-Mount COMPACT HEAT SINKS FOR DUAL STUD-MOUNTED SEMICONDUCTOR CASES

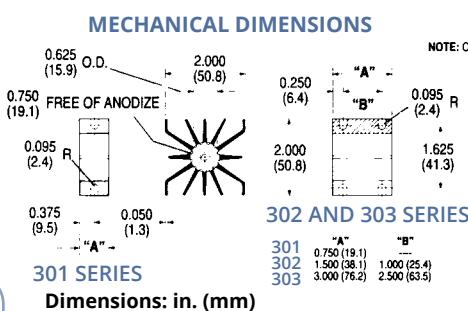
#### 301, 302, & 303 SERIES

The large fin area in minimum total volume provided by the radial design of the **301/302/303 Series** offers maximum heat transfer efficiency in natural convection. All types are available with one tapped mounting hole for rectifiers and other stud-mounting semiconductors; the 302 and 303 Series offer maximum cost savings with dual mounting locations ("MM" and "NN" mounting hole patterns) for two stud-mount devices.

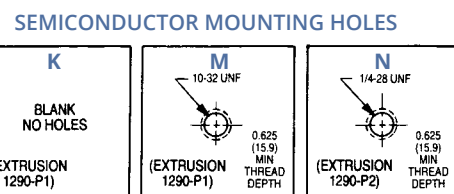


Standard P/N	Outline Dimensions in. (mm)	Length "A" in. (mm)	Mounting Hole(s) Pattern and Number	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
301K	2.000 (50.8) x 2.000 (50.8)	0.750 (19.1)	None	70°C @ 15W	2.5°C/W @ 250 LFM	0.0580 (26.31)
301M	2.000 (50.8) x 2.000 (50.8)	0.750 (19.1)	(1) 10-32UNF, 0.625 in. thread depth	70°C @ 15W	2.5°C/W @ 250 LFM	0.0580 (26.31)
301N	2.000 (50.8) x 2.000 (50.8)	0.750 (19.1)	(1) 1/4 -28UNF, 0.625 in. thread depth	70°C @ 15W	2.5°C/W @ 250 LFM	0.0580 (26.31)
302M	2.000 (50.8) x 2.000 (50.8)	1.500 (38.1)	(1) 10-32UNF, 0.625 in. thread depth	50°C @ 15W	1.8°C/W @ 250 LFM	0.1330 (60.33)
302MM	2.000 (50.8) x 2.000 (50.8)	1.500 (38.1)	(2) 10-32UNF, 0.625 in. thread depth	50°C @ 15W	1.8°C/W @ 250 LFM	0.1330 (60.33)
302N	2.000 (50.8) x 2.000 (50.8)	1.500 (38.1)	(1) 1/4 -28UNF, 0.625 in. thread depth	50°C @ 15W	1.8°C/W @ 250 LFM	0.1330 (60.33)
302NN	2.000 (50.8) x 2.000 (50.8)	1.500 (38.1)	(2) 1/4 -28UNF, 0.625 in. thread depth	50°C @ 15W	1.8°C/W @ 250 LFM	0.1330 (60.33)
303M	2.000 (50.8) x 2.000 (50.8)	3.000 (76.2)	(1) 10-32UNF, 0.625 in. thread depth	37°C @ 15W	1.3°C/W @ 250 LFM	0.2680 (121.56)
303MM	2.000 (50.8) x 2.000 (50.8)	3.000 (76.2)	(2) 10-32UNF, 0.625 in. thread depth	37°C @ 15W	1.3°C/W @ 250 LFM	0.2680 (121.56)
303N	2.000 (50.8) x 2.000 (50.8)	3.000 (76.2)	(1) 1/4 -28UNF, 0.625 in. thread depth	37°C @ 15W	1.3°C/W @ 250 LFM	0.2680 (121.56)
303NN	2.000 (50.8) x 2.000 (50.8)	3.000 (76.2)	(2) 1/4 -28UNF, 0.625 in. thread depth	37°C @ 15W	1.3°C/W @ 250 LFM	0.2680 (121.56)

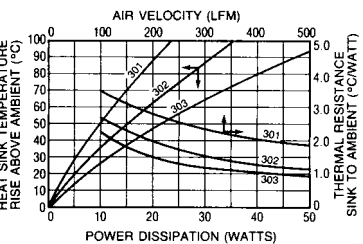
Material: Aluminum Alloy, Black Anodized.



NOTE: CROSS-HATCHED AREAS FREE OF ANODIZE.



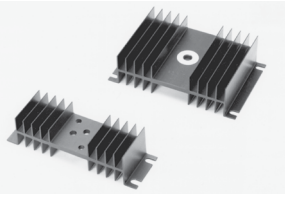
NATURAL AND FORCED CONVECTION CHARACTERISTICS



TO-3; Stud-Mount

#### DOUBLE-SURFACE HEAT SINKS FOR TO-3 CASE STYLES

#### 401 & 403 SERIES

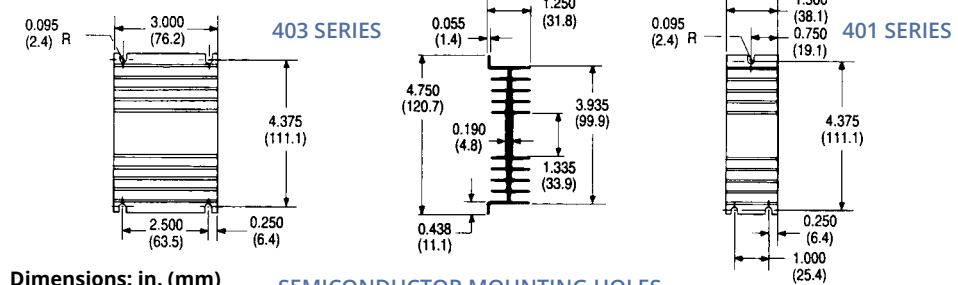


With fins oriented vertically in cabinet sidewall applications, **401 and 403 Series** heat sinks are recommended for critical space applications where maximum heat dissipation is required for high-power TO-3 case styles. Forced convection performance is also exemplary with these double surface fin types. Semiconductor mounting hole style "F" offers a single centered 0.270 in. (6.9)-diameter mounting hole (with a 0.750 in. (19.1)-diameter area free of anodize) for mounting stud-type diodes and rectifiers. Hole pattern "V" available upon request.

Standard P/N	Width in. (mm)	Overall Dimensions in. (mm)	Height in. (mm)	Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
401A	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	(1) TO-3	80°C @ 30W	1.5°C/W @ 250 LFM	0.1500 (68.04)
401F	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	0.270 in. (6.9)-Dia Hole	80°C @ 30W	1.5°C/W @ 250 LFM	0.1500 (68.04)
401K	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	None	80°C @ 30W	1.5°C/W @ 250 LFM	0.1500 (68.04)
403A	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	(1) TO-3	55°C @ 30W	0.9°C/W @ 250 LFM	0.3500 (158.76)
403F	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	0.270 in. (6.9)-Dia Hole	55°C @ 30W	0.9°C/W @ 250 LFM	0.3500 (158.76)
403K	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	None	55°C @ 30W	0.9°C/W @ 250 LFM	0.3500 (158.76)

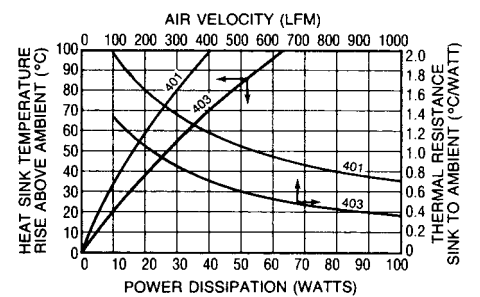
Material: Aluminum Alloy, Black Anodized.

MECHANICAL DIMENSIONS

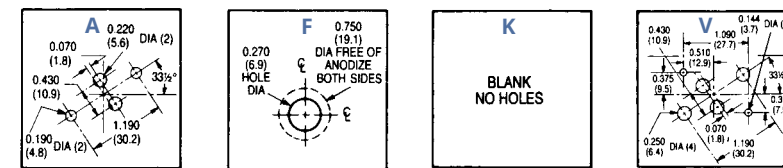


Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS

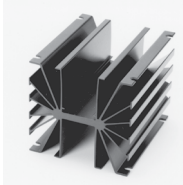


SEMICONDUCTOR MOUNTING HOLES



(EXTRUSION PROFILE 1024)

#### 441 SERIES HIGH-PERFORMANCE NATURAL CONVECTION HEAT SINKS FOR RECTIFIERS AND DIODES



#### 441 SERIES

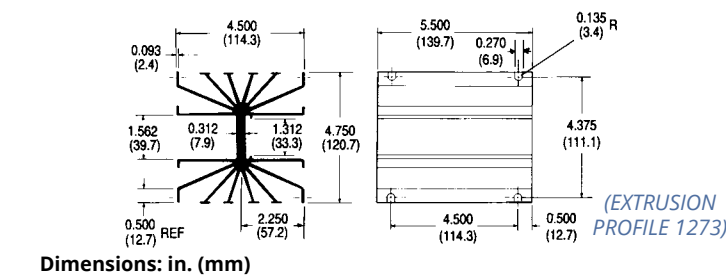
DESIGNED FOR VERTICAL MOUNTING WITHIN A POWER SUPPLY ENCLOSURE OR EQUIPMENT CABINET WITHOUT FORCED AIRFLOW AVAILABLE. THIS WAKEFIELD-VETTE 441 SERIES HEAT SINK WILL DISSIPATE UP TO 100 WATTS EFFICIENTLY IN NATURAL CONVECTION WITH A MAXIMUM 55°C HEAT SINK TEMPERATURE RISE ABOVE AMBIENT. WHEN APPLIED IN A FORCED CONVECTION ENVIRONMENT, THE 441K TYPE WILL ACHIEVE THERMAL RESISTANCE OF 0.18°C/W (SINK TO AMBIENT) AT 1000 LFM. SUPPLIED WITH NO PRE-DRILLED DEVICE MOUNTING HOLE PATTERN.

Stud-Mount

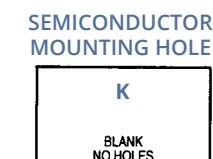
Standard P/N	Nominal Dimensions			Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
	Width in. (mm)	Length in. (mm)	Height in. (mm)		Natural Convection	Forced Convection	
441K	4.750 (120.7)	5.500 (139.7)	4.500 (114.3)	None	34°C @ SOW 47°C @ 80W	0.30°C/W @ 250 LFM 0.19°C/W @ 600 LFM	1.9700 (893.59)

Material: Aluminum Alloy, Black Anodized.

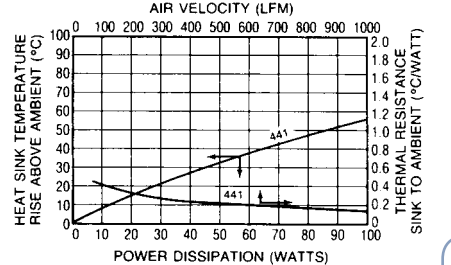
MECHANICAL DIMENSIONS



Dimensions: in. (mm)



NATURAL AND FORCED CONVECTION CHARACTERISTICS



## EXTRUDED HEAT SINKS FOR POWER SEMICONDUCTORS

### 413, 421, & 423 SERIES

LOW-HEIGHT DOUBLE-SURFACE HEAT SINKS FOR TO-3 CASE STYLES AND DIODES

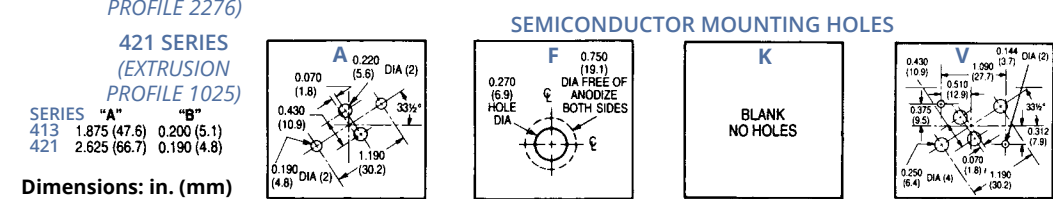
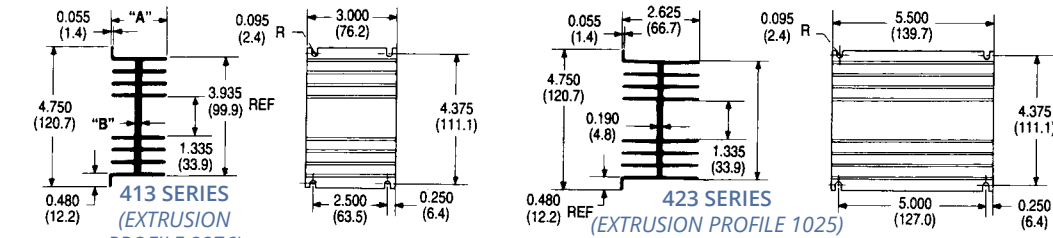
TO-3; DO-5; Stud-Mount

Space-saving double surface **413, 421, and 423 Series** utilize finned surface area on both sides of the power semiconductor mounting surface to provide maximum heat dissipation in a compact profile. Ready to install on popular power components in natural and forced convection applications. Apply Wakefield-Vette Type 126 silicone-free thermal compound or Wakefield-Vette DeltaPad™ interface materials for maximum performance.

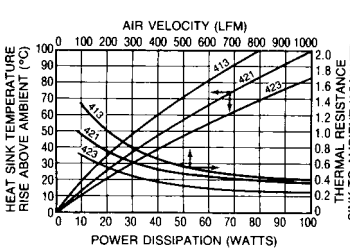
Standard P/N	Nominal Dimensions			Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
	Width in. (mm)	Length in. (mm)	Height "A" in. (mm)		Natural Convection	Forced Convection	
413A	4.750 (120.7)	3.000 (76.2)	1.875 (47.6)	(1) TO-3	72°C @ 50W	0.85°C/W @ 250 LFM	0.6300 (285.77)
413F	4.750 (120.7)	3.000 (76.2)	1.875 (47.6)	0.270 in. (6.9)-Dia Hole	72°C @ 50W	0.85°C/W @ 250 LFM	0.6300 (285.77)
413K	4.750 (120.7)	3.000 (76.2)	1.875 (47.6)	None	72°C @ 50W	0.85°C/W @ 250 LFM	0.6300 (285.77)
421A	4.750 (120.7)	3.000 (76.2)	2.625 (66.7)	(1) TO-3	58°C @ 50W	0.7°C/W @ 250 LFM	0.6300 (285.77)
421F	4.750 (120.7)	3.000 (76.2)	2.625 (66.7)	0.270 in. (6.9)-Dia Hole	58°C @ 50W	0.7°C/W @ 250 LFM	0.6300 (285.77)
421K	4.750 (120.7)	3.000 (76.2)	2.625 (66.7)	None	58°C @ 50W	0.7°C/W @ 250 LFM	0.6300 (285.77)
423A	4.750 (120.7)	5.500 (140.2)	2.625 (66.7)	(1) TO-3	47°C @ 50W	0.5°C/W @ 250 LFM	1.1700 (530.71)
423K	4.750 (120.7)	5.500 (140.2)	2.625 (66.7)	None	47°C @ 50W	0.5°C/W @ 250 LFM	1.1700 (530.71)

Material: Aluminum Alloy, Black Anodized.

#### MECHANICAL DIMENSIONS



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS

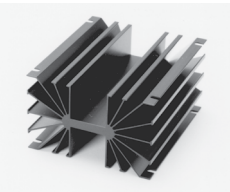


## HIGH-PERFORMANCE HEAT SINKS FOR 30-100W METAL POWER SEMICONDUCTORS

TO-3; Stud-Mount

### 431 & 433 SERIES

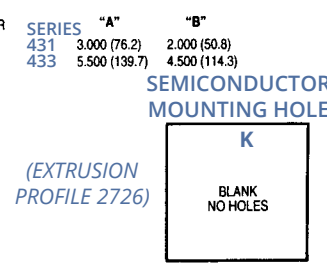
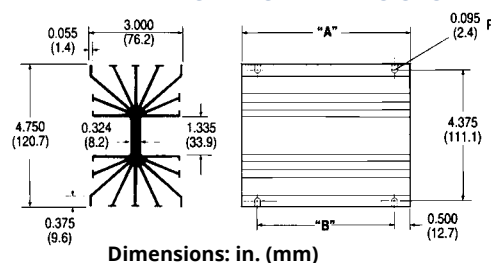
Need maximum heat dissipation from a TO-3 rectifier heat sink in minimum space? The Wakefield-Vette **431 and 433 Series** center channel double-surface heat sinks offer the highest performance-to-weight ratio for minimum volume occupied for TO-3, diode, and stud-mount metal power semiconductors in the 30- to 100-watt operating range. Additional interface resistance reduction for maximized overall performance can be achieved with proper application of Wakefield-Vette Type 126 silicone-free thermal compound.



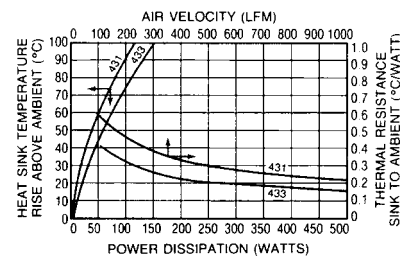
Standard P/N	Nominal Dimensions			Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
	Width in. (mm)	Length "A" in. (mm)	Height in. (mm)		Natural Convection	Forced Convection	
431K	4.750 (120.7)	3.000 (76.2)	3.000 (76.2)	None	55°C @ 50W	0.40°C/W @ 250 LFM	0.7800 (353.81)
433K	4.750 (120.7)	5.500 (139.7)	3.000 (76.2)	None	42°C @ 50W	0.28°C/W @ 250 LFM	1.4900 (675.86)

Material: Aluminum Alloy, Black Anodized.

#### MECHANICAL DIMENSIONS

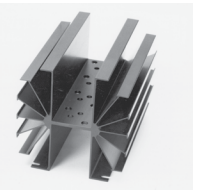


#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## LIGHTWEIGHT QUADRUPLE MOUNT HEAT SINK FOR TO-3 CASE STYLES

### 435 SERIES



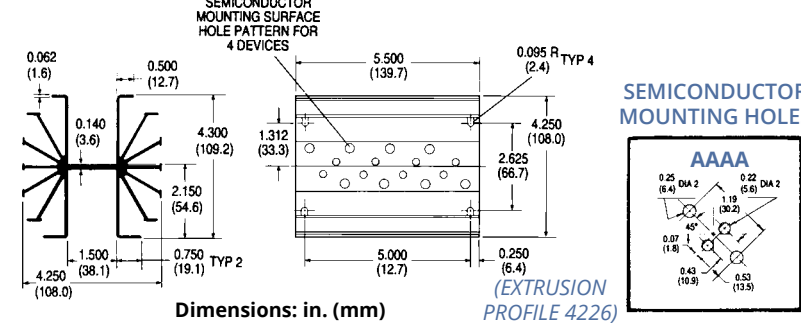
TO-3

This lightweight high-performance heat sink is designed to mount and cool efficiently one to four TO-3 style metal case power semiconductors. The Type 435AAAA is the standard configuration available from stock, pre-drilled for mounting four TO-3 style devices. Increased performance can be achieved with the proper selection and installation of a Wakefield-Vette Type 175 DeltaPad Kapton™ interface material for each power semiconductor or, for maximum reduction of case-to-sink interface loss, the application of Wakefield-Vette Type 126 silicone-free thermal compound.

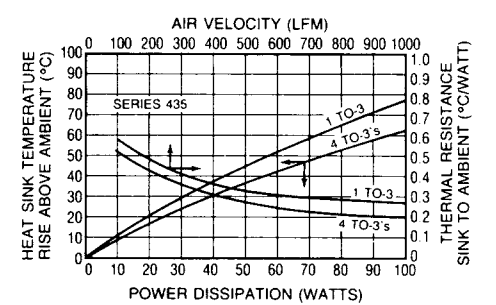
Standard P/N	Nominal Dimensions			Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
	Width in. (mm)	Length in. (mm)	Height in. (mm)		Natural Convection	Forced Convection	
435AAAA	4.250 (108.0)	5.500 (139.7)	4.300 (109.2)	(4) TO-3	37°C @ 50W 54°C @ 80W	0.38°C/W @ 250 LFM 0.24°C/W @ 600 LFM	1.1500 (521.64)

Material: Aluminum Alloy, Black Anodized.

#### MECHANICAL DIMENSIONS



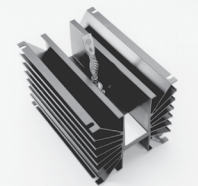
#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## 486 & 489 SERIES

HEAT SINKS FOR HIGH-POWER HEX-TYPE RECTIFIERS AND DIODES

Stud-Mount

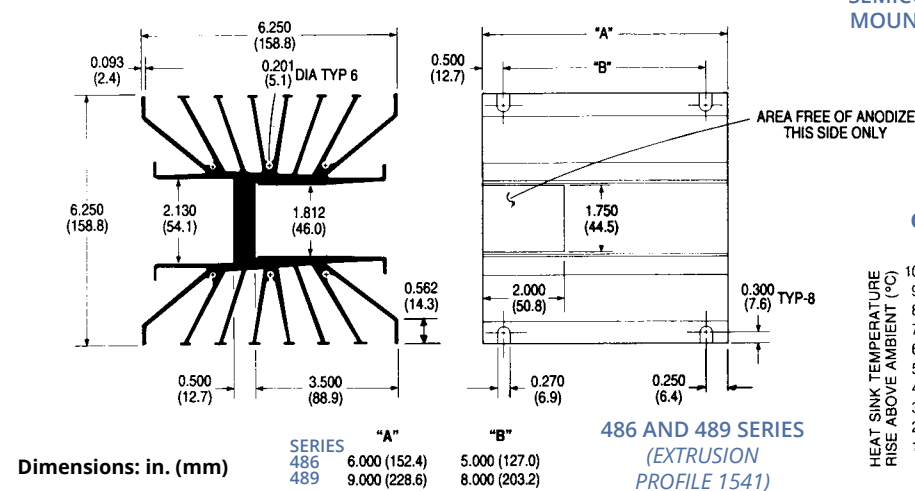


These two heat sink types accept industry standard 1.750 in. (44.5) hex-type devices for mounting and efficient heat dissipation. Each type is provided with a 1.750 in. (44.5) x 2.000 in. (50.8) area on the semiconductor base mounting surface which is free of anodize.

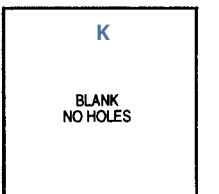
Standard P/N	Nominal Dimensions				Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
	Width in. (mm)	Length in. (mm)	Height in. (mm)	Hex Style Type		Natural Convection	Forced Convection	
486K	6.250 (158.8)	6.000 (152.4)	6.250 (158.8)	1.750 in. Hex	None	24°C @ 50W 86°C @ 250W	0.20°C/W @ 250 LFM 0.13°C/W @ 500 LFM	4.2100 (1909.66)
489K	6.250 (158.8)	9.000 (228.6)	6.250 (158.8)	1.750 in. Hex	None	19°C @ 50W 75°C @ 250W	0.15°C/W @ 250 LFM 0.10°C/W @ 500 LFM	6.1400 (2785.10)

Material: Aluminum Alloy, Black Anodized.

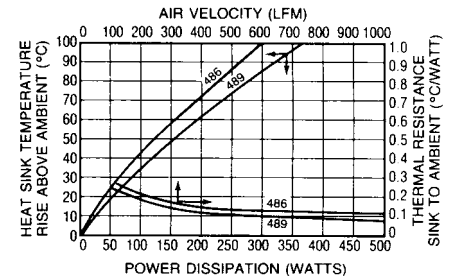
#### MECHANICAL DIMENSIONS



#### SEMICONDUCTOR MOUNTING HOLE



#### NATURAL AND FORCED CONVECTION CHARACTERISTICS



## EXTRUDED HEAT SINKS FOR POWER SEMICONDUCTORS

### 465 & 476 SERIES

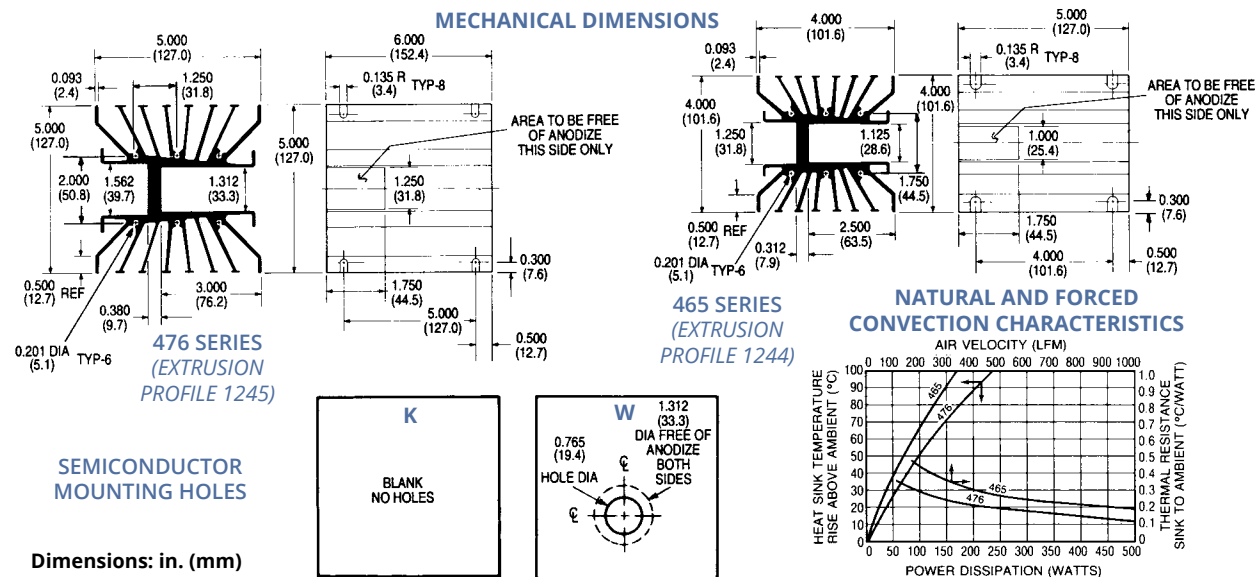
HIGH-POWER HEAT SINKS FOR MEDIUM  
HEX-TYPE RECTIFIERS AND DIODES

Stud-Mount

Wakefield-Vette Engineering has designed four standard heat sink types for ease of installation and efficient heat dissipation for industry standard hex-type rectifiers and similar stud-mount power devices: 465, 476, 486, and 489 Series. The **465 and 476 Series** shown here are designed for 1.060 in. Hex (465 Type) and 1.250 in. Hex (476 Type). The 476W Type is available pre-drilled for an 0.765 in. (19.4) dia,

Standard P/N	Nominal Dimensions			Hex Style		Thermal Performance at Typical Load		Weight lbs. (grams)
	Width in. (mm)	Length in. (mm)	Height in. (mm)	Hex Style Type	Mounting Hole Pattern	Natural Convection	Forced Convection	
465K	4.000 (101.6)	5.000 (127.0)	4.000 (101.6)	1.060 in. Hex	None	38°C @ 50W	0.27°C/W @ 500 LFM	1.9300 (875.45)
476K	5.000 (127.0)	6.000 (152.4)	5.000 (127.0)	1.250 in. Hex	None	25°C @ 50W	0.19°C/W @ 500 LFM	2.8200 (1279.15)
476W	5.000 (127.0)	6.000 (152.4)	5.000 (127.0)	1.250 in. Hex	0.765 in. (19.4) Dia. Center Mount	25°C @ 50W	0.19°C/W @ 500 LFM	2.8000 (1270.08)

**Material:** Aluminum Alloy, Black Anodized.



### KING SIZE HEAT SINKS FOR HIGH-POWER RECTIFIERS

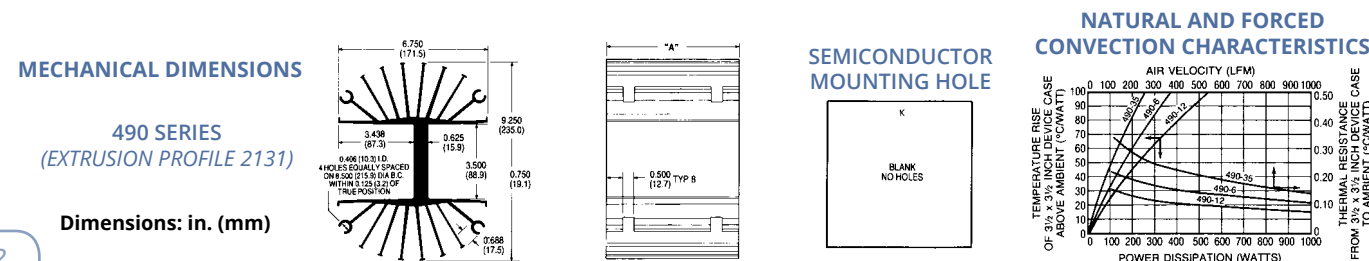
### 490 SERIES

General Purpose

The **490 Series** can be used to mount a single high-power rectifier or a grouping of smaller power devices. The semiconductor device mounting surface is free of anodize on the entire surface on one side only; finish overall is black anodize. Use Type 109 mounting brackets (see accessories section) for mounting to enclosure wall and for electrical isolation. The anodize-free mounting surface is milled for maximum contact area. The 490 Series Can also be drilled for mounting and cooling IGBTs and other isolated power modules.

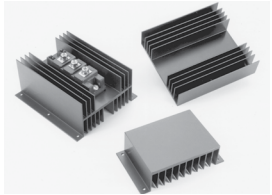
Standard P/N	Nominal Dimensions			Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
	Width in. (mm)	Length "A" in. (mm)	Height in. (mm)		Natural Convection	Forced Convection	
490-35K	9.250 (235.0)	3.500 (88.9)	6.750 (171.5)	None	84°C @ 200W	0.18°C/W @ 600 LFM	3.2400 (1469.66)
490-6K	9.250 (235.0)	6.000 (152.4)	6.750 (171.5)	None	60°C @ 200W	0.13°C/W @ 600 LFM	5.4700 (2481.19)
490-12K	9.250 (235.0)	12.000 (304.8)	6.750 (171.5)	None	45°C @ 200W	0.09°C/W @ 600 LFM	10.6200(4817.23)

**Material:** Aluminum Alloy, Black Anodized.



## PERFORMANCE, LOW PROFILE HEAT SINKS FOR POWER MODULES & IGBT'S

### 394, 395, & 396 SERIES

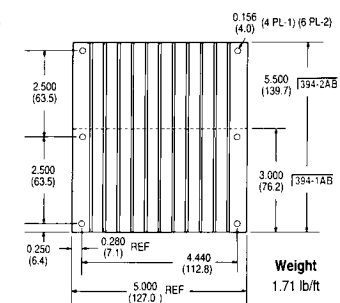


Standard P/N	Overall Dimensions: in. (mm)			Device Base Mounting Area (mm)	Base Mounting Holes	Thermal Resistance at Typical Load	
	Length in. (mm)	Height in. (mm)	Width in. (mm)			Natural Convection (θ <sub>sa</sub> ) <sup>(1)</sup> (°C/W)	Forced Convection (θ <sub>sa</sub> ) (°C/W @ 500 LFM)
394-1AB	3.000 (76.2)	1.500 (38.1)	5.000 (127.0)	101 x 76	4	1.85	0.90
394-2AB	5.500 (139.7)	1.500 (38.1)	5.000 (127.0)	101 x 139	6	1.51	0.60
395-1AB	3.000 (76.2)	2.500 (63.5)	5.000 (127.0)	50 x 76	4	1.10	0.50
395-2AB	5.500 (139.7)	2.500 (63.5)	5.000 (127.0)	50 x 139	6	0.90	0.32
396-1AB	3.000 (76.2)	1.380 (35.1)	5.000 (127.0)	50 x 76	4	1.85	1.07
396-2AB	5.500 (139.7)	1.380 (35.1)	5.000 (127.0)	50 x 139	6	1.51	0.64

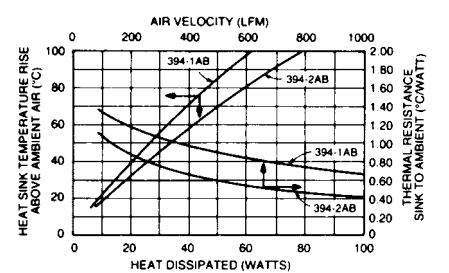
**Note:** 1. Thermal resistance values shown are for black anodized finish at 50°C rise above ambient.

### MECHANICAL DIMENSIONS

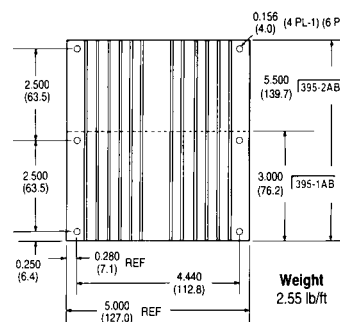
#### 394 SERIES (EXTRUSION PROFILE 7332)



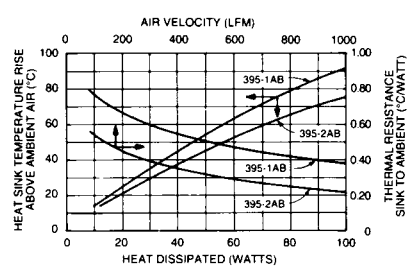
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



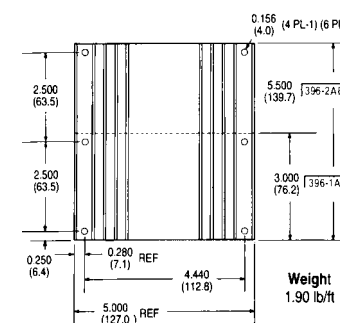
#### 395 SERIES (EXTRUSION PROFILE 7330)



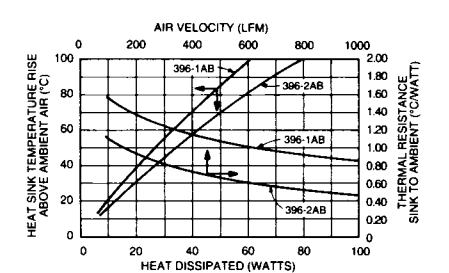
### NATURAL AND FORCED CONVECTION CHARACTERISTICS



#### 396 SERIES (EXTRUSION PROFILE 7331)

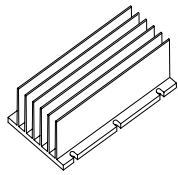


### NATURAL AND FORCED CONVECTION CHARACTERISTICS





## EXTRUDED HEAT SINKS FOR DC/DC CONVERTERS



### 557, 558, & 559 SERIES

HEAT SINKS FOR "FULL-BRICK"  
DC/DC CONVERTERS

TO-220 and TO-218

#### FEATURES AND BENEFITS

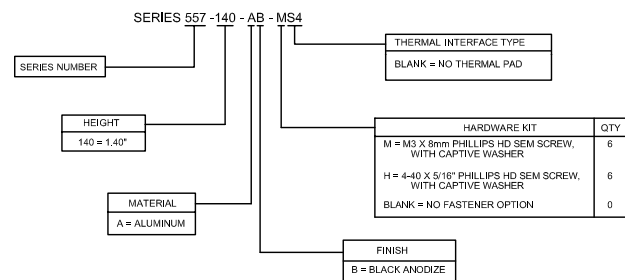
- Standard mounting hole pattern mates with Vicor DC/DC converters.
- Aluminum extruded fin construction keeps DC/DC converter modules cool in both forced and natural convection applications.
- Three fin heights, two flow direction options.
- Black anodized finish standard.
- Integral thermal interface pad option eliminates need to order and install pad separately.
- Ordering a single part number with the hardware kit option provides everything necessary to keep your converter cool.

Standard P/N	Footprint Dimensions in. (mm)	Height in. (mm)	Fin Orientation	Number of Fins	Forced Convection Thermal Resistance at 300 ft/min (C/W)	Natural Convection Power Dissipation (Watts) 40°C Rise Heat Sink to Ambient
557-140AB	4.60 (116.8) x 2.40 (61.0)	1.40 (35.6)	Horizontal	6	1.3	14
558-75AB	2.40 (61.0) x 4.60 (116.8)	0.75 (19.1)	Vertical	16	1.8	12
559-50AB	2.40 (61.0) x 4.60 (116.8)	0.50 (12.7)	Vertical	27	2.2	10

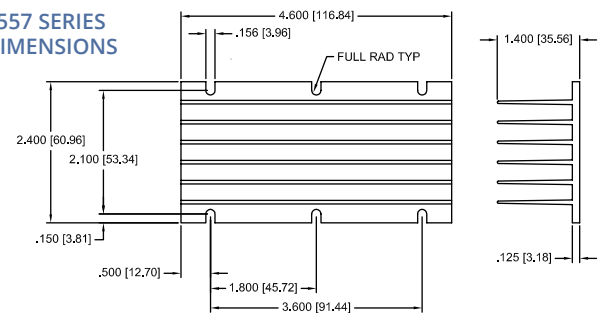
Material: Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS

##### PRODUCT DESIGNATION



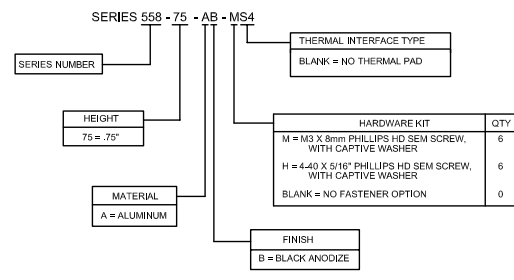
##### 557 SERIES DIMENSIONS



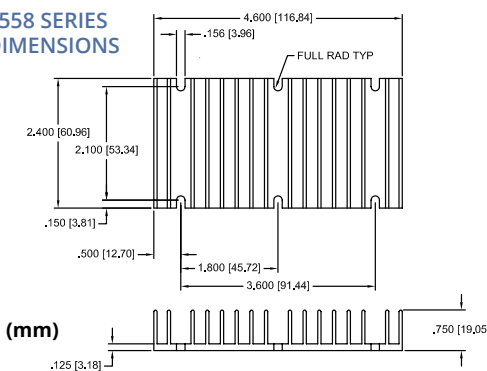
Dimensions: in. (mm)

#### MECHANICAL DIMENSIONS

##### PRODUCT DESIGNATION



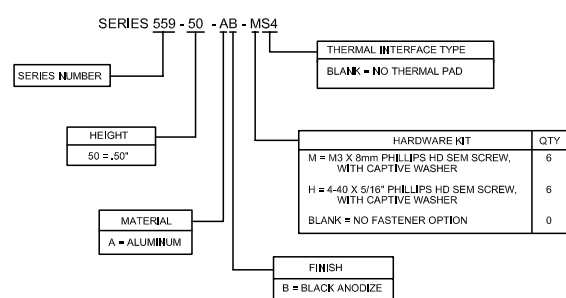
##### 558 SERIES DIMENSIONS



Dimensions: in. (mm)

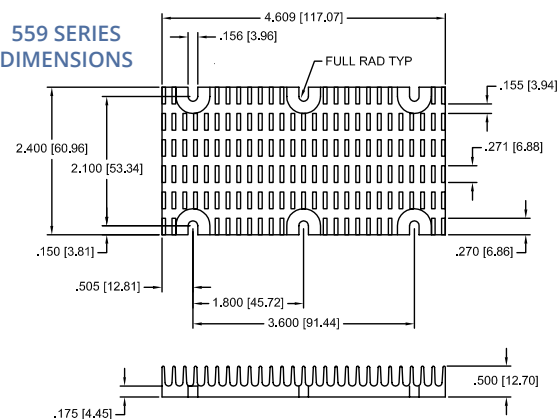
#### MECHANICAL DIMENSIONS

##### PRODUCT DESIGNATION



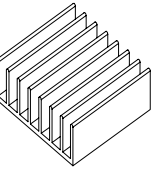
Dimensions: in. (mm)

##### 559 SERIES DIMENSIONS



HEAT SINKS FOR "HALF-BRICK"  
DC/DC CONVERTERS

### 517, 527, 518, & 528 SERIES



TO-220 and TO-218

#### FEATURES AND BENEFITS

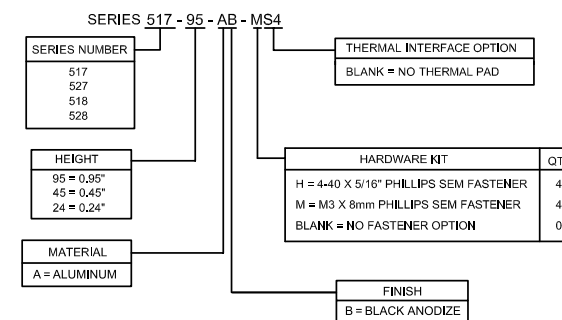
- Standard mounting hole patterns mate with the majority of "half-brick" DC/DC converters on the market.
- Aluminum extruded fin construction keeps DC/DC converter modules cool in both forced and natural convection applications.
- Vertical and horizontal fin configurations available in a variety of heights.
- Black anodized finish standard.
- Integral thermal interface pad option eliminates need to order and install pad separately.
- Ordering a single part number with the hardware kit option provides everything necessary to keep your converter cool.

Standard P/N	Footprint Dimensions in. (mm)	Height in. (mm)	Fin Orientation	Number of Fins	Thermal Performance	
					Natural Convection Power Dissipation (Watts) 60°C Rise Heat Sink to Ambient	Forced Convection Thermal Resistance at 300 ft/min (C/W)
517-95AB	2.28 (57.9) x 2.40 (61.0)	0.95 (24.1)	Horizontal	8	11W	2.0
527-45AB	2.28 (57.9) x 2.40 (61.0)	0.45 (11.4)	Horizontal	11	7W	3.2
527-24AB	2.28 (57.9) x 2.40 (61.0)	0.24 (6.1)	Horizontal	11	5W	5.8
518-95AB	2.40 (61.0) x 2.28 (57.9)	0.95 (24.1)	Vertical	8	11W	2.0
528-45AB	2.40 (61.0) x 2.28 (57.9)	0.45 (11.4)	Vertical	11	7W	3.2
528-24AB	2.40 (61.0) x 2.28 (57.9)	0.24 (6.1)	Vertical	11	5W	5.8

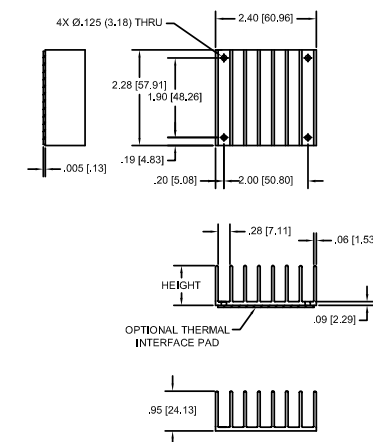
Material: Aluminum, Black Anodized

#### MECHANICAL DIMENSIONS

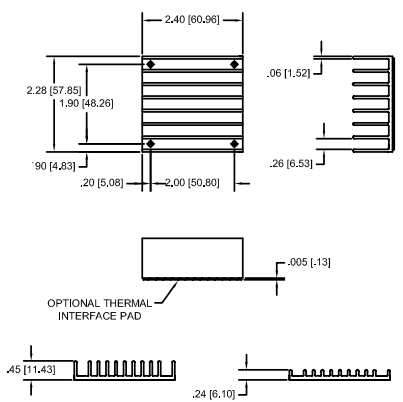
##### PRODUCT DESIGNATION



##### 517/527 SERIES DIMENSIONS



##### 518/528 SERIES DIMENSIONS



Dimensions: in. (mm)

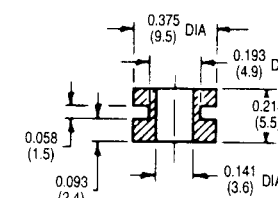
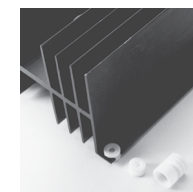
## MOUNTING HARDWARE FOR EXTRUDED HEAT SINKS

### 100 SERIES

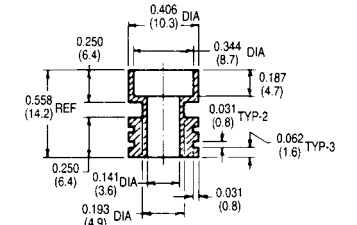
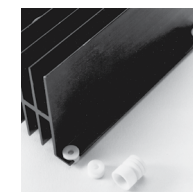
TEFLON MOUNTING INSULATORS

Standard P/N	Description	For Use with Series	Mounting Hardware	Material	Hipot Rating (VAC)	Weight lbs. (grams)
103	Spool-shaped insulator	300, 400, 600, 111, 113	#6-32 screw	Teflon	1500	0.00012 (0.05)
107	Spool-shaped insulator	300, 400, 600, 111, 113	#6-32 screw, nut	Teflon	5000	0.0034 (1.54)

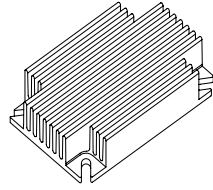
#### 103 SERIES



#### 107 SERIES



## EXTRUDED HEAT SINKS FOR DC/DC CONVERTERS



### 537 & 547 SERIES

HEAT SINKS FOR "QUARTER-BRICK"  
DC/DC CONVERTERS

TO-220 and TO-218

#### FEATURES AND BENEFITS

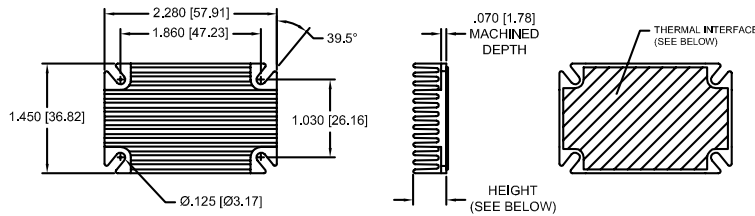
- Mounting slots accommodate two hole patterns: 1.86" x 1.03" and 2.00" x 1.20", fitting the vast majority of quarter-brick converters on the market.
- Designed for optimum use in forced convection applications.
- Vertical and horizontal fin configurations available in a variety of heights.
- Black anodized finish standard.
- Integral thermal interface pad option eliminates need to order and install pad separately.
- Ordering a single part number with the hardware kit option provides everything necessary to keep your converter cool.

Standard P/N	Footprint Dimensions in. (mm)	Height in. (mm)	Fin Orientation	Number of Fins	Forced Convection Thermal Resistance at 300 ft/min (C/W)
537-95AB	2.28 (57.9) x 1.45 (36.8)	0.95 (24.1)	Horizontal	8	2.1
537-45AB	2.28 (57.9) x 1.45 (36.8)	0.45 (11.4)	Horizontal	13	2.3
537-24AB	2.28 (57.9) x 1.45 (36.8)	0.24 (6.1)	Horizontal	14	4.2
547-95AB	1.45 (36.8) x 2.28 (57.9)	0.95 (24.1)	Vertical	11	2.2
547-45AB	1.45 (36.8) x 2.28 (57.9)	0.45 (11.4)	Vertical	20	2.1
547-24AB	1.45 (36.8) x 2.28 (57.9)	0.24 (6.1)	Vertical	22	3.5

Material: Aluminum, Black Anodized

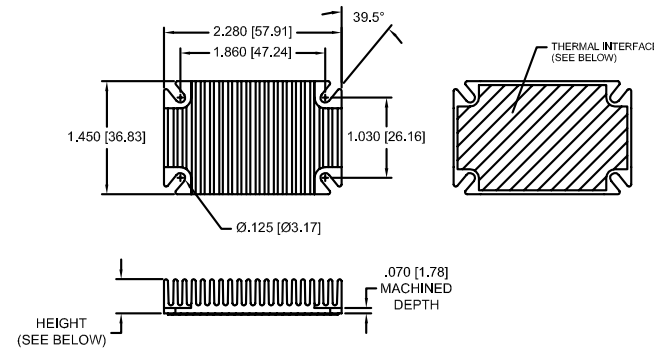
#### MECHANICAL DIMENSIONS

##### 537 SERIES DIMENSIONS



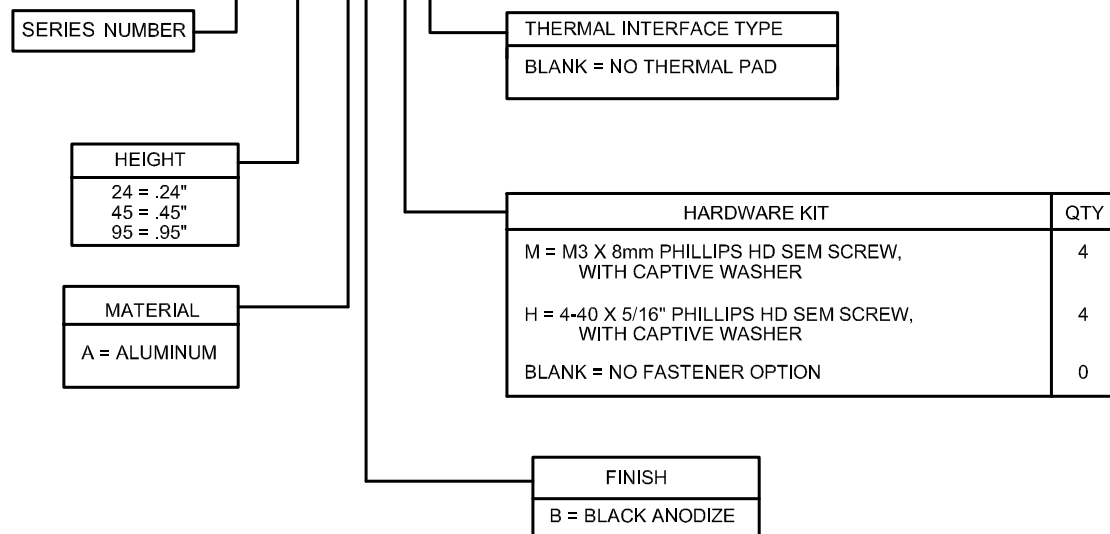
Dimensions: in. (mm)

##### 547 SERIES DIMENSIONS



#### PRODUCT DESIGNATION

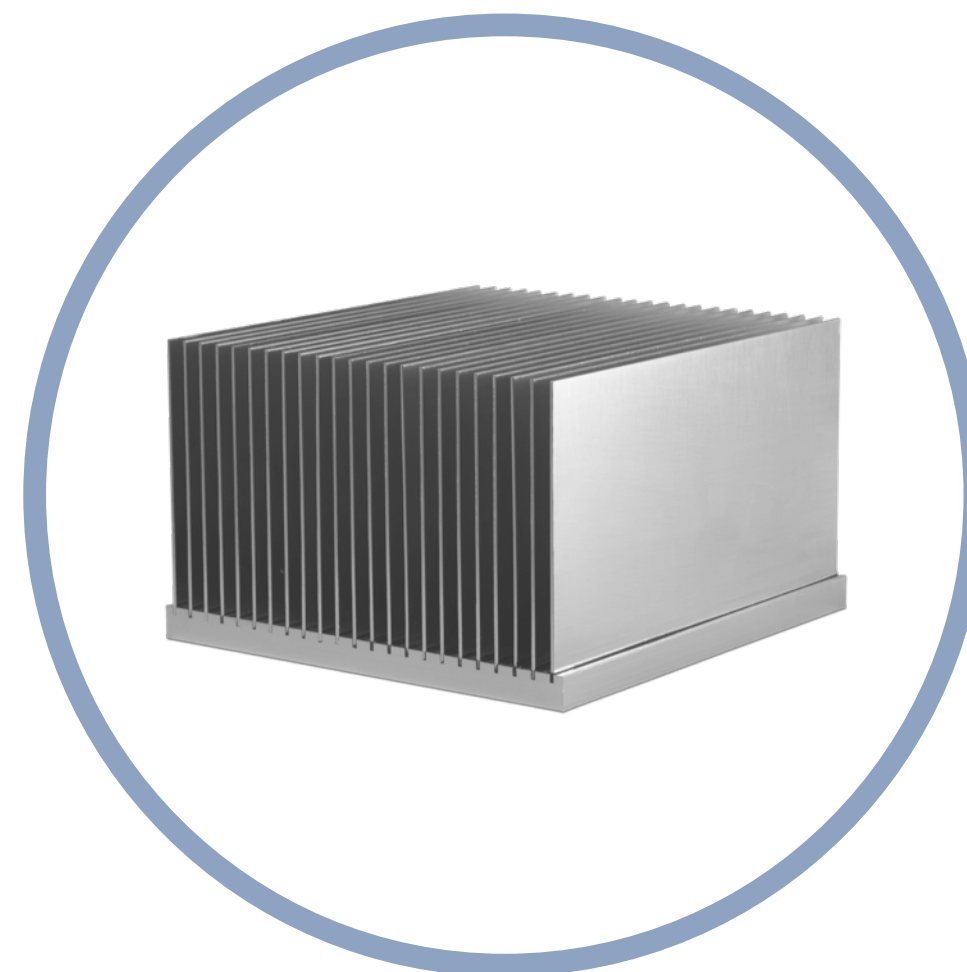
SERIES 537 - 95 - AB - MS4



# BONDED FIN HEAT SINKS

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<i>High Fin Density Heat Sinks for Power Modules, IGBTs, Relays</i> .....	100-101
<i>Custom Bonded Fin Heat Sinks &amp; Assemblies</i> .....	102
<i>maxiTHERM-HD<sup>3</sup>™ Bonded Fin Forced Convection Series #1</i> .....	103
<i>maxiTHERM-HD<sup>3</sup>™ Bonded Fin Forced Convection Series #2</i> .....	104

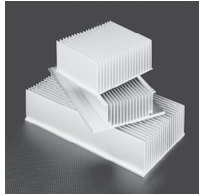


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*Wakefield-Vette offers a variety of natural and forced convection bonded fin heat sink assemblies. Configurable in a variety of ways, they are reliable, cost effective, and highly efficient thermal management solutions for high power and densely packaged applications, even in demanding shock and vibration environments. Bonded fin heat sinks are used when the required combination of large heat sink size, tall fins and high fin density make simple extrusions impractical.*

*We offer these products in our standard catalog and also custom fabricated to meet a customer's needs.*

# HIGH FIN DENSITY HEAT SINKS FOR POWER MODULES, IGBTs, RELAYS



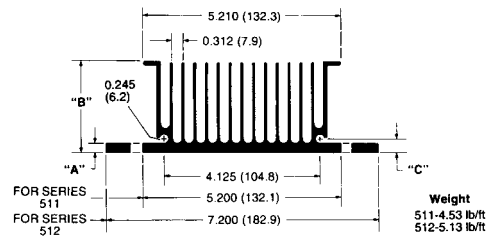
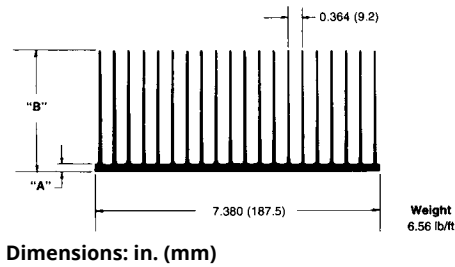
## 510, 511 & 512 SERIES

Standard Catalog P/N <sup>(5)</sup> Milled Base <sup>(1)</sup>	Nonmilled Base <sup>(2)</sup>	Base Width in. (mm)	Length in. (mm)	Height		Thermal Resistance <sup>(5)</sup> ( $\theta_{sa}$ ) at Typical Load	
				Milled Base <sup>(1)</sup> ("M Series") in. (mm)	Nonmilled Base <sup>(2)</sup> ("U" Series) in. (mm)	Natural Convection <sup>(3)</sup> ( $^{\circ}\text{C}/\text{W}$ )	Forced Convection <sup>(4)</sup> ( $^{\circ}\text{C}/\text{W}$ @ 100 CFM)
510-3M	510-3U	7.380 (187.452)	3.000 (76.2)	3.106 (78.9)	3.136 (79.7)	0.56	0.088
510-6M	510-6U	7.380 (187.452)	6.000 (152.4)	3.106 (78.9)	3.136 (79.7)	0.38	0.070
510-9M	510-9U	7.380 (187.452)	9.000 (228.6)	3.106 (78.9)	3.136 (79.7)	0.29	0.066
510-12M	510-12U	7.380 (187.452)	12.000 (304.8)	3.106 (78.9)	3.136 (79.7)	0.24	0.062
510-14M	510-14U	7.380 (187.452)	14.000 (355.6)	3.106 (78.9)	3.136 (79.7)	0.21	0.059
511-3M	511-3U	5.210 (132.33)	3.000 (76.2)	2.350 (59.7)	2.410 (61.2)	0.90	0.120
511-6M	511-6U	5.210 (132.33)	6.000 (152.4)	2.350 (59.7)	2.410 (61.2)	0.65	0.068
511-9M	511-9U	5.210 (132.33)	9.000 (228.6)	2.350 (59.7)	2.410 (61.2)	0.56	0.060
511-12M	511-12U	5.210 (132.33)	12.000 (304.8)	2.350 (59.7)	2.410 (61.2)	0.45	0.045
512-3M	512-3U	7.200 (182.88)	3.000 (76.2)	2.350 (59.7)	2.410 (61.2)	0.90	0.120
512-6M	512-6U	7.200 (182.88)	6.000 (152.4)	2.350 (59.7)	2.410 (61.2)	0.65	0.068
512-9M	512-9U	7.200 (182.88)	9.000 (228.6)	2.350 (59.7)	2.410 (61.2)	0.56	0.060
512-12M	512-12U	7.200 (182.88)	12.000 (304.8)	2.350 (59.7)	2.410 (61.2)	0.45	0.045

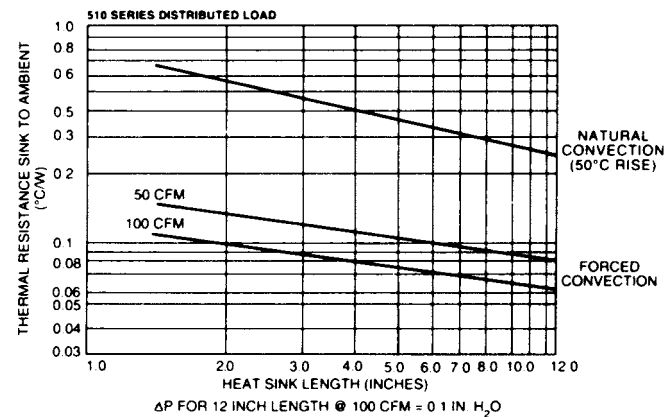
510 SERIES			
Series	A	B	Flatness
510-U	0.216 (5.5)	3.136 (79.7)	0.006 in./in. (0.15 mm/mm)
510-M	0.165 (4.2)	3.106 (78.9)	0.002 in./in. (0.05 mm/mm)

511 AND 512 SERIES				
Series	A	B	C	Flatness
511-U 512-U	0.250 (6.4)	2.410 (61.2)	0.372 (9.4)	0.006 in./in. (0.15 mm/mm)
511-M 512-M	0.220 (5.6)	2.350 (59.7)	0.342 (8.7)	0.002 in./in. (0.05 mm/mm)

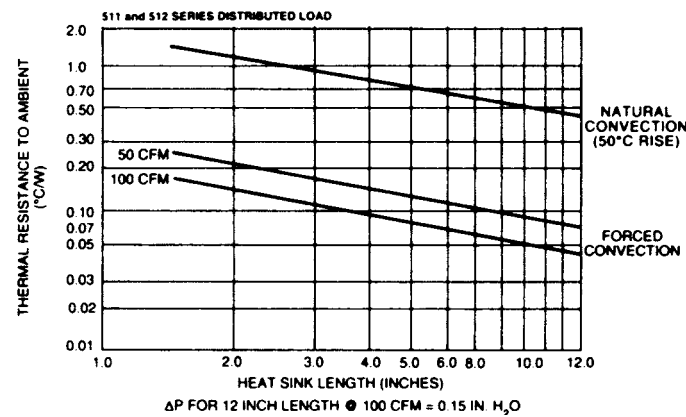
### MECHANICAL DIMENSIONS



### NATURAL AND FORCED CONVECTION CHARACTERISTICS



### NATURAL AND FORCED CONVECTION CHARACTERISTICS

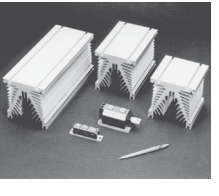


### NOTES:

1. Precision-milled base for maximum heat transfer performance (flatness 0.002 in./in.)
2. Nonmilled base flatness: 0.006 in./in.
3. Natural convection heat dissipation for distributed heat sources at 50°C rise.
4. Forced convection heat dissipation for distributed heat sources at 100 cubic feet per minute, shrouded condition.
5. Standard models are provided without finish.

# HIGH PERFORMANCE HEAT SINKS FOR POWER MODULES, IGBTs AND SOLID STATE RELAYS

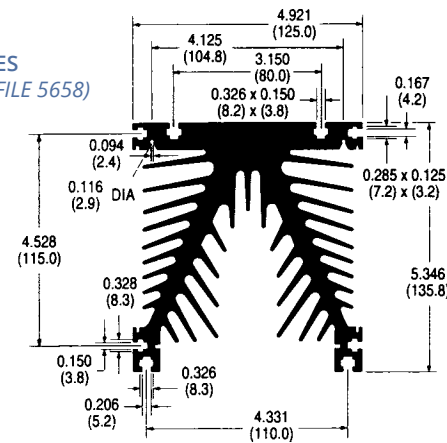
## 392 SERIES



Standard P/N, Finish		Length in. (mm)	Thermal Resistance at Typical Load		Weight lbs. (grams)
Black Anodized	Gold Iridite		Natural Convection ( $\theta_{sa}$ ) ( $^{\circ}\text{C}/\text{W}$ )	Forced Convection ( $\theta_{sa}$ ) ( $^{\circ}\text{C}/\text{W}$ )	
392-120AB	392-120AG	4.725 (120.0)	0.50	0.16 @ 100 CFM	4.452 (2019.43)
392-180AB	392-180AG	7.087 (180.0)	0.43	0.11 @ 100 CFM	6.636 (3010.09)
392-300AB	392-300AG	11.811 (300.0)	0.33	0.08 @ 100 CFM	10.420 (4726.51)

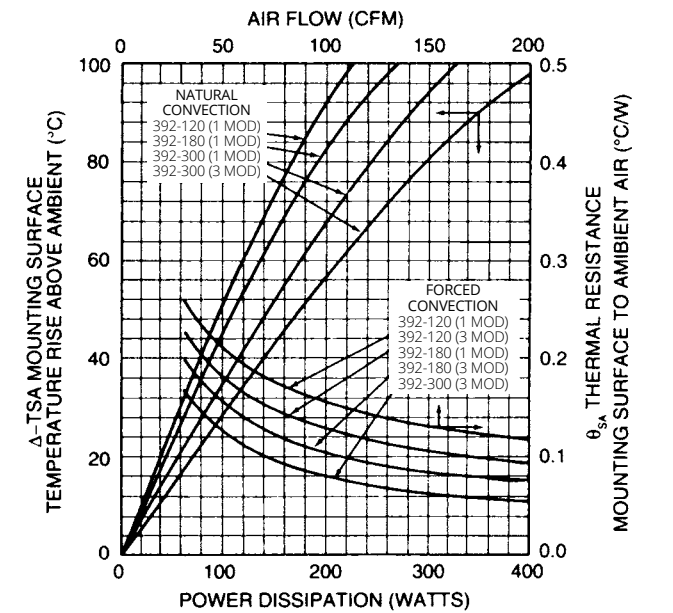
### MECHANICAL DIMENSIONS

#### 392 SERIES (EXTRUSION PROFILE 5658)

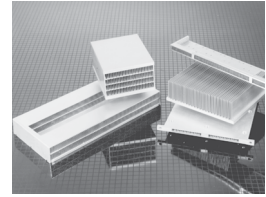


Dimensions: in. (mm)

### NATURAL AND FORCED CONVECTION CHARACTERISTICS

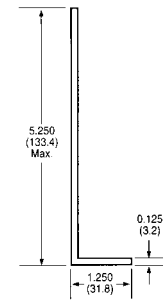


# CUSTOM BONDED FIN HEAT SINKS & ASSEMBLIES

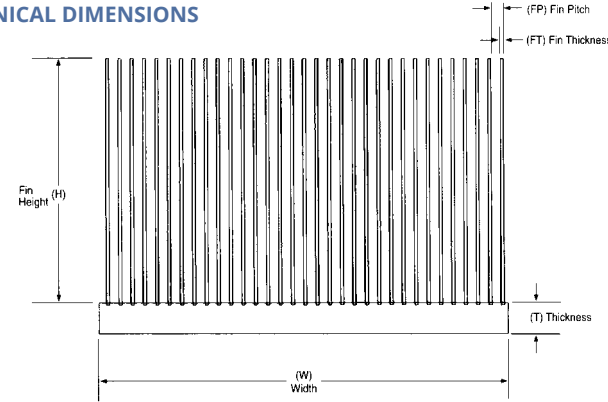


Wakefield-Vette offers an extensive line of natural convection and forced convection custom bonded fin heat sinks assemblies. Configurable in a variety of ways, they are reliable, cost effective, and highly efficient thermal management solutions for high power and densely packaged applications, even in demanding shock and vibration environments.

**MOUNTING LEG**  
(EXTRUSION PROFILE 8930)  
(EXTRUSION PROFILE 8120)



**MECHANICAL DIMENSIONS**



Dimensions: in. (mm)

Base Extrusion Profile No.	BONDED FIN BASES					Thermal Resistance °C/W			
	W	T	FT	FP	Max # Fins	Natural Convection		Forced Convection	
						H = 2"	H = 4"	H = 2"	H = 4"
8711	2.800 (71.1)	0.520 (13.2)	.050 (1.3)	0.275 (5.4)	10	1.360	0.830	0.459	0.277
8731	3.615 (91.8)	0.575 (14.6)	.050 (1.3)	0.239 (6.1)	15	1.110	0.685	0.281	0.168
8546	4.000 (101.6)	0.500 (12.7)	.050 (1.3)	0.200 (5.1)	20	1.330	0.823	0.215	0.144
8737	4.425 (112.4)	0.650 (16.5)	.050 (1.3)	0.238 (6.0)	18	0.937	0.580	0.233	0.140
8119	4.750 (120.7)	0.500 (12.7)	.050 (1.3)	0.288 (7.3)	16	0.880	0.539	0.222	0.157
8712	5.000 (127.0)	0.530 (13.5)	.050 (1.3)	0.198 (5.0)	25	1.122	0.692	0.170	0.101
8732	5.650 (143.5)	0.500 (12.7)	.050 (1.3)	0.200 (5.1)	28	1.011	0.625	0.152	0.090
8556	6.000 (152.4)	0.500 (12.7)	.050 (1.3)	0.250 (6.4)	24	0.751	0.438	0.153	0.107
8542	6.620 (168.1)	0.500 (12.7)	.050 (1.3)	0.200 (5.1)	33	0.880	0.519	0.122	0.082
8671	7.230 (183.6)	0.550 (14.0)	.050 (1.3)	0.239 (6.1)	30	0.655	0.399	0.123	0.086
8823	7.440 (189.0)	0.525 (13.3)	.050 (1.3)	0.200 (5.1)	37	0.820	0.500	0.118	0.070
8734	7.500 (190.5)	0.560 (14.2)	.050 (1.3)	0.400 (10.2)	19	0.550	0.310	0.213	0.130
8545	8.000 (203.2)	0.500 (12.7)	.050 (1.3)	0.200 (5.1)	40	0.591	0.353	0.095	0.053
8709	8.327 (211.5)	0.400 (10.2)	.050 (1.3)	0.215 (5.5)	37	0.507	0.310	0.081	0.048
8715	8.780 (223.0)	0.600 (15.2)	.050 (1.3)	0.270 (6.9)	28	0.384	0.231	0.106	0.063
8707	10.00 (254.0)	0.550 (14.0)	.050 (1.3)	0.238 (6.0)	42	0.361	0.220	0.071	0.042
8121	10.78 (273.8)	0.560 (14.2)	.050 (1.3)	0.238 (6.0)	45	0.348	0.209	0.065	0.040
8733	12.60 (320.0)	0.600 (15.2)	.050 (1.3)	0.207 (5.3)	60	0.383	0.235	0.075	0.030
8714	14.00 (355.6)	0.525 (13.3)	.050 (1.3)	0.250 (6.4)	56	0.275	0.168	0.053	0.032
8735	15.00 (381.0)	0.625 (15.9)	.050 (1.3)	0.250 (6.4)	60	0.264	0.161	0.049	0.030

**NOTES:**

1. Natural and forced convection thermal resistances based on 6.000 in. length for profiles less than 8.000" wide.
2. Natural and forced convection thermal resistances based on 12.000 in. length for profiles 8.000" wide and greater
3. Forced convection thermal resistance based on 500 LFM, shrouded, horizontal. distributed heat load.
4. Forced convection bonded fin assemblies use standard "muffin" fans.
5. Dimensions shown are as extruded. To improve flatness across the width, bases can be machined. Machined base thickness will be reduced.

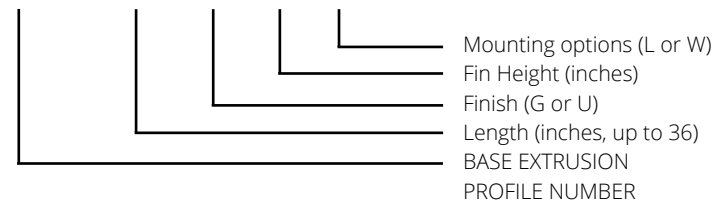
**Order Guide - Example**

Example Part Number - BE8546-1200-U4W

- BE8546 = Bonded fin base extrusion profile identifier
- Length (inches; 12.00 shown, two decimal point assumed)
- Finish (G = Gold Chromate, U = Unfinished)
- Fin Height (4 inches shown)
- Mounting Options (L = Mounting Legs, W = No Mounting Legs)

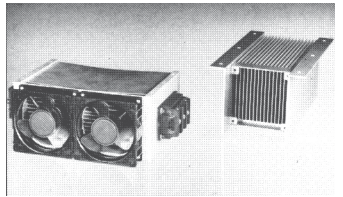
**Part Numbering Order Guide\***

BEXXXX -XX- X X X



# maxiTHERM-HD<sup>3</sup>™ BONDED FIN FORCED CONVECTION SERIES #1

**SERIES #1**

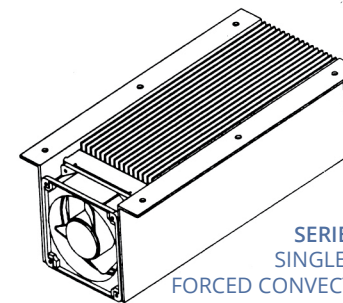


maxiTHERM-HD<sup>3</sup>™ Bonded Fin Forced Convection Series #1 heat sinks provide more effective cooling per cubic inch of space compared to extruded heat sinks. Exceptionally low thermal resistance values in forced convection applications are achieved with "Series #1" models, as low as 0.024°C/W for a double unit employing 2 fans. Mounting hole pattern is 4.125 in. sq. for standard 120 mm axial ("box") fans. These heat sinks are ideal for a variety of high power applications, even in the most demanding shock and vibration environments.

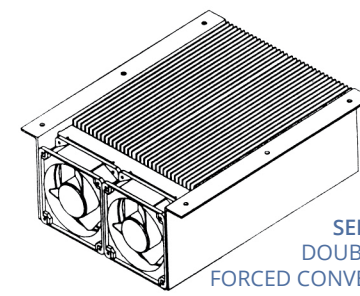
SERIES #1 (5.25" TALL ASSEMBLY)						
maxiTHERM-HD <sup>3</sup> ™ Package Series #1	Standard Muffin Fan (S)	Dimension (in inches)			Perimeter (in inches)	Thermal Resistance °C/W
		"A"	"B"	"C"		
1A	1	7.000 (177.8)	2.500 (63.5)	4.500 (114.3)	742.5 (18859.5)	0.10
1B	1	9.500 (241.3)	3.750 (95.3)	7.000 (114.3)	1515.0 (38481.0)	0.09
1C	1	12.000 (304.8)	5.000 (127.0)	9.500 (114.3)	1567.5 (39814.5)	0.07
1D	1	14.500 (368.3)	6.250 (158.8)	12.000 (114.3)	1980.5 (50304.7)	0.05
1E	2	14.590 (370.6)	6.000 (152.4)	12.000 (114.3)	4536.0 (115214.4)	0.028
1F	2	16.590 (429.0)	7.000 (177.8)	14.000 (114.3)	5292.0 (134416.8)	0.025
1G	2	18.590 (472.2)	8.000 (203.2)	16.000 (114.3)	6048.0 (153619.2)	0.024

1Z NON-STANDARD LENGTH  
ZZ NON-STANDARD CONFIGURATION & LENGTH

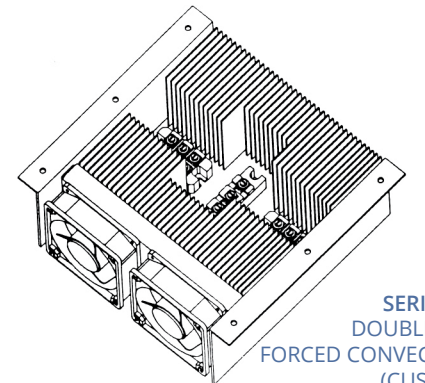
Refer to the following page for ordering information.



**SERIES #1**  
SINGLE FAN  
FORCED CONVECTION



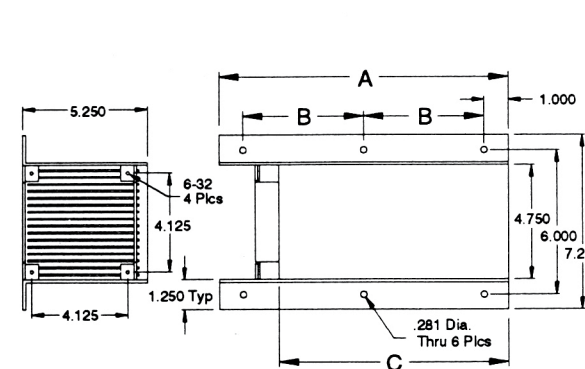
**SERIES #1**  
DOUBLE FAN  
FORCED CONVECTION



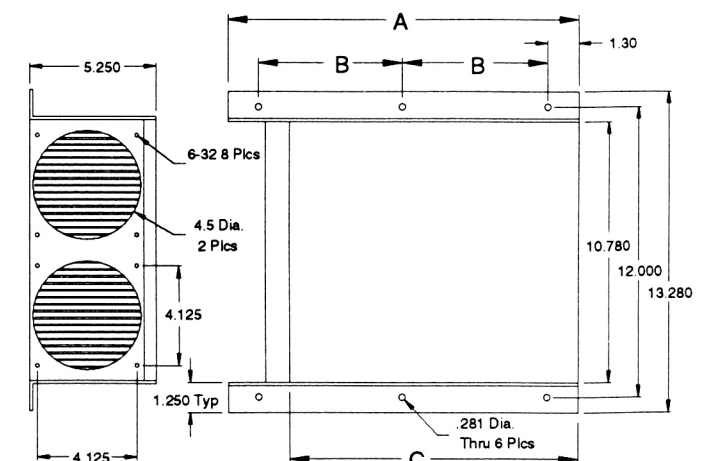
**SERIES #1**  
DOUBLE FAN  
FORCED CONVECTION  
(CUSTOM)

**MECHANICAL DIMENSIONS**

**SERIES #1**  
SINGLE FAN FORCED CONVECTION



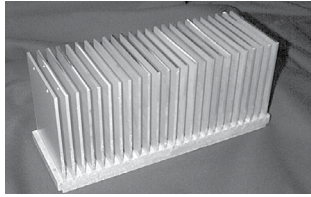
**SERIES #1**  
DOUBLE FAN FORCED CONVECTION



**NOTES:**

1. Standard muffin fans not included, order separately.

# maxiTHERM-HD<sup>3</sup>™ BONDED FIN FORCED CONVECTION SERIES #2



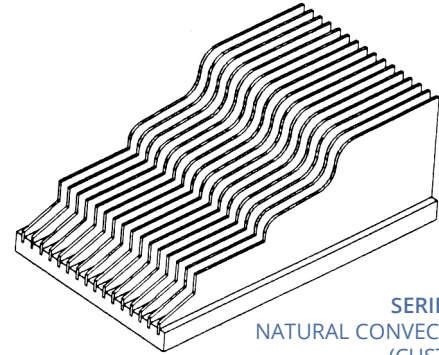
## SERIES #2

maxiTHERM-HD<sup>3</sup>™ Bonded Fin Natural Convection Series #2 heat sinks are designed for a variety of high power applications. These heat sinks are ideal even in the most demanding shock and vibration environments. Standard heat sink lengths range from 7.000 in. (177.8 mm) to 18.590 in. (472.2 mm) and the overall height is 3.130 in. (79.5 mm). Custom lengths, mounting options, and other configurations can be accommodated.

SERIES #2 (3.13" TALL ASSEMBLY)				
maxiTHERM-HD <sup>3</sup> ™ Package Series #2	Dimension (in inches)		Perimeter (in inches)	Thermal Resistance °C/W
	"A"	"B"		
2A	4.500 (114.3)	1.250 (31.8)	427.5 (10858.5)	0.41**
2B	9.500 (177.8)	2.500 (63.5)	665.0 (16891.0)	0.38**
2C	9.500 (241.3)	3.750 (95.3)	902.0 (22910.8)	0.35**
2D	12.000 (304.8)	5.000 (127.0)	1140.0 (28956.0)	0.33**

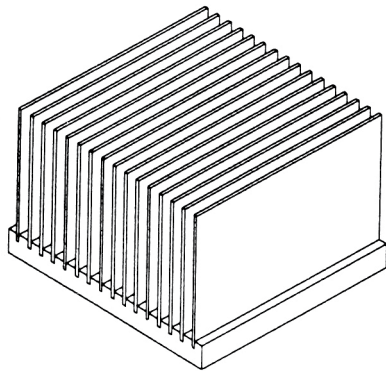
  

ZZ	NON-STANDARD LENGTH
ZZ	NON-STANDARD CONFIGURATION & LENGTH

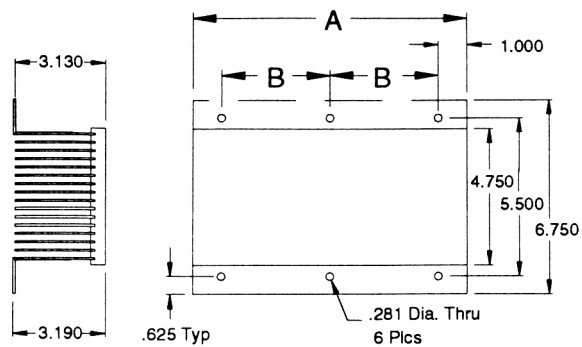


SERIES #2  
NATURAL CONVECTION  
(CUSTOM)

### SERIES #2 NATURAL CONVECTION



### MECHANICAL DIMENSIONS



### NOTES:

- All non-standard parts must have a modifier.
- 1Z and 2Z denoting non-standard lengths should only be used for non-standard "A" dimensions. Part # must contain a modifier.
- \*3. When 105 CFM fan (s) used – fan mounting hole pattern for standard axial ("muffin") fan.
- \*\*4. Natural convection based on 50°C heat sink temperature rise above ambient.

### ORDERING INFORMATION

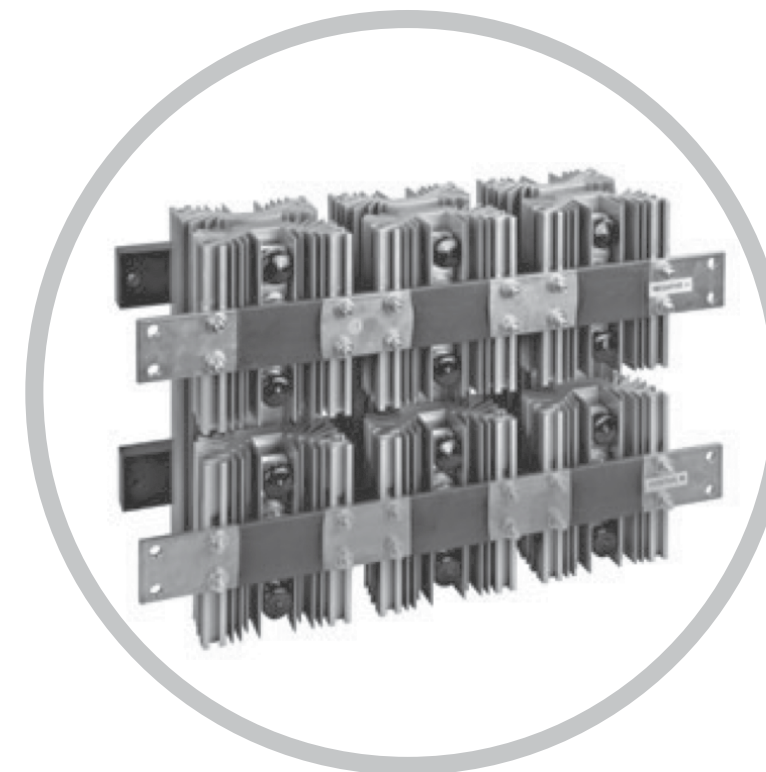
BE8-	-*	-*	-*	-*	MODIFIER
					NNNN Factory issued number for modification to customer requirements.
					PLATING OPTIONS
					GI Gold Iridite
					CI Clear Iridite
					N No Plating (Wash & Etch)
					MOUNTING OPTIONS
					L Mounting Legs
					F Fan Brackets & Mounting Legs (series #1 only)
					W No Brackets or Legs
					PACKAGE LENGTH ("A" Dimension)
					SERIES #1 (5.25" tall assembly)
					PN LENGTH
					1A 7.000"
					1B 9.500"
					1C 12.000"
					1D 14.500"
					1E 14.590"
					1F 16.590"
					1G 18.590"
					1Z non-standard lengths (Note 2)
					ZZ non-standard configuration & length
					PACKAGE LENGTH ("A" Dimension)
					SERIES #2 (3.13" tall assembly)
					PN LENGTH
					2A 4.500"
					2B 7.000"
					2C 9.500"
					2D 12.000"
					2Z non-standard length (Note 2)
					ZZ non-standard configuration & length
					BASE EXTRUSION NUMBER
					BE8119 Base profile identifier (SINGLE)
					BE8121 Base profile identifier (DOUBLE)

# PRECISION CLAMP HEAT SINKS

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*Precision Compression Mounting Clamp Systems ..... 108-112*

*132/133 Series High-performance Heat Sinks For  
Compression Type Devices ..... 112-113*



*Wakefield-Vette compression pack heat sink and clamp systems provide customers with the complete system solution for proper installation and heat dissipation for high-power compression pack semiconductors. These high-quality mounting clamp assemblies are the industry standard for mounting, compressing, and clamping press-pack SCR, thyristors, rectifiers, and other high power disc packaged devices. Devices of these styles are most commonly found in power distribution equipment, industrial controls, transportation systems, and power supply and conversion systems.*

*A clamp system consists of a crossbar and a spring assembly. The crossbar is a steel bar with two threaded rods installed in it. The rods are generally knurled and cold rolled into the bar to ensure proper fit. The cross bar assembly is covered in an epoxy coating which acts as an electrical insulator to ensure the devices are properly grounded. The crossbar is installed through the center web of the heat sink and sits in a channel surrounded by fins needed for thermal performance.*

*On the back of the heat sink, a puck style device is installed and then the spring assembly is installed in the threaded rods of the crossbar. By tightening the nuts on the spring assembly, a compression force is applied to the center of the puck. Each spring assembly has a force gauge integrated into it to ensure ease of assembly and consistency of force applied to the many devices used in a system.*

*The cross bar assembly is available in various lengths to meet the various needs of the industry. All components for device mounting are available separately for all standard compression requirements from 800 lbs. to 16,000 lbs.*

# PRECISION COMPRESSION MOUNTING CLAMP SYSTEMS

Wakefield-Vette compression pack heat sinks and clamp systems provide electrical and industrial equipment manufacturers with complete system solutions for proper installation and heat dissipation for high-power compression pack semiconductor. All components for device mounting and cooling are available separately for all standard compression requirements from 800 lbs (362.9 kg) to 16,000 lbs (7,257.5 kg) force in both natural and forced convection applications.

Clamp Assembly Series	Maximum Clamping Force Force Range	Maximum Diameter (Ref) Power Disc Device	Crossbar Stud Centerline to Centerline Dimension
130 Series	800 lbs (362.9 kg) - 2,000 lbs (907.2 kg)	2.25 in. (57.2 mm)	2.750 in. (69.9 mm) Ref
139 Series	3,000 lbs (1,360.8 kg) and 5,000 lbs (2,268.0 kg)	3.50 in. (88.9 mm)	4.000 in. (101.6 mm) Ref
143 Series	1,000 lbs (453.6 kg) - 6,000 lbs (2,721.6 kg)	3.50 in. (88.9 mm)	4.000 in. (101.6 mm) Ref
144 Series	1,000 lbs (453.6 kg) - 6,000 lbs (2,721.6 kg)	4.00 in. (101.6 mm)	4.625 in. (117.5 mm) Ref
145 Series	2,000 lbs (907.2 kg) - 10,000 lbs (4,535.9 kg)	4.50 in. (114.3 mm)	5.500 in. (139.7 mm) Ref
146 Series	8,000 lbs (3,628.8 kg) - 16,000 lbs (7,257.5 kg)	5.25 in. (133.4 mm)	6.000 in. (152.4 mm) Ref
131/132/133 Series	High-Performance Press Pack Heat Sinks		

These high-quality mounting clamp assemblies are the worldwide standard for mounting, compression, and clamping press-pack SCR, thyristor, and other high power disc packaged devices utilized in power distribution equipment, industrial controls, transportation systems, and power supply and conversion systems.

Clamp assemblies will accommodate devices with overall case diameters to 5.25 in. (133.4 mm) maximum. Vertical device mounting space available for assemblies is determined by selecting an appropriate series crossbar by length which, when a series spring assembly is selected (based on maximum clamping force required), will provide the necessary vertical clearance space. For the 130 and 139 Series, this determination is made by subtracting the chosen spring assembly "Z" dimension (refer to dimensional tables) from the crossbar assembly "X" dimension minimum and maximum values, to calculate the available device mounting space clearance for the particular assembly combination. Spring assembly "Z" dimension is the dimension measured from the spring assembly device mounting surface to the spring assembly top surface. Some series have fixed dimensions for alpha characters. All spring assemblies are designed with a force indicator gauge.

Max SCR DIA	Clamp Series	Force Range	Extrusion Profile	
101.6 mm	ALL	800 - 16000 LBS	XX7151	
84 mm	ALL	800 - 16000 LBS	XX6351	
63 mm	ALL	800 - 16000 LBS	XX5735	
	144	800 - 6000 LBS	XX5360	
	143	800 - 6000 LBS	XX10239	
	144	800 - 6000 LBS	O16235	
	144	800 - 6000 LBS	O14442	
	143	800 - 6000 LBS	XX3529	
	143	800 - 6000 LBS	XX5730	
	143	800 - 6000 LBS	O14191	
50 mm	143	800 - 6000 LBS	XX5733	
	143	800 - 6000 LBS	XX3559-2	
	143	800 - 6000 LBS	XX5736	
	143	800 - 6000 LBS	XX3561-2	
	143	800 - 6000 LBS	XX5732	
	143	800 - 6000 LBS	XX5731	
	143	800 - 6000 LBS	XX3560-2	
	143	800 - 6000 LBS	O13450	
	143	800 - 6000 LBS	XX4554	
	143	800 - 6000 LBS	XX5331	
	143	800 - 6000 LBS	O03537	
	143	800 - 6000 LBS	XX5306	
	40 mm	143	800 - 6000 LBS	O14779

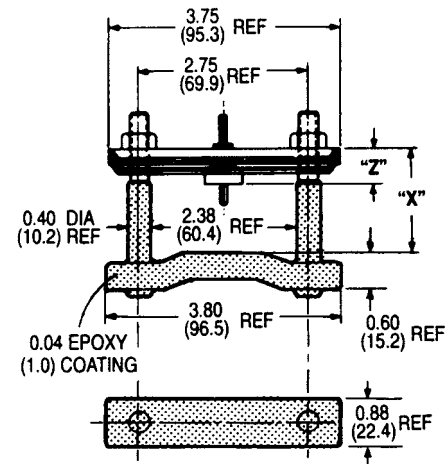


## 130 SERIES

### COMPRESSION MOUNTING CLAMP ASSEMBLIES FOR SEMICONDUCTORS TO 2.25 IN. (57.2 MM) DIAMETER

130 SERIES CROSSBAR 800 lb - 2,000 lb (362.8 kg - 907.2 kg)			
Crossbar Device Mounting, Surface to Spring Assembly Top Surface Dimension			
Model No.	"X" Dimension		Weight lbs. (grams)
	Min. in. (mm)	Max. in. (mm)	
130-A	1.74 (44.2)	2.12 (53.8)	0.4 (181.44)
130-B	2.05 (52.1)	2.43 (61.7)	0.418 (189.60)
130-C	2.36 (59.9)	2.74 (69.6)	0.427 (193.68)
130-D	2.67 (67.8)	3.05 (77.5)	0.437 (198.22)
130-E	2.98 (75.7)	3.36 (85.3)	0.447 (202.76)
130-F	3.29 (83.6)	3.67 (93.2)	0.461 (209.11)
130-G	3.60 (91.4)	3.98 (101.1)	0.476 (215.91)
130-H	3.91 (99.3)	4.29 (109.0)	0.486 (220.45)
130-J	4.22 (107.2)	4.60 (116.8)	0.497 (225.44)
130-K	4.53 (115.1)	4.91 (124.7)	0.51 (231.33)
130-L	4.34 (122.9)	5.22 (132.6)	0.52 (235.87)
130-M	5.15 (130.8)	5.53 (140.5)	0.534 (242.22)
130-N	5.46 (138.7)	5.84 (147.3)	0.544 (246.75)
130-P	5.77 (146.6)	6.15 (156.2)	0.559 (253.56)

#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

### COMPRESSION MOUNTING CLAMP ASSEMBLIES FOR SEMICONDUCTORS TO 2.25 IN. (57.2 MM) DIAMETER

## 130 SERIES

130 SERIES SPRING ASSEMBLY				
Model No.	No. of Leaves	"Z" Dim. in. (mm)	Max Force lb. (kg)	Weight lbs. (gms)
130-1	2	0.90 (22.9)	2,000 (907.2)	0.331 (150.14)
130-2	2	0.50 (12.7)	800 (362.8)	0.19 (86.18)
130-3	3	0.61 (15.5)	1,200 (544.3)	0.219 (99.34)
130-4	4	0.72 (18.3)	1,600 (727.8)	0.333 (151.05)
130-5	5	0.83 (21.1)	2,000 (907.2)	0.408 (185.07)

#### NOTES:

- Spring assemblies are stainless steel leaves with a force indicator gauge, except the lowest cost Type 130-1 spring assembly manufactured from automotive grade stainless steel.

**Order Guide:** Order Crossbar and Spring Assembly separately by type number from table.  
**Dimensions:** in. (mm) lb. (kg)



## 139 SERIES

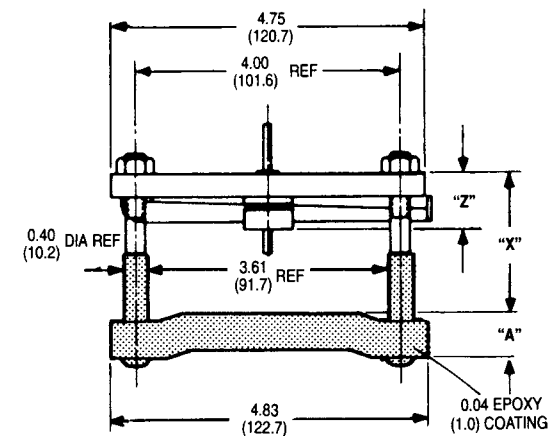
### COMPRESSION MOUNTING CLAMP ASSEMBLIES FOR SEMICONDUCTORS TO 3.50 IN. (88.9 MM) DIAMETER

139 SERIES CROSSBAR 3,000 lb - 5,000 lb (1,360.8 kg - 2,268.0 kg), Crossbar Device Mounting, Surface to Spring Assembly, Top Surface Dimension							
139-3 SERIES CROSSBAR - 3,000 LB (1,360.8)				139-5 SERIES CROSSBAR - 5,000 LB (2,268.0)			
Model No.	"X" Dimension		Weight lbs. (grams)	Model No.	"X" Dimension		Weight lbs. (grams)
	Min in. (mm)	Max in. (mm)			Min in. (mm)	Max in. (mm)	
139-3A	1.52 (38.6)	1.89 (48.0)	0.689 (312.52)	139-5A	1.52 (38.6)	1.89 (48.0)	0.94 (426.38)
139-3B	1.83 (46.5)	2.21 (56.1)	0.7 (317.51)	139-5B	1.83 (46.5)	2.21 (56.1)	0.96 (435.45)
139-3C	2.14 (54.4)	2.52 (64.0)	0.706 (320.24)	139-5C	2.14 (54.4)	2.52 (64.0)	0.98 (444.52)
139-3D	2.45 (62.2)	2.83 (71.9)	0.721 (327.04)	139-5D	2.45 (62.2)	2.83 (71.9)	1.01 (458.13)
139-3E	2.77 (70.4)	3.14 (79.8)	0.732 (332.03)	139-5E	2.77 (70.4)	3.14 (79.8)	1.02 (462.66)
139-3F	3.08 (78.2)	3.45 (87.6)	0.741 (336.11)	139-5F	3.08 (78.2)	3.45 (87.6)	1.033 (468.56)
139-3G	3.39 (86.1)	3.77 (95.8)	0.762 (345.64)	139-5G	3.39 (86.1)	3.77 (95.8)	1.053 (477.63)
139-3H	3.70 (94.0)	4.08 (103.6)	0.773 (350.63)	139-5H	3.70 (94.0)	4.08 (103.6)	1.074 (487.64)
130-3J	4.01 (101.9)	4.39 (111.5)	0.784 (355.62)	139-5J	4.33 (101.9)	4.39 (111.5)	1.064 (482.62)
139-3K	4.33 (110.0)	4.70 (119.4)	0.79 (358.34)	139-5K	4.33 (110.0)	4.70 (119.4)	1.075 (487.61)
139-3L	4.64 (117.9)	5.01 (127.3)	0.793 (359.70)	139-5L	4.64 (117.9)	5.01 (127.3)	1.088 (493.51)
139-3M	4.95 (125.7)	5.33 (135.4)	0.796 (361.06)	139-5M	4.95 (125.7)	5.33 (135.4)	1.102 (499.86)
139-3N	5.26 (133.6)	5.64 (143.3)	0.832 (377.39)	139-5N	5.26 (133.6)	5.64 (143.3)	1.11 (503.49)
139-3P	5.57 (141.5)	5.95 (151.1)	0.838 (380.11)	139-5P	5.57 (141.5)	5.95 (151.1)	1.171 (531.16)

CROSSBAR HEIGHT AND WIDTH		
Series Number	Height "A" Reference in. (mm)	Width "B" Reference in. (mm)
139-3	0.72 (18.3)	0.95 (24.1)
139-5	1.02 (25.9)	0.83 (21.1)

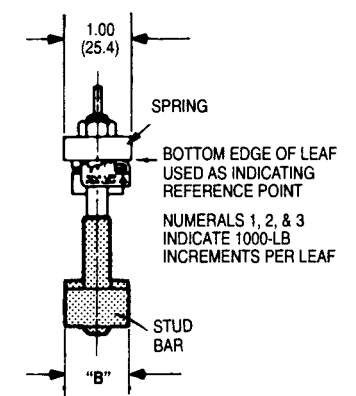
139 SERIES SPRING ASSEMBLY			
Model Number	Number of Leaves	"Z" Dimension in. (mm)	Maximum Force lb. (kg)
139-1	1	0.87(22.1)	3,000 (1,360.8)
139-2	2	1.25(31.8)	5,000 (2,268.0)

#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

**Order Guide:** Order Crossbar and Spring Assembly separately by type number from table.  
**Dimensions:** in. (mm) lb. (kg)





## PRECISION COMPRESSION MOUNTING CLAMP SYSTEMS

### 143 SERIES

COMPRESSION MOUNTING CLAMP ASSEMBLIES FOR SEMICONDUCTORS TO 3.50 IN. (88.9 MM) DIAMETER

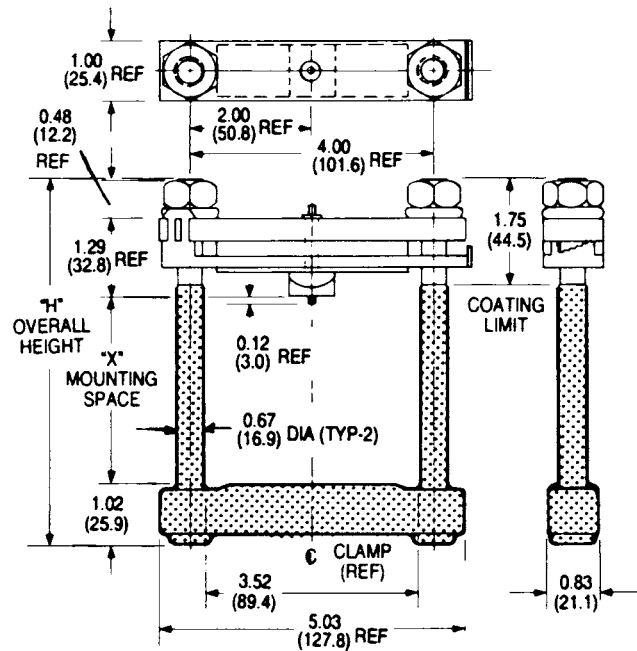
143 SERIES CROSSBAR 2,000 lb - 6,000 lb (907.2 kg - 2,721.6 kg)				
Crossbar Device Mounting, Surface to Spring Assembly, Top Surface Dimension				
Model No.	"X" Dimension		Overall Height "H" in. (mm)	Weight lbs. (grams)
	Min in. (mm)	Max in. (mm)		
143-A	1.30 (33.0)	1.80 (45.7)	4.68 (118.9)	1,100 (498.95)
143-B	1.86 (45.7)	2.30 (58.4)	5.18 (131.6)	1,125 (510.29)
143-C	2.30 (58.4)	2.80 (71.1)	5.68 (144.3)	1,150 (521.63)
143-D	2.80 (71.1)	3.30 (83.8)	6.18 (157.0)	1,175 (532.97)
143-E	3.30 (83.8)	3.80 (96.5)	6.68 (169.7)	1,200 (544.31)
143-F	3.80 (96.5)	4.30 (109.2)	7.18 (182.4)	1,225 (555.65)
143-G	4.30 (109.2)	4.80 (121.9)	1.68 (195.1)	1,250 (566.99)
143-H	4.80 (121.9)	5.30 (134.6)	8.18 (207.8)	1,275 (578.33)
143-J	5.30 (134.6)	5.80 (147.3)	8.68 (220.5)	1,300 (589.67)
143-K	5.80 (147.3)	6.30 (160.0)	9.18 (233.2)	1,325 (601.00)
143-L	6.30 (160.0)	6.80 (172.7)	9.68 (245.9)	1,350 (612.35)

143 SERIES SPRING ASSEMBLY			
Model Number	Number of Leaves	Max. Clamping Force lb. (kg)	Weight lb. (grams)
143-2	2	6,000 (2,721.6)	0.813 (368.77)

**Order Guide:**  
Order Crossbar and Spring Assembly separately by type number from table.

**Dimensions:**  
in. (mm)  
lb. (kg)

#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

COMPRESSION MOUNTING CLAMP ASSEMBLIES FOR SEMICONDUCTORS TO 4.00 IN. (101.6 MM) DIAMETER

### 144 SERIES

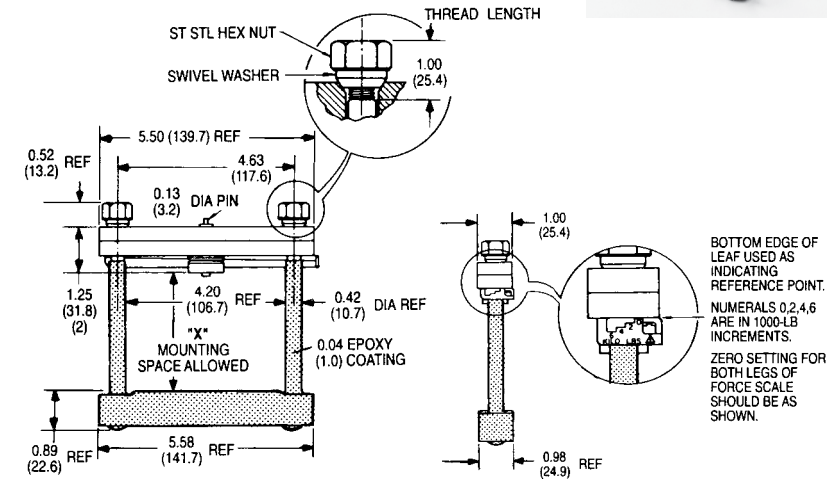
144 SERIES CROSSBAR 1,000 lb - 6,000 lb (453.6 kg - 2,721.6 kg)			
Crossbar Device Mounting, Surface to Spring Assembly, Top Surface Dimension			
Model No.	"X" Dimension		Weight lbs. (grams)
	Min in. (mm)	Max in. (mm)	
144-A	1.50 (38.1)	2.00 (50.8)	1,231 (558.37)
144-B	2.00 (50.8)	2.50 (63.5)	1,262 (572.43)
144-C	2.50 (63.5)	3.00 (76.2)	1,285 (582.87)
144-D	3.00 (76.2)	3.50 (88.9)	1,310 (594.21)
144-E	3.50 (88.9)	4.00 (101.6)	1,352 (613.26)

144 SERIES SPRING ASSEMBLY		
Model No.	Clamping Force Range lb. (kg)	Weight lbs. (grams)
144-2	1,000 (453.6) - 6,000 (2,721)	1.772 (803.77)

**Order Guide:**  
Order Crossbar and Spring Assembly separately by type number from table.

**Dimensions:**  
in. (mm)  
lb. (kg)

#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

### 145 SERIES

COMPRESSION MOUNTING CLAMP ASSEMBLIES FOR SEMICONDUCTORS TO 4.50 IN. (114.3 MM) DIAMETER

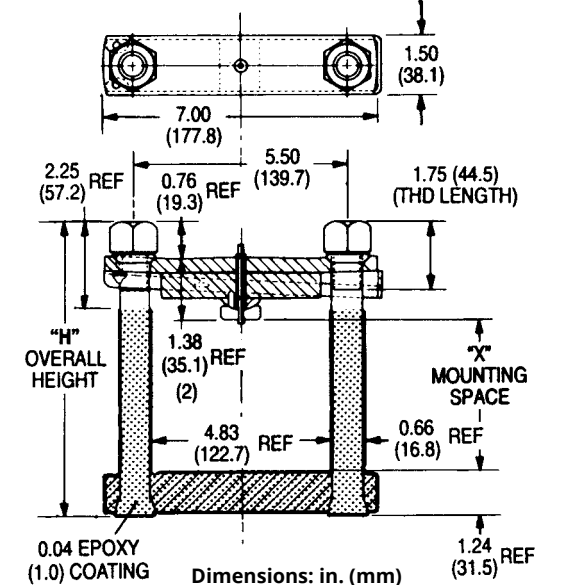
145 SERIES CROSSBAR 2,000 lb - 10,000 lb (907.2 kg - 4,535.9 kg)				
Crossbar Device Mounting, Surface to Spring Assembly, Top Surface Dimension				
Model No.	"X" Dimension		Overall Height "H" in. (mm)	Weight lbs. (grams)
	Min in. (mm)	Max in. (mm)		
145-A	1.75 (44.5)	2.50 (63.5)	6.00 (152.4)	3,845 (1,744.06)
145-B	2.50 (63.5)	3.25 (82.6)	6.75 (171.5)	3,987 (1,808.47)
145-C	3.25 (82.6)	4.00 (101.6)	7.50 (190.5)	4,06 (1,841.58)
145-D	4.00 (101.6)	4.75 (120.7)	8.25 (209.6)	4,187 (1,899.19)
145-E	4.75 (120.7)	5.50 (139.7)	9.00 (228.6)	4,37 (1,982.20)
145-F	5.50 (139.7)	6.25 (158.8)	9.75 (247.7)	4,459 (2,022.57)

145 SERIES SPRING ASSEMBLY		
Model No.	Clamping Force Range lb. (kg)	Weight lbs. (grams)
145-2	2,000 (907.2) - 10,000 (4,535.9)	2.01 (911.72)

**Order Guide:**  
Order Crossbar and Spring Assembly separately by type number from table.

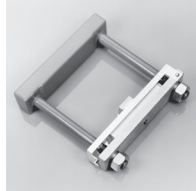
**Dimensions:**  
in. (mm)  
lb. (kg)

#### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

# PRECISION COMPRESSION MOUNTING CLAMP SYSTEMS



## 146 SERIES

COMPRESSION MOUNTING CLAMP ASSEMBLIES FOR SEMICONDUCTORS TO 5.25 IN. (133.5 MM) DIAMETER

**146 SERIES CROSSBAR**  
8,000 lb -16,000 lb (3,628.7 kg - 7,257.4 kg)

Crossbar Device Mounting, Surface to Spring Assembly, Top Surface Dimension

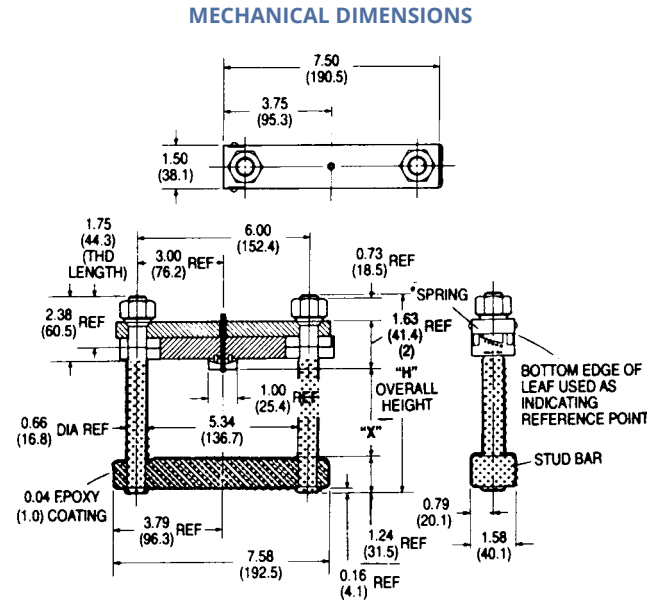
Model No.	"X" Dimension		Overall Height "H" in. (mm)	Weight lbs. (grams)
	Min in. (mm)	Max in. (mm)		
146-A	1.54 (39.1)	2.29 (58.2)	5.92 (150.4)	3.813 (1729.55)
146-B	2.29 (58.2)	3.04 (77.2)	6.67 (169.4)	3.938 (1786.25)
146-C	3.04 (77.2)	3.79 (96.3)	7.42 (188.5)	4.063 (1842.95)
146-D	3.79 (96.3)	4.54 (115.3)	8.17 (207.5)	4.188 (1899.64)
146-E	4.54 (115.3)	5.29 (134.4)	8.92 (226.6)	4.313 (1956.34)
146-F	5.29 (134.4)	6.04 (153.4)	9.67 (245.6)	4.438 (2013.04)
146-G	6.04 (153.4)	6.79 (172.5)	10.42 (264.7)	4.563 (2069.74)

**146 SERIES SPRING ASSEMBLY**

Model Number	Number of Leaves	Clamping Force Range lb. (kg)	Maximum Force lb. (grams)
146-2	2	8,000 (3,628.7) - 16,000 (7,257.5)	2,688 (1,219.26)

**Order Guide:** Order Crossbar and Spring Assembly separately by type number from table.

**Dimensions:** in. (mm) / lb. (kg)

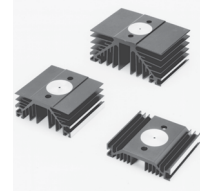


Dimensions: in. (mm)

## 132 & 133 SERIES

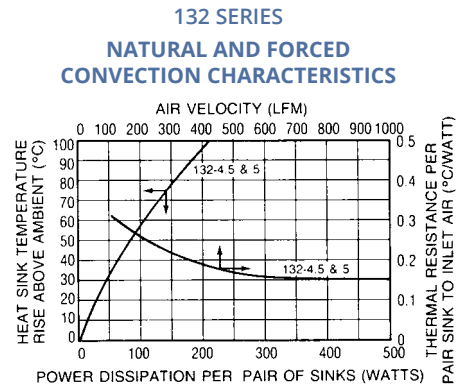
# 132/133 SERIES HIGH-PERFORMANCE HEAT SINKS FOR COMPRESSION TYPE DEVICES

## 132 & 133 SERIES

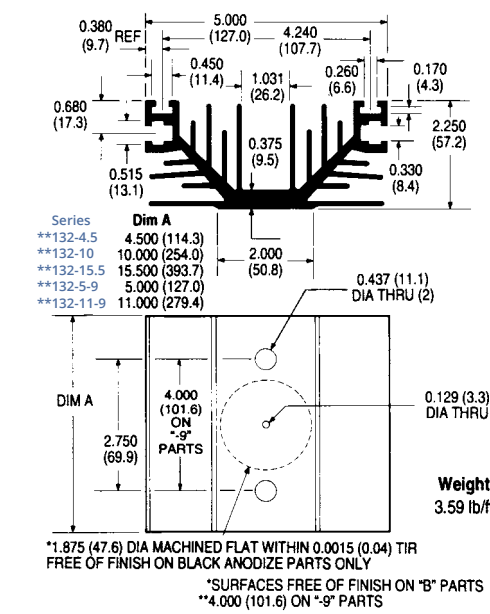


Standard P/N	Black Anodize (4,5)	Gold Iridite	Width in. (mm)	Nominal Dimensions: (1) Length "A" in. (mm)	Height in. (mm)	Clamp System Series (5)	Thermal Performance at Typical Load (2)	
							Natural Convection (°C/W) (3)	Convection (°C/W) @ 500 LFM
132-4.5B	132-4.5G	5.000 (127.0)	4.500 (114.3)	2.250 (57.2)	130	0.61	0.170	
132-10B	132-10G	5.000 (127.0)	10.000 (254.0)	2.250 (57.2)	130	0.38	0.130	
132-15.5B	132-15.5G	5.000 (127.0)	15.500 (393.7)	2.250 (57.2)	130	0.28	0.100	
132-5-B9	132-5-G9	5.000 (127.0)	5.000 (127.0)	2.250 (57.2)	139	0.61	0.170	
132-11-B9	132-11-G9	5.000 (127.0)	11.000 (299.4)	2.250 (57.2)	139	0.37	0.120	
133-4.5B	133-4.5G	7.000 (139.2)	4.500 (114.3)	3.125 (79.4)	130	0.37	0.110	
133-7.5B	133-7.5G	7.000 (139.2)	7.500 (190.5)	3.125 (79.4)	130	0.28	0.085	
133-10B	133-10G	7.000 (139.2)	10.000 (254.0)	3.125 (79.4)	130	0.26	0.082	
133-5-B9	133-5-G9	7.000 (139.2)	5.000 (127.0)	3.125 (79.4)	139	0.37	0.110	
133-7.5-B9	133-7.5-G9	7.000 (139.2)	7.500 (190.5)	3.125 (79.4)	139	0.28	0.085	
133-11-B9	133-11-G9	7.000 (139.2)	11.000 (279.4)	3.125 (79.4)	139	0.24	0.076	

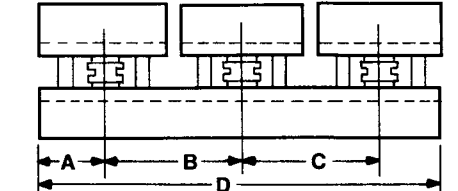
**Material:** Aluminum, Black Anodized  
**Finish:** B = Black Anodized, G = Gold Iridite



**MECHANICAL DIMENSIONS 132 SERIES (EXTRUSION PROFILE 3560-2)**

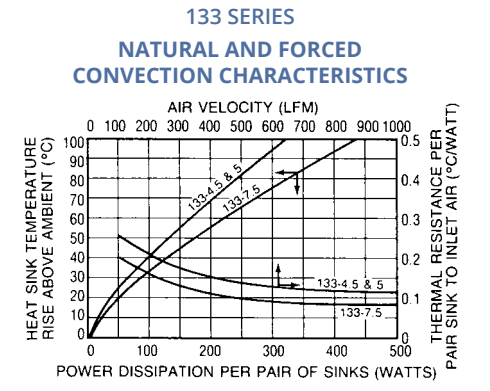


### MULTIPLE ASSEMBLY CONFIGURATION

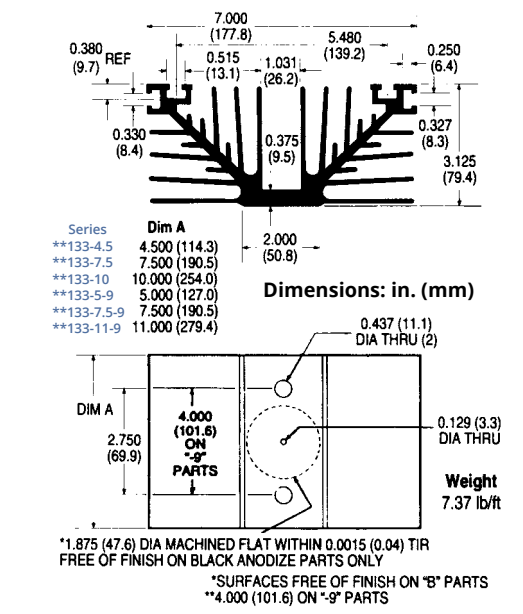


Type	Use with	A	B	C	D
132-4.5	-	-	-	See Fig.132	-
132-10	2 ea 132-4.5	2.25	5.50	-	10.0
132-15.5	3 ea 132-4.5	2.25	5.50	-	15.5
133-4.5	-	-	-	See Fig.133	-
133-7.5	-	-	-	See Fig.133	-
133-10	2 ea 133-4.5	2.25	5.50	-	10.0
132-5-9**	-	-	-	See Fig.132	-
132-11-9**	2 ea 132-5-9	2.50	6.00	-	11.00
133-5-9**	-	-	-	See Fig. 133	-
133-7.5-9**	-	-	-	See Fig. 133	-
133-11-9**	2 ea 133-5-9	2.50	6.00	-	11.00

\*\* -9 indicates heat sinks drilled for 139 clamp.



**MECHANICAL DIMENSIONS 133 SERIES (EXTRUSION PROFILE 3559-2)**



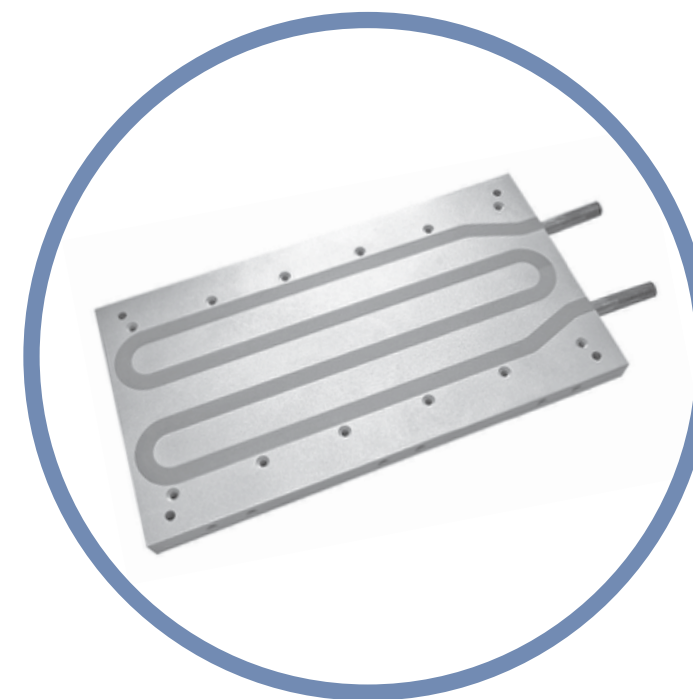
### NOTES:

- Nominal dimensions for one heat sink of this type.
- Thermal performance values shown are per pair of heat sinks.
- Natural convection performance at 50°C heat sink rise above ambient.
- Black anodize finish [1.875 in. (47.6 mm) diameter spot face. Device mounting surface area free of finish].
- Predrilled heat sinks accept 130 and 139 Series clamp systems.

# LIQUID COOLING

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<i>Liquid Cold Plates For High-Performance Components &amp; Systems</i> .....	116–117
<i>Exposed Tube Liquid Cold Plates</i> .....	118–119
<i>Full Buried Tube Liquid Cold Plates</i> .....	120–122



*Liquid cooling is a natural evolution beyond air cooling where either due to thermal requirements or footprint requirements, the desired performance can no longer be economically met by air cooling.*

*There are many ways to accomplish liquid cooling, but the most common method is to have a plate with a flow path that moves liquid under the devices. After the heat is absorbed into the liquid, it is taken out of the plate and into the larger system. While water or water/glycol are the most common fluids used in liquid cooling, gasoline, oil, and refrigerant are other fluids that can be utilized.*

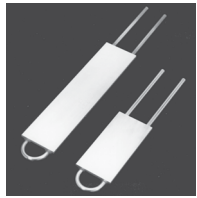
*There are lots of ways to construct a cold plate and the methods can be driven by the level of performance needed, the materials needed or the environmental requirements.*

*One construction method is to use a series of cross drilled holes in a plate. The holes intersect in the plate to determine the flow pattern and unneeded patterns are plugged. This construction method can be cost effective, but the pattern is limited to straight lines.*

*Another method is to embed a tube in a plate by machining a groove in the plate. The tube can either be placed toward the top surface of the plate to provide better cooling to devices mounted on that surface, or it can be embedded further into the plate so that it cools devices mounted on both sides of the plate. This option provides greater flexibility, but the thermal performance is limited because of the surface area of the tube perimeter.*

*To get more performance, extended surface area in contact with the fluid is required and this leads to machined cold plates. The cold plate is constructed of a plate that has been machined to form some flow passages and then a cover is assembled to capture the flow. The extended surface area can be machined in place or installed by use of a piece of folded fin. The cover can be flat or be another machined plate. The method of assembly of the two parts can be done by gasket/screw, glue/screw, brazing, or welding and is dependent on the required performance and the requirements of the environment.*

# LIQUID COLD PLATES FOR HIGH-PERFORMANCE COMPONENTS & SYSTEMS



## 180-10 & 180-11 SERIES

LIQUID COLD PLATES FOR RECTIFIERS AND POWER DIODES

General Purpose

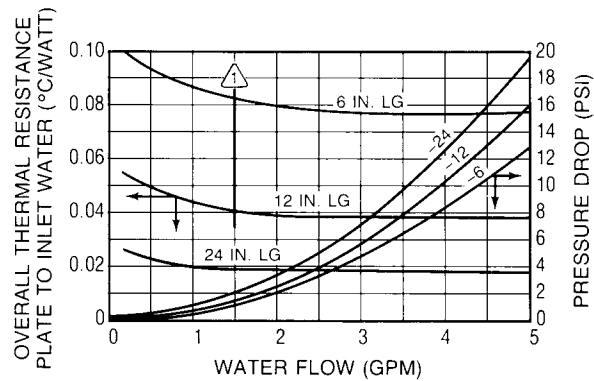
Standard P/N	Cold Plate Body Nominal Dimensions				Overall Length in. (mm)	Overall Thermal Resistance (Plate to Inlet Water)	Weight lbs. (grams)
	Length "A" in. (mm)	Width in. (mm)	Thickness in. (mm)	Channel Width in. (mm)			
180-10-6C	6.000 (152.4)	3.000 (76.2)	0.625 (15.9)	1.250 (31.8)	13.406 (340.5)	0.084°C/W @ 1.5 GPM	0.850 (385.56)
180-10-12C	12.000 (304.8)	3.000 (76.2)	0.625 (15.9)	1.250 (31.8)	19.406 (429.9)	0.041°C/W @ 1.5 GPM	1.700 (771.12)
180-10-24C	24.000 (609.6)	3.000 (76.2)	0.625 (15.9)	1.250 (31.8)	31.406 (797.7)	0.020°C/W @ 1.5 GPM	2.900 (1315.4)
180-11-6C	6.000 (152.4)	5.000 (127.2)	0.688 (17.5)	1.813 (46.1)	13.688 (347.7)	0.084°C/W @ 1.5 GPM	1.500 (680.40)
180-11-12C	12.000 (304.8)	5.000 (127.2)	0.688 (17.5)	1.813 (46.1)	19.688 (500.1)	0.041°C/W @ 1.5 GPM	2.867 (1300.47)
180-11-24C	24.000 (609.6)	5.000 (127.2)	0.688 (17.5)	1.813 (46.1)	31.688 (804.9)	0.020°C/W @ 1.5 GPM	5.730 (2599.13)

Material: Aluminum, no finish. Tubing: Copper (stainless steel tubing available on special order).

### LOCAL THERMAL RESISTANCE PER DEVICE PLATE TO INLET WATER (°C/WATT)

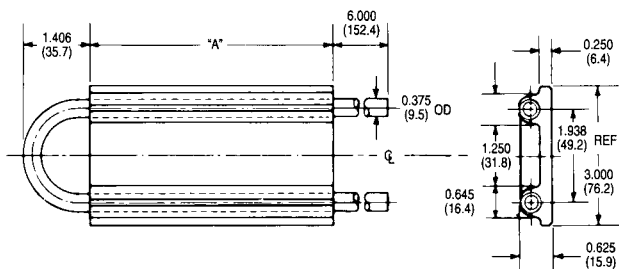
℄ to ℄ Device Spacing Inches	Flow - GPM				
	½	1	2	3	4
1.0 (25.4)	0.59	0.52	0.48	0.47	0.46
2.0 (50.8)	0.40	0.36	0.33	0.32	0.31
3.0 (76.2)	0.29	0.26	0.24	0.23	0.22

### PERFORMANCE CHARACTERISTICS

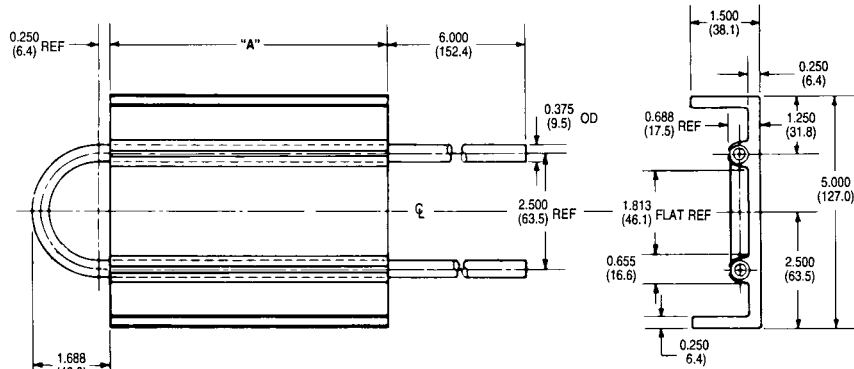


### MECHANICAL DIMENSIONS

#### 180-10 SERIES

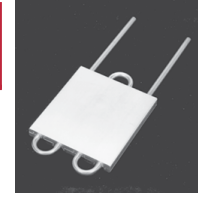


#### 180-11 SERIES



Dimensions: in. (mm)

Standard P/N	Length "A" in. (mm)
180-10-6C	6.000 in. (152.4)
180-10-12C	12.000 in. (304.8)
180-10-24C	24.000 in. (609.6)
180-11-6C	6.000 in. (152.4)
180-11-12C	12.000 in. (304.8)
180-11-24C	24.000 in. (609.6)



General Purpose

LIQUID COLD PLATES FOR RECTIFIERS, DIODES, AND POWER MODULES

## 180-12 & 180-20 SERIES

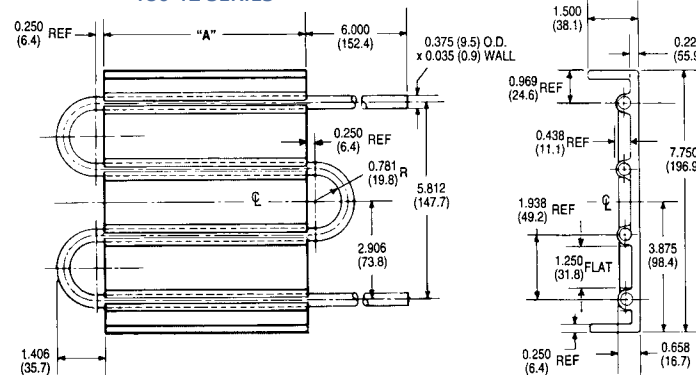
Standard P/N	Cold Plate Body Nominal Dimensions			Mounting Surfaces	Overall Length in. (mm)	Overall Thermal Resistance (Plate to Inlet Water)	Weight lbs. (grams)
	Length "A" in. (mm)	Width in. (mm)	Thickness in. (mm)				
180-12-6C	6.000 (152.4)	7.750 (196.9)	0.658 (16.7)	Single	13.406 (340.5)	0.038°C/W @ 1.0 GPM	2.270 (1029.67)
180-12-12C	12.000 (304.8)	7.750 (196.9)	0.658 (16.7)	Single	19.406 (429.9)	0.018°C/W @ 1.0 GPM	4.300 (1950.48)
180-12-24C	24.000 (609.6)	7.750 (196.9)	0.658 (16.7)	Single	31.406 (797.7)	0.009°C/W @ 1.0 GPM	8.600 (3900.96)
180-20-6C	6.000 (152.4)	5.500 (139.7)	0.690 (17.5)	Double	13.125 (333.4)	0.038°C/W @ 1.0 GPM	1.090 (494.42)

### LOCAL THERMAL RESISTANCE PER DEVICE PLATE TO INLET WATER (°C/WATT)

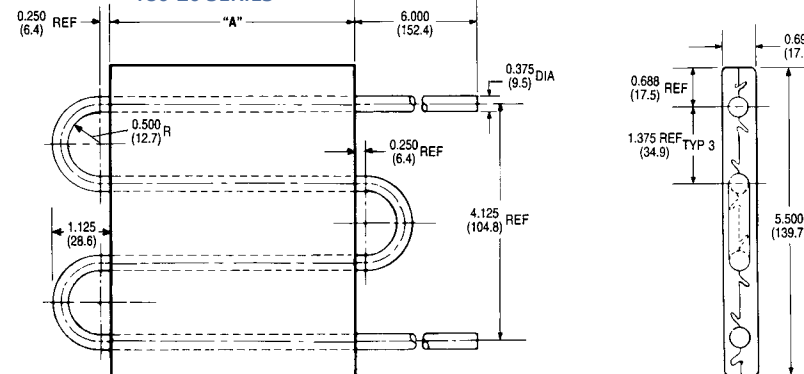
℄ to ℄ Device Spacing Inches	Flow - GPM				
	½	1	2	3	4
1.0 (25.4)	0.76	0.67	0.62	0.59	0.57
2.0 (50.8)	0.58	0.49	0.43	0.40	0.39
3.0 (76.2)	0.42	0.34	0.30	0.28	0.27

### MECHANICAL DIMENSIONS

#### 180-12 SERIES

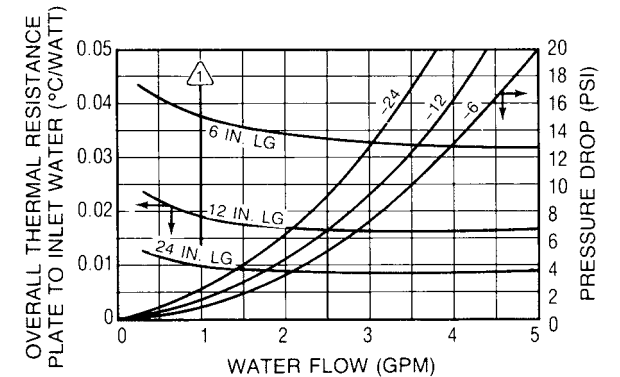


#### 180-20 SERIES



Dimensions: in. (mm)

### PERFORMANCE CHARACTERISTICS



△ = RECOMMENDED MAXIMUM FLOW

Standard P/N	Length "A" in. (mm)
180-12-6C	6.000 in. (152.4)
180-12-12C	12.000 in. (304.8)
180-12-24C	24.000 in. (609.6)
180-20-6C	6.000 in. (152.4)

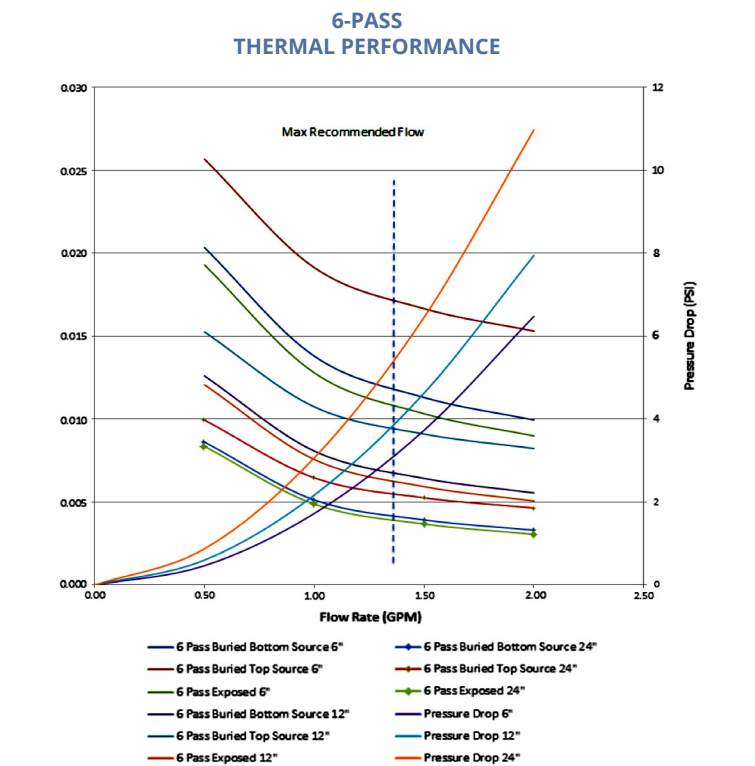
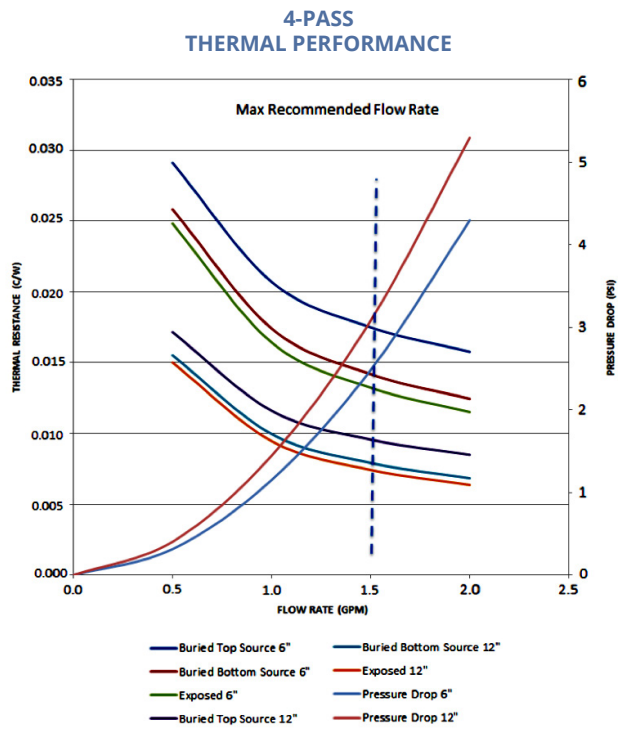
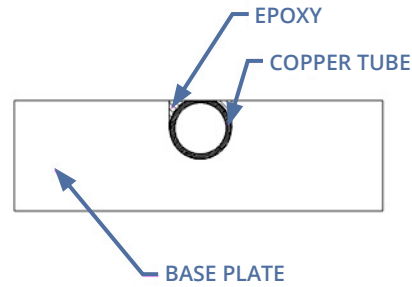
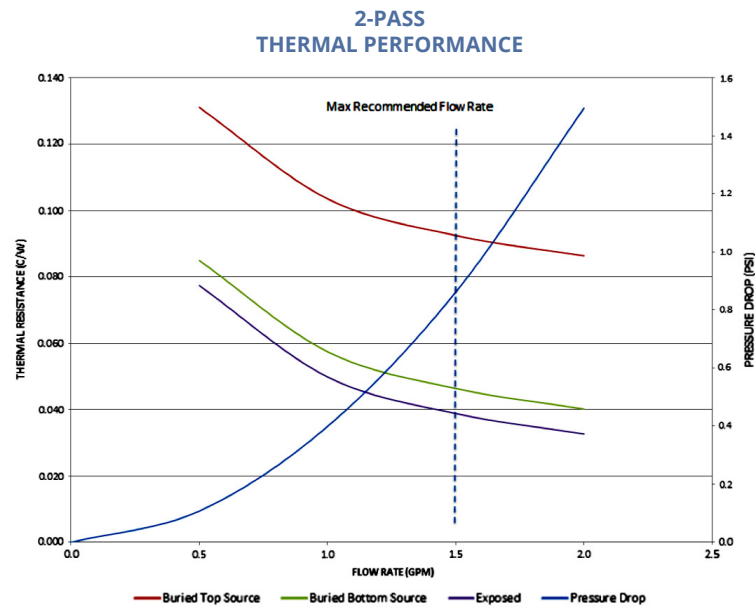
# EXPOSED TUBE LIQUID COLD PLATES

Wakefield-Vette's exposed tube liquid cold plates ensure minimum thermal resistance between the power device and the cold plate by placing the coolant tube in direct contact with the power device's base. Direct contact reduces the number of thermal interfaces between device and fluid thus increasing performance for the application.

Part Number	Description	"X" Dimension Inches	Passes	Figure
120455	Exposed Tube 2- Pass Cold plate	N/A	2	1
120456	Exposed Tube 4- Pass Cold plate	6.00	4	2
120457	Exposed Tube 4- Pass Cold plate	12.00	4	2
120458	Exposed Tube 6- Pass Cold plate	6.00	6	3
120459	Exposed Tube 6- Pass Cold plate	12.00	6	3
120460	Exposed Tube 6- Pass Cold plate	24.00	6	3

**KEY SPECIFICATIONS**

- Base Plate: Extruded Aluminum.
- Copper Tube Material: .0375" OD x .049" wall.
- Thermal Epoxy fill with high thermal conductivity.

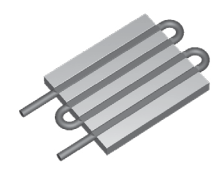
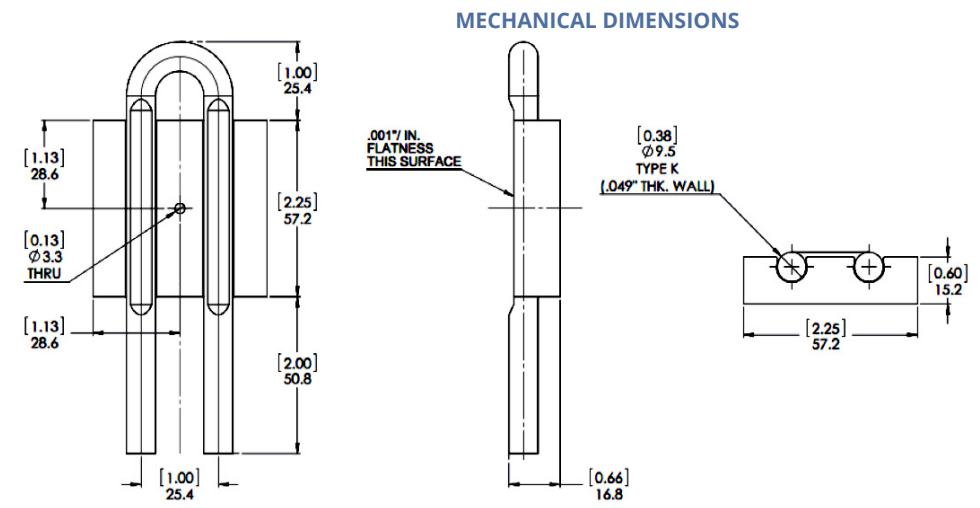
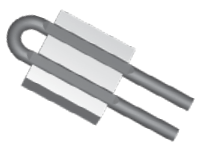


**Custom Exposed Tube  
Liquid Cold Plates Available**

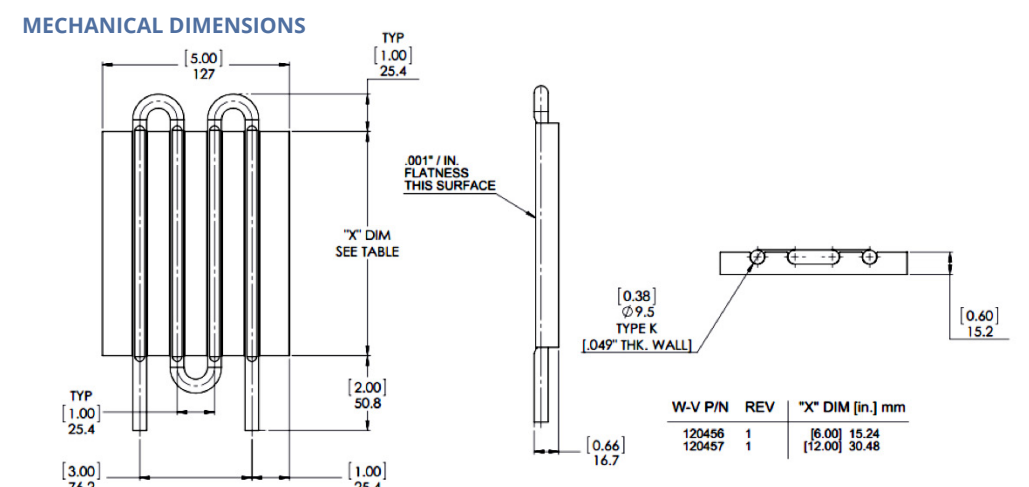
Contact Wakefield-Vette for more information  
or visit [www.wakefield-vette.com](http://www.wakefield-vette.com)



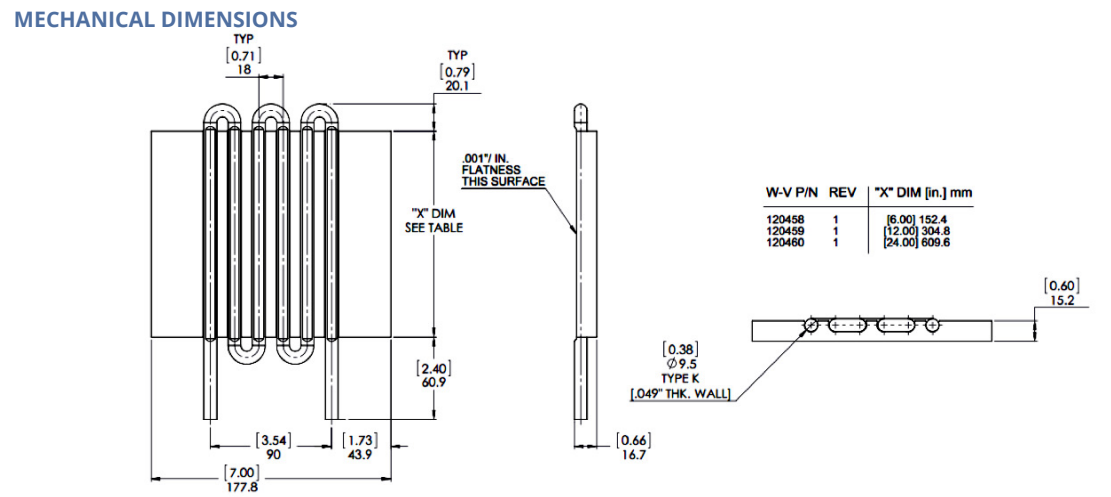
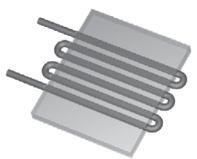
## PART NUMBER 120455



## PART NUMBER 120456 & 120457



## PART NUMBER 120458, 120459, & 120460

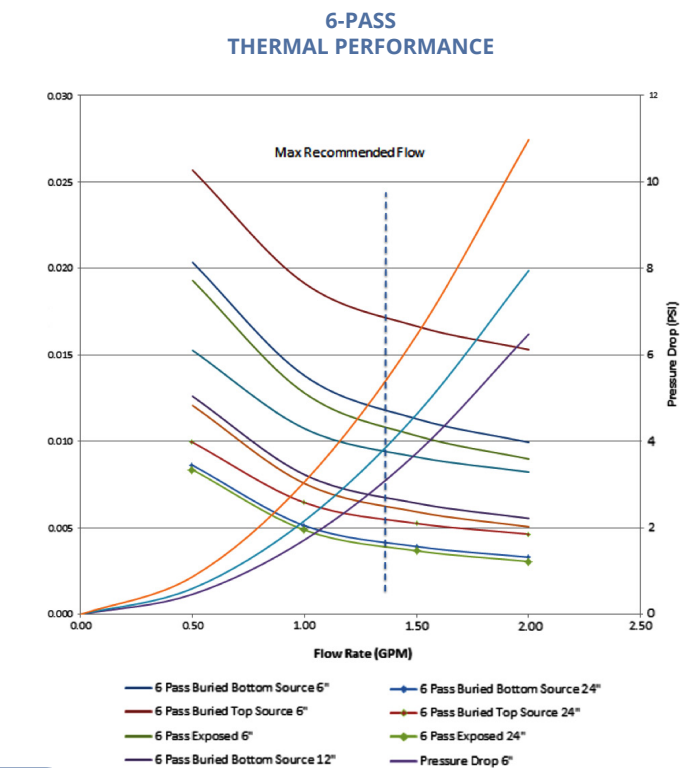
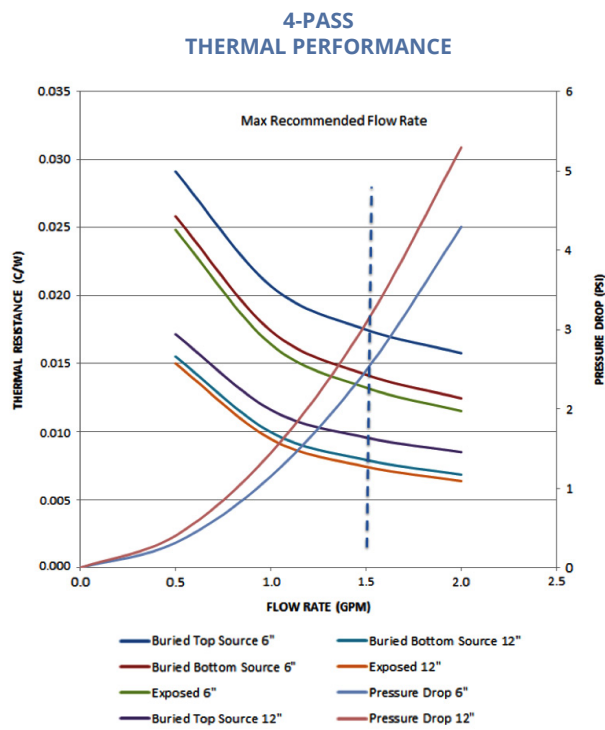
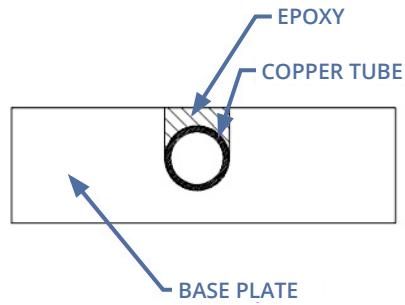
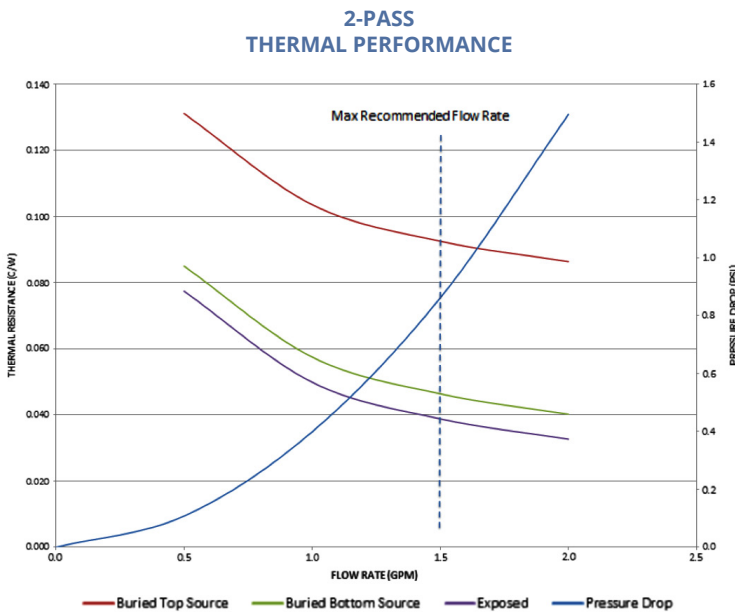


# FULL BURIED TUBE LIQUID COLD PLATES

Wakefield-Vette's fully buried tube liquid cold plates have the ability to cool both sides of the cold plate because of it's positioning within the base plate. Another key feature of the fully buried tube is that it is not exposed to the outside environment. Some engineers prefer the epoxy layer above the tube to protect the tube from leakage.

Part Number	Description	"X" Dimension Inches	Passes	Figure
120959	Fully Buried Tube 2- Pass Cold plate	N/A	2	1
120960	Fully Buried Tube 4- Pass Cold plate	6.00	4	2
120961	Fully Buried Tube 4- Pass Cold plate	12.00	4	2
120962	Fully Buried Tube 6- Pass Cold plate	6.00	6	3
120963	Fully Buried Tube 6- Pass Cold plate	12.00	6	4
120964	Fully Buried Tube 6- Pass Cold plate	24.00	6	5

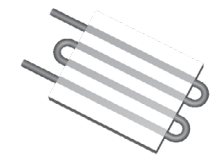
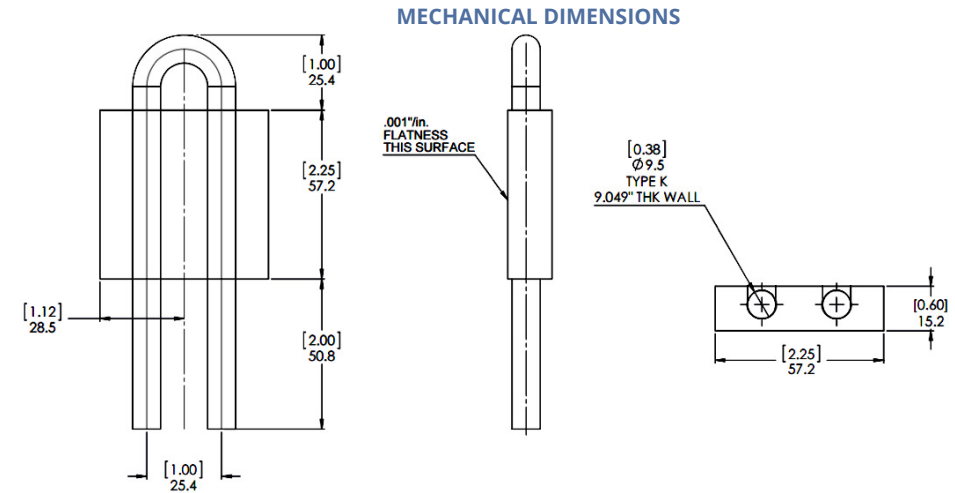
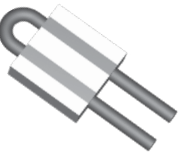
KEY SPECIFICATIONS	
• Base Plate: Extruded Aluminum.	
• Copper Tube Material: .0375" OD x .049" wall.	
• Thermal Epoxy fill with high thermal conductivity.	



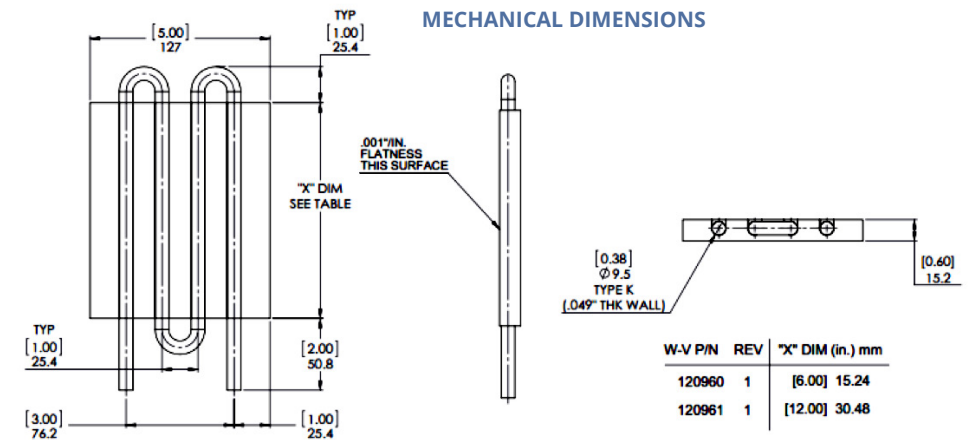
**Custom Full Buried Tube Liquid Cold Plates Available**  
 Contact Wakefield-Vette for more information or visit [www.wakefield-vette.com](http://www.wakefield-vette.com)



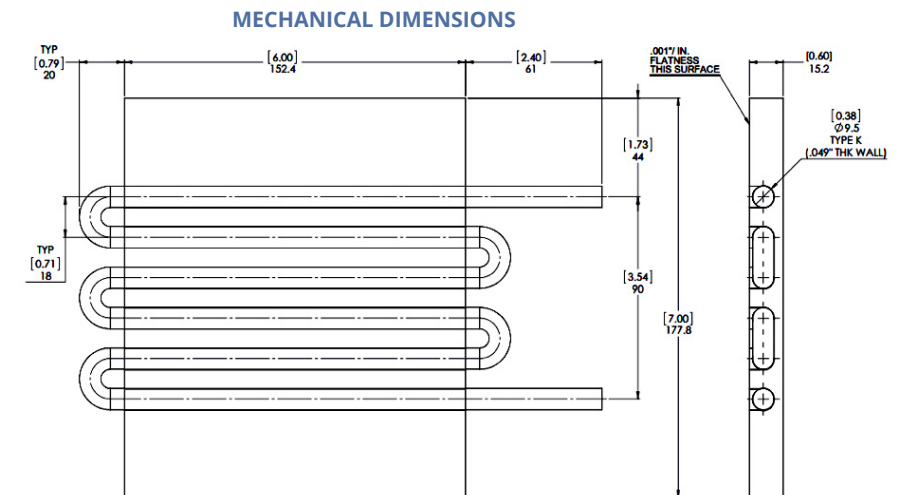
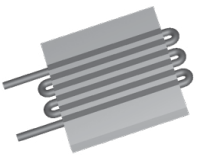
## PART NUMBER 120959



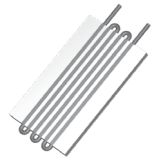
## PART NUMBER 120960 & 120961



## PART NUMBER 12062



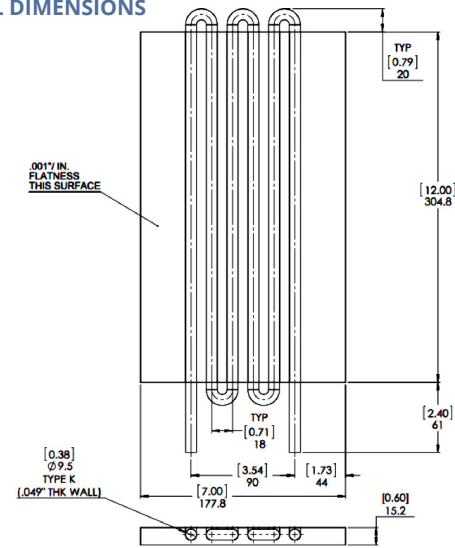
# FULL BURIED TUBE LIQUID COLD PLATES



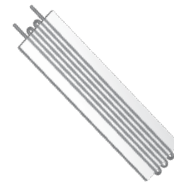
**PART NUMBER 120963**



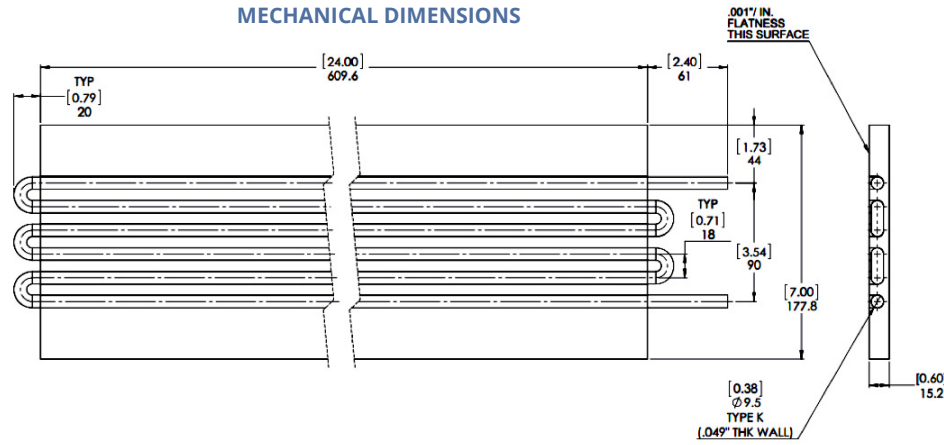
MECHANICAL DIMENSIONS



**PART NUMBER 120964**

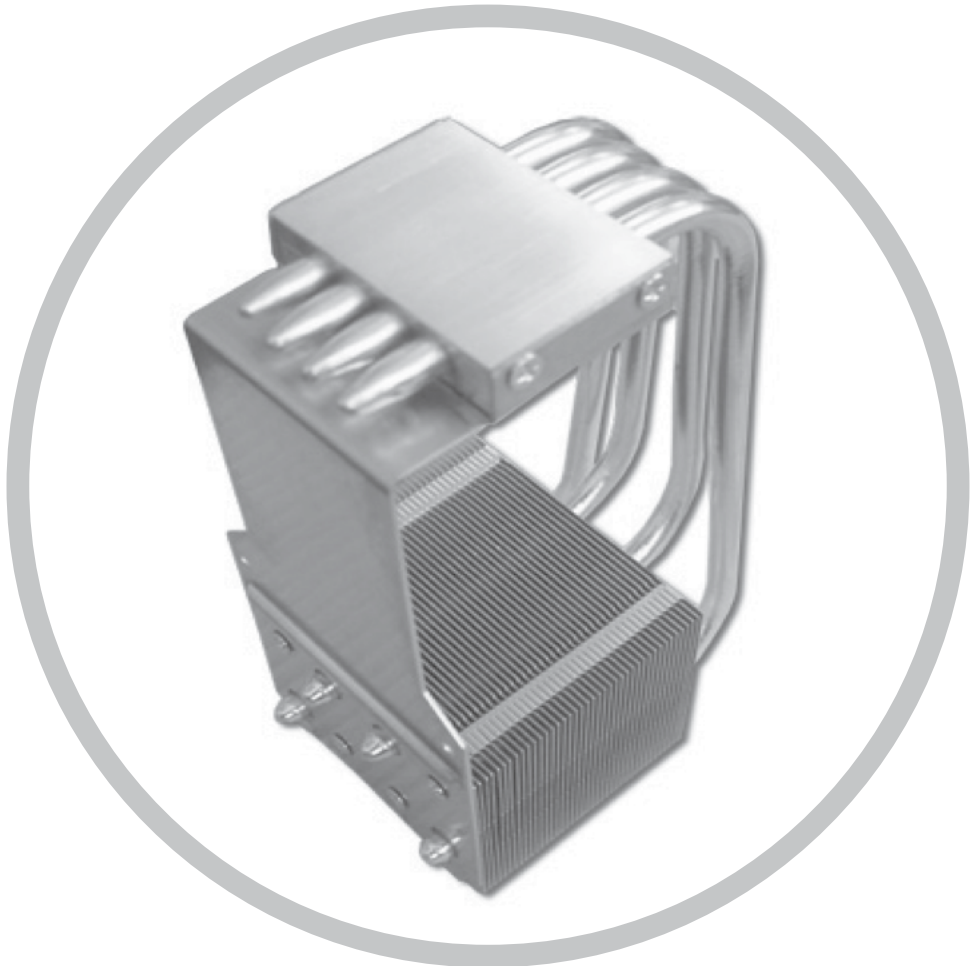


MECHANICAL DIMENSIONS



# PHASE CHANGE

*Heat Pipe Selection Guide* ..... 126-131  
*Vapor Chamber Design Guide* ..... 132-137



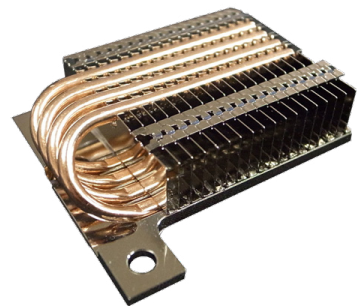
*Fluid Phase Change applications, often referred to as “re-circulating,” use closed loop heat pipes to transfer heat quickly through evaporation and condensation within the heat pipe. Because of their high thermal efficiency, heat pipes are often designed into advanced heat sink technologies when increased thermal density or physical size restrictions exist. This similar process is utilized in vapor chamber technology as well.*



## HEAT PIPE SELECTION GUIDE

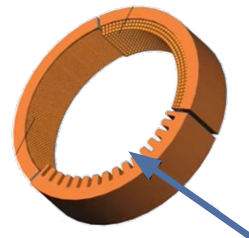
### HEAT PIPE INTRODUCTION

Heat pipes are used to transport heat over a distance with very low thermal resistance. This is very helpful when small or distant heat sources need to be dissipated over a larger area or moved to a remote heat exchanger. Heat pipes are a **Fluid Phase Change application**, often referred to as “re-circulating,” because they use a closed loop to transfer heat quickly through evaporation and condensation within the heat pipe.

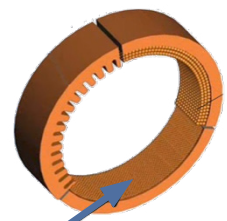


Heat pipes do not actually dissipate the heat to the environment, but serve to move heat efficiently within a thermal system. A heat pipe is a copper tube with an internal wick structure that is sealed on both ends with a small amount of water inside. As heat is applied to the pipe, the water will boil and turn to a gas, which then travels to the colder section of the heat pipe where it condenses back to a liquid. It is the evaporating and condensing of the water that form a pumping action to move the water (and thus the heat) from end to end of the pipe. There are many types of wick structure that can be used within the heat pipe and they are generally classified into grooved, mesh, powder and hybrid.

A **grooved heat pipe** is a copper tube with a series of shallow grooves around the internal perimeter of the heat pipe. While the water is a liquid, it travels in the grooves and while it is a vapor it travels in the open space of the pipe. Grooved pipes can be used in horizontal orientations, but are very limited in performance if used above 15° out of horizontal.



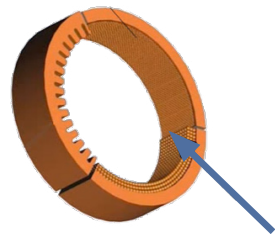
GROOVED HEAT PIPE



MESH HEAT PIPE

A **mesh heat pipe** is a smooth wall copper tube with a woven copper mesh installed along the interior of the pipe. The mesh is designed to remain in contact with the walls of the pipe in areas where the pipe may be bent or flattened. Mesh pipes can be used in horizontal and orientations up to 30° out of horizontal.

A **powder wick heat pipe** can also be known as a **sintered heat pipe**. During the manufacturing process a mandrel is installed in the center of the pipe and copper powder is poured into the pipe around the mandrel. After the powder is sufficiently packed, the parts are placed into a sintering oven. Once at temperature, the copper powder will stick to the pipe and to itself, forming numerous internal pockets like a sponge. Because of the small pocket sizes, sintered pipes can efficiently move the water and can be used horizontally, vertically and all points in between including upside down.



POWDER WICK HEAT PIPE

Wakefield-Vette primarily sells sintered, or powder, style heat pipes due to their higher performance and the best heat pipe for your application.

### WHY USE HEAT PIPES?

Heat pipes have proven to be robust and reliable over many years in these types of applications. The next section will give more technical detail on the performance of heat pipes depending on diameter, length, and angle of use. Many thermal systems benefit from the addition of heat pipes, especially when heat sources are dense and/or remote to the final heat exchanger. Computer applications, such as processors, graphics cards and other chip-sets, have high thermally dissipated power in a small area. Fan heat sink combinations used in these applications can offer high-performance dissipation to the ambient, but much of the battle is to bring the heat to the heat exchanger with as little temperature change as possible. Heat pipes excel at this and can transport large heat loads from small areas with very little temperature difference.

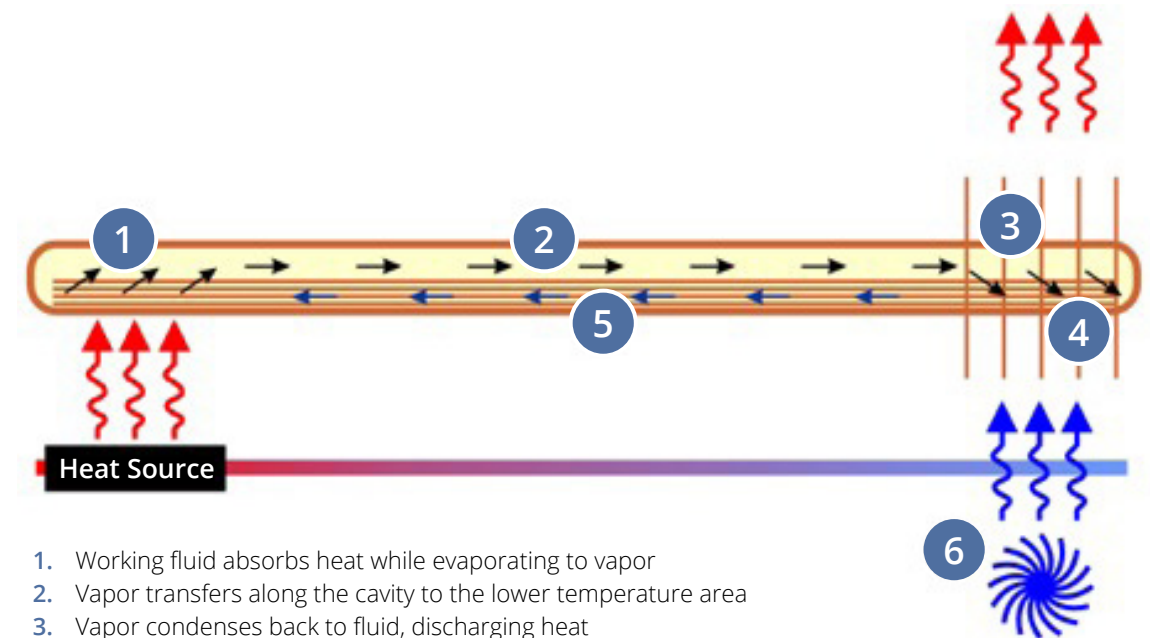
Heat pipes are used in many harsh environments such as:

- Telecommunications
- Aerospace
- Transportation
- Computers and Data Centers

#### KEY FEATURES

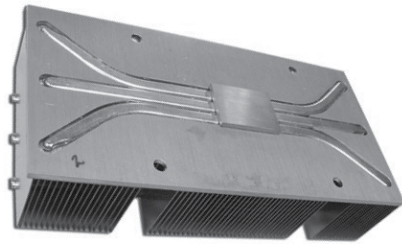
- Material: Copper
- Wick Structure: Powder Sintered Copper
- Light Weight
- Versatile with high thermal performance

### HOW HEAT PIPES OPERATE



1. Working fluid absorbs heat while evaporating to vapor
2. Vapor transfers along the cavity to the lower temperature area
3. Vapor condenses back to fluid, discharging heat
4. Fluid is absorbed by the sintered/powdered wick structure
5. Fluid returns to high temperature end via capillary force in the wick structure
6. Natural or forced convection air flow dissipates excess heat to ambient

# HEAT PIPE SELECTION GUIDE



## HEAT PIPE BASICS

When selecting the diameter and length of heat pipe it is important to consider the orientation with respect to gravity and overall heat load for the thermal system. The transport of vapor within the heat pipe is responsible for the thermal conduction from one end to the other. A larger diameter heat pipe can transport more vapor, translating into a larger heat carrying capacity. Also, the orientation of the pipe with respect to gravity plays a role in the thermal capacity of a heat pipe.

### HEAT PIPE BASICS

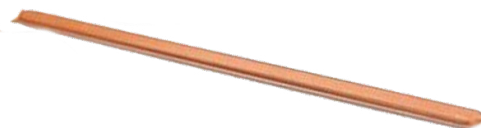
- Picking the correct pipe
- Transport
- General parameters
- Bending
- Flattening

When selecting the diameter and length of heat pipe it is important to consider the orientation with respect to The thermal capacity is increased when the heat source is lower than the condenser (or ambient heat exchanger) because gravity assists the return of condensed water back to the heat source. The opposite is also true as the thermal capacity is reduced when the condensed water must move by capillary forces back to the heat source against gravity. This effect is exaggerated with longer heat pipes and testing has shown that the gravity effect can nearly the double the thermal capacity in the advantageous direction and cut the capacity in half in the deleterious direction from the heat pipe in the horizontal orientation. In the short heat pipe extreme (3"-4" length), this effect is nearly zero, so please consult with Wakefield-Vette engineers to find the right solution for your application.

MAXIMUM HEAT TRANSFER TABLE (POWDER TYPE)		HEAT PIPE LENGTH = 150MM			
Qmax Type	Out Diameter Φ3mm	Out Diameter Φ4mm	Out Diameter Φ5mm	Out Diameter Φ6mm	Out Diameter Φ8mm
Flatten t=2.0mm	13.2 W	16.6 W	20.5 W		
Flatten t=2.5mm	13.2 W	19.8 W	23.6 W	34.0 W	51.5 W
Flatten t=3.0mm	13.1 W	19.8 W	28.4 W	39.2 W	67.5 W
Round Pipe	13.2 W	19.8 W	30.1 W	48.1 W	74.2 W



MAXIMUM HEAT TRANSFER TABLE (POWDER TYPE)		HEAT PIPE LENGTH = 250MM			
Qmax Type	Out Diameter Φ3mm	Out Diameter Φ4mm	Out Diameter Φ5mm	Out Diameter Φ6mm	Out Diameter Φ8mm
Flatten t=2.0mm	7.2 W	10.1 W	12.2 W		
Flatten t=2.5mm	8.1 W	11.2 W	13.1 W	16.5 W	23.0 W
Flatten t=3.0mm	8.2 W	12.1 W	14.1 W	22.0 W	37.0 W
Round Pipe	9.0 W	12.3 W	15.6 W	29.3 W	45.0 W



## FLATTENING HEAT PIPES



Flattening is another aspect of heat pipes that effect their performance. Often it is necessary to flatten a heat pipe to fit into a desired shape or gap or to increase the contact area of the pipe with the heat. Since flattening reduces the effective cross-sectional area of the round pipe, the thermal capacity is reduced, just as if a smaller diameter pipe was being used. The larger diameter of the starting heat pipe, the larger reduction of thermal capacity is seen when flattening. Also, the larger diameter pipes cannot be flattened to the same ultimate dimension as the smaller pipes without disrupting heat flow altogether. This is also true for bending of pipes. The radius of bending is usually 3-5x the diameter of the heat pipe depending on the pipe diameter and the process of bending the pipe. The potential danger is to collapse the pipe, effectively cutting off vapor and thermal transport.

SIZE OF FLATTED HEAT PIPES			
Diameter (mm)	Thickness (mm)	Width (mm)	Tolerance (mm)
4mm	3	4.65	+/- 0.15
	2.5	5	+/- 0.15
	2	5.23	+/- 0.15
5mm	3.5	5.97	+/- 0.15
	3	6.25	+/- 0.15
	2	6.83	+/- 0.15
6mm	4	7.3	+/- 0.15
	3.5	7.58	+/- 0.15
8mm	6	9.35	+/- 0.15
	5	9.95	+/- 0.15
	4	10.5	+/- 0.15
	3	10.99	+/- 0.15

*Bending radius for heat pipes of different diameters depending on the method of bending.*

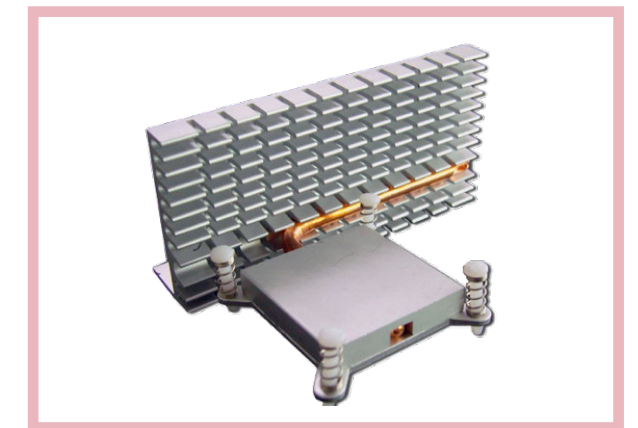
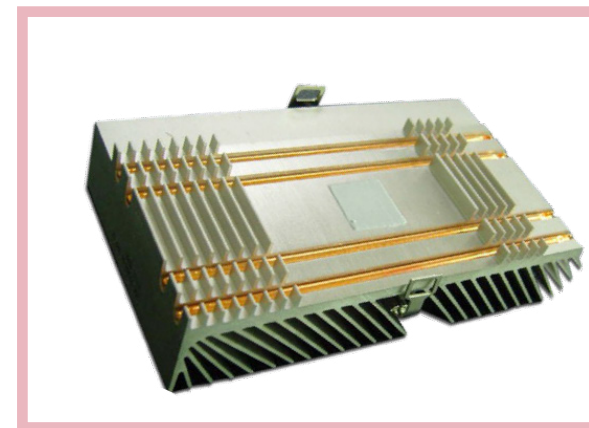
### BENDING

#### By Hand:

- 4mm: 4 x diameter
- 6mm: 4 x diameter
- 8mm: 5 x diameter

#### Tooling:

- 4mm: 3 x diameter
- 6mm: 3 x diameter
- 8mm: 4 x diameter

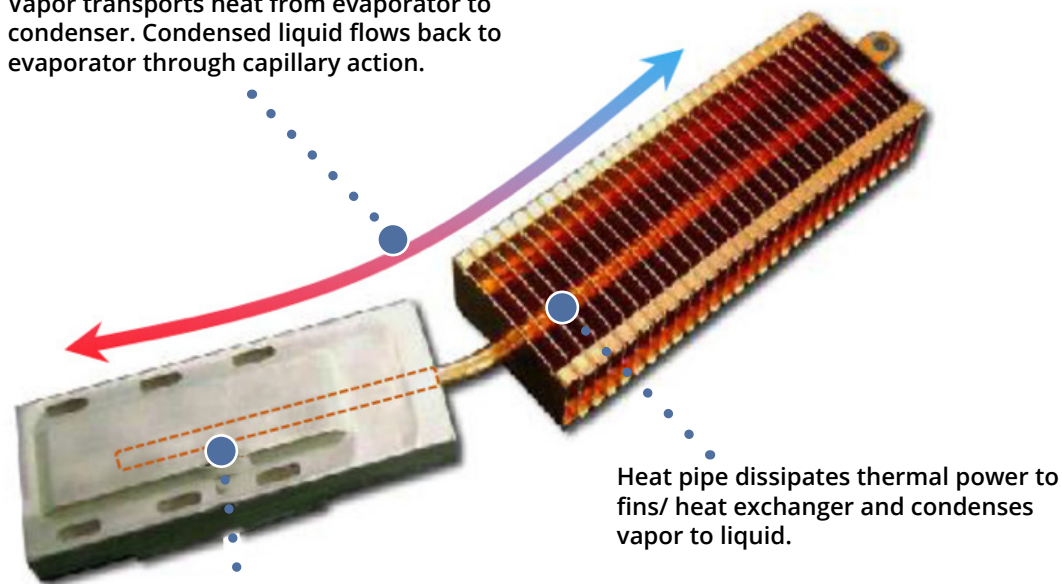


## HEAT PIPE SELECTION GUIDE

### HEAT PIPE ASSEMBLIES

Interfacing heat pipes with plates and heat exchangers is predominately about maximizing contact area while adhering to the flattening and bending guidelines mentioned above. In most cases, the heat pipes are slotted into channels/grooves in the plate to maximize contact. The heat pipe can be secured into the groove using solder or thermal epoxy, which also augments the contact area of the heat pipe. The heat pipe can also be clamped between two plates with matching channels/grooves which are fastened together. In the clamped configuration, thermal grease can be used to increase the contact of the heat pipe to the plates to reduce the thermal resistance of the contact interface, just as the thermal epoxy and solder did in the prior example.

Vapor transports heat from evaporator to condenser. Condensed liquid flows back to evaporator through capillary action.



Embedded heat pipe in plate absorbs heat through vaporization of liquid.

Heat pipe dissipates thermal power to fins/ heat exchanger and condenses vapor to liquid.

### WAKEFIELD-VETTE STANDARD HEAT PIPES

Wakefield-Vette offers individual Heat Pipes through distribution. These most common offerings are a great option for testing, sampling, and validating your heat pipe solution into eventual production.

When building or testing your heat sink assembly please feel free to contact one of Wakefield Vette's authorized distributors to purchase. Always remember to contact us for free consultation on assembly design or parameter questions.

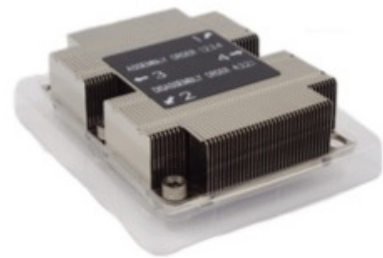
Wakefield-Vette Part Number	Description
121686	Round Heat Pipe 4 x 70mm
121687	Round Heat Pipe 4 x 100mm
121688	Round Heat Pipe 4 x 150mm
110578	Round Heat Pipe 6 x 100mm
110579	Round Heat Pipe 6 x 150mm
110580	Round Heat Pipe 6 x 200mm
110581	Round Heat Pipe 6 x 250mm
110582	Round Heat Pipe 6 x 300mm
121968	Round Heat Pipe 8 x 100mm
110583	Round Heat Pipe 8 x 200mm
110584	Round Heat Pipe 8 x 250mm
110585	Round Heat Pipe 8 x 300mm
121689	Round Heat Pipe 10 x 100mm
121690	Round Heat Pipe 10 x 200mm
121691	Round Heat Pipe 10 x 250mm
121692	Round Heat Pipe 10 x 300mm
121716	Flat Heat Pipe 2.5 x 100mm
121717	Flat Heat Pipe 2.5 x 150mm
121718	Flat Heat Pipe 2.5 x 200mm
121719	Flat Heat Pipe 2.5 x 250mm
121720	Flat Heat Pipe 3 x 100 mm
121721	Flat Heat Pipe 3 x 150 mm
121722	Flat Heat Pipe 3 x 200 mm
121723	Flat Heat Pipe 3 x 250 mm
121724	Flat Heat Pipe 3 x 300 mm
121725	Flat Heat Pipe 4.5 x 100mm
121726	Flat Heat Pipe 4.5 x 150 mm
121727	Flat Heat Pipe 4.5 x 200 mm
121728	Flat Heat Pipe 4.5 x 250 mm
121729	Flat Heat Pipe 4.5 x 300 mm
120231	Ultra Thin 6MM DIA X 1.50MM
120229	Ultra Thin 5MM DIA X 1.00MM

## VAPOR CHAMBER DESIGN GUIDE

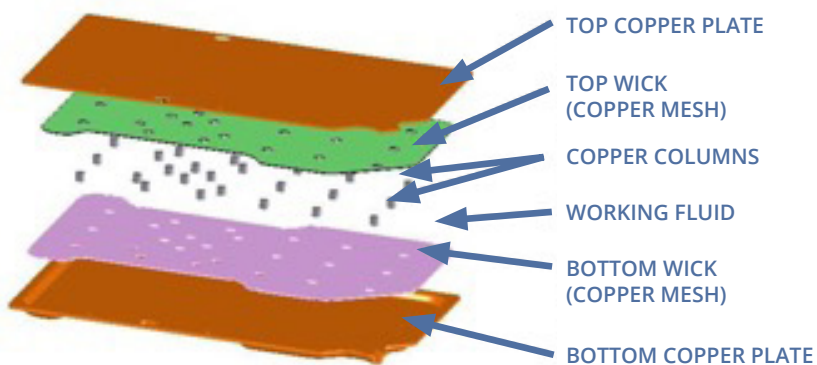
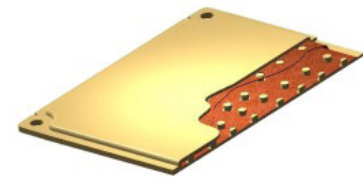
### VAPOR CHAMBER INTRODUCTION

**Vapor Chambers** are used to transport heat over a distance with very low thermal resistance. This is very helpful when small heat sources need to be dissipated over a larger area. Vapor chambers are a **Fluid Phase Change application** because they use a closed loop to transfer heat quickly through evaporation and condensation within the chamber. The particular aspect useful in designs is that vapor chambers transport heat in a plane, more effectively "spreading heat" compared to a heat pipe which transports heat over a distance in a straight line.

Vapor chambers, like heat pipes, do not actually dissipate the heat to the environment, but serve to move heat efficiently within a thermal system. A vapor chamber is made from copper plates (top and bottom) with an internal wick structure that is sealed around the perimeter with a small amount of water inside. As heat is applied to the chamber, the water will boil and turn to a gas, which then travels to the colder section of the vapor chamber, where heat is dissipated through an external heat exchanger, where it condenses back to a liquid. It is the evaporating and condensing of the water that form a pumping action to move the water (and thus the heat) from the area of the heat source to all other areas of the vapor chamber.



There are a few types of wick structure that can be used within the vapor chamber, but most commercial chambers are classified as mesh or powder. In both cases, the powder or mesh line the copper plate surfaces to allow water flow to/from all directions within the area of the vapor chamber. Often, when mesh is used as the wick structure, different sized meshes are used together to promote condensation or transport of liquid depending on the void size. Vapor chambers are best used in horizontal orientations. The effects of gravity may vary depending on application and orientation, but one must consider lower performance if used above 15° out of horizontal.



During the manufacturing process copper columns are used throughout the vapor chamber to support the plates that act as the lids and contain the liquid and vapor. The copper mesh is oriented within the chamber pressed against the copper plates. The plates are sealed around the perimeter via diffusion bonding. In some cases, soldering or welding are used, but diffusion bonding allows for the strongest and highest temperature compatible seal for the vapor chamber. The diffusion bonding process also allows the mesh to bond to the copper plates as well.

### WHY USE VAPOR CHAMBERS?

Vapor chambers have proven to be robust and reliable over many years in these types of applications. The next section will give more technical detail on the performance of vapor chambers depending on thickness and area. Many thermal systems benefit from the addition of vapor chambers, especially when heat sources are dense and the final heat exchanger is much larger and the heat from the source must be spread to a larger area effectively to efficiently use the heat exchanger. Computer applications, such as processors, graphics cards and other chip-sets, have high thermally dissipated power in a small area. Fan heat sink combinations used in these applications can offer high-performance dissipation to the ambient, but much of the battle is to spread the heat to the heat exchanger with as little temperature change as possible. Vapor chambers excel at this and can transport large heat loads from small areas with very little temperature difference.

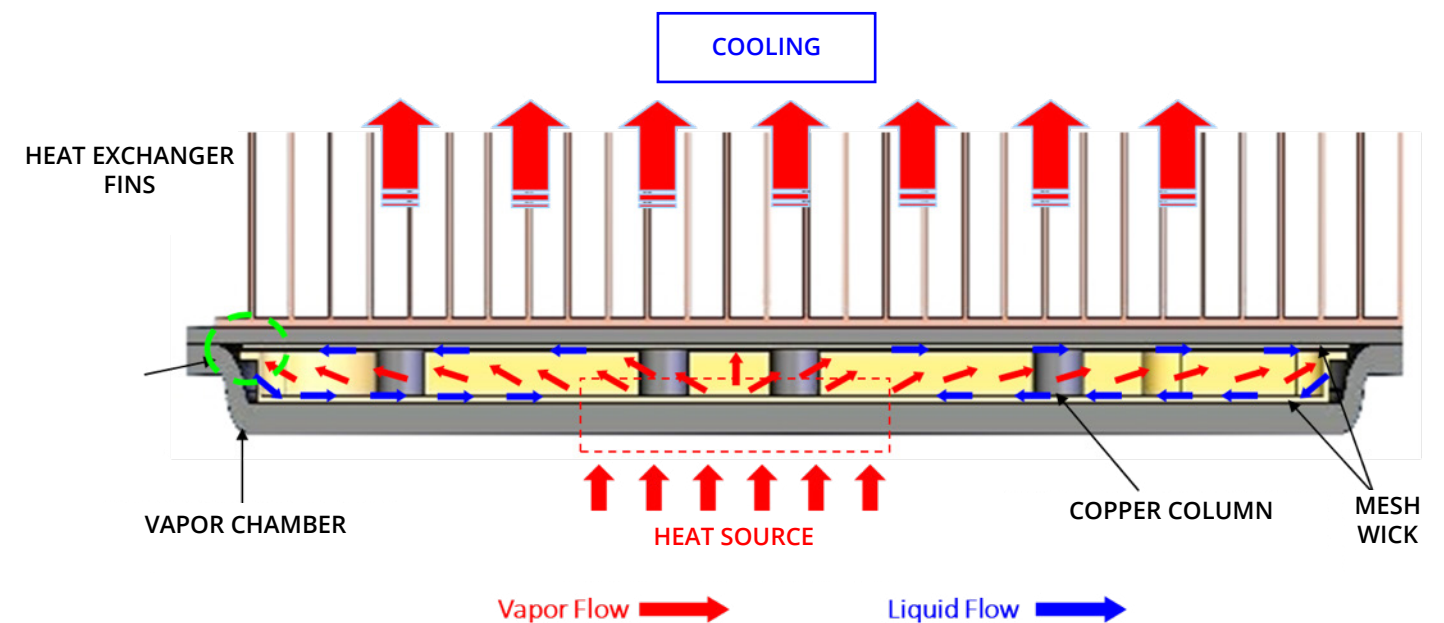
#### Vapor chambers are used in many harsh environments such as:

- Computers and Data Centers
- Telecommunications
- Aerospace
- Transportation

#### KEY FEATURES

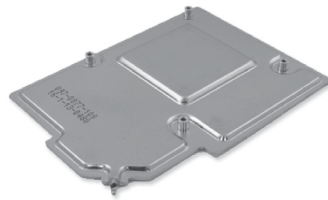
- Material: Copper
- Wick Structure: Copper Mesh
- Light Weight
- Versatile with high thermal performance

### HOW VAPOR CHAMBERS OPERATE



# VAPOR CHAMBER DESIGN GUIDE

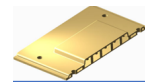
## VAPOR CHAMBER BASICS



When considering the use of a vapor chamber in your application, it is important to consider the orientation with respect to gravity and overall heat load for the thermal system. The transport of vapor within the vapor chamber is responsible for the thermal conduction from one area to the other. A thicker vapor chamber can transport more vapor, translating into a larger heat carrying capacity. Although vapor chambers can have complex shapes and mounting features, they are not typically bent and integration can be more direct with the heat source than with heat pipes.

### VAPOR CHAMBER BASICS

- Comparison to Heat Pipes
- Transport
- General parameters

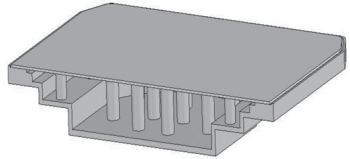


VAPOR CHAMBER		HEAT PIPE
2-Phase heat transfer	Theory	2-Phase heat Transfer
2-D heat distribution. Spreading heat by a single vapor chamber. Suitable for large heat flux and high power.	Application	1-D heat distribution. Using one or more heat pipes to spread heat. Suitable for long distance between heat source and heat exchanger.
Complex shape in X and Y direction with pedestal.	Shape	Round, flattened or bent in any direction.
Mounted with through-holes in vapor chamber	Fixtures	Additional fixture plates needed to mount heat pipes.
Direct contact. Mounting pressure to 90PSI	Heat Source Contact	A base plate required to contact the heat source unless flattened/machined.
T=5mm > 400W; T=3mm > 200W; T=1mm > 60W	Qmax	Ø5 > 20W; Ø6 > 40W; Ø8 > 60W
Vapor chamber has larger tooling cost so high volume applications can lower cost to ~2X heat pipe. However, solution may need only 1 vapor chamber compared to many heat pipes and fixture/base plates.	Cost	Lower cost for a single heat pipe, but may also need tooling cost for bending/flattening.

In many applications, the decision to use a vapor chamber is frequently compared to a thermal solution using heat pipes. In both cases, 2-phase transport is used as a vapor moves heat within the chamber or pipe and the liquid is condensed at the heat exchanger and transported back to the heat source. However, the main aspects of applications that differentiate vapor chambers from heat pipes are:

- **High power density:** when the heat source is small but heat generation is large, vapor chambers can more easily transport the heat to a larger area. A heat pipe solution would require multiple pipes, which may be difficult to integrate within the footprint of the heat source.
- **High power:** when the application must dissipate large wattage, a vapor chamber spreads the heat to a large area efficiently with similar temperatures of the chamber surface. This allows more efficient use of the final heat exchanger since hot spots are minimized. Heat pipes can also spread the heat, but unless many are ganged together, the hot spots may still persist.

## VAPOR CHAMBERS THERMAL CAPACITY

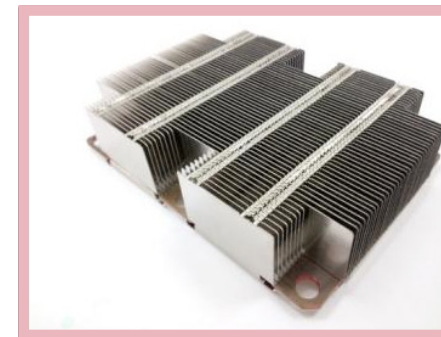


Much like heat pipes, the ultimate dimension in determining heat carrying capacity of a vapor chamber is the volume of the vapor space. This is determined by the thickness and area of the vapor chamber. For most applications, the thickness of the vapor chamber does not exceed 3mm, however pedestals and other surface features can be used to contact specific heat sources while leaving clearance for other board mounted objects. These pedestals can be extended 5mm from the vapor chamber lid plate. Mounting holes can also be integrated within the area of the vapor chamber for better integration with the heat source and locating the heat source at the center of the vapor chamber with good pressure application.



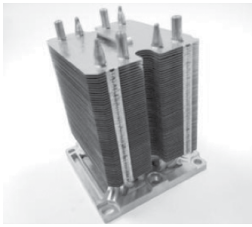
	HEAT CARRYING CAPACITY (Q-MAX) BY VAPOR CHAMBER THICKNESS							
	1.0mm	1.2mm	1.5mm	2.0mm	2.3mm	2.5mm	3.0mm	>3.0mm
45*45	10W	15W	20W	25W	60W	80W	100W	>100W
90*90	40W	50W	80W	100W	150W	180W	250W	>300W
120*120	40W	50W	80W	100W	160W	200W	275W	>300W
150*150			80W	100W	170W	220W	300W	>300W
200*200				100W	175W	225W	>300W	>300W
250*250					180W	240W	>300W	>300W
300*300							>300W	>300W

**Note:** Heat source = 30\*30mm  
This table is for reference. Q-max is related to heat source power density and effectiveness of final heat exchanger.

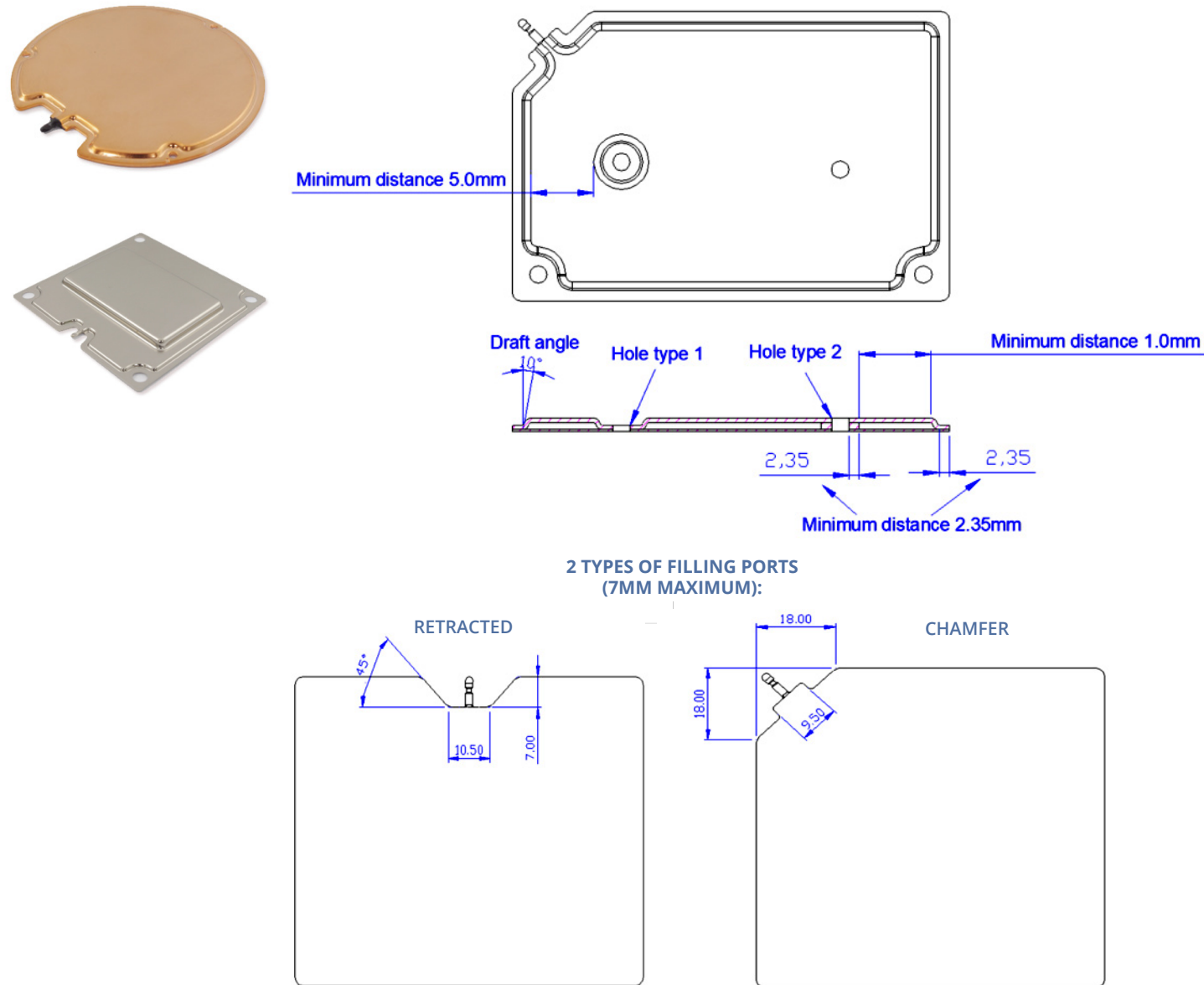


# VAPOR CHAMBER DESIGN GUIDE

## VAPOR CHAMBER ASSEMBLIES



Interfacing vapor chambers with plates and heat exchangers is predominately about maximizing contact area. In most cases, the vapor chambers are soldered to heat exchanger fins for air cooled applications. The vapor chambers can also be soldered to liquid cold plates to take advantage of spreading the heat before final heat exchange with the liquid. In many cases, the vapor chambers are also integrated with heat pipes to take the heat that has spread in the plane of the vapor chamber and extend it in the vertical dimension to more efficiently interact with cooling fins. Integrating with the heat source is most commonly done with pressure, up to 90 psi, and the use of a thermal grease or other interface material to maximize surface area contact to the source.

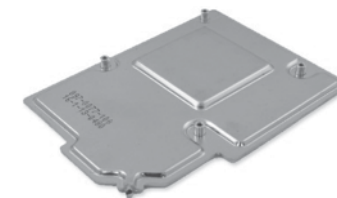


## WAKEFIELD-VETTE STANDARD VAPOR CHAMBERS

Wakefield-Vette offers individual vapor chambers through distribution. These most common offerings are a great option for testing, sampling, and validating your vapor chamber solution into eventual production. When building or testing your heat sink assembly please feel free to contact one of Wakefield-Vette's authorized distributors to purchase. Always remember to contact us for free consultation on assembly design or parameter questions.

WKV Part #	Product Description	Thermal Resistance	Length	Width	Thickness	qMax
VC-1131-8175-517	Standard Vapor Chamber 113.1mm x 81.75mm X 5.17mm	0.145	113.1	81.75	5.7	180W~
VC-90-90-3	Standard Vapor Chamber 90mm x 90mm x 3.00mm	0.143	90	90	3	150W~
VC-106-70-3	Standard Vapor Chamber 106mm x70mm x 3mm	0.150	106	70	3	150W~
VC-106-82-3	Standard Vapor Chamber 106mm x 82mm x 3mm	0.140	106	82	3	150W~

### PART NUMBER VC-1131-8175-517



#### Product Info Description

Dimension(mm): L: 113mm / W: 81.8mm / T: 5.7mm  
Operation Power: 180W~

#### Product Info Details

Thermal Resistance: 0.145°C/W  
Operation Temp: 40~130°C  
Platform : VGA

### PART NUMBER VC-90-90-3



#### Product Info Description

Dimension(mm): L: 90mm / W: 90mm / T: 3mm  
Operation Power: 150W~

#### Product Info Details

Thermal Resistance: 0.143°C/W  
Operation Temp: 40~140°C  
Platform : Intel 2011 Square

### PART NUMBER VC-106-70-3



#### Product Info Description

Dimension(mm): L: 106mm / W: 70mm / T: 3mm  
Operation Power: 150W~

#### Product Info Details

Thermal Resistance: 0.150°C/W  
Operation Temp: 40~140°C  
Platform : Intel 2011 Narrow

### PART NUMBER VC-106-82-3



#### Product Info Description

Dimension(mm): L: 106mm / W: 82mm / T: 3mm  
Operation Power: 150W~

#### Product Info Details

Thermal Resistance: 0.140°C/W  
Operation Temp: 40~140°C  
Platform : Intel 2011 Narrow

# THERMAL INTERFACE PRODUCTS

*Thermal Compounds, Adhesives & Interface Materials* ..... 140-145  
*High Performance Thermal Compound* ..... 140  
*General & Thermal High Performance Epoxy* ..... 146-155



*Cost-effective accessory products that facilitate installation and improve the thermal performance of both standard and custom heat dissipation components. Included are thermal joint compounds; filled epoxy systems; adhesives; thermally conductive insulating wafers, washers, pads and mounting hardware.*

## THERMAL COMPOUNDS, ADHESIVES & INTERFACE MATERIALS

### 120 SERIES

The **120 Series** Silicone Oil-Based Thermal Joint Compound fills the minute air gap between mating surfaces with a grease-like material containing zinc oxide in a silicone oil carrier. It possesses an excellent thermal resistance of only 0.05°C/W for a 0.001 in. film with an area of one square inch. There is no measurable increase in case temperature of a mounted semiconductor on a heat sink after the 6-month stabilization period (Time versus Thermal Resistivity graph below).

TYPICAL VALUES FOR THERMAL RESISTANCE, CASE TO SINK (Øcs) WHEN THERMAL JOINT COMPOUNDS ARE USED

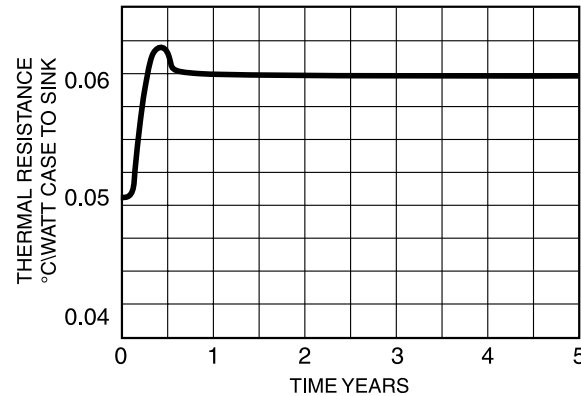
Case Style Characteristics	Mounting Torque in inch • pounds (N•M)	Typical Thermal Resistance (°C/W)
TO-3	8 (0.9)	0.09
TO-66	9 (0.9)	0.14
TO-220	8 (0.9)	0.50
0.19 (4.8) stud x 0.44 (11.2) hex	15 (1.7)	0.16
0.25 (6.4) stud x 0.69 (17.5) hex	30 (3.39)	0.10
0.38 (9.7) stud x 1.06 (26.9) hex	75 (8.47)	0.07
0.50 (12.7) stud x 1.06 (26.9) hex	125 (14.12)	0.07
0.75 (19.1) stud x 1.25 (31.8) hex	600 (67.79)	0.052

#### 120 SERIES - THERMAL JOINT COMPOUND

Characteristic	Description
Volume Resistivity	5 X 10 <sup>14</sup> ohm-cm
Dielectric Strength	225 volts/mil
Specific Gravity	2.1 min.
Thermal Conductivity @ 36°C	0.735 W/(m)(K)
	5.1(Btu) (in.)/(hr)(ft <sup>2</sup> )(°F)
Thermal Resistivity (P)	56 (°C)(in.)/watt
Bleed, % after 24 hrs @ 200°C	0.5
Evaporation, % after 24 hrs @ 200°C	0.5
Color	opaque white
Shelf life	5 years
Operating Temperature Range (°C)	-40/+200

#### 120 SERIES - ORDER GUIDE

Series - P/N	Container Size
120-SA	4 gram plastic pak
120-2	2 oz (0.06 kg) jar
120-5	5 oz (0.14 kg) tube
120-8	8 oz (0.23 kg) jar
120-80	5 lb (2.27 kg) can
120-320	20 lb (9.08 kg) can



## HIGH PERFORMANCE THERMAL COMPOUND

### 122 SERIES

**122 Series Thermal Joint Compound** is a stable, silicone based, thixotropic paste developed to provide premium performance at an affordable price. It is formulated to significantly reduce contact thermal resistance where power densities are concentrated in devices such as flip chip, reduced die size, and 'overclock' microprocessors. When applied as a thin film between a Wakefield-Vette heat sink and device it possesses superior thermal conductivity compared to traditional 'grease'. It is compatible with automated or manual dispensing methods and is fully RoHS compliant.



#### 122 SERIES THERMAL JOINT COMPOUND

Typical Characteristics	Description
Appearance	Smooth Gray paste
Thermal Conductivity	2.5 W / m °K, 17.3 (Btu) (in.)/(hr) (ft <sup>2</sup> ) (°F)
Thermal Resistance	0.02 °C in 2 / W
Bleed	0.015 wt%, 24 hrs at 200°C
Evaporation	0.150 wt%, 24 hrs at 200°C
Volume Resistivity	1.4 x 10 <sup>10</sup> ohm-cm
Dielectric Strength	225 volts/mil
Specific Gravity	2.23 (gm/cc) at 25°C
Operating Range	-40°C to 205°C
Shelf Life	5 years

#### 122 SERIES - ORDER GUIDE

Series - P/N	Container Size
122-10CC	10cc syringe
122-2	2 oz (0.06 kg) jar
122-30CC	30cc syringe

## THERMAL COMPOUNDS, ADHESIVES & INTERFACE MATERIALS

### 126 SERIES

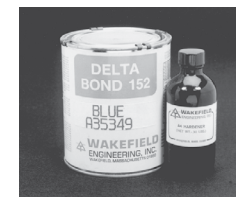
The **126 Series** is a nontoxic, synthetic, ester-based (nonsilicone) Thermal Joint Compound with metal oxide fillers designed to enhance thermal performance characteristics of plastic and metal package devices exceeding that of silicone-based compounds. Solved are problems associated with contamination of wave solder baths and migration of silicone-based products. Shelf life: 5 years.

#### 126 SERIES THERMAL JOINT COMPOUND

Characteristics	Description
Appearance	Smooth, white homogeneous paste
Solids Content, wt %	65% min
Thermal Conductivity at 36°C	.69 W / m °K, 4.8 (Btu)(in.)/(hr) (ft <sup>2</sup> ) (°F)
Interface Thermal Resistance	0.043°C/W TO-3 at 0.0008 thick film
Bleed, 24 hrs at 200°C, wt%	0.09% max
Evaporation, 24 hrs at 200°C, wt%	0.6 max
Volume Resistivity	2.3 x 10 <sup>12</sup> ohms-cm
Dielectric Strength	200 volts/mil
Specific Gravity @ 60°F	2.93 (gm/cc)
Penetration	280 to 320
Operating Range	-40°C to 200°C

#### 126 SERIES - ORDER GUIDE

Series - P/N	Container Size
126-2	2 oz (0.6 kg) jar
126-4	4 oz (0.11 kg) tube
126-4S	4 oz (0.11 kg) syringe
126-5LB	5 lb (2.27 kg) can



### DELTABOND™ 152

**DeltaBond™ 152** adhesive is ideal for general cementing; thermally bonding semiconductors and components to chassis or heat sinks, while electrically isolating one from the other; fabricating heat sinks or thermal links; and for all permanent bonding of assemblies which require high thermally conductive interfaces. It produces a rigid, high strength bond to most materials when cured. **DeltaBond™ 152** is available in bi-packs, kits, and quarts. Order one bottle of hardener A-4 or B-4 per one quart of **DeltaBond™ 152** separately. Shelf life: 152KA 1 year, all others 2 years.

#### DELTABOND™ 152

Characteristics	Hardener Type	
Typical Properties Fully Cured	A4	B4
Thermal conductivity - W/(m) (°K)	0.836	0.908
(Btu) (in.)/(hr) (ft <sup>2</sup> ) (°F)	5.8	6.3
Thermal resistivity - (°C) (in.) watt	47	42
Bond shear strength 77°F	2,900	2,300
1 in. overlap - psi 125°F	2,200	2,000
etched aluminum to etched aluminum to 212°F	400	800
Heat distortion point - °F	130	225
Minimum dielectric strength, v/mil, 0.125 in. sample	400	400
Max operation Continuous	65	150
temp - °C Intermittent	100	190

#### DELTABOND™ 152

Mixing Proportions and Working Properties		
Characteristics	A4	B4
Parts of hardener per 100 parts of resin by weight	7.5	3.5
*Working Time - at 77°F	45 min	30 min
†Initial cure time 77°F	8 hrs	6 hrs
150°F	45 min	30 min
250°F	20 min	15 min
‡Post-cure time at a temp in °F	4 hrs @200°F	4 hrs @ 200°F
‡Alternate room temp. aging time at 77°F	4 days	4 days
Working consistency (77°F)	viscous liquid	paste
Working viscosity (77°F) cps	25,000	—

#### NOTES:

\* Since the hardener/resin reaction is exothermic, it is important that batch size be matched to hardener speed. Working times given are for approximate batch sizes: A—200 gms, B—200 gms. Larger batch sizes will greatly reduce working time.

\*\* For optimum electrical properties, dry parts for 15 minutes at 150°F (65°C) or 30 minutes at 75°F (24°C) to slowly evaporate the thinner and then final cure for 4 hours at 275°F (135°C).

† After initial cure, material may be handled, removed from fixture, etc., but has not yet achieved full properties and should be room temperature aged or post-cured as shown to achieve full physical and electrical properties.

‡ After initial cure, material may be brought to full physical and electrical properties during post-cure or may be room temperature aged for charted length of time to achieve same full properties.

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#### DELTABOND™ 152

Ordering Guide - Resin and Hardener			
Model Number	Resin		Hardener
	Part No.	Container	Part Number
DeltaBond™ 152	152-1A	Bi-Pack (1 oz)	Included in PIN 152-1 A ("A-4") Type Included in P/N 152-1 B ("B-4") Type Included in P/N 152-KA A-4 (0.316 lb), B-4 (0.14 lb), (order 1 only)
	152-1B	Bi-Pack (1 oz)	
	152-KA	Kit (7 oz Resin, 0.5 oz Hardener)	
	152-Q	1 quart (4 lbs)	
All hardener part numbers: A-4, B-4			



# THERMAL COMPOUNDS, ADHESIVES & INTERFACE MATERIALS



## DELTACAST™ 153

**DeltaCast™ 153** is a pourable casting resin having thermal expansion characteristics similar to aluminum and copper allowing assemblies to operate over a very wide temperature range. Ideal for encapsulating components and assemblies, this series' major advantages and uses include potted systems (virtually indestructible), protecting components and systems from moisture and contaminants, securing proprietary circuitry, mechanical support of devices, removal of heat from hot components and the assembly equalizing temperatures, and high voltage isolation. **DeltaCast™ 153** is available in quarts and gallons. Order one bottle of hardener A4 or B4 per one quart of **DeltaCast™ 153** separately. Shelf life: 2 years.

DELTACAST™153		
Characteristics	Hardener Type	
	A4	B4
Typical Properties Fully Cured		
Thermal conductivity - W/(m) (°K)	0.836	0.908
(Btu) (in.)/(hr) (ft²) (°F)	5.8	6.3
Thermal resistivity - (°C) (in.) watt	47	42
Bond shear strength 77°F	2,500	1,900
1 in. overlap - psi 125°F etched aluminum to etched aluminum 212°F	—	—
Heat distortion point - °F	130	225
Minimum dielectric strength, v/mil, 0.125 in. sample	400	400
Max operation Continuous temp - °C	65	150
Intermittent	100	190

DELTACAST™153		
Mixing Proportions and Working Properties		
Characteristics	A4	B4
Parts of hardener per 100 parts of resin by weight	7.5	3.5
*Working Time - at 77°F	45 min	30 min
† Initial cure time 77°F	8 hrs	6 hrs
150°F	45 min	30 min
250°F	20 min	15 min
‡Post-cure time at a temp in °F	4 hrs @200°F	4 hrs @ 200°F
‡Alternate room temp. aging time at 77°F	4 days	4 days
Working consistency (77°F)	heavy liquid	viscous liquid
Working viscosity (77°F) cps	10,000	30,000

DELTACAST™153			
Ordering Guide - Resin and Hardener			
Model Number	Resin		Hardener
	Part No.	Container	Part Number
DeltaCast™ 153	153-Q	1 quart (4 lbs)	A-4 (0.316 lb), B-4 (0.14 lb), (order 1 only)
All hardener part numbers: A-4, B-4			

## DELTABOND™ 154

**DeltaBond™ 154** is a medium viscosity, aluminum-filled resin with the best thermal conductivity of this series. It is, however, neither a good electrical insulator nor conductor. Its principal application is that of a good thermal mechanical adhesive for applications such as bonding fins to base plates or structural mounting blocks or brackets to heat sinks. Order one bottle of hardener A4 or B4 per one quart of **DeltaBond™ 154** separately. Shelf life: 2 years.



DELTABOND™ 154		
Mixing Proportions and Working Properties		
Characteristics	A4	B4
Parts of hardener per 100 parts of resin by weight	11.0	4.5
*Working Time - at 77°F	45 min	30 min
† Initial cure time 77°F	8 hrs	6 hrs
150°F	45 min	30 min
250°F	20 min	15 min
‡Post-cure time at a temp in °F	4 hrs @200°F	4 hrs @ 200°F
‡Alternate room temp. aging time at 77°F	4 days	4 days
Working consistency (77°F)	viscous liquid	paste
Working viscosity (77°F) cps	25,000	—

DELTABOND™ 154		
Characteristics	Hardener Type	
Typical Properties Fully Cured	A4	B4
Thermal conductivity - W/(m) (°K)	1.053	1.154
(Btu) (in.)/(hr) (ft²) (°F)	7.3	8.0
Thermal resistivity - (°C) (in.) watt	37	34
Bond shear strength 77°F	3,000	2,400
1 in. overlap - psi 125°F	2,300	2,100
etched aluminum to etched aluminum 212°F	500	800
Heat distortion point - °F	130	225
Minimum dielectric strength, v/mil, 0.125 in. sample	NA*	NA*
Max operation Continuous temp - °C	65	150
Intermittent	100	190

## DELTABOND™ 154

DELTABOND™154			
Ordering Guide - Resin and Hardener			
Model Number	Resin		Hardener
	Part No.	Container	Part Number
DeltaBond™	154-Q1	quart (2.5 lbs)	A-4 (0.316 lb), B-4 (0.14 lb), (order 1 only)
All hardener part numbers: A-4, B-4			



## DELTABOND™ 155

**DeltaBond™ 155** is an epoxy adhesive formulated for use within the semiconductor industry. An easy to mix spread thixotropic paste, it offers high heat transfer, low shrinkage, and a coefficient of thermal expansion comparable to that of copper and aluminum. This adhesive is principally used to form thermally conductive joints in fabricated heat sinks and between heat sinks and power devices. When used to bond semiconductors to heat sinks, it also serves as an electrical insulator. Its strong bond to a wide variety of substrates resists severe temperature cycling. **DeltaBond™ 155** is only available in kit size. Simply squeeze out equal lengths and mix to uniform color. Shelf life: 1 year.

DELTABOND™ 155	
Characteristics	Hardener Type
Typical Properties Fully Cured	DeltaBond™155
Thermal conductivity - W/(m) (°K)	0.836
(Btu) (in.)/(hr) (ft²) (°F)	5.8
Thermal resistivity - (°C) (in.) watt	47
Bond shear strength 77°F	2,600
1 in. overlap - psi 125°F etched aluminum to etched aluminum 212°F	—
Heat distortion point - °F	130
Minimum dielectric strength, v/mil, 0.125 in. sample	400
Max operation Continuous temp - °C	65
Intermittent	100

DELTABOND™ 155	
Mixing Proportions and Working Properties	
Parts of hardener per 100 parts of resin	by volume 100
*Working Time - at 77°F	90 min
†Initial cure time 77°F	8 hrs
150°F	45 min
250°F	20 min
‡Post-cure time at a temp in °F	4 hrs @ 200°F
‡Alternate room temp. aging time at 77°F	4 days
Working consistency (77°F)	paste
Working viscosity (77°F) cps	paste

DELTABOND™ 155			
Ordering Guide - Resin and Hardener			
Model Number	Resin	Hardener	
	Part No.	Container	Part Number
DeltaBond™ 155	155 Kit	(3 oz resin, 3 oz hardener)	Included in P/N 155

### NOTES:

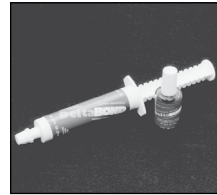
\* Since the hardener/resin reaction is exothermic, it is important that batch size be matched to hardener speed. Working times given are for approximate batch sizes: A—200 gms, B—200 gms. Larger batch sizes will greatly reduce working time.

† After initial cure, material may be handled, removed from fixture, etc., but has not yet achieved full properties and should be room temperature aged or post-cured as shown to achieve full physical and electrical properties.

‡ After initial cure, material may be brought to full physical and electrical properties during post-cure or may be room temperature aged for charted length of time to achieve same full properties.

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# THERMAL COMPOUNDS, ADHESIVES & INTERFACE MATERIALS



## DELTABOND™ 156

**DeltaBond™ 156** Thermally Conductive Adhesive is a modified acrylic adhesive designed for permanent mounting on components where heat must be effectively transmitted. Recommended for electromechanical assemblies to bond components and dissipate heat, it replaces mechanical fasteners and compressible pads, silicone grease, and epoxies; eliminates air entrapment, and other variables related to epoxy mixing. This soft paste requires no mixing and flows easily to allow thin bond lines. Primer activated, cure begins upon assembly. DeltaBond™ Activator fixtures at room temperature in less than 5 minutes. Full strength is developed in 4 to 12 hours and fillets become dry to the touch in 24 hours. It is not recommended to use this durable adhesive without the use of DeltaBond™ Activator. **DeltaBond™ 156** is available in kit size; order 156-K (25 ml Syringe and Activator Kit). Shelf life: 1 year.

DELTABOND™ 156		
Characteristics	Description	
Typical Properties Fully Cured	Description	
Test	Results	ASTM
Temperature Range	-65 to 300°F (-54 to 149°C) 300°F to (177°C) Intermittent	
Tensile Strength, at break	2360 psi	D638
Modulus	233,000 psi	D638
Elongation, at break	7.75%	D638
Outgassing	2.5% TLM	E595
Coefficient of Thermal Expansion	0.05% CVCM	
Tensile Shear	7.1 x 10 <sup>-4</sup> (cm/cm°C)	D1002
Thermal Conductivity, K (absolute at 86°F (30°C))	2500psi 3.47 Btu x in./hr ft <sup>2</sup> °F (0.50 W/m °C)	

Note: The absolute thermal conductivity test was developed specifically for measuring thermal properties of thin film adhesive bonds.

DELTABOND™ 156		
Typical Electrical Properties		
Test	Results	ASTM
Dielectric Strength	220 volts/mil	D149
Dielectric Constant, 77°F (25°C)		D150
100 Hz	14.92	
1000 Hz	14.26	
1MM Hz	12.34	
Dissipation Factor, 77°F (25°C)		D150
100 Hz	0.05	
1000 Hz	0.03	
1MM Hz	0.06	
Volume Resistivity	5.2x10 <sup>11</sup> (ohms-cm)	D257
Surface Resistivity	8.6 x 10 <sup>13</sup> (ohms)	D257

Note: DeltaBond™ Thermally Conductive Adhesive-High Strength contains a metallic filler which, in certain applications, may have an effect on electrical properties. Therefore, test each particular application to ensure that electrical properties are as required.

DELTABOND™ 156			
Ordering Guide - Resin and Hardener			
Model Number	Resin		Hardener
	Part No.	Container	Part Number
DeltaBond™ 156	156-K	Resin Kit Hardener Syringe - 0.85 fl oz - 25 ml - 2 oz net/0.44 oz fl contents bottle -12ml	Included in kit hardener with brush applicator - 4.2 oz total wt/kt

### NOTES:

- \* Since the hardener/resin reaction is exothermic, it is important that batch size be matched to hardener speed. Working times given are for approximate batch sizes: A—200 gms, B—200 gms. Larger batch sizes will greatly reduce working time.
- † After initial cure, material may be handled, removed from fixture, etc., but has not yet achieved full properties and should be room temperature aged or post-cured as shown to achieve full physical and electrical properties.
- ‡ After initial cure, material may be brought to full physical and electrical properties during post-cure or may be room temperature aged for charted length of time to achieve same full properties.

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## DELTAPADS™ THERMALLY CONDUCTIVE INSULATORS 173 & 174 SERIES

TO-3, TO-66, TO-220, DO-4, DO-5 SHEET

## GREASELESS THERMALLY CONDUCTIVE KAPTON® REINFORCED INSULATORS 175 SERIES



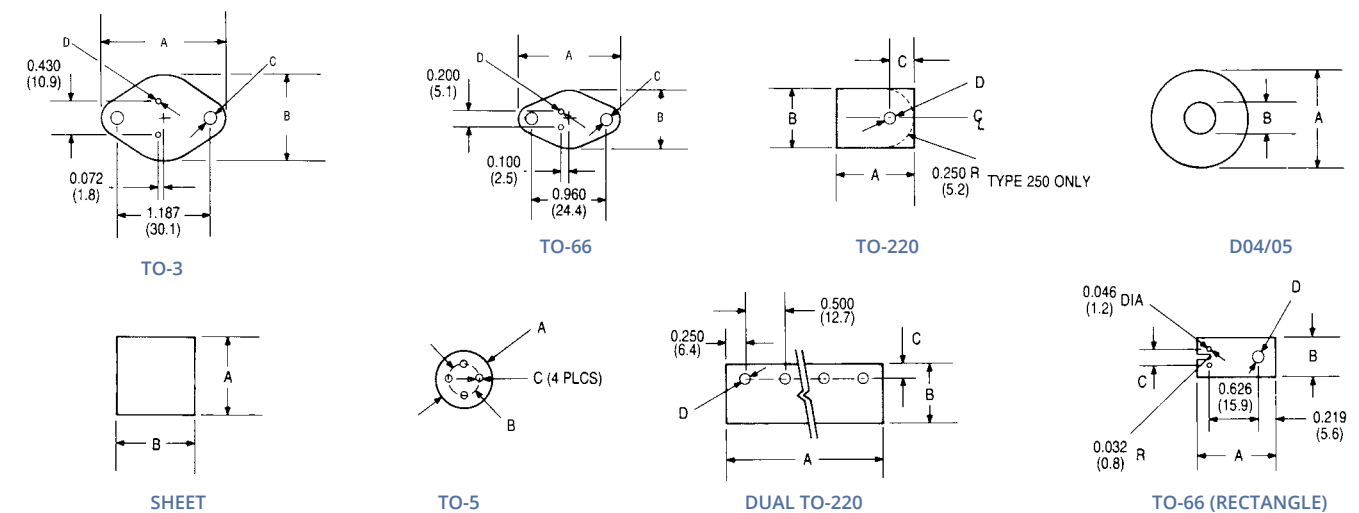
The **173, 174, and 175 Series** are highly efficient thermally conductive insulators designed for semiconductor interface to heat sinks. Their properties eliminate messy concerns associated with thermal greases.

Characteristics	DeltaPads™ 173-7 Series	DeltaPads™ 173-9 Series	DeltaPads™ 174-9 Series	Kapton® 175-6 Series	Test Method
Material Thickness	0.007 in.	0.009 in.	0.009 in.	0.006 in.	Micrometer
Color	Gray	Gray	Tan	Gray	Visual
Tear Strength, lb/in. Typical100	100	100	100	ASTM 0624	
Volume Resistivity, megohm-cm, Minimum Normal	1.0 x 10 <sup>9</sup>	1.0 x 10 <sup>9</sup>	1.0 x 10 <sup>13</sup>	1 x 10 <sup>13</sup>	ASTM D257
Breakdown Voltage, Minimum	4,000	5,000	5,000	6,000	ASTM 0149
Dielectric Constant at 60 Hz and 100 V Maximum	2.70	2.40	2.50	5.5 @ 1,000 Hz	ASTM D 150
Continuous Use Temperature, °C	-60/+200	-60/+200	-60/+200	-60/+200	-
Thermal Conductivity, cal/cm sec. °C, Minimum	3 x 10 <sup>-3</sup>	3 x 10 <sup>-3</sup>	1 x 10 <sup>-2</sup>	1.2 x 10 <sup>-3</sup>	-
Thermal Resistance (TO-3), 1 in. <sup>2</sup> °C/W	0.33	0.50	0.25	0.40	-
Recommended Mounting Pressure, lb/in. <sup>2</sup>	350/550	350/550	350/550	350/550	Formula*

$$*P \text{ (pressure in psi)} = \frac{T \text{ (torque [in.-lb]} \times N \text{ (number of fasteners)}}{0.2 \times D \text{ (Thread Dia)} \times A \text{ (contact surface area square inches)}}$$

173-7 Series		173-9 Series	174-9 Series	175-6 Series
No Adhesive	Adhesive Backing	No Adhesive	No Adhesive	Greaseless
-	-	173-9-210P	-	175-6-210P
173-7-220P	-	-	-	175-6-220P
173-7-230P	-	173-9-230P	-	175-6-230P
173-7-240P	173-7-240A	173-9-240P	-	175-6-240P
-	-	-	-	175-6-250P
-	-	-	-	175-6-280P
-	-	-	174-9-310P	175-6-310P
-	-	-	-	175-6-320P
-	-	-	-	175-6-330P
-	-	-	-	175-6-410P
-	-	-	-	175-6-610P
173-7-1212P	-	173-9-1212P	174-9-1212P	-

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

Contact us: (603) 635-2800

## GENERAL & THERMAL HIGH PERFORMANCE EPOXY



### BONDATHERM™



#### KEY FEATURES OF THE BONDATHERM EQUALIZER KITS:

- Eliminates improper ratios and mixing errors
- Reduces material waste
- Eliminates employee contact with resins
- Eliminates messy hand mixing and transferring
- Increases productivity
- Resins are protected from moisture contamination

BondaTherm™

Wakefield-Vette Part Number	Description	Packaging
BT-101-50M BT-102-50M BT-301-50M BT-301-200M	Non-Sag 5 Minute BondaTherm Epoxy Adhesive Toughened, Flexible Adhesive System Fast Curing Thermally Conductive Adhesive Fast Curing Thermally Conductive Adhesive	50ml Dual Cartridges 50ml Dual Cartridges 50ml Dual Cartridges 200ml Dual Cartridges
BT-01-50M BT-01-200M BT-02-50M BT-02-200M	BondaTherm Equalizer Dispense Gun (50ml) BondaTherm Equalizer Dispense Gun (200ml) BondaTherm Equalizer Static Mixer (50ml) BondaTherm Equalizer Static Mixer (200ml)	- - - -
BT-101-50M-EQZ BT-102-50M-EQZ BT-301-50M-EQZ BT-301-200M-EQZ	Two Dual Cartridges (BT-101-50M), One Gun (BT-01-50M), Three Mixers (BT-02-50M) Two Dual Cartridges (BT-102-50M), One Gun (BT-01-50M), Three Mixers (BT-02-50M) Two Dual Cartridges (BT-301-50M), One Gun (BT-01-50M), Three Mixers (BT-02-50M) Two Dual Cartridges (BT-301-200M), One Gun (BT-01-200M), Three Mixers (BT-02-200M)	Kit Kit Kit Kit
BT-103-50M BT-302-50M	5 Minute Clear Bondatherm Epoxy Adhesive Fast Curing Aluminum Filled Bondatherm Epoxy Adhesive	50ml Dual Cartridges 50ml Dual Cartridges
BT-401-H BT-402-H BT-403-H	Silver Filled Bondatherm 2 gram Epoxy Hinge Packs Thermally Conductive Epoxy Potting UL Listed 100 gram Bondatherm Hinge Pack Aluminum Filled Bondatherm Epoxy Adhesive for Heat Sinks 100 gram Hinge Pack	2 gram hinge pack 100 gram hinge pack 100 gram hinge pack

### BONDATHERM™ CARTRIDGES BT-101-50M



These high bond strength adhesives are clear 100% solids, two component, non-sag adhesives with a quick setting time of 5–46 minutes at room temperature. They are excellent for bonding plated metals, pewter, glass, wood, ceramic, felt, cement, gem stones, most plastics and rubbers. These adhesives were tested in our laboratory for flame retardancy properties. According to our test results they meet the requirements of UL94HB.

#### APPLICATIONS:

These unique adhesives are ideally suited for a wide range of electronic, electrical, industrial, structural, and jewelry applications. These adhesives are also an excellent choice for field repairs. They are offered in the popular BondaTherm Equalizer Kit dual barrel cartridge dispensing system and bulk packaging.

#### FEATURES

- Non-sag consistency
- High bond strength
- Fast room temperature cure – three speeds to choose from
- Water & chemical resistance
- Outstanding thermal shock resistance
- 1:1 mix ratio
- Impact resistance

#### Specifications

Color	Semi-transparent (available in black)
Mix ratio by volume	1:01
Mixed viscosity, 25°C cps*	Non-Sag 100
Solids content, %	100
Specific gravity, 25°C	1.15
Shore D hardness	86
10-3005NS	72
10-3020NS	65
10-3046NS	
Work Life, 25°C, minutes	3-5
10-3005NS	10-15
10-3020NS	25-30
10-3046NS	
Handling time, 25°C, minutes	15-20
10-3005NS	30-35
10-3020NS	55-60
10-3046NS	
Cure time, 25°C, hours	24-48
Coefficient of thermal expansion (in/in/°C)	60x10 <sup>-6</sup>
Operating temperature range, °C	50 to *130
Dielectric strength, V/mil	420
Izod Impact ft-lb/in	2.7
Dielectric constant, 1KHz at 25°C	4
Dissipation factor, 1KHz at 25°C	0.017
Volume resistivity, ohm-cm at 25°C	2.0 x 10 <sup>14</sup>
Shear strength, psi	1,500
Aluminum (etched)	1,000
Cold rolled steel	960
Copper	725
Brass	750
Stainless Steel	900
Galvanized Steel	500
ABS	335
PVC	
Polycarbonate	250
Compression strength, psi	8,500
<b>Adhesive coverage:</b> a .005-inch bond line will yield approximately 320 sq. ft./gallon	

### BONDATHERM™ CARTRIDGES BT-101-50M

#### INSTRUCTIONS FOR USE:

1. Thoroughly mix equal parts of resin to catalyst by weight or volume.
2. Apply evenly to both surface(s) to be bonded.
3. Application to the substrates should be made within five minutes. Larger quantities and/or higher temperatures will reduce the working time. Avoid mixing large quantities and/or at high temperature due to the possibility of creating a high exothermic temperature.
4. Join the coated surfaces. Allow to cure at 60°F (16°C) or higher until adhesive is set. Heat may be added up to 200°F (93°C) to accelerate the cure.
5. Avoid moving parts during cure. Pressure to the substrates is recommended. Maximum shear strength is obtained with a 3-5 mil bond line.

## GENERAL & THERMAL HIGH PERFORMANCE EPOXY



### BT-102-50M BONDATHERM™ CARTRIDGES

A two component system that forms strong structural bonds at room temperature. This unique adhesive system provides high peel and shear strengths. This is excellent for bonding many metals and woods, most plastics and rubbers and masonry products.

**BT-102-50M** is a toughened, flexible, and impact resistant epoxy adhesive. **BT-102-50M** is a two component system that forms strong structural bonds at room temperature. This unique adhesive system provides high peel and shear strengths. **BT-102-50M** is excellent for bonding many metals and woods, most plastics and rubbers and masonry products. This system is designed for electronic, aerospace and other demanding industrial applications. This product is available in the popular BondaTherm Equalizer dual barrel cartridge system.

FEATURES	
• Impact resistant	
• Excellent electrical insulator	
• High peel and shear	
• Outstanding structural bonds	
• Convenient 1:1 Ratio	
• Retention of strength after environmental aging	

Typical Specifications	
Mixed viscosity, 25°C, cps	150,000
Specific gravity, 25°C,	
Resin	1.32
Catalyst	1.2
Gel time, 100 grams, 25°C	70 minutes
Tensile shear strength, psi	2,600
Durometer, shore D	70
Dielectric strength, V/mil	410
Dielectric constant, 60 Hz	4.4
Dissipation factor, 60 Hz	0.02
Volume resistivity, ohm-cm	1.1 x 10 <sup>15</sup>
Thermal conductivity, btu-in/hr-ft <sup>2</sup> -°F	4
Coefficient of thermal expansion, per °C	10 x 10 <sup>-5</sup>
<b>Adhesive coverage:</b> a .005-inch bond line will yield approximately 320 sq. ft./gallon	

#### INSTRUCTIONS FOR USE:

- Surfaces must be clean and grease free. Use an oil free solvent such as acetone to wipe surfaces. Adhesion can be substantially increased by abrading the surfaces to be bonded with emery cloth, sand paper, carbide grinding tools, and sand blasting. A roughened, porous surface will produce the best results. Any oxidized metal films should be removed just prior to application of the epoxy adhesive mixture.
- Thoroughly mix equal parts of resin and catalyst by volume.
- Apply mixed product evenly to both surfaces.
- Join the adhesive coated surfaces within 60 minutes of mixing resin and catalyst.
- Cure according to one of the following schedules:
 

77°F	24-48 hours
150°F	2 hours
180°F	1 hour
200°F	30 minutes

#### STORAGE, HANDLING, AND AVAILABILITY:

- Store in a cool, dry place in original containers.
- Keep containers closed and stir well before using.

### BONDATHERM™ CARTRIDGES

### BT-301-50M & BT-301-200M



The **BT-301-50M** and **BT-301-200M** have simple 1:1 mix ratios and develop a 1,400 psi Lap Shear strength (aluminum to aluminum) in four hours at room temperature. After just twenty four hours the strength is over 2,200 psi. This is perfect for any thermally conductive applications. Both cartridges are a two component fast curing thermally conductive epoxy adhesive.

These products are specifically formulated for use in the convenient BondaTherm Equalizer dual barrel cartridge system. The **BT-301-50M** and **BT-301-200M** offer fast heat dissipation for a wide range of electronic applications. The black resin and white hardener provide an excellent visual indication of a complete mix.

FEATURES	
• Fast room temperature cure	
• Thermally conductive	
• Forms strong bonds to a variety of substrates	
• Electrically insulating	
• Vibration and impact resistant	

Typical Properties	
Color	
Resin	Black
Hardener	White
Mixed	Dark Gray
Viscosity, @25°C, cps	
Resin	70,000
Hardener	70,000
Specific Gravity, @25°C	
Resin	1.5
Hardener	1.5
Gel Time, 25°C, 15 grams	15 minutes
Durometer, Shore D	
@25°C	80
@70°C	50
Lapshear Strength (Al to Al), psi	
After 4 hours	1,413
After 24 hours	2,231
Thermal Conductivity, W/m - °K	1.04
Dielectric Strength, V/mil	440
Dielectric Constant, 25°C, 100Hz	5.3
Volume Resistivity, ohm-cm, 25°C	2.4 x 10 <sup>12</sup>
Coefficient of Thermal Expansion, ppm/°C	
Below Tg	45
Above Tg	175
Operating Temperature, °C	-40 to +120

#### INSTRUCTIONS FOR USE:

- Surfaces must be clean and grease free. Use an oil free solvent such as acetone to wipe surfaces. Adhesion can be substantially increased by abrading the surfaces to be bonded with emery cloth, sand paper, carbide grinding tools, and sand blasting. A roughened, porous surface will produce the best results. Any oxidized metal films should be removed just prior to application of the epoxy adhesive mixture.
- Dispense material from BondaTherm Equalizer. Apply mixed product to substrate to be bonded.
- Join substrates within 3-5 minutes.
- Cure according to one of the following schedules:
 

25°C	2-4 hours
65°C	< 10 minutes

#### STORAGE, HANDLING AND AVAILABILITY:

- Store in a cool, dry place in original containers.
- Please read and understand the Safety Data Sheet (SDS) before using this product.

#### NOTES:

- At room temperature, the BT-301-50M and BT-301-200M will reach handle cure within 1-2 hours. The lap shear strength is 1,413 psi after 4 hours.
- This product is an adhesive and is not designed for potting and encapsulating applications. The BT-301-50M and BT-301-200M are fast reacting epoxy systems and they will create a high exothermic temperature in large mass sizes (avoid mass sizes greater than 25 grams).

## GENERAL & THERMAL HIGH PERFORMANCE EPOXY



### BT-103-50M BONDATHERM™ CARTRIDGES

These high bond strength adhesives are clear 100% solids, two component, low viscosity adhesives with a quick setting time of 5-46 minutes at room temperature. They are excellent for bonding plated metals, pewter, glass, wood, ceramic, felt, cement, gem stones, most plastics, and rubbers. These adhesives were tested in our laboratory for flame retardancy properties. According to our test results they meet the requirements of UL94HB.

These unique adhesives are ideally suited for a wide range of electronic, electrical, industrial, structural, and jewelry applications. These adhesives are also an excellent choice for field repairs. They are offered in the popular TriggerBond® dual barrel cartridge dispensing system and bulk packaging.

#### FEATURES

- High bond strength
- Outstanding thermal shock resistance
- Water and chemical resistance
- Impact resistance
- 1:1 mix ratio
- Fast room temperature cure – three speeds to choose from

#### INSTRUCTIONS FOR USE:

1. Thoroughly mix equal parts of resin to catalyst by weight or volume.
2. Apply evenly to both surface(s) to be bonded.
3. Application to the substrates should be made within five minutes. Larger quantities and/or higher temperatures will reduce the working time.
4. Avoid mixing large quantities and/or at high temperature due to the possibility of creating a high exothermic temperature.
5. Join the coated surfaces. Allow to cure at 60°F (16°C) or higher until adhesive is set. Heat may be added up to 200°F (93°C) to accelerate the cure.
6. Avoid moving parts during cure. Pressure to the substrates is recommended. Maximum shear strength is obtained with a 3-5 mil bond line.

Typical Specifications (10-3005)	
Color	Clear (available in black)
Mix ratio by volume	1:01
Mixed viscosity, 25°C cps * Solids Content, %	12,000 100
Specific gravity, 25°C Shore D hardness	1.15 86 72 65
Work Life, 25°C, minutes	3-5 10-15 25-30
Handling time, 25°C, minutes	15-20 30-35 55-60
Cure time, 25°C, hours	24-48
Coefficient of thermal expansion (in/in/°C)	60x10 <sup>-6</sup>
Operating temperature range, °C Dielectric strength V/mil	50 to 130 420
Izod Impact, ft-lb/in. Dielectric constant, 1KHz at 25°C	2.7 4.00
Dissipation factor, 1KHZ at 25°C Volume resistivity, ohm-cm at 25°C Shear strength, psi	.017 2.0 x 10 <sup>14</sup>
Aluminum (etched) Cold rolled	1,500
Steel Copper	1,000
Brass	960
Stainless Steel	725
Galvanized Steel	750
ABS	900
PVC	500
Polycarbonate	335
Compression strength, psi	250
<b>Adhesive coverage:</b> a .005-inch bond line will yield approximately 320 sq. ft./gallon	

### BONDATHERM HARDWARE

Wakefield-Vette Part Number	Description
BT-01-50M	BondaTherm Equalizer Dispense Gun (50ml)
BT-01-200M	BondaTherm Equalizer Dispense Gun (200ml)
BT-02-50M	BondaTherm Equalizer Static Mixer (50ml)
BT-02-200M	BondaTherm Equalizer Static Mixer (200ml)

#### BONDATHERM EQUALIZER GUN



### BT-01-50M BONDATHERM™ CARTRIDGES

FOR USE W/ 200ML CARTRIDGES

### BT-01-200M



#### BONDATHERM EQUALIZER STATIC MIXERS



### BT-02-50M FOR USE W/ 50ML CARTRIDGES

FOR USE W/ 200ML CARTRIDGES

### BT-01-200M



## GENERAL & THERMAL HIGH PERFORMANCE EPOXY

### BONDATHERM EQUALIZER KIT™

Wakefield-Vette Part Number	Description	Packaging
BT-101-50M-EQZ	Two Dual Cartridges (BT-101-50M), One Gun (BT-01-50M), Three Mixers (BT-02-50M)	Kit
BT-102-50M-EQZ	Two Dual Cartridges (BT-102-50M), One Gun (BT-01-50M), Three Mixers (BT-02-50M)	Kit
BT-301-50M-EQZ	Two Dual Cartridges (BT-301-50M), One Gun (BT-01-50M), Three Mixers (BT-02-50M)	Kit
BT-301-200M-EQZ	Two Dual Cartridges (BT-301-200M), One Gun (BT-01-200M), Three Mixers (BT-02-200M)	Kit

### (2) Dual Cartridges, (1) Dispense Gun, (3) Static Mixers



### BONDATHERM HINGE PACKS

### BT-401-H



**BT-401-H** is a two component epoxy adhesive filled with silver. This electrically conductive epoxy resin formulation offers continuity of conductivity with an electrical resistivity value of less than  $1 \times 10^{-4}$  ohm-cm. 40-3900 is also well known for its wide operating temperature range, -50 to + 170°C.

**BT-401-H** is specifically designed for adhesive bonding in microelectronic and optoelectronic applications. Due to its excellent continuity, it has also been used extensively in applications such as micro-wave EMI and RFI shielding, in the assembly or repair of printed circuit boards, wave guides, electronic modules, flat cable, high frequency shields, connectors, circuitry, and as a cold solder.

**BT-401-H** is formulated with pure silver (no alloys) and is designed in a convenient 1:1 mix ratio. Both the resin and hardener have silver powder dispersed.

#### FEATURES

- Electrically conductive
- Thermally conductive
- Room temperature cure
- Easy 1:1 mix ratio
- Good bond strength

#### STORAGE, HANDLING, AND AVAILABILITY:

- BT-401-H Resin and hardener should be stored at 25°C in original tightly sealed containers. Expected shelf life is twelve months in original unopened containers.
- Filler settling is common with these products. Gently stir resin and hardener before using to make sure fillers are evenly dispersed.

Typical Specifications	
Mix Ratio, by Weight	1:1
Color	Silver
Mixed Viscosity	Creamy Paste
Pot Life, 100 gram mass @ 25°C	1 Hour
Specific Gravity, 25°C	
Resin	2.98
Hardener	1.8
Hardness, Shore D	70
Thermal Conductivity, W/m- °K	7.93
Tensile Lapshear, psi (Al to Al)	700
Flexural Strength, psi	10,200
Volume Resistivity, ohm-cm	0.0001
Operating Temp. Range, °C	-50 to +170
Cure Schedule	a) 24 hours @ 25°C b) 1 hour @ 65°C c) 15 minutes @ 90°C

## GENERAL & THERMAL HIGH PERFORMANCE EPOXY



### BT-402-H

#### BONDATHERM HINGE PACKS

This system has been formulated to meet the stringent non-burning requirements of UL94 V-0. **BT-402-H** Black Epoxy is used with Catalyst 190 and are listed with Underwriter's Laboratory for passing UL94 V-0. This system offers excellent heat transfer, low shrinkage, and outstanding insulation properties. **BT-402-H** Black with Catalyst 190 passes NASA's outgassing requirements per ASTM E595-07. Other Catalyst's are available as well (30, 150).

Typical applications for **BT-402-H** include encapsulating power supplies, transformers, coils, insulators, and sensors. This system is an excellent choice for applications requiring high thermal conductivity and flame retardancy.

Typical Specifications	
Viscosity @ 25°C cps, Resin	60,000
Mixed with Cat. 190	28,000
Mixed with Cat. 30	17,000
Mixed with Cat. 150	1,500
Specific Gravity, 25°C	1.6
Hardness, Shore D	90
Color	Black
Tensile Strength, psi	9,850
Linear Shrinkage, in/in	0.002
Operating Temp. Range, °C	60 to 200
Dielectric Strength, V/mil Dielectric Constant at 60 Hz	485
Volume Resistivity, ohm-cm, 25°C	5.6
Dissipation Factor, 60 Hz	1.5 x 10 <sup>-5</sup>
Thermal Conductivity, W/m- °K	0.015
Compressive Strength, psi	2.16
Coefficient of Expansion, in/in °F	15,000
Heat Distortion, °C Outgassing	1.4 x 10 <sup>-5</sup>
(with Cat. 190)	155
%TML	0.5
%CVCM	0.01

#### INSTRUCTIONS FOR USE:

- A. With Catalyst 190 listed with UL 94 V-0 (room temperature curing):
  1. By weight, thoroughly mix 5 parts Catalyst 190 to 100 parts BT-402-H resin.
  2. Degas and pour. Cure at room temperature for 12-24 hours at 25°C ambient.
- B. With Catalyst 30 listed with UL 94 V-0 and RTI Rating of 130°C (Heat curing - Recommended for higher operating temperature and physical property applications):
  1. By weight, thoroughly mix 10 parts Catalyst 30 to 100 parts BT-402-H resin.
  2. Pour and cure according to one of the following recommended cure schedules:
    - a) 85°C (185°F) 3-4 hours
    - b) 100°C (212°F) 2-3 hours
 For optimum performance, an additional 2 hours @ 365°F (185°C) is recommended.
- C. With Catalyst 150 (room temperature/heat curing):
  1. By weight, thoroughly mix 17 parts Catalyst 150 to 100 parts BT-402-H resin.
  2. Degas and pour. Cure at room temperature for 24 hours or for 2-3 hours at 35-40°C.



#### BONDATHERM HINGE PACKS

### BT-403-H

**BT-403-H** is a two component, aluminum filled epoxy system. This system is used for making heat resistant tools, parts, or bonds that require the highest thermal conductivity and heat resistance. We have developed this extremely conductive epoxy by formulating it with a unique combination of fillers, particle sizes and dispersion techniques.

**BT-403-H** has good heat dissipation making this a popular choice for a variety of heat sink applications. Its viscosity is particularly suited for Fin bonding. **BT-403-H** passes NASA's outgassing requirements per ASTM E-595-07.

#### FEATURES

- Excellent Thermal Conductivity
- Superior Adhesion
- Low Viscosity allows quick self leveling

Typical Specifications	
Color	Grey
Viscosity, 25°C, Resin	130,000
Mixed	8,000
Specific Gravity, 25°C	1.81
Working time, 100 grams, 25°C	5 Hours
Durometer, Shore D	90
25°C	65
100°C	
Tensile Strength, psi, 25°C Aluminum to Aluminum 1" overlap	9,000
	2,500
Compressive Strength, PSI, 25°C Mix Ratio, by weight	18,500
Operating temperature, °C	100:10
Coefficient of Thermal Expansion, °C	-55 to 155
Thermal Conductivity, W/m- °K	28 x 10 <sup>-6</sup>
4.5	
Outgassing	
% TML	0.91
% CVCM	0.07

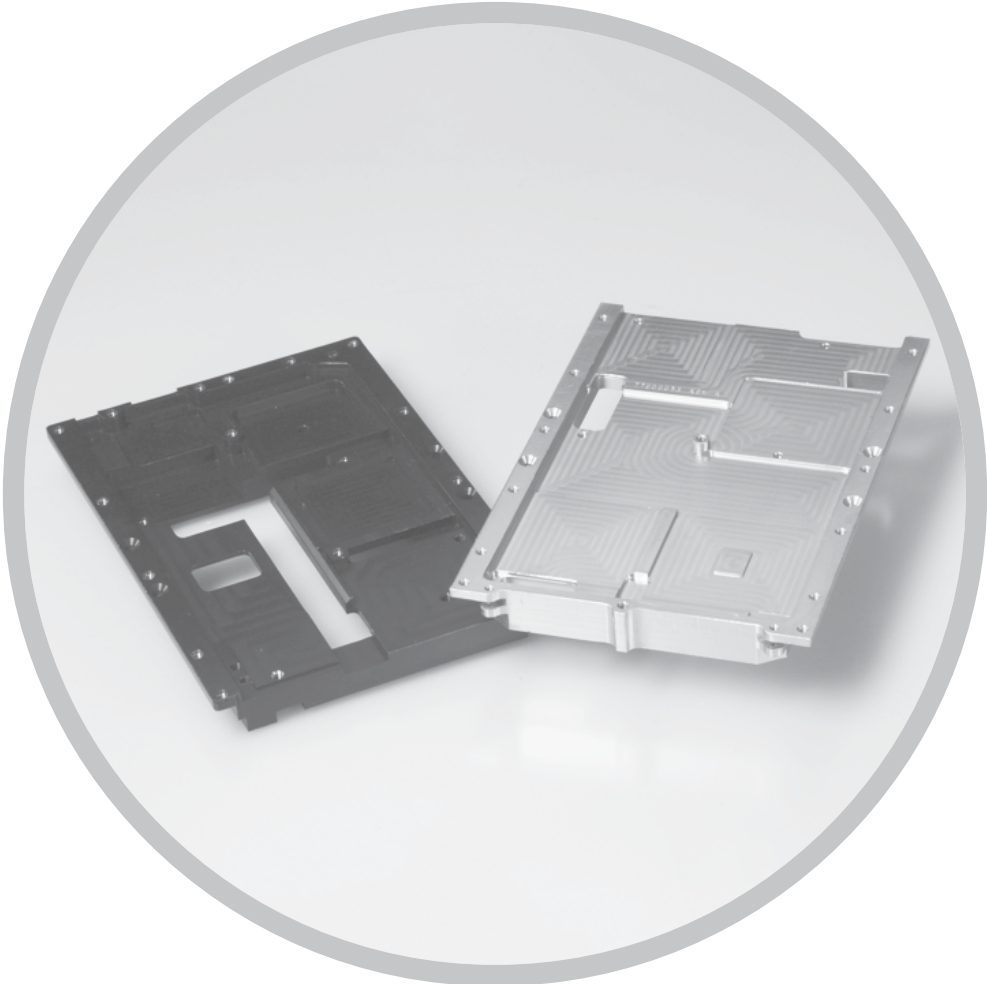
#### STORAGE, HANDLING, AND AVAILABILITY:

- BT-401-H Resin and hardener should be stored at 25°C in original tightly sealed containers. Expected shelf life is twelve months in original unopened containers.
- Filler settling is common with these products. Gently stir resin and hardener before using to make sure fillers are evenly dispersed.

# MIL EMBEDDED

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- Front Panels* ..... 158
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## FRONT PANELS



Standard & custom front panels that are silk-screened, fully assembled, and ready to mount.

Parts are made from extrusion and manufactured on high-speed CNC machines, providing a superior finish and precision fit to a specific application.

### FEATURES AND OPTIONS

- Panel cutouts
- Multi-color silk-screened
- Choice of EMC gaskets
- Choice of surface finish
- Optional hot swap microswitch installation
- Assembly and kitting

### APPLICATIONS

- VME Flat Panel
- Compact PCI
- 1101.10 compliant
- Electrical/Electronic instrumentation, controls, and devices.
- Electronic communication equipment.
- Computer system front and rear back panels.
- 19 inch panel plates - 1U, 2U and 3U make for many different applications.
- Audio devices, vacuum tube amplifiers, and signal processing equipment.



## FMC & PMC BEZEL KITS DATA SHEETS

**FMC & PMC Mezzanine Cards** describes a specification of I/O mezzanine modules in conjunction with FPGA or another device with configurable I/O capability. The design allows use on any industry standard slot card with form factors such as VME, VPX, CompactPCI, AdvancedTCA, MicroTCA, PCI, PXI, and many others.. Wakefield-Vette can customize your specific application needs for custom FMC & PMC Bezels.

### FEATURES

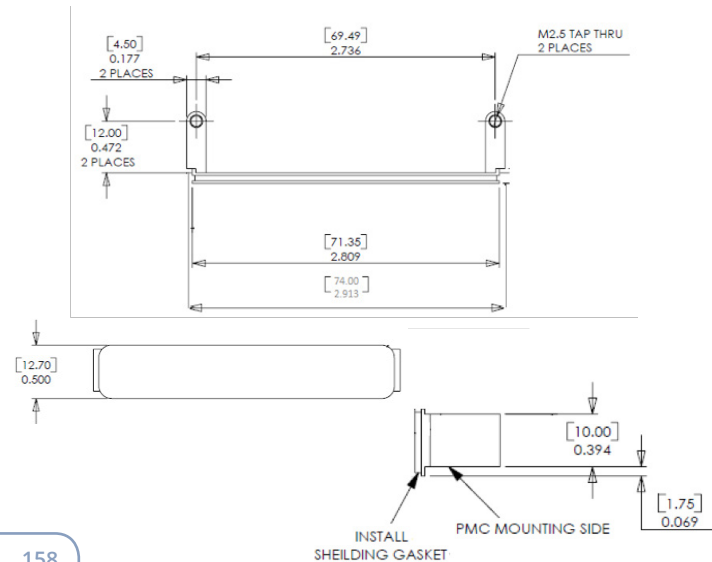
- Material: Aluminum
- Kit: Bezel, Elastomer Gasket, Two M2.5 x 6mm PH Stainless Steel Screws
- Custom cutouts, silkscreen or overlays available

WV Part Number	Description	Kit Description	Size
PMC-BEZEL-KIT-01	Aluminum PMC Bezel Kit (1050056-00)	PMC Bezel, Elastomer Gasket, Qty. Two M2.5 x 6mm Screws	0.659" L x 0.500" W x 2.913" H (16.75mm x 12.70mm x 74.00mm)
FMC-BEZEL-KIT-01	Aluminum FMC Bezel Kit (1050117-00)	FMC Bezel, Elastomer Gasket, Qty. Two M2.5 x 6mm Screws	0.659" L x 0.500" W x 2.404" H (16.75mm x 12.70mm x 61.00mm)
PMC-GASKET-01	PMC EMC GASKET O RING (1070010-00)	Spare, Replacement Component	
FMC-GASKET-01	FMC EMC GASKET O RING (1070036-00)	Spare, Replacement Component	



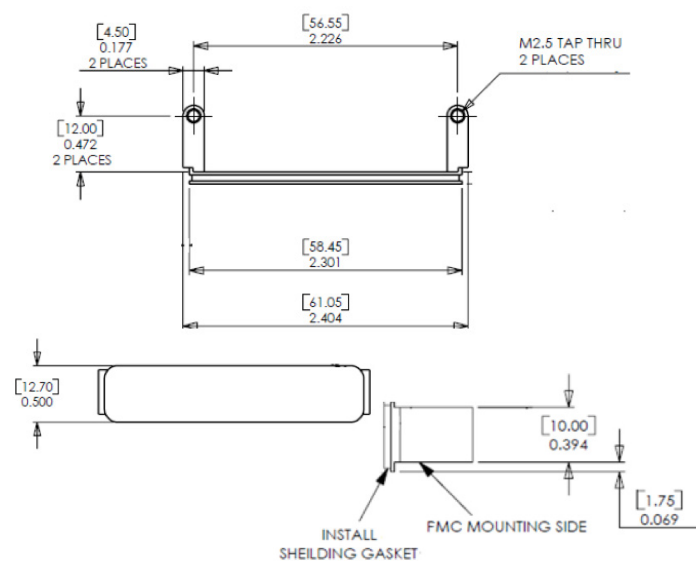
### PMC-BEZEL-KIT-01

KIT WITH PMC GASKET & MOUNTING HARDWARE



### FMC-BEZEL-KIT-01

KIT WITH FMC GASKET & MOUNTING HARDWARE



## WEDGELOCKS



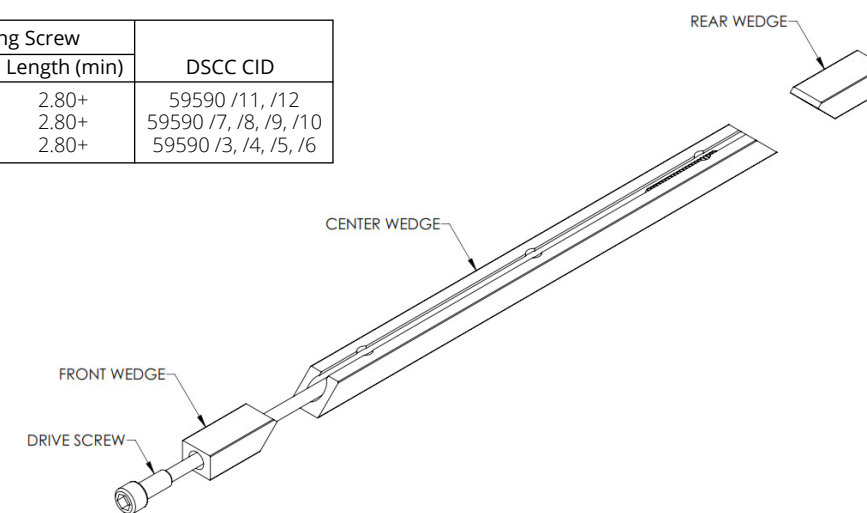
Rugged fastener or retainer used to clamp a PCB within a cold wall slot.

- Provides clamping force to resist shock and vibration in rugged environments
- Provides a thermally conductive path from the heat frame to the cold wall
- Flexible mounting options to meet customer requirements
- Available separately or integrated into Heat Frame
- Ability to cross competitors Part Numbers

Wedgelocks are available in various profiles and allow for configurable length, mounting and plating selections. For configurations not shown within the data sheets, please contact the factory to review.

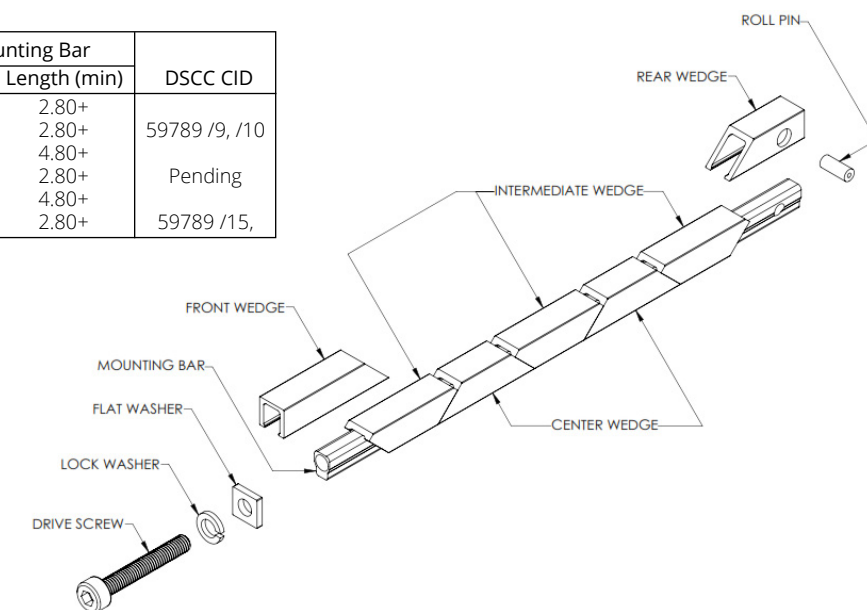
### "B" STYLE WEDGELOCK

"B" Style	# of Wedges	Assembly with Long Screw			DSCC CID
		Height	Width	Length (min)	
418B	3	0.180	0.240	2.80+	59590 /11, /12
422B	3	0.220	0.220	2.80+	59590 /7, /8, /9, /10
426B	3	0.260	0.225	2.80+	59590 /3, /4, /5, /6



### "C" STYLE WEDGELOCK

"C" Style	# of Wedges	Assembly with Mounting Bar			DSCC CID
		Height	Width	Length (min)	
419C	5	0.192	0.25	2.80+	59789 /9, /10
422C	5	0.225	0.225	2.80+	
422C7	7	0.225	0.225	4.80+	
426C	5	0.260	0.250	2.80+	Pending
426C7	7	0.260	0.250	4.80+	
438C	5	0.375	0.365	2.80+	59789 /15,

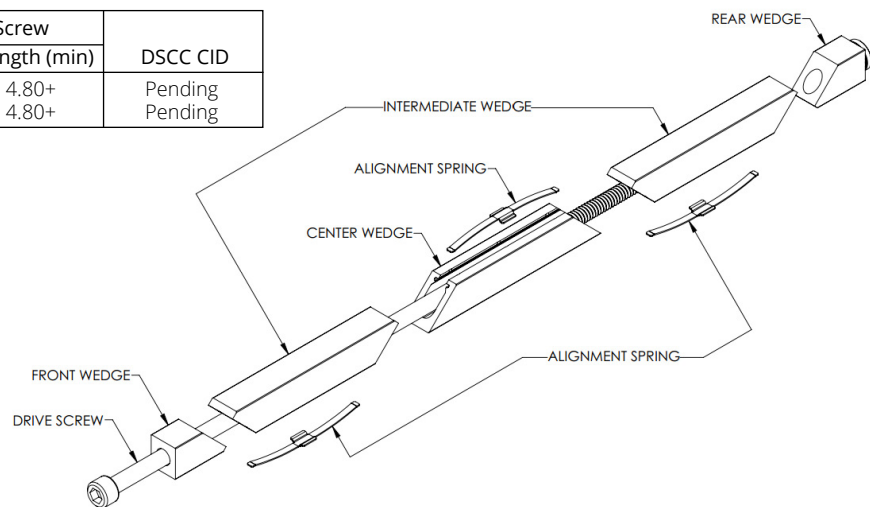


\* All dimension provided in Inches  
 \*\* Standard profiles and lengths listed, inquire for other sizes

## WEDGELOCKS

### "D" STYLE WEDGELOCK

"D" Style	# of Wedges	Assembly with Long Screw			DSCC CID
		Height	Width	Length (min)	
422D	5	0.220	0.220	4.80+	Pending
426D	5	0.260	0.225	4.80+	Pending



\* All dimension provided in Inches  
 \*\* Standard profiles and lengths listed, inquire for other sizes

### WAVELOCK™ DATA SHEET

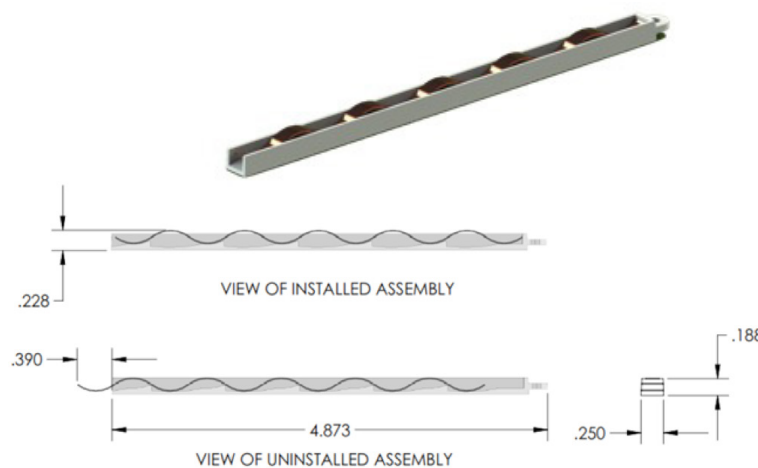
**Wavelock™** is a patent-pending, low-cost, high-performing, form fit, and function alternative to wedgelocks for some applications. A Wavelock assembly consists of only two discrete parts and represents the simplest form of a card retainer within a wedgelock envelope. The discrete parts are a wave spring and an injection molded carrier. Additional benefits include easy tool-free installation and visual indication of correct installation.

FEATURES AND BENEFITS
<ul style="list-style-type: none"> <li>• Low cost for light shock and vibration applications.</li> <li>• Light weight assembly with uniform clamping force.</li> <li>• Narrow width for maximum PCB component area.</li> <li>• Low profile design allows for decreased slot pitch.</li> <li>• Special lengths, finish, and other design options available.</li> </ul>

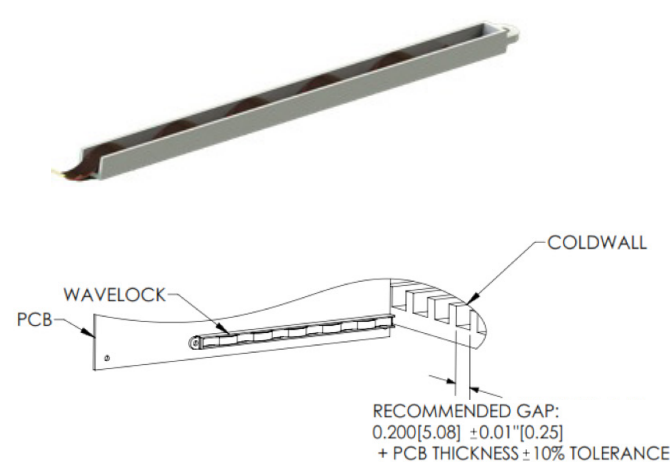
MATERIAL
<ul style="list-style-type: none"> <li>• Carrier: Polysulfone (PSU)</li> <li>• Wave Spring: 17-7 PH Stainless Condition C to CH900</li> </ul>



ENGAGED STATE



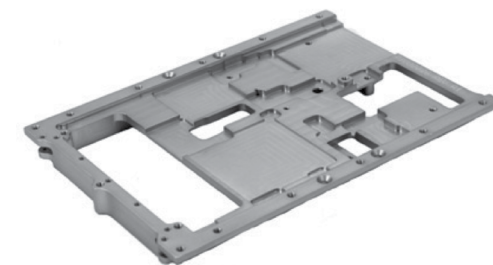
RELAXED STATE



## HEAT FRAMES

Milled aluminum heat frames are used with electronics design to meet or exceed rugged specification requirements.

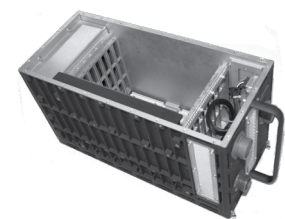
Heat frames are CNC precision-machined out of solid aluminum (or copper) and precisely match the topography or skyline of an electronic printed circuit board being ruggedized.



FEATURES AND OPTIONS
<ul style="list-style-type: none"> <li>• Plating options include Chromate, Black Anodize, and Electroless Nickel.</li> <li>• Integrated Heatpipes when needed</li> <li>• When combined with thermal-interface material or "gap pads," conduction-cooled heat frames increase a board's operating temperature range, as well as its resistance to shock and vibration.</li> <li>• Designs can integrate Front or Rear I/O and can also include Top and Bottom Covers for compliance with Two-Level Maintenance.</li> <li>• When integrated with wedgelocks and ejectors, this product allows VME, cPCI and other boards to fit within conduction cooled chassis slot dimensions with zero insertion force.</li> </ul>

APPLICATIONS
<ul style="list-style-type: none"> <li>• IEEE 1101.2</li> <li>• VITA 30.1</li> <li>• VITA 48 (both 0.8" and 1.0" slot pitch)</li> <li>• Mezzanine cards</li> <li>• Ruggedized Enviroments</li> </ul>

## ATR BOXES / ENCLOSURES



Typically the rugged housings for multiple VME, CompactPCI or VPX computers boards. Enclosures can be bolted, brazed or epoxied together.

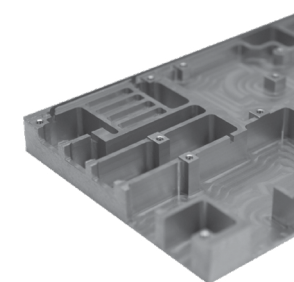
- Standard configuration COTS and Custom ATR enclosures
- Power supply and Backplane available when required
- Brazed or Epoxied and bolted Solutions
- Complete Custom Design capabilities to meet specific customer constraints
- Finishes Anodize :
- Chem Film
- Dual Plating
- Painting

## COMPLEX RF SHIELD ENCLOSURES

Complex machined parts can be executed through Wakefield-Vette's North Carolina facility. One major product line it supports intricate machined parts for the RF industry.

RF shielded enclosures refers to any box, chassis, or other packaging that prevents the passing of electromagnetic interference or radio frequency.

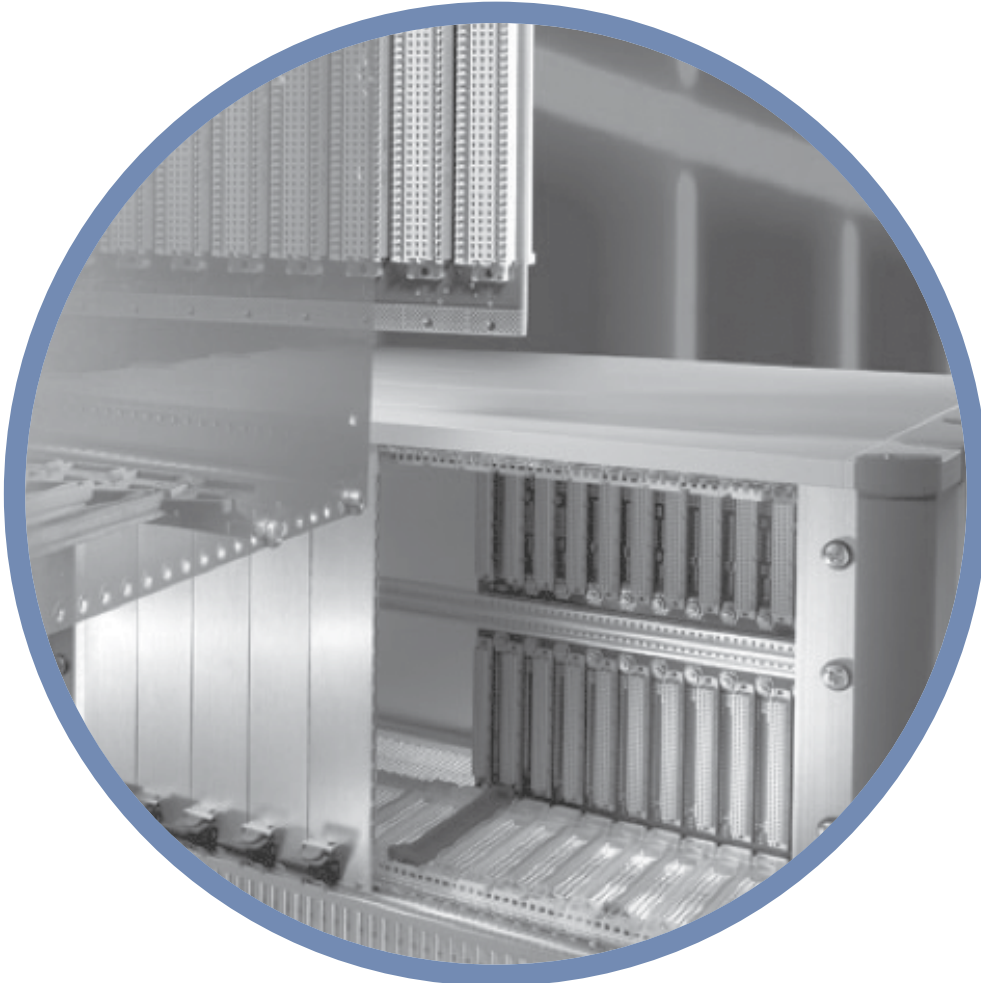
APPLICATIONS	
<ul style="list-style-type: none"> <li>• Desktop Shielded Enclosure</li> <li>• Software-defined Radios</li> <li>• Rugged/Embedded Computing</li> <li>• TEMPEST/Secure Computing</li> </ul>	<ul style="list-style-type: none"> <li>• Sensor Equipment</li> <li>• Surveillance Equipment</li> <li>• Tactical Devices</li> <li>• EMI Shielded Enclosure for Communications Equipment</li> </ul>



# ELECTRONICS PACKAGING SYSTEMS

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*Electronic Packaging Systems* ..... 164-165  
*System Level Packaging* ..... 166-167



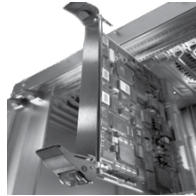
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*Wakefield-Vette manufactures both custom and standard electronic packaging solutions. In June of 2015, Wakefield-Vette announced an exclusive strategic partnership with Heitec AG, a recognized leader in electronic packaging systems (EPS), to sell, customize, and service the Heitec product line (formerly Rittal) to the North American marketplace.*

*Wakefield-Vette has the ability to modify a customer's unique specification within a quick turnaround time which separates it broad product line from the rest in North America.*

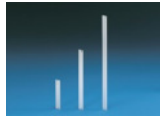
*Wakefield-Vette has achieved a leading position in the Rugged COTS packaging marketplace, providing for VME/VME64x, VXS/VPX, VXI,PXI, AdvancedTCA, and MicroTCA, and CompactPCI/2.16 architectures.*

## ELECTRONIC PACKAGING SYSTEMS



### FRONT PANELS & EJECTOR HANDLES

Wakefield-Vette manufactures custom front panels that are silk-screened, fully assembled, and ready to mount to your PCB. Parts are made from extrusion and manufactured on high-speed CNC machines to mill your custom cut outs and features, providing a superior finish and precision fit to your board. We also have the ability to stamp front panel cutouts to meet your specifications or high volume requirements.



#### STANDARD FRONT PANELS

Subrack system for direct mounting in a cabinet. Mounting either on top hat rails or on mounting plate. Suitable for installation of standardized PCBs or plug-in units.



#### INJECTORS & EJECTORS

We offer all VME and compactPCI related front panel accessories, including gaskets and handles to meet Vita 41, 46, 48, 57, and IEEE 1101.10 requirements.



#### CUSTOM FRONT PANELS

In addition to a variety of standard finishes and options, Wakefield-Vette offers custom front panel production along with our in-house silk-screening process. We offer build to order ATCA and PCI panels, as well as customized AMC, PMC, and FMC bezels.



#### MEZZANINE FRONT PANELS

Extruded aluminum and Zinc Die Cast for PCI mezzanine cards and conforms to IEEE 1386.

### ELECTRONIC PACKAGING SYSTEMS COMPONENTS



Besides complete subrack and system solutions Wakefield-Vette offers a wide range of individual components and accessories for setup, mounting and upgrade. Our inside and outside sales staff will gladly help you to find the right selection of components and support you in compiling the optimum package to fulfill your individual preferences and requirements.



#### CARD GUIDES

Keyable Guide rails to IEEE 1101.10. Prepared to accommodate a ground contact for assembly of a plug-type connection. Available in different form factors and material including plastic.



#### COVERS

Covers are slid into the front and rear horizontal rails for mounting backplanes/connectors. There are several styles of this product line.



#### HORIZONTAL RAILS

The adaptor rails accommodate the guide rails when fastened to the center horizontal rail. Front and rear horizontal rails available to meet the very simple to the very complex subrack configurations including rails to meet the IEEE 11001.10/1101.11 specifications.



#### BACKPLANES

Wakefield-Vette offers various backplanes. Our engineering team can help assist in any backplane design with your PICMG, VITA-based, VME, VME 64X, cPCI, uTCA, or custom architecture design.



### SUBRACKS

The modular concept of Ripac subracks facilitates a wide range of application options with a minimum of components. All Ripac subracks are based on the same horizontal rails and system components. The difference lies in the design of the side panels and installation options. The subracks are shock and vibration-tested and comply with IEC 60 297-3-101, -102, -103.



#### RIPAC COMPACT

Subrack system for direct mounting in a cabinet. Mounting either on Din rails or on mounting plate. Suitable for installation of standardized PCBs or plug-in units.



#### RIPAC ECO

Subrack system for standard applications. Suitable for installation of standardized PCBs or plug-in units of 160 and 220 mm depth.



#### RIPAC VARIO EMC

Subrack system for EMC applications or complex installations. Suitable for installation of standardized PCBs or plug-in units up to 400 mm depth.



#### RIPAC EASY

Subrack system for standard applications or high mechanical loads. In cases that require easy handling and fast assembly.



#### RIPAC VARIO

Subrack system for standard applications or complex installations. Suitable for installation of standardized PCBs or plug-in units up to 400 mm depth.



#### RIPAC VARIO MOBILE

Subrack system for applications in rail vehicles. Suitable for installation of standardized PCBs or plug-in units.



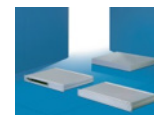
### ELECTRONIC CASES

The RiCase instrument case impresses with its modern design and high functionality. Particular features include the numerous color variants and the all-metal enclosure construction. The Ripac Vario-Module system enclosure (desktop or rack-mount enclosure) is fully compatible with the latest Ripac subrack range, making it ideal for individual configuration and assembly as a microcomputer system. At just 1 U, the HeiBox system enclosure offers a high packaging density in the smallest space.



#### HEIBOX ECO

Cost optimized 1 U system housing for use as rack-mount enclosure or instrument case.



#### RIBOX

Optionally for use as an instrument case or rack-mount enclosure. Accommodates Eurocards/Double Eurocards (horizontal), bridges, hubs, routers or modems.



#### RICASE

Instrument case for installation of 19" slide-in assemblies and elements. For mobile and stationary applications.



#### RIPAC VARIO MODULE

Optionally for use as an instrument case or rack-mount enclosure. External dimensions according to IEC 60 297-1 for installation in enclosures.

## SYSTEM LEVEL PACKAGING



### CPCI / CPCI SERIAL

Wakefield-Vette offers a wide selection of CompactPCI systems that conform to IEC 60 297-3 and IEEE 1101.1/10/11, as well as PICMG 2.0. Systems include backplane and power supply, excellent cooling, fully assembled, pre-wired and tested.



### RACK MOUNT SYSTEMS

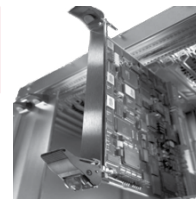
Configuration of 19" industrial computer systems according to CompactPCI specification for Telecommunication and Industrial Automation.



### CPCI SERIAL PLATFORM SYSTEMS

Configuration of 19" industrial computer systems according to CompactPCI Serial specification.

### MicroTCA



MicroTCA offers standardized modularity, compact design and high scalability and bandwidth. Additionally, the consistent platform strategy reduces the time to market. Whenever ultra fast data transmission or data storage is required, MicroTCA systems are the first choice. This is true not only for telecom applications but also for industrial control systems or medical engineering.



### CubeTCA

Based on the MTCA specification the compact CubeTCA offers a wide range of application fields in the industrial sector. The CubeTCA can either be assembled directly on the mounting plate or integrated within the target system.



### AIR MANAGEMENT PANELS

Filler sheets are mounted on the AMC face plates and are used to route the airflow in ATCA carriers and MicroTCA systems.



### MicroTCA DEVELOPMENT SYSTEM

Instrument MicroTCA development systems are suited for design of hard and software or for testing AMC modules.



### FACE PLATES

These face plates are used for AMC cards and ATCA carriers, or as filler panels in MicroTCA systems.



### MicroTCA RACK MOUNT SYSTEMS

MicroTCA specification is designed as an amendment to the ATCA standard as a lower-cost compact version for the low-end sector. The main features are a compact design, high scalability, modularity and considerably reduced system costs.



### PicoTCA

Based on the MTCA specification, PicoTCA is a modular ready-to-run system, which carries up to 12 AMCs and 1 MCH. Due to the robust construction, the 19" rack can be used both in the telecommunication and in the industrial sector.

### VME



Wakefield-Vette supplies complete plug & play solutions for VME applications. Systems are based on standard components which may be configured to your specification. VME systems are complete with power supply, backplane, measures for EMC and ESD protection, climate control, fully assembled, pre-wired, and tested.



### BACKPLANES

The VME64 is a new addition to the VME family to ANSI/VITA 1-1994 and supports 64-bit data traffic. The VME64x extends the VME family to ANSI/VITA 1.1-1997 and is available with the optional 133-pole 2 mm connector J0. 160-pole connectors are used with VME64x.



### MPS MONITORING

The monitoring electronics for microcomputer packaging systems (MPS) offers a highly flexible, scalable security concept for key parameters such as temperature, voltage and fan speed.



### RACK MOUNT SYSTEMS

Ripac systems available in many different variations. Prepared to accommodate VMEbus boards and drives while having MPS Monitoring feature.



### SLIM BOX VARIO

Configuration of 19" industrial computer systems according to VME specification.



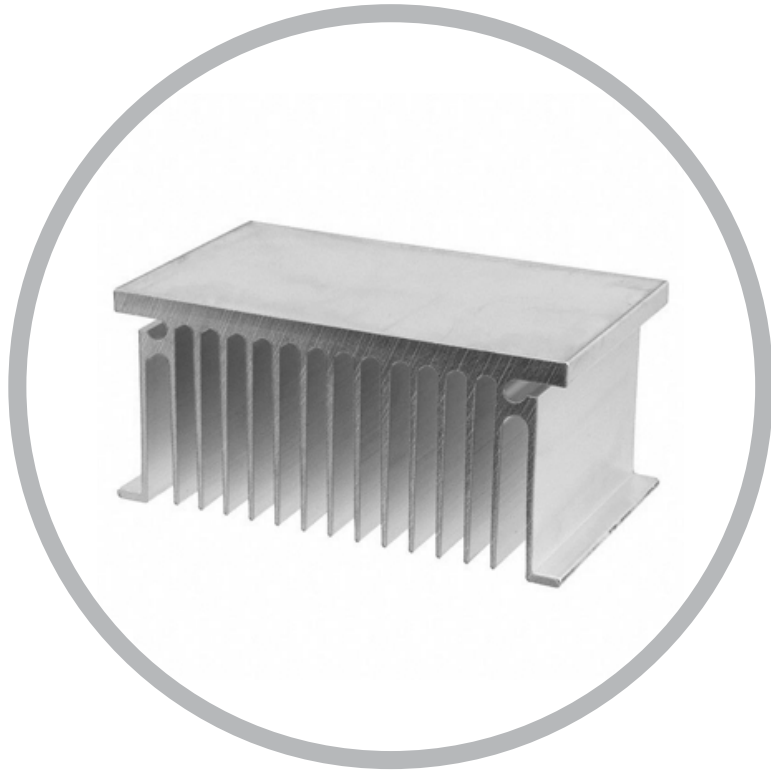
### NOTES

A series of horizontal lines for taking notes, spanning the width of the page.



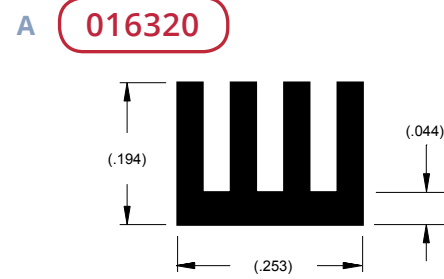
# THERMAL EXTRUSION PROFILES

<i>Flatback Extrusions</i> .....	172-234
<i>L-style Extrusions</i> .....	235-239
<i>Center Channel Extrusions</i> .....	239-245
<i>Multi Channel Extrusions</i> .....	245-247
<i>Flatback with Integral Mounting Feet</i> .....	248-252
<i>T-style Extrusions</i> .....	252-256
<i>H-style Extrusions</i> .....	256-262
<i>Double-Side Extrusions</i> .....	262-263
<i>Mounting Shelf Extrusions</i> .....	263-265
<i>Press Pack Extrusions</i> .....	265-268
<i>Power Module Extrusions</i> .....	268-269
<i>Forced Convection Extrusions</i> .....	269-271
<i>Modular Extrusions / Enclosures</i> .....	271-272
<i>Hollow Extrusions</i> .....	272-273
<i>Miscellaneous Extrusions</i> .....	273-276

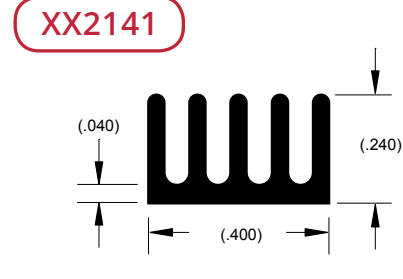


*Extruded heat sinks are the most common heat sink used for thermal management today. They are manufactured by pushing hot aluminum billets through a steel die to produce the final shape. The most common aluminum alloy is 6063-T5, but other 6XXX alloys can also be examined as needed. When the material is extruded, the initial sticks are 30-40 feet and length and are very soft. The material is stretched by grabbing both ends to produce a straight stick. After stretching, the material can be either air or over aged depending upon the required final hardness of the material. After the aging process, the material is cut to the final length and any final fabrication (holes, pockets, or other secondary machining) can be done. Extruded heat sinks are usually supplied with a "finish" such as anodizing which can enhance its thermal performance. The heat sinks can also be supplied with a chromate finish which provides some corrosion protection or can be used as a primer before a final paint or powder coating is applied.*

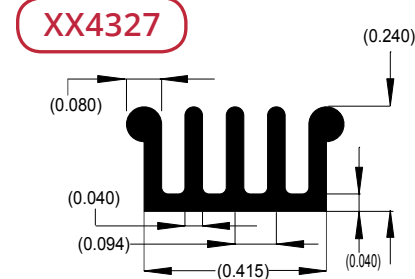
*While each extruded shape is unique to the requirements that it was designed for, extruded heat sinks are the most cost-effective cooling solution. Each shape is engineered to achieve the optimal thermal and structural performance. Wakefield-Vette partners with a large list of vendors which insures that you have the best thermal solution based on your system structure and thermal requirements.*



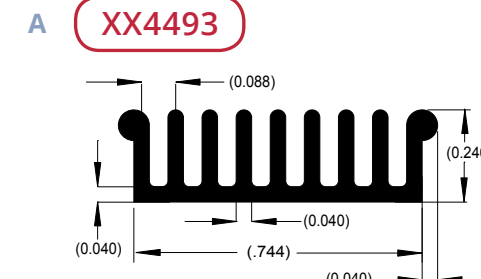
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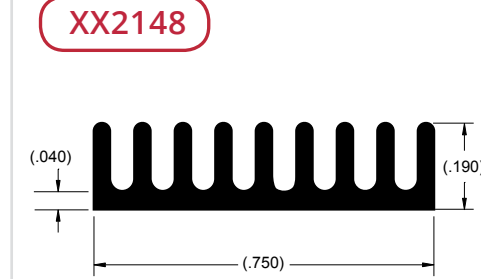
Per.	2.71	in.
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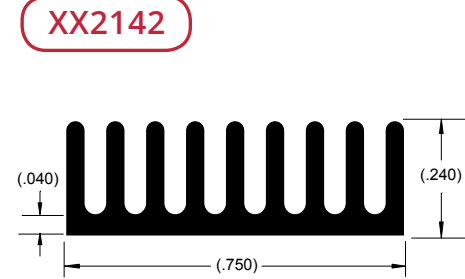
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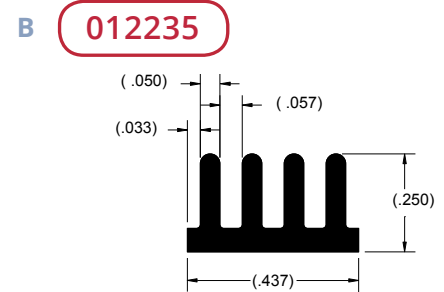
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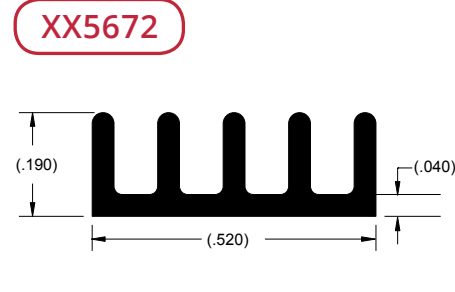
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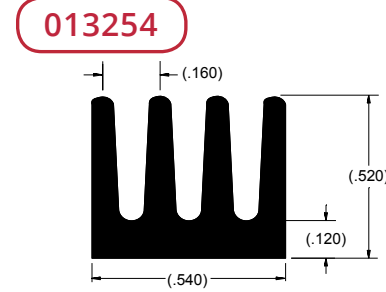
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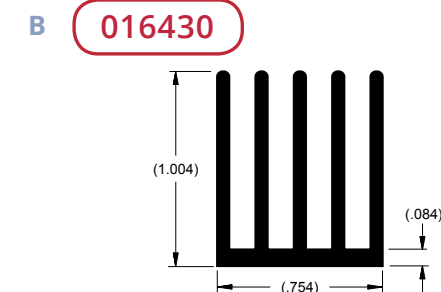
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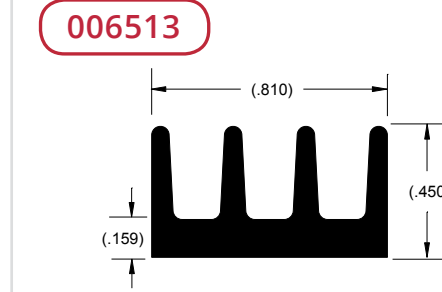
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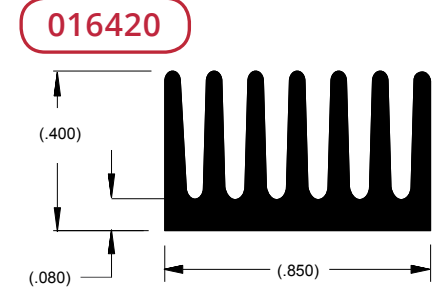
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WT.	0.21	lb/ft
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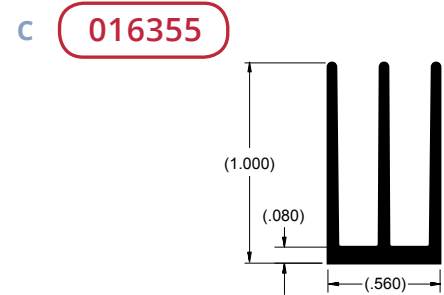
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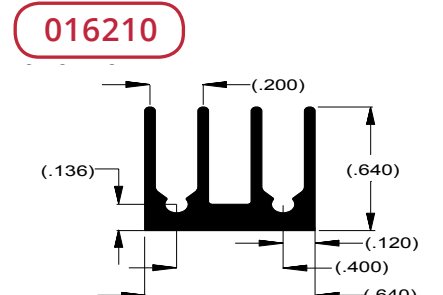
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WT.	0.24	lb/ft
θsa	15.10	°C/w/3"



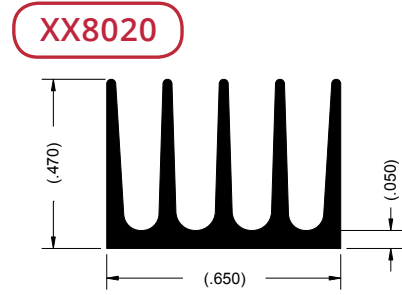
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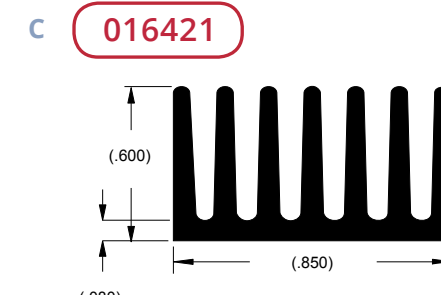
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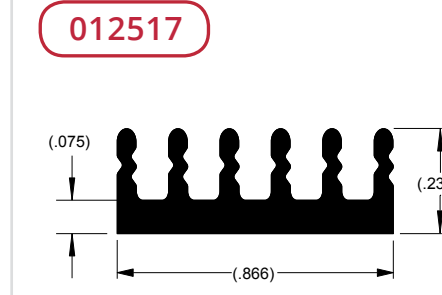
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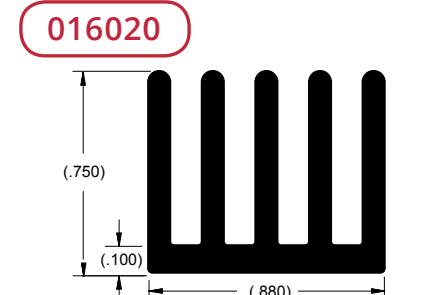
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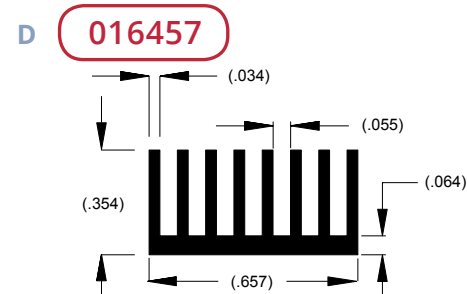
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WT.	0.34	lb/ft
θsa	9.70	°C/w/3"



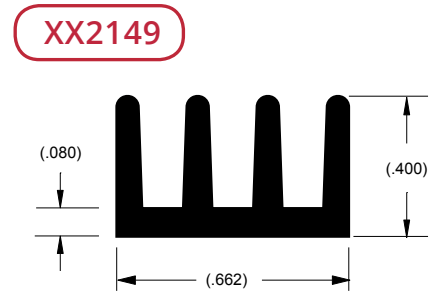
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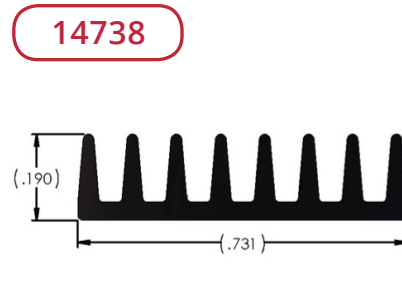
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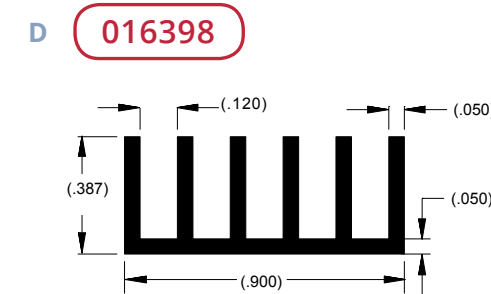
Per.	6.08	in.
WT.	0.15	lb/ft
θsa	15.80	°C/w/3"



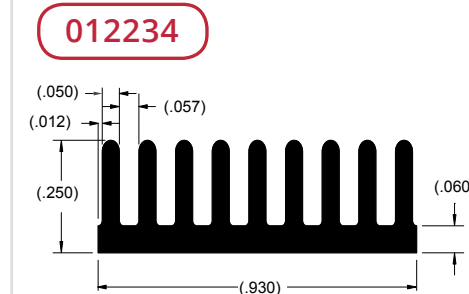
Per.	3.86	in.
WT.	0.14	lb/ft
θsa	8.80	°C/w/3"



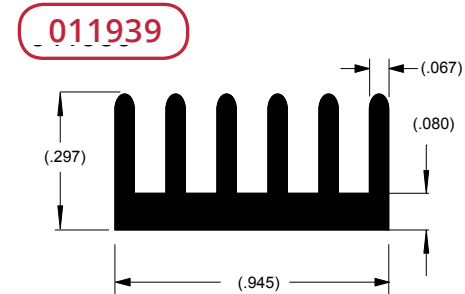
Per.	3.63	in.
WT.	0.08	lb/ft
θsa	19.29	°C/w/3"



Per.	5.94	in.
WT.	0.18	lb/ft
θsa	12.30	°C/w/3"

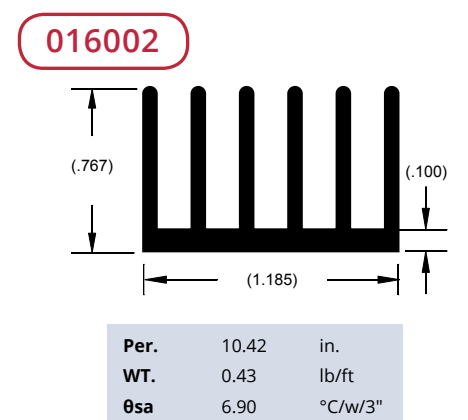
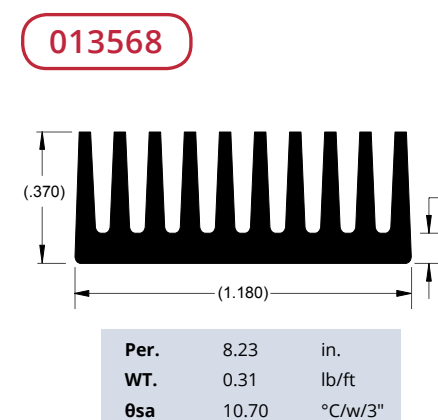
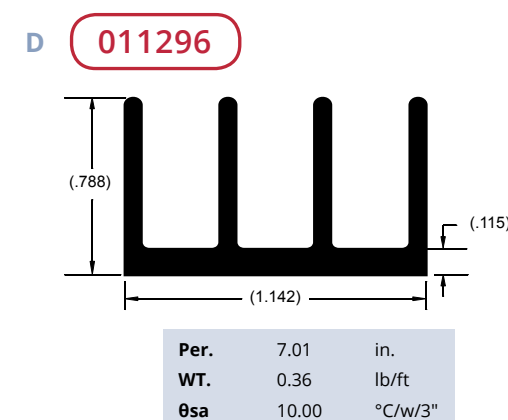
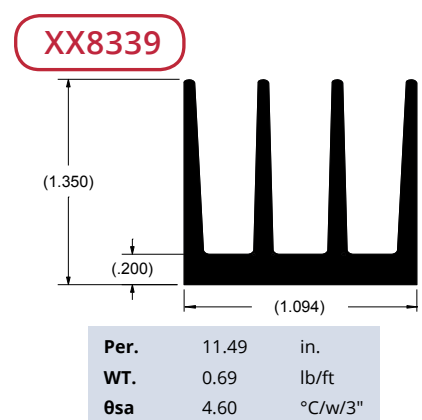
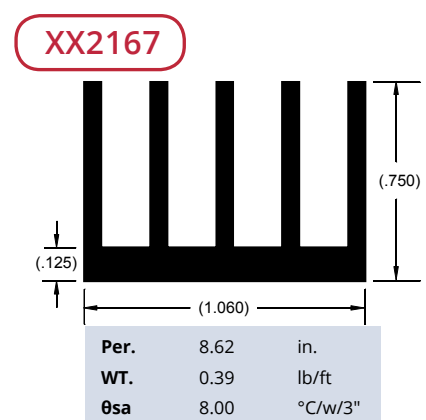
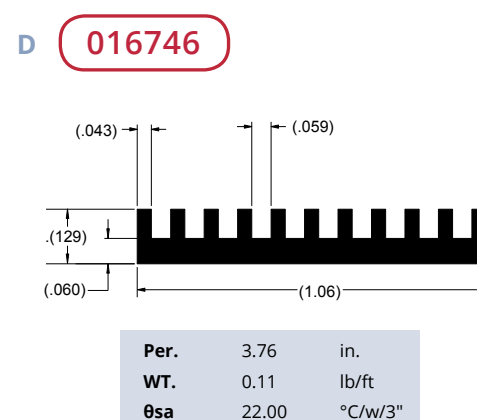
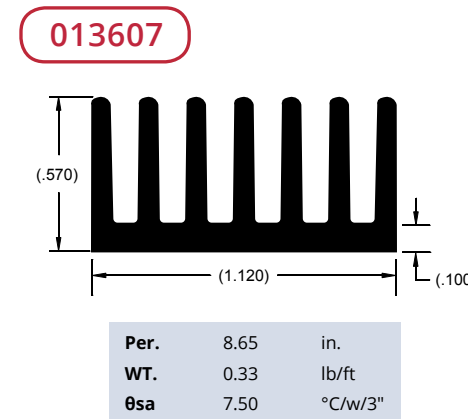
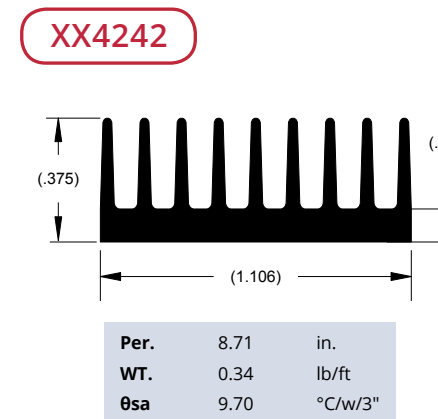
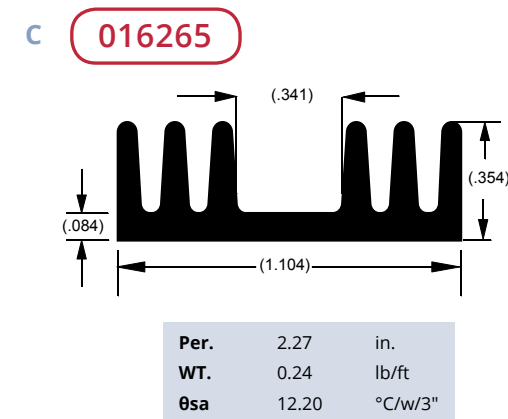
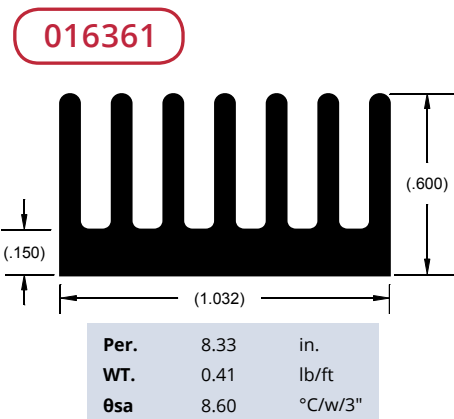
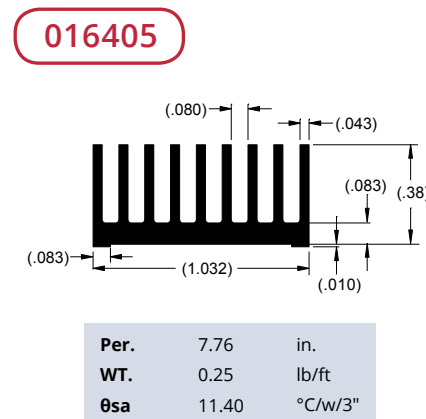
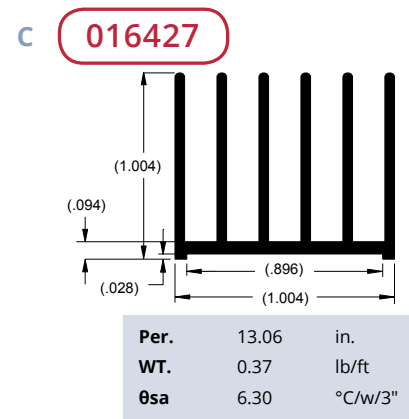
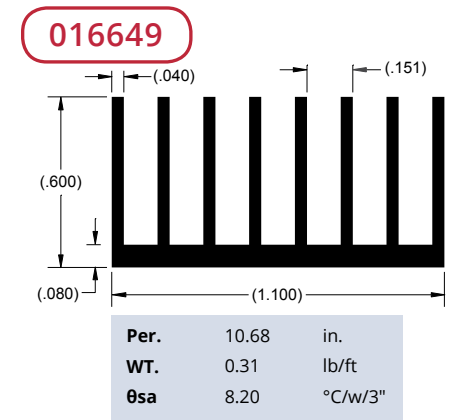
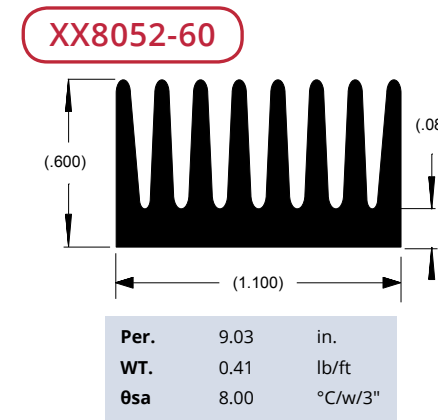
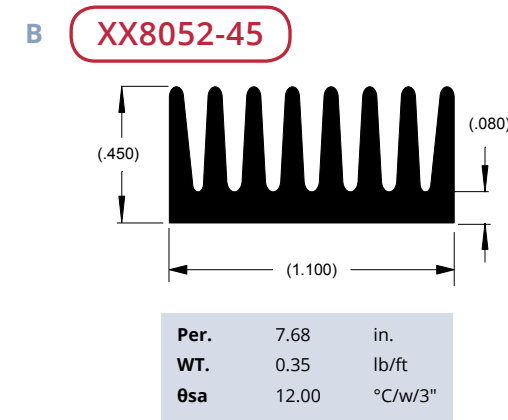
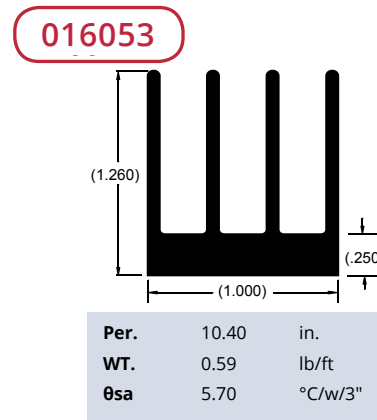
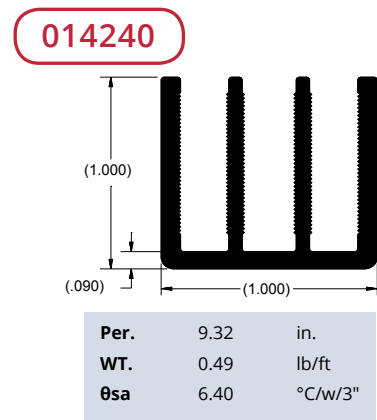
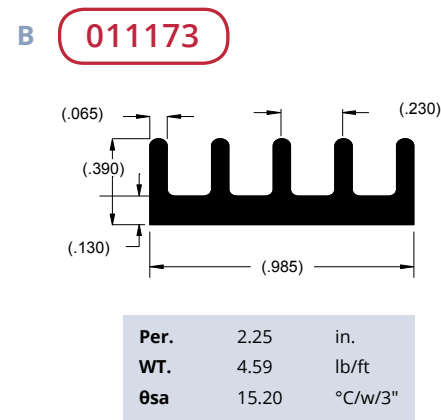
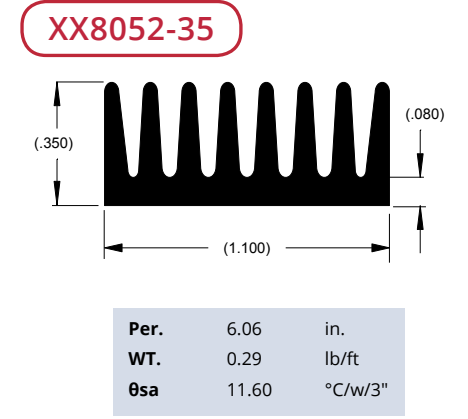
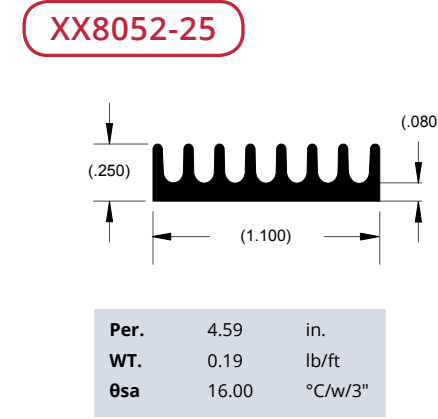
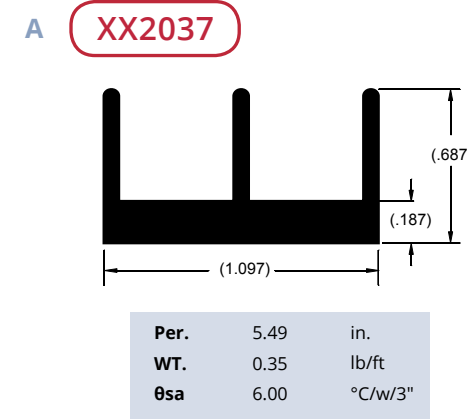
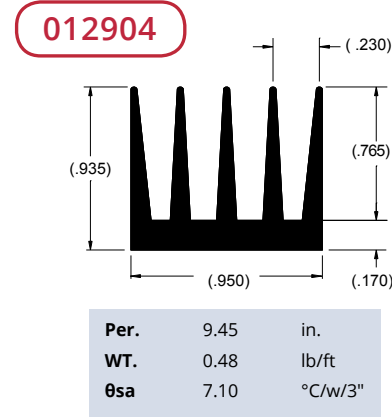
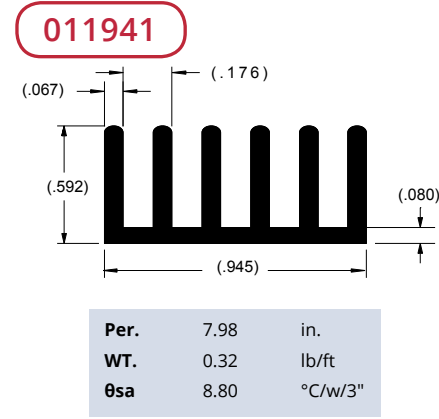
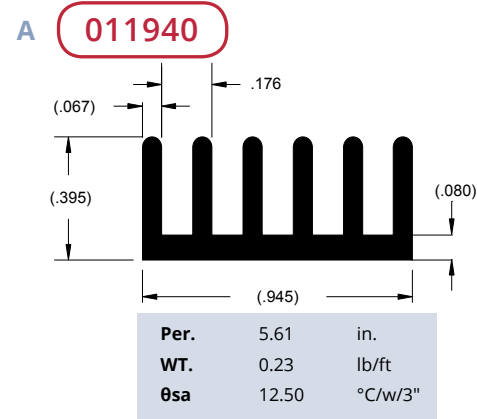


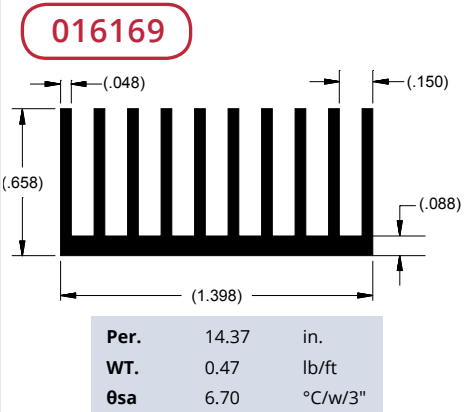
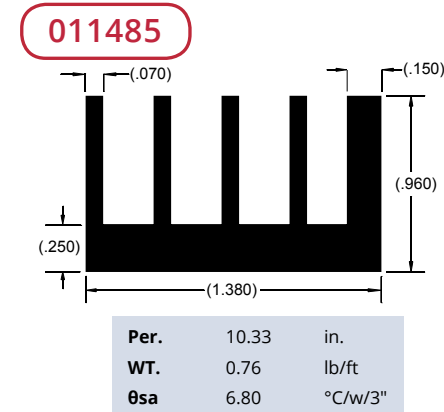
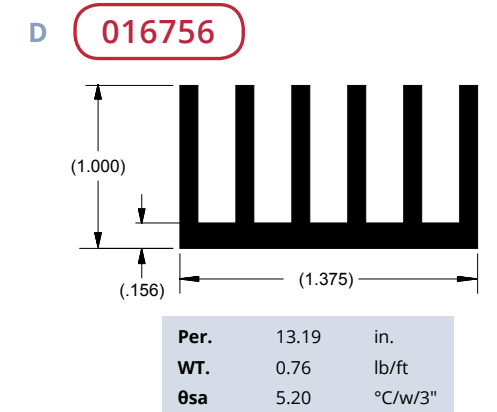
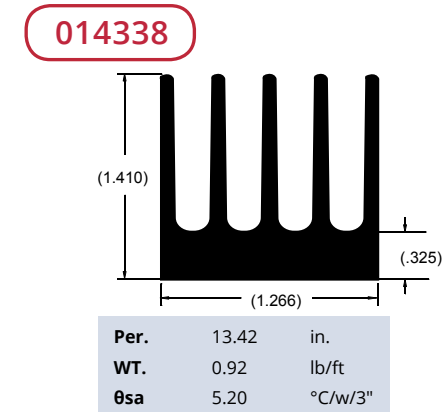
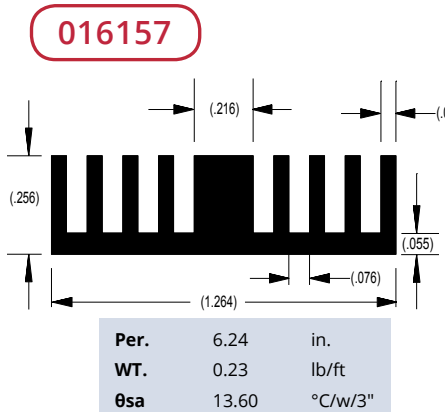
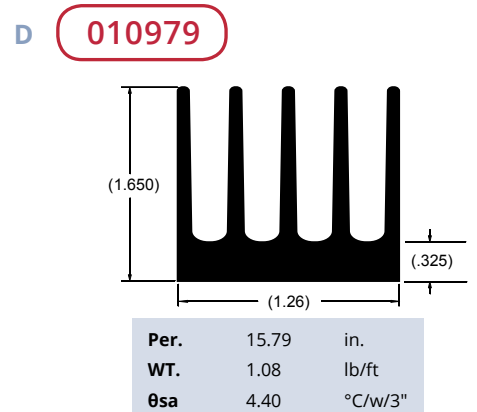
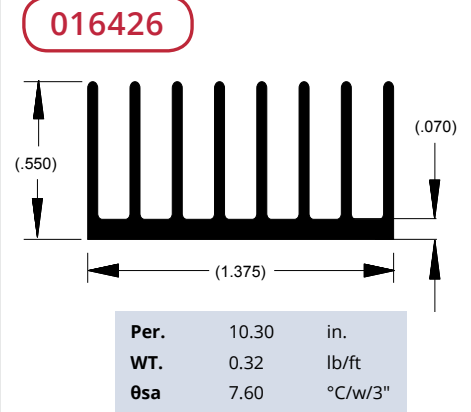
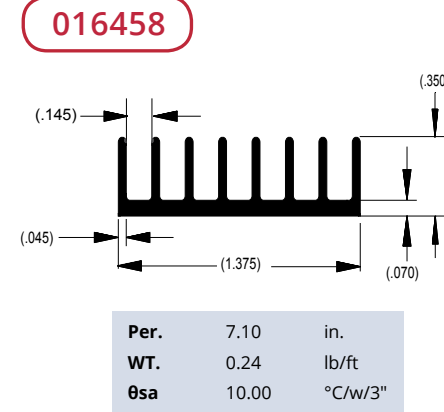
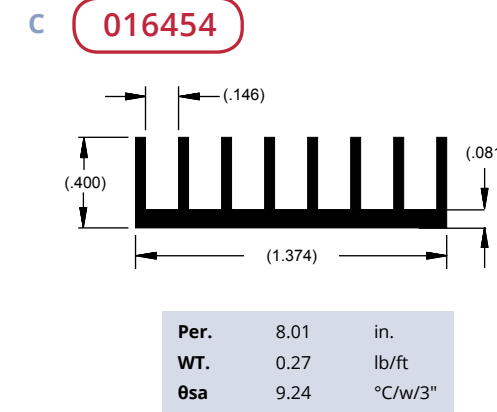
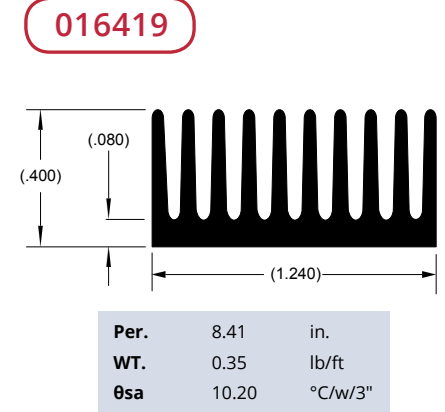
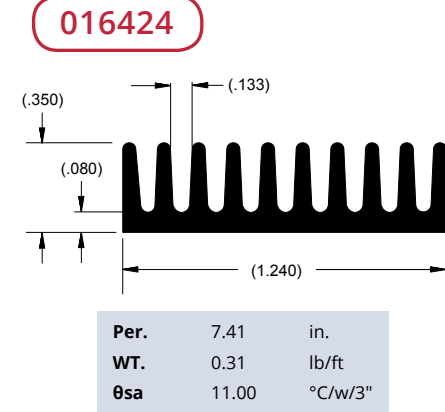
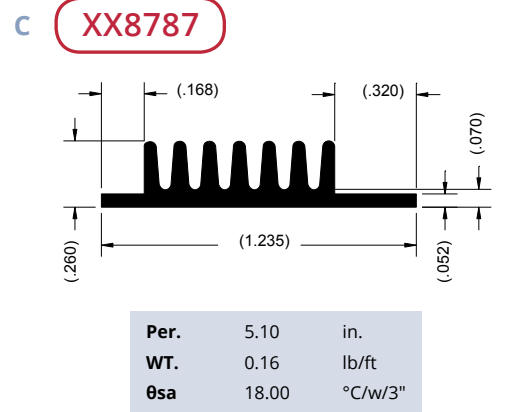
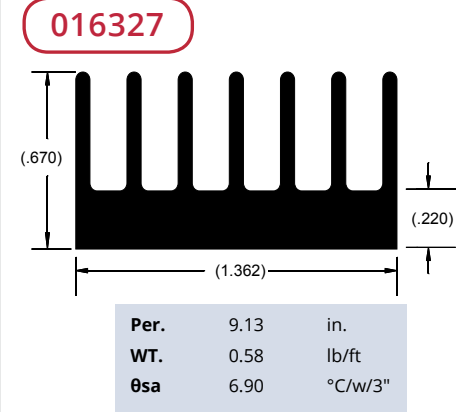
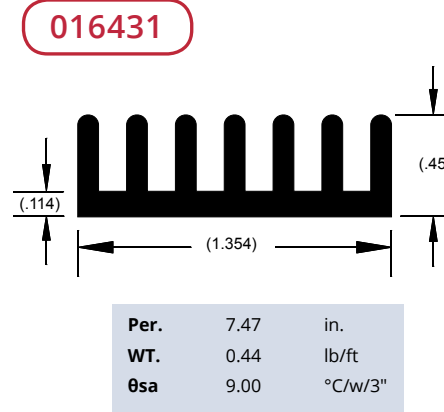
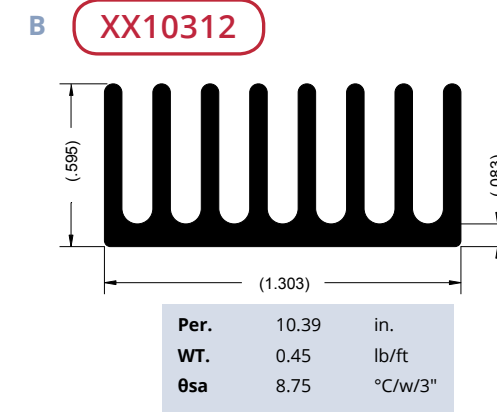
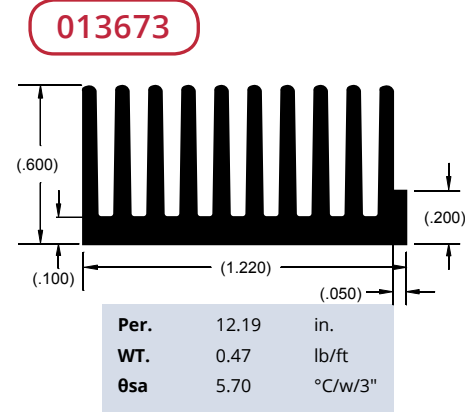
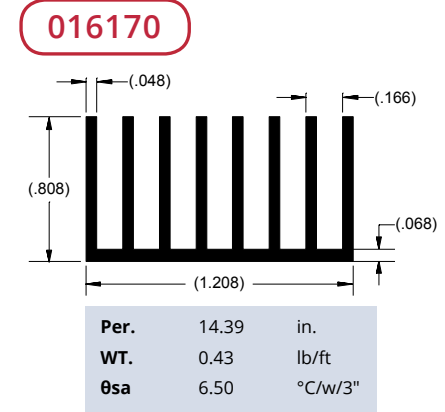
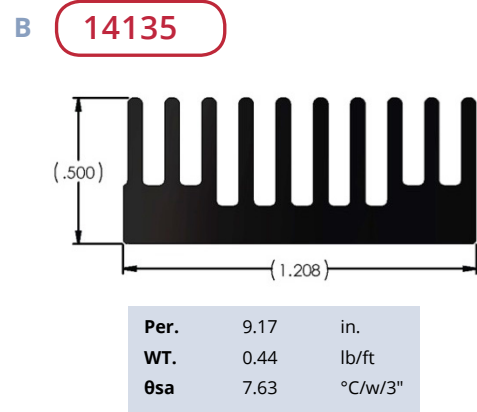
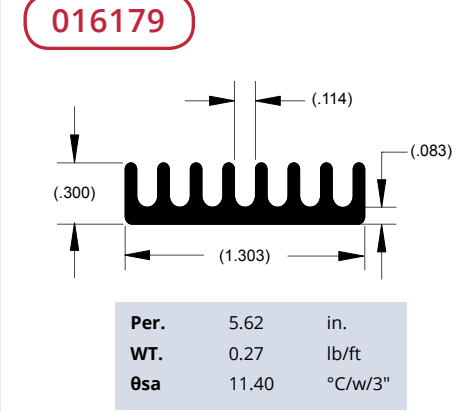
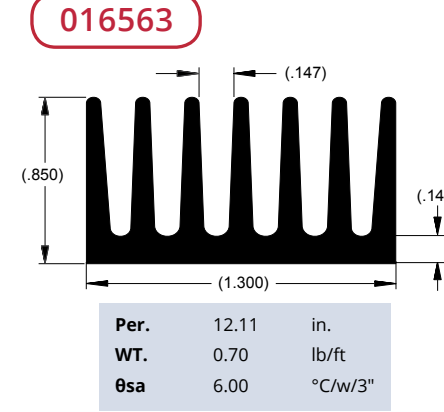
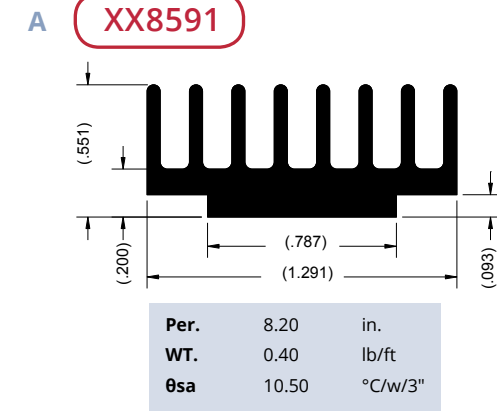
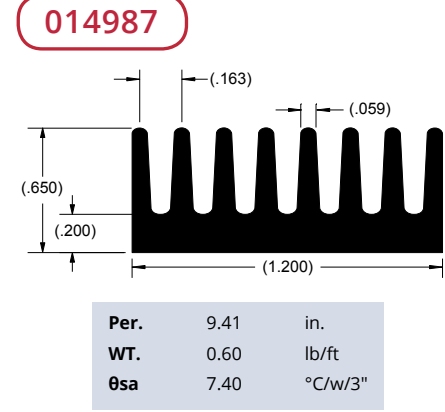
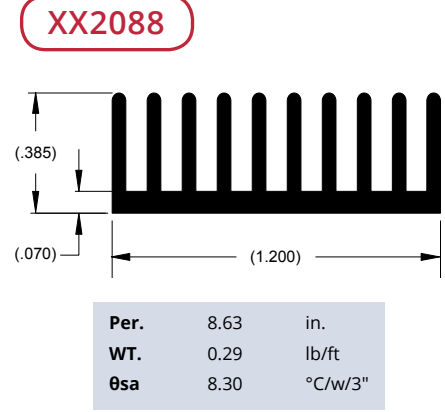
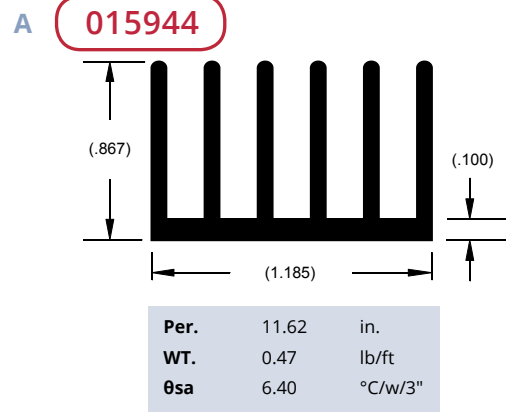
Per.	5.13	in.
WT.	0.16	lb/ft
θsa	13.64	°C/w/3"

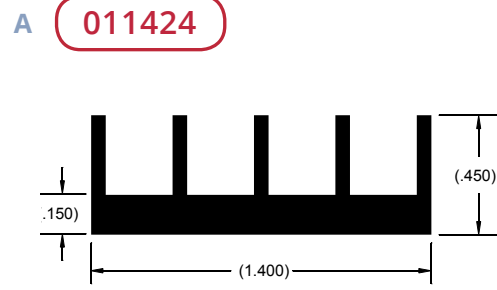


Per.	4.44	in.
WT.	0.19	lb/ft
θsa	15.60	°C/w/3"

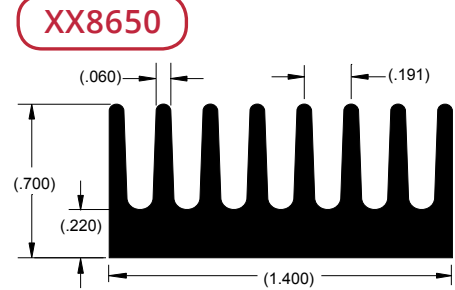




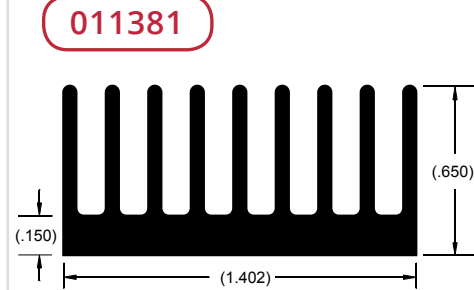




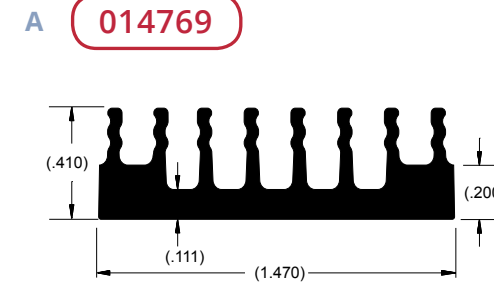
**Per.** 6.07 in.  
**WT.** 0.35 lb/ft  
**θsa** 11.50 °C/w/3"



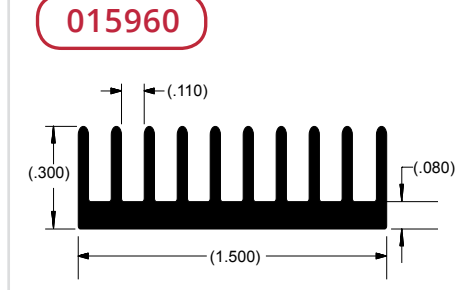
**Per.** 10.22 in.  
**WT.** 0.70 lb/ft  
**θsa** 8.80 °C/w/3"



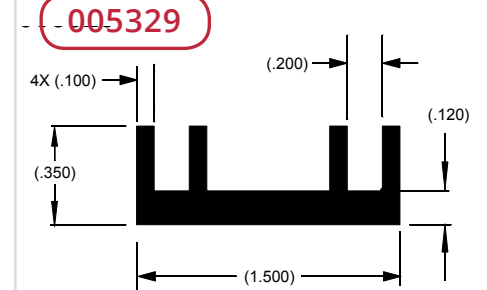
**Per.** 11.23 in.  
**WT.** 0.52 lb/ft  
**θsa** 6.20 °C/w/3"



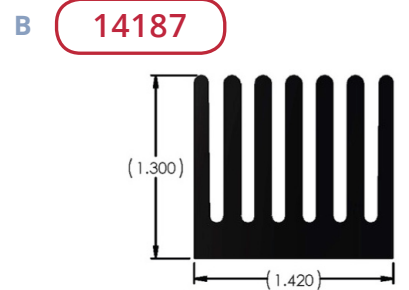
**Per.** 7.44 in.  
**WT.** 0.39 lb/ft  
**θsa** 8.80 °C/w/3"



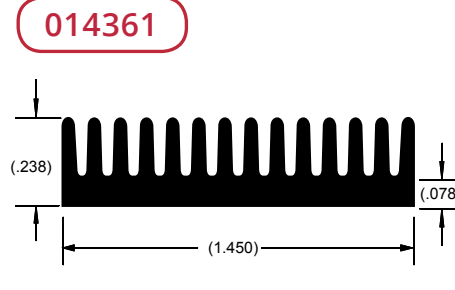
**Per.** 7.35 in.  
**WT.** 0.27 lb/ft  
**θsa** 10.50 °C/w/3"



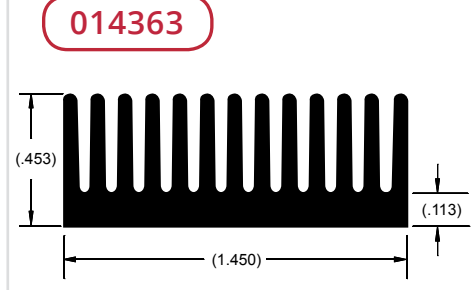
**Per.** 5.54 in.  
**WT.** 0.33 lb/ft  
**θsa** 12.70 °C/w/3"



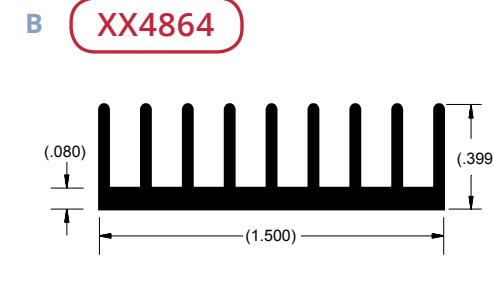
**Per.** 17.42 in.  
**WT.** 1.44 lb/ft  
**θsa** 4.01 °C/w/3"



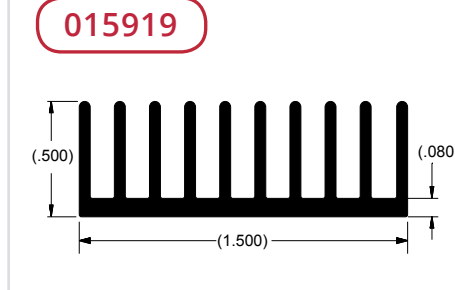
**Per.** 6.89 in.  
**WT.** 0.25 lb/ft  
**θsa** 10.20 °C/w/3"



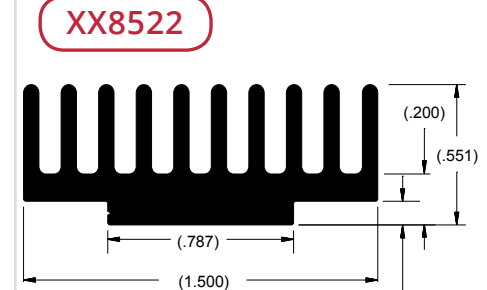
**Per.** 11.27 in.  
**WT.** 0.47 lb/ft  
**θsa** 6.20 °C/w/3"



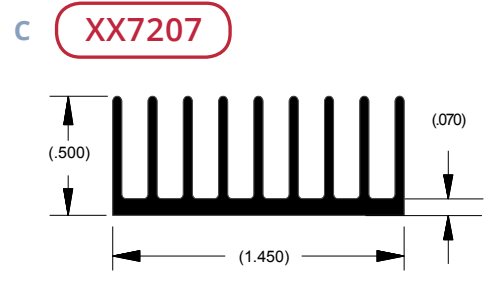
**Per.** 8.47 in.  
**WT.** 0.28 lb/ft  
**θsa** 9.60 °C/w/3"



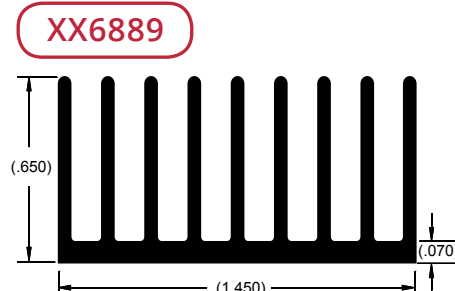
**Per.** 11.35 in.  
**WT.** 0.39 lb/ft  
**θsa** 7.70 °C/w/3"



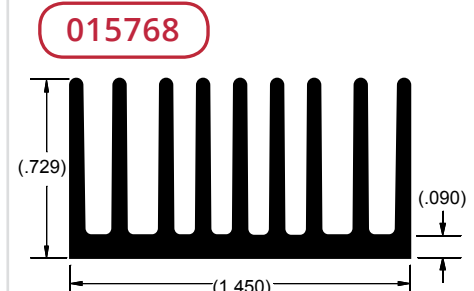
**Per.** 9.88 in.  
**WT.** 0.55 lb/ft  
**θsa** 9.80 °C/w/3"



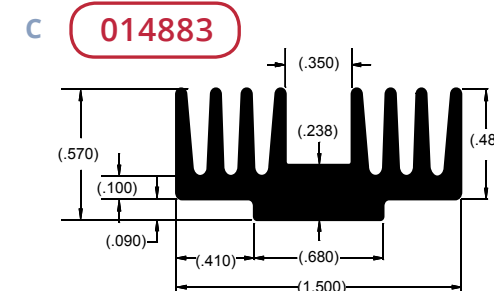
**Per.** 10.78 in.  
**WT.** 0.33 lb/ft  
**θsa** 7.00 °C/w/3"



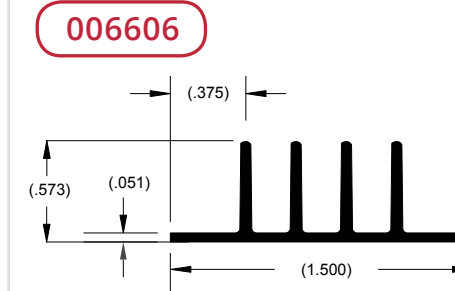
**Per.** 13.20 in.  
**WT.** 0.40 lb/ft  
**θsa** 6.20 °C/w/3"



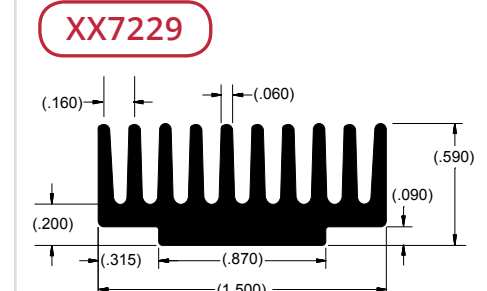
**Per.** 14.12 in.  
**WT.** 0.54 lb/ft  
**θsa** 6.20 °C/w/3"



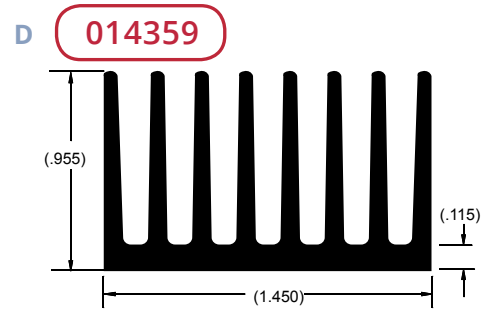
**Per.** 8.65 in.  
**WT.** 0.51 lb/ft  
**θsa** 8.10 °C/w/3"



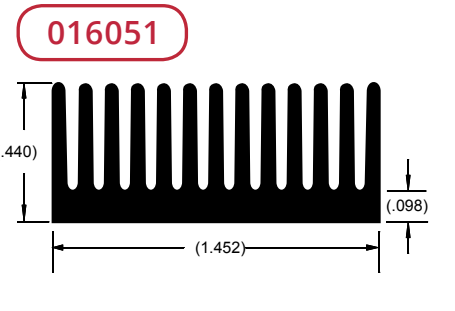
**Per.** 7.07 in.  
**WT.** 0.23 lb/ft  
**θsa** 9.60 °C/w/3"



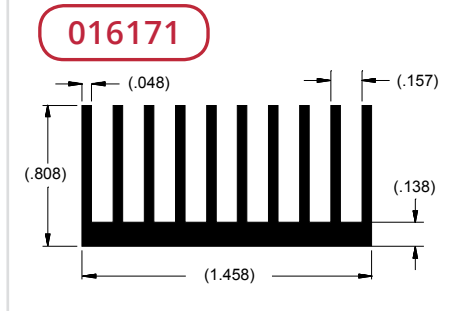
**Per.** 10.40 in.  
**WT.** 0.61 lb/ft  
**θsa** 7.00 °C/w/3"



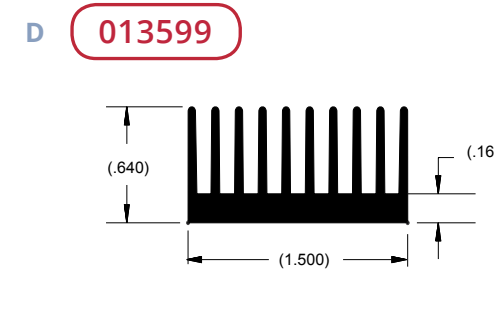
**Per.** 15.97 in.  
**WT.** 0.70 lb/ft  
**θsa** 4.40 °C/w/3"



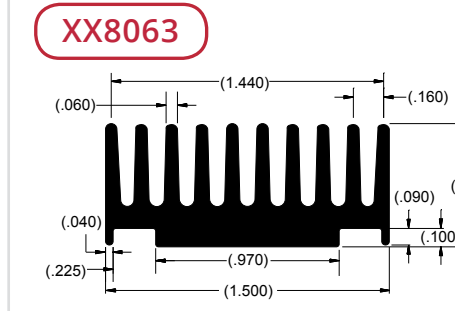
**Per.** 11.25 in.  
**WT.** 0.47 lb/ft  
**θsa** 9.40 °C/w/3"



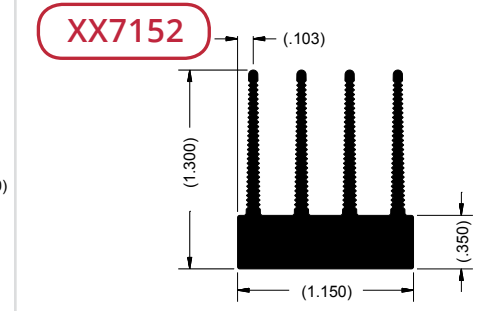
**Per.** 16.56 in.  
**WT.** 0.63 lb/ft  
**θsa** 5.70 °C/w/3"



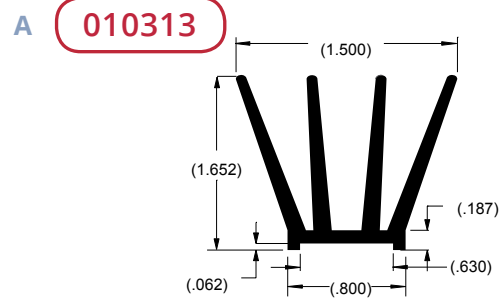
**Per.** 12.72 in.  
**WT.** 6.07 lb/ft  
**θsa** 6.80 °C/w/3"



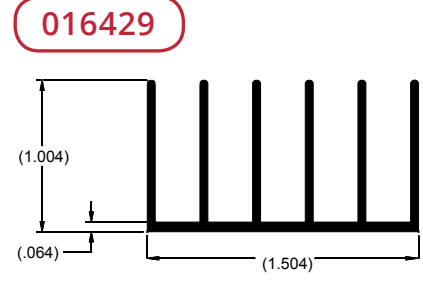
**Per.** 11.97 in.  
**WT.** 0.72 lb/ft  
**θsa** 6.00 °C/w/3"



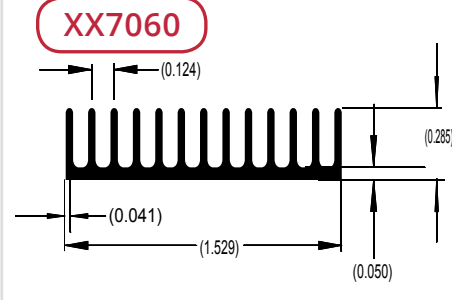
**Per.** 12.50 in.  
**WT.** 0.75 lb/ft  
**θsa** 5.00 °C/w/3"



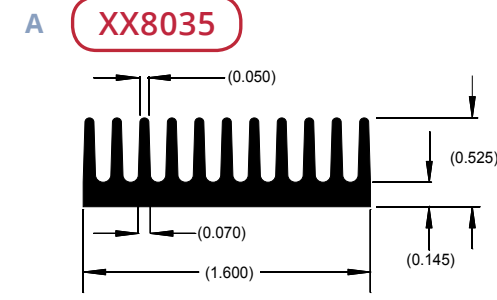
Per.	14.75	in.
WT.	0.84	lb/ft
θsa	4.70	°C/w/3"



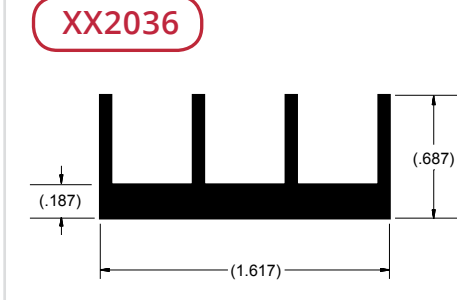
Per.	14.303	in.
WT.	0.412	lb/ft
θsa	4.90	°C/w/3"



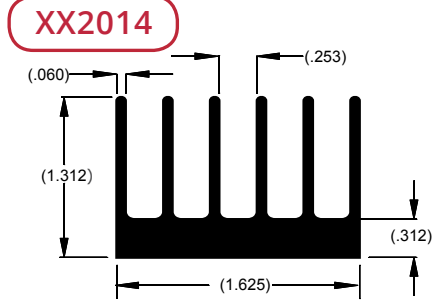
Per.	12.72	in.
WT.	0.61	lb/ft
θsa	14.00	°C/w/3"



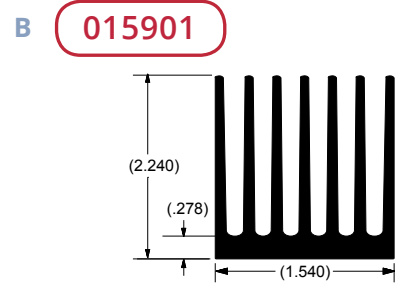
Per.	11.05	in.
WT.	0.58	lb/ft
θsa	7.00	°C/w/3"



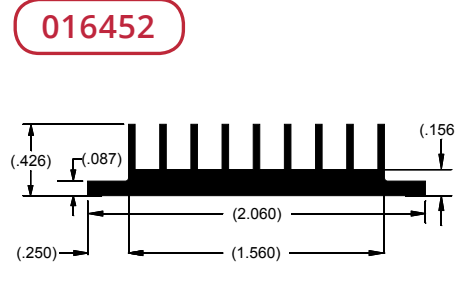
Per.	7.58	in.
WT.	0.51	lb/ft
θsa	4.90	°C/w/3"



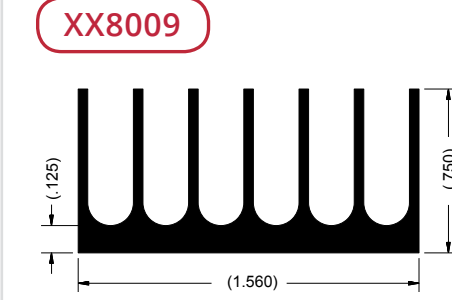
Per.	15.45	in.
WT.	1.05	lb/ft
θsa	3.20	°C/w/3"



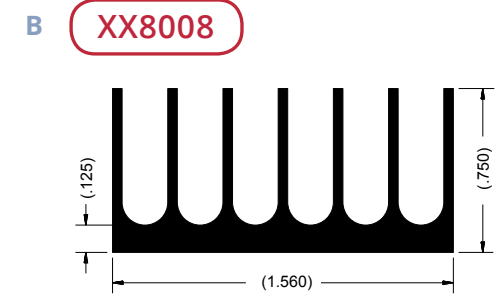
Per.	30.32	in.
WT.	1.93	lb/ft
θsa	3.30	°C/w/3"



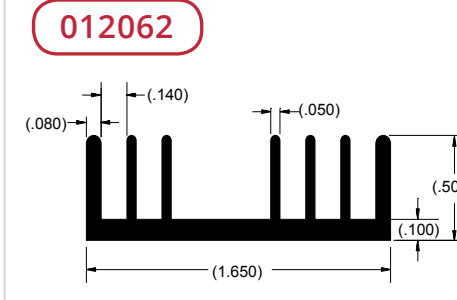
Per.	9.29	in.
WT.	0.46	lb/ft
θsa	8.10	°C/w/3"



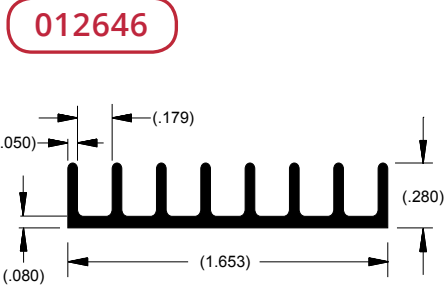
Per.	9.00	in.
WT.	0.53	lb/ft
θsa	5.50	°C/w/3"



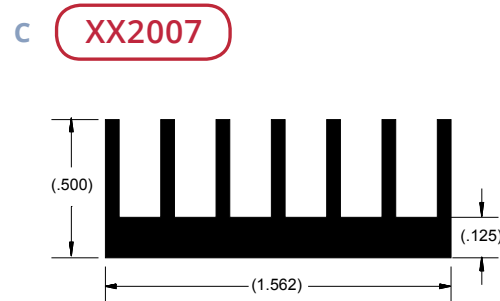
Per.	9.00	in.
WT.	0.53	lb/ft
θsa	5.50	°C/w/3"



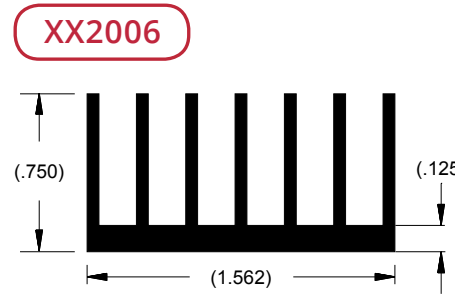
Per.	8.92	in.
WT.	0.39	lb/ft
θsa	7.80	°C/w/3"



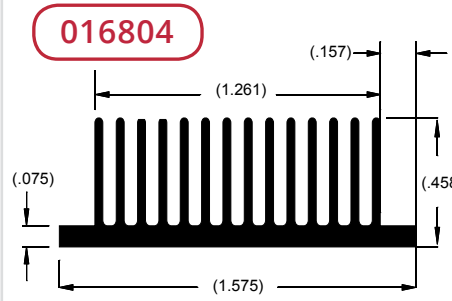
Per.	6.73	in.
WT.	0.20	lb/ft
θsa	10.40	°C/w/3"



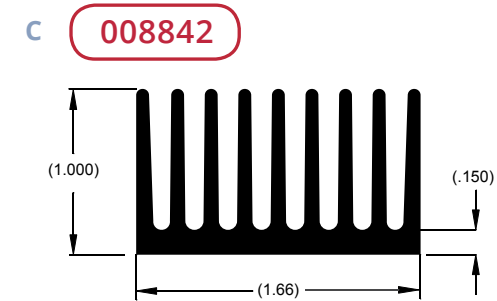
Per.	8.62	in.
WT.	0.43	lb/ft
θsa	8.00	°C/w/3"



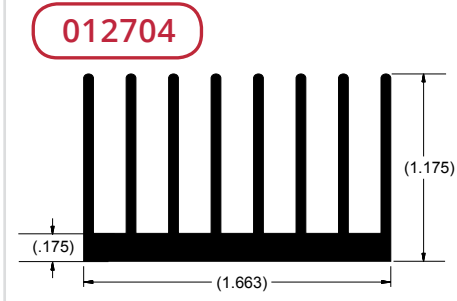
Per.	12.12	in.
WT.	0.57	lb/ft
θsa	5.40	°C/w/3"



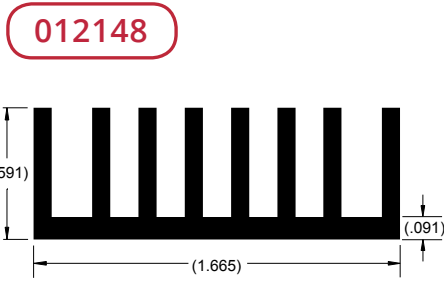
Per.	13.59	in.
WT.	0.36	lb/ft
θsa	9.80	°C/w/3"



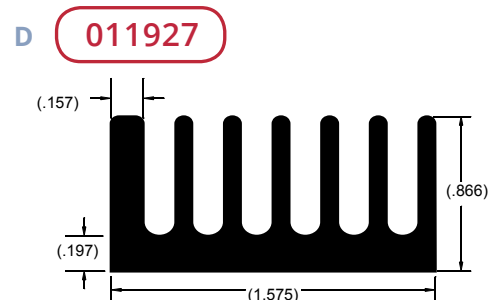
Per.	18.15	in.
WT.	1.03	lb/ft
θsa	4.90	°C/w/3"



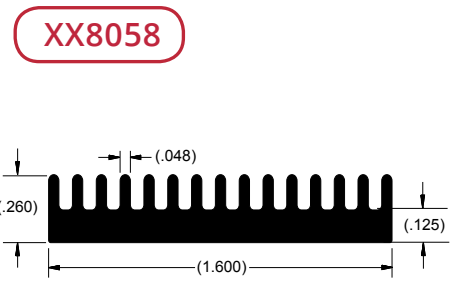
Per.	19.43	in.
WT.	0.83	lb/ft
θsa	3.60	°C/w/3"



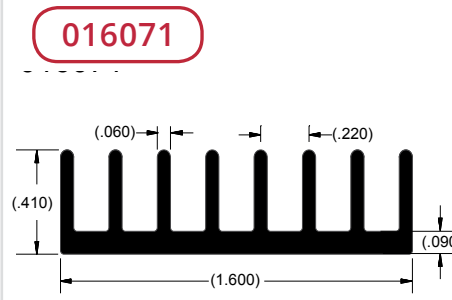
Per.	11.45	in.
WT.	0.51	lb/ft
θsa	6.10	°C/w/3"



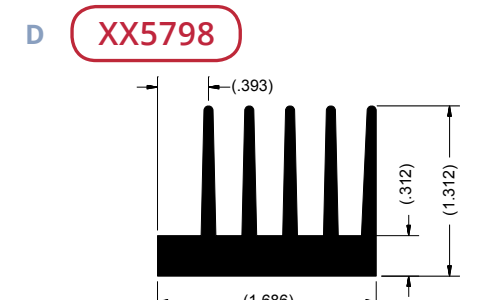
Per.	12.27	in.
WT.	0.87	lb/ft
θsa	5.70	°C/w/3"



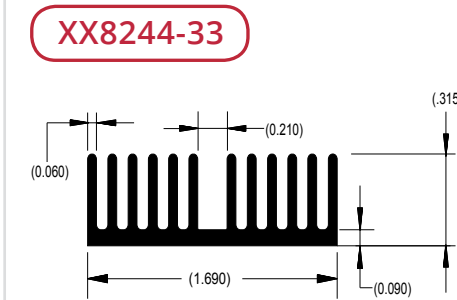
Per.	7.00	in.
WT.	0.34	lb/ft
θsa	14.00	°C/w/3"



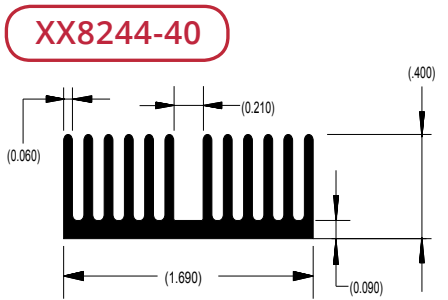
Per.	8.20	in.
WT.	0.36	lb/ft
θsa	8.30	°C/w/3"



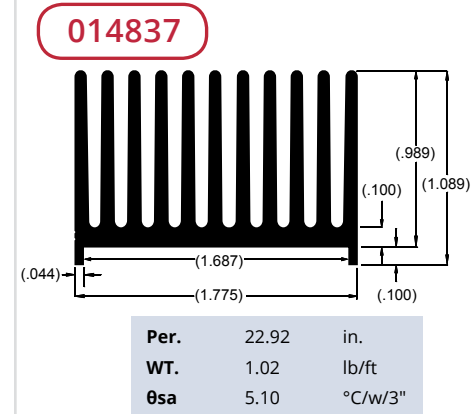
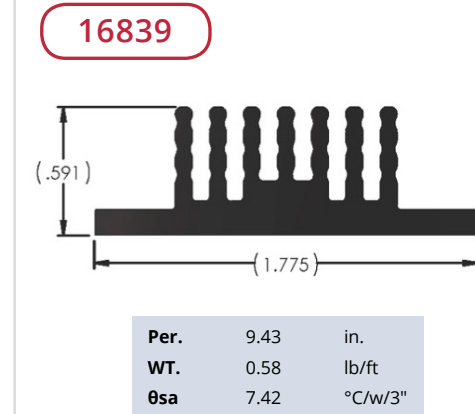
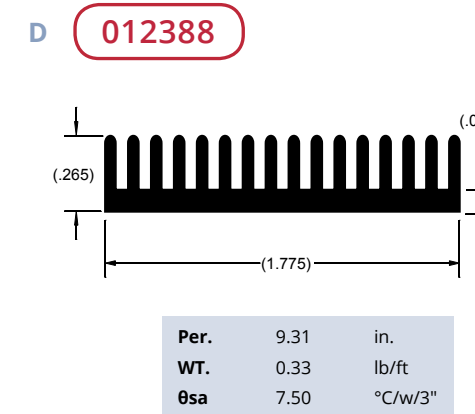
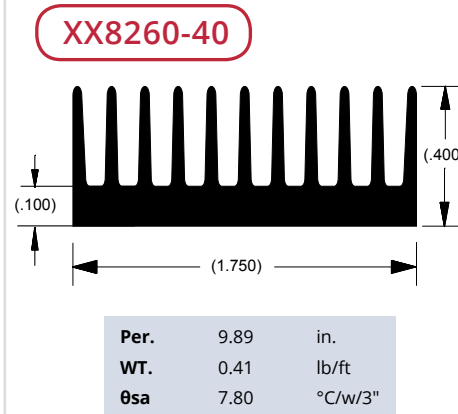
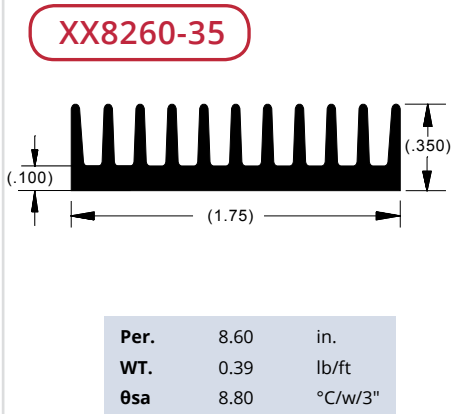
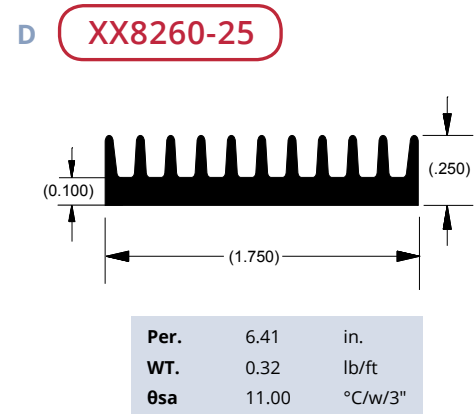
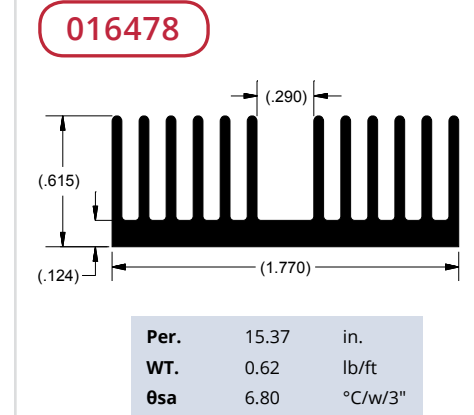
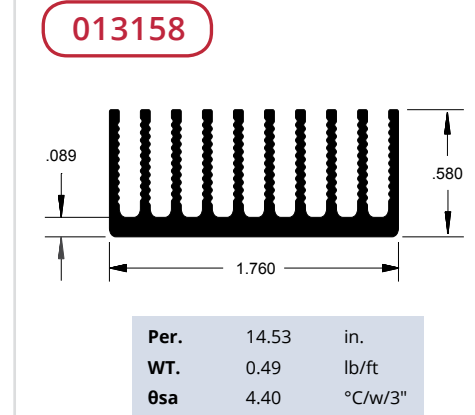
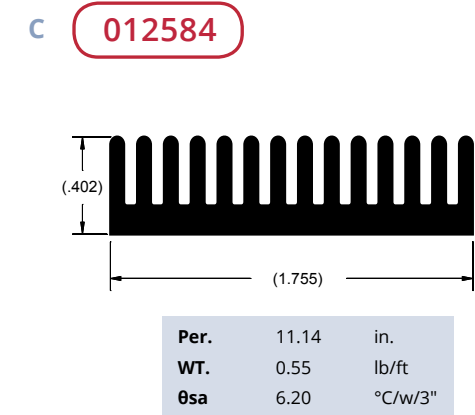
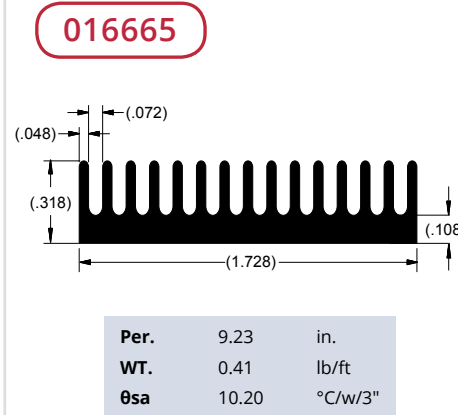
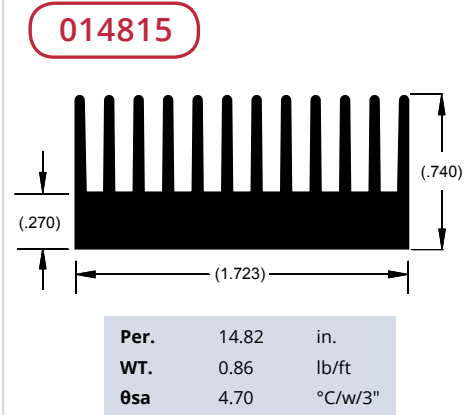
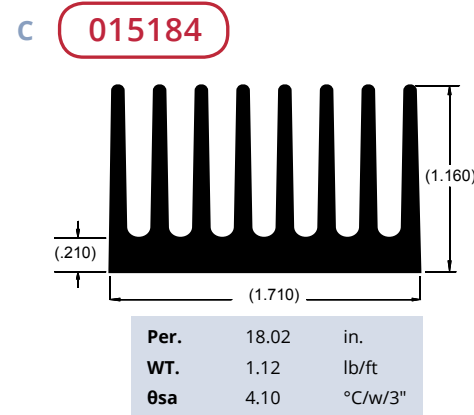
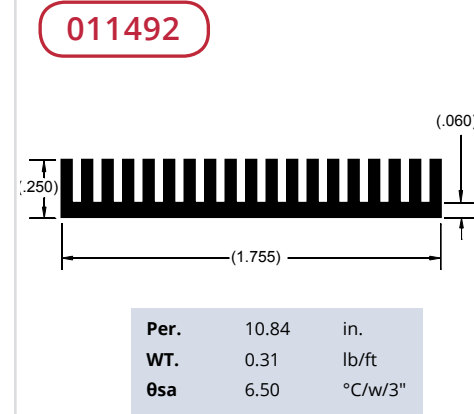
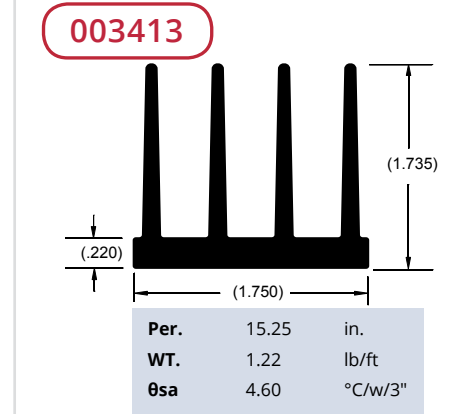
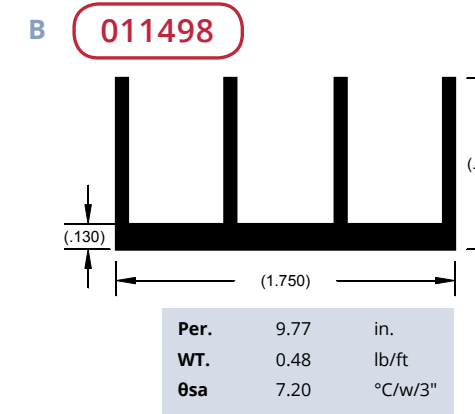
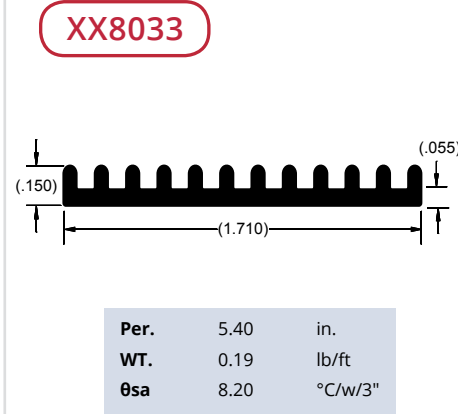
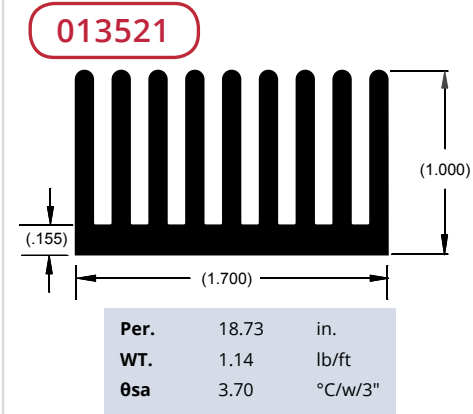
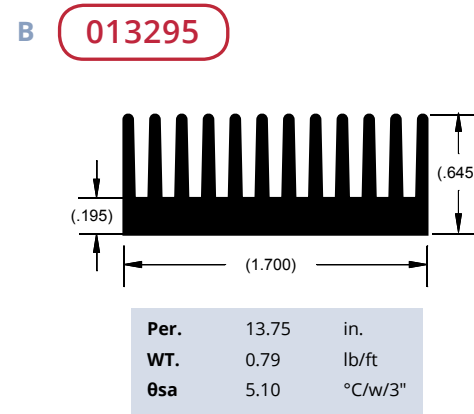
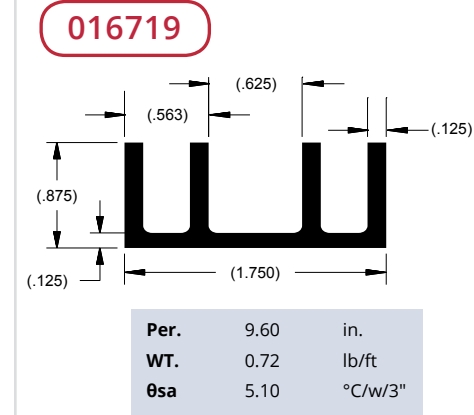
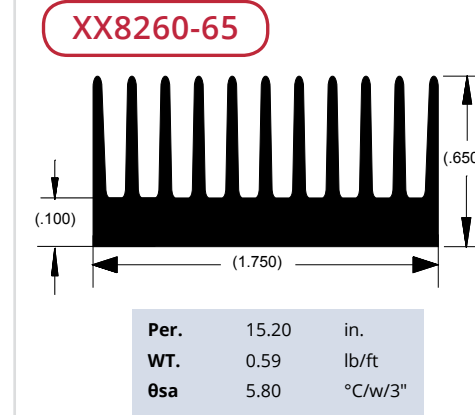
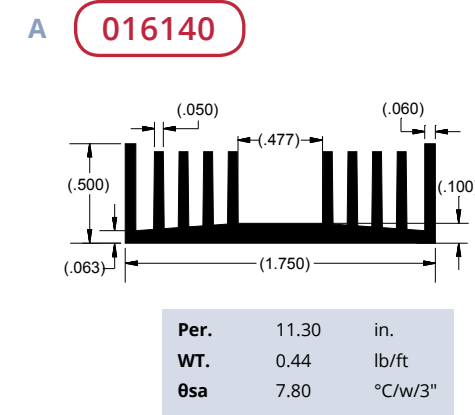
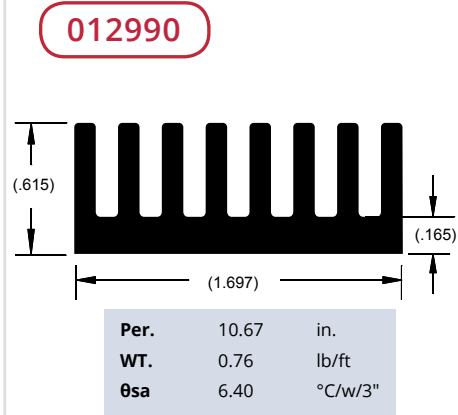
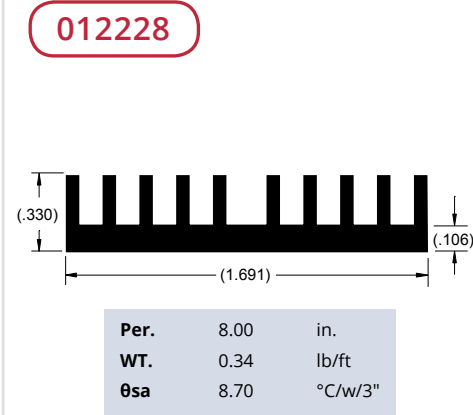
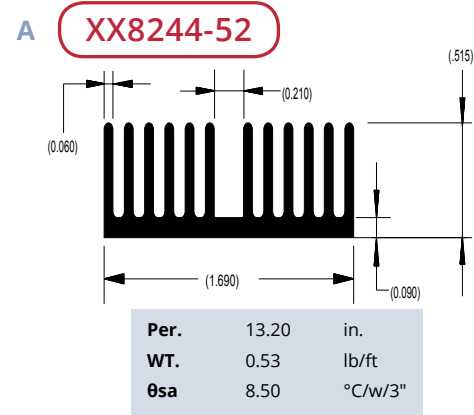
Per.	13.66	in.
WT.	1.04	lb/ft
θsa	5.30	°C/w/3"

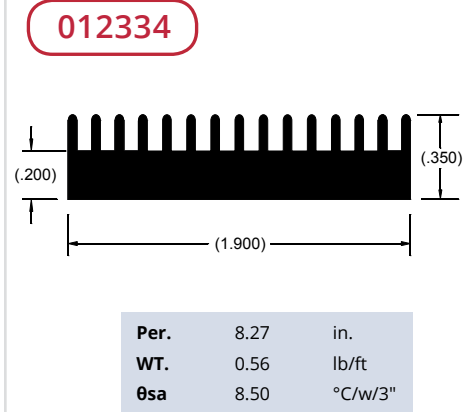
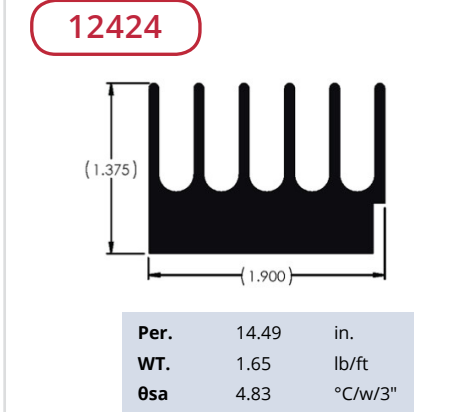
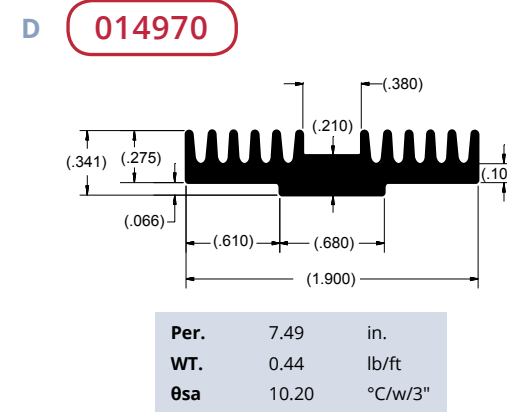
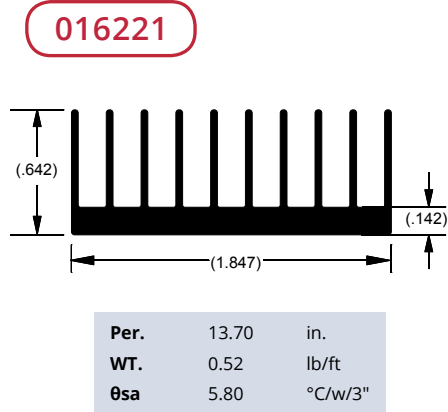
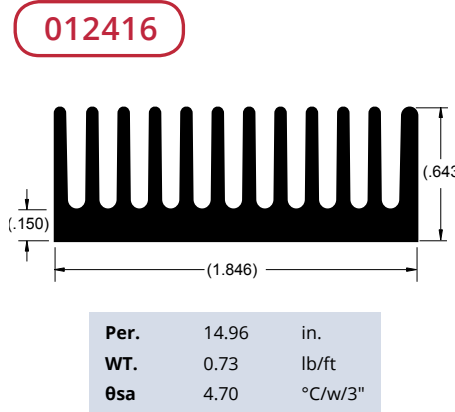
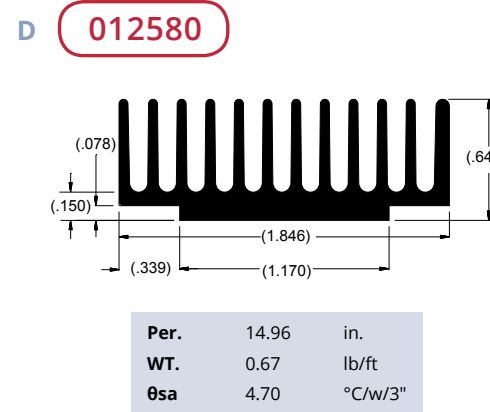
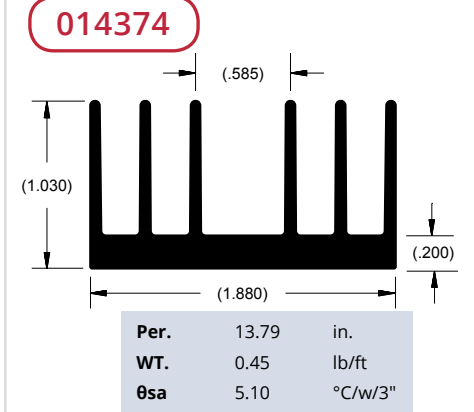
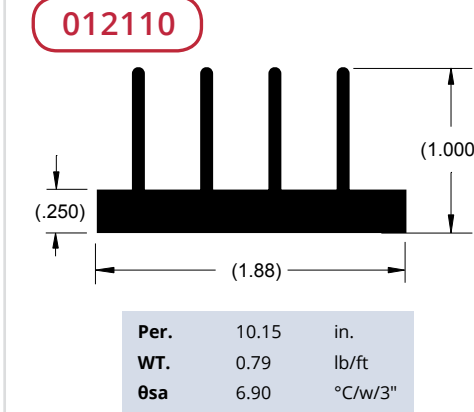
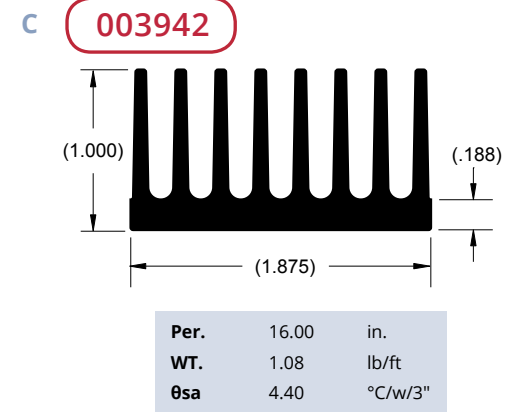
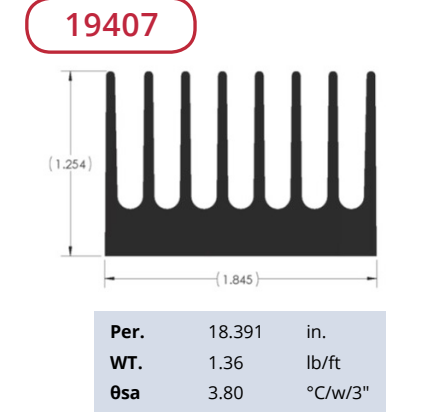
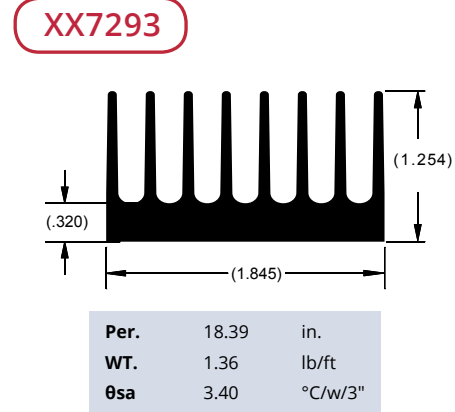
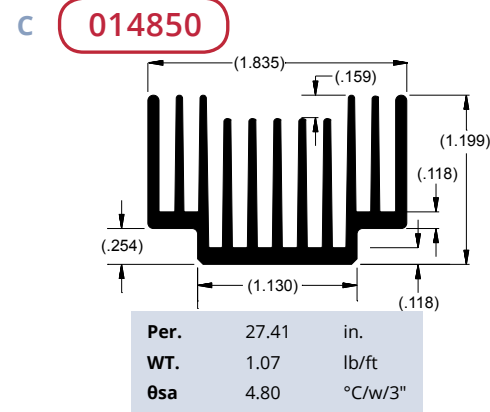
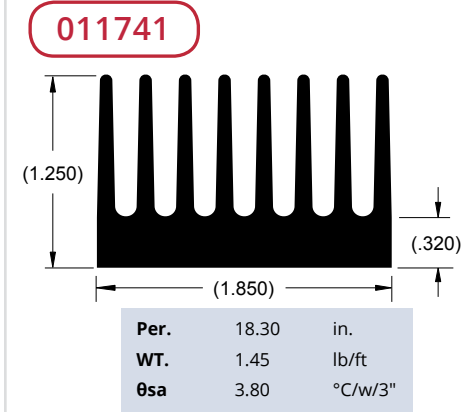
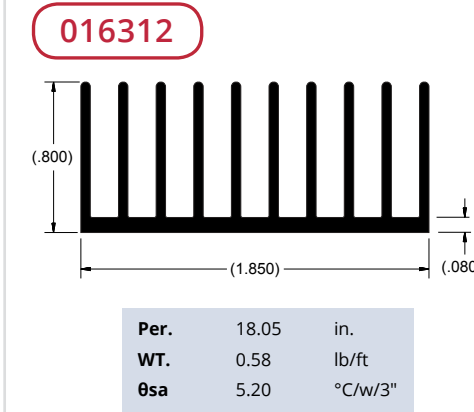
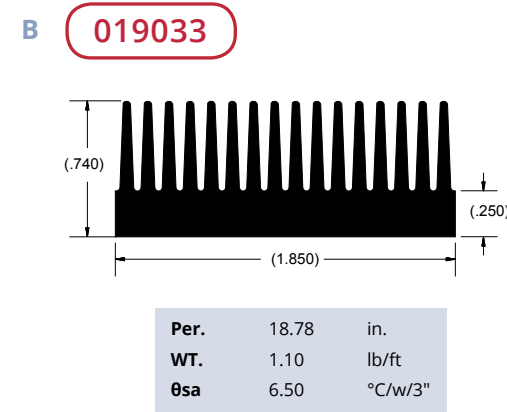
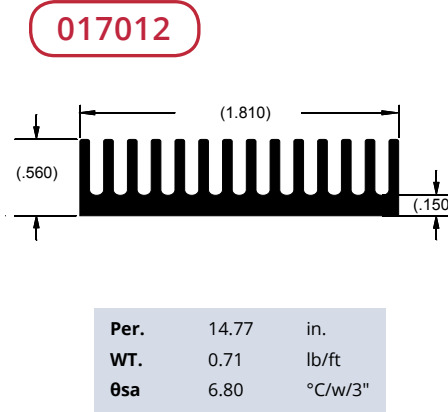
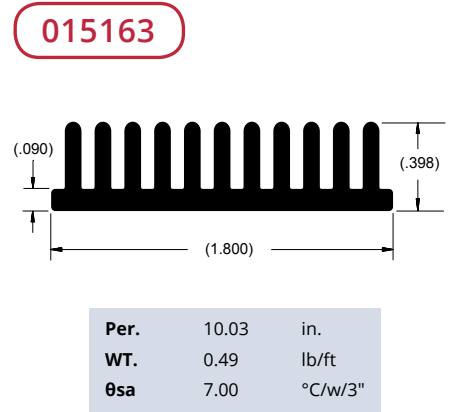
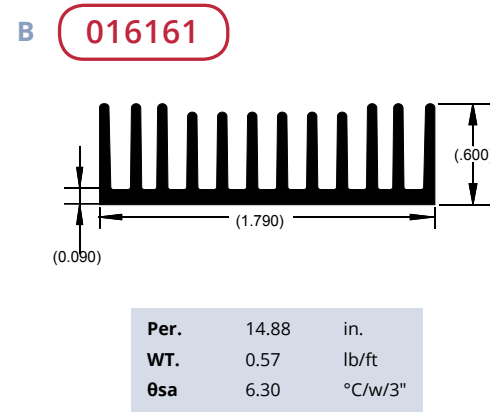
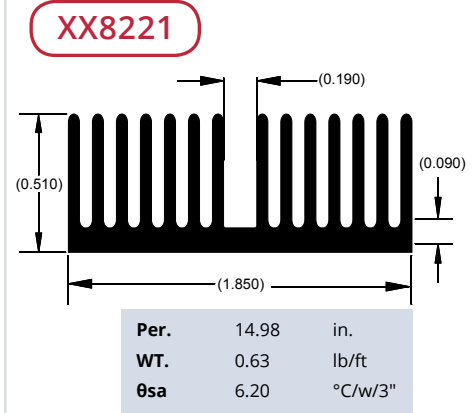
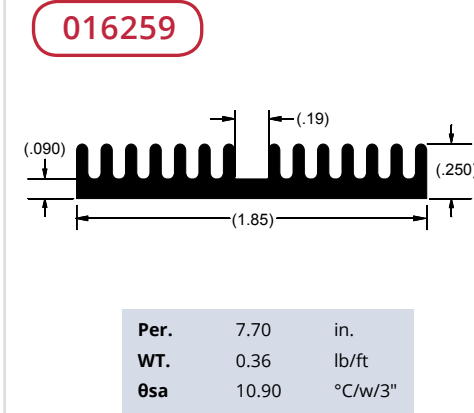
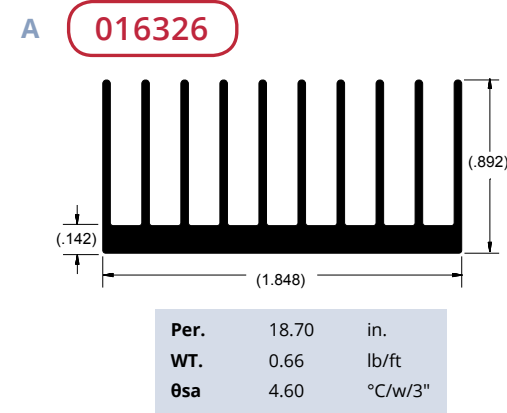
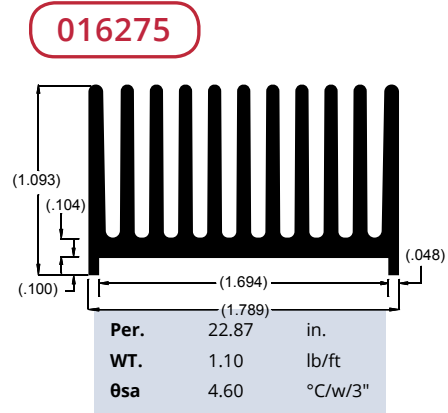
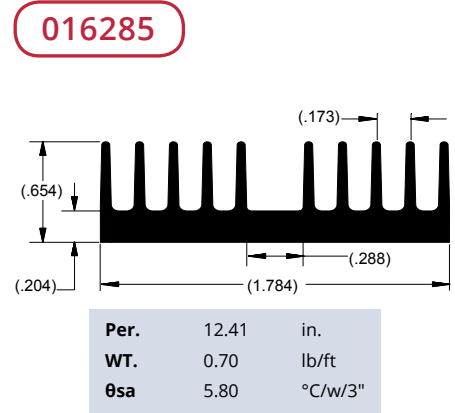
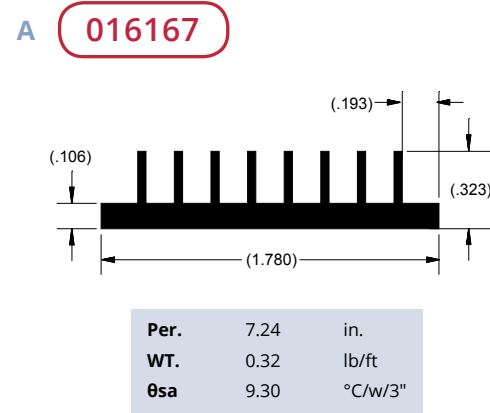


Per.	8.40	in.
WT.	0.37	lb/ft
θsa	10.00	°C/w/3"



Per.	10.40	in.
WT.	0.45	lb/ft
θsa	9.30	°C/w/3"





**A 15672**

Per.	12.95	in.
WT.	0.45	lb/ft
θsa	5.40	°C/w/3"

**015672**

Per.	17.78	in.
WT.	0.45	lb/ft
θsa	7.00	°C/w/3"

**012246**

Per.	15.39	in.
WT.	0.56	lb/ft
θsa	4.50	°C/w/3"

**A 013208**

Per.	18.07	in.
WT.	0.87	lb/ft
θsa	3.90	°C/w/3"

**013210**

Per.	20.61	in.
WT.	0.97	lb/ft
θsa	3.40	°C/w/3"

**015921**

Per.	7.86	in.
WT.	0.31	lb/ft
θsa	11.50	°C/w/3"

**B 013151**

Per.	13.69	in.
WT.	0.77	lb/ft
θsa	5.10	°C/w/3"

**XX2239**

Per.	13.56	in.
WT.	0.78	lb/ft
θsa	5.70	°C/w/3"

**011448**

Per.	14.76	in.
WT.	0.60	lb/ft
θsa	4.70	°C/w/3"

**B 016650**

Per.	11.98	in.
WT.	0.38	lb/ft
θsa	8.00	°C/w/3"

**004506**

Per.	11.50	in.
WT.	0.55	lb/ft
θsa	6.10	°C/w/3"

**014727**

Per.	13.66	in.
WT.	0.76	lb/ft
θsa	5.10	°C/w/3"

**C 016436**

Per.	9.20	in.
WT.	0.34	lb/ft
θsa	12.00	°C/w/3"

**008702**

Per.	18.34	in.
WT.	1.08	lb/ft
θsa	3.80	°C/w/3"

**XX8195**

Per.	77.43	in.
WT.	0.37	lb/ft
θsa	10.00	°C/w/3"

**C 013075**

Per.	25.12	in.
WT.	2.35	lb/ft
θsa	2.80	°C/w/3"

**016149**

Per.	24.02	in.
WT.	2.75	lb/ft
θsa	3.10	°C/w/3"

**016428**

Per.	21.98	in.
WT.	0.83	lb/ft
θsa	4.20	°C/w/3"

**D 011465**

Per.	10.46	in.
WT.	0.85	lb/ft
θsa	6.70	°C/w/3"

**013205**

Per.	10.63	in.
WT.	0.53	lb/ft
θsa	6.60	°C/w/3"

**013206**

Per.	13.63	in.
WT.	0.63	lb/ft
θsa	5.10	°C/w/3"

**D 012106**

Per.	22.81	in.
WT.	1.33	lb/ft
θsa	3.10	°C/w/3"

**014432**

Per.	8.15	in.
WT.	0.36	lb/ft
θsa	8.60	°C/w/3"

**010980**

Per.	15.60	in.
WT.	0.65	lb/ft
θsa	4.50	°C/w/3"

Not all stocked. Example shapes are not all tooled.

**A 016172**

Per.	19.10	in.
WT.	0.76	lb/ft
θsa	4.70	°C/w/3"

**016555**

Per.	15.29	in.
WT.	0.87	lb/ft
θsa	4.70	°C/w/3"

**014476**

Per.	15.75	in.
WT.	0.74	lb/ft
θsa	4.40	°C/w/3"

**A XX8641**

Per.	22.60	in.
WT.	1.36	lb/ft
θsa	5.20	°C/w/3"

**014235**

Per.	29.12	in.
WT.	1.79	lb/ft
θsa	2.40	°C/w/3"

**013647**

Per.	29.92	in.
WT.	1.41	lb/ft
θsa	2.60	°C/w/3"

**B 012712**

Per.	11.20	in.
WT.	0.30	lb/ft
θsa	6.20	°C/w/3"

**XX8355-40**

Per.	9.44	in.
WT.	0.67	lb/ft
θsa	7.00	°C/w/3"

**012182**

Per.	7.74	in.
WT.	0.36	lb/ft
θsa	9.00	°C/w/3"

**B 015955**

Per.	9.95	in.
WT.	0.43	lb/ft
θsa	7.40	°C/w/3"

**014802**

Per.	13.81	in.
WT.	0.53	lb/ft
θsa	6.10	°C/w/3"

**012103**

Per.	15.65	in.
WT.	0.72	lb/ft
θsa	4.50	°C/w/3"

**C 011740**

Per.	16.23	in.
WT.	0.45	lb/ft
θsa	4.30	°C/w/3"

**XX8355-65**

Per.	14.90	in.
WT.	0.95	lb/ft
θsa	5.20	°C/w/3"

**012242**

Per.	20.64	in.
WT.	0.68	lb/ft
θsa	3.40	°C/w/3"

**C 014249**

Per.	15.85	in.
WT.	1.18	lb/ft
θsa	4.40	°C/w/3"

**009239**

Per.	25.15	in.
WT.	2.23	lb/ft
θsa	2.80	°C/w/3"

**21884**

Per.	18.60	in.
WT.	3.49	lb/ft
θsa	3.76	°C/w/3"

**D 013513**

Per.	16.26	in.
WT.	0.97	lb/ft
θsa	4.30	°C/w/3"

**XX8355-80**

Per.	18.200	in.
WT.	1.120	lb/ft
θsa	4.40	°C/w/3"

**XX8355-100**

Per.	22.64	in.
WT.	1.39	lb/ft
θsa	3.80	°C/w/3"

**D 016510**

Per.	17.92	in.
WT.	1.09	lb/ft
θsa	4.80	°C/w/3"

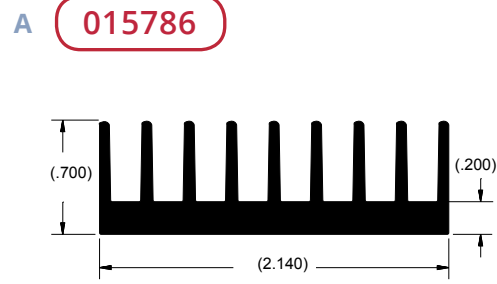
**016256**

Per.	21.86	in.
WT.	1.28	lb/ft
θsa	5.10	°C/w/3"

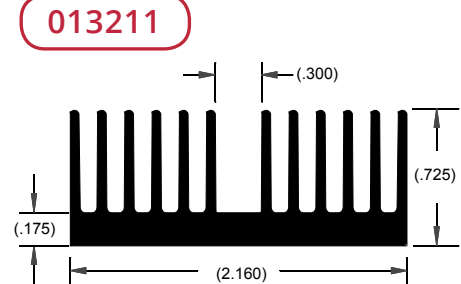
**XX2035**

Per.	9.64	in.
WT.	0.66	lb/ft
θsa	4.30	°C/w/3"

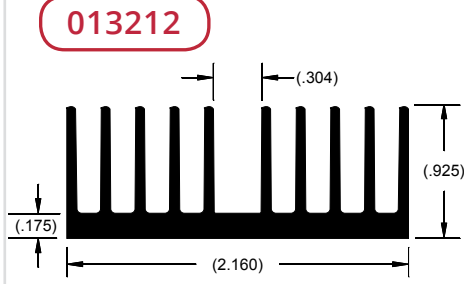




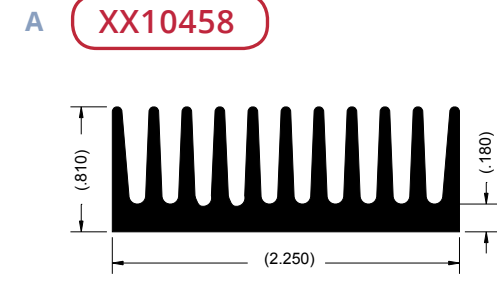
Per.	13.24	in.
WT.	0.87	lb/ft
θsa	5.10	°C/w/3"



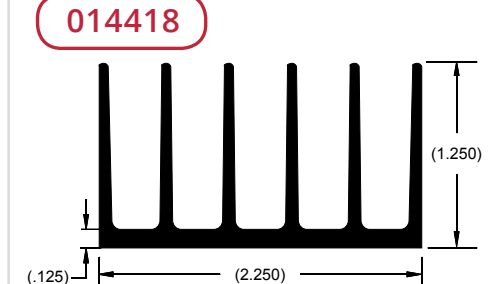
Per.	17.21	in.
WT.	0.90	lb/ft
θsa	4.10	°C/w/3"



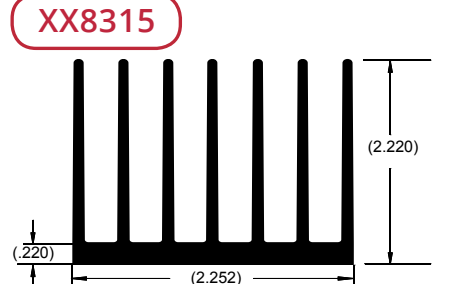
Per.	19.13	in.
WT.	0.96	lb/ft
θsa	3.70	°C/w/3"



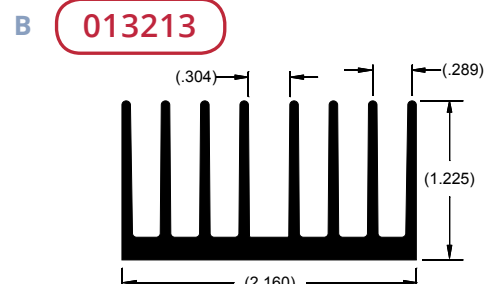
Per.	17.49	in.
WT.	1.21	lb/ft
θsa	4.80	°C/w/3"



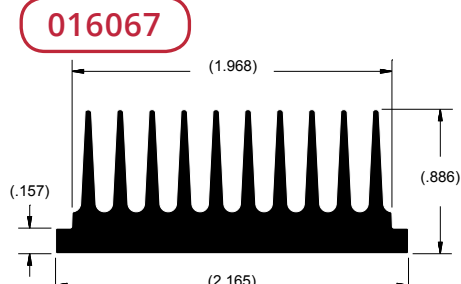
Per.	18.25	in.
WT.	0.84	lb/ft
θsa	3.80	°C/w/3"



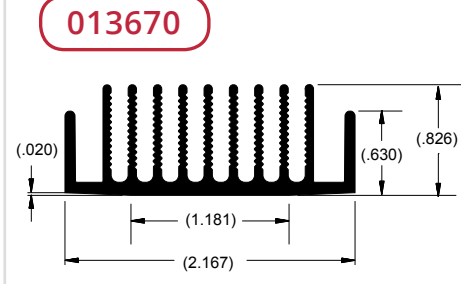
Per.	32.42	in.
WT.	1.79	lb/ft
θsa	2.40	°C/w/3"



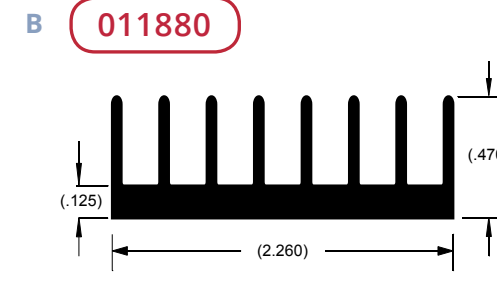
Per.	20.97	in.
WT.	1.12	lb/ft
θsa	3.30	°C/w/3"



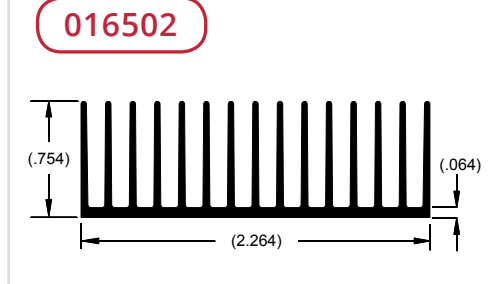
Per.	16.25	in.
WT.	1.17	lb/ft
θsa	5.20	°C/w/3"



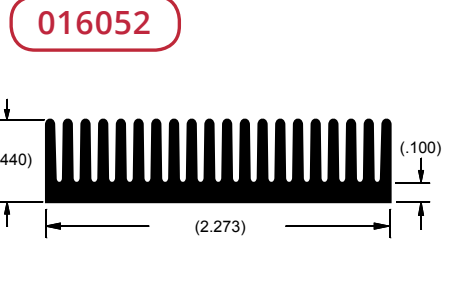
Per.	21.91	in.
WT.	0.81	lb/ft
θsa	3.20	°C/w/3"



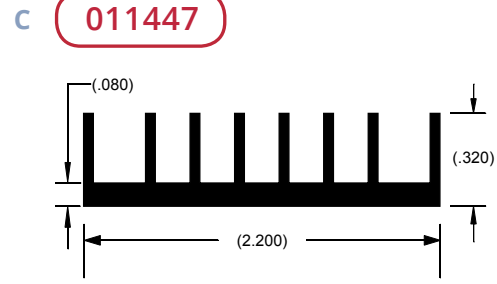
Per.	10.24	in.
WT.	0.54	lb/ft
θsa	6.80	°C/w/3"



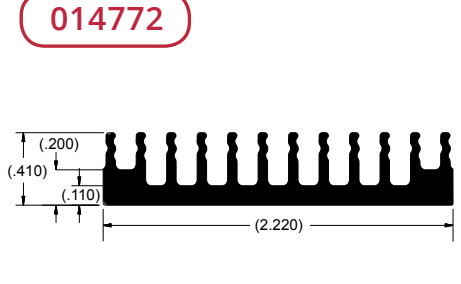
Per.	24.75	in.
WT.	0.67	lb/ft
θsa	4.80	°C/w/3"



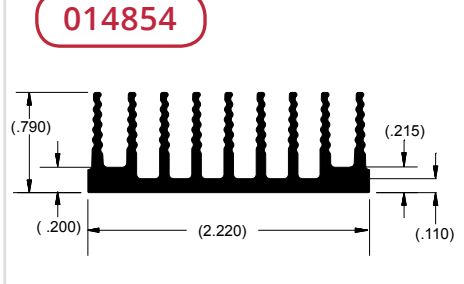
Per.	17.71	in.
WT.	0.72	lb/ft
θsa	7.60	°C/w/3"



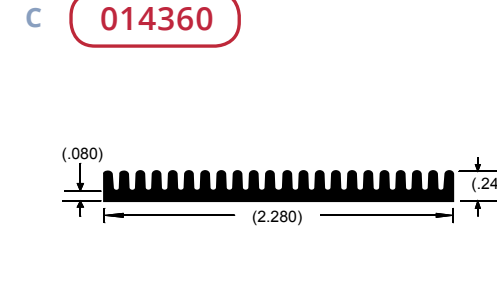
Per.	8.34	in.
WT.	0.34	lb/ft
θsa	8.40	°C/w/3"



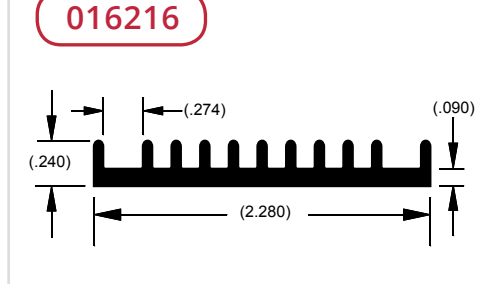
Per.	11.28	in.
WT.	0.56	lb/ft
θsa	7.00	°C/w/3"



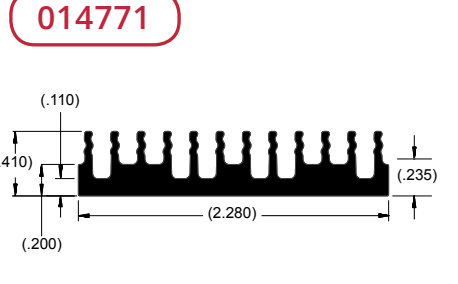
Per.	17.46	in.
WT.	0.80	lb/ft
θsa	4.60	°C/w/3"



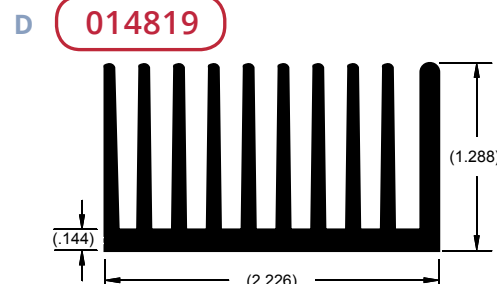
Per.	10.93	in.
WT.	0.39	lb/ft
θsa	10.40	°C/w/3"



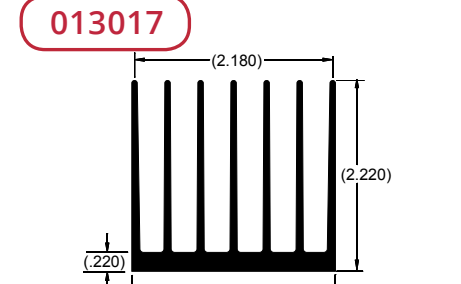
Per.	7.58	in.
WT.	0.36	lb/ft
θsa	9.20	°C/w/3"



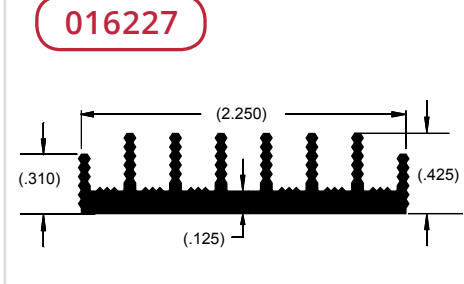
Per.	10.79	in.
WT.	0.63	lb/ft
θsa	7.80	°C/w/3"



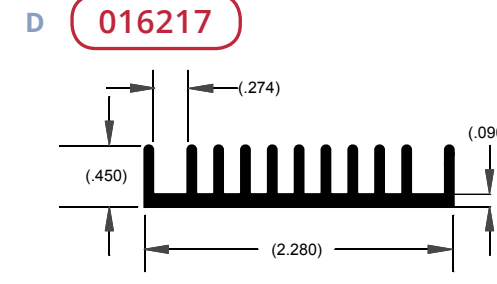
Per.	27.09	in.
WT.	1.48	lb/ft
θsa	3.50	°C/w/3"



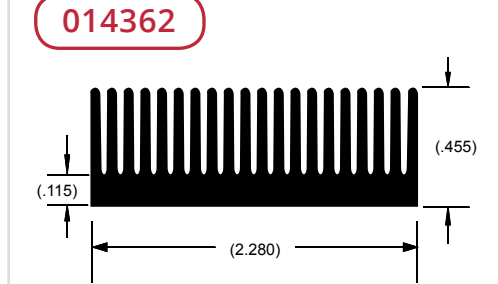
Per.	32.38	in.
WT.	1.79	lb/ft
θsa	2.40	°C/w/3"



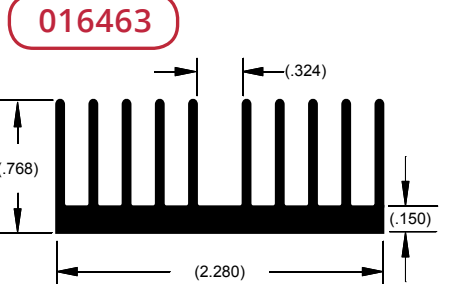
Per.	10.50	in.
WT.	0.53	lb/ft
θsa	6.60	°C/w/3"



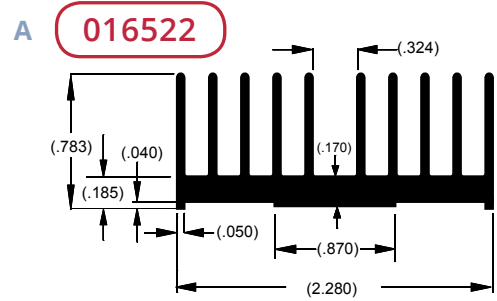
Per.	12.21	in.
WT.	0.52	lb/ft
θsa	6.40	°C/w/3"



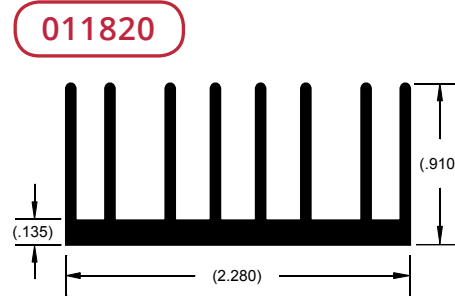
Per.	17.31	in.
WT.	0.73	lb/ft
θsa	4.00	°C/w/3"



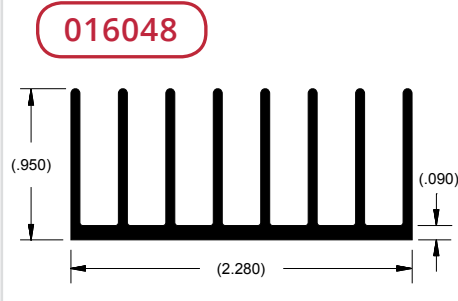
Per.	18.17	in.
WT.	0.75	lb/ft
θsa	4.20	°C/w/3"



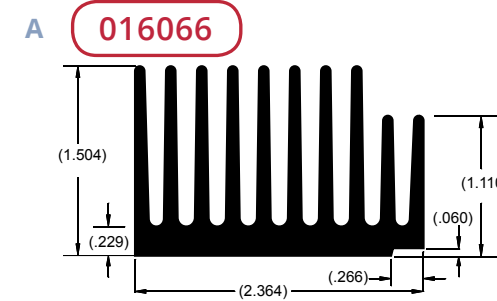
Per.	16.65	in.
WT.	0.79	lb/ft
θsa	4.80	°C/w/3"



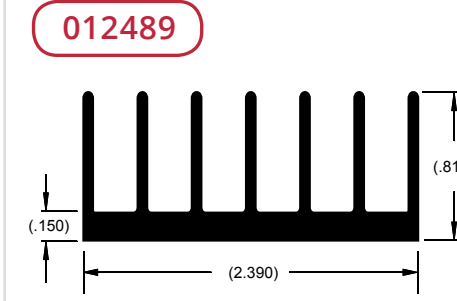
Per.	17.02	in.
WT.	0.81	lb/ft
θsa	4.10	°C/w/3"



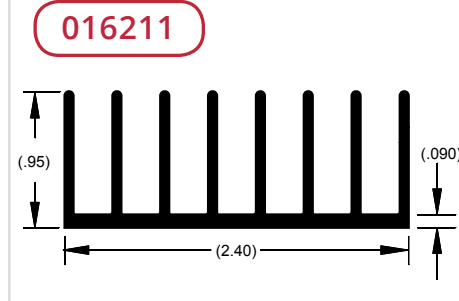
Per.	18.17	in.
WT.	0.75	lb/ft
θsa	4.20	°C/w/3"



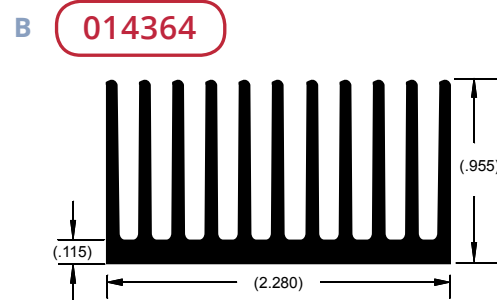
Per.	27.93	in.
WT.	1.95	lb/ft
θsa	3.20	°C/w/3"



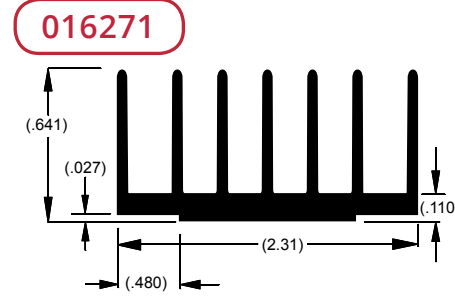
Per.	12.18	in.
WT.	0.79	lb/ft
θsa	5.70	°C/w/3"



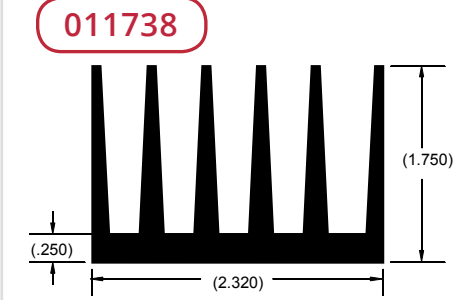
Per.	18.43	in.
WT.	0.75	lb/ft
θsa	3.80	°C/w/3"



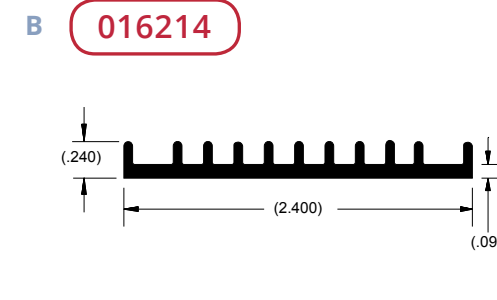
Per.	22.46	in.
WT.	1.03	lb/ft
θsa	3.10	°C/w/3"



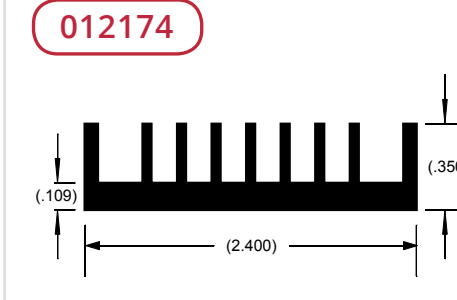
Per.	11.95	in.
WT.	0.56	lb/ft
θsa	5.10	°C/w/3"



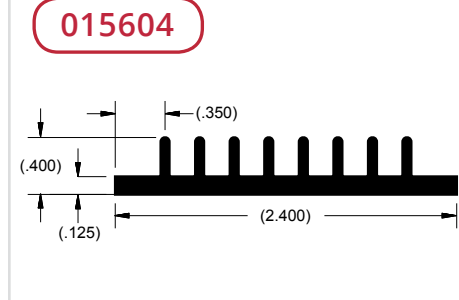
Per.	22.26	in.
WT.	1.88	lb/ft
θsa	3.10	°C/w/3"



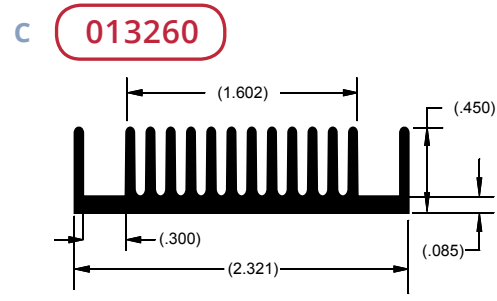
Per.	7.82	in.
WT.	0.37	lb/ft
θsa	9.10	°C/w/3"



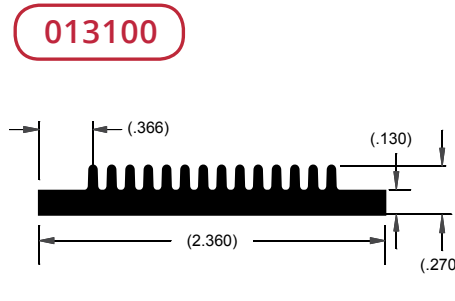
Per.	9.29	in.
WT.	0.48	lb/ft
θsa	7.50	°C/w/3"



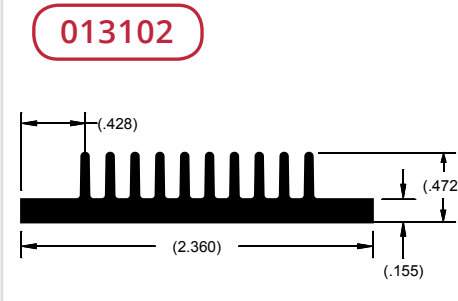
Per.	9.14	in.
WT.	0.51	lb/ft
θsa	8.00	°C/w/3"



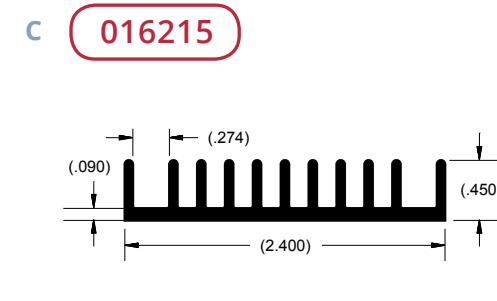
Per.	14.21	in.
WT.	0.58	lb/ft
θsa	4.90	°C/w/3"



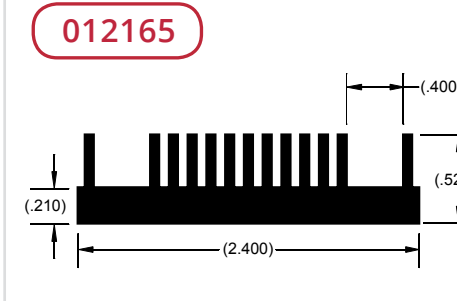
Per.	8.13	in.
WT.	0.48	lb/ft
θsa	8.60	°C/w/3"



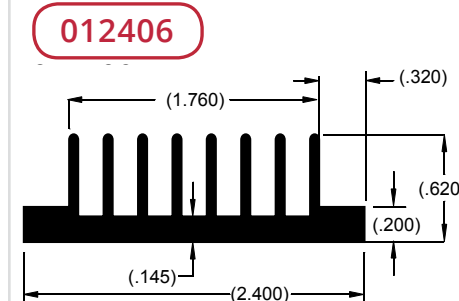
Per.	10.56	in.
WT.	0.63	lb/ft
θsa	6.60	°C/w/3"



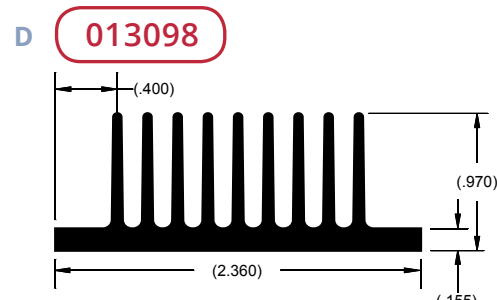
Per.	12.44	in.
WT.	0.54	lb/ft
θsa	6.30	°C/w/3"



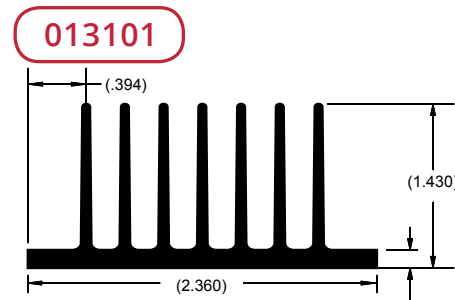
Per.	13.17	in.
WT.	0.87	lb/ft
θsa	5.30	°C/w/3"



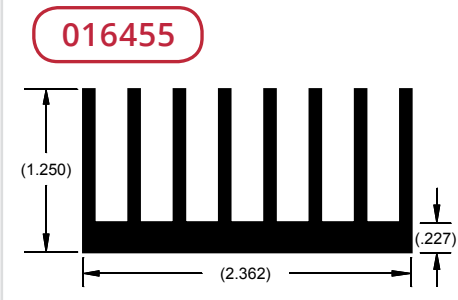
Per.	12.42	in.
WT.	0.71	lb/ft
θsa	5.60	°C/w/3"



Per.	18.88	in.
WT.	0.95	lb/ft
θsa	3.70	°C/w/3"



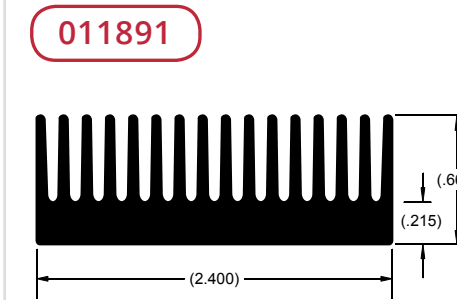
Per.	22.23	in.
WT.	1.07	lb/ft
θsa	3.10	°C/w/3"



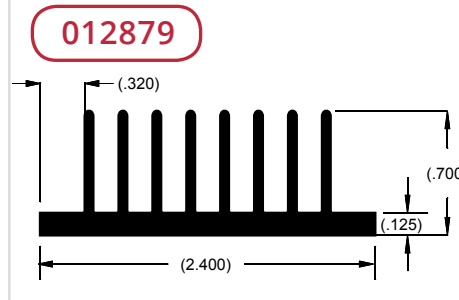
Per.	21.56	in.
WT.	1.42	lb/ft
θsa	3.30	°C/w/3"



Per.	18.95	in.
WT.	0.86	lb/ft
θsa	3.70	°C/w/3"



Per.	18.44	in.
WT.	1.25	lb/ft
θsa	3.80	°C/w/3"



Per.	14.68	in.
WT.	0.70	lb/ft
θsa	4.80	°C/w/3"

**A 12540**

Per.	16.18	in.
WT.	0.87	lb/ft
θsa	4.32	°C/w/3"

**014964**

Per.	21.36	in.
WT.	0.79	lb/ft
θsa	3.30	°C/w/3"

**12407**

Per.	12.41	in.
WT.	0.90	lb/ft
θsa	5.64	°C/w/3"

**A 014326**

Per.	35.57	in.
WT.	1.30	lb/ft
θsa	2.00	°C/w/3"

**12487**

Per.	9.13	in.
WT.	0.48	lb/ft
θsa	7.66	°C/w/3"

**016618**

Per.	11.47	in.
WT.	0.60	lb/ft
θsa	7.30	°C/w/3"

**B 012613**

Per.	17.24	in.
WT.	0.80	lb/ft
θsa	4.10	°C/w/3"

**014427**

Per.	23.40	in.
WT.	0.89	lb/ft
θsa	3.00	°C/w/3"

**014373**

Per.	25.35	in.
WT.	1.13	lb/ft
θsa	2.80	°C/w/3"

**B 015941**

Per.	9.77	in.
WT.	0.38	lb/ft
θsa	9.30	°C/w/3"

**015920**

Per.	11.43	in.
WT.	0.43	lb/ft
θsa	8.40	°C/w/3"

**014269**

Per.	18.21	in.
WT.	0.78	lb/ft
θsa	3.80	°C/w/3"

**C 014960**

Per.	28.19	in.
WT.	1.29	lb/ft
θsa	2.50	°C/w/3"

**011890**

Per.	22.01	in.
WT.	1.41	lb/ft
θsa	3.20	°C/w/3"

**012661**

Per.	27.57	in.
WT.	1.33	lb/ft
θsa	2.50	°C/w/3"

**C 016010**

Per.	14.26	in.
WT.	0.71	lb/ft
θsa	5.00	°C/w/3"

**015902**

Per.	47.46	in.
WT.	3.06	lb/ft
θsa	4.10	°C/w/3"

**XX8410**

Per.	24.67	in.
WT.	3.88	lb/ft
θsa	2.10	°C/w/3"

**D 014701**

Per.	40.80	in.
WT.	2.09	lb/ft
θsa	1.70	°C/w/3"

**19803**

Per.	25.89	in.
WT.	1.25	lb/ft
θsa	2.70	°C/w/3"

**013141**

Per.	34.12	in.
WT.	1.33	lb/ft
θsa	2.10	°C/w/3"

**D 016225**

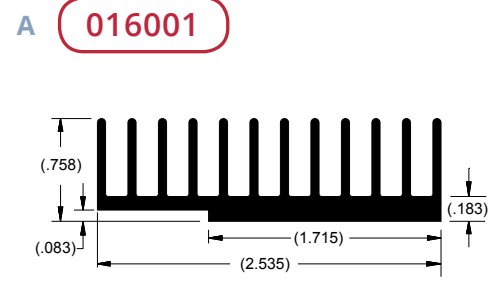
Per.	17.41	in.
WT.	0.85	lb/ft
θsa	7.10	°C/w/3"

**XX8373**

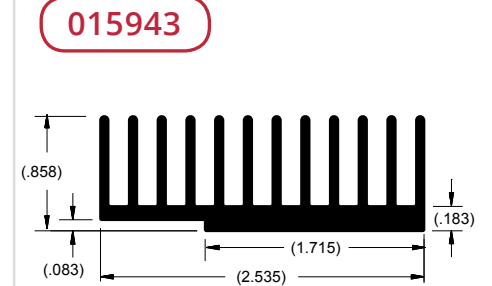
Per.	14.97	in.
WT.	0.76	lb/ft
θsa	6.00	°C/w/3"

**014762**

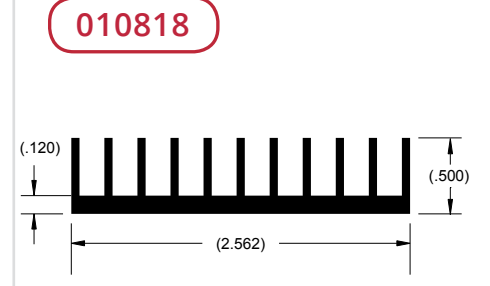
Per.	15.52	in.
WT.	0.70	lb/ft
θsa	4.50	°C/w/3"



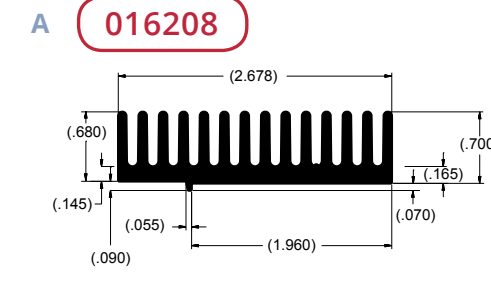
Per.	18.74	in.
WT.	0.97	lb/ft
θsa	4.60	°C/w/3"



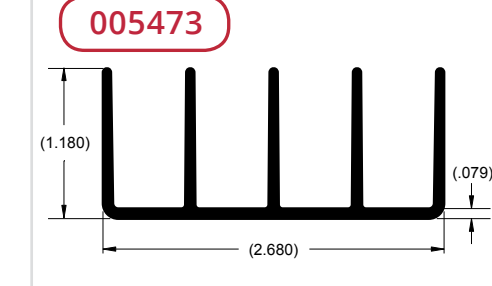
Per.	21.14	in.
WT.	1.14	lb/ft
θsa	4.20	°C/w/3"



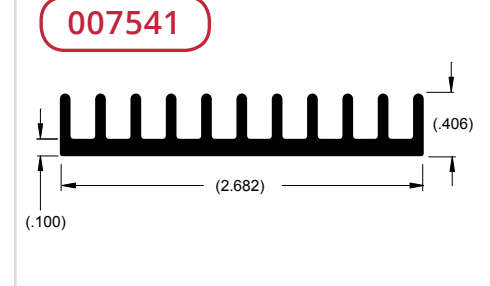
Per.	13.48	in.
WT.	0.68	lb/ft
θsa	5.20	°C/w/3"



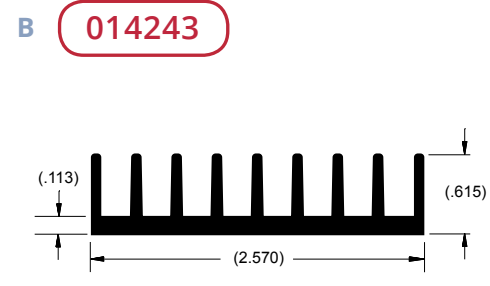
Per.	5.54	in.
WT.	0.03	lb/ft
θsa	5.90	°C/w/3"



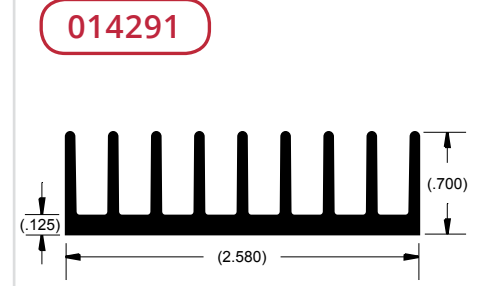
Per.	16.52	in.
WT.	0.70	lb/ft
θsa	4.20	°C/w/3"



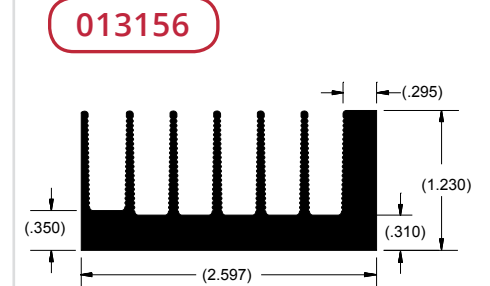
Per.	10.58	in.
WT.	0.50	lb/ft
θsa	6.60	°C/w/3"



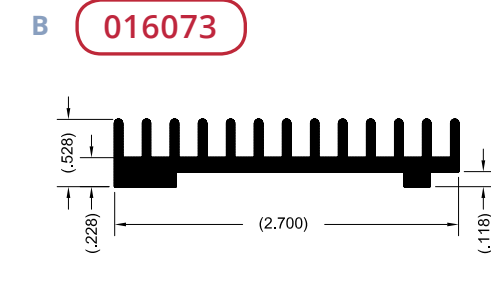
Per.	13.84	in.
WT.	0.76	lb/ft
θsa	5.10	°C/w/3"



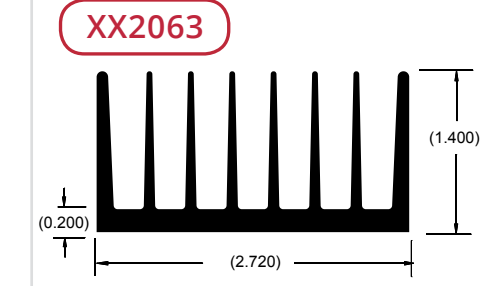
Per.	15.25	in.
WT.	0.79	lb/ft
θsa	4.60	°C/w/3"



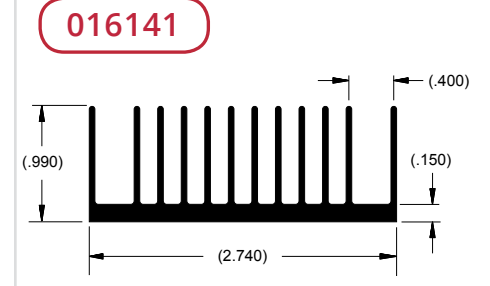
Per.	18.12	in.
WT.	1.74	lb/ft
θsa	3.90	°C/w/3"



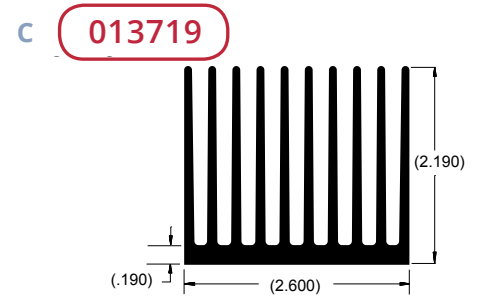
Per.	13.80	in.
WT.	0.71	lb/ft
θsa	5.30	°C/w/3"



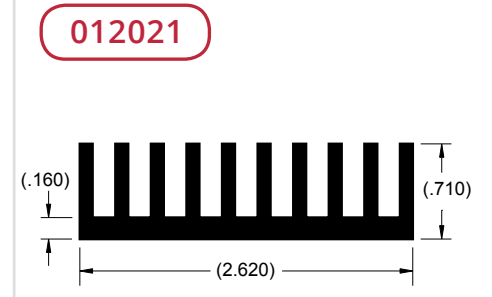
Per.	24.24	in.
WT.	1.65	lb/ft
θsa	1.90	°C/w/3"



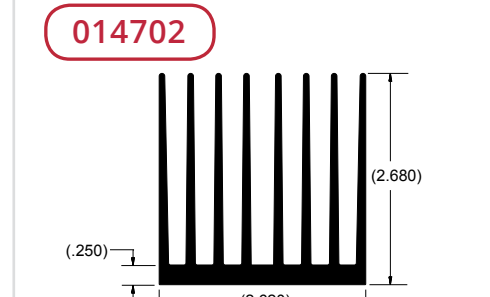
Per.	25.40	in.
WT.	1.10	lb/ft
θsa	3.60	°C/w/3"



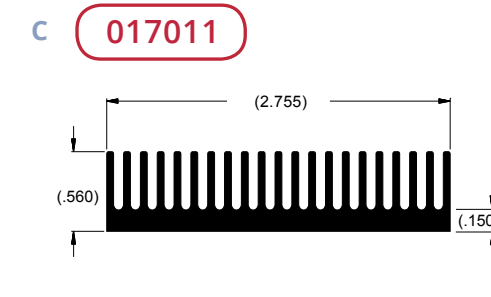
Per.	44.29	in.
WT.	2.58	lb/ft
θsa	1.60	°C/w/3"



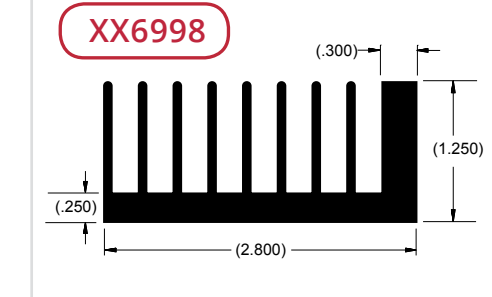
Per.	16.56	in.
WT.	1.16	lb/ft
θsa	4.20	°C/w/3"



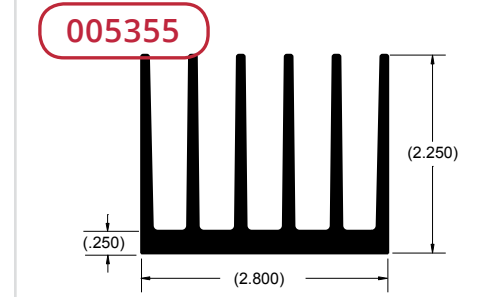
Per.	44.19	in.
WT.	2.91	lb/ft
θsa	1.60	°C/w/3"



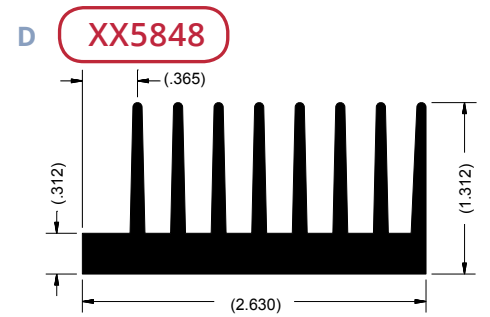
Per.	22.07	in.
WT.	1.07	lb/ft
θsa	6.10	°C/w/3"



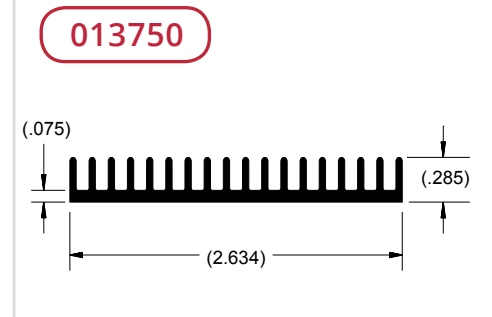
Per.	24.10	in.
WT.	1.80	lb/ft
θsa	2.90	°C/w/3"



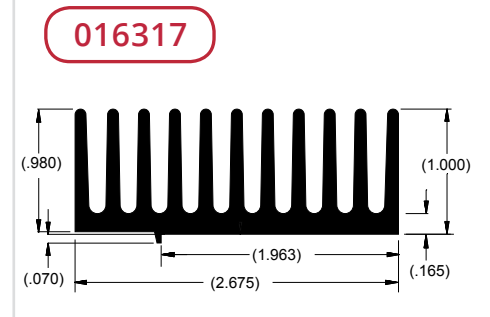
Per.	30.00	in.
WT.	2.33	lb/ft
θsa	2.30	°C/w/3"



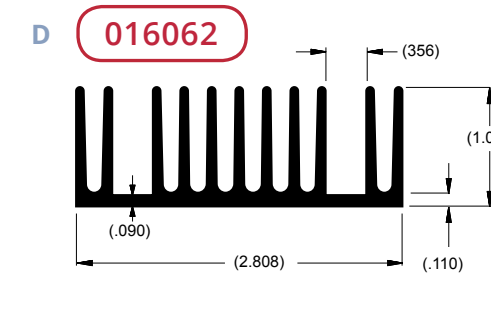
Per.	21.37	in.
WT.	1.63	lb/ft
θsa	3.50	°C/w/3"



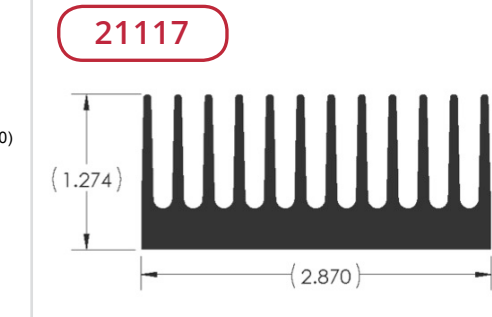
Per.	12.37	in.
WT.	0.47	lb/ft
θsa	5.70	°C/w/3"



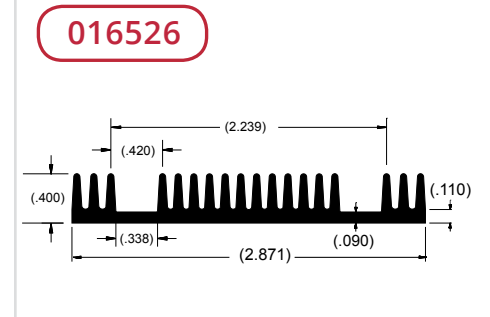
Per.	22.91	in.
WT.	1.67	lb/ft
θsa	3.90	°C/w/3"



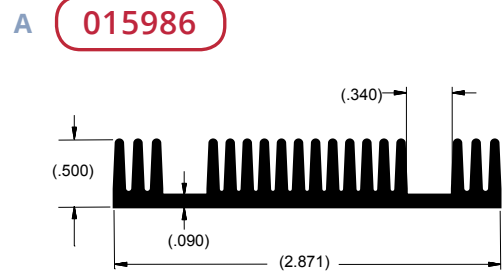
Per.	24.47	in.
WT.	1.20	lb/ft
θsa	3.40	°C/w/3"



Per.	27.36	in.
WT.	2.32	lb/ft
θsa	2.56	°C/w/3"



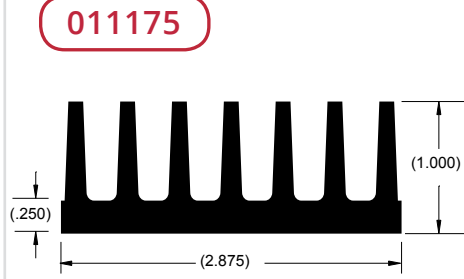
Per.	15.24	in.
WT.	0.77	lb/ft
θsa	7.00	°C/w/3"



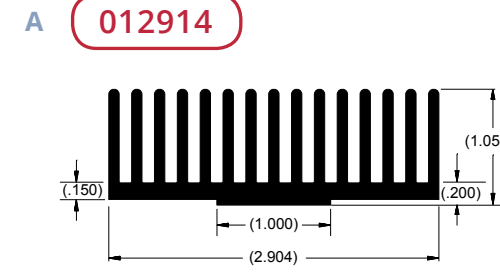
Per.	18.85	in.
WT.	0.88	lb/ft
θsa	6.30	°C/w/3"



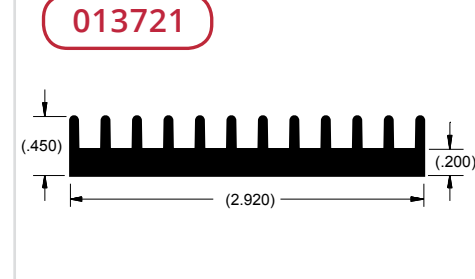
Per.	25.86	in.
WT.	1.81	lb/ft
θsa	2.80	°C/w/3"



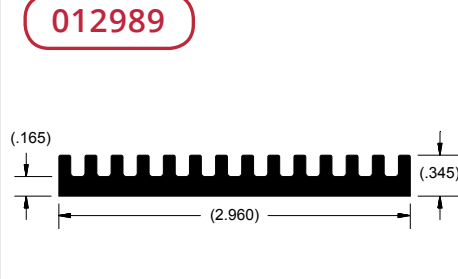
Per.	16.33	in.
WT.	1.86	lb/ft
θsa	4.30	°C/w/3"



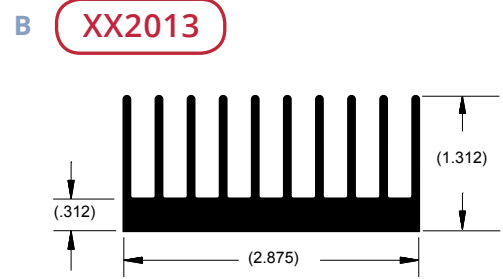
Per.	30.94	in.
WT.	1.86	lb/ft
θsa	2.30	°C/w/3"



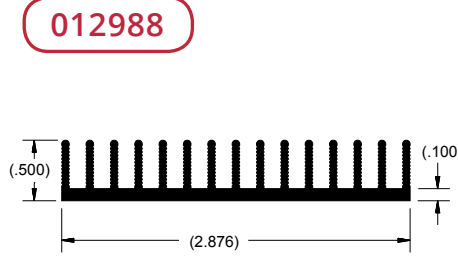
Per.	11.76	in.
WT.	0.91	lb/ft
θsa	6.00	°C/w/3"



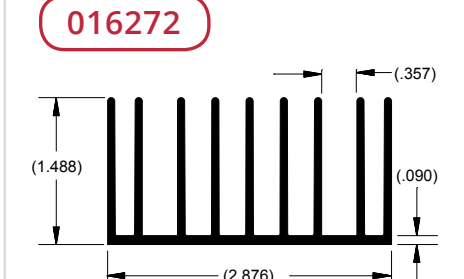
Per.	10.74	in.
WT.	0.89	lb/ft
θsa	6.50	°C/w/3"



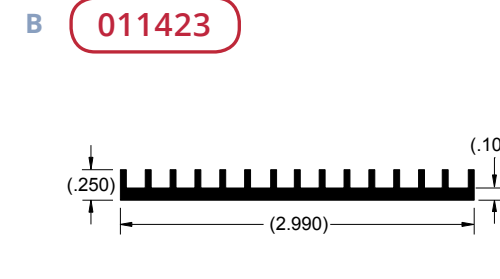
Per.	25.66	in.
WT.	1.76	lb/ft
θsa	2.30	°C/w/3"



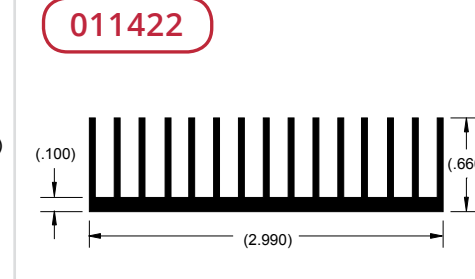
Per.	20.13	in.
WT.	0.72	lb/ft
θsa	3.50	°C/w/3"



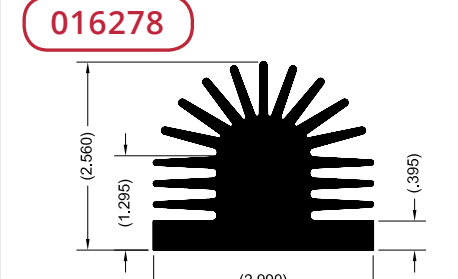
Per.	30.65	in.
WT.	1.44	lb/ft
θsa	2.60	°C/w/3"



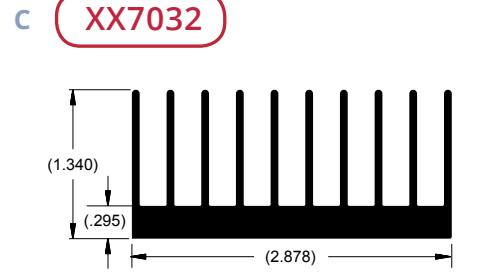
Per.	10.56	in.
WT.	0.48	lb/ft
θsa	6.60	°C/w/3"



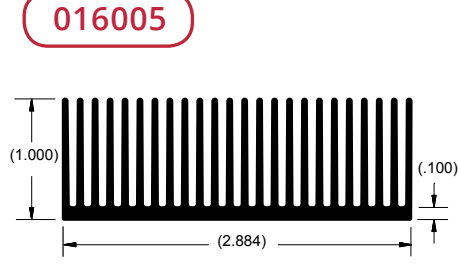
Per.	22.86	in.
WT.	0.84	lb/ft
θsa	3.10	°C/w/3"



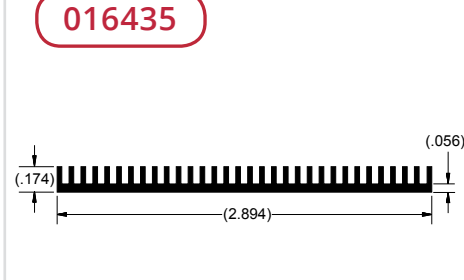
Per.	31.34	in.
WT.	4.84	lb/ft
θsa	2.30	°C/w/3"



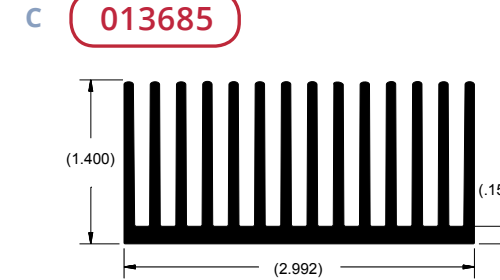
Per.	28.41	in.
WT.	1.91	lb/ft
θsa	2.80	°C/w/3"



Per.	48.21	in.
WT.	1.23	lb/ft
θsa	5.80	°C/w/3"



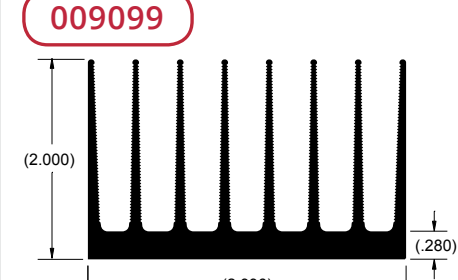
Per.	13.45	in.
WT.	0.36	lb/ft
θsa	12.10	°C/w/3"



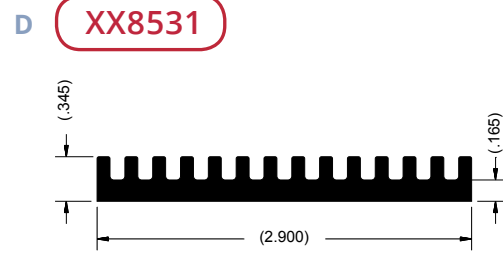
Per.	40.47	in.
WT.	2.32	lb/ft
θsa	1.70	°C/w/3"



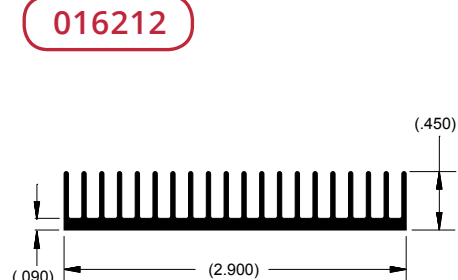
Per.	33.84	in.
WT.	1.80	lb/ft
θsa	2.10	°C/w/3"



Per.	45.93	in.
WT.	2.56	lb/ft
θsa	1.50	°C/w/3"



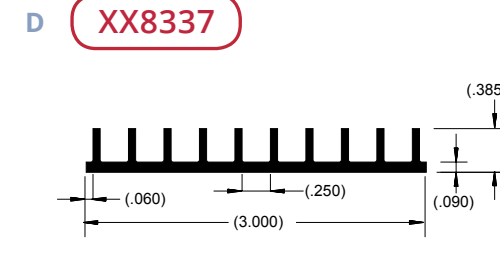
Per.	10.70	in.
WT.	0.83	lb/ft
θsa	8.50	°C/w/3"



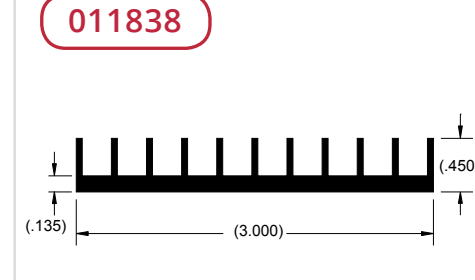
Per.	19.78	in.
WT.	0.63	lb/ft
θsa	5.60	°C/w/3"



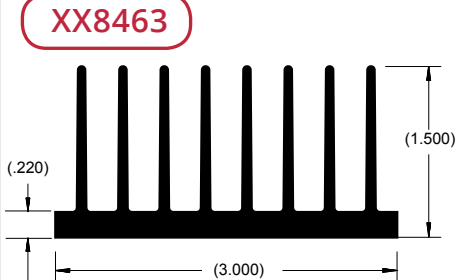
Per.	26.14	in.
WT.	1.82	lb/ft
θsa	3.10	°C/w/3"



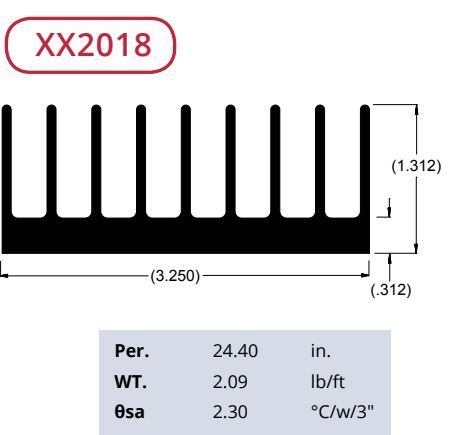
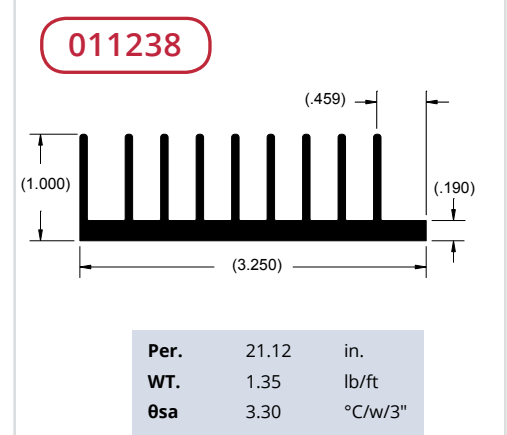
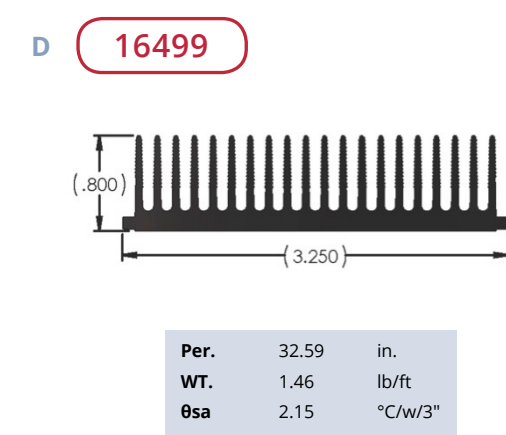
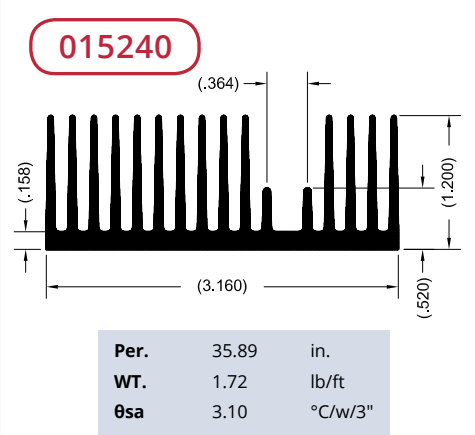
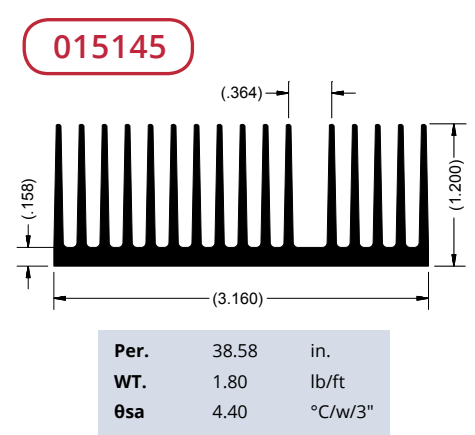
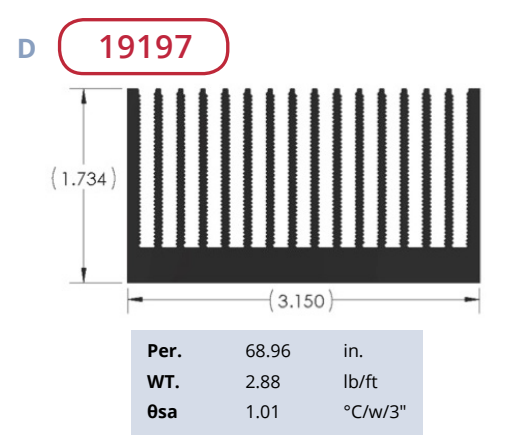
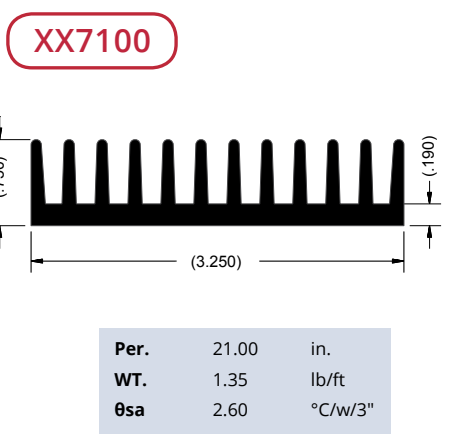
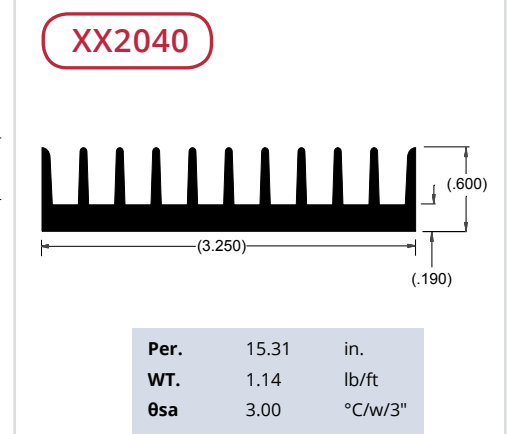
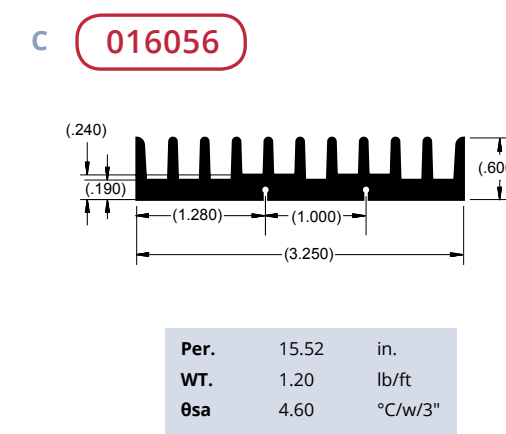
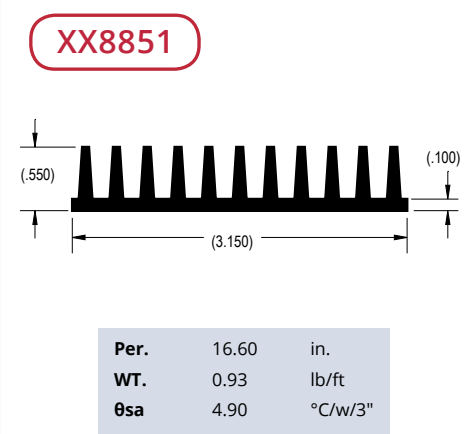
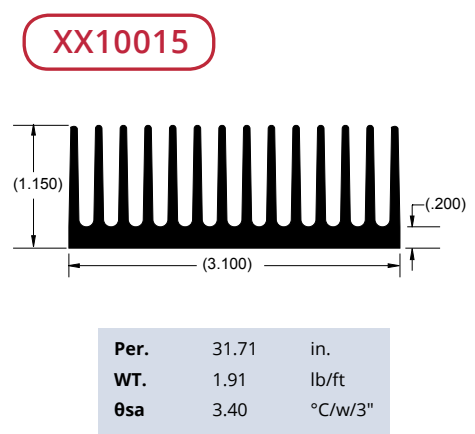
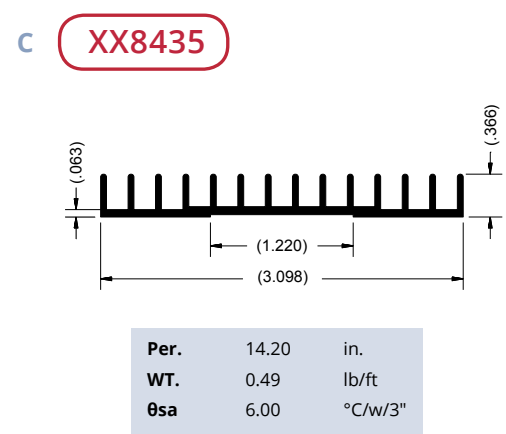
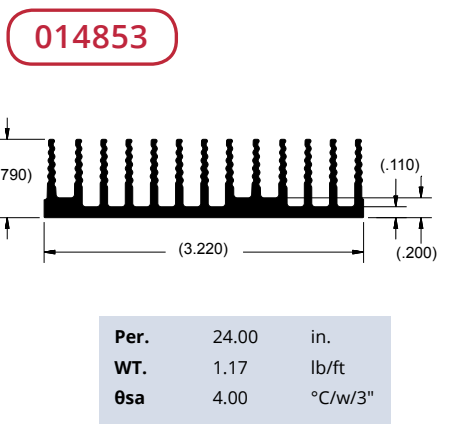
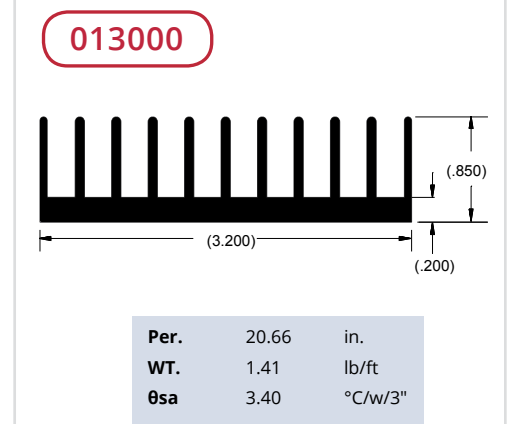
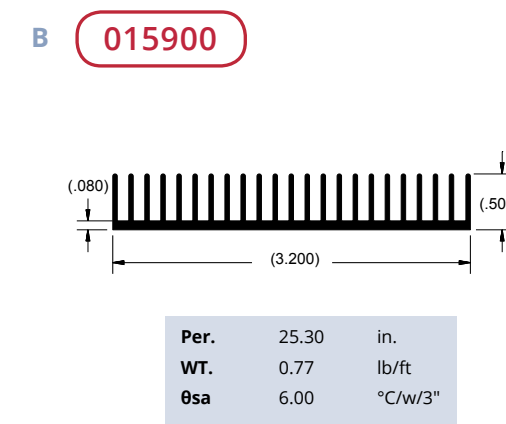
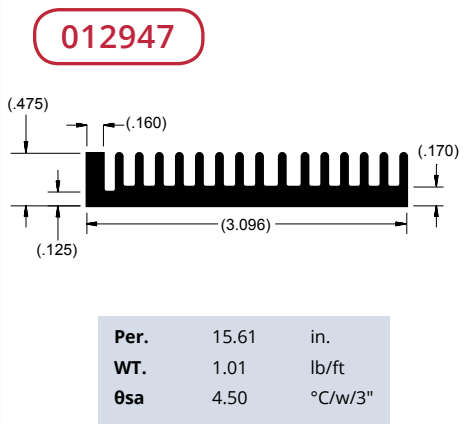
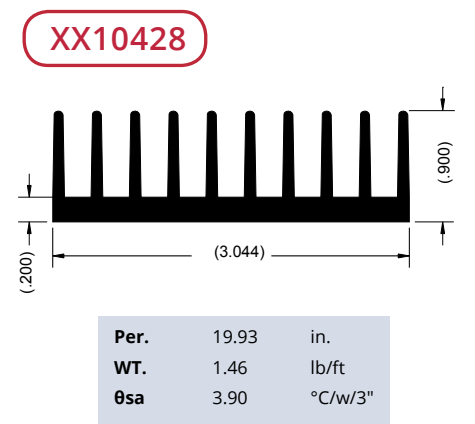
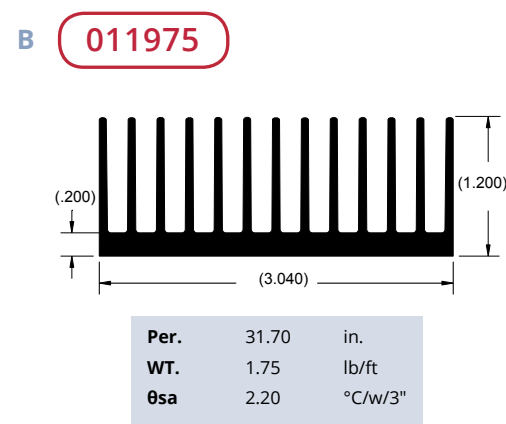
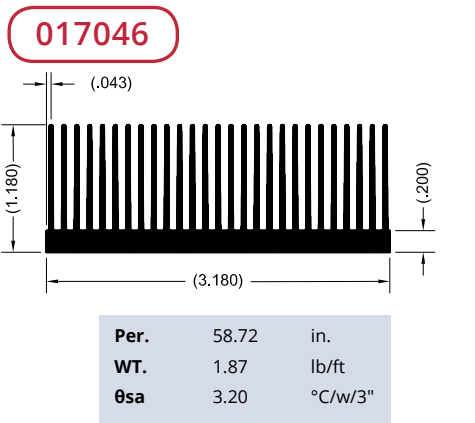
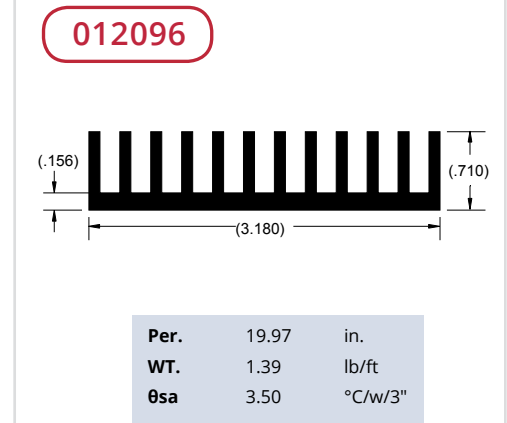
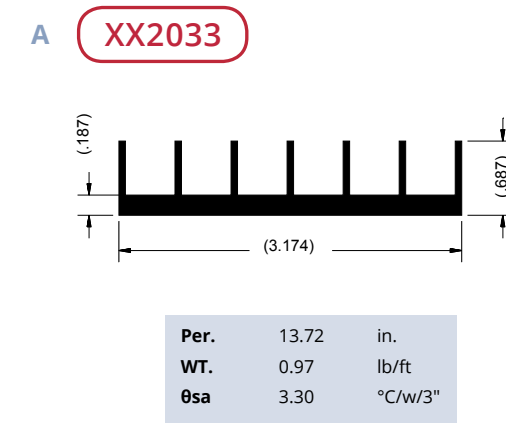
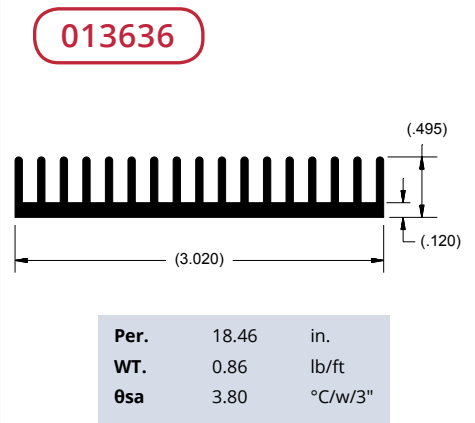
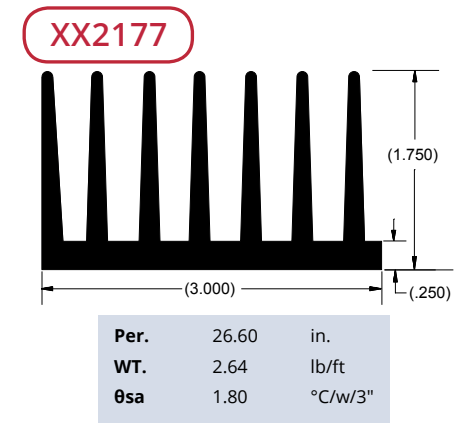
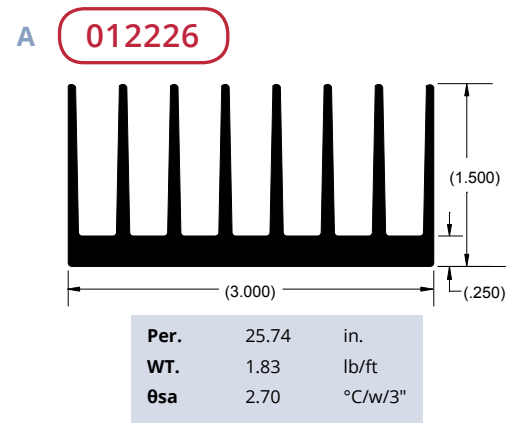
Per.	11.70	in.
WT.	0.51	lb/ft
θsa	5.50	°C/w/3"

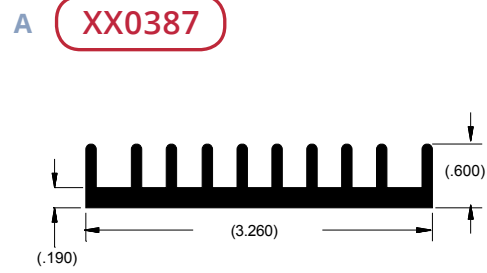


Per.	13.11	in.
WT.	0.67	lb/ft
θsa	5.30	°C/w/3"

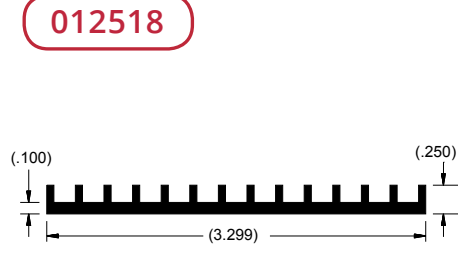


Per.	26.30	in.
WT.	1.54	lb/ft
θsa	2.80	°C/w/3"

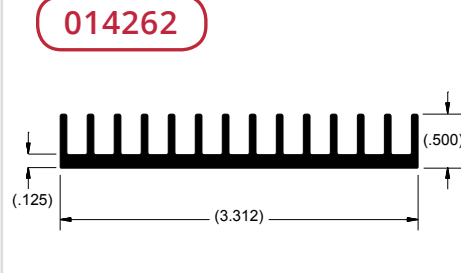




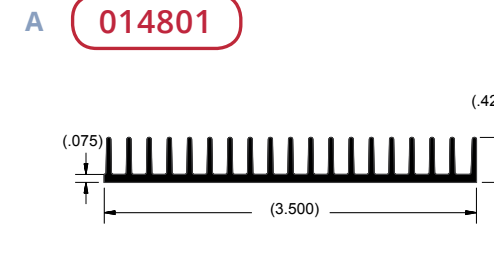
Per.	15.10	in.
WT.	1.23	lb/ft
θsa	4.40	°C/w/3"



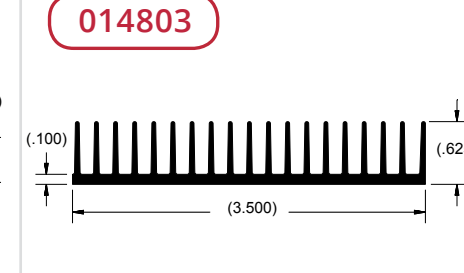
Per.	10.89	in.
WT.	0.54	lb/ft
θsa	6.40	°C/w/3"



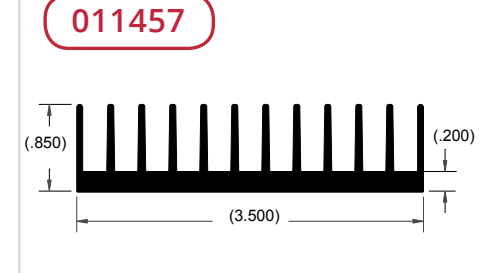
Per.	16.94	in.
WT.	0.88	lb/ft
θsa	4.10	°C/w/3"



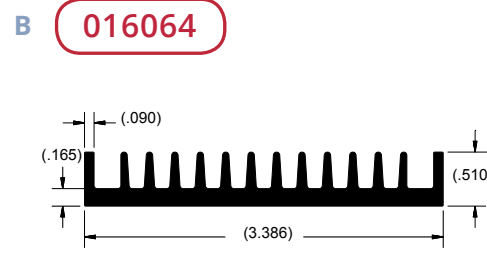
Per.	19.65	in.
WT.	0.67	lb/ft
θsa	5.30	°C/w/3"



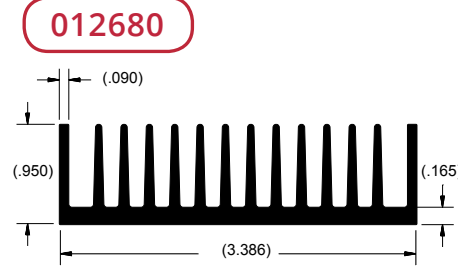
Per.	26.23	in.
WT.	0.98	lb/ft
θsa	4.50	°C/w/3"



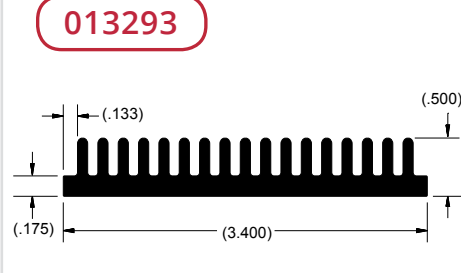
Per.	22.48	in.
WT.	1.48	lb/ft
θsa	3.00	°C/w/3"



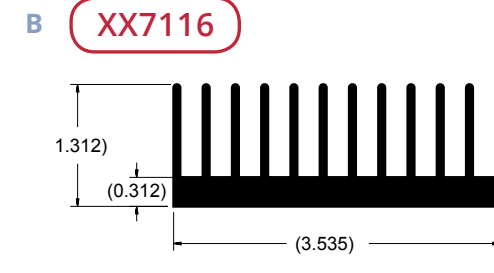
Per.	15.71	in.
WT.	1.13	lb/ft
θsa	5.20	°C/w/3"



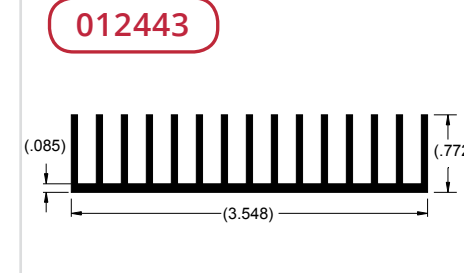
Per.	27.96	in.
WT.	1.74	lb/ft
θsa	2.50	°C/w/3"



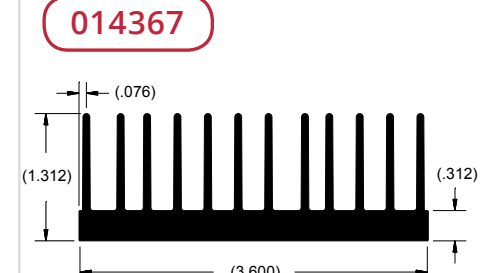
Per.	17.07	in.
WT.	1.29	lb/ft
θsa	4.10	°C/w/3"



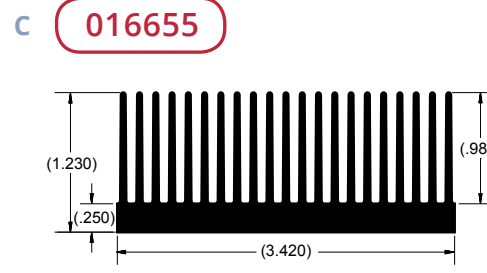
Per.	31.33	in.
WT.	2.32	lb/ft
θsa	2.40	°C/w/3"



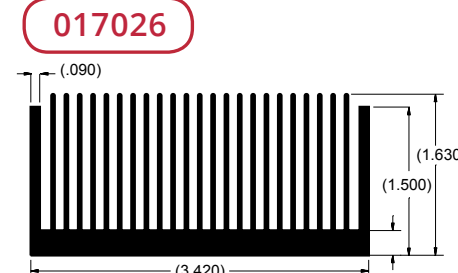
Per.	27.76	in.
WT.	1.10	lb/ft
θsa	2.50	°C/w/3"



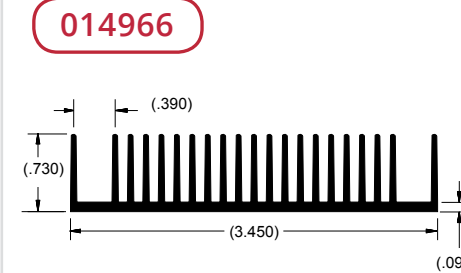
Per.	31.04	in.
WT.	2.42	lb/ft
θsa	2.30	°C/w/3"



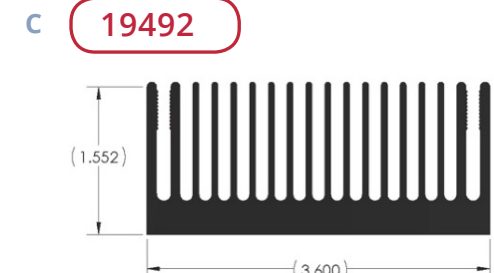
Per.	47.29	in.
WT.	2.33	lb/ft
θsa	4.90	°C/w/3"



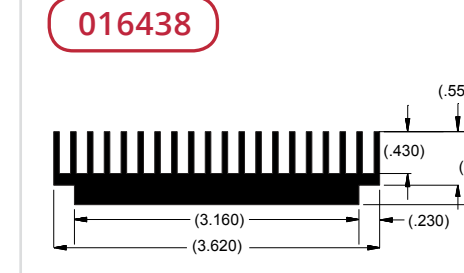
Per.	75.51	in.
WT.	2.47	lb/ft
θsa	5.40	°C/w/3"



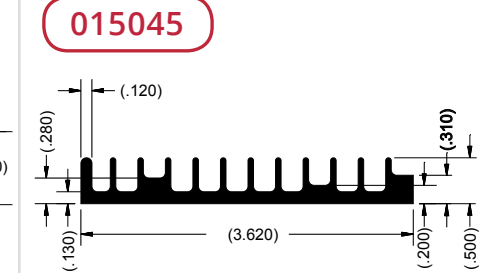
Per.	33.25	in.
WT.	1.22	lb/ft
θsa	4.80	°C/w/3"



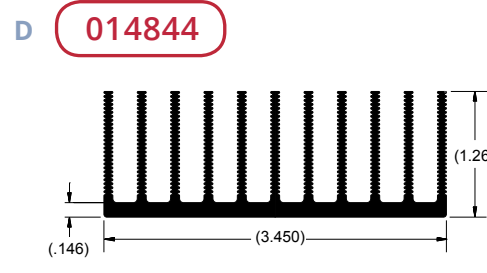
Per.	51.76	in.
WT.	3.39	lb/ft
θsa	1.35	°C/w/3"



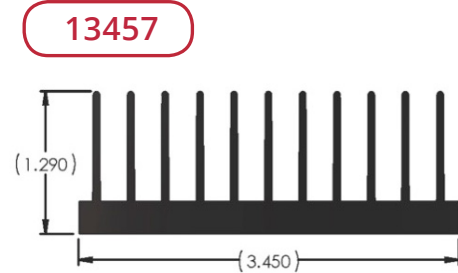
Per.	25.08	in.
WT.	1.92	lb/ft
θsa	4.20	°C/w/3"



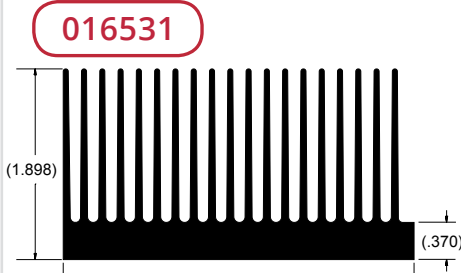
Per.	15.01	in.
WT.	1.04	lb/ft
θsa	4.90	°C/w/3"



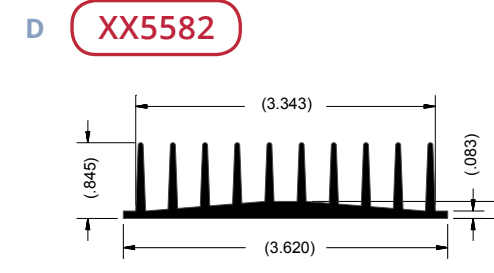
Per.	44.42	in.
WT.	1.62	lb/ft
θsa	1.60	°C/w/3"



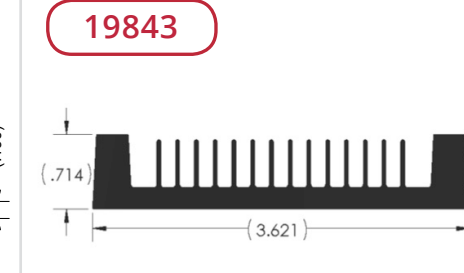
Per.	28.99	in.
WT.	2.07	lb/ft
θsa	2.41	°C/w/3"



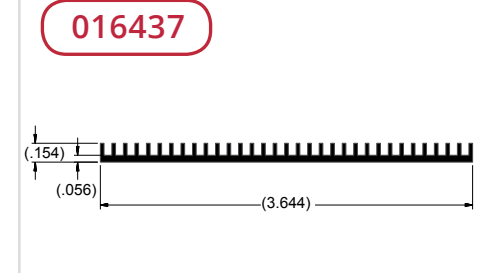
Per.	64.12	in.
WT.	3.67	lb/ft
θsa	2.60	°C/w/3"



Per.	20.71	in.
WT.	1.26	lb/ft
θsa	2.80	°C/w/3"



Per.	21.58	in.
WT.	1.67	lb/ft
θsa	3.24	°C/w/3"



Per.	13.87	in.
WT.	0.38	lb/ft
θsa	12.00	°C/w/3"

Not all stocked. Example shapes are not all tooled.

**A XX2005**

Per.	19.09	in.
WT.	0.93	lb/ft
θsa	3.70	°C/w/3"

**009797**

Per.	26.14	in.
WT.	1.42	lb/ft
θsa	2.50	°C/w/3"

**017030**

Per.	90.66	in.
WT.	2.75	lb/ft
θsa	5.20	°C/w/3"

**A XX2250**

Per.	33.78	in.
WT.	4.16	lb/ft
θsa	1.90	°C/w/3"

**21295**

Per.	46.61	in.
WT.	2.67	lb/ft
θsa	1.50	°C/w/3"

**016270**

Per.	38.86	in.
WT.	1.84	lb/ft
θsa	2.50	°C/w/3"

**B XX2019**

Per.	26.80	in.
WT.	1.17	lb/ft
θsa	2.20	°C/w/3"

**012108**

Per.	27.04	in.
WT.	0.92	lb/ft
θsa	2.60	°C/w/3"

**014284**

Per.	27.38	in.
WT.	1.83	lb/ft
θsa	2.50	°C/w/3"

**B 012396**

Per.	21.49	in.
WT.	2.53	lb/ft
θsa	3.30	°C/w/3"

**XX10192**

Per.	21.60	in.
WT.	1.32	lb/ft
θsa	3.61	°C/w/3"

**17049**

Per.	34.61	in.
WT.	3.83	lb/ft
θsa	2.02	°C/w/3"

**C 012423**

Per.	34.74	in.
WT.	3.74	lb/ft
θsa	2.00	°C/w/3"

**013542**

Per.	15.57	in.
WT.	1.12	lb/ft
θsa	4.60	°C/w/3"

**XX2052**

Per.	15.66	in.
WT.	2.61	lb/ft
θsa	2.80	°C/w/3"

**C XX5079**

Per.	39.77	in.
WT.	2.66	lb/ft
θsa	1.50	°C/w/3"

**016304**

Per.	39.82	in.
WT.	2.57	lb/ft
θsa	1.80	°C/w/3"

**012932**

Per.	15.95	in.
WT.	0.75	lb/ft
θsa	4.40	°C/w/3"

**D 011758**

Per.	28.77	in.
WT.	2.06	lb/ft
θsa	2.40	°C/w/3"

**015019**

Per.	51.89	in.
WT.	4.89	lb/ft
θsa	2.50	°C/w/3"

**011077**

Per.	17.56	in.
WT.	0.70	lb/ft
θsa	4.00	°C/w/3"

**D 012166**

Per.	21.44	in.
WT.	1.49	lb/ft
θsa	6.20	°C/w/3"

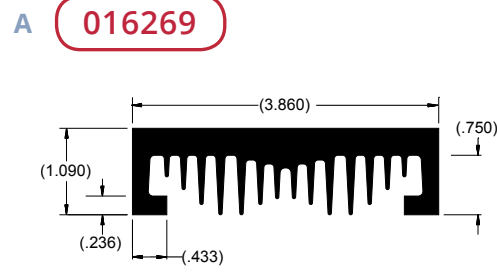
**013143**

Per.	47.17	in.
WT.	2.66	lb/ft
θsa	1.50	°C/w/3"

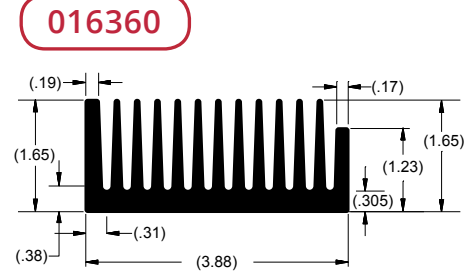
**19457**

Per.	33.426	in.
WT.	2.51	lb/ft
θsa	2.09	°C/w/3"

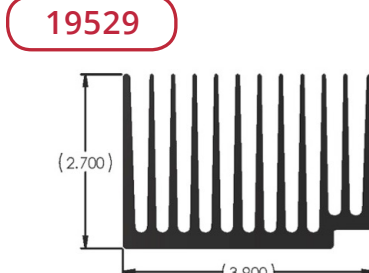




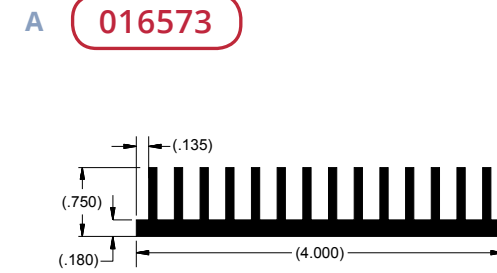
Per.	25.82	in.
WT.	2.93	lb/ft
θsa	3.30	°C/w/3"



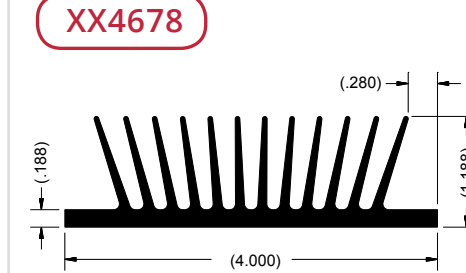
Per.	40.33	in.
WT.	3.89	lb/ft
θsa	2.90	°C/w/3"



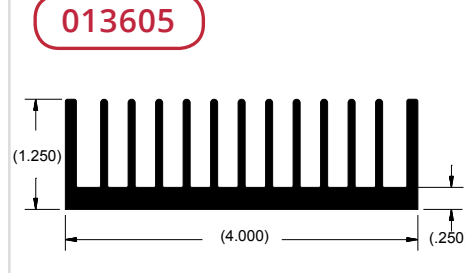
Per.	63.88	in.
WT.	4.66	lb/ft
θsa	1.09	°C/w/3"



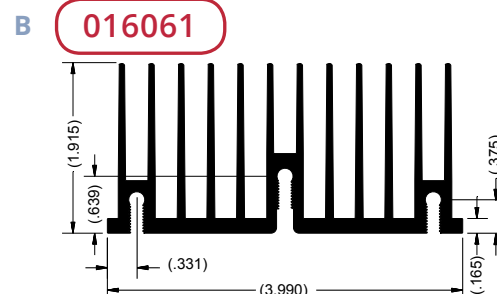
Per.	24.32	in.
WT.	1.73	lb/ft
θsa	3.70	°C/w/3"



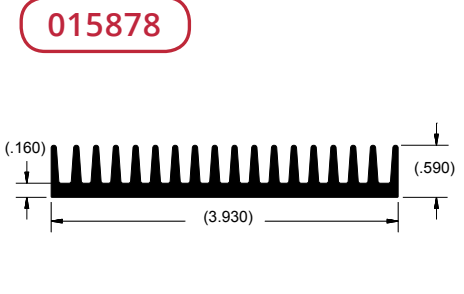
Per.	32.90	in.
WT.	1.93	lb/ft
θsa	2.30	°C/w/3"



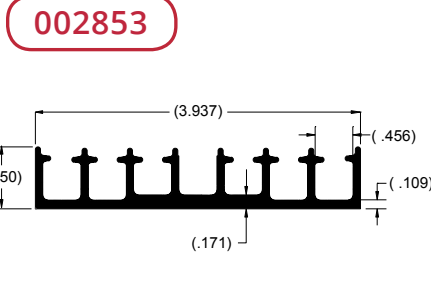
Per.	33.87	in.
WT.	2.55	lb/ft
θsa	2.10	°C/w/3"



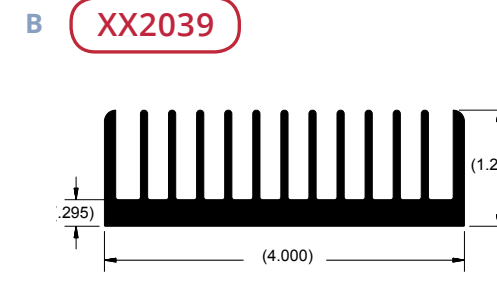
Per.	51.63	in.
WT.	2.81	lb/ft
θsa	2.30	°C/w/3"



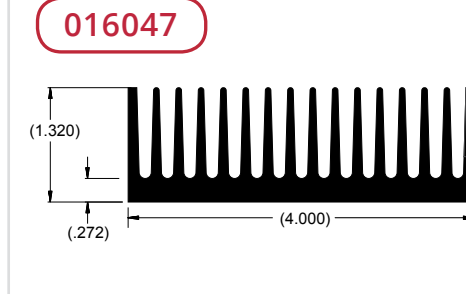
Per.	21.95	in.
WT.	1.54	lb/ft
θsa	9.70	°C/w/3"



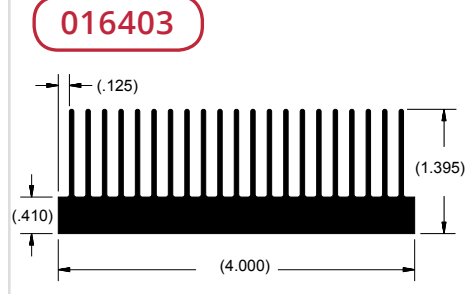
Per.	22.00	in.
WT.	1.20	lb/ft
θsa	3.20	°C/w/3"



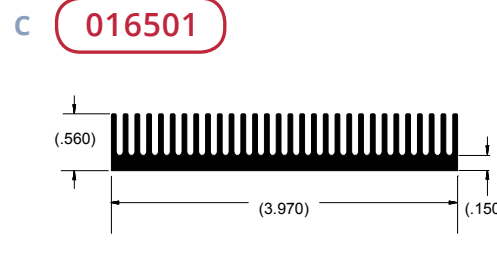
Per.	33.66	in.
WT.	2.75	lb/ft
θsa	1.90	°C/w/3"



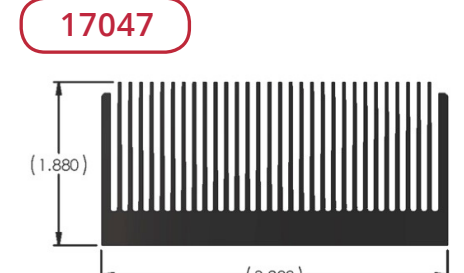
Per.	40.03	in.
WT.	3.15	lb/ft
θsa	2.70	°C/w/3"



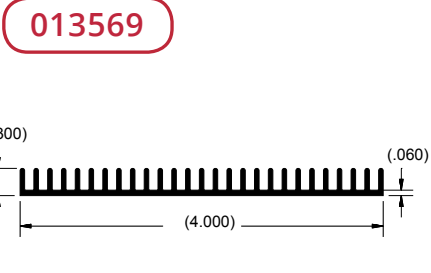
Per.	49.20	in.
WT.	3.21	lb/ft
θsa	3.40	°C/w/3"



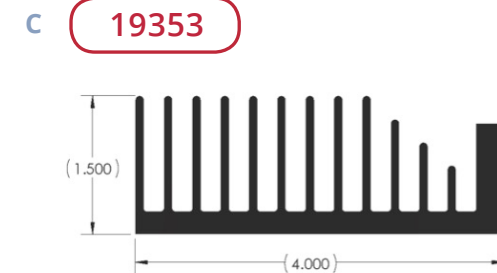
Per.	31.46	in.
WT.	1.55	lb/ft
θsa	6.10	°C/w/3"



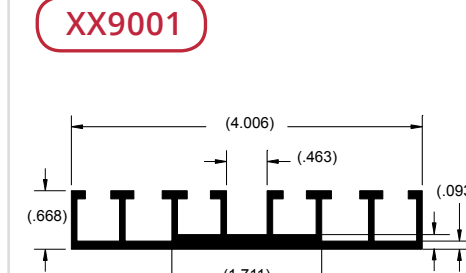
Per.	102.27	in.
WT.	4.33	lb/ft
θsa	0.68	°C/w/3"



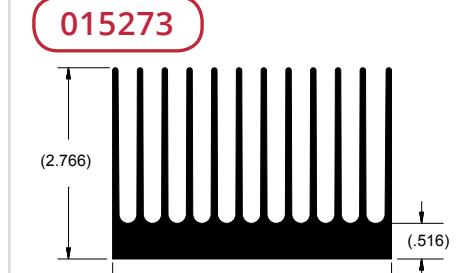
Per.	20.17	in.
WT.	0.67	lb/ft
θsa	7.20	°C/w/3"



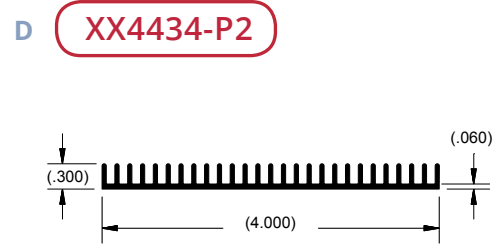
Per.	36.60	in.
WT.	2.99	lb/ft
θsa	1.91	°C/w/3"



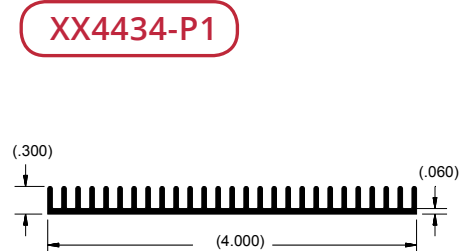
Per.	19.51	in.
WT.	1.08	lb/ft
θsa	2.40	°C/w/3"



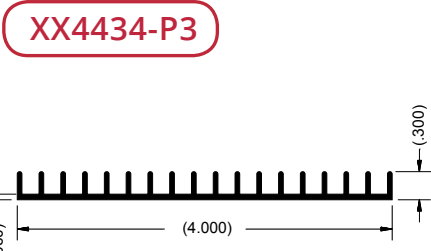
Per.	61.28	in.
WT.	5.37	lb/ft
θsa	1.80	°C/w/3"



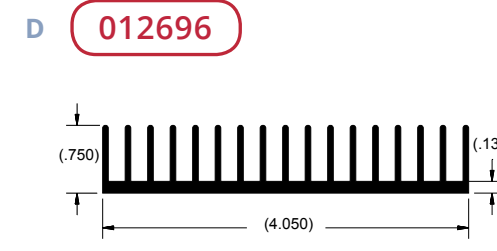
Per.	20.16	in.
WT.	0.67	lb/ft
θsa	2.70	°C/w/3"



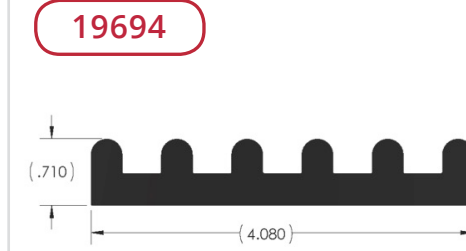
Per.	16.22	in.
WT.	0.55	lb/ft
θsa	3.00	°C/w/3"



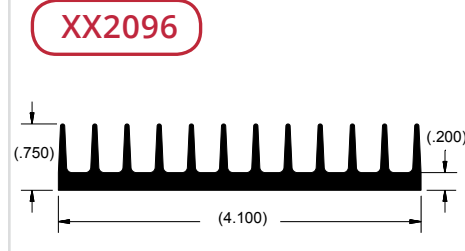
Per.	23.96	in.
WT.	0.76	lb/ft
θsa	7.00	°C/w/3"



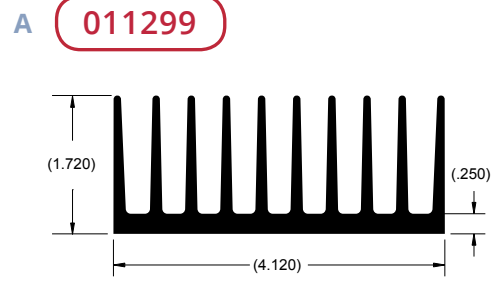
Per.	28.99	in.
WT.	1.41	lb/ft
θsa	2.40	°C/w/3"



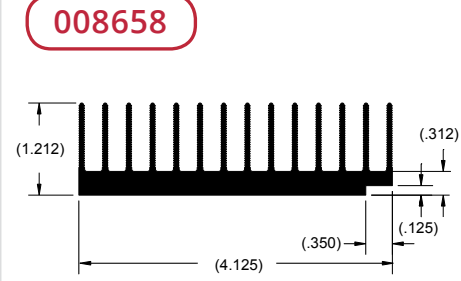
Per.	12.34	in.
WT.	2.50	lb/ft
θsa	5.66	°C/w/3"



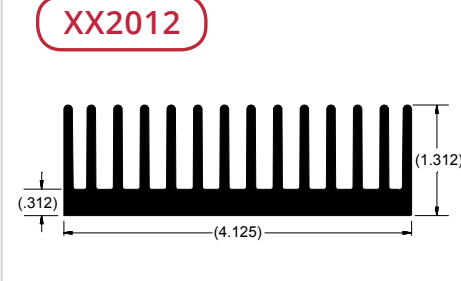
Per.	20.48	in.
WT.	1.56	lb/ft
θsa	2.50	°C/w/3"



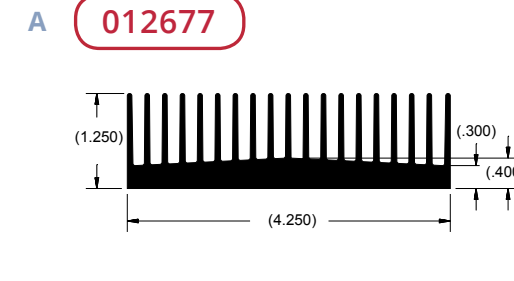
**Per.** 36.66 in.  
**WT.** 3.41 lb/ft  
**θsa** 1.90 °C/w/3"



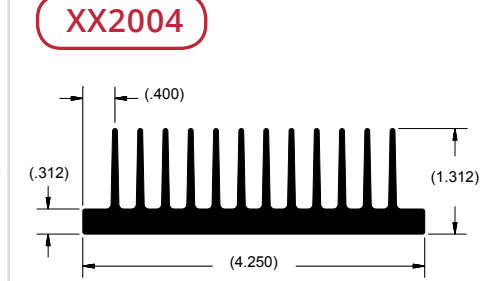
**Per.** 42.61 in.  
**WT.** 2.41 lb/ft  
**θsa** 2.20 °C/w/3"



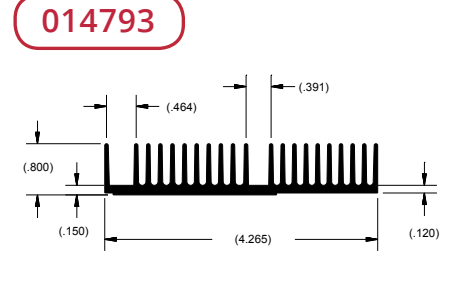
**Per.** 35.79 in.  
**WT.** 3.30 lb/ft  
**θsa** 2.00 °C/w/3"



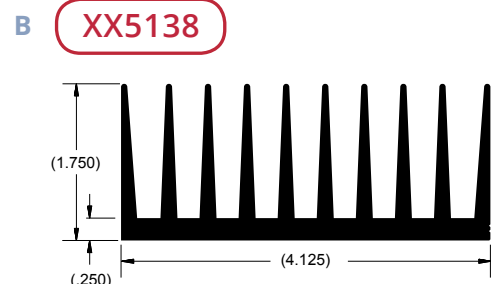
**Per.** 42.21 in.  
**WT.** 3.16 lb/ft  
**θsa** 1.70 °C/w/3"



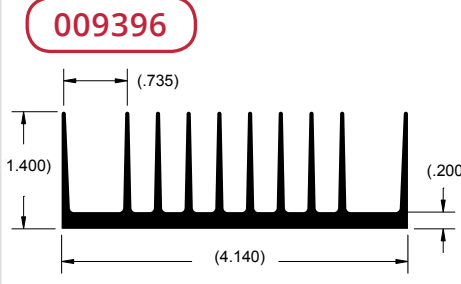
**Per.** 31.70 in.  
**WT.** 2.75 lb/ft  
**θsa** 2.20 °C/w/3"



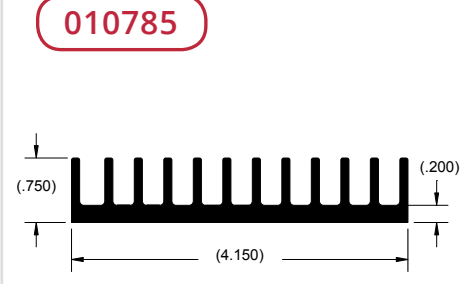
**Per.** 34.36 in.  
**WT.** 1.78 lb/ft  
**θsa** 4.30 °C/w/3"



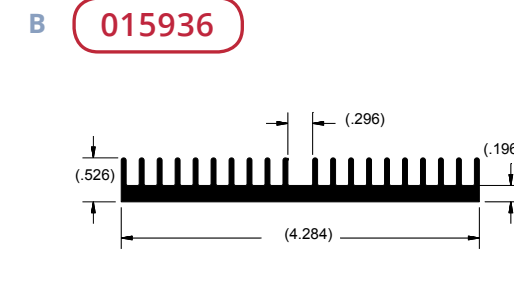
**Per.** 37.30 in.  
**WT.** 3.53 lb/ft  
**θsa** 1.90 °C/w/3"



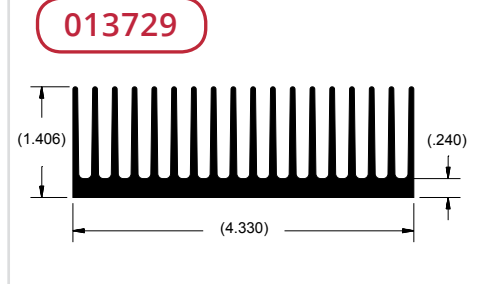
**Per.** 31.61 in.  
**WT.** 2.07 lb/ft  
**θsa** 2.10 °C/w/3"



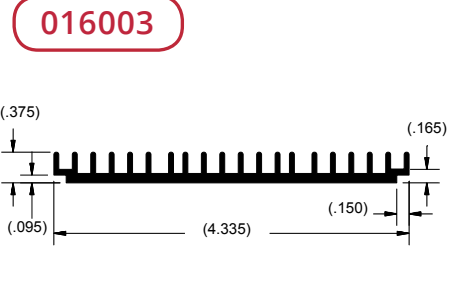
**Per.** 21.17 in.  
**WT.** 1.80 lb/ft  
**θsa** 3.20 °C/w/3"



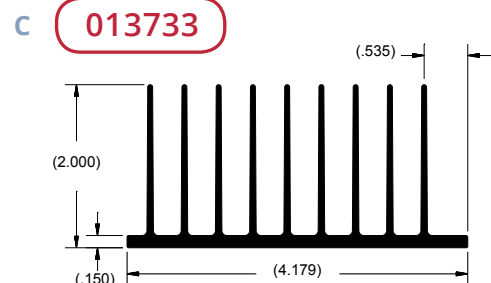
**Per.** 21.39 in.  
**WT.** 1.47 lb/ft  
**θsa** 4.50 °C/w/3"



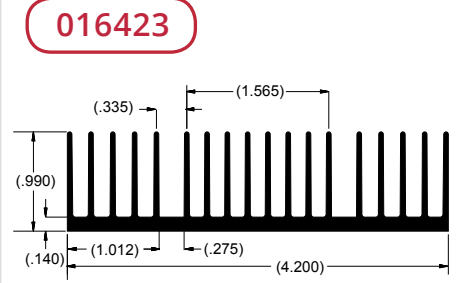
**Per.** 49.27 in.  
**WT.** 3.13 lb/ft  
**θsa** 1.40 °C/w/3"



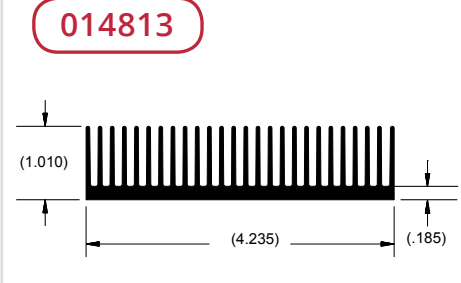
**Per.** 18.90 in.  
**WT.** 0.95 lb/ft  
**θsa** 6.10 °C/w/3"



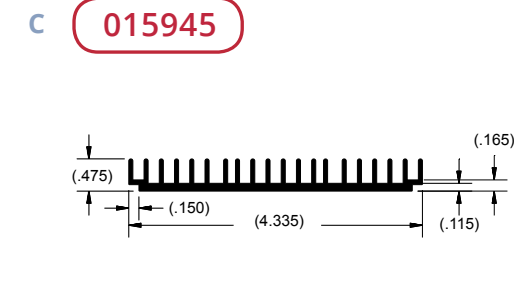
**Per.** 41.06 in.  
**WT.** 2.16 lb/ft  
**θsa** 1.70 °C/w/3"



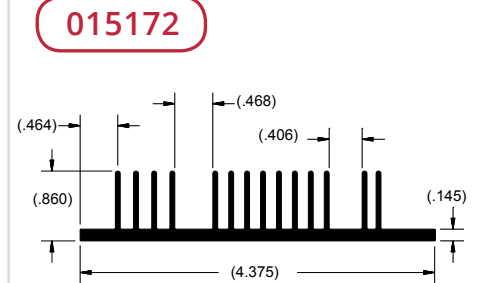
**Per.** 38.35 in.  
**WT.** 1.72 lb/ft  
**θsa** 2.90 °C/w/3"



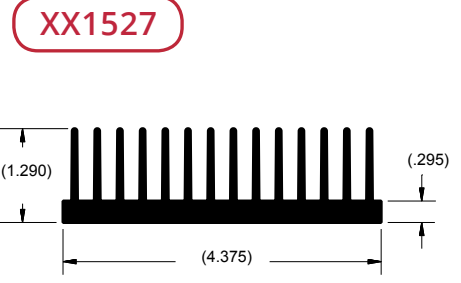
**Per.** 50.61 in.  
**WT.** 2.46 lb/ft  
**θsa** 1.40 °C/w/3"



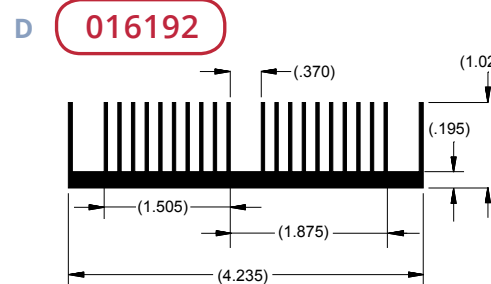
**Per.** 22.40 in.  
**WT.** 1.09 lb/ft  
**θsa** 5.80 °C/w/3"



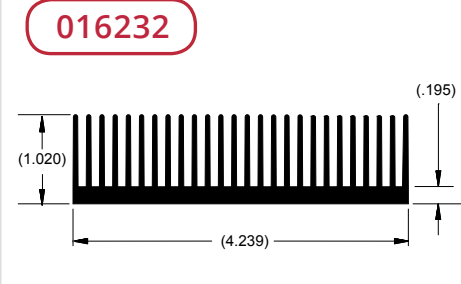
**Per.** 28.44 in.  
**WT.** 1.48 lb/ft  
**θsa** 4.20 °C/w/3"



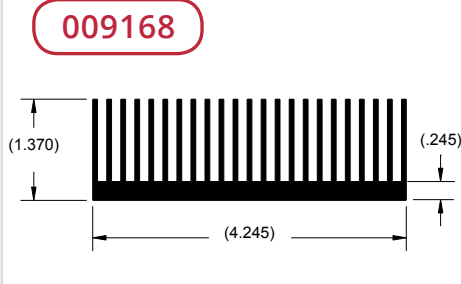
**Per.** 36.45 in.  
**WT.** 2.58 lb/ft  
**θsa** 1.40 °C/w/3"



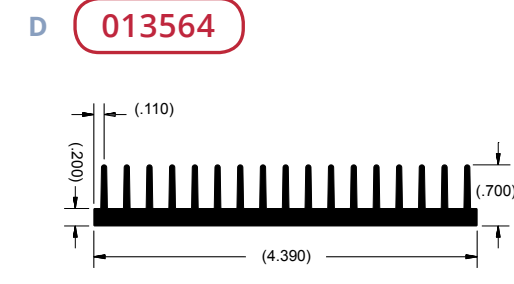
**Per.** 45.16 in.  
**WT.** 1.88 lb/ft  
**θsa** 3.60 °C/w/3"



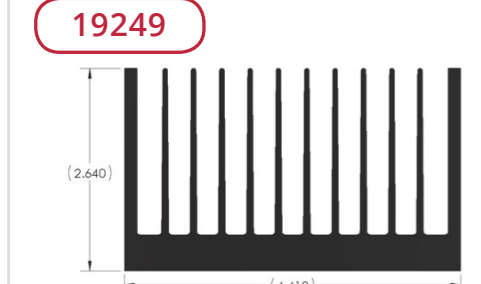
**Per.** 50.70 in.  
**WT.** 2.49 lb/ft  
**θsa** 3.70 °C/w/3"



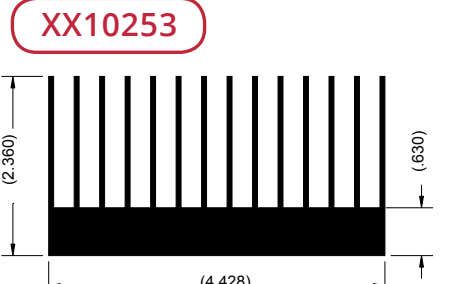
**Per.** 59.90 in.  
**WT.** 3.30 lb/ft  
**θsa** 3.50 °C/w/3"



**Per.** 25.37 in.  
**WT.** 1.74 lb/ft  
**θsa** 2.80 °C/w/3"



**Per.** 60.91 in.  
**WT.** 5.27 lb/ft  
**θsa** 1.15 °C/w/3"



**Per.** 58.56 in.  
**WT.** 5.24 lb/ft  
**θsa** 1.36 °C/w/3"

**A 17080**

Per.	118.88	in.
WT.	6.34	lb/ft
θsa	0.59	°C/w/3"

**012397**

Per.	18.60	in.
WT.	1.52	lb/ft
θsa	3.80	°C/w/3"

**XX2050**

Per.	38.94	in.
WT.	3.32	lb/ft
θsa	2.20	°C/w/3"

**A 013096**

Per.	16.43	in.
WT.	0.97	lb/ft
θsa	4.30	°C/w/3"

**013099**

Per.	22.70	in.
WT.	1.20	lb/ft
θsa	3.10	°C/w/3"

**012894**

Per.	44.20	in.
WT.	2.13	lb/ft
θsa	1.60	°C/w/3"

**B 017033**

Per.	69.28	in.
WT.	3.57	lb/ft
θsa	3.60	°C/w/3"

**012749**

Per.	36.08	in.
WT.	3.14	lb/ft
θsa	1.90	°C/w/3"

**19787**

Per.	61.33	in.
WT.	2.97	lb/ft
θsa	1.14	°C/w/3"

**B 016321**

Per.	106.91	in.
WT.	6.57	lb/ft
θsa	3.40	°C/w/3"

**015712**

Per.	149.60	in.
WT.	9.13	lb/ft
θsa	2.90	°C/w/3"

**003676**

Per.	32.39	in.
WT.	1.56	lb/ft
θsa	2.20	°C/w/3"

**C 010998**

Per.	26.42	in.
WT.	1.78	lb/ft
θsa	2.60	°C/w/3"

**XX4652**

Per.	40.32	in.
WT.	2.37	lb/ft
θsa	1.80	°C/w/3"

**015174**

Per.	57.50	in.
WT.	4.19	lb/ft
θsa	1.20	°C/w/3"

**C 007657**

Per.	24.83	in.
WT.	1.27	lb/ft
θsa	3.40	°C/w/3"

**XX3286**

Per.	24.92	in.
WT.	1.28	lb/ft
θsa	2.40	°C/w/3"

**012987**

Per.	45.36	in.
WT.	3.07	lb/ft
θsa	1.50	°C/w/3"

**D XX0233**

Per.	36.00	in.
WT.	3.15	lb/ft
θsa	1.90	°C/w/3"

**19409**

Per.	47.335	in.
WT.	3.37	lb/ft
θsa	1.48	°C/w/3"

**013756**

Per.	42.33	in.
WT.	2.61	lb/ft
θsa	1.70	°C/w/3"

**D 015862**

Per.	65.91	in.
WT.	2.55	lb/ft
θsa	1.80	°C/w/3"

**011944**

Per.	19.85	in.
WT.	1.16	lb/ft
θsa	3.90	°C/w/3"

**014770**

Per.	22.28	in.
WT.	1.18	lb/ft
θsa	6.20	°C/w/3"

**A 013618**

Per.	17.69	in.
WT.	1.14	lb/ft
θsa	4.00	°C/w/3"

**013716**

Per.	31.72	in.
WT.	1.54	lb/ft
θsa	2.20	°C/w/3"

**012823**

Per.	27.45	in.
WT.	1.40	lb/ft
θsa	2.50	°C/w/3"

**A 014320**

Per.	33.46	in.
WT.	2.81	lb/ft
θsa	2.10	°C/w/3"

**21153**

Per.	21.43	in.
WT.	0.89	lb/ft
θsa	3.26	°C/w/3"

**XX7150**

Per.	32.42	in.
WT.	2.85	lb/ft
θsa	2.40	°C/w/3"

**B 012614**

Per.	33.85	in.
WT.	1.63	lb/ft
θsa	2.10	°C/w/3"

**012777**

Per.	39.24	in.
WT.	1.77	lb/ft
θsa	1.80	°C/w/3"

**013717**

Per.	55.74	in.
WT.	2.44	lb/ft
θsa	1.30	°C/w/3"

**B 013664**

Per.	33.16	in.
WT.	3.45	lb/ft
θsa	2.10	°C/w/3"

**12447**

Per.	42.64	in.
WT.	5.23	lb/ft
θsa	1.64	°C/w/3"

**016652**

Per.	36.63	in.
WT.	3.66	lb/ft
θsa	1.70	°C/w/3"

**C 016374**

Per.	57.59	in.
WT.	3.29	lb/ft
θsa	2.30	°C/w/3"

**012918**

Per.	58.19	in.
WT.	3.74	lb/ft
θsa	1.20	°C/w/3"

**21105**

Per.	34.97	in.
WT.	4.20	lb/ft
θsa	2.00	°C/w/3"

**C 016242**

Per.	32.67	in.
WT.	3.07	lb/ft
θsa	2.30	°C/w/3"

**XX2030**

Per.	19.68	in.
WT.	1.40	lb/ft
θsa	2.40	°C/w/3"

**011005**

Per.	20.12	in.
WT.	1.05	lb/ft
θsa	3.50	°C/w/3"

**D 21139**

Per.	55.67	in.
WT.	5.45	lb/ft
θsa	1.26	°C/w/3"

**014965**

Per.	40.63	in.
WT.	1.52	lb/ft
θsa	1.70	°C/w/3"

**013203**

Per.	50.60	in.
WT.	3.17	lb/ft
θsa	1.40	°C/w/3"

**D 12405**

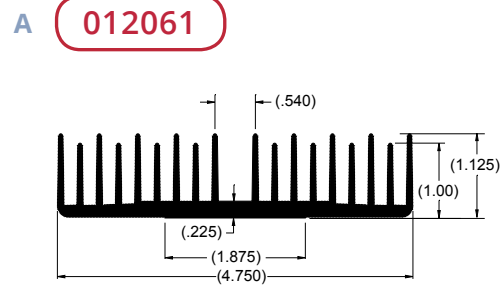
Per.	21.41	in.
WT.	1.30	lb/ft
θsa	3.27	°C/w/3"

**011942**

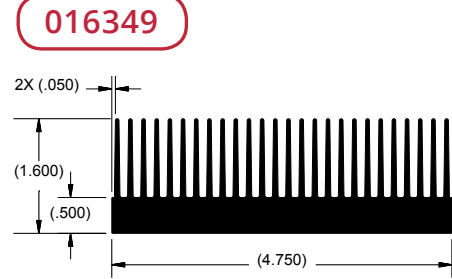
Per.	30.87	in.
WT.	1.60	lb/ft
θsa	2.30	°C/w/3"

**016123**

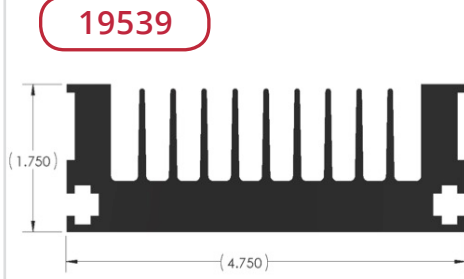
Per.	37.14	in.
WT.	3.09	lb/ft
θsa	3.60	°C/w/3"



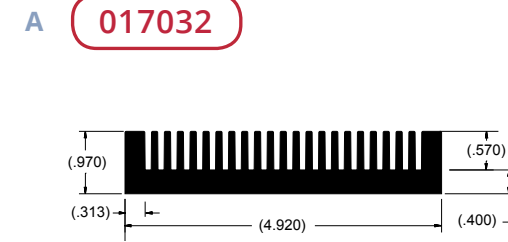
Per.	47.09	in.
WT.	2.40	lb/ft
θsa	1.50	°C/w/3"



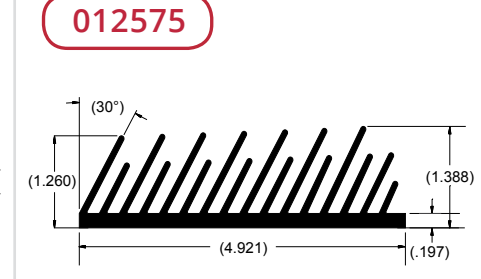
Per.	65.77	in.
WT.	5.04	lb/ft
θsa	3.80	°C/w/3"



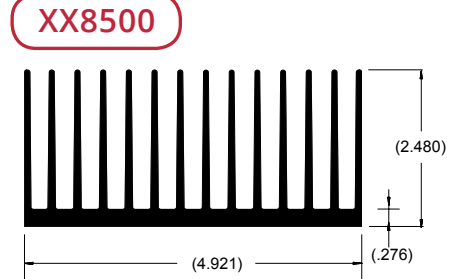
Per.	36.72	in.
WT.	5.37	lb/ft
θsa	1.90	°C/w/3"



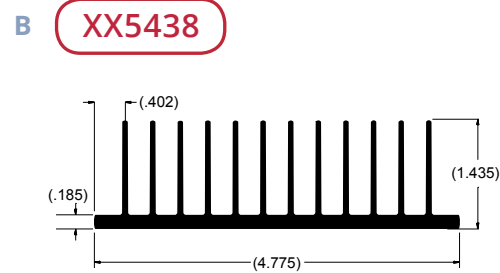
Per.	2.70	in.
WT.	4.11	lb/ft
θsa	4.80	°C/w/3"



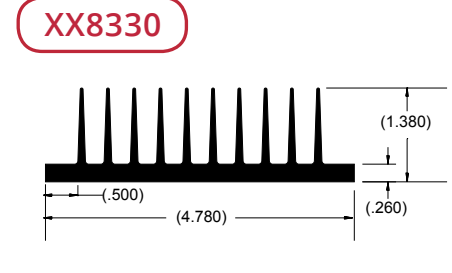
Per.	45.17	in.
WT.	2.92	lb/ft
θsa	1.50	°C/w/3"



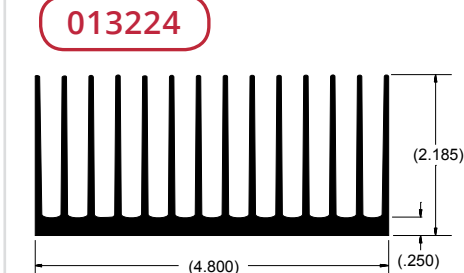
Per.	60.50	in.
WT.	6.47	lb/ft
θsa	1.30	°C/w/3"



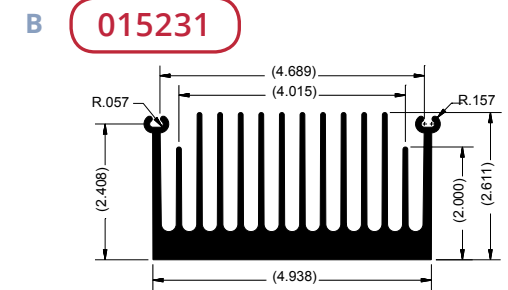
Per.	39.26	in.
WT.	2.41	lb/ft
θsa	1.80	°C/w/3"



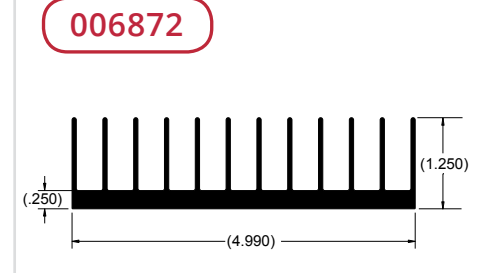
Per.	31.15	in.
WT.	2.50	lb/ft
θsa	1.90	°C/w/3"



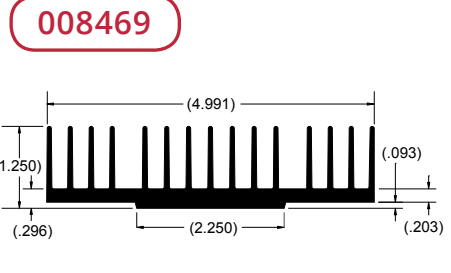
Per.	63.47	in.
WT.	3.88	lb/ft
θsa	1.10	°C/w/3"



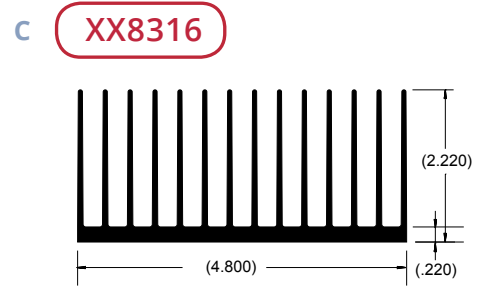
Per.	66.74	in.
WT.	6.52	lb/ft
θsa	1.60	°C/w/3"



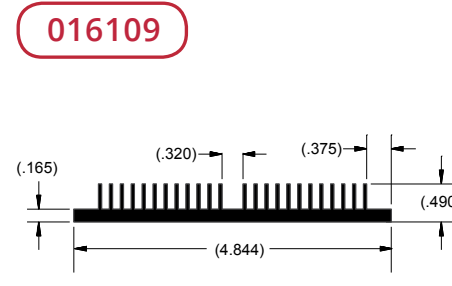
Per.	34.48	in.
WT.	2.39	lb/ft
θsa	2.00	°C/w/3"



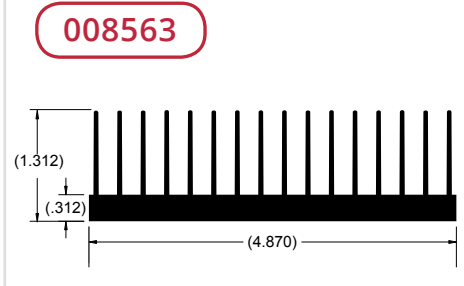
Per.	38.65	in.
WT.	2.74	lb/ft
θsa	2.40	°C/w/3"



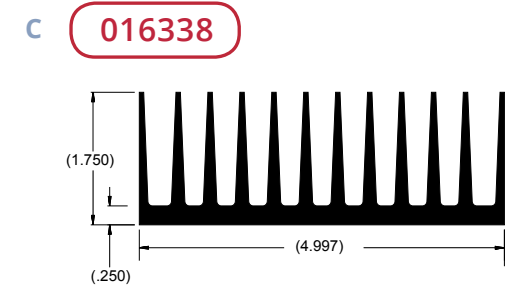
Per.	64.95	in.
WT.	3.52	lb/ft
θsa	1.40	°C/w/3"



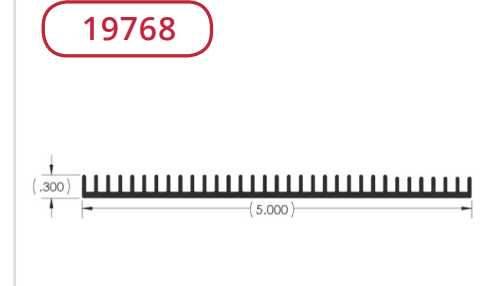
Per.	25.62	in.
WT.	1.43	lb/ft
θsa	4.84	°C/w/3"



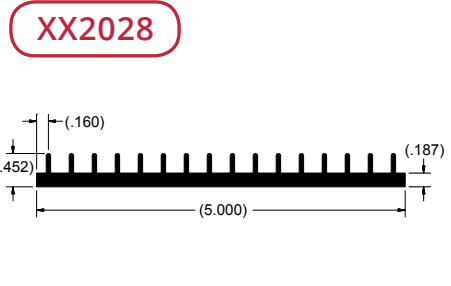
Per.	42.36	in.
WT.	3.07	lb/ft
θsa	1.70	°C/w/3"



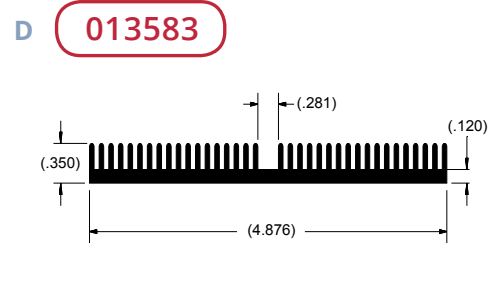
Per.	44.54	in.
WT.	4.08	lb/ft
θsa	1.70	°C/w/3"



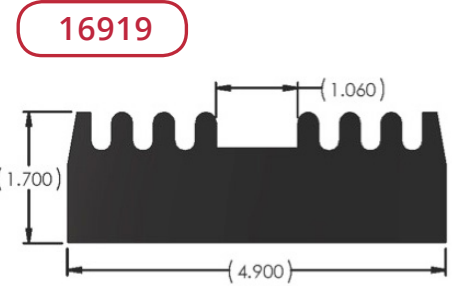
Per.	23.34	in.
WT.	0.89	lb/ft
θsa	3.00	°C/w/3"



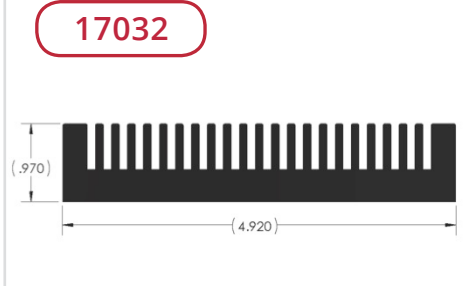
Per.	18.44	in.
WT.	1.42	lb/ft
θsa	3.00	°C/w/3"



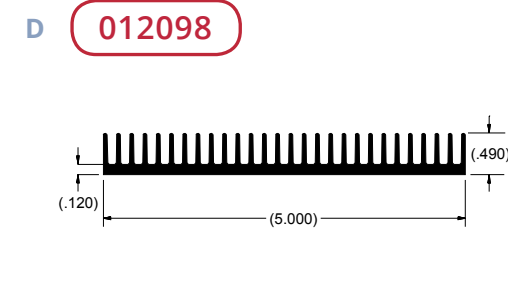
Per.	25.59	in.
WT.	1.30	lb/ft
θsa	2.70	°C/w/3"



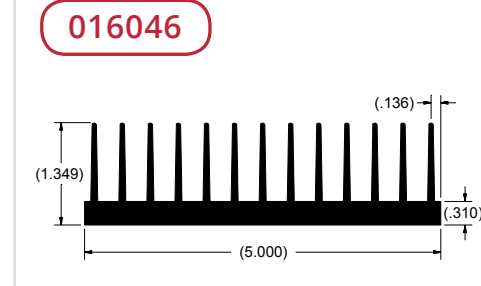
Per.	18.51	in.
WT.	8.34	lb/ft
θsa	3.78	°C/w/3"



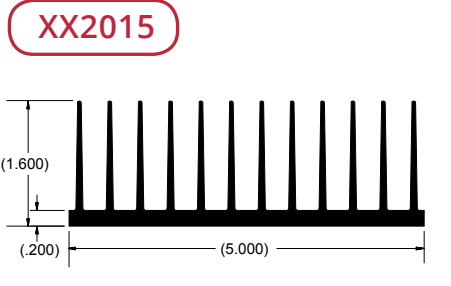
Per.	36.47	in.
WT.	4.31	lb/ft
θsa	1.92	°C/w/3"



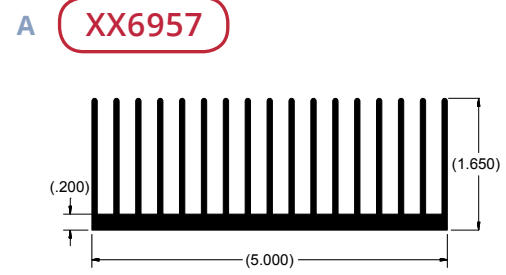
Per.	29.33	in.
WT.	1.38	lb/ft
θsa	2.40	°C/w/3"



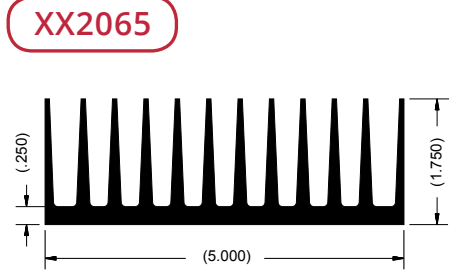
Per.	18.44	in.
WT.	1.42	lb/ft
θsa	2.10	°C/w/3"



Per.	42.85	in.
WT.	2.75	lb/ft
θsa	1.60	°C/w/3"



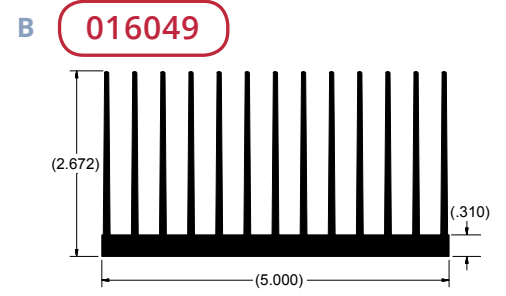
Per.	58.68	in.
WT.	3.32	lb/ft
θsa	1.50	°C/w/3"



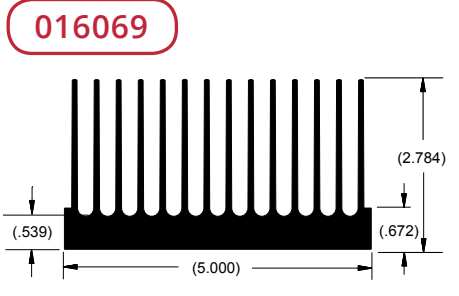
Per.	44.59	in.
WT.	4.08	lb/ft
θsa	1.60	°C/w/3"



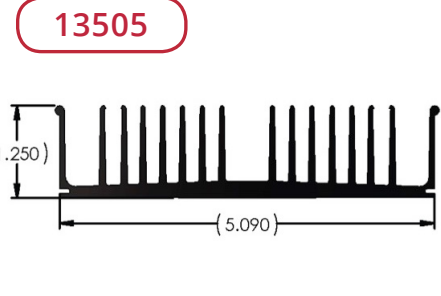
Per.	87.86	in.
WT.	5.49	lb/ft
θsa	0.80	°C/w/3"



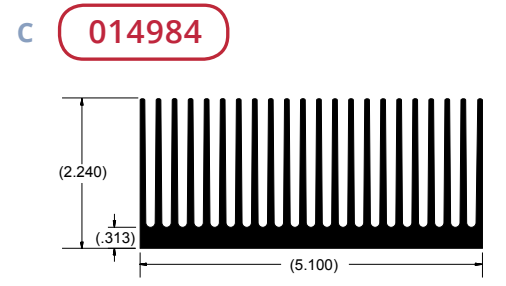
Per.	71.21	in.
WT.	4.76	lb/ft
θsa	1.40	°C/w/3"



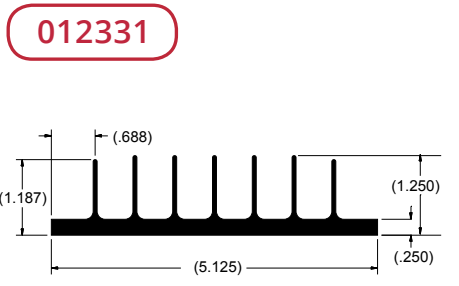
Per.	71.73	in.
WT.	6.65	lb/ft
θsa	1.50	°C/w/3"



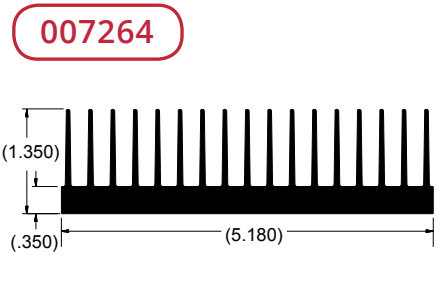
Per.	43.60	in.
WT.	2.61	lb/ft
θsa	1.60	°C/w/3"



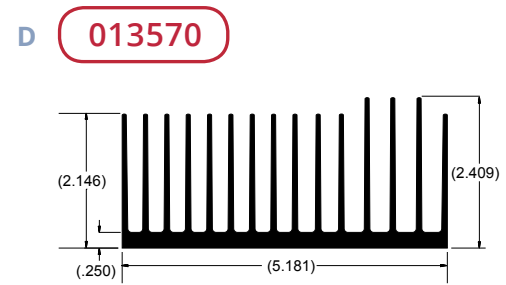
Per.	93.10	in.
WT.	5.28	lb/ft
θsa	1.80	°C/w/3"



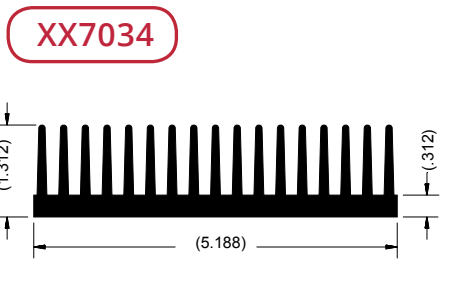
Per.	23.69	in.
WT.	2.04	lb/ft
θsa	3.00	°C/w/3"



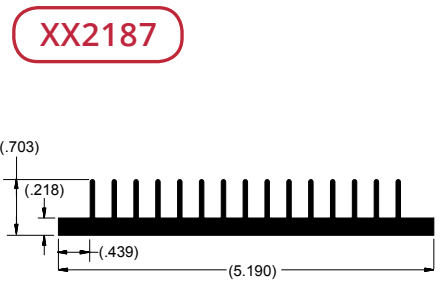
Per.	45.06	in.
WT.	3.50	lb/ft
θsa	1.60	°C/w/3"



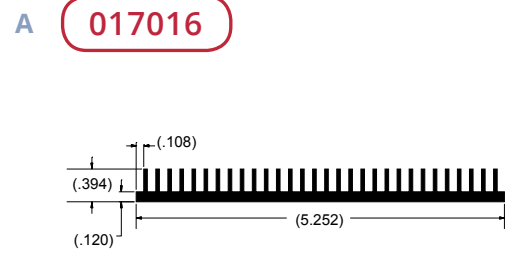
Per.	67.82	in.
WT.	4.28	lb/ft
θsa	1.60	°C/w/3"



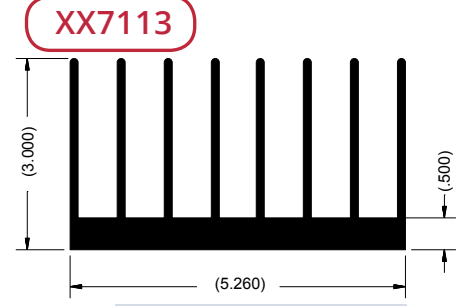
Per.	43.85	in.
WT.	3.52	lb/ft
θsa	1.70	°C/w/3"



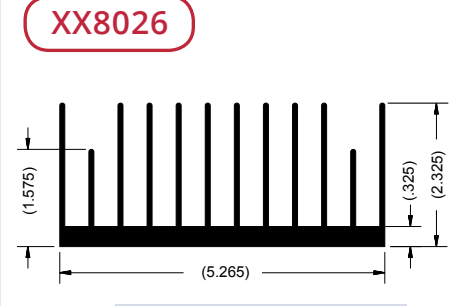
Per.	24.79	in.
WT.	1.90	lb/ft
θsa	2.90	°C/w/3"



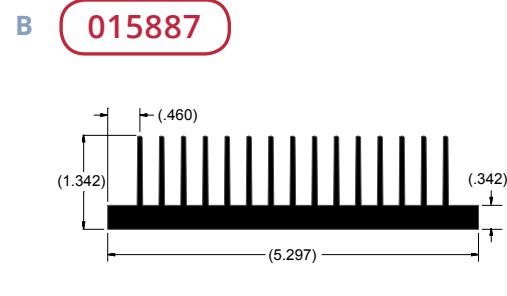
Per.	27.19	in.
WT.	1.26	lb/ft
θsa	4.90	°C/w/3"



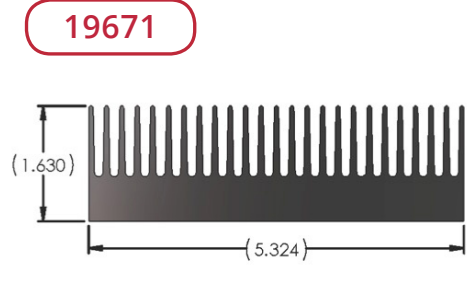
Per.	51.00	in.
WT.	6.73	lb/ft
θsa	1.10	°C/w/3"



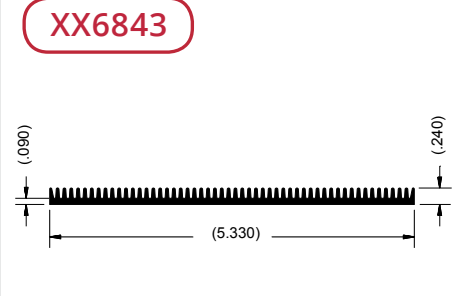
Per.	55.37	in.
WT.	4.40	lb/ft
θsa	1.30	°C/w/3"



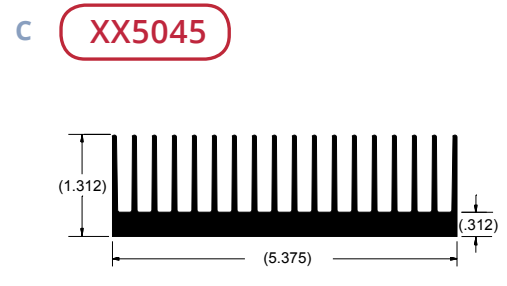
Per.	40.63	in.
WT.	3.46	lb/ft
θsa	2.40	°C/w/3"



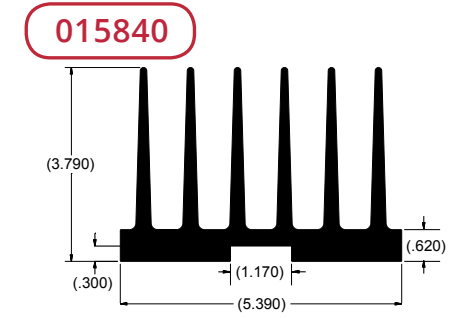
Per.	59.37	in.
WT.	6.37	lb/ft
θsa	1.18	°C/w/3"



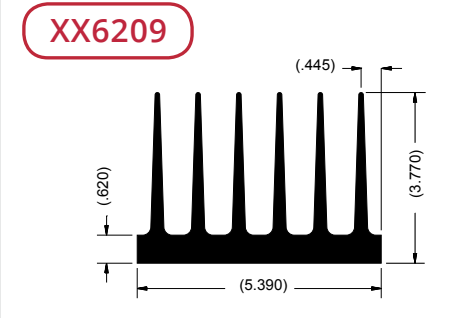
Per.	23.00	in.
WT.	1.02	lb/ft
θsa	1.02	°C/w/3"



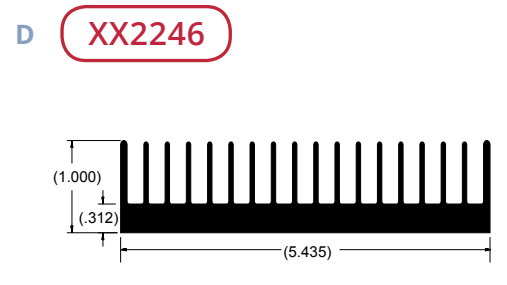
Per.	47.33	in.
WT.	3.55	lb/ft
θsa	1.80	°C/w/3"



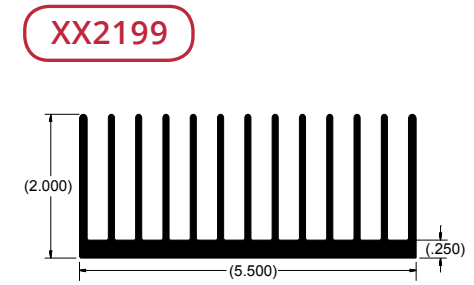
Per.	49.36	in.
WT.	8.43	lb/ft
θsa	1.10	°C/w/3"



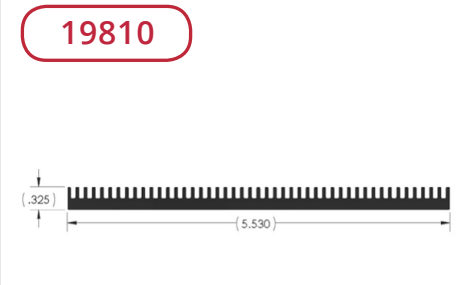
Per.	47.52	in.
WT.	8.60	lb/ft
θsa	1.40	°C/w/3"



Per.	35.25	in.
WT.	3.02	lb/ft
θsa	1.90	°C/w/3"



Per.	57.00	in.
WT.	4.48	lb/ft
θsa	1.20	°C/w/3"



Per.	24.76	in.
WT.	1.60	lb/ft
θsa	2.82	°C/w/3"

**A XX2002**

Per.	41.90	in.
WT.	3.67	lb/ft
θsa	1.50	°C/w/3"

**XX6933**

Per.	35.45	in.
WT.	1.85	lb/ft
θsa	1.80	°C/w/3"

**19036**

Per.	65.83	in.
WT.	3.26	lb/ft
θsa	1.06	°C/w/3"

**A XX8415**

Per.	81.69	in.
WT.	7.37	lb/ft
θsa	1.30	°C/w/3"

**013237**

Per.	38.67	in.
WT.	2.10	lb/ft
θsa	1.80	°C/w/3"

**016060**

Per.	81.06	in.
WT.	7.97	lb/ft
θsa	1.30	°C/w/3"

**B 19350**

Per.	138.05	in.
WT.	7.10	lb/ft
θsa	0.51	°C/w/3"

**016253**

Per.	41.36	in.
WT.	4.06	lb/ft
θsa	2.00	°C/w/3"

**016138**

Per.	64.08	in.
WT.	5.62	lb/ft
θsa	2.20	°C/w/3"

**B 013601**

Per.	59.01	in.
WT.	2.86	lb/ft
θsa	1.20	°C/w/3"

**014462**

Per.	65.25	in.
WT.	3.89	lb/ft
θsa	1.10	°C/w/3"

**19343**

Per.	74.30	in.
WT.	7.79	lb/ft
θsa	0.94	°C/w/3"

**C 19155**

Per.	44.62	in.
WT.	2.73	lb/ft
θsa	1.57	°C/w/3"

**012671**

Per.	26.67	in.
WT.	1.29	lb/ft
θsa	2.60	°C/w/3"

**XX2903**

Per.	23.87	in.
WT.	1.72	lb/ft
θsa	2.80	°C/w/3"

**C 002981**

Per.	40.00	in.
WT.	2.90	lb/ft
θsa	1.70	°C/w/3"

**21257**

Per.	49.78	in.
WT.	7.73	lb/ft
θsa	1.40	°C/w/3"

**14407**

Per.	85.79	in.
WT.	5.47	lb/ft
θsa	0.81	°C/w/3"

**D 013532**

Per.	64.81	in.
WT.	4.02	lb/ft
θsa	1.10	°C/w/3"

**010248**

Per.	59.80	in.
WT.	5.31	lb/ft
θsa	1.20	°C/w/3"

**15037**

Per.	40.40	in.
WT.	1.89	lb/ft
θsa	1.73	°C/w/3"

**D 016168**

Per.	72.89	in.
WT.	3.78	lb/ft
θsa	1.90	°C/w/3"

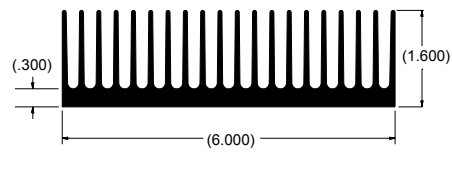
**011743**

Per.	36.74	in.
WT.	1.59	lb/ft
θsa	1.90	°C/w/3"

**012464**

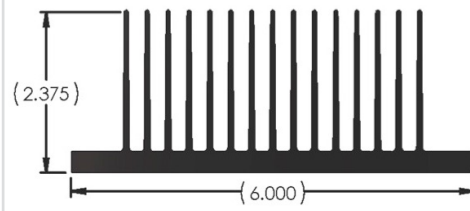
Per.	49.68	in.
WT.	3.61	lb/ft
θsa	1.40	°C/w/3"

**A 013796**



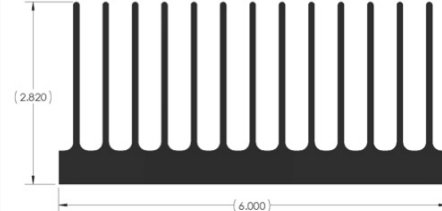
Per.	61.82	in.
WT.	4.76	lb/ft
θsa	1.10	°C/w/3"

**19341**



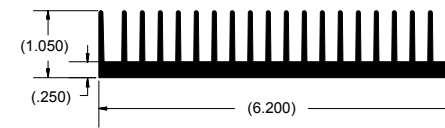
Per.	73.88	in.
WT.	5.07	lb/ft
θsa	0.95	°C/w/3"

**19864**



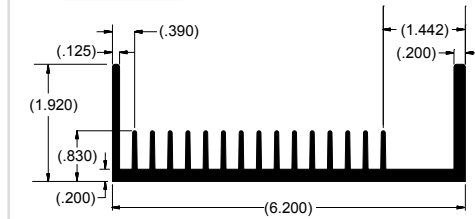
Per.	70.81	in.
WT.	7.43	lb/ft
θsa	0.99	°C/w/3"

**A 016188**



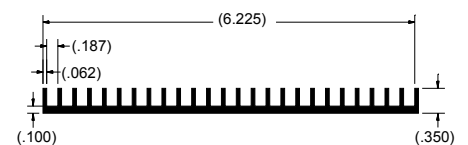
Per.	43.90	in.
WT.	3.38	lb/ft
θsa	2.50	°C/w/3"

**016187**



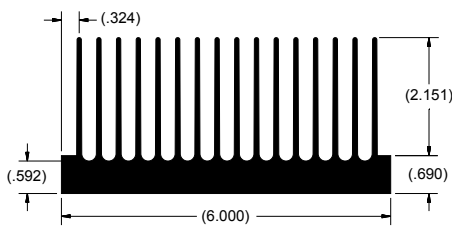
Per.	37.74	in.
WT.	3.05	lb/ft
θsa	2.70	°C/w/3"

**012693**



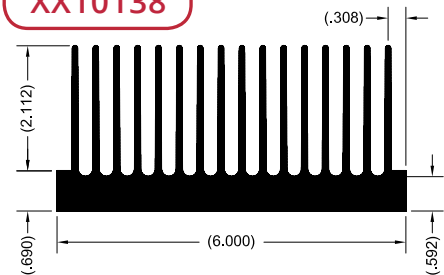
Per.	25.77	in.
WT.	1.24	lb/ft
θsa	2.70	°C/w/3"

**B 016070**



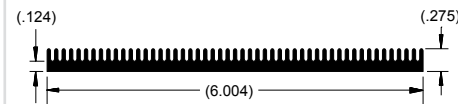
Per.	82.68	in.
WT.	8.16	lb/ft
θsa	1.60	°C/w/3"

**XX10138**



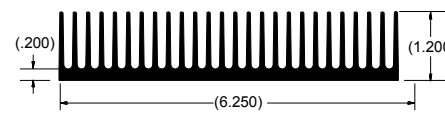
Per.	82.67	in.
WT.	8.17	lb/ft
θsa	0.97	°C/w/3"

**012054**



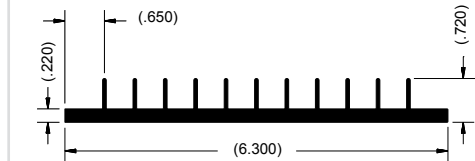
Per.	25.08	in.
WT.	1.32	lb/ft
θsa	2.80	°C/w/3"

**B XX8144**



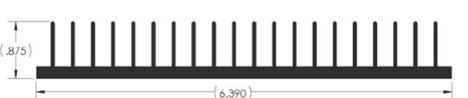
Per.	61.81	in.
WT.	3.78	lb/ft
θsa	1.70	°C/w/3"

**XX5067**



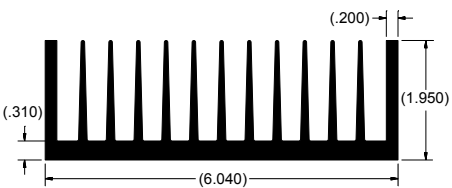
Per.	23.76	in.
WT.	2.07	lb/ft
θsa	2.70	°C/w/3"

**21848**



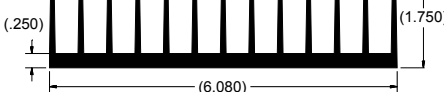
Per.	40.03	in.
WT.	2.47	lb/ft
θsa	1.75	°C/w/3"

**C 016250**



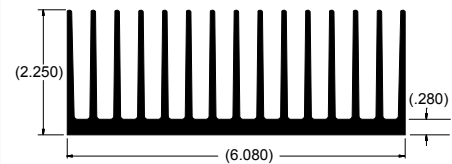
Per.	53.84	in.
WT.	5.27	lb/ft
θsa	1.40	°C/w/3"

**XX6676**



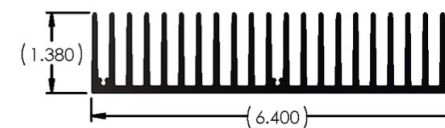
Per.	50.73	in.
WT.	3.56	lb/ft
θsa	1.30	°C/w/3"

**013277**



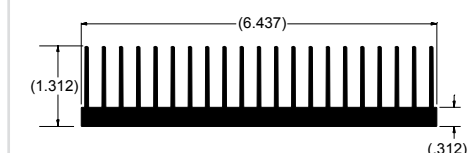
Per.	69.93	in.
WT.	5.53	lb/ft
θsa	1.40	°C/w/3"

**C 12382**



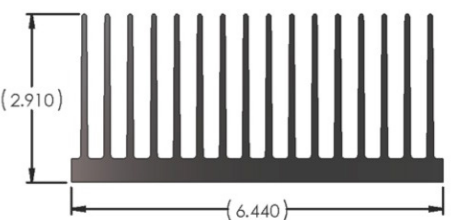
Per.	66.42	in.
WT.	3.81	lb/ft
θsa	1.05	°C/w/3"

**003385**



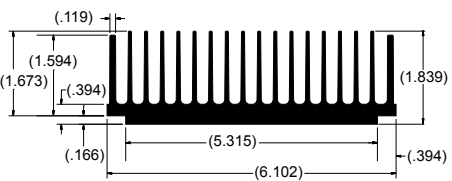
Per.	54.75	in.
WT.	4.03	lb/ft
θsa	1.30	°C/w/3"

**21107**



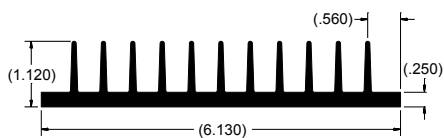
Per.	91.72	in.
WT.	7.98	lb/ft
θsa	0.76	°C/w/3"

**D 013512**



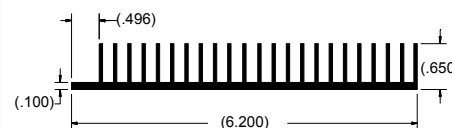
Per.	62.47	in.
WT.	5.21	lb/ft
θsa	1.10	°C/w/3"

**XX2161**



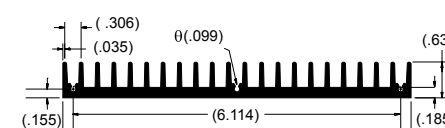
Per.	30.72	in.
WT.	2.96	lb/ft
θsa	1.80	°C/w/3"

**011425**



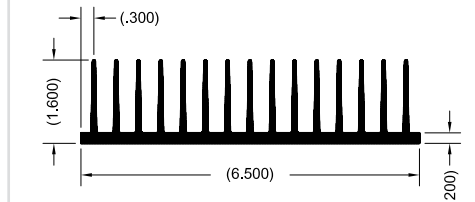
Per.	37.71	in.
WT.	1.61	lb/ft
θsa	1.90	°C/w/3"

**D 013266**



Per.	32.29	in.
WT.	2.38	lb/ft
θsa	2.20	°C/w/3"

**006664**



Per.	56.00	in.
WT.	3.42	lb/ft
θsa	0.0	°C/w/3"

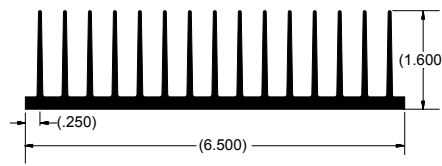
**XX8403**



Per.	61.19	in.
WT.	5.49	lb/ft
θsa	1.30	°C/w/3"

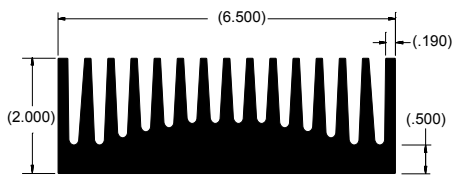


A XX4509



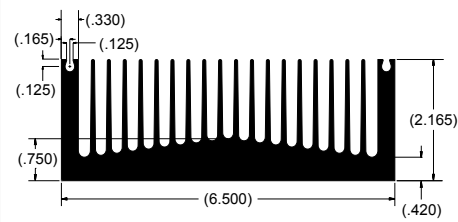
Per.	53.80	in.
WT.	3.45	lb/ft
θsa	1.30	°C/w/3"

016593



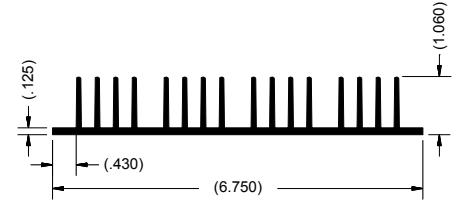
Per.	50.24	in.
WT.	10.17	lb/ft
θsa	1.60	°C/w/3"

016607



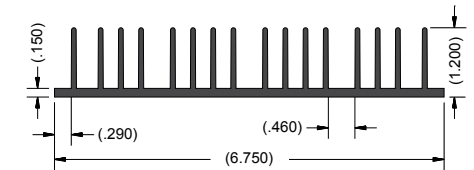
Per.	75.67	in.
WT.	8.54	lb/ft
θsa	1.40	°C/w/3"

A XX2494



Per.	46.37	in.
WT.	2.65	lb/ft
θsa	1.70	°C/w/3"

XX2027



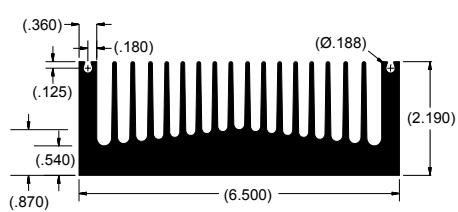
Per.	46.69	in.
WT.	2.91	lb/ft
θsa	1.40	°C/w/3"

19596



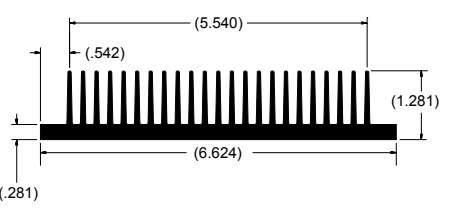
Per.	47.01	in.
WT.	3.49	lb/ft
θsa	1.49	°C/w/3"

B 016222



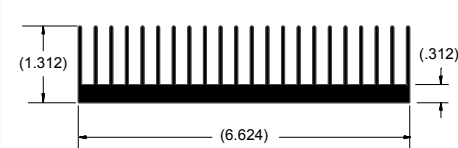
Per.	65.32	in.
WT.	9.66	lb/ft
θsa	1.40	°C/w/3"

013621



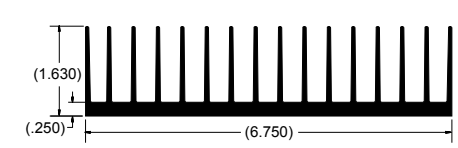
Per.	57.72	in.
WT.	4.31	lb/ft
θsa	2.70	°C/w/3"

XX7031



Per.	57.29	in.
WT.	4.12	lb/ft
θsa	1.30	°C/w/3"

B 012116



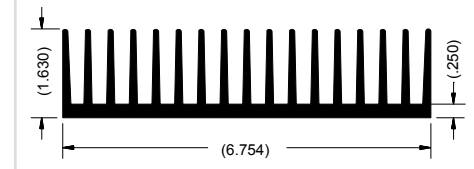
Per.	56.90	in.
WT.	4.00	lb/ft
θsa	1.60	°C/w/3"

015769



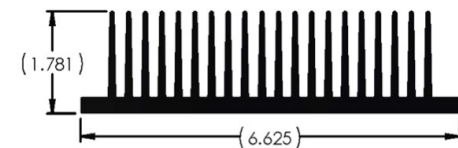
Per.	97.40	in.
WT.	6.53	lb/ft
θsa	1.70	°C/w/3"

XX7029



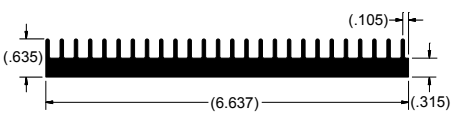
Per.	57.28	in.
WT.	4.08	lb/ft
θsa	1.30	°C/w/3"

C 12714



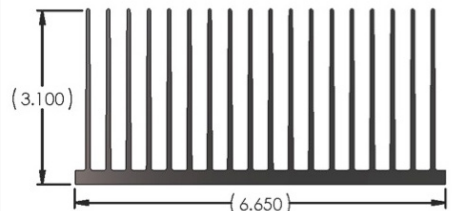
Per.	71.70	in.
WT.	5.99	lb/ft
θsa	0.98	°C/w/3"

015906



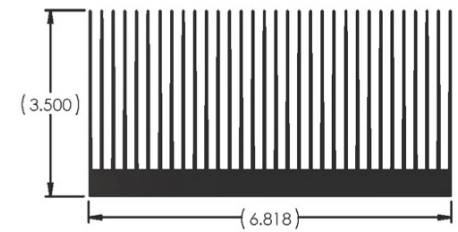
Per.	29.17	in.
WT.	3.15	lb/ft
θsa	3.30	°C/w/3"

19679



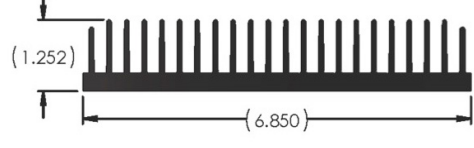
Per.	116.00	in.
WT.	6.65	lb/ft
θsa	0.60	°C/w/3"

C 19333



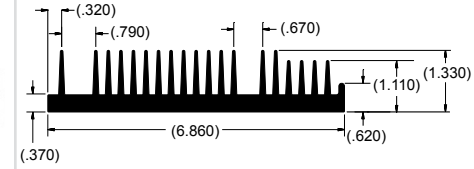
Per.	205.33	in.
WT.	9.80	lb/ft
θsa	0.34	°C/w/3"

16335



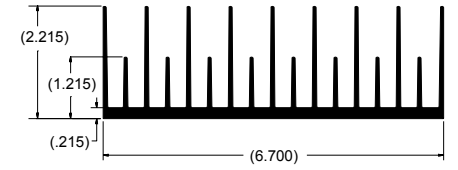
Per.	53.53	in.
WT.	4.67	lb/ft
θsa	1.31	°C/w/3"

016362



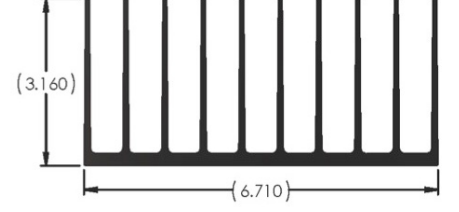
Per.	47.30	in.
WT.	5.14	lb/ft
θsa	2.50	°C/w/3"

D 014746



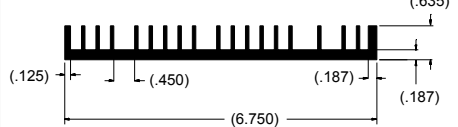
Per.	65.00	in.
WT.	3.80	lb/ft
θsa	1.20	°C/w/3"

21081



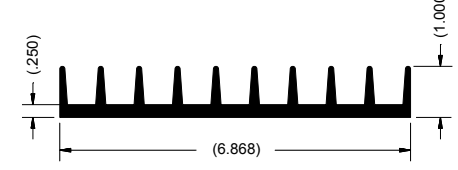
Per.	70.97	in.
WT.	5.55	lb/ft
θsa	0.99	°C/w/3"

013659



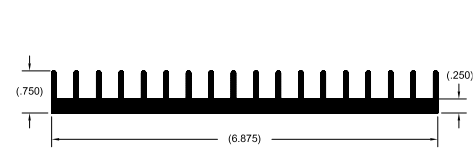
Per.	31.75	in.
WT.	2.40	lb/ft
θsa	2.20	°C/w/3"

D XX2071



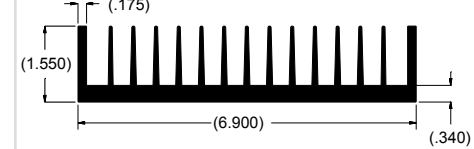
Per.	27.94	in.
WT.	3.33	lb/ft
θsa	1.90	°C/w/3"

015633



Per.	31.38	in.
WT.	2.86	lb/ft
θsa	2.30	°C/w/3"

016290



Per.	49.47	in.
WT.	5.04	lb/ft
θsa	1.50	°C/w/3"

**A 015745**

Per.	79.31	in.
WT.	6.91	lb/ft
θsa	1.40	°C/w/3"

**XX6274**

Per.	97.90	in.
WT.	9.15	lb/ft
θsa	0.80	°C/w/3"

**XX2091**

Per.	57.81	in.
WT.	4.70	lb/ft
θsa	1.20	°C/w/3"

**A XX7063**

Per.	59.37	in.
WT.	4.74	lb/ft
θsa	1.20	°C/w/3"

**012414**

Per.	46.41	in.
WT.	1.77	lb/ft
θsa	1.50	°C/w/3"

**19536**

Per.	47.12	in.
WT.	2.77	lb/ft
θsa	1.48	°C/w/3"

**B 16373**

Per.	78.13	in.
WT.	8.87	lb/ft
θsa	0.89	°C/w/3"

**19493**

Per.	26.00	in.
WT.	1.63	lb/ft
θsa	2.69	°C/w/3"

**015837**

Per.	123.97	in.
WT.	9.16	lb/ft
θsa	1.30	°C/w/3"

**B 013929**

Per.	80.79	in.
WT.	6.03	lb/ft
θsa	0.90	°C/w/3"

**19113**

Per.	62.04	in.
WT.	5.99	lb/ft
θsa	1.13	°C/w/3"

**012395**

Per.	52.74	in.
WT.	6.18	lb/ft
θsa	1.30	°C/w/3"

**C 014306**

Per.	127.28	in.
WT.	10.34	lb/ft
θsa	0.90	°C/w/3"

**006369**

Per.	54.70	in.
WT.	4.57	lb/ft
θsa	1.70	°C/w/3"

**014757**

Per.	33.06	in.
WT.	2.34	lb/ft
θsa	2.10	°C/w/3"

**C XX4771**

Per.	61.75	in.
WT.	4.54	lb/ft
θsa	1.10	°C/w/3"

**013597**

Per.	59.05	in.
WT.	4.20	lb/ft
θsa	1.20	°C/w/3"

**XX5523**

Per.	46.78	in.
WT.	2.88	lb/ft
θsa	1.80	°C/w/3"

**D 014401**

Per.	45.17	in.
WT.	3.79	lb/ft
θsa	1.60	°C/w/3"

**006663**

Per.	44.10	in.
WT.	5.28	lb/ft
θsa	2.50	°C/w/3"

**016556**

Per.	49.55	in.
WT.	2.47	lb/ft
θsa	5.30	°C/w/3"

**D 19273**

Per.	136.54	in.
WT.	17.21	lb/ft
θsa	0.51	°C/w/3"

**014113**

Per.	116.11	in.
WT.	7.30	lb/ft
θsa	0.60	°C/w/3"

**013677**

Per.	107.22	in.
WT.	7.68	lb/ft
θsa	0.60	°C/w/3"

Not all stocked. Example shapes are not all tooled.

**A XX5113**

Per.	132.30	in.
WT.	6.56	lb/ft
θsa	0.68	°C/w/3"

**21408**

Per.	79.52	in.
WT.	4.99	lb/ft
θsa	0.88	°C/w/3"

**014468**

Per.	56.88	in.
WT.	5.47	lb/ft
θsa	1.20	°C/w/3"

**A 014085**

Per.	49.41	in.
WT.	5.72	lb/ft
θsa	1.40	°C/w/3"

**19052**

Per.	32.65	in.
WT.	2.58	lb/ft
θsa	2.14	°C/w/3"

**XX2009**

Per.	65.91	in.
WT.	4.30	lb/ft
θsa	1.20	°C/w/3"

**B 012504**

Per.	94.48	in.
WT.	6.95	lb/ft
θsa	0.70	°C/w/3"

**19535**

Per.	95.28	in.
WT.	9.50	lb/ft
θsa	0.73	°C/w/3"

**19721**

Per.	56.67	in.
WT.	2.73	lb/ft
θsa	1.23	°C/w/3"

**B XX2074**

Per.	66.79	in.
WT.	9.30	lb/ft
θsa	1.10	°C/w/3"

**19707 & PH18403**

Per.	227.36	in.
WT.	45.85	lb/ft
θsa	0.31	°C/w/3"

**XX4483**

Per.	51.78	in.
WT.	2.56	lb/ft
θsa	1.50	°C/w/3"

**C 016133**

Per.	47.88	in.
WT.	8.12	lb/ft
θsa	1.30	°C/w/3"

**19832**

Per.	208.02	in.
WT.	10.93	lb/ft
θsa	0.34	°C/w/3"

**012843**

Per.	30.40	in.
WT.	3.13	lb/ft
θsa	2.20	°C/w/3"

**C 19902**

Per.	54.81	in.
WT.	7.33	lb/ft
θsa	1.28	°C/w/3"

**013068**

Per.	49.28	in.
WT.	2.56	lb/ft
θsa	1.40	°C/w/3"

**13068**

Per.	49.30	in.
WT.	2.56	lb/ft
θsa	1.42	°C/w/3"

**D 19700**

Per.	103.36	in.
WT.	8.22	lb/ft
θsa	0.68	°C/w/3"

**19275**

Per.	87.12	in.
WT.	6.94	lb/ft
θsa	0.80	°C/w/3"

**XX8077**

Per.	63.84	in.
WT.	6.56	lb/ft
θsa	1.00	°C/w/3"

**D XX2095**

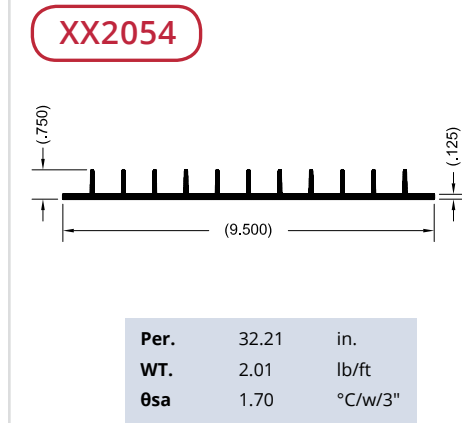
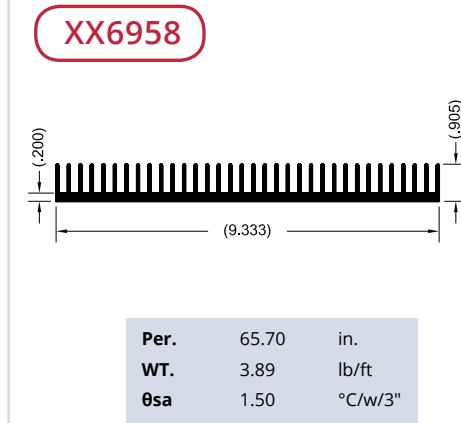
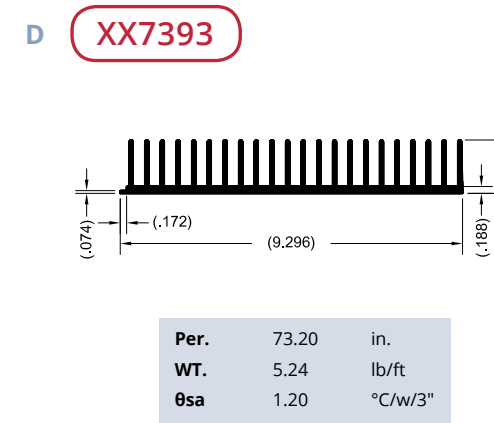
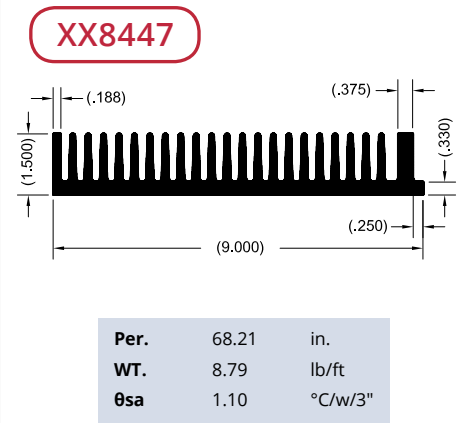
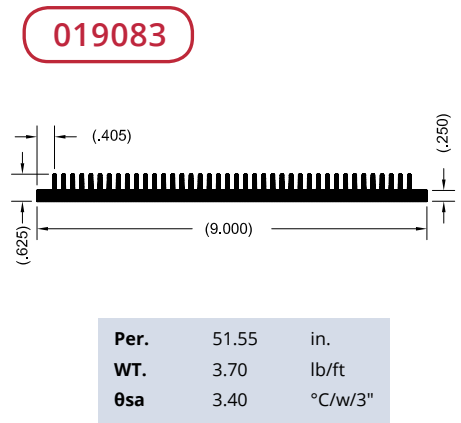
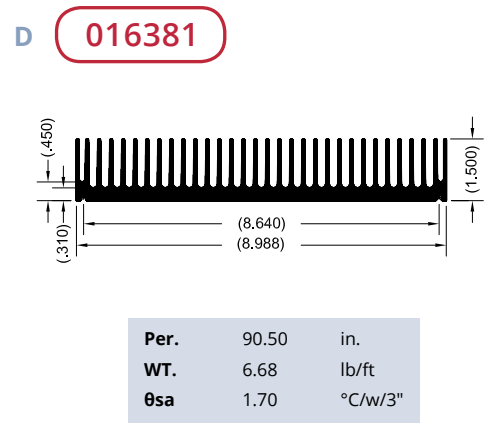
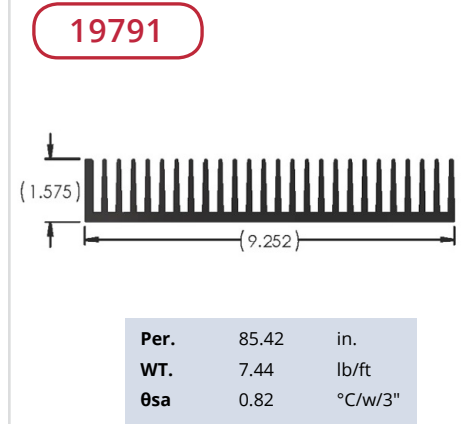
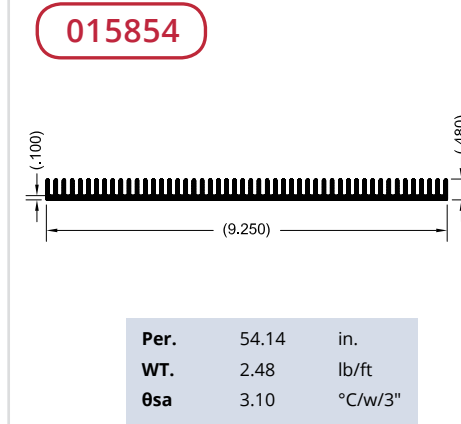
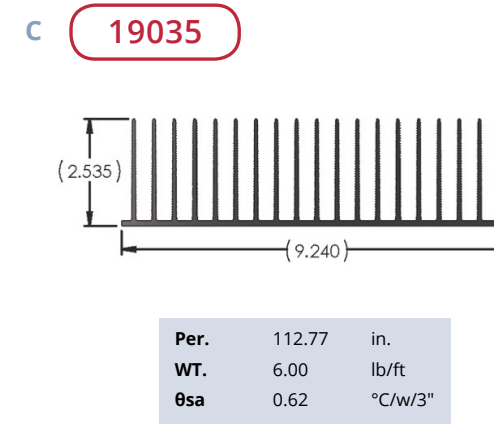
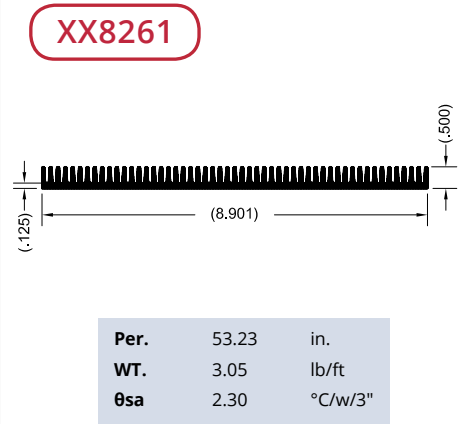
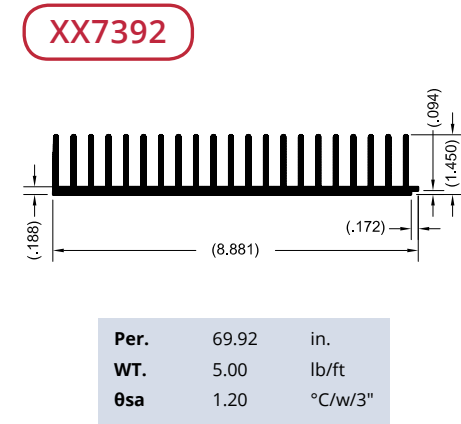
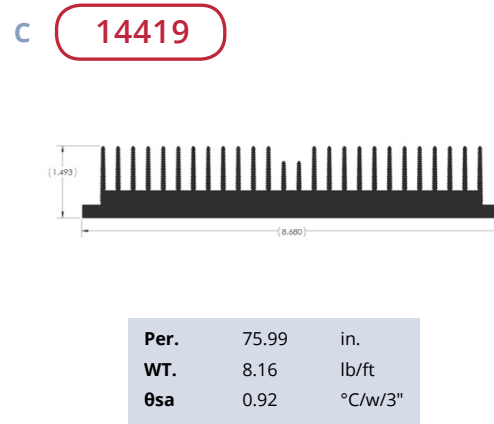
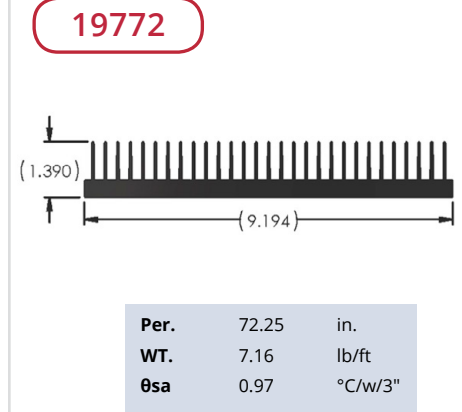
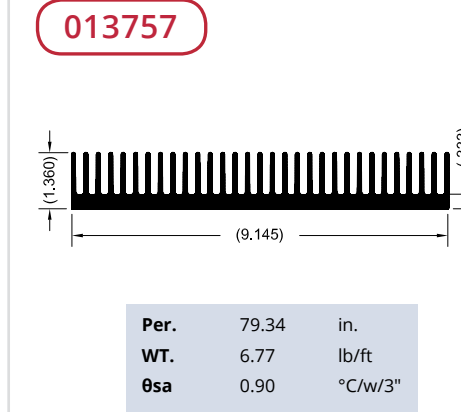
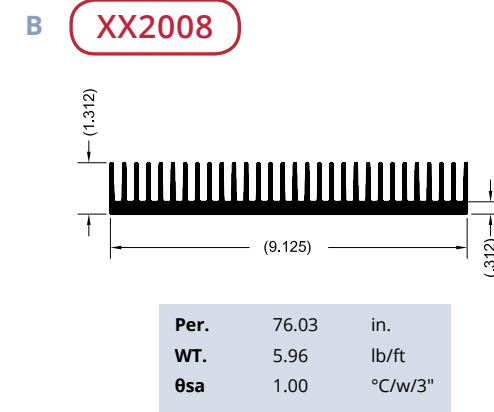
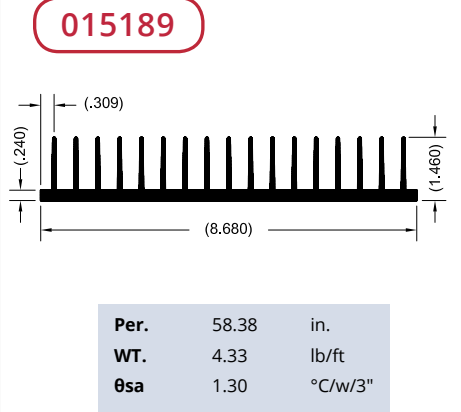
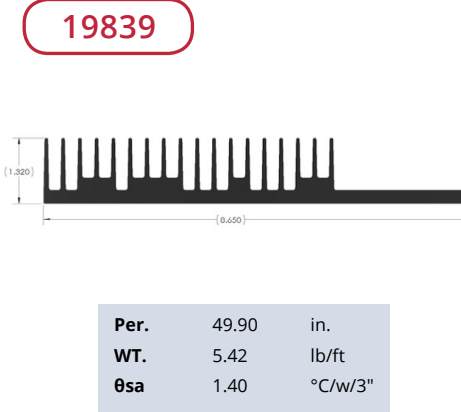
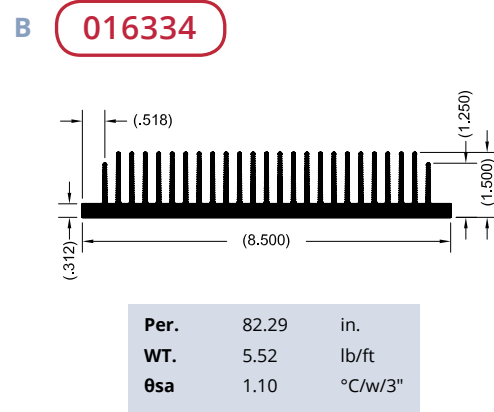
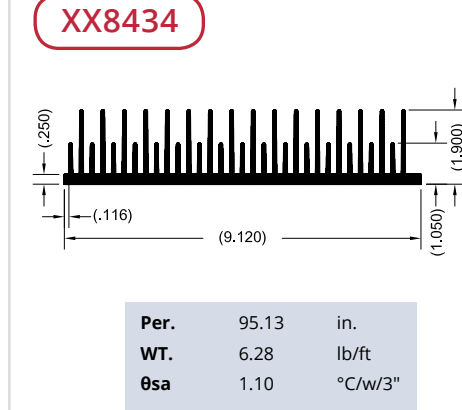
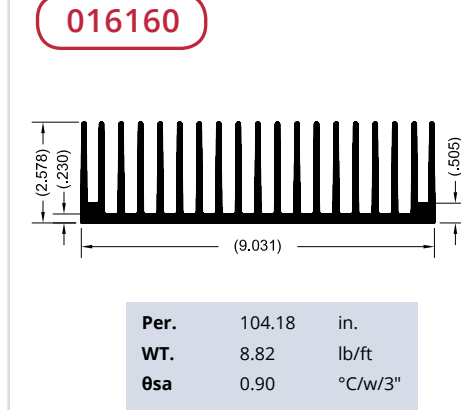
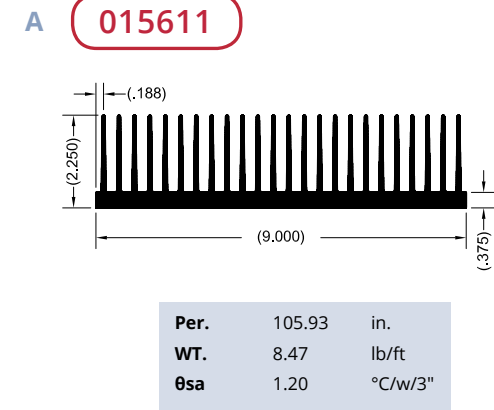
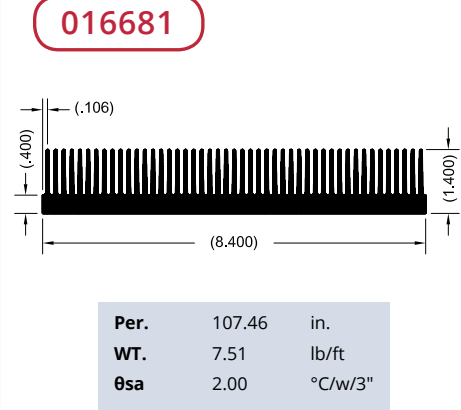
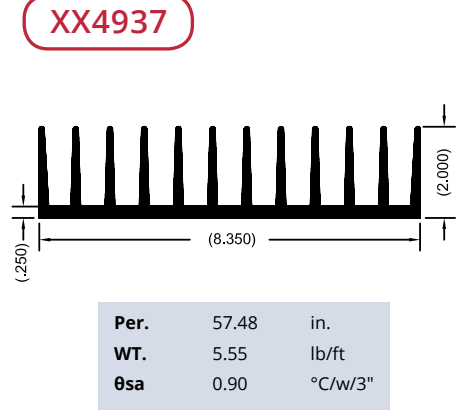
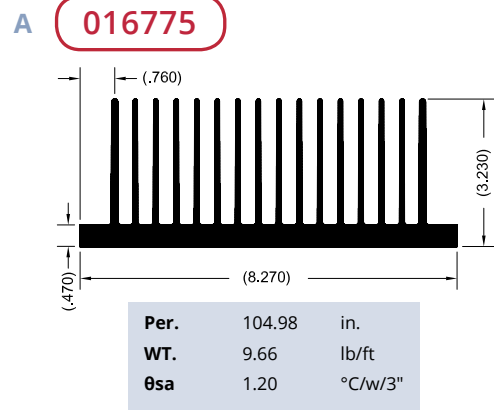
Per.	75.57	in.
WT.	9.53	lb/ft
θsa	0.96	°C/w/3"

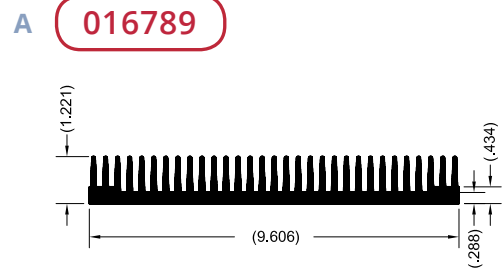
**16486**

Per.	33.41	in.
WT.	5.52	lb/ft
θsa	2.09	°C/w/3"

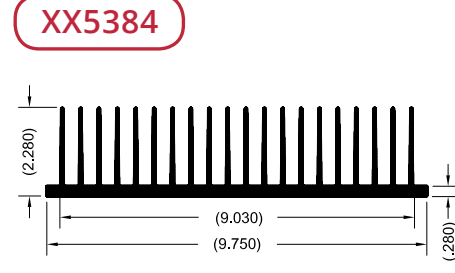
**016200**

Per.	75.42	in.
WT.	5.67	lb/ft
θsa	1.30	°C/w/3"

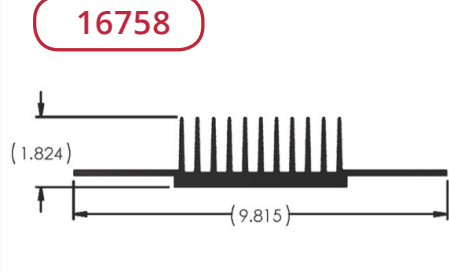




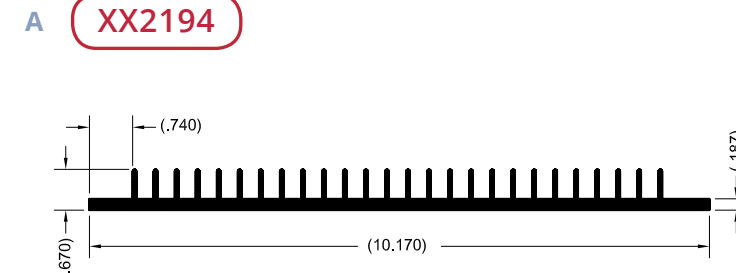
Per.	73.30	in.
WT.	7.25	lb/ft
θsa	2.10	°C/w/3"



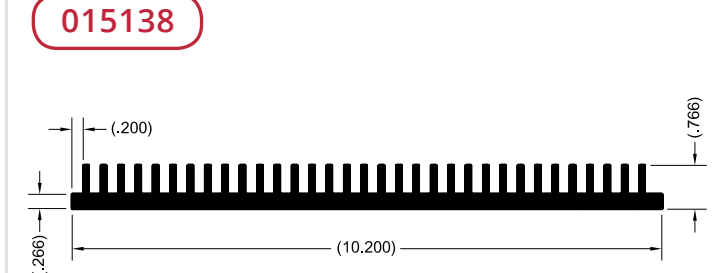
Per.	98.46	in.
WT.	7.40	lb/ft
θsa	0.75	°C/w/3"



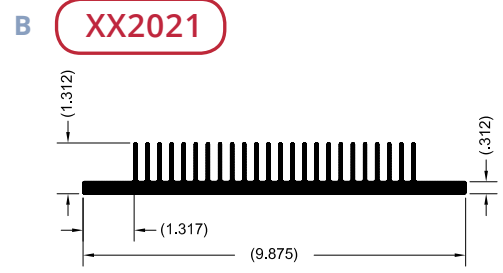
Per.	55.45	in.
WT.	5.02	lb/ft
θsa	1.26	°C/w/3"



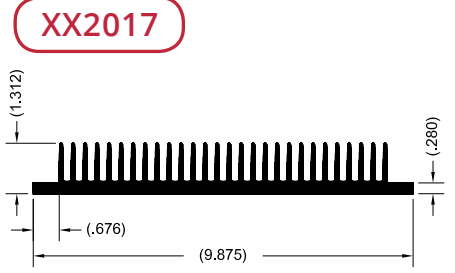
Per.	45.13	in.
WT.	3.24	lb/ft
θsa	1.50	°C/w/3"



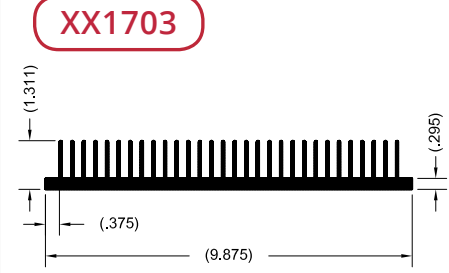
Per.	53.93	in.
WT.	5.24	lb/ft
θsa	1.30	°C/w/3"



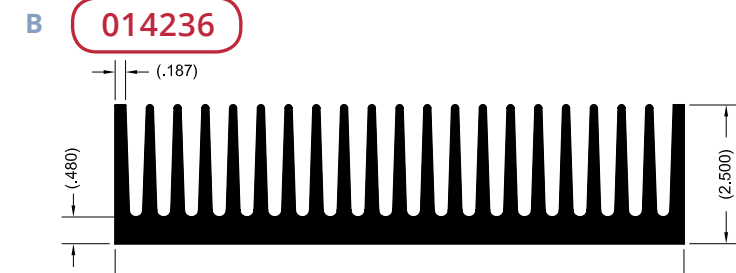
Per.	66.42	in.
WT.	5.58	lb/ft
θsa	1.20	°C/w/3"



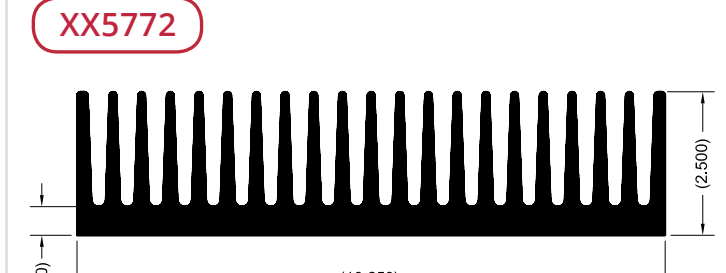
Per.	73.22	in.
WT.	6.38	lb/ft
θsa	1.10	°C/w/3"



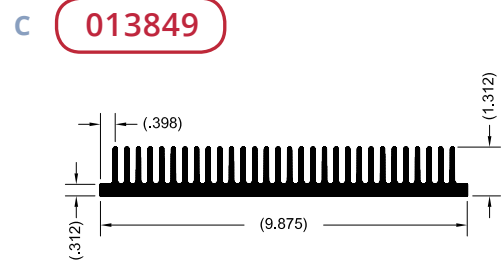
Per.	78.03	in.
WT.	6.15	lb/ft
θsa	0.91	°C/w/3"



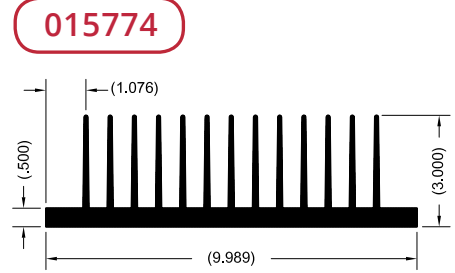
Per.	100.80	in.
WT.	15.28	lb/ft
θsa	1.10	°C/w/3"



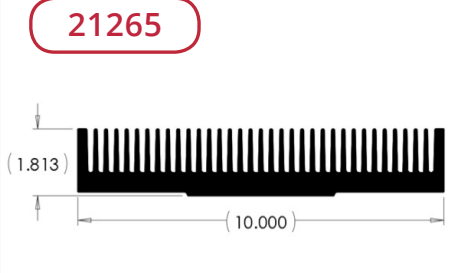
Per.	99.79	in.
WT.	15.90	lb/ft
θsa	0.71	°C/w/3"



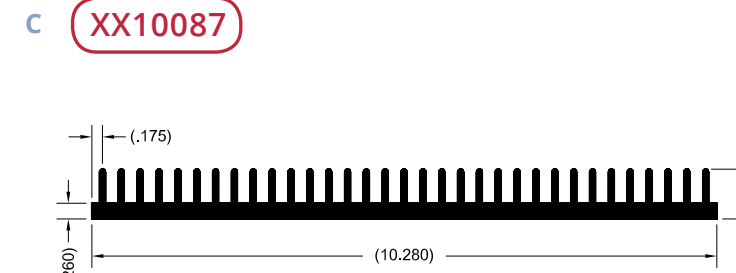
Per.	76.21	in.
WT.	7.25	lb/ft
θsa	1.00	°C/w/3"



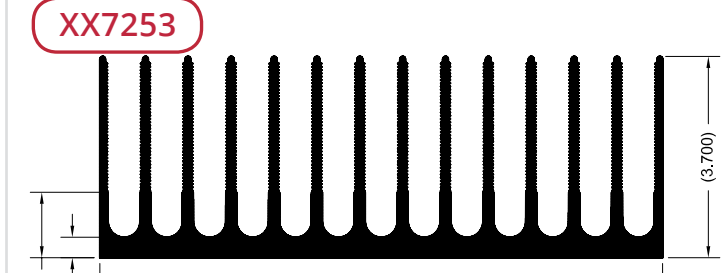
Per.	84.68	in.
WT.	10.74	lb/ft
θsa	0.90	°C/w/3"



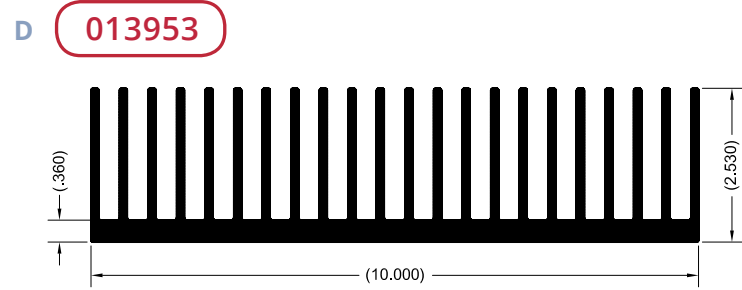
Per.	100.37	in.
WT.	12.27	lb/ft
θsa	0.70	°C/w/3"



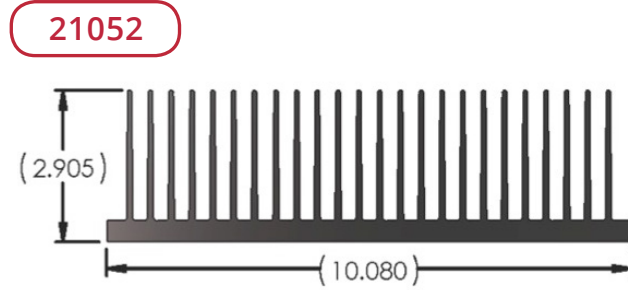
Per.	56.77	in.
WT.	5.17	lb/ft
θsa	1.40	°C/w/3"



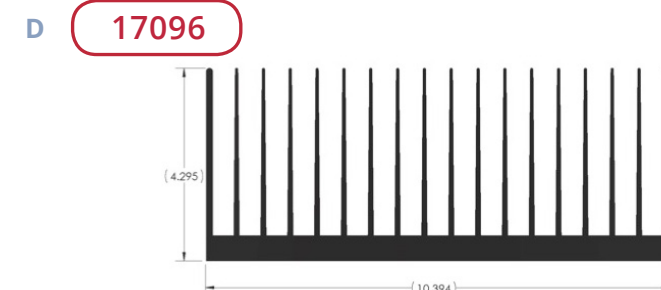
Per.	151.74	in.
WT.	13.89	lb/ft
θsa	0.69	°C/w/3"



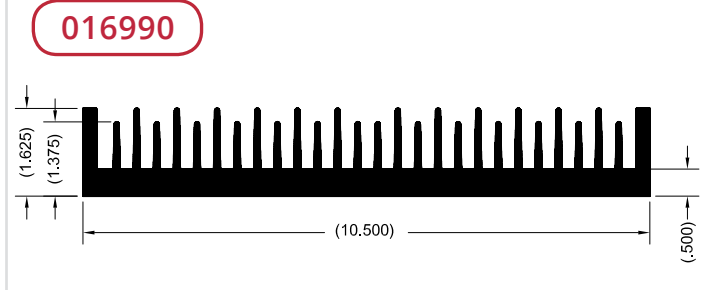
Per.	114.78	in.
WT.	11.26	lb/ft
θsa	0.60	°C/w/3"



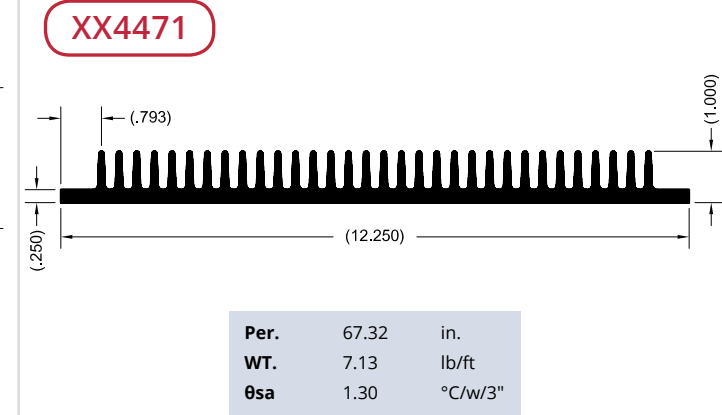
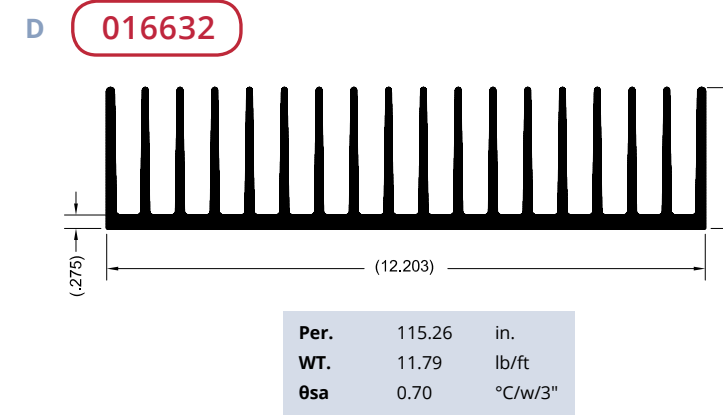
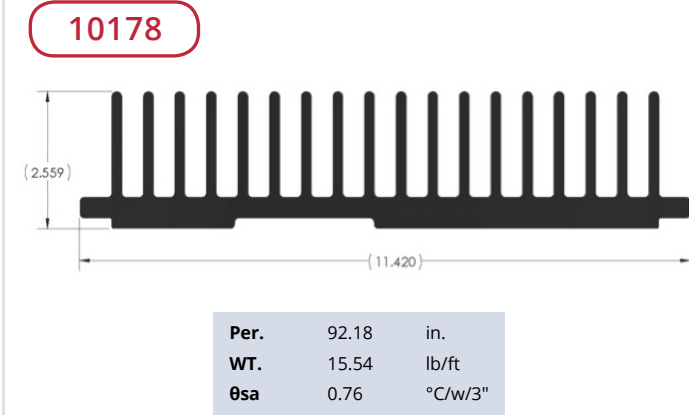
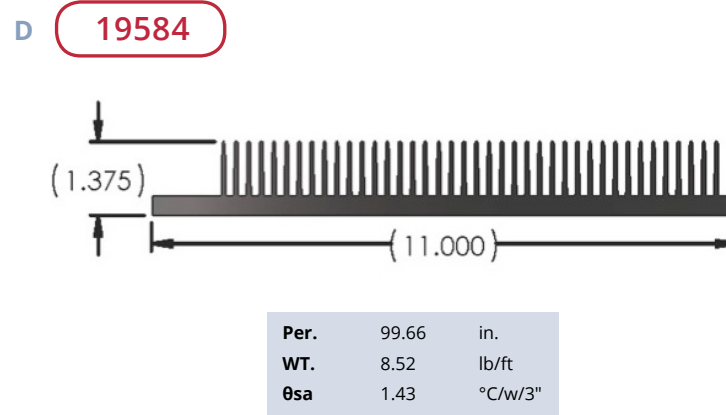
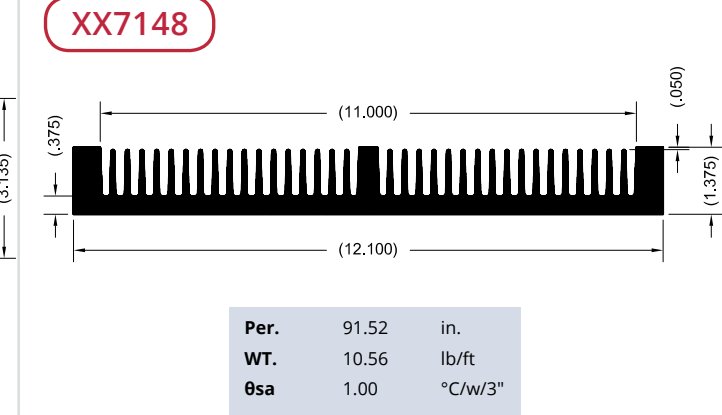
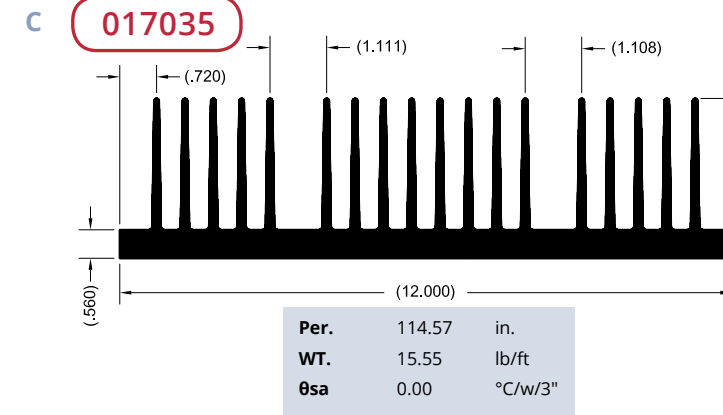
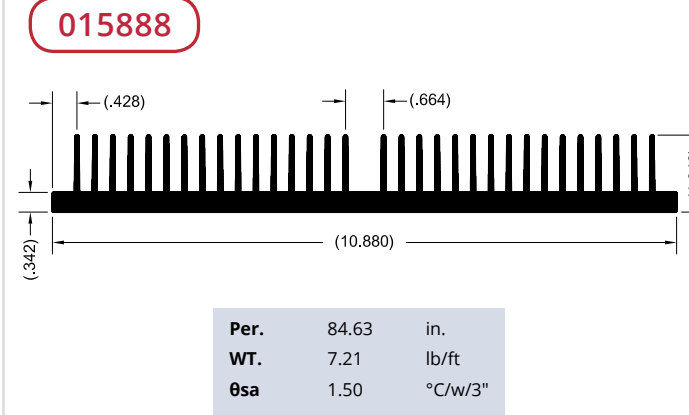
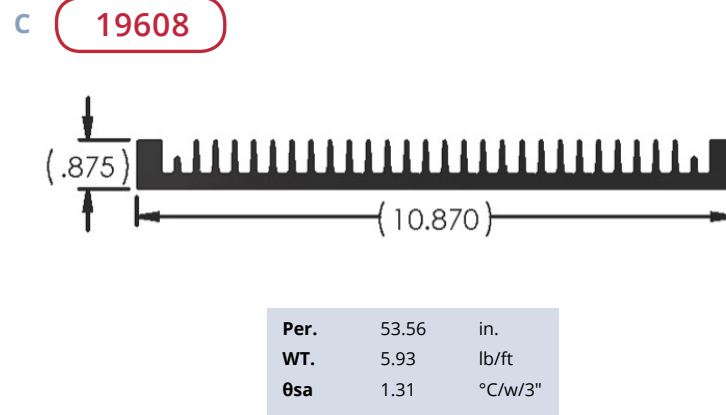
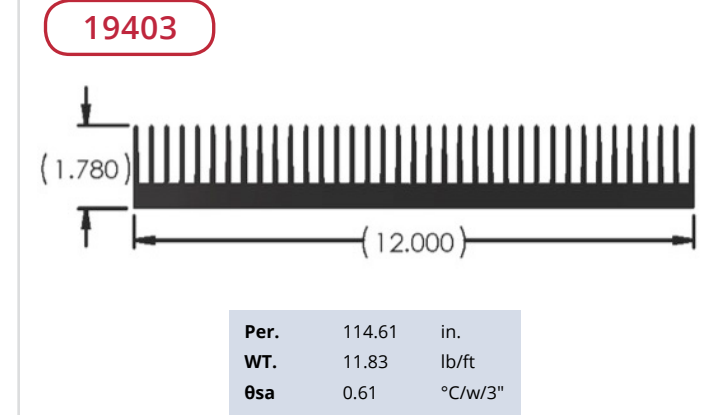
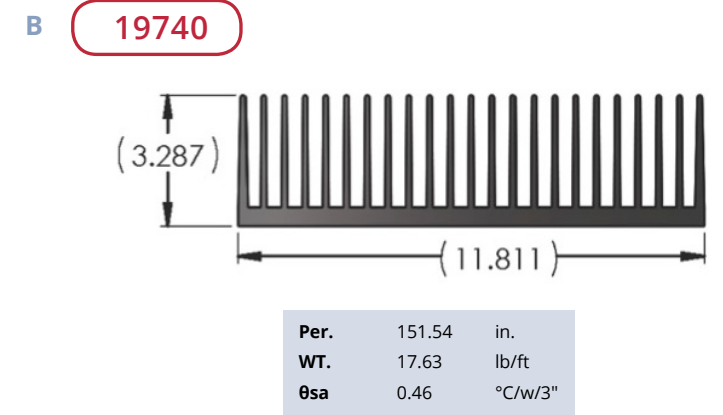
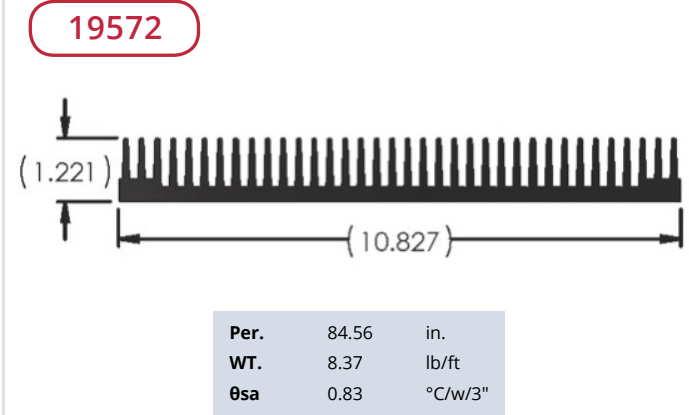
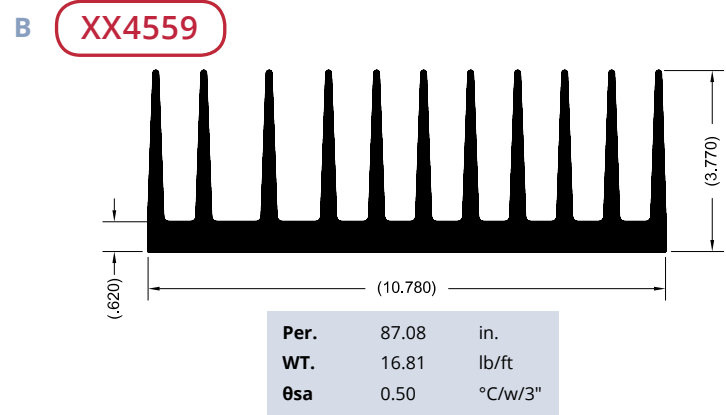
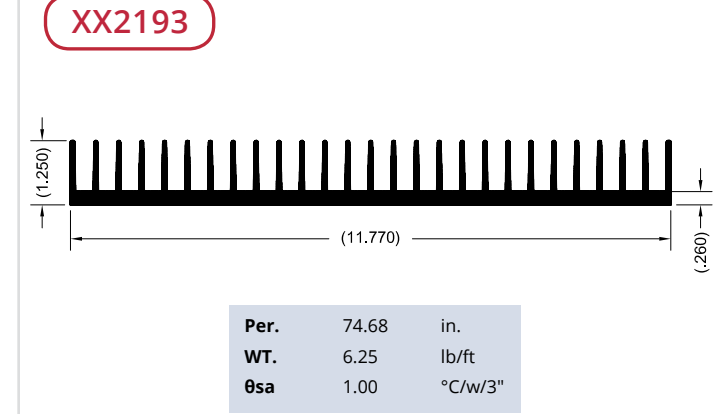
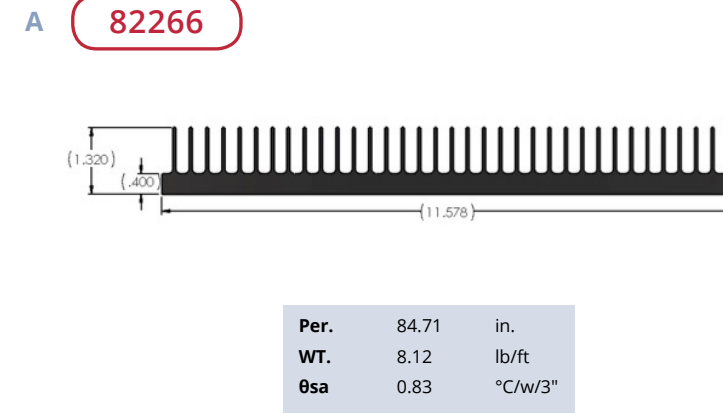
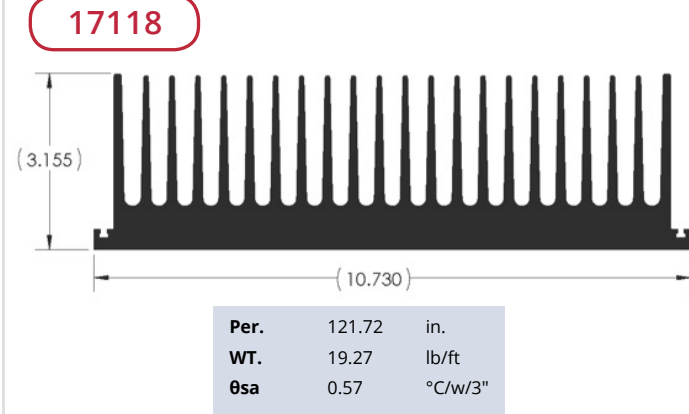
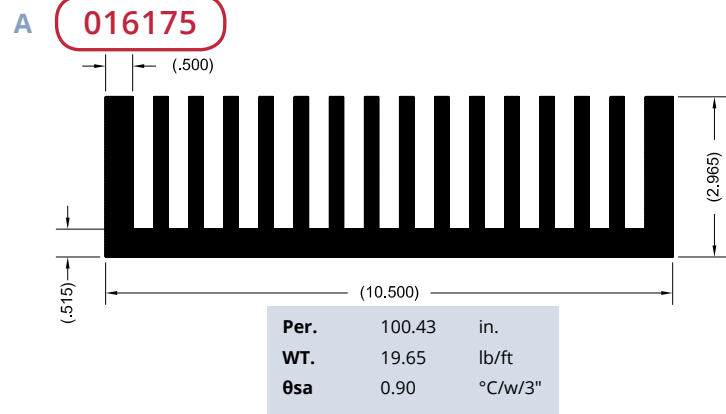
Per.	137.98	in.
WT.	12.10	lb/ft
θsa	0.51	°C/w/3"



Per.	154.23	in.
WT.	15.86	lb/ft
θsa	0.45	°C/w/3"

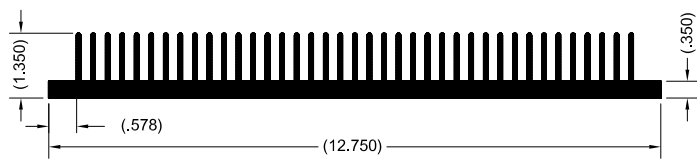


Per.	75.47	in.
WT.	10.06	lb/ft
θsa	1.30	°C/w/3"



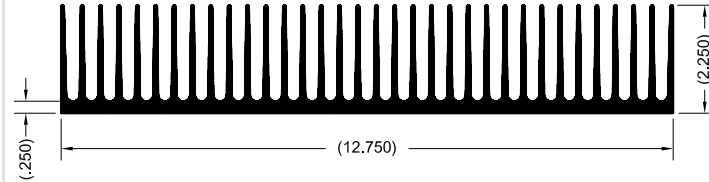
A

**XX2170**



Per.	102.86	in.
WT.	9.07	lb/ft
θsa	0.60	°C/w/3"

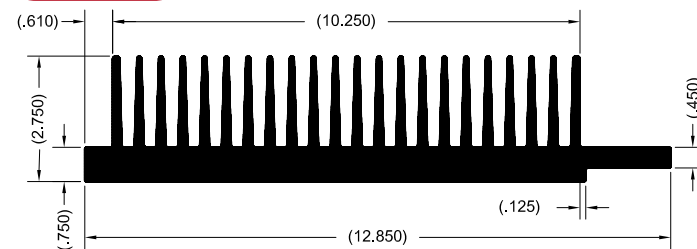
**XX2044**



Per.	155.65	in.
WT.	11.00	lb/ft
θsa	0.56	°C/w/3"

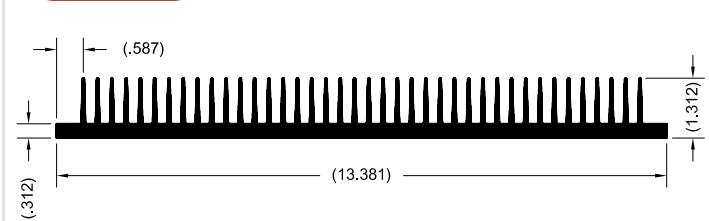
B

**XX7214**



Per.	110.91	in.
WT.	18.71	lb/ft
θsa	0.65	°C/w/3"

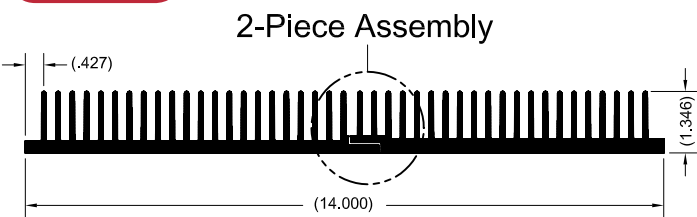
**XX5429**



Per.	110.91	in.
WT.	18.71	lb/ft
θsa	0.65	°C/w/3"

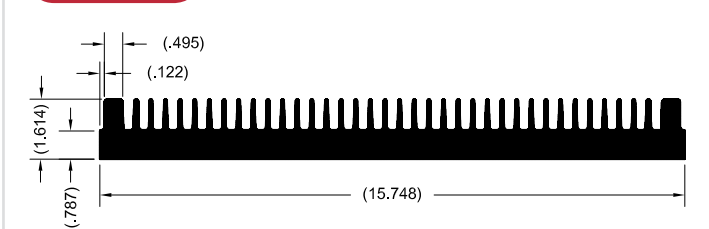
C

**013772**



Per.	60.84	in.
WT.	5.08	lb/ft
θsa	0.60	°C/w/3"

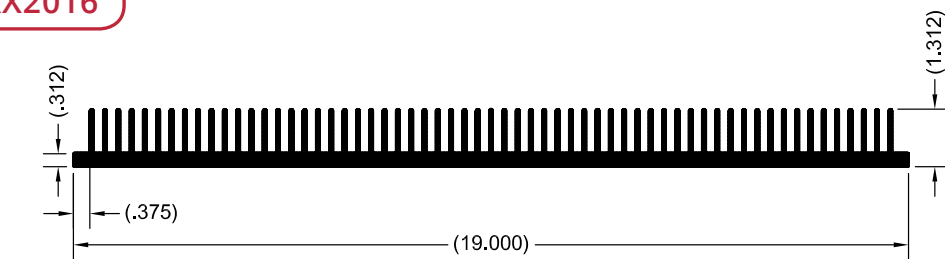
**016543**



Per.	91.53	in.
WT.	19.20	lb/ft
θsa	1.10	°C/w/3"

D

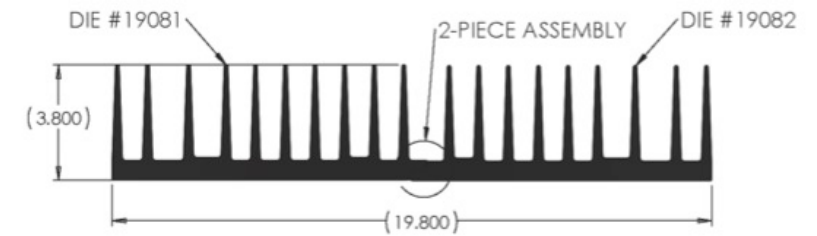
**XX2016**



Per.	110.91	in.
WT.	18.71	lb/ft
θsa	0.65	°C/w/3"

A

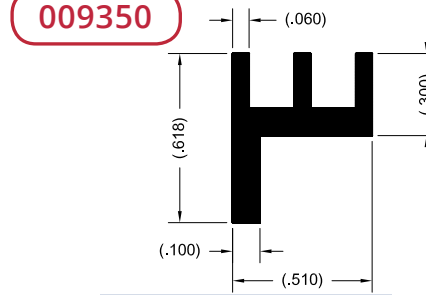
**19081 & 19082**



Per.	153.20	in.
WT.	30.19	lb/ft
θsa	0.46	°C/w/3"

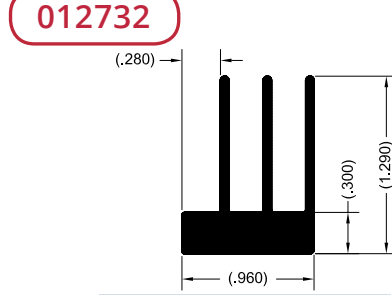
B

**009350**



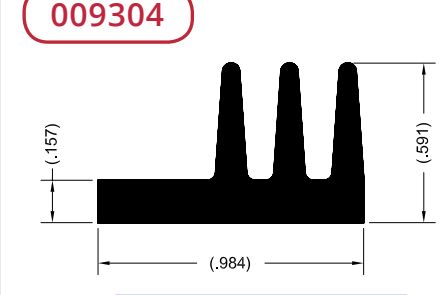
Per.	3.07	in.
WT.	0.14	lb/ft
θsa	22.80	°C/w/3"

**012732**



Per.	8.22	in.
WT.	0.56	lb/ft
θsa	6.50	°C/w/3"

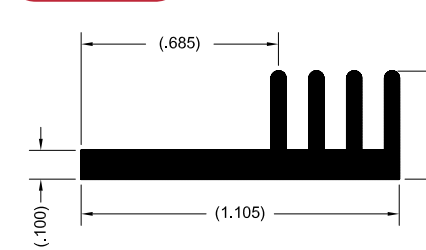
**009304**



Per.	4.89	in.
WT.	0.33	lb/ft
θsa	14.30	°C/w/3"

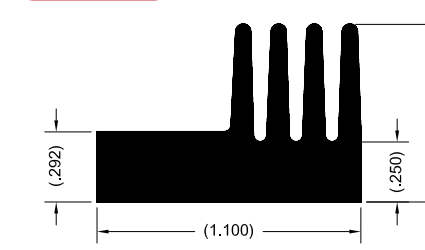
C

**009893**



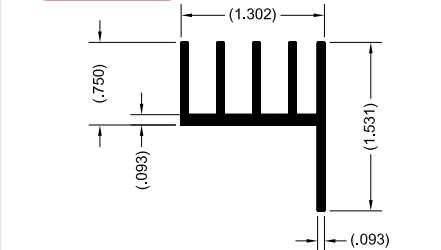
Per.	4.61	in.
WT.	0.20	lb/ft
θsa	15.20	°C/w/3"

**013691**



Per.	6.31	in.
WT.	0.52	lb/ft
θsa	11.10	°C/w/3"

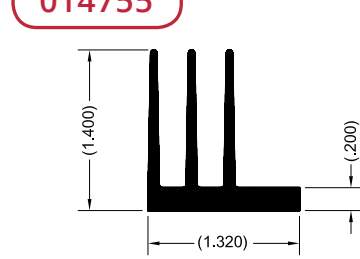
**XX5269**



Per.	10.92	in.
WT.	0.48	lb/ft
θsa	7.30	°C/w/3"

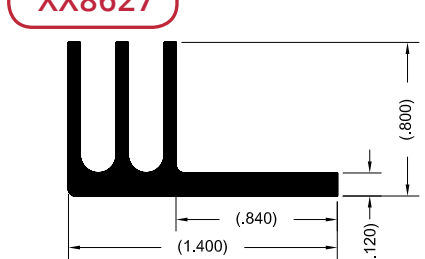
D

**014755**



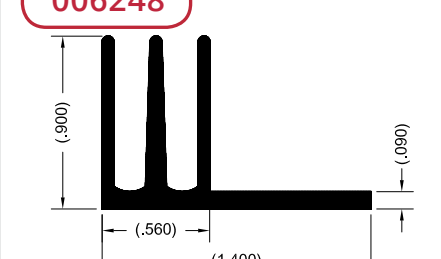
Per.	9.97	in.
WT.	0.63	lb/ft
θsa	5.70	°C/w/3"

**XX8627**

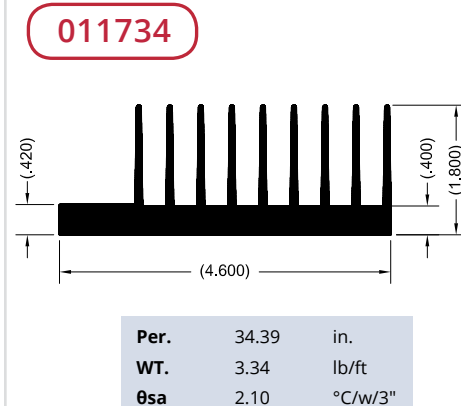
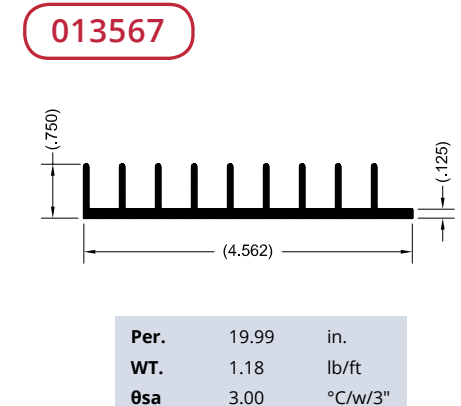
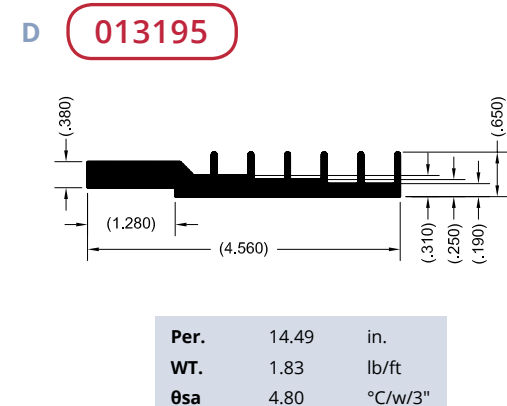
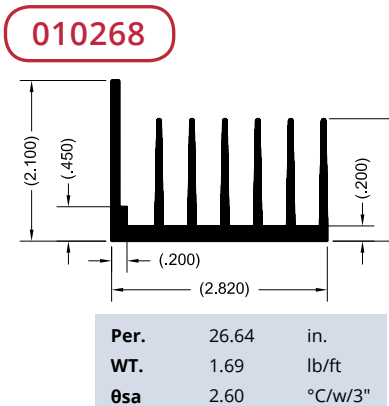
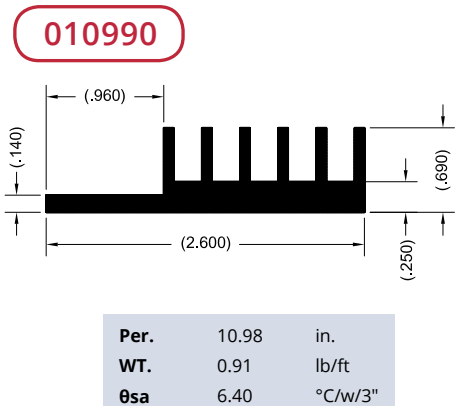
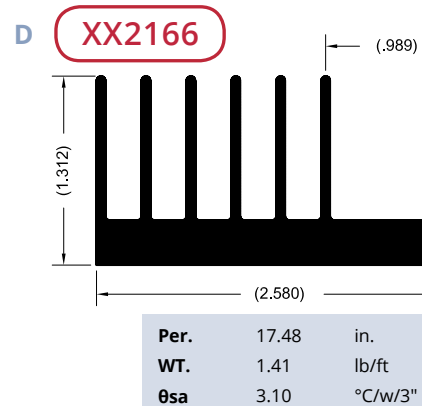
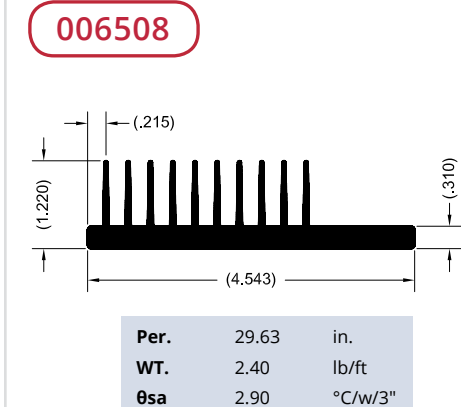
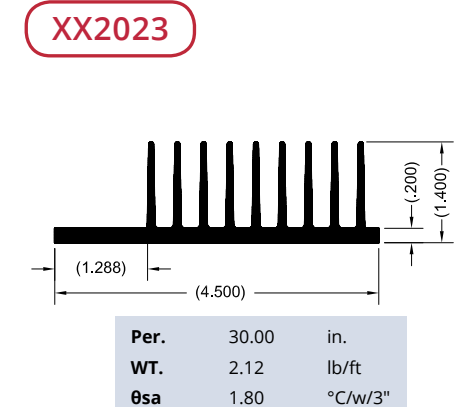
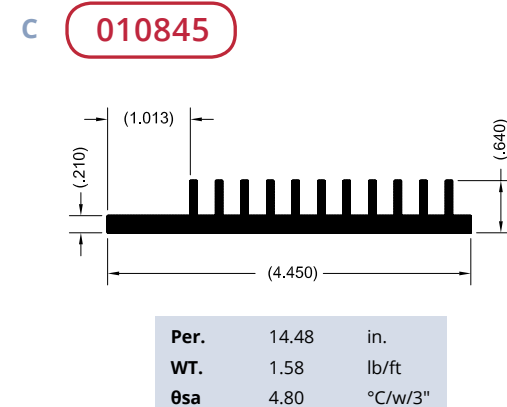
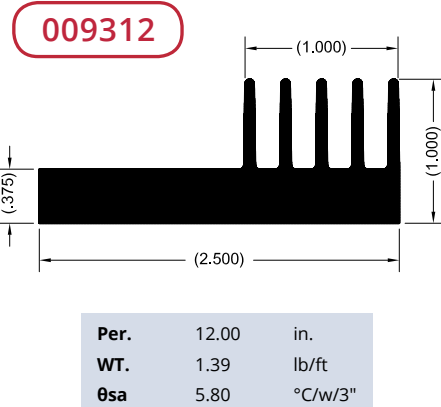
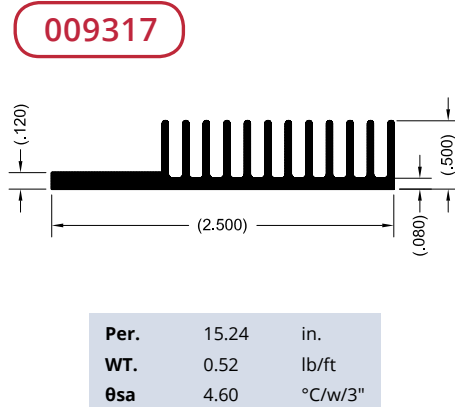
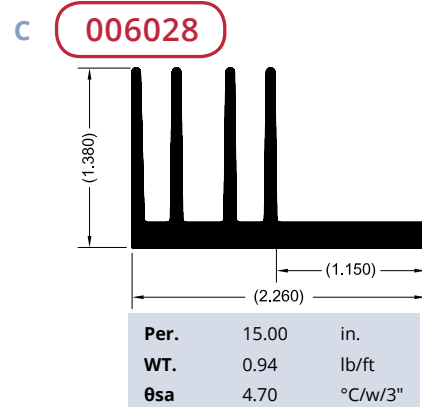
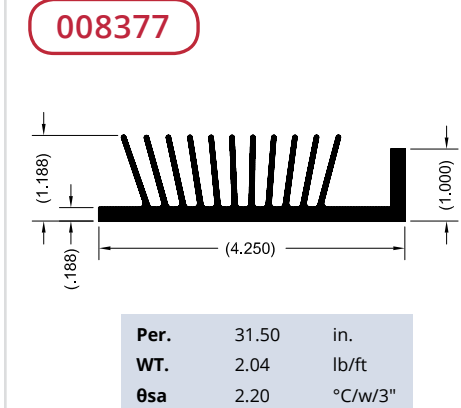
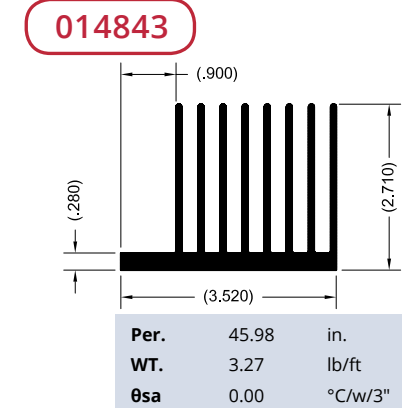
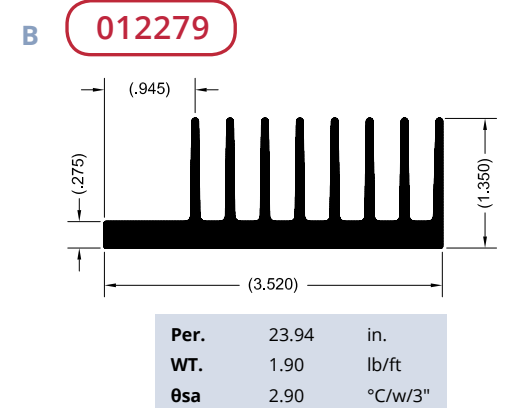
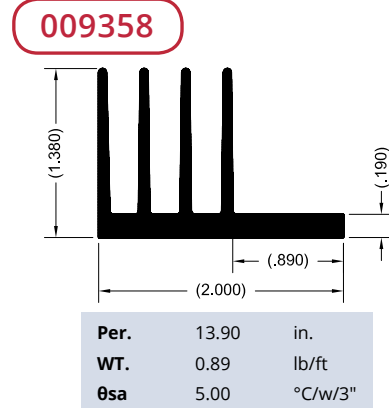
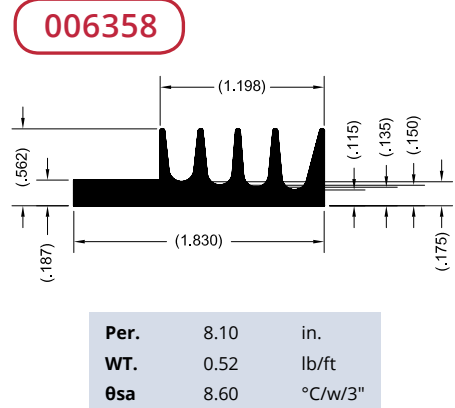
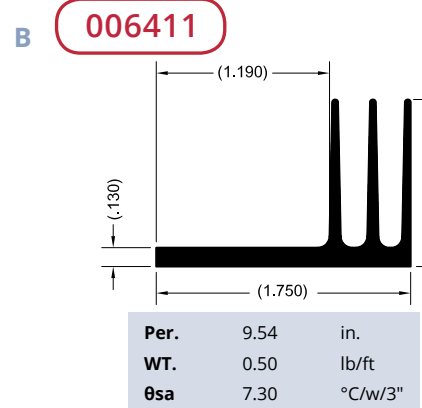
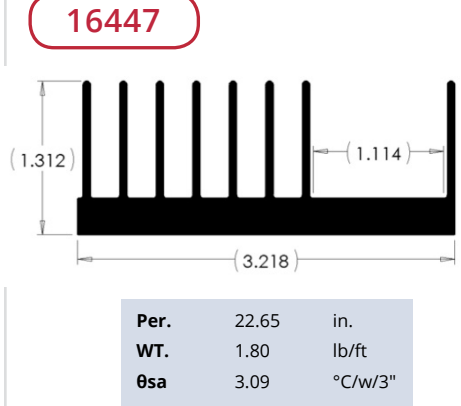
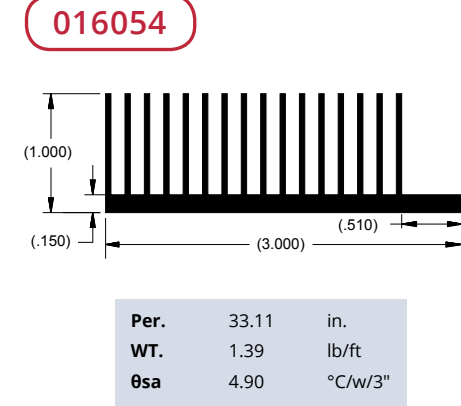
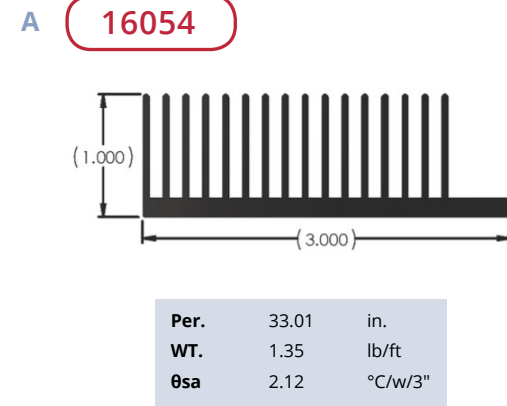
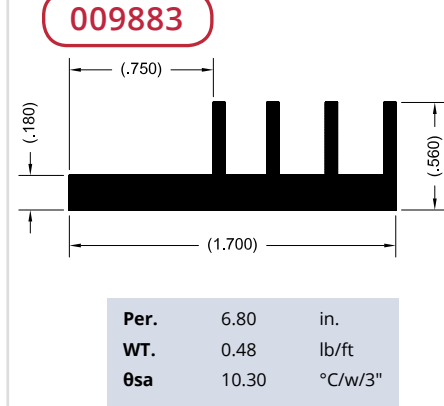
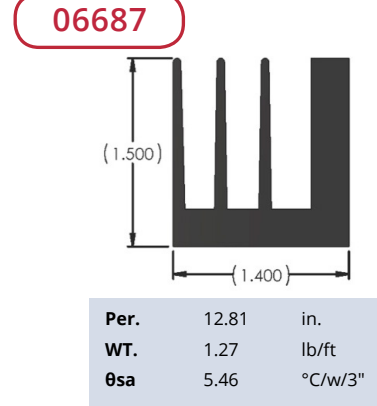
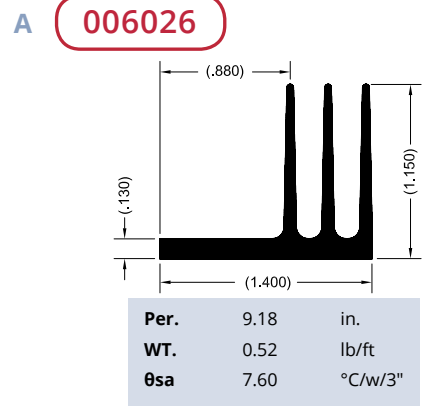


Per.	6.92	in.
WT.	0.36	lb/ft
θsa	7.00	°C/w/3"

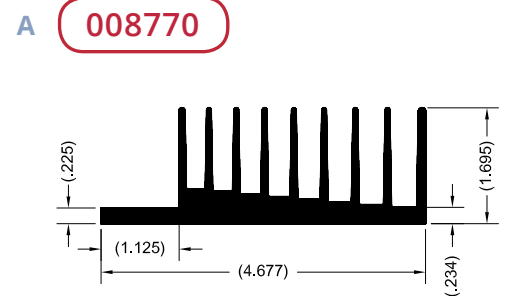
**006248**



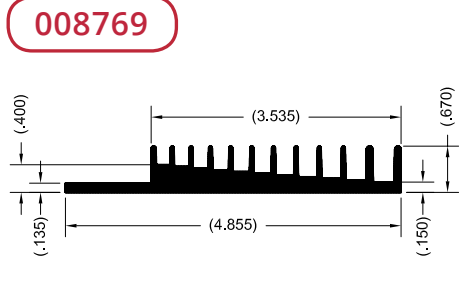
Per.	7.61	in.
WT.	0.37	lb/ft
θsa	9.20	°C/w/3"



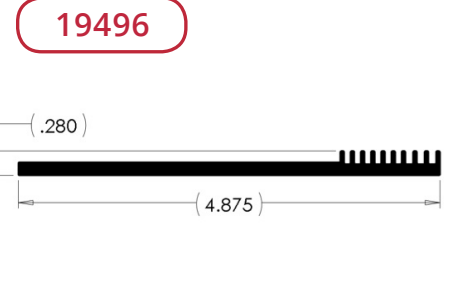




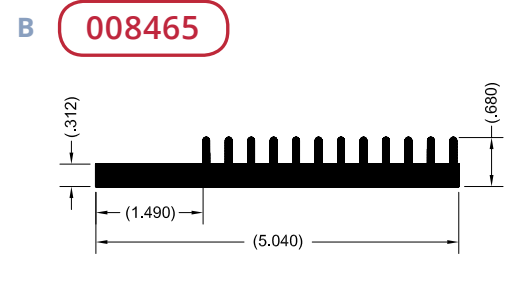
Per.	32.75	in.
WT.	3.04	lb/ft
θsa	2.10	°C/w/3"



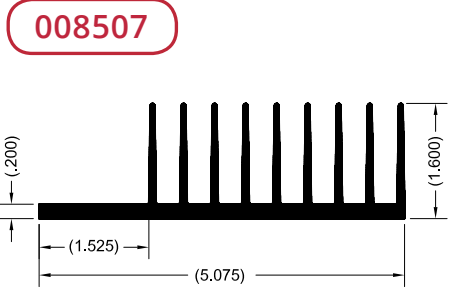
Per.	19.24	in.
WT.	1.65	lb/ft
θsa	3.60	°C/w/3"



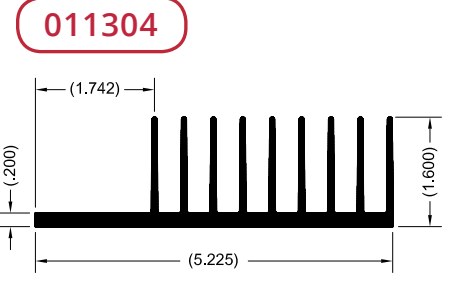
Per.	12.75	in.
WT.	0.93	lb/ft
θsa	5.48	°C/w/3"



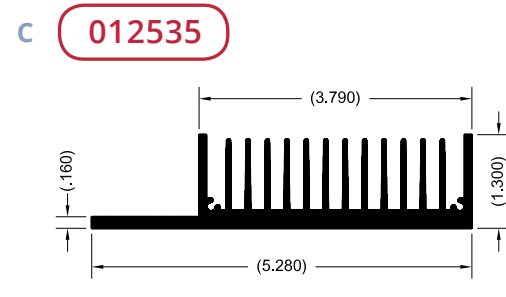
Per.	19.54	in.
WT.	2.34	lb/ft
θsa	3.60	°C/w/3"



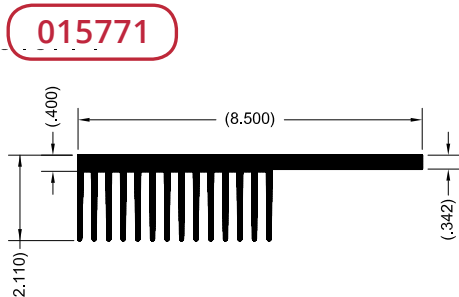
Per.	35.08	in.
WT.	2.43	lb/ft
θsa	2.60	°C/w/3"



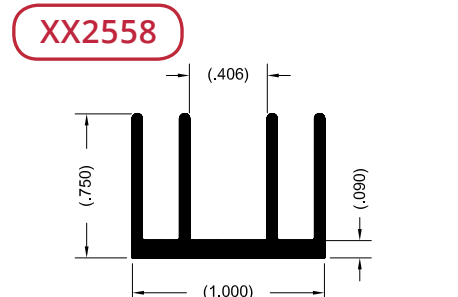
Per.	34.60	in.
WT.	2.37	lb/ft
θsa	2.00	°C/w/3"



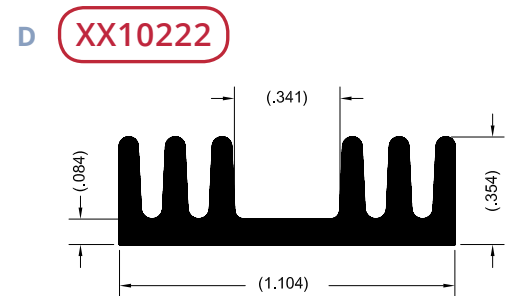
Per.	39.12	in.
WT.	2.54	lb/ft
θsa	1.80	°C/w/3"



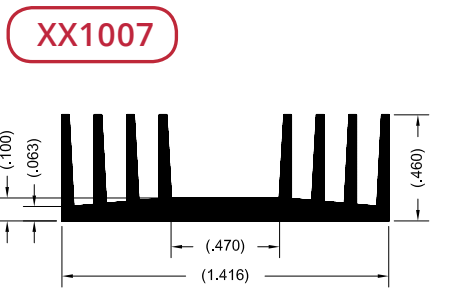
Per.	64.44	in.
WT.	6.35	lb/ft
θsa	0.00	°C/w/3"



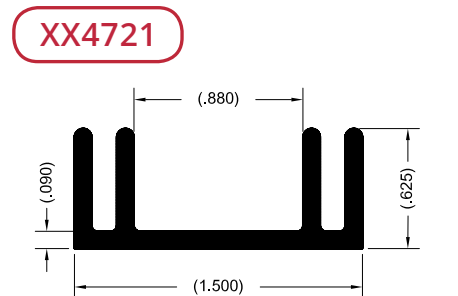
Per.	7.46	in.
WT.	0.27	lb/ft
θsa	8.00	°C/w/3"



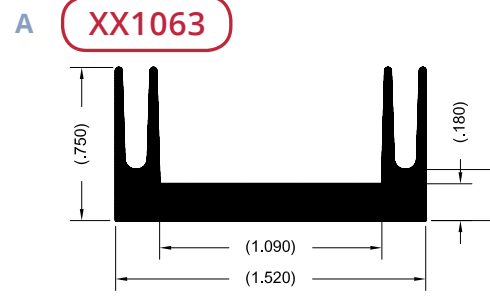
Per.	5.15	in.
WT.	0.99	lb/ft
θsa	10.00	°C/w/3"



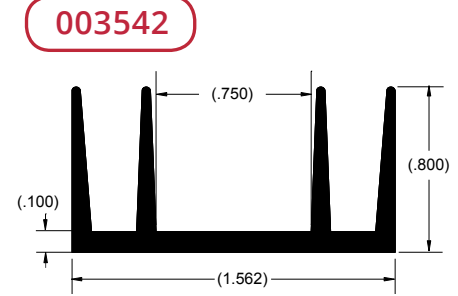
Per.	8.88	in.
WT.	0.29	lb/ft
θsa	6.40	°C/w/3"



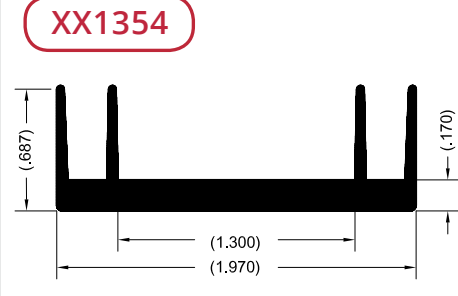
Per.	7.23	in.
WT.	0.39	lb/ft
θsa	10.30	°C/w/3"



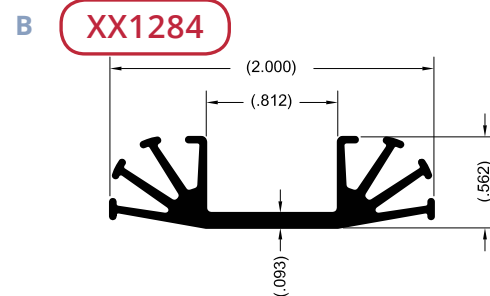
Per.	7.45	in.
WT.	0.46	lb/ft
θsa	5.10	°C/w/3"



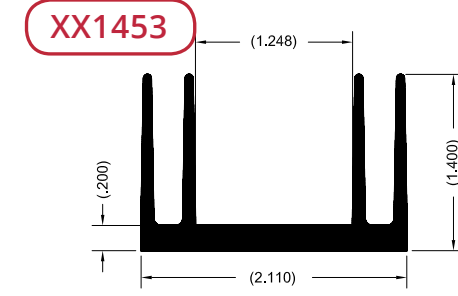
Per.	8.95	in.
WT.	0.41	lb/ft
θsa	7.80	°C/w/3"



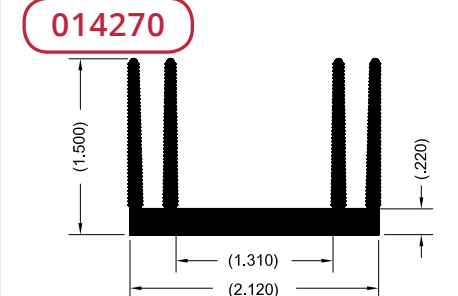
Per.	8.24	in.
WT.	0.52	lb/ft
θsa	4.30	°C/w/3"



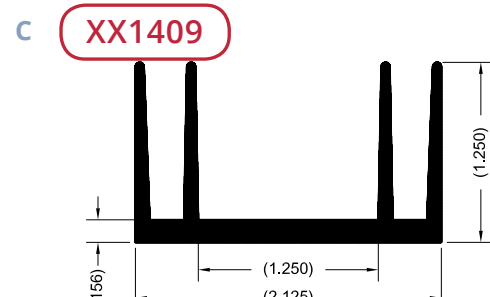
Per.	9.96	in.
WT.	0.37	lb/ft
θsa	6.50	°C/w/3"



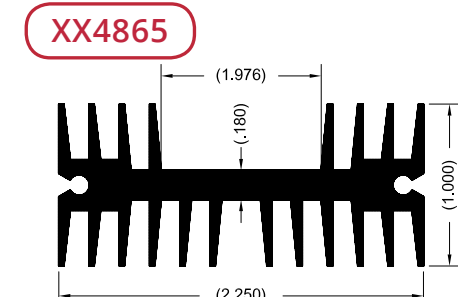
Per.	13.86	in.
WT.	1.00	lb/ft
θsa	3.50	°C/w/3"



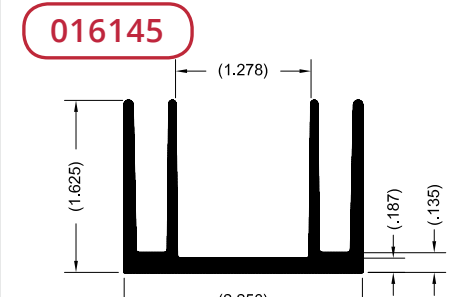
Per.	22.50	in.
WT.	1.07	lb/ft
θsa	3.10	°C/w/3"



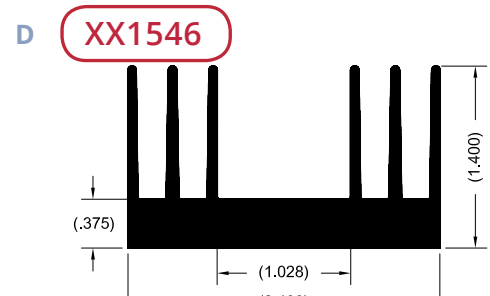
Per.	13.05	in.
WT.	0.81	lb/ft
θsa	3.80	°C/w/3"



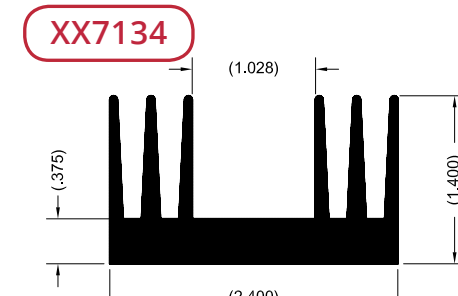
Per.	20.15	in.
WT.	1.02	lb/ft
θsa	3.50	°C/w/3"



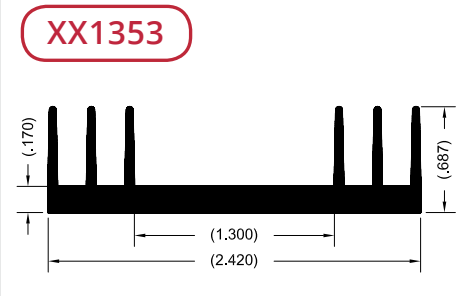
Per.	16.17	in.
WT.	1.01	lb/ft
θsa	3.70	°C/w/3"



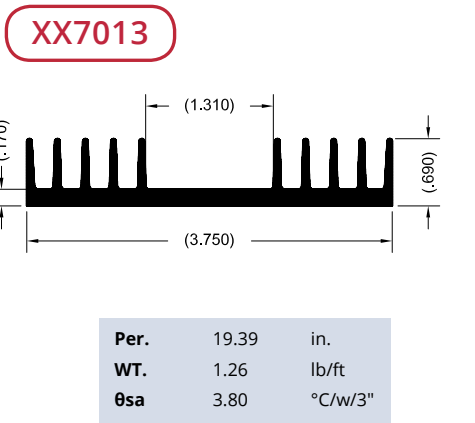
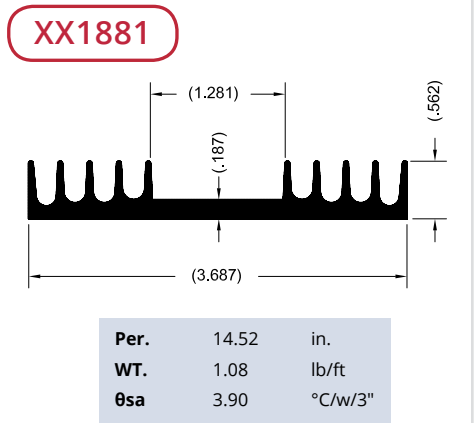
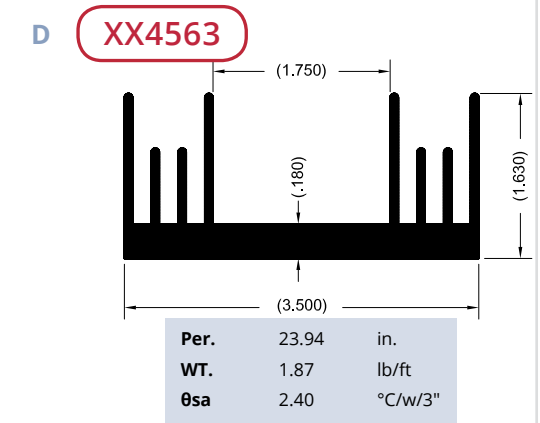
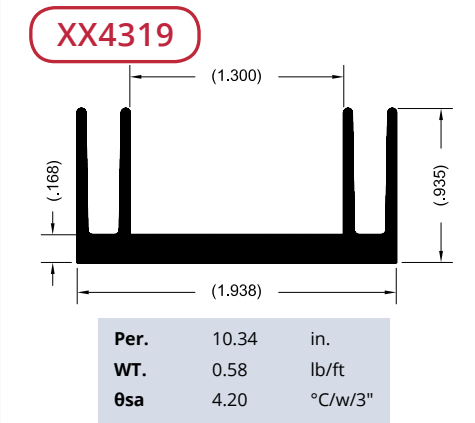
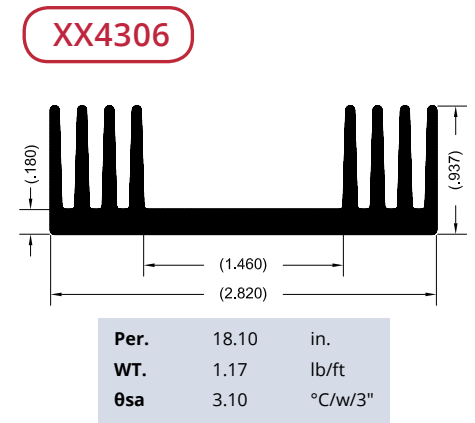
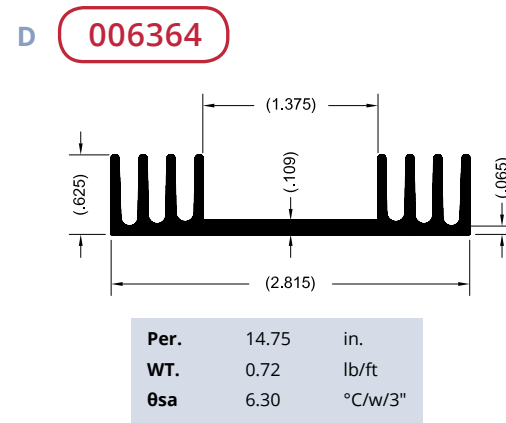
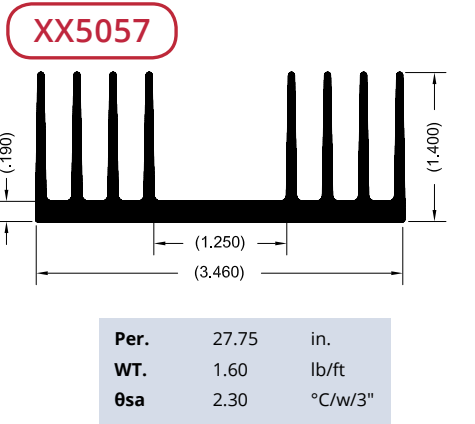
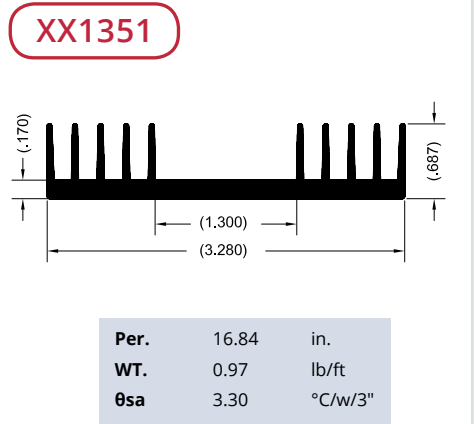
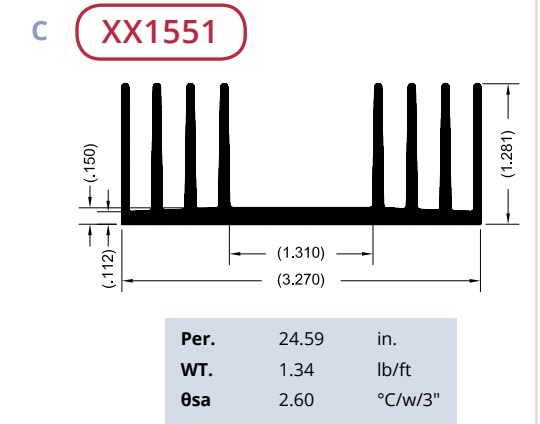
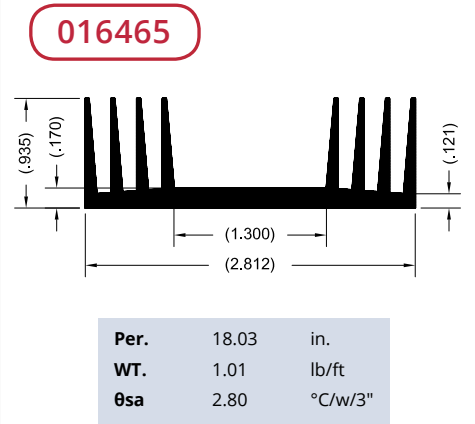
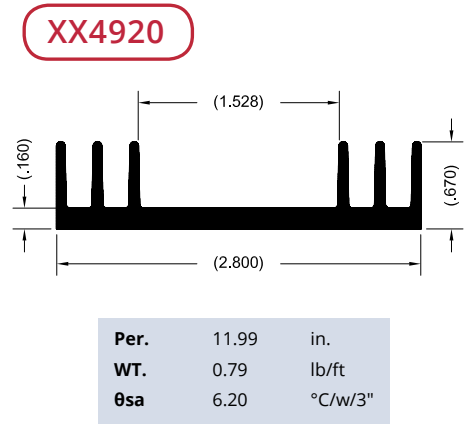
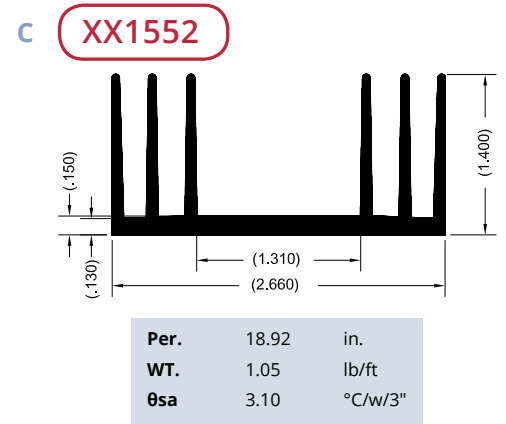
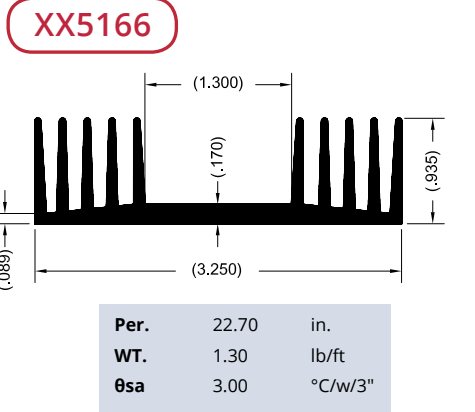
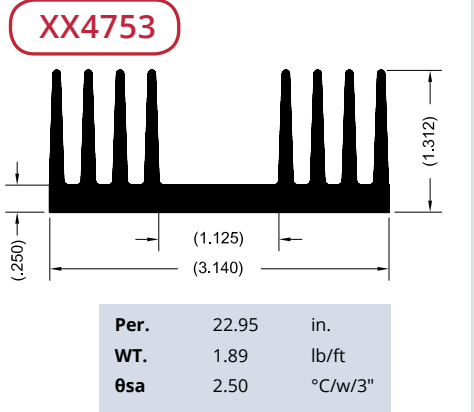
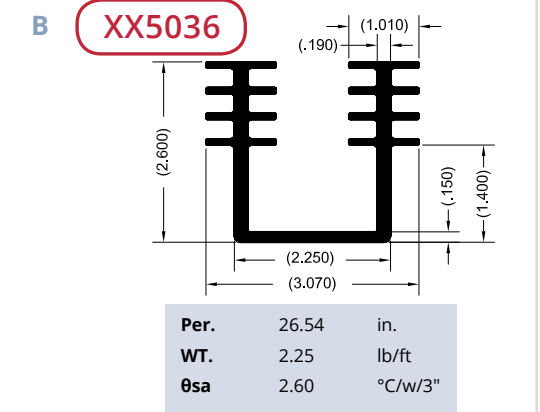
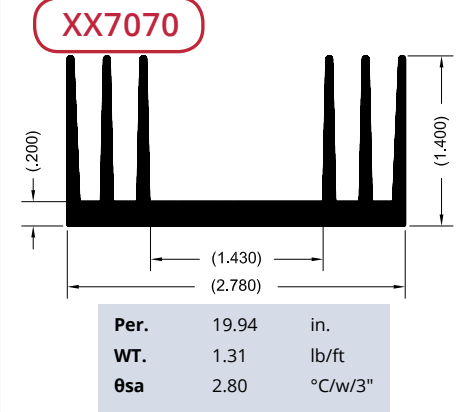
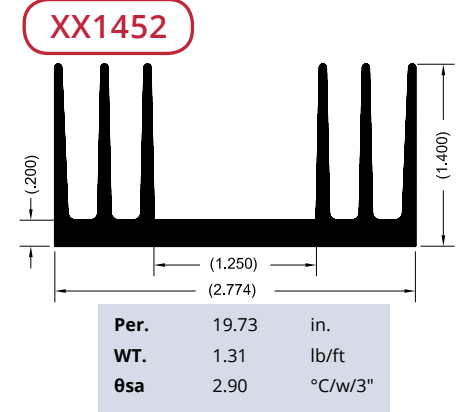
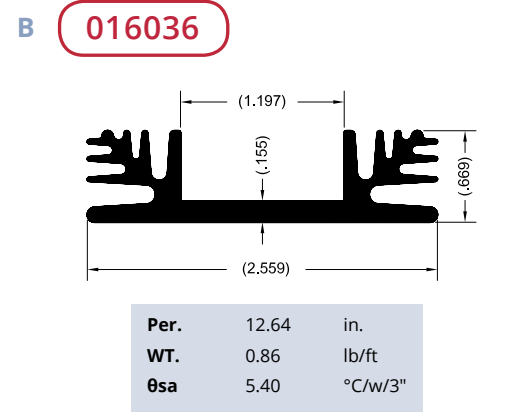
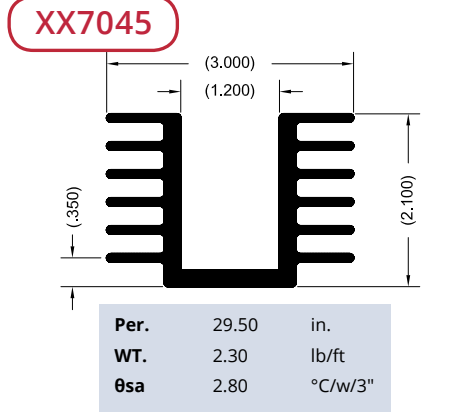
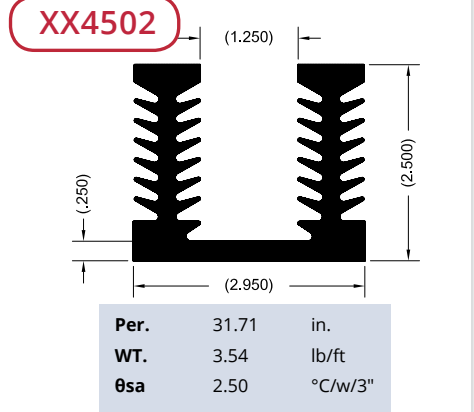
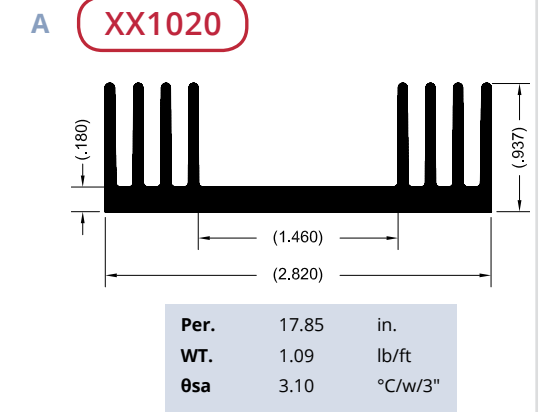
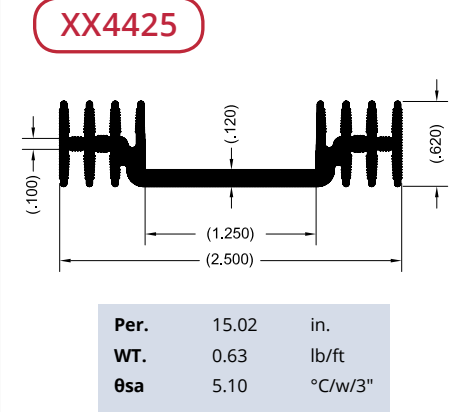
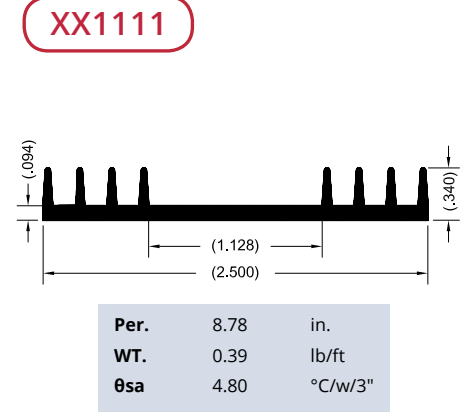
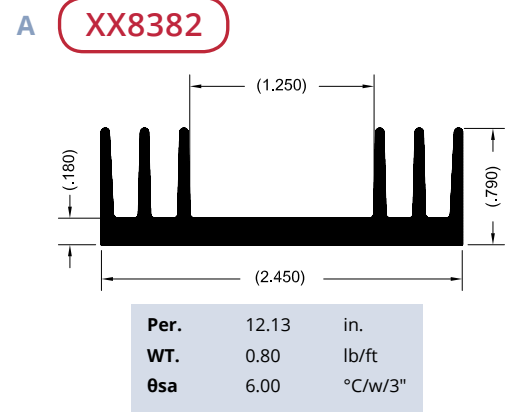
Per.	17.49	in.
WT.	1.61	lb/ft
θsa	3.70	°C/w/3"

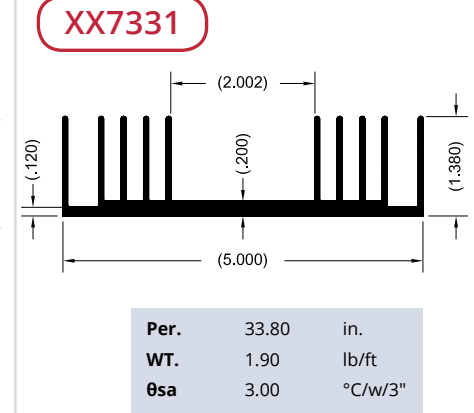
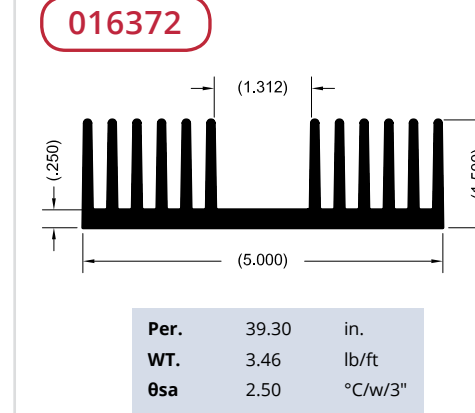
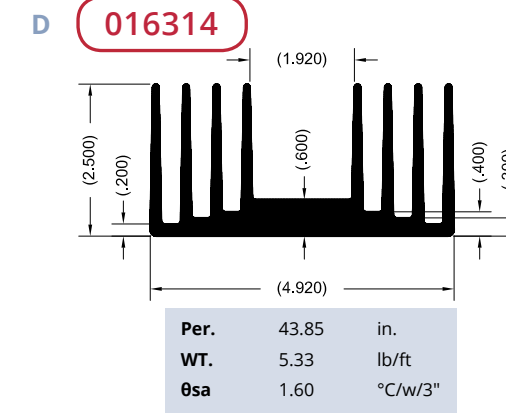
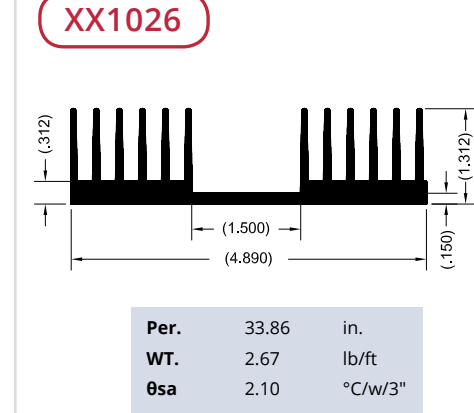
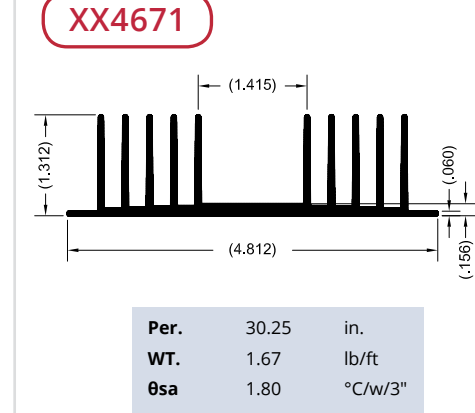
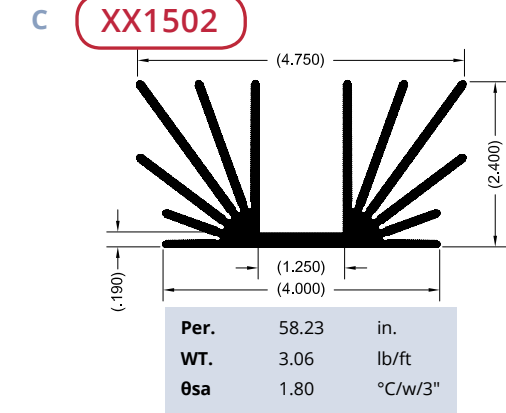
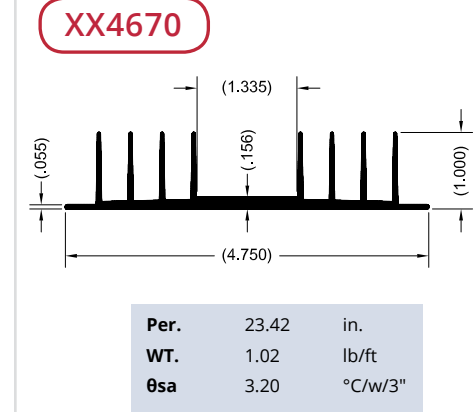
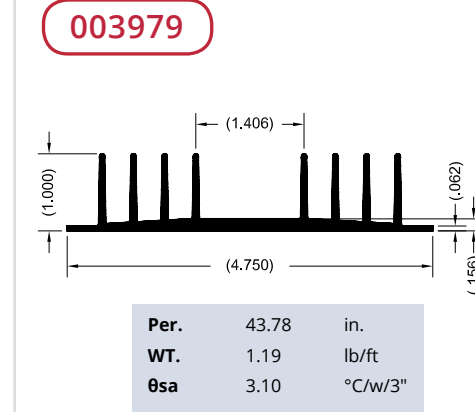
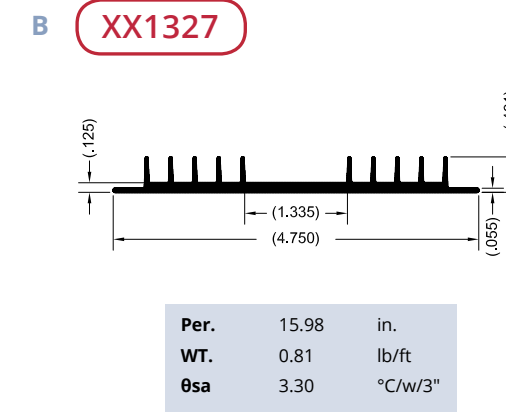
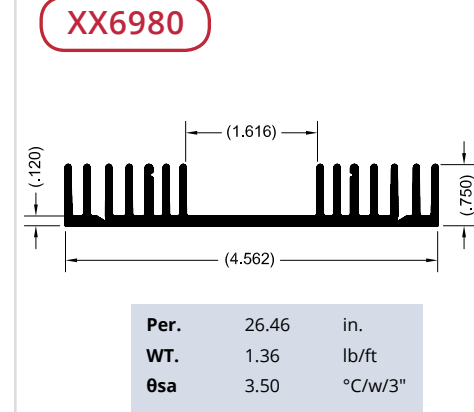
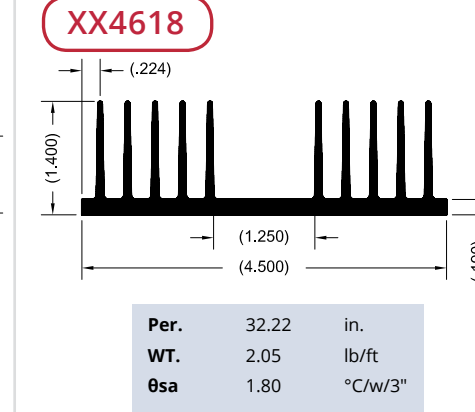
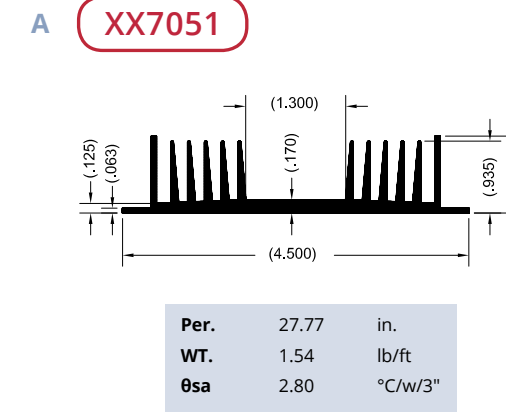
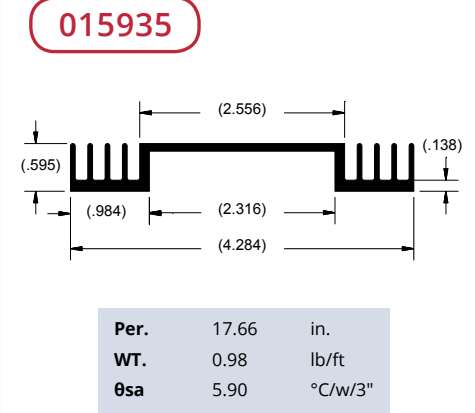
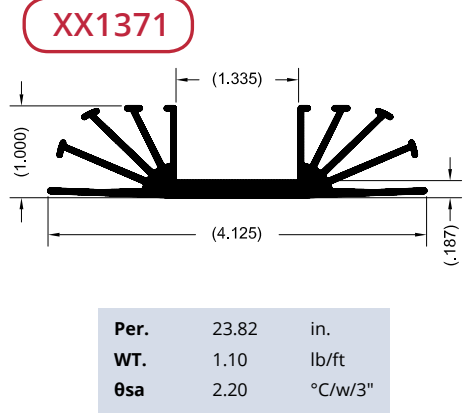
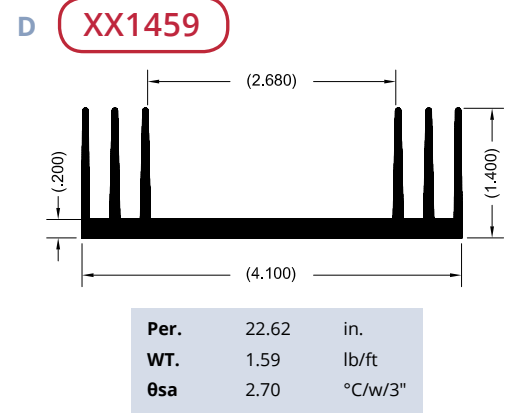
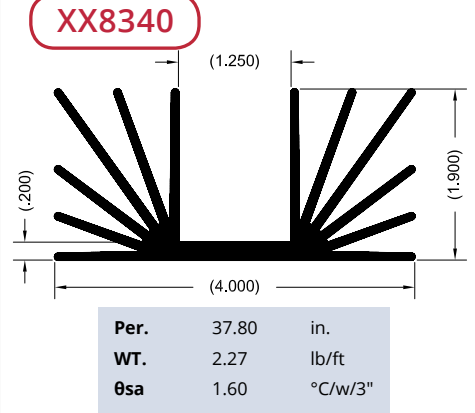
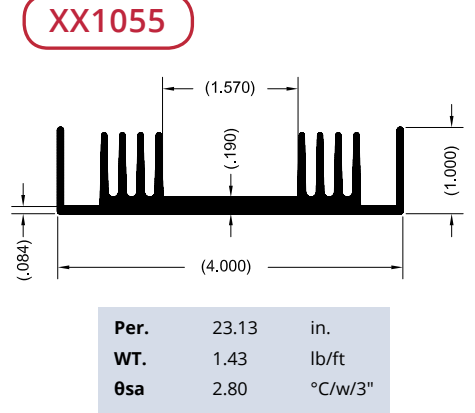
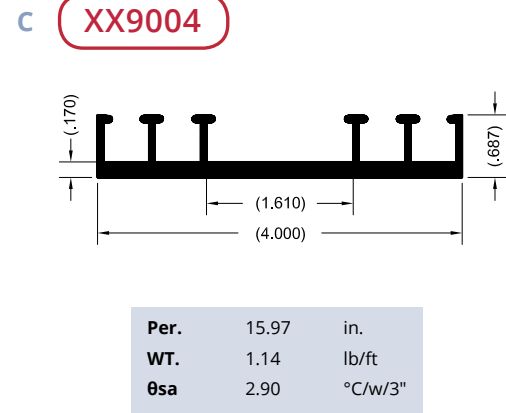
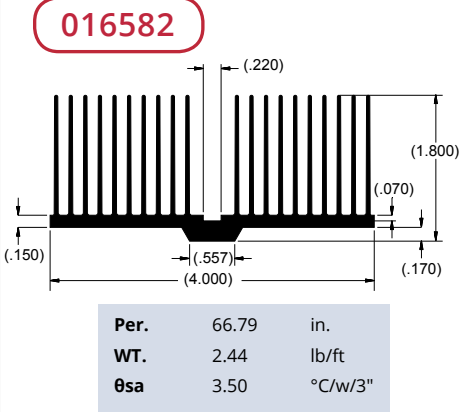
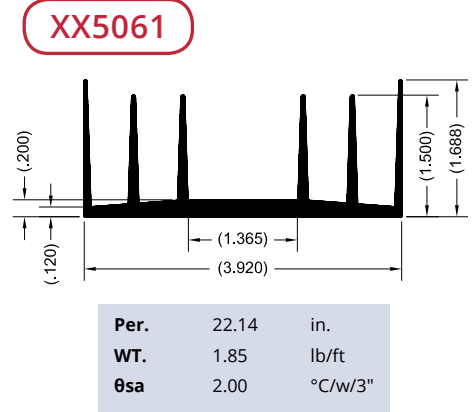
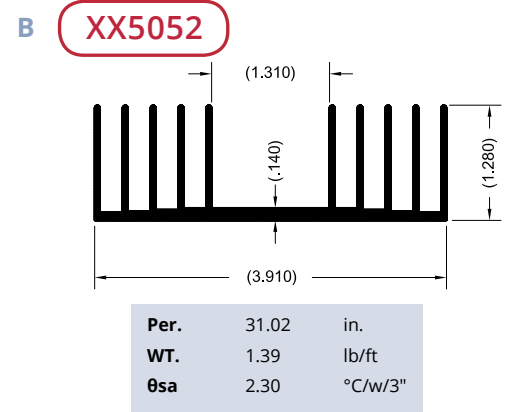
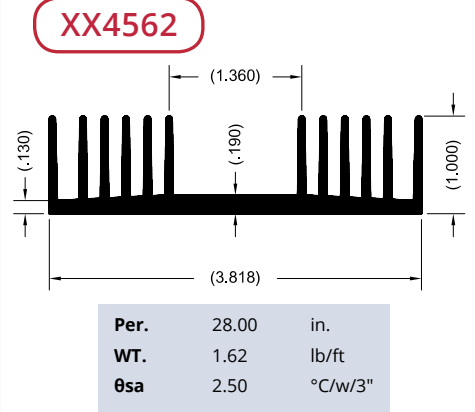
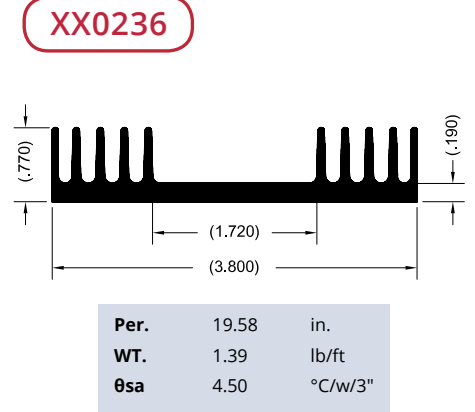
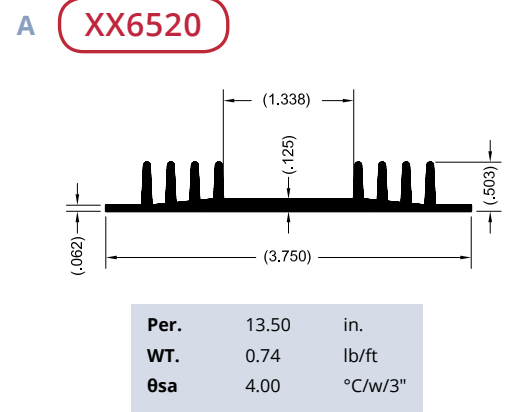


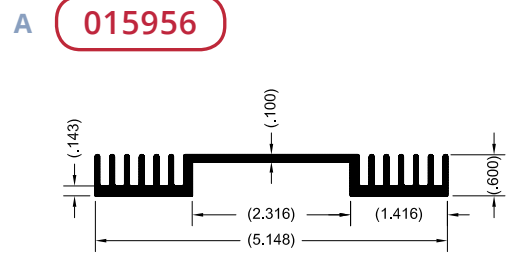
Per.	17.32	in.
WT.	1.76	lb/ft
θsa	2.00	°C/w/3"



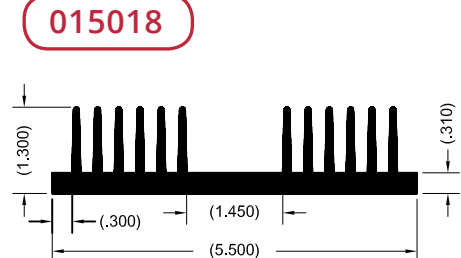
Per.	11.16	in.
WT.	0.68	lb/ft
θsa	4.00	°C/w/3"



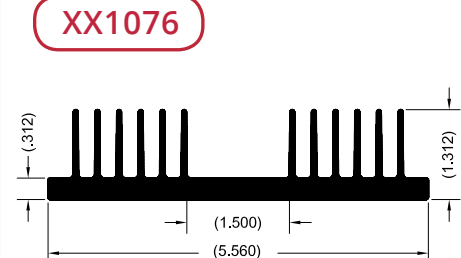




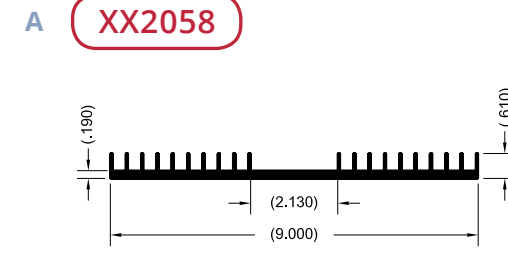
Per.	22.78	in.
WT.	1.26	lb/ft
θsa	4.90	°C/w/3"



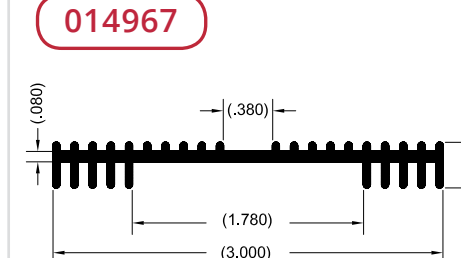
Per.	34.46	in.
WT.	3.46	lb/ft
θsa	2.50	°C/w/3"



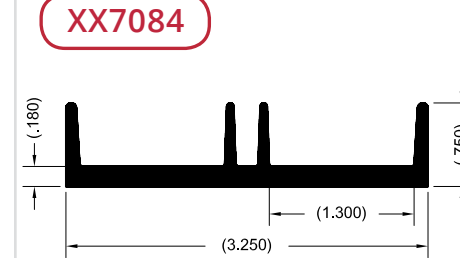
Per.	34.57	in.
WT.	3.14	lb/ft
θsa	1.60	°C/w/3"



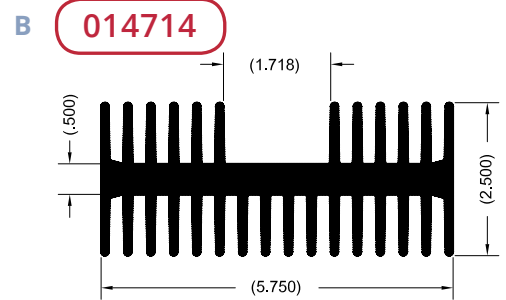
Per.	35.18	in.
WT.	2.66	lb/ft
θsa	1.60	°C/w/3"



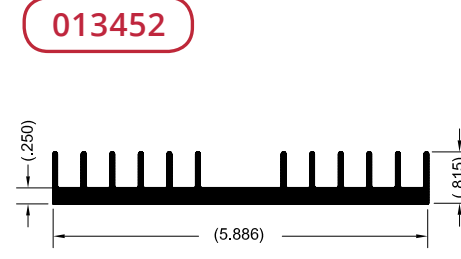
Per.	12.32	in.
WT.	0.48	lb/ft
θsa	5.70	°C/w/3"



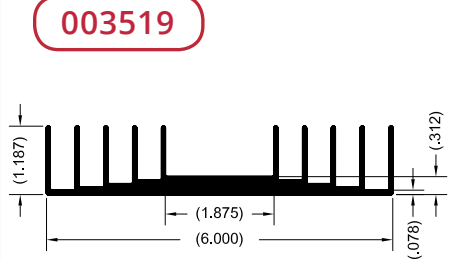
Per.	11.50	in.
WT.	0.96	lb/ft
θsa	4.50	°C/w/3"



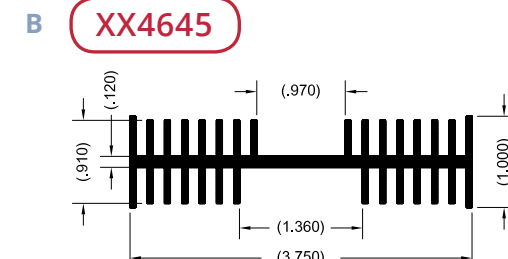
Per.	86.54	in.
WT.	7.43	lb/ft
θsa	0.80	°C/w/3"



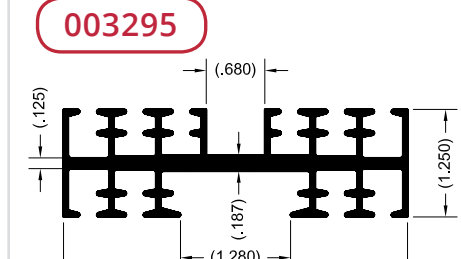
Per.	25.26	in.
WT.	2.27	lb/ft
θsa	2.50	°C/w/3"



Per.	32.02	in.
WT.	2.26	lb/ft
θsa	2.10	°C/w/3"



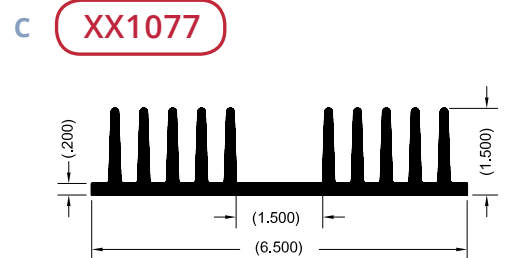
Per.	31.06	in.
WT.	1.41	lb/ft
θsa	2.80	°C/w/3"



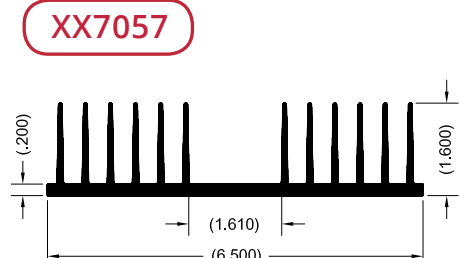
Per.	27.00	in.
WT.	1.56	lb/ft
θsa	2.60	°C/w/3"



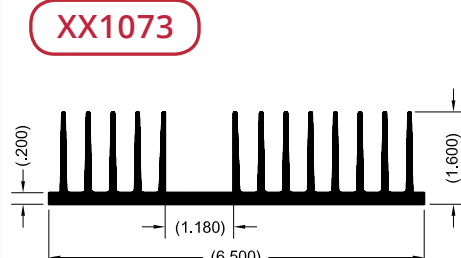
Per.	28.06	in.
WT.	1.70	lb/ft
θsa	2.20	°C/w/3"



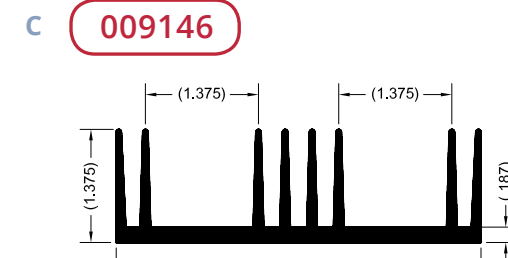
Per.	37.67	in.
WT.	4.03	lb/ft
θsa	1.40	°C/w/3"



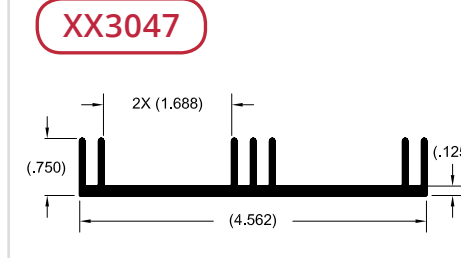
Per.	45.98	in.
WT.	3.07	lb/ft
θsa	1.70	°C/w/3"



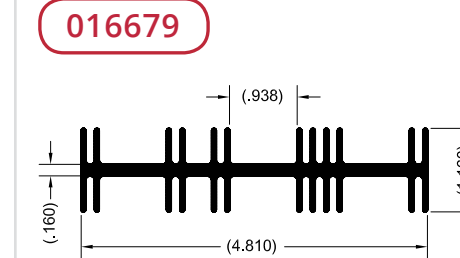
Per.	48.32	in.
WT.	3.20	lb/ft
θsa	1.30	°C/w/3"



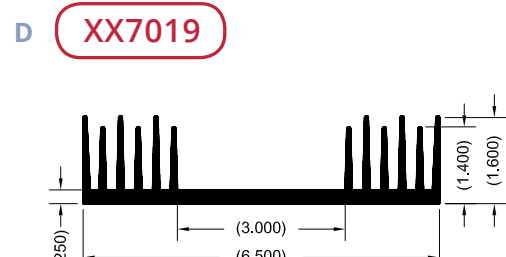
Per.	27.56	in.
WT.	2.13	lb/ft
θsa	3.40	°C/w/3"



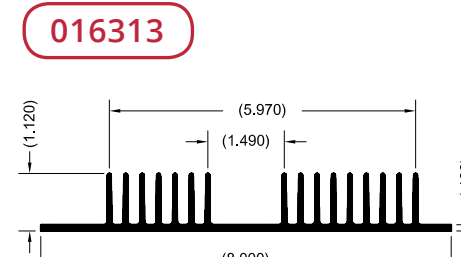
Per.	17.84	in.
WT.	1.01	lb/ft
θsa	2.70	°C/w/3"



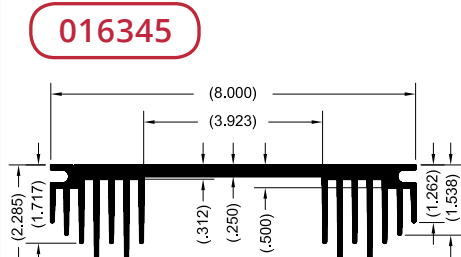
Per.	32.13	in.
WT.	1.85	lb/ft
θsa	2.50	°C/w/3"



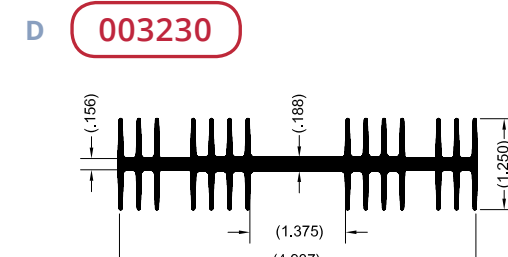
Per.	41.93	in.
WT.	3.63	lb/ft
θsa	1.60	°C/w/3"



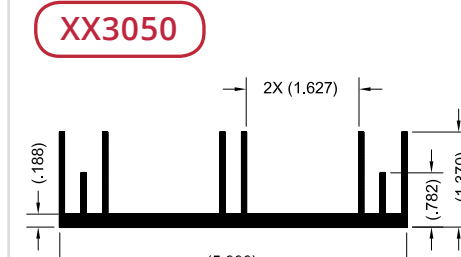
Per.	46.61	in.
WT.	2.70	lb/ft
θsa	2.30	°C/w/3"



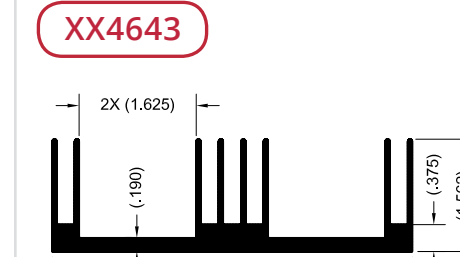
Per.	57.23	in.
WT.	4.66	lb/ft
θsa	1.90	°C/w/3"



Per.	34.75	in.
WT.	1.95	lb/ft
θsa	2.00	°C/w/3"



Per.	26.94	in.
WT.	1.73	lb/ft
θsa	2.20	°C/w/3"



Per.	30.28	in.
WT.	2.24	lb/ft
θsa	2.30	°C/w/3"

**A XX9014**

Per.	26.40	in.
WT.	1.99	lb/ft
θsa	2.20	°C/w/3"

**007999**

Per.	31.80	in.
WT.	2.04	lb/ft
θsa	2.26	°C/w/3"

**XX4917**

Per.	35.65	in.
WT.	2.47	lb/ft
θsa	1.25	°C/w/3"

**A 014324**

Per.	53.57	in.
WT.	3.94	lb/ft
θsa	1.30	°C/w/3"

**016333**

Per.	48.03	in.
WT.	4.08	lb/ft
θsa	2.20	°C/w/3"

**XX3002**

Per.	72.21	in.
WT.	4.83	lb/ft
θsa	1.10	°C/w/3"

**B 04842**

Per.	28.36	in.
WT.	1.68	lb/ft
θsa	2.47	°C/w/3"

**XX4617**

Per.	45.00	in.
WT.	2.74	lb/ft
θsa	1.40	°C/w/3"

**XX1112**

Per.	29.37	in.
WT.	1.58	lb/ft
θsa	2.40	°C/w/3"

**B XX5060**

Per.	62.78	in.
WT.	5.21	lb/ft
θsa	0.87	°C/w/3"

**XX8182**

Per.	48.81	in.
WT.	3.49	lb/ft
θsa	1.30	°C/w/3"

**XX5541**

Per.	66.93	in.
WT.	5.14	lb/ft
θsa	1.10	°C/w/3"

**C 016529**

Per.	29.12	in.
WT.	1.81	lb/ft
θsa	3.50	°C/w/3"

**XX3022**

Per.	42.99	in.
WT.	3.04	lb/ft
θsa	1.50	°C/w/3"

**XX3017**

Per.	43.15	in.
WT.	3.21	lb/ft
θsa	1.60	°C/w/3"

**C 016503**

Per.	64.61	in.
WT.	4.07	lb/ft
θsa	1.90	°C/w/3"

**XX7055**

Per.	23.50	in.
WT.	1.15	lb/ft
θsa	2.40	°C/w/3"

**019133**

Per.	54.48	in.
WT.	4.04	lb/ft
θsa	2.40	°C/w/3"

**D 006412**

Per.	41.00	in.
WT.	2.82	lb/ft
θsa	1.70	°C/w/3"

**XX3012**

Per.	53.45	in.
WT.	4.46	lb/ft
θsa	1.50	°C/w/3"

**XX3013**

Per.	49.20	in.
WT.	3.21	lb/ft
θsa	1.60	°C/w/3"

**D 014343**

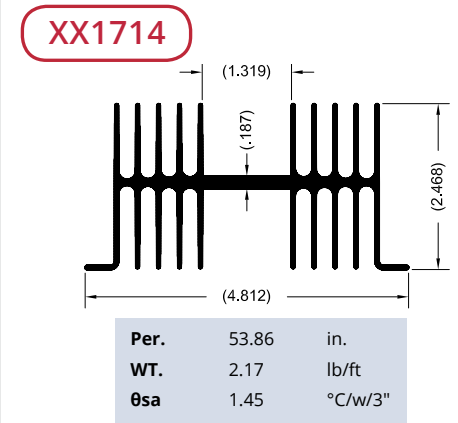
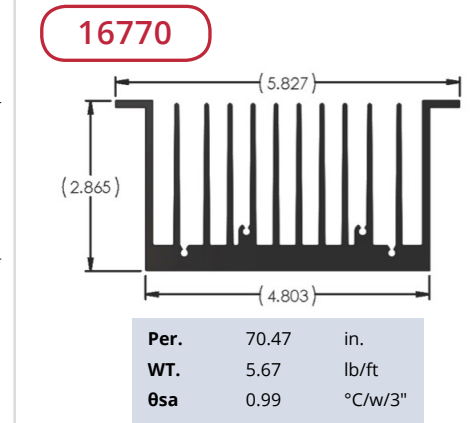
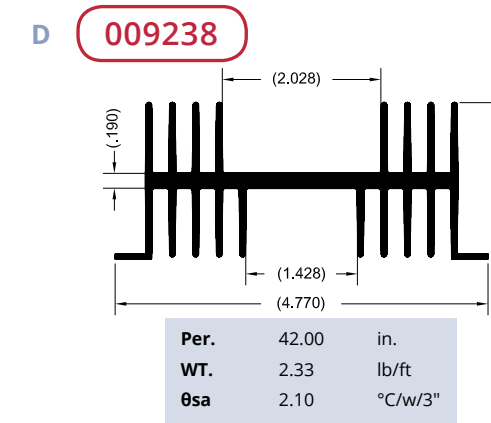
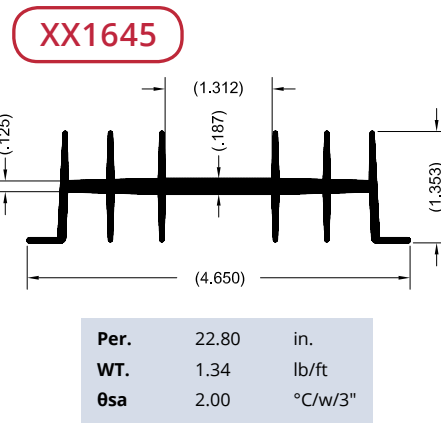
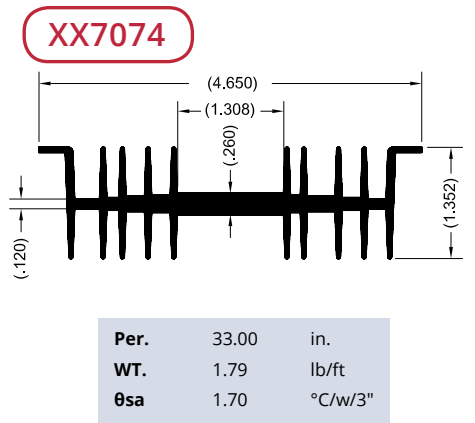
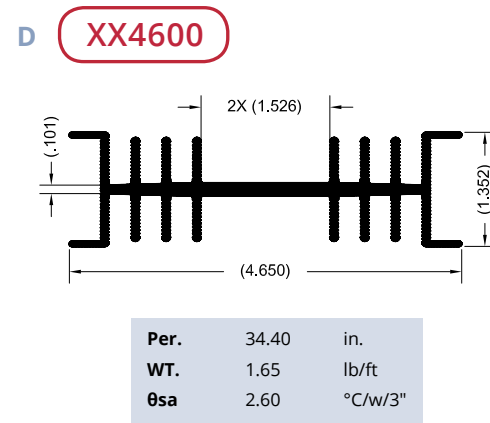
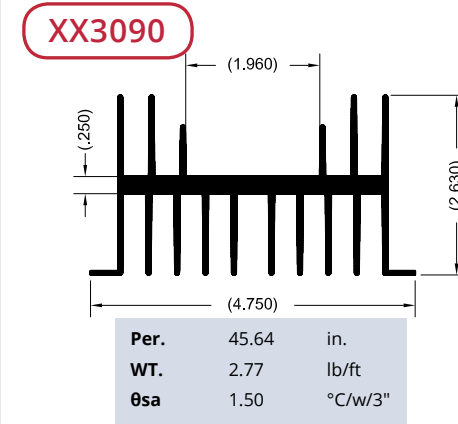
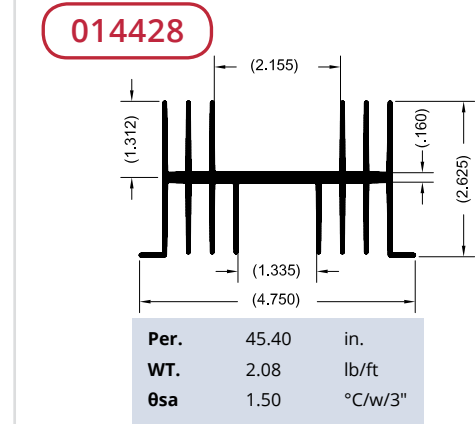
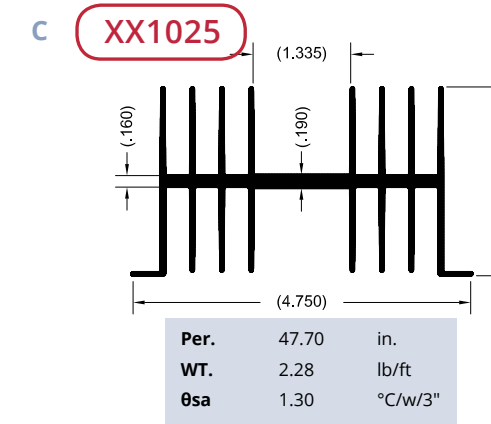
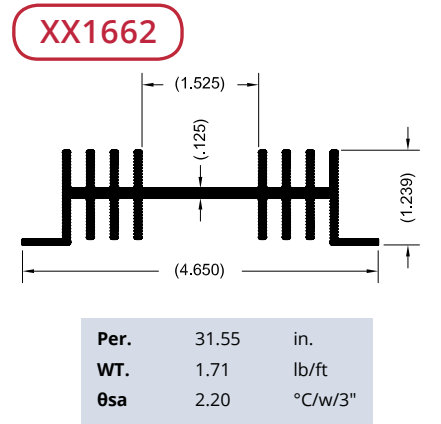
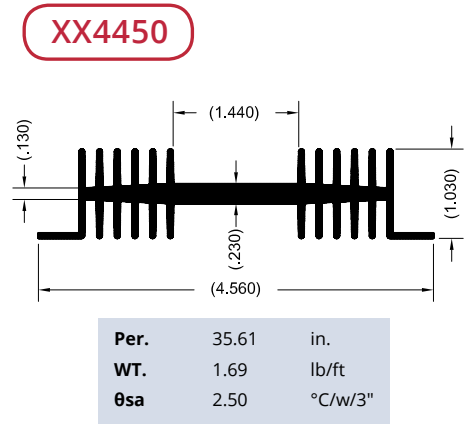
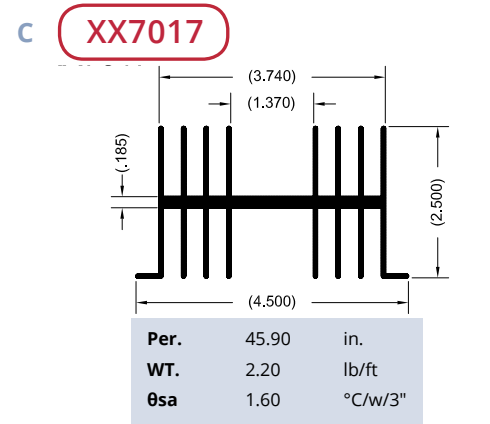
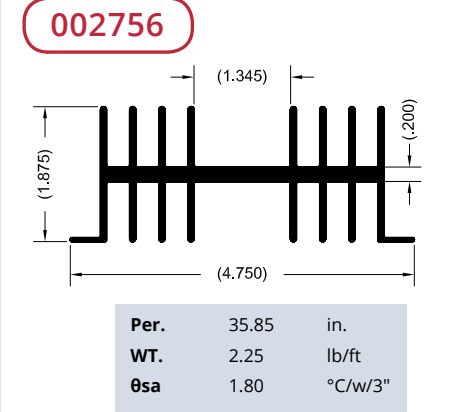
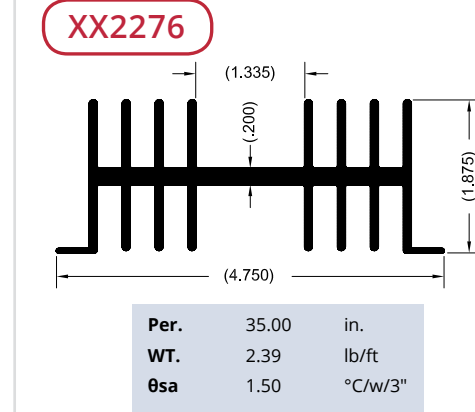
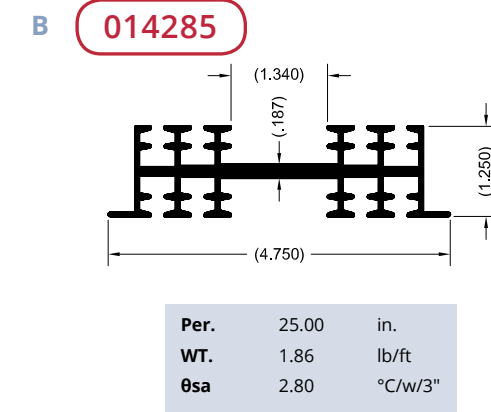
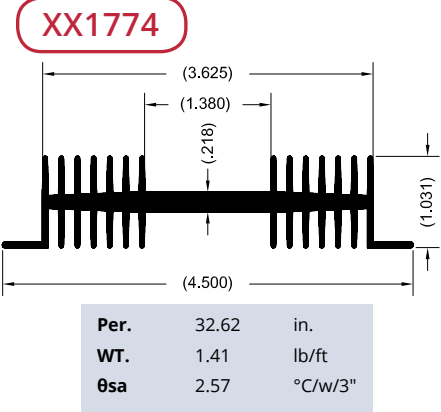
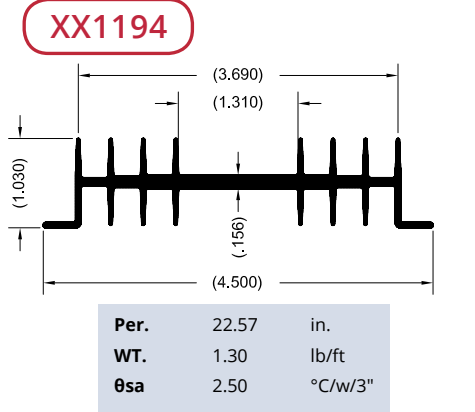
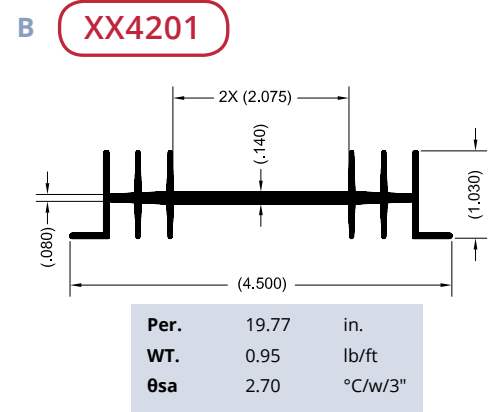
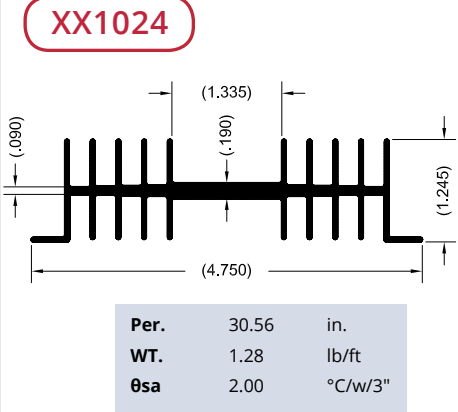
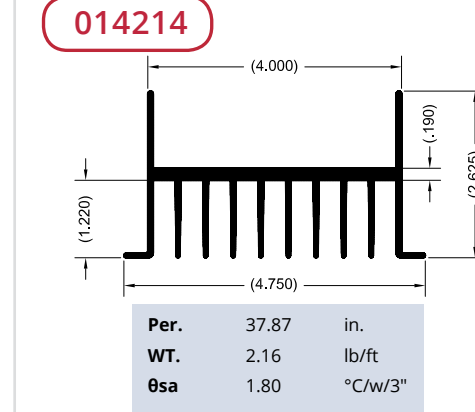
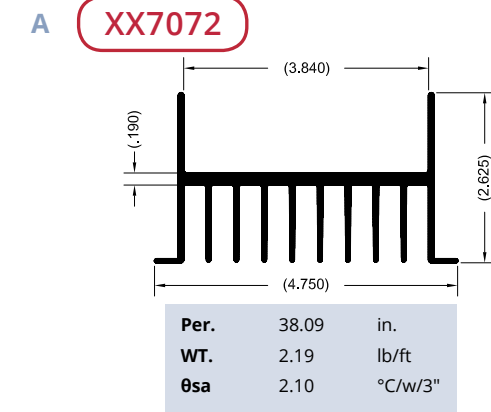
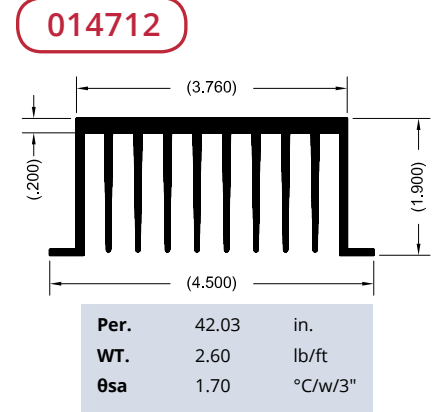
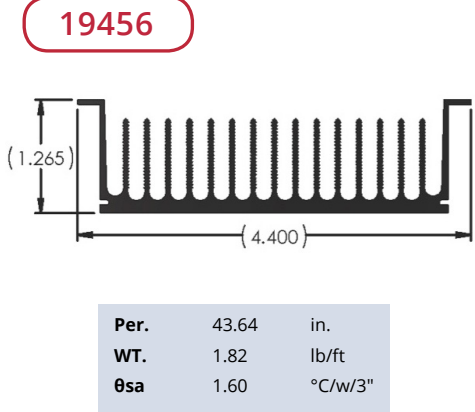
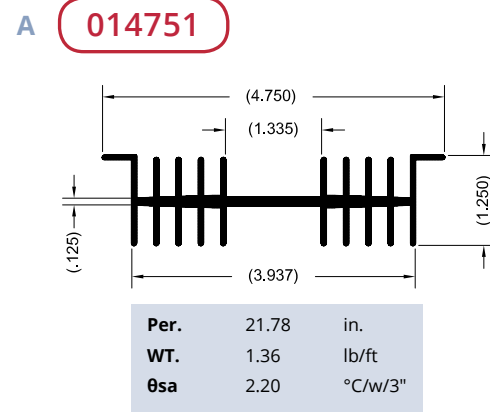
Per.	29.47	in.
WT.	1.71	lb/ft
θsa	2.40	°C/w/3"

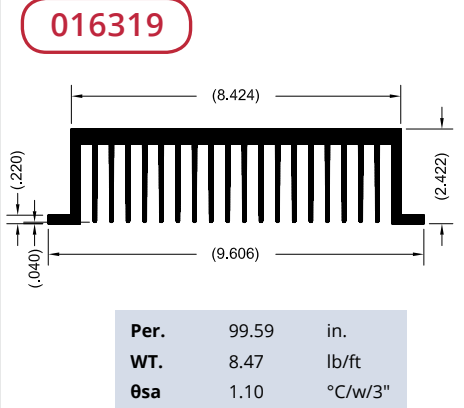
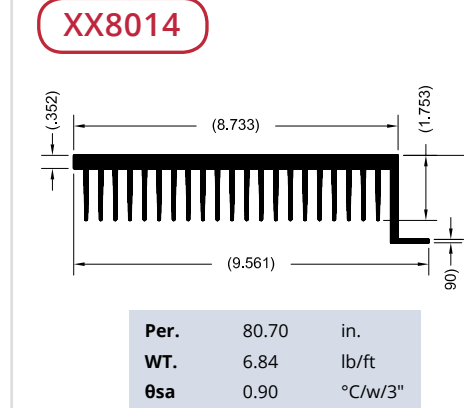
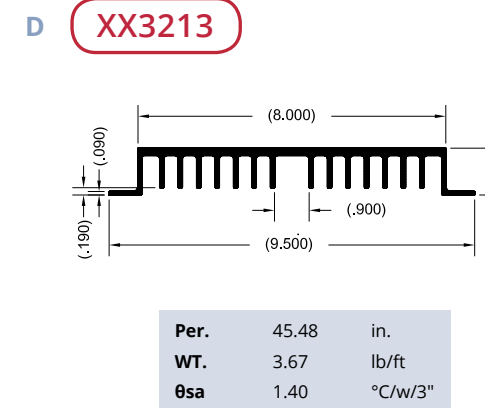
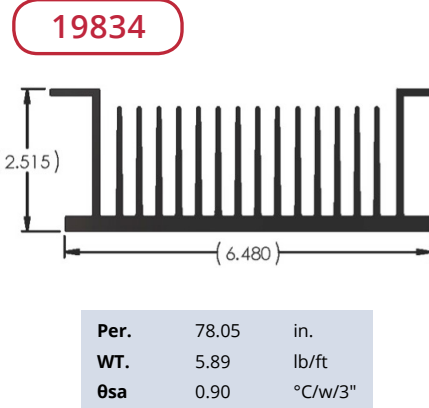
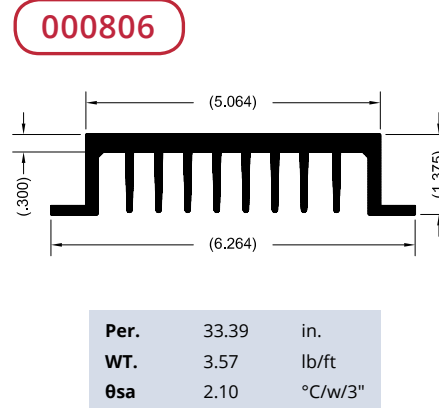
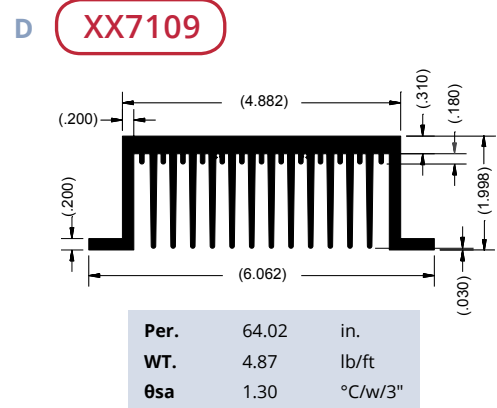
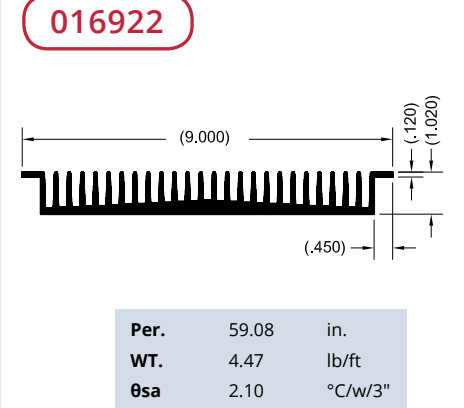
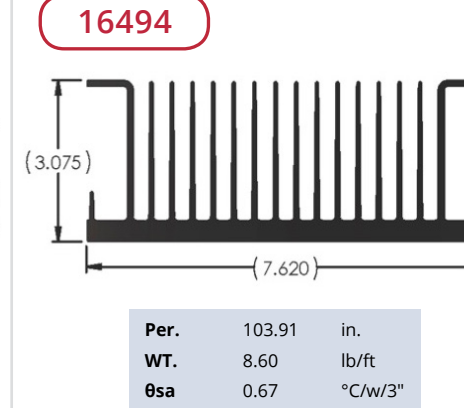
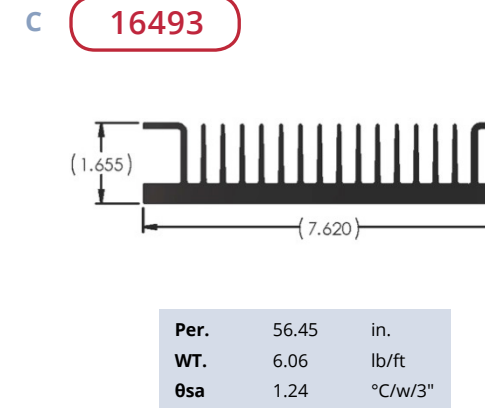
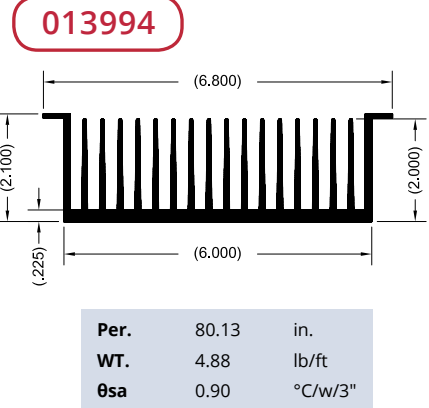
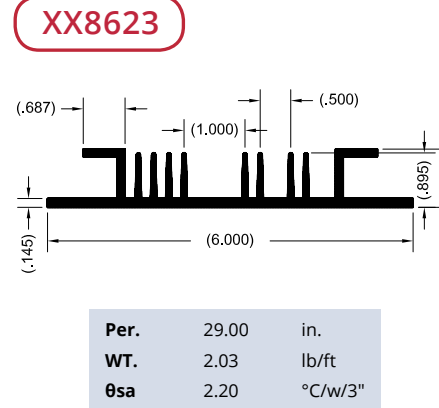
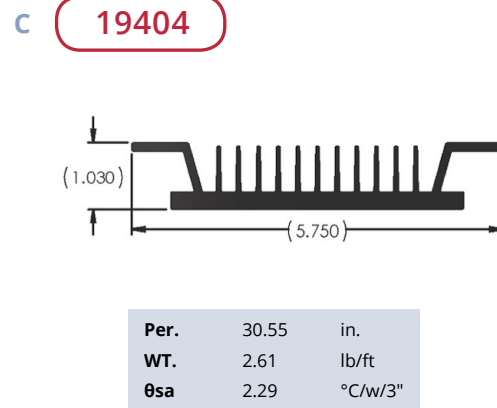
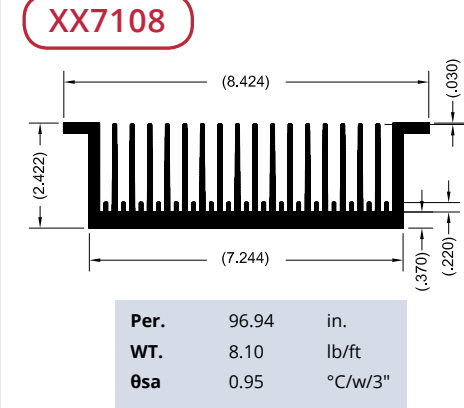
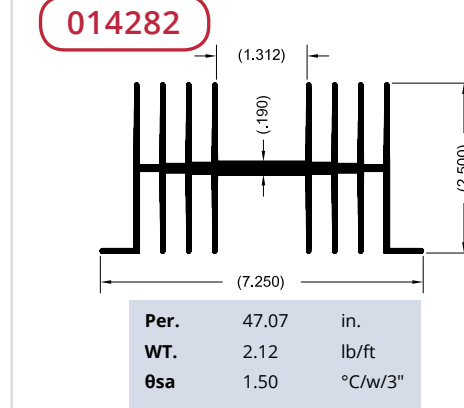
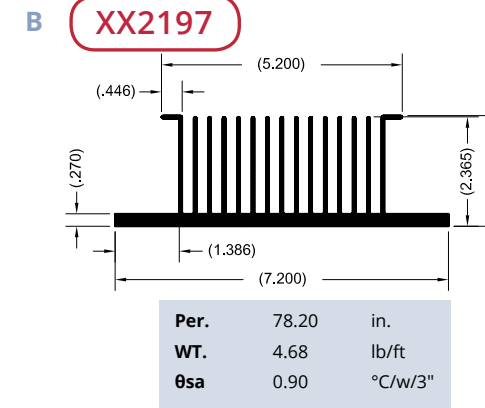
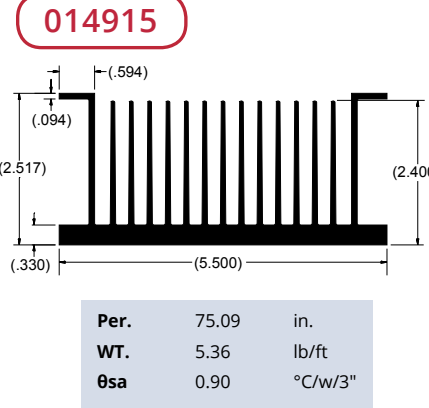
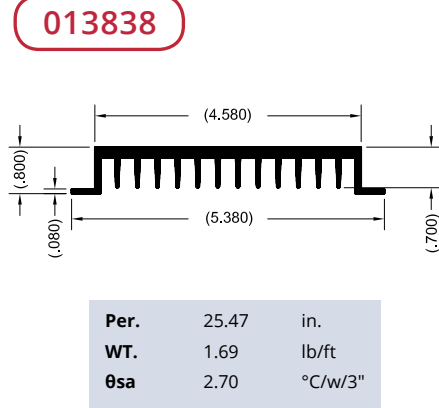
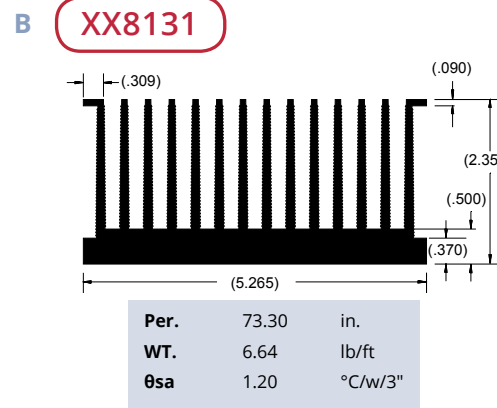
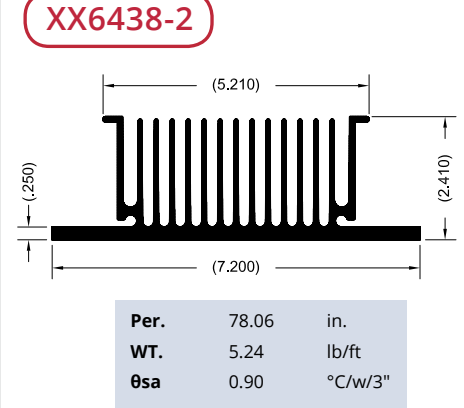
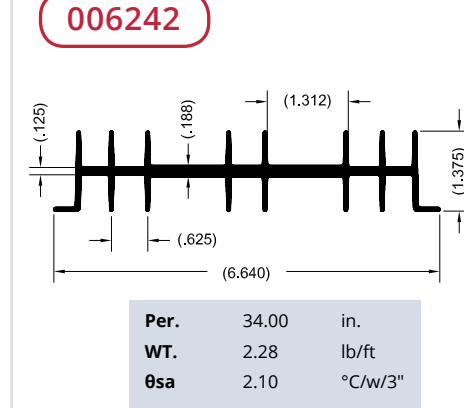
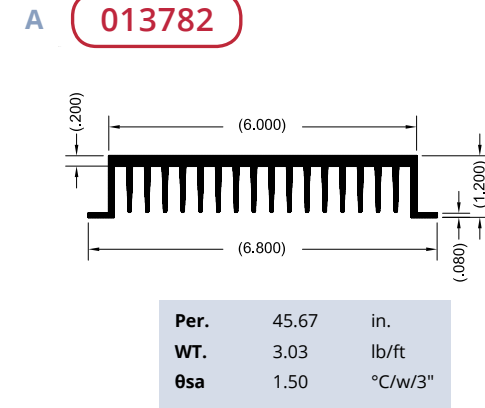
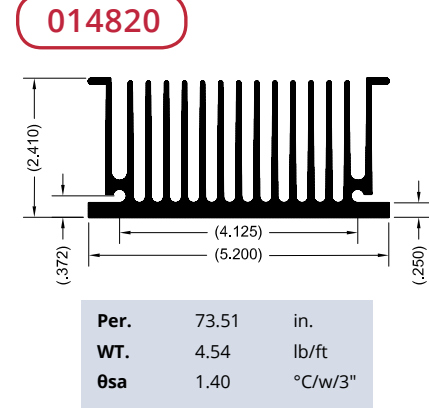
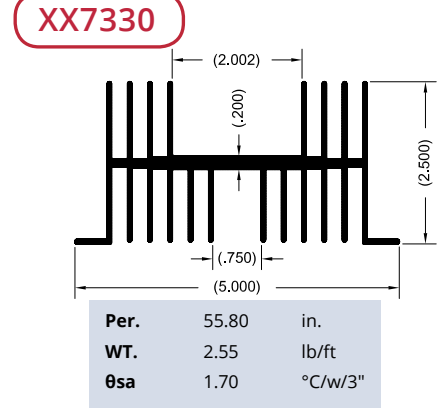
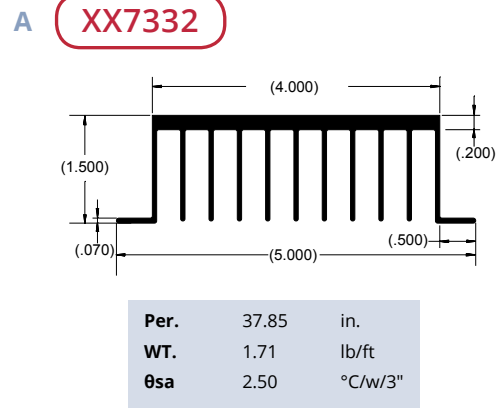
**014344**

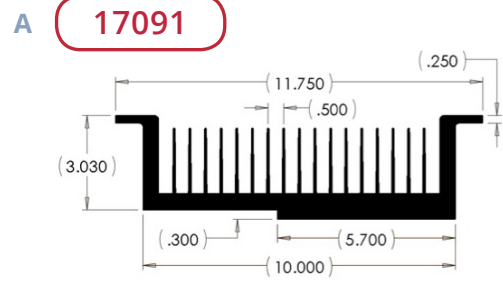
Per.	17.43	in.
WT.	0.90	lb/ft
θsa	4.00	°C/w/3"

**XX4874**

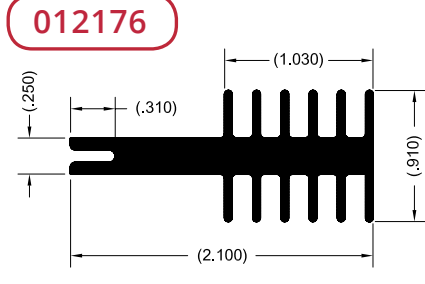
Per.	30.64	in.
WT.	2.60	lb/ft
θsa	2.10	°C/w/3"



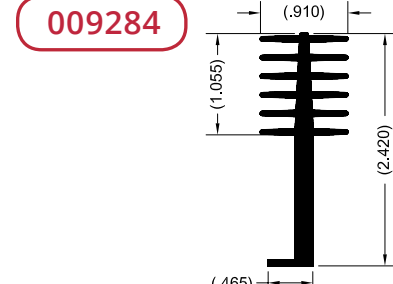




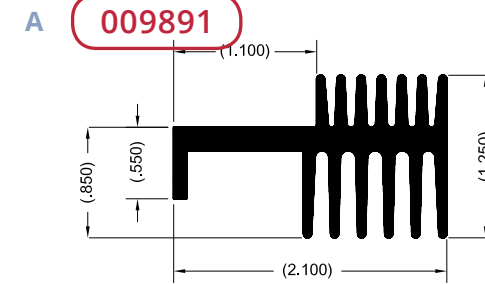
Per.	105.27	in.
WT.	15.43	lb/ft
θsa	0.66	°C/w/3"



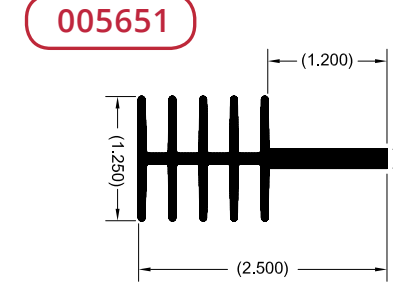
Per.	12.65	in.
WT.	0.81	lb/ft
θsa	5.50	°C/w/3"



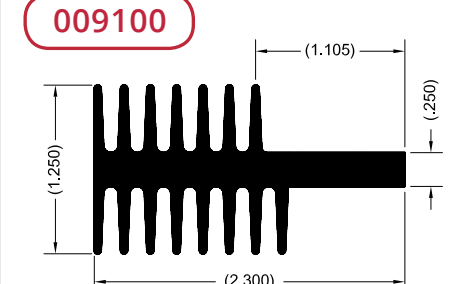
Per.	15.24	in.
WT.	0.80	lb/ft
θsa	4.60	°C/w/3"



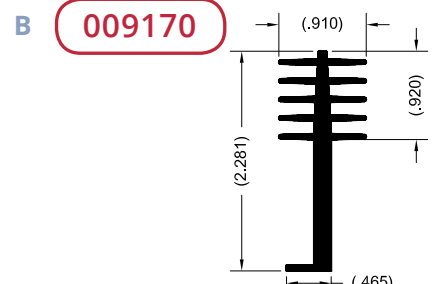
Per.	14.74	in.
WT.	1.11	lb/ft
θsa	4.70	°C/w/3"



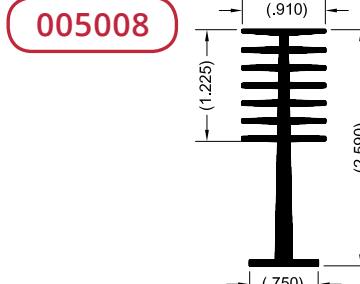
Per.	18.00	in.
WT.	0.88	lb/ft
θsa	3.90	°C/w/3"



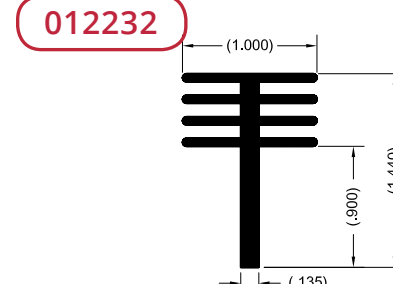
Per.	20.10	in.
WT.	1.23	lb/ft
θsa	3.50	°C/w/3"



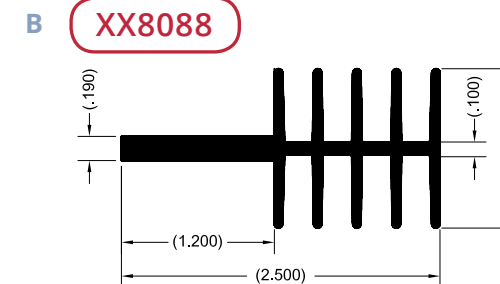
Per.	13.50	in.
WT.	0.73	lb/ft
θsa	5.20	°C/w/3"



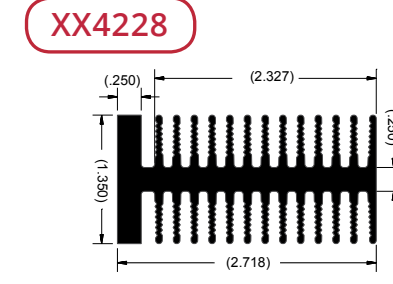
Per.	20.00	in.
WT.	0.81	lb/ft
θsa	3.50	°C/w/3"



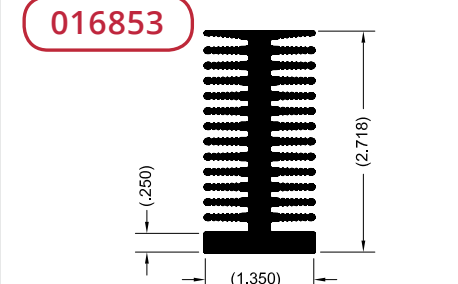
Per.	9.80	in.
WT.	0.47	lb/ft
θsa	7.10	°C/w/3"



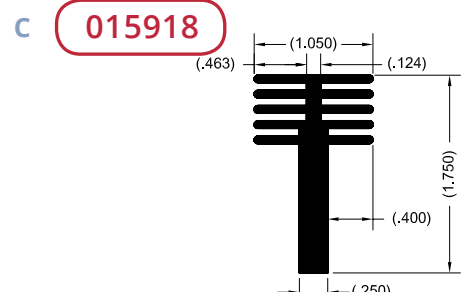
Per.	14.65	in.
WT.	0.93	lb/ft
θsa	4.20	°C/w/3"



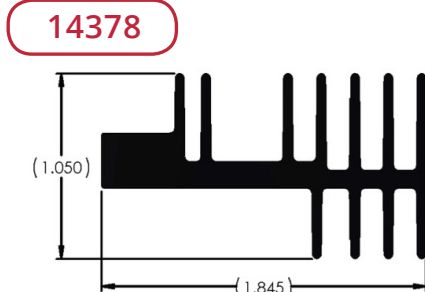
Per.	38.93	in.
WT.	2.29	lb/ft
θsa	1.90	°C/w/3"



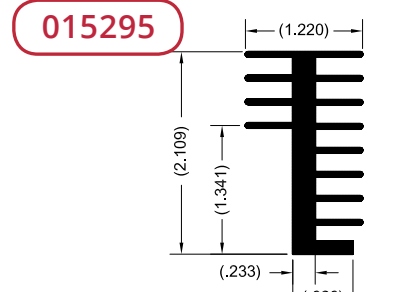
Per.	39.17	in.
WT.	2.28	lb/ft
θsa	3.10	°C/w/3"



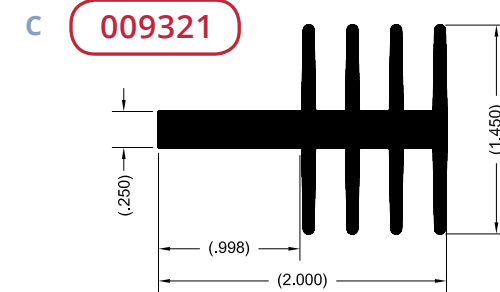
Per.	13.22	in.
WT.	0.78	lb/ft
θsa	0.00	°C/w/3"



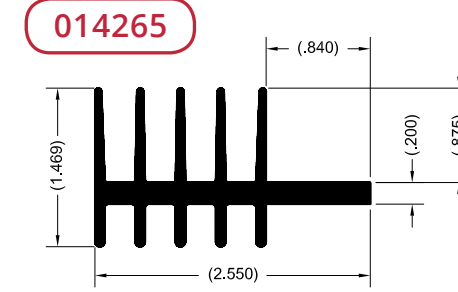
Per.	13.90	in.
WT.	0.72	lb/ft
θsa	5.03	°C/w/3"



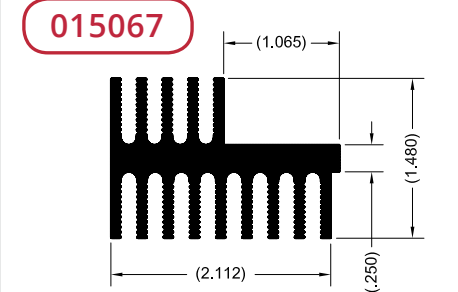
Per.	17.15	in.
WT.	1.04	lb/ft
θsa	0.00	°C/w/3"



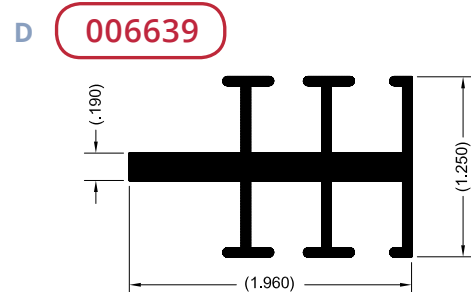
Per.	14.83	in.
WT.	1.02	lb/ft
θsa	4.70	°C/w/3"



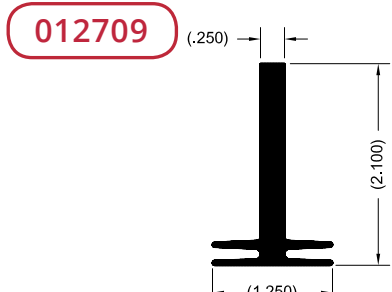
Per.	17.37	in.
WT.	1.33	lb/ft
θsa	4.00	°C/w/3"



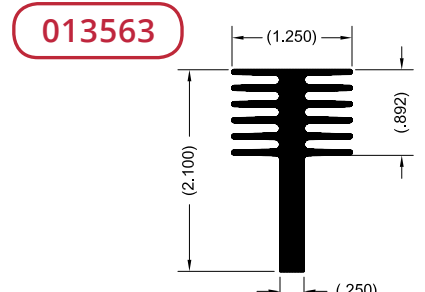
Per.	24.06	in.
WT.	1.50	lb/ft
θsa	2.90	°C/w/3"



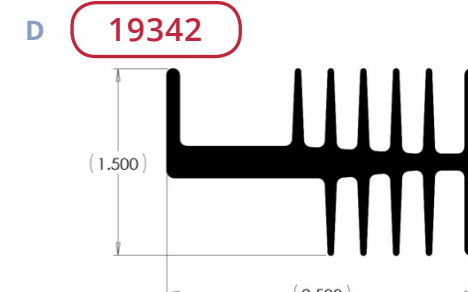
Per.	16.00	in.
WT.	0.73	lb/ft
θsa	4.40	°C/w/3"



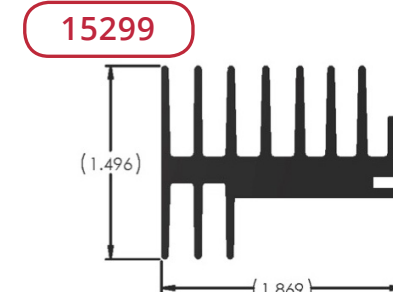
Per.	8.40	in.
WT.	0.76	lb/ft
θsa	8.30	°C/w/3"



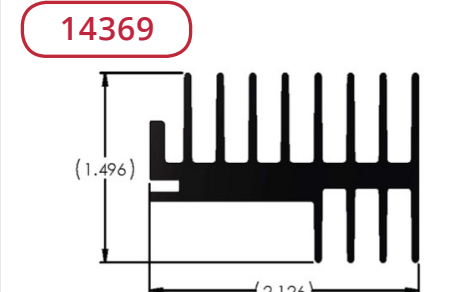
Per.	15.81	in.
WT.	1.02	lb/ft
θsa	4.40	°C/w/3"



Per.	19.99	in.
WT.	1.32	lb/ft
θsa	3.50	°C/w/3"

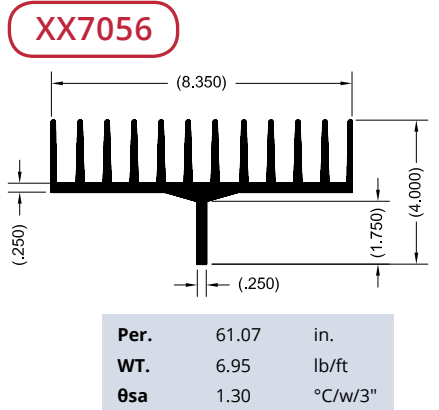
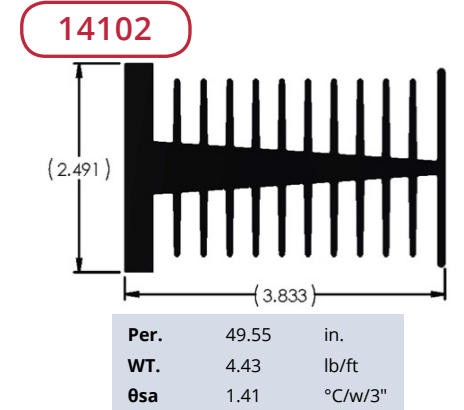
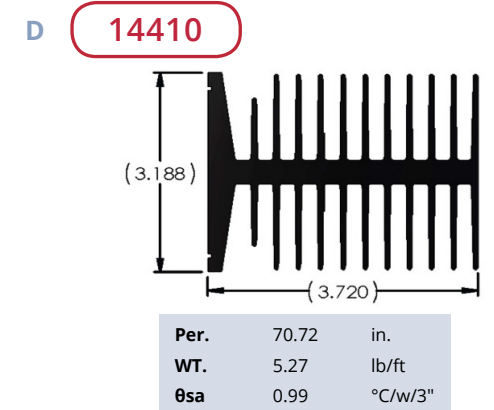
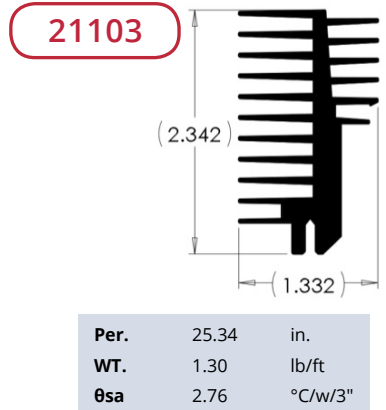
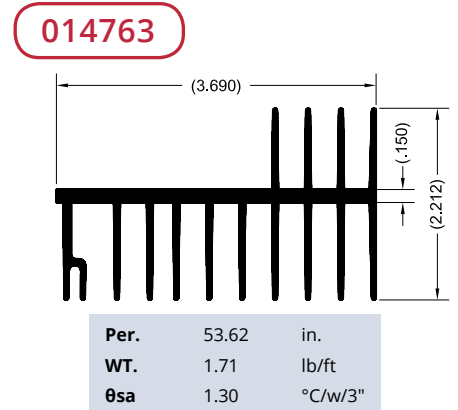
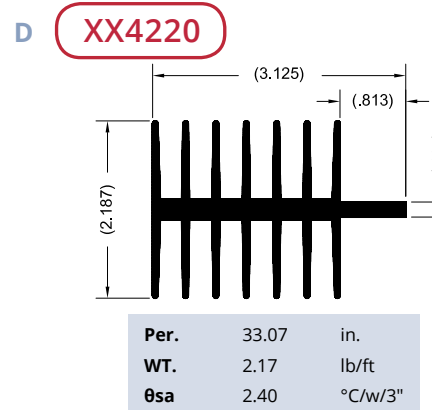
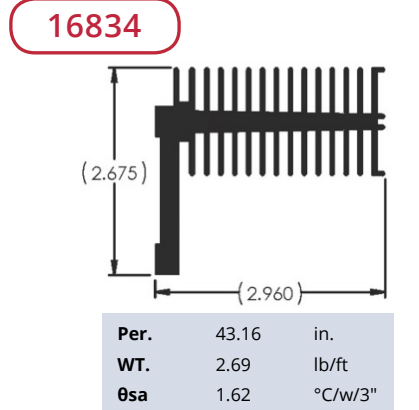
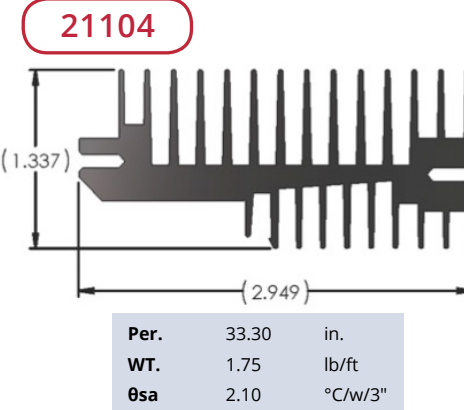
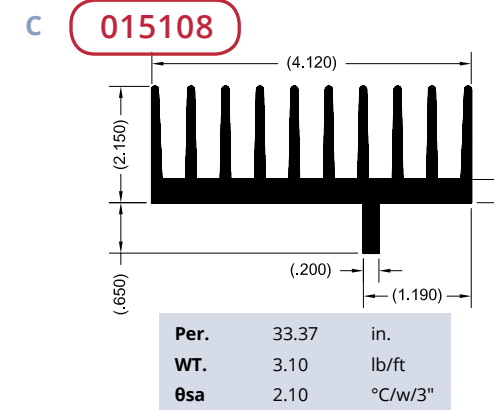
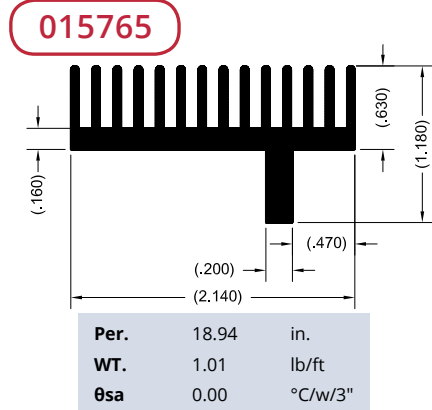
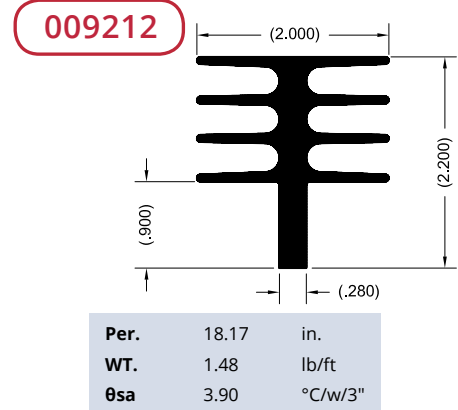
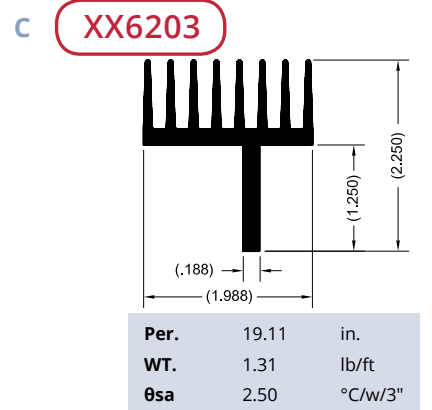
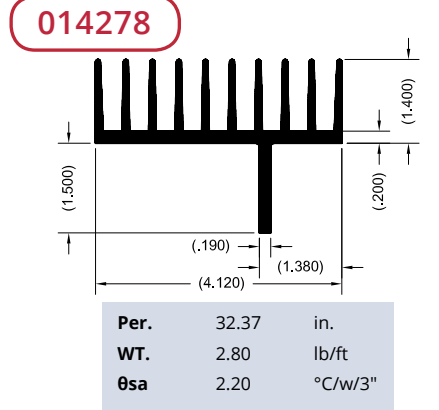
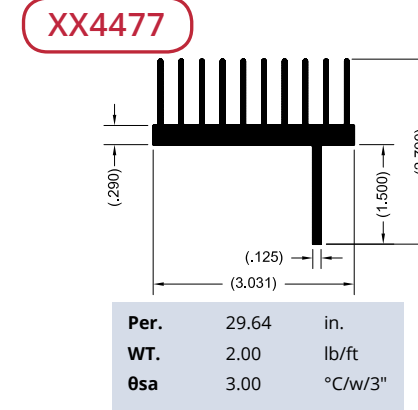
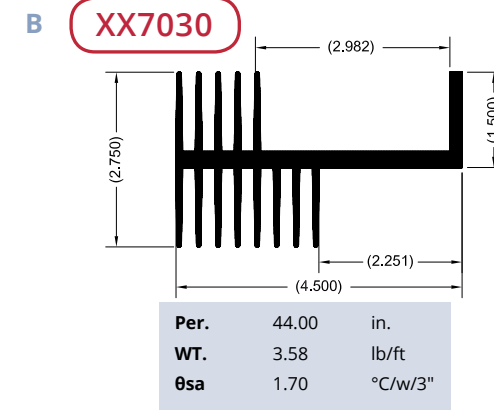
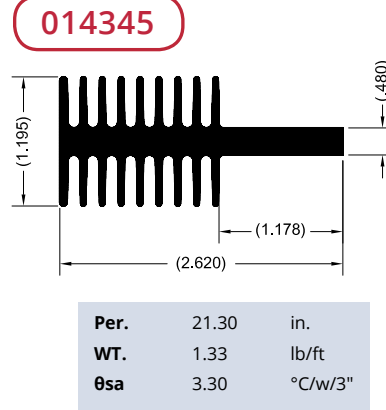
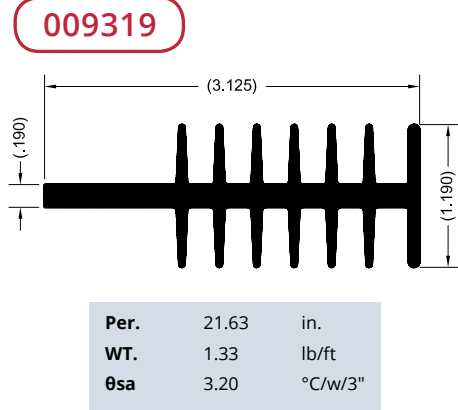
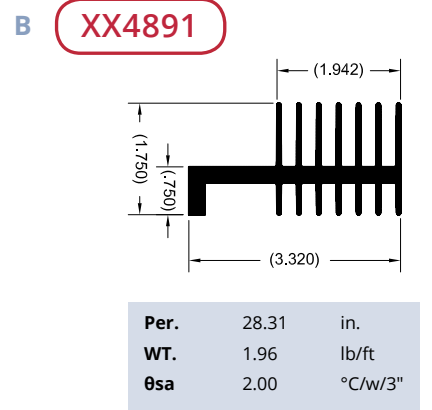
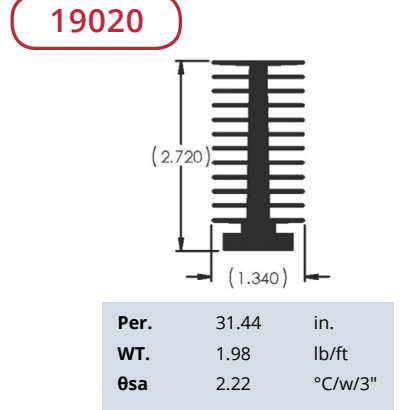
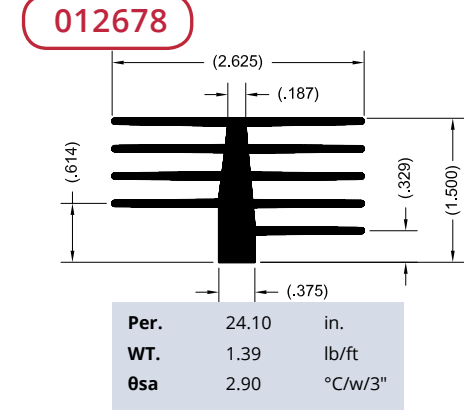
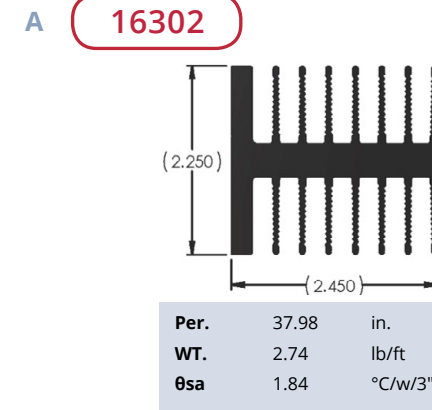
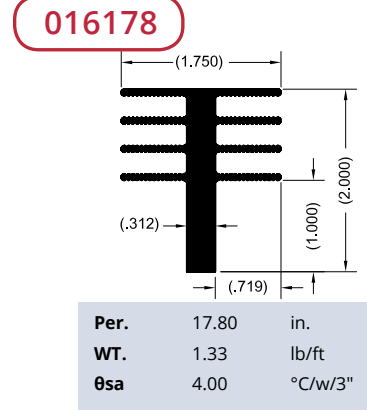
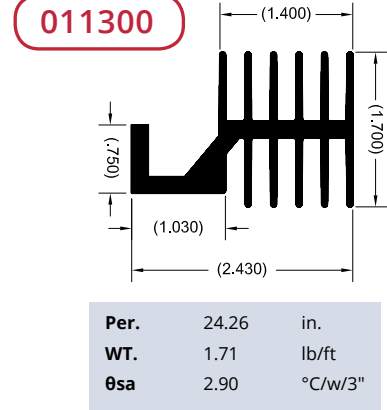
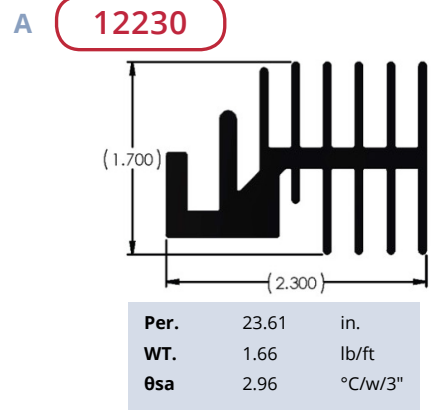


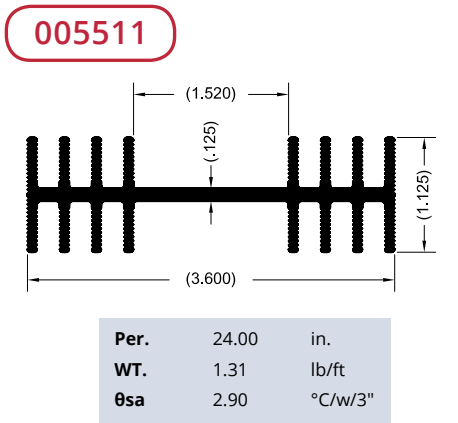
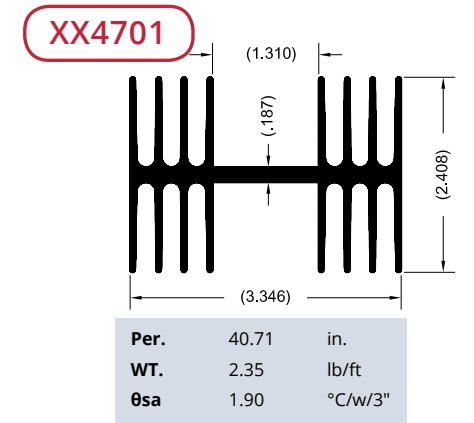
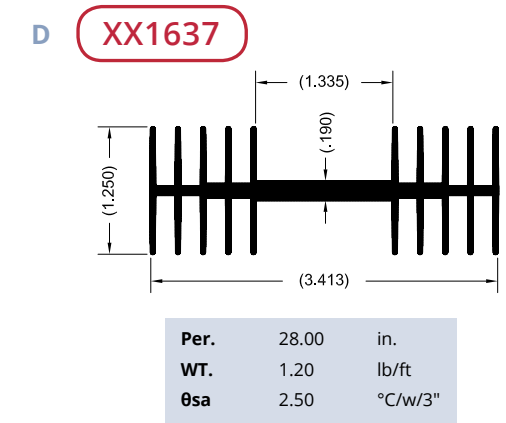
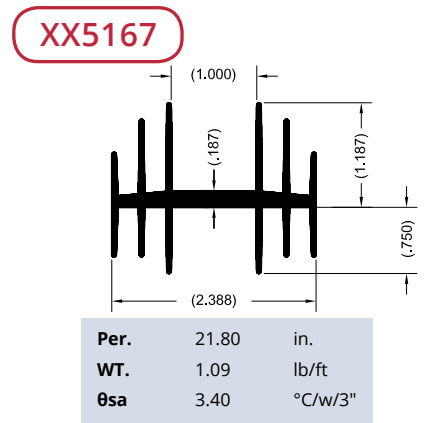
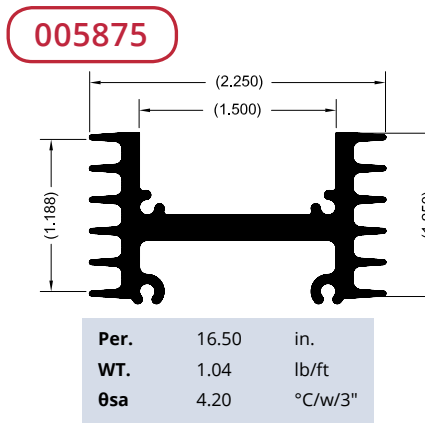
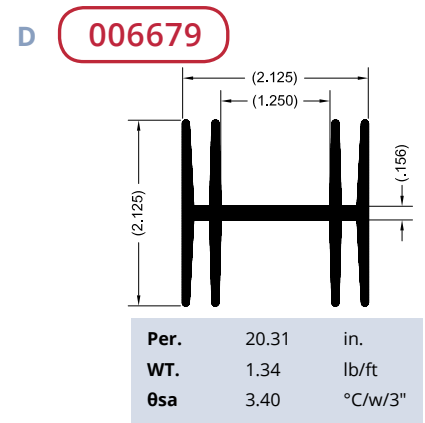
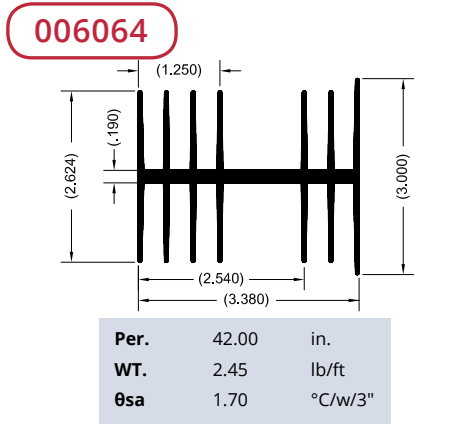
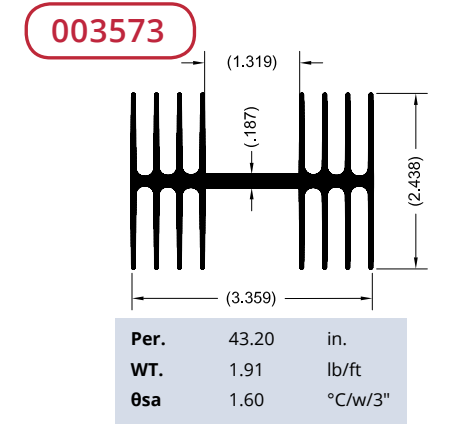
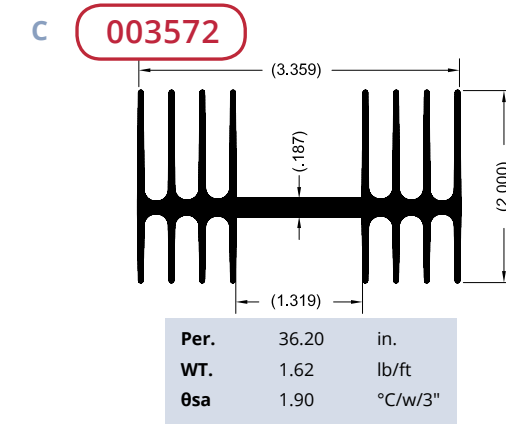
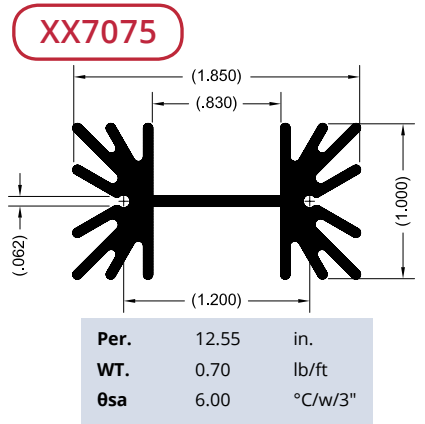
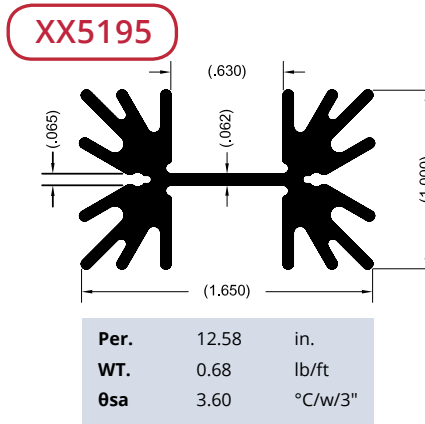
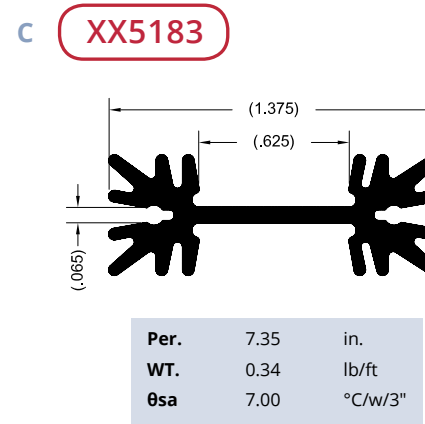
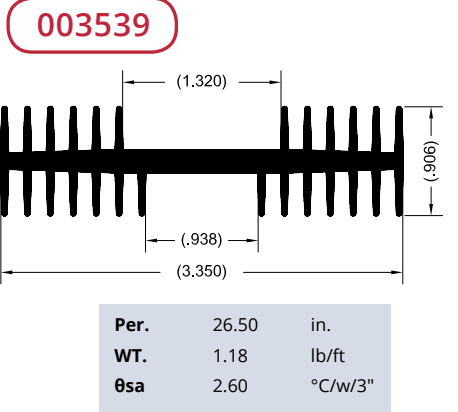
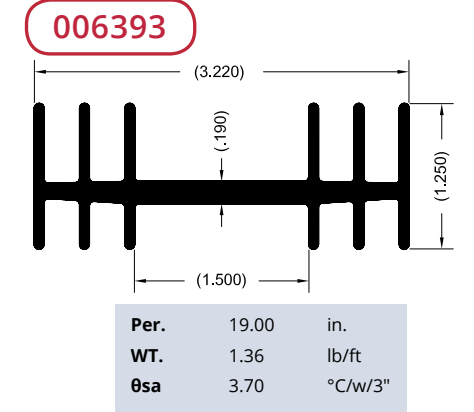
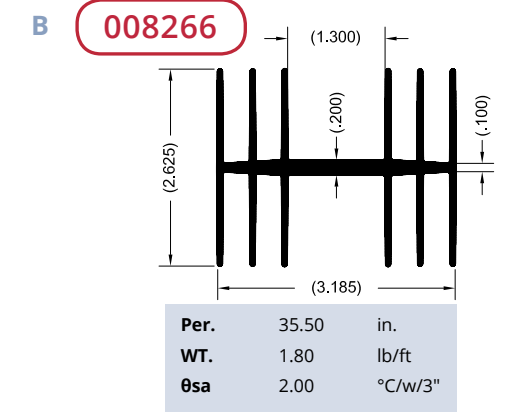
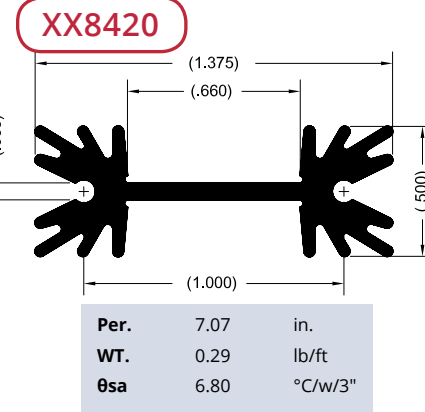
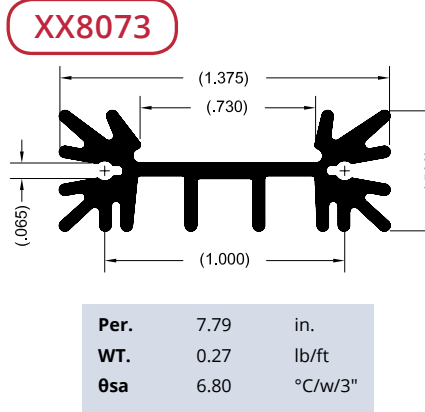
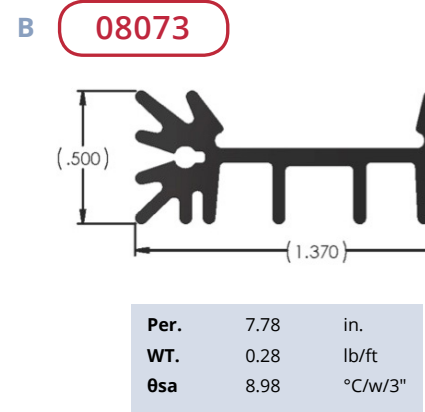
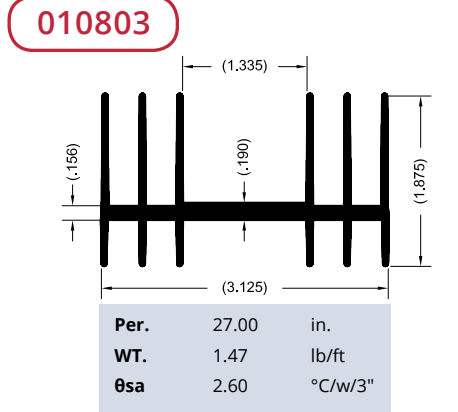
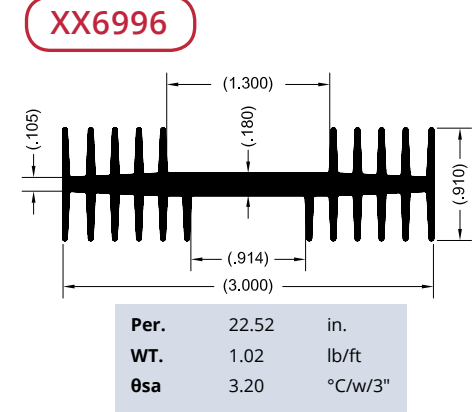
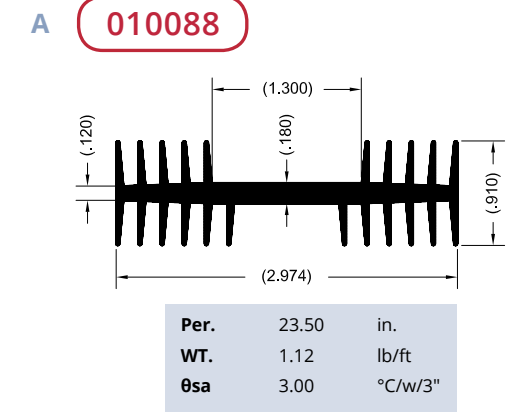
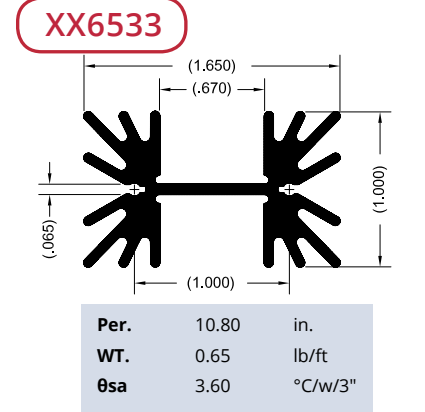
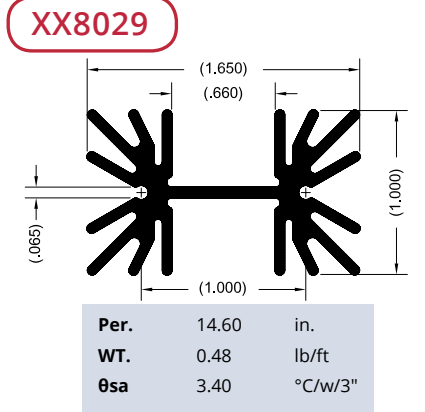
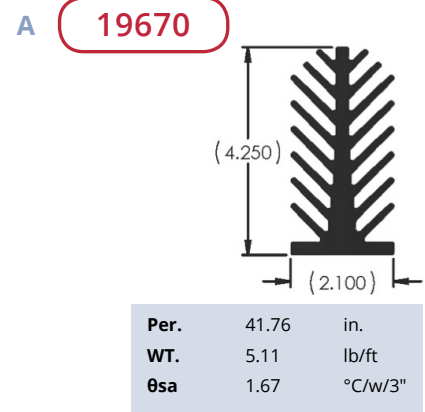
Per.	18.01	in.
WT.	1.14	lb/ft
θsa	3.88	°C/w/3"

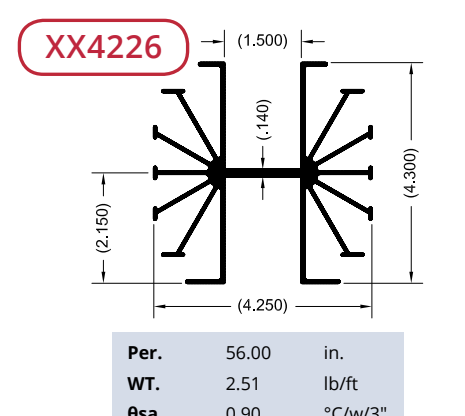
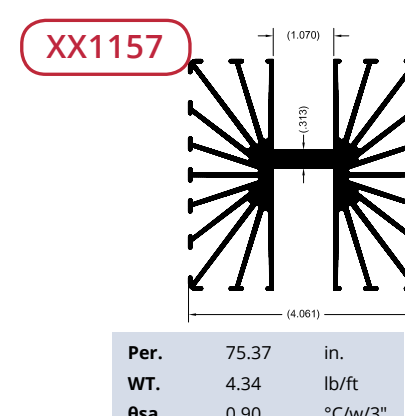
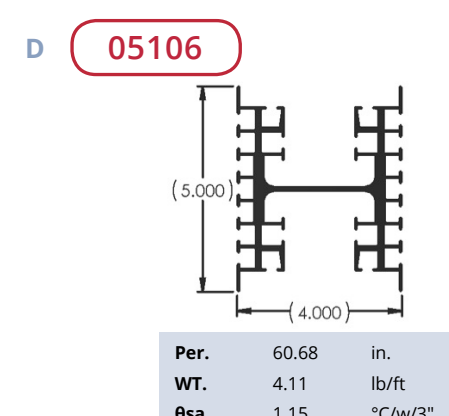
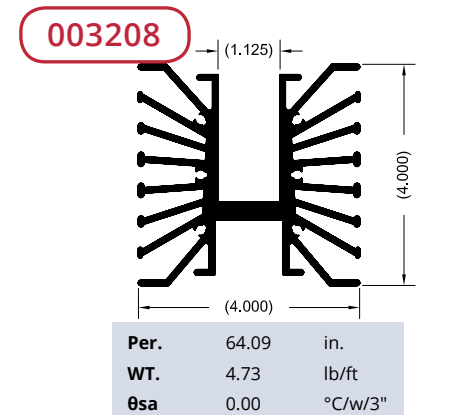
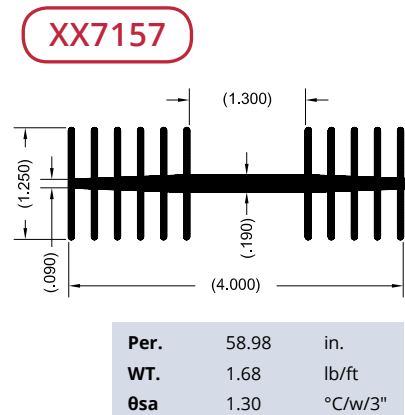
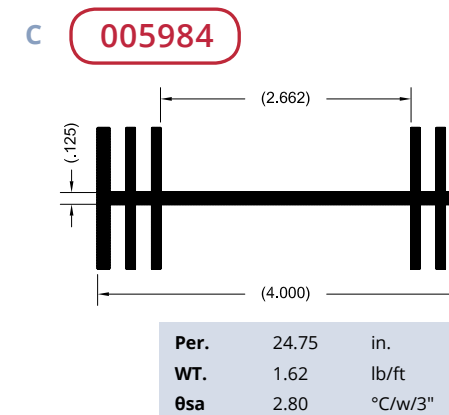
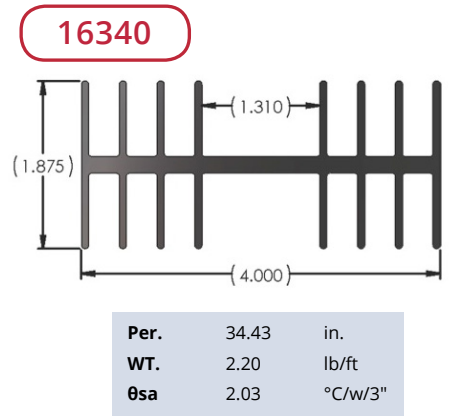
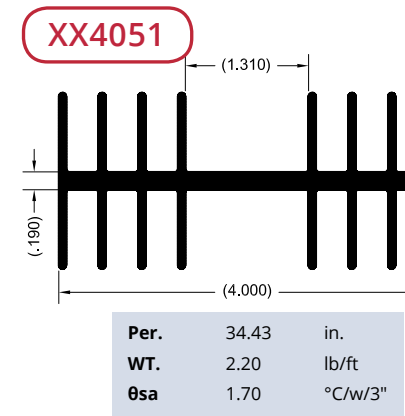
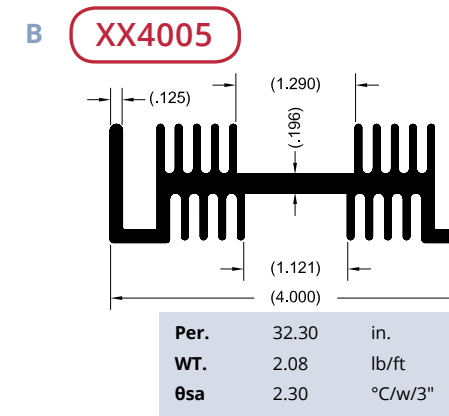
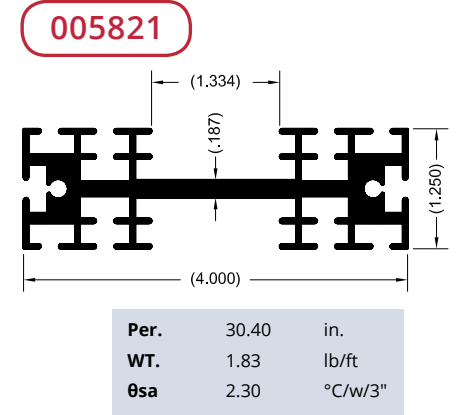
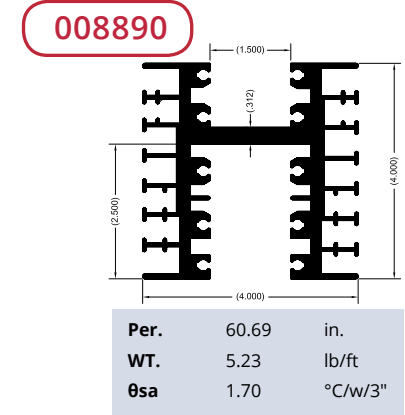
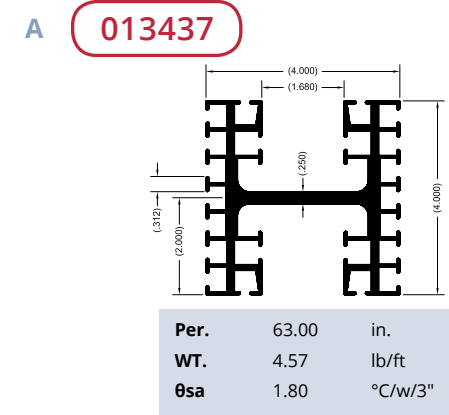
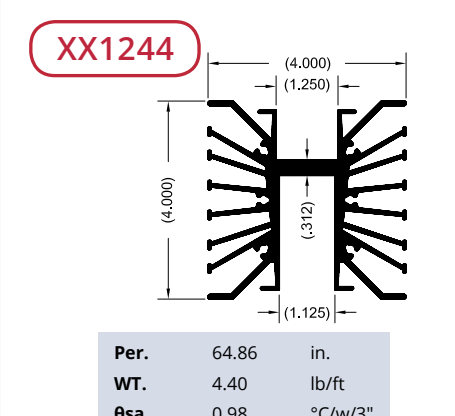
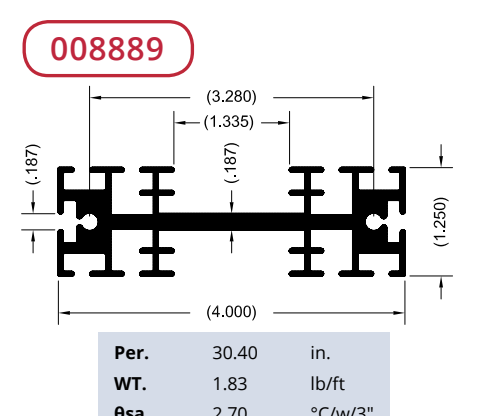
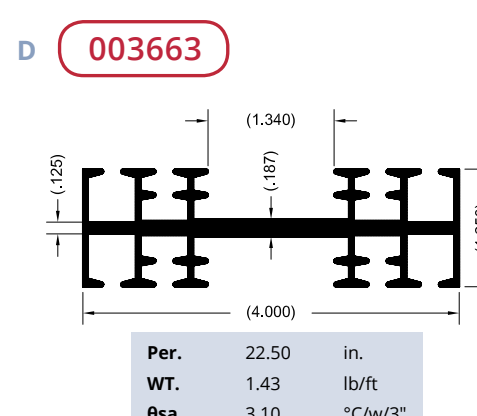
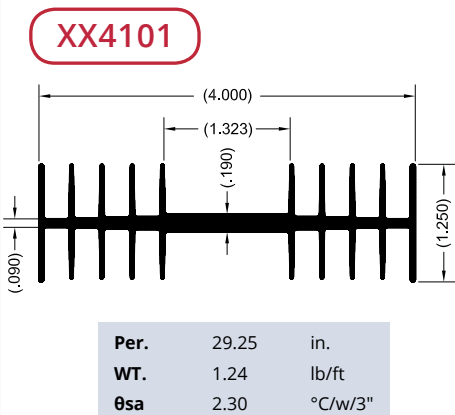
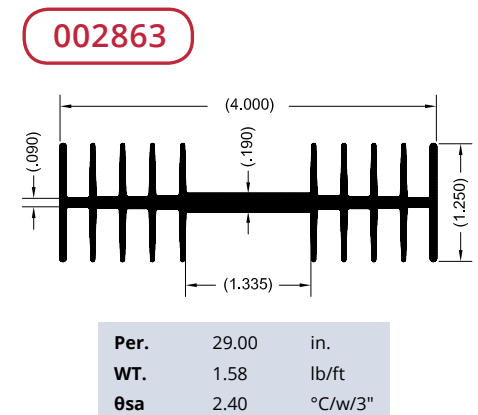
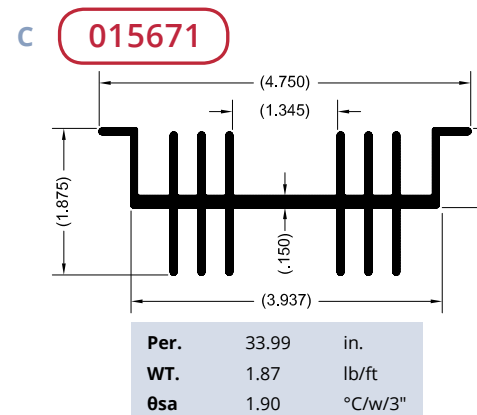
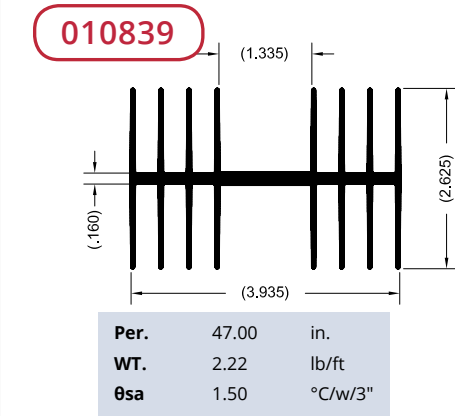
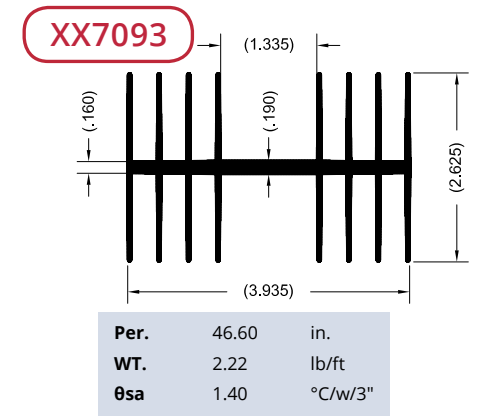
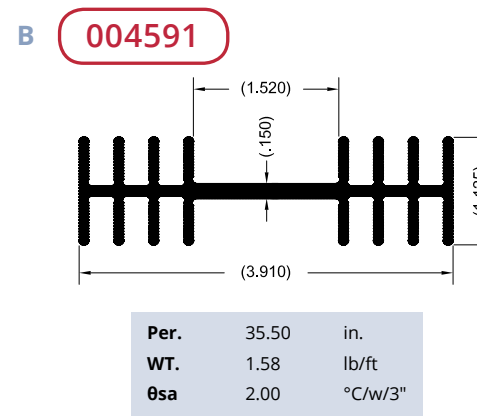
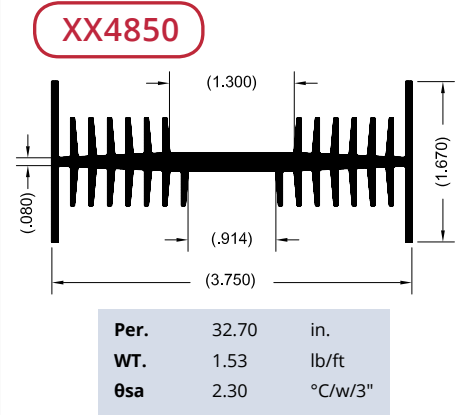
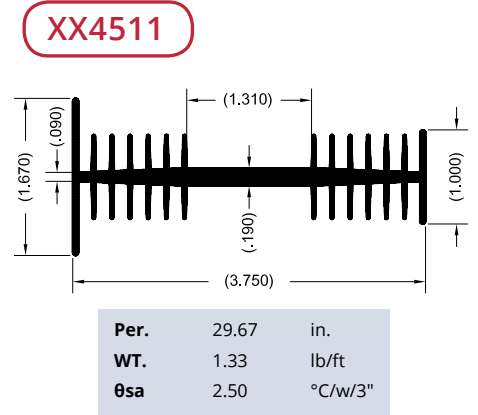
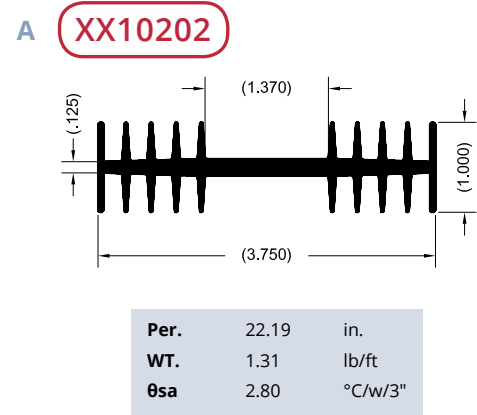


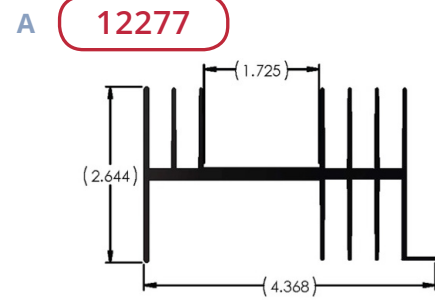
Per.	21.10	in.
WT.	1.23	lb/ft
θsa	3.31	°C/w/3"



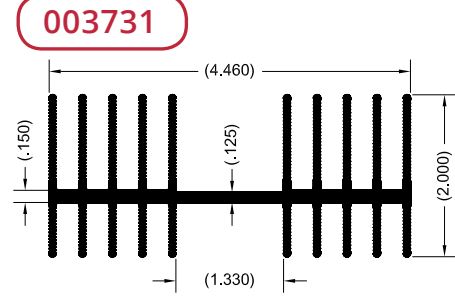




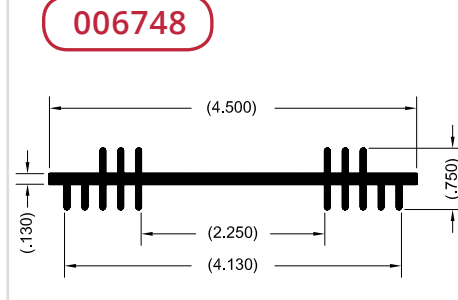




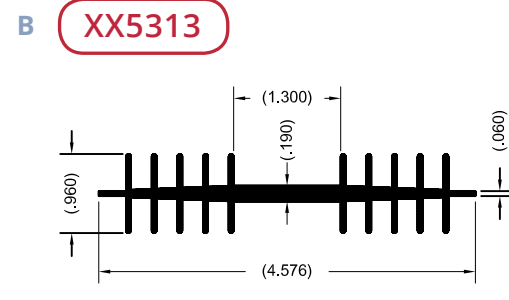
Per.	37.73	in.
WT.	1.96	lb/ft
θsa	1.85	°C/w/3"



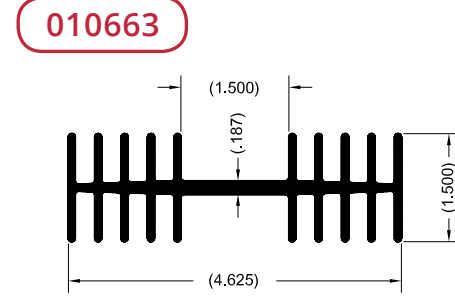
Per.	43.50	in.
WT.	2.22	lb/ft
θsa	1.60	°C/w/3"



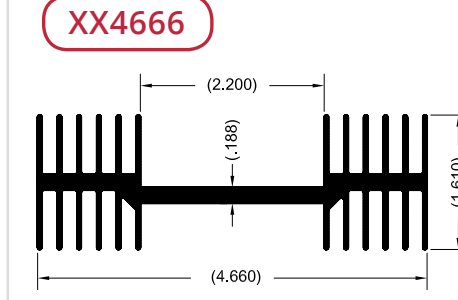
Per.	21.66	in.
WT.	1.15	lb/ft
θsa	3.20	°C/w/3"



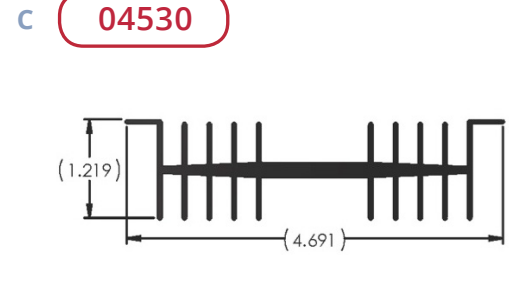
Per.	25.98	in.
WT.	1.40	lb/ft
θsa	3.30	°C/w/3"



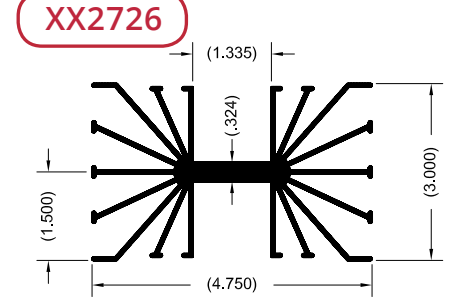
Per.	34.75	in.
WT.	2.27	lb/ft
θsa	2.00	°C/w/3"



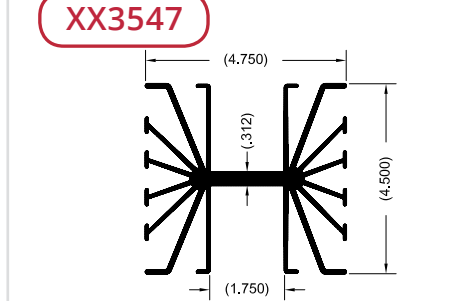
Per.	41.71	in.
WT.	2.48	lb/ft
θsa	2.10	°C/w/3"



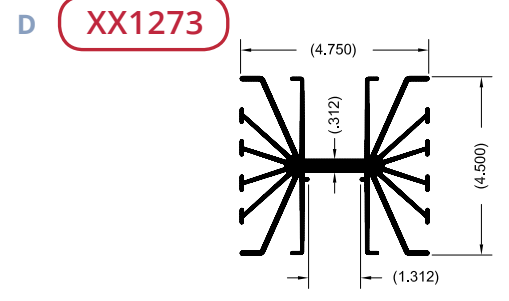
Per.	30.59	in.
WT.	1.59	lb/ft
θsa	2.29	°C/w/3"



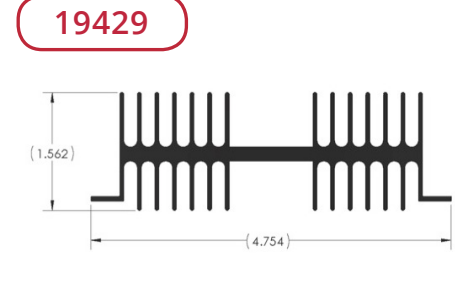
Per.	65.31	in.
WT.	2.93	lb/ft
θsa	1.10	°C/w/3"



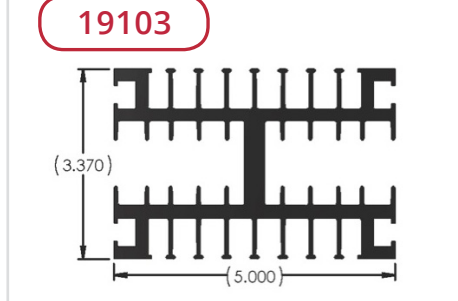
Per.	69.74	in.
WT.	4.10	lb/ft
θsa	0.80	°C/w/3"



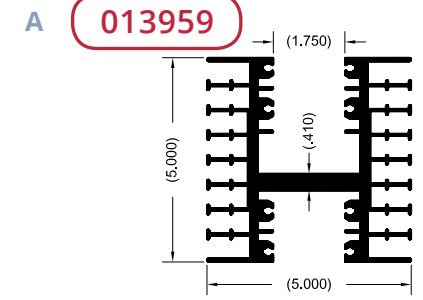
Per.	71.36	in.
WT.	4.11	lb/ft
θsa	0.80	°C/w/3"



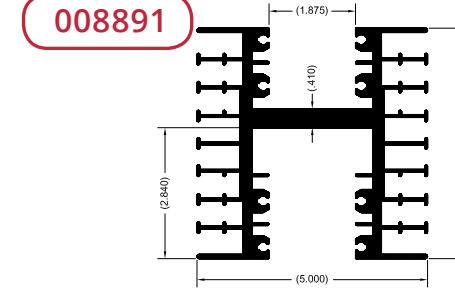
Per.	45.39	in.
WT.	2.19	lb/ft
θsa	1.54	°C/w/3"



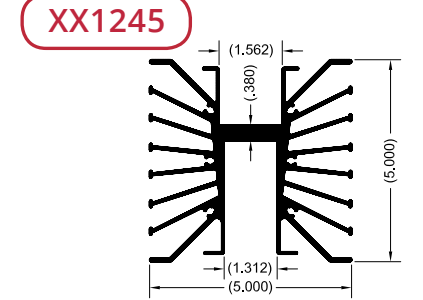
Per.	67.45	in.
WT.	5.99	lb/ft
θsa	1.04	°C/w/3"



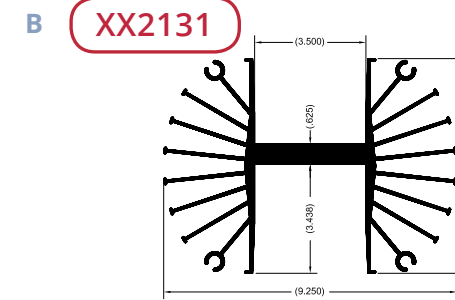
Per.	71.00	in.
WT.	7.91	lb/ft
θsa	1.00	°C/w/3"



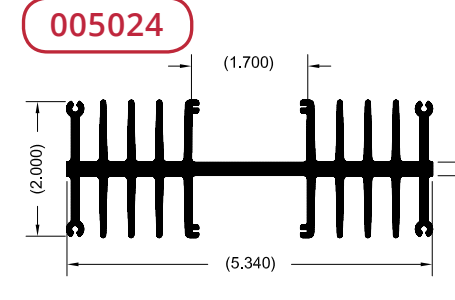
Per.	82.64	in.
WT.	7.23	lb/ft
θsa	1.40	°C/w/3"



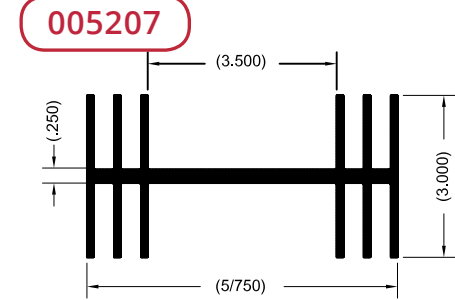
Per.	81.91	in.
WT.	5.16	lb/ft
θsa	0.72	°C/w/3"



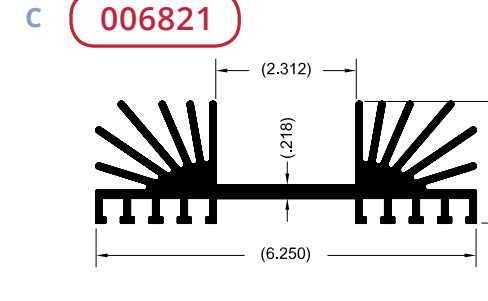
Per.	118.25	in.
WT.	9.60	lb/ft
θsa	0.40	°C/w/3"



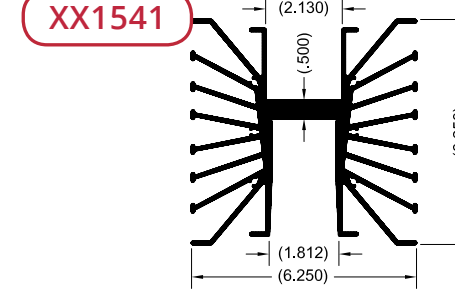
Per.	51.75	in.
WT.	3.23	lb/ft
θsa	1.40	°C/w/3"



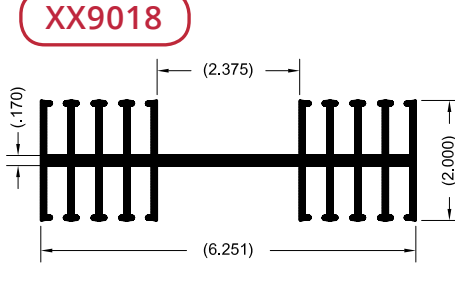
Per.	45.00	in.
WT.	4.20	lb/ft
θsa	1.60	°C/w/3"



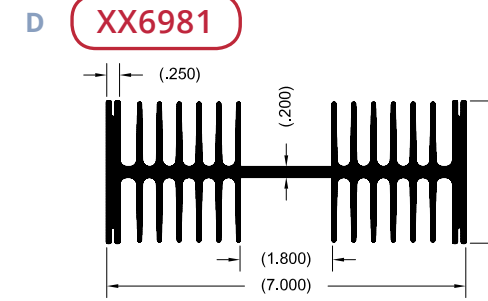
Per.	49.70	in.
WT.	4.50	lb/ft
θsa	1.40	°C/w/3"



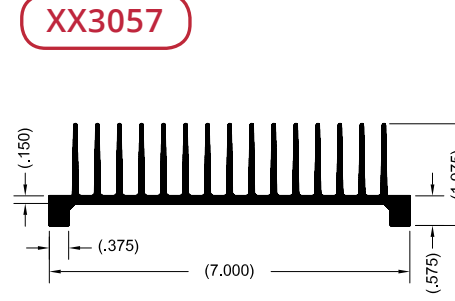
Per.	102.77	in.
WT.	7.54	lb/ft
θsa	0.59	°C/w/3"



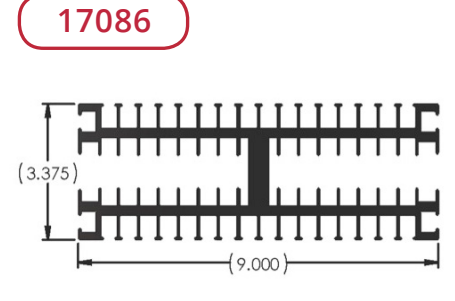
Per.	53.10	in.
WT.	3.49	lb/ft
θsa	1.40	°C/w/3"



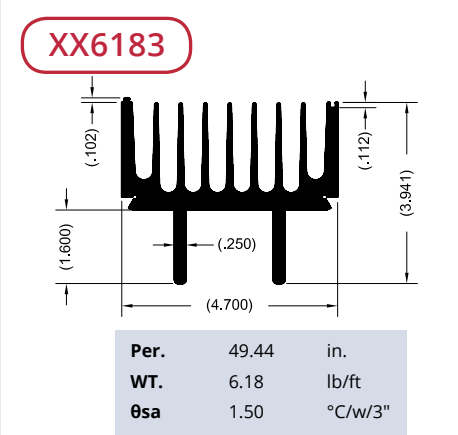
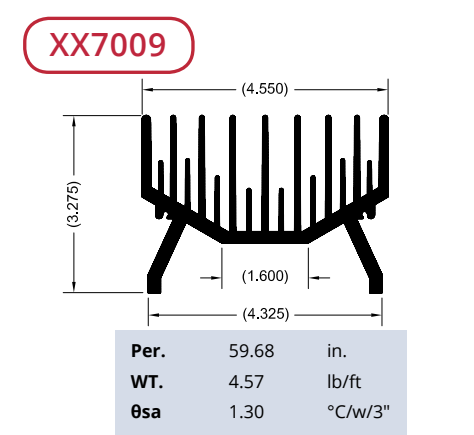
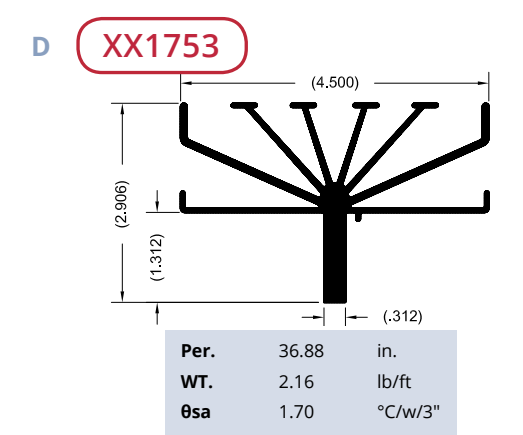
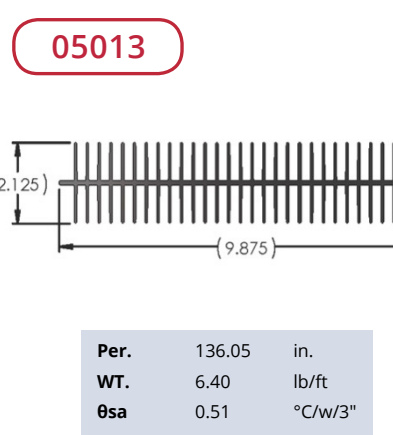
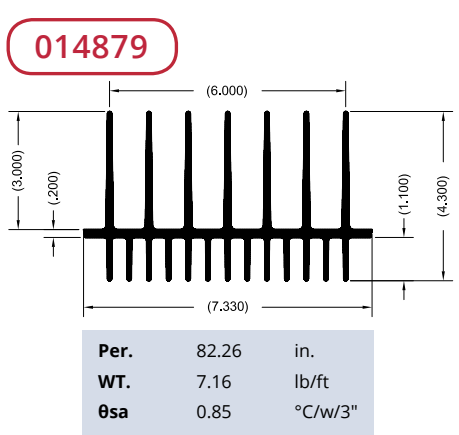
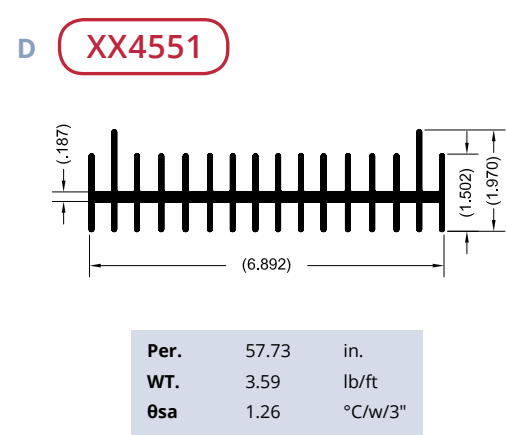
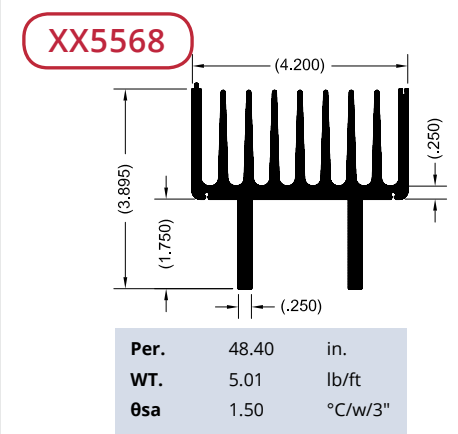
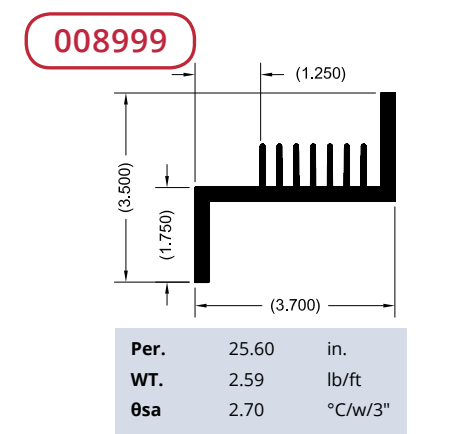
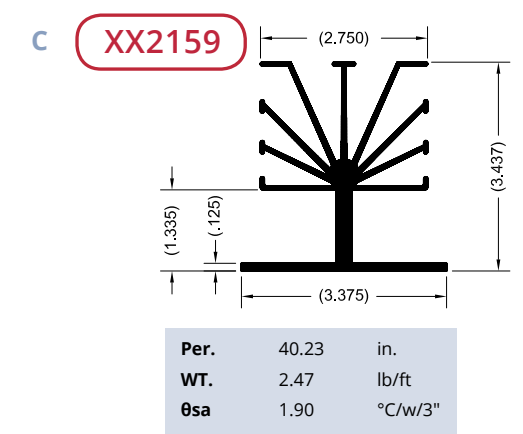
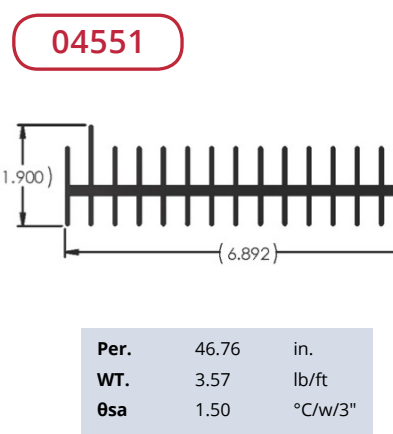
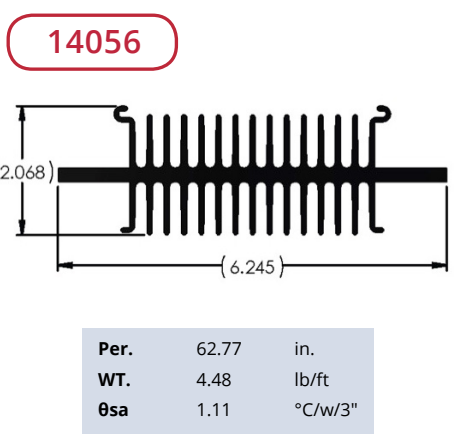
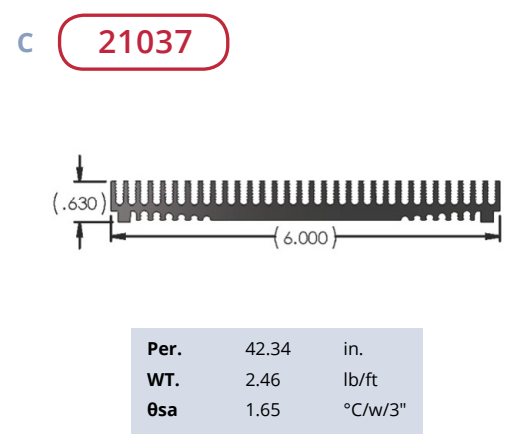
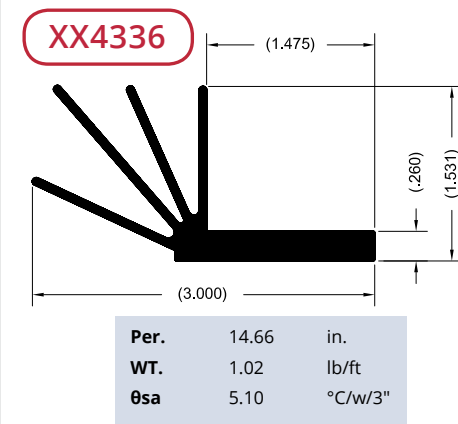
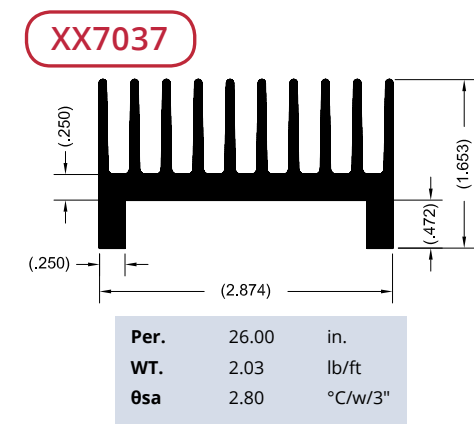
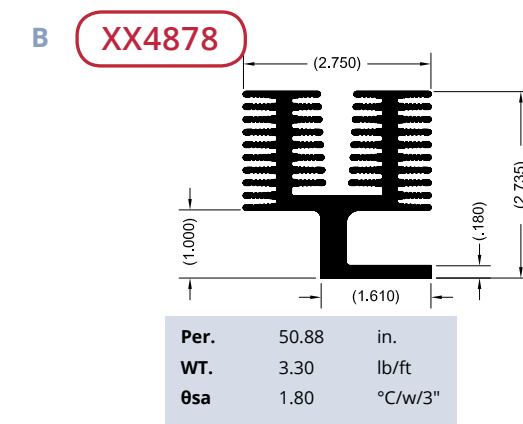
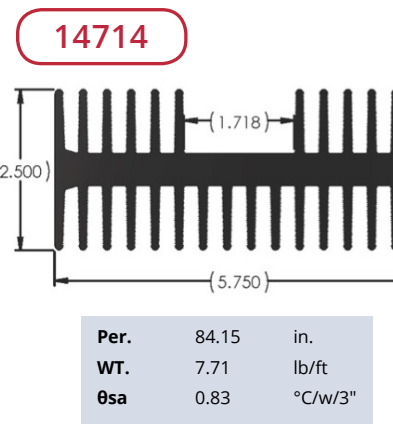
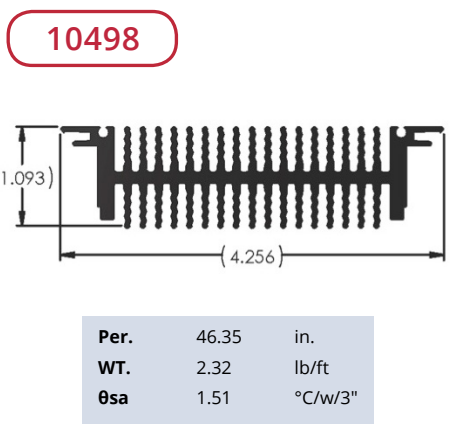
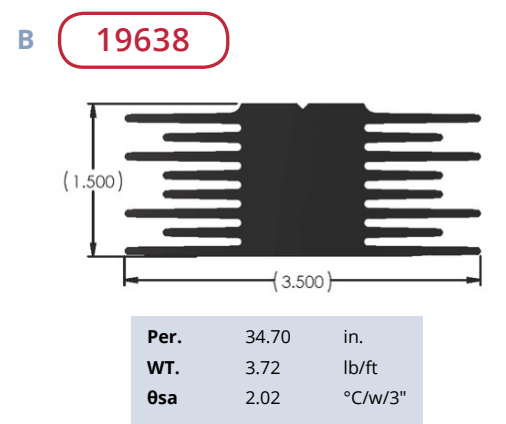
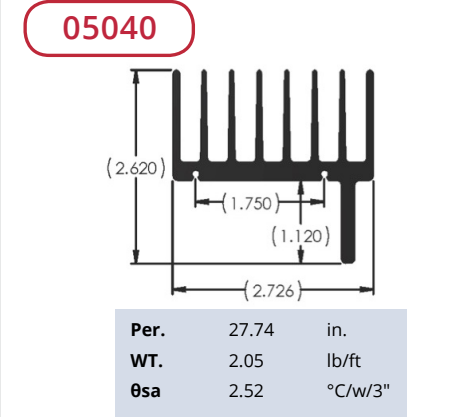
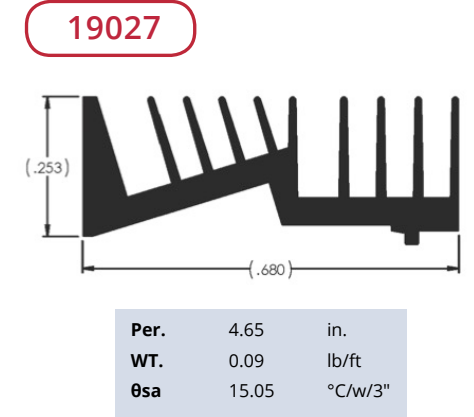
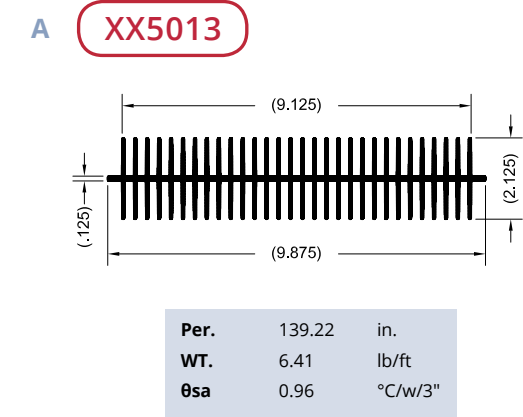
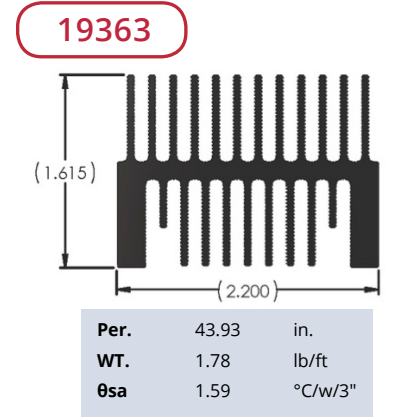
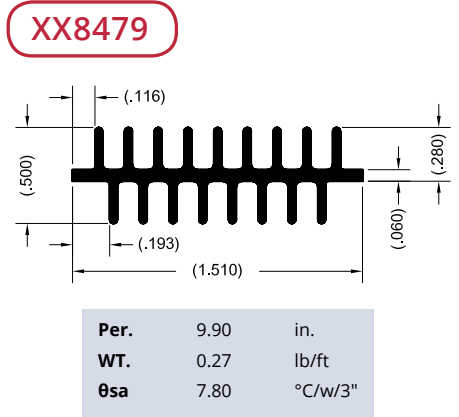
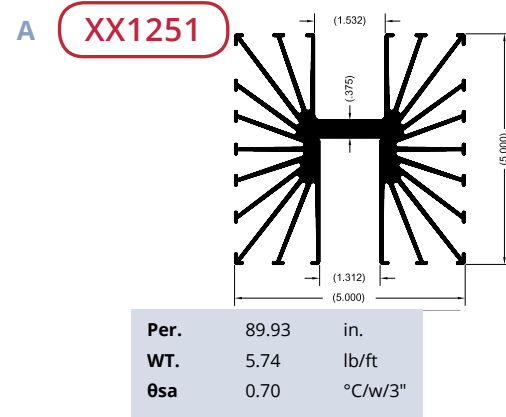
Per.	82.00	in.
WT.	6.08	lb/ft
θsa	1.00	°C/w/3"

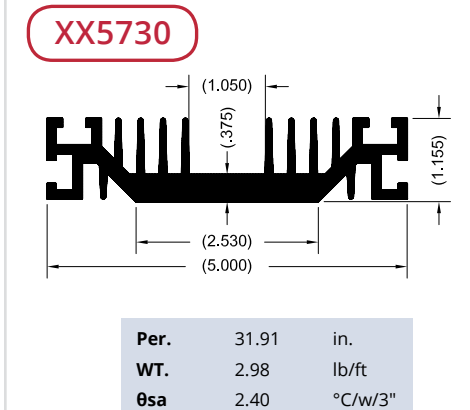
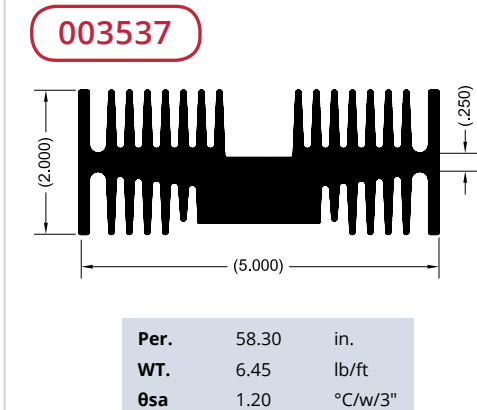
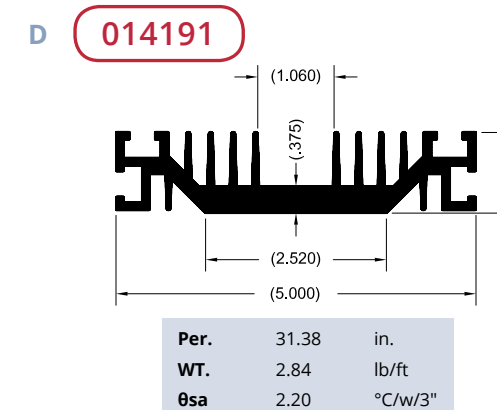
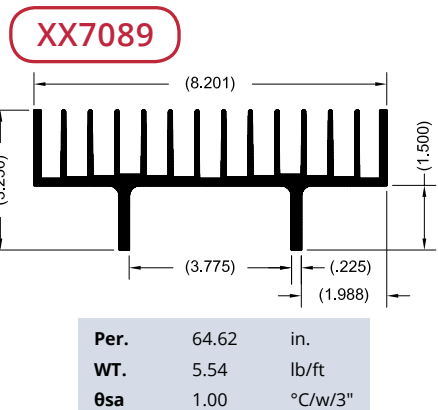
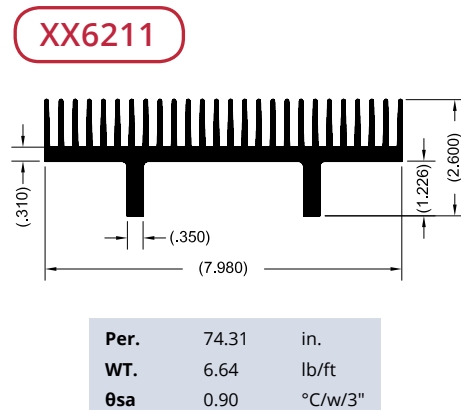
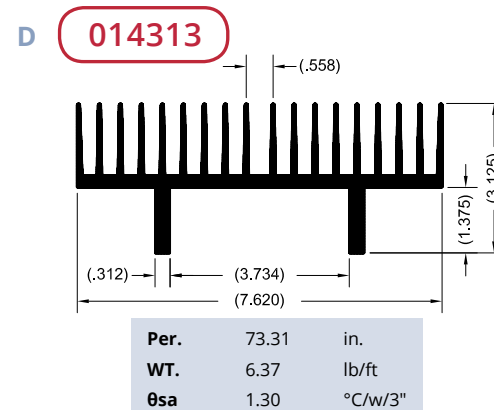
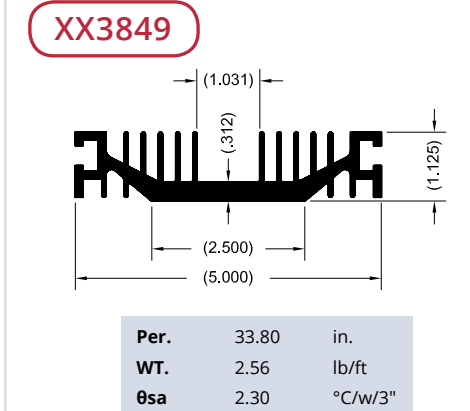
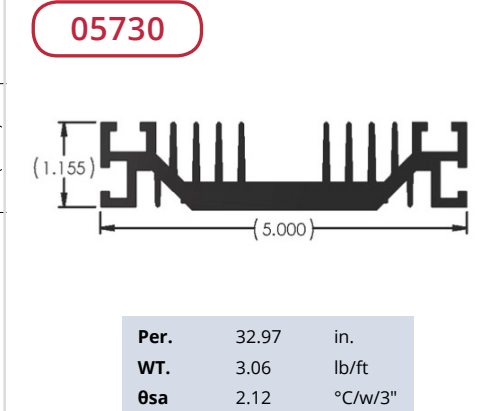
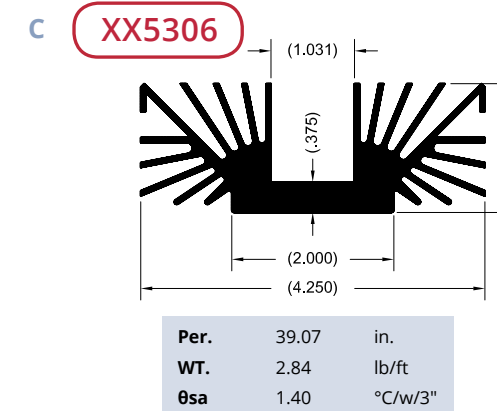
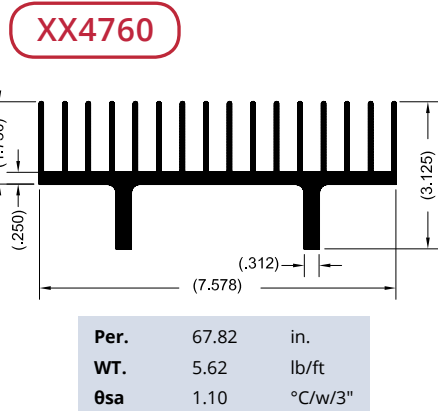
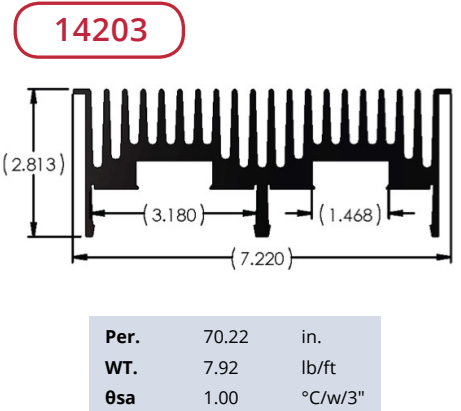
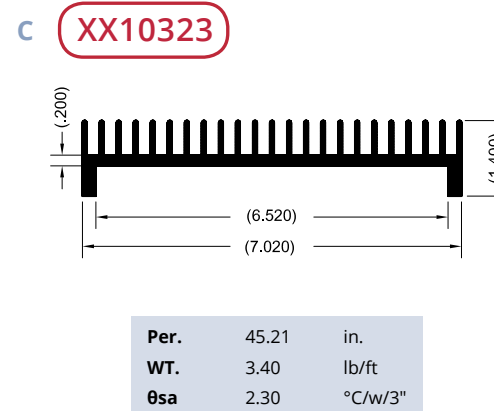
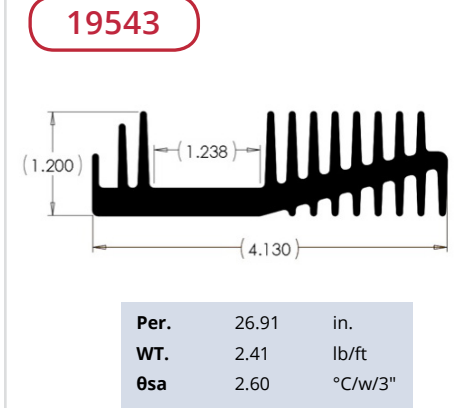
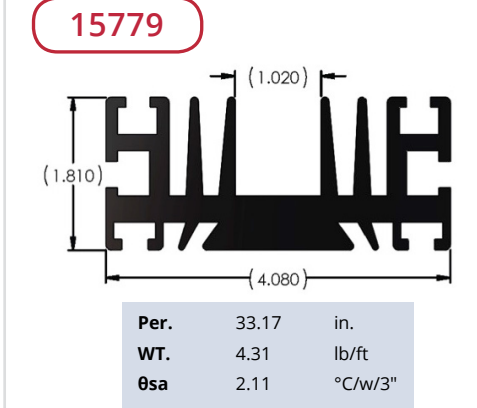
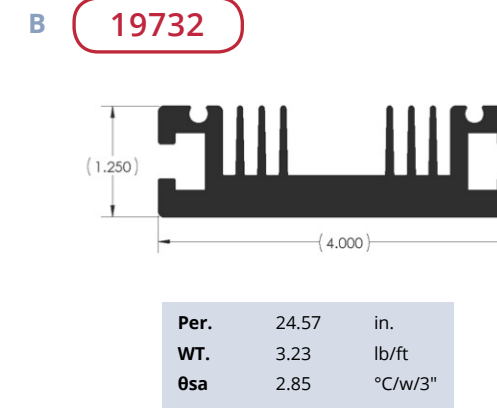
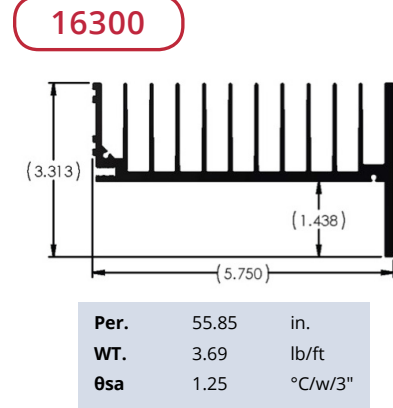
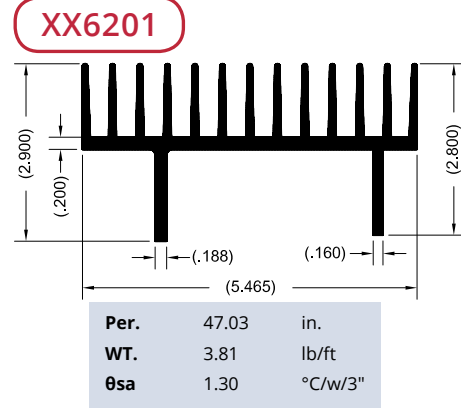
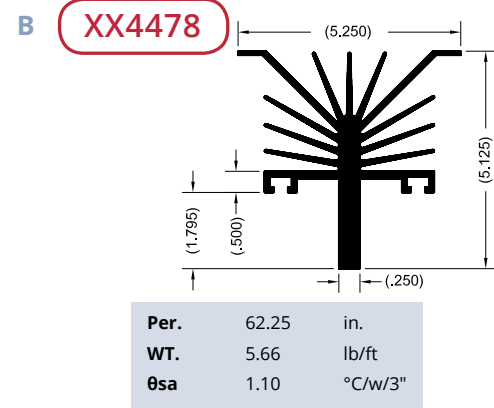
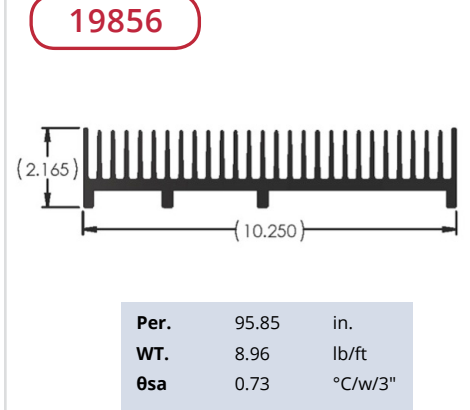
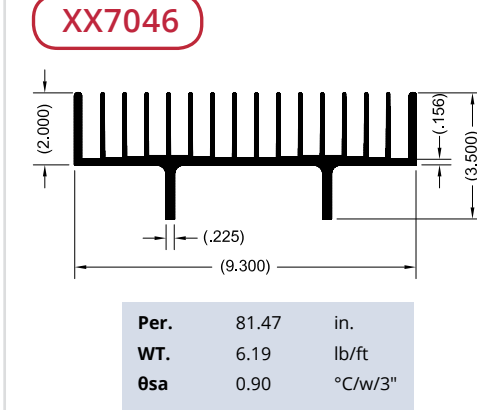
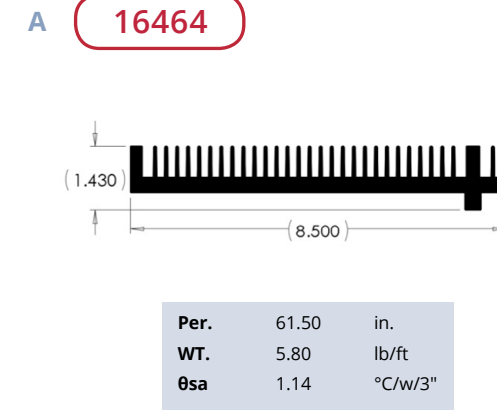
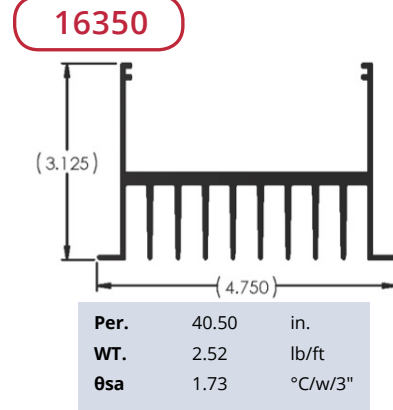
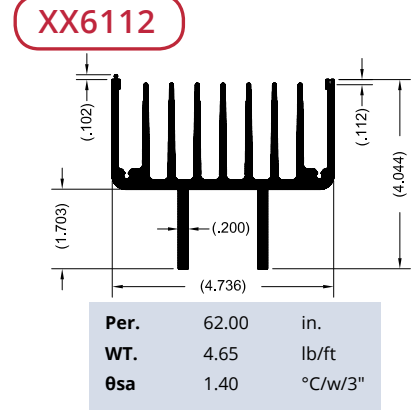
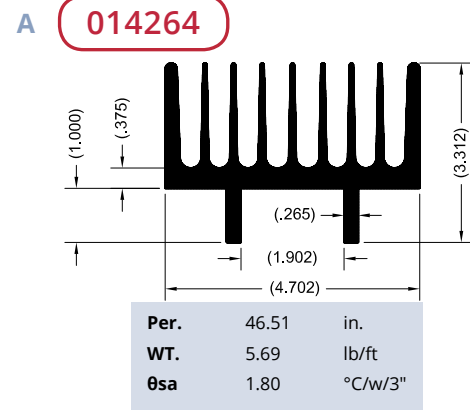


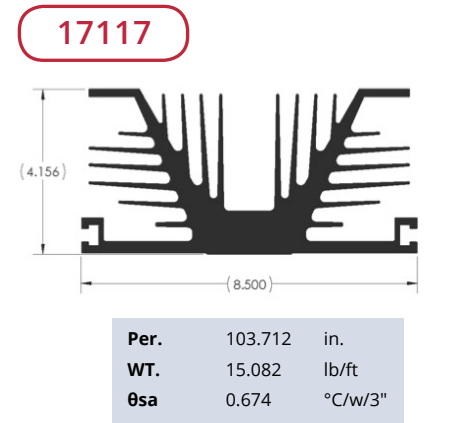
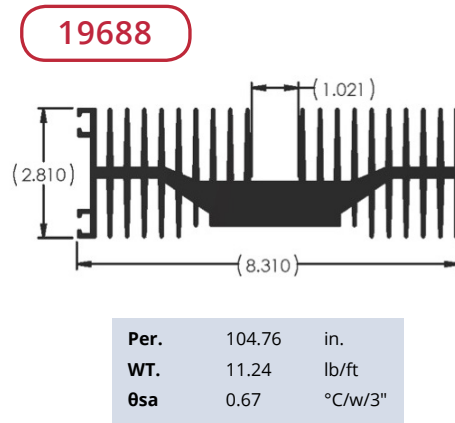
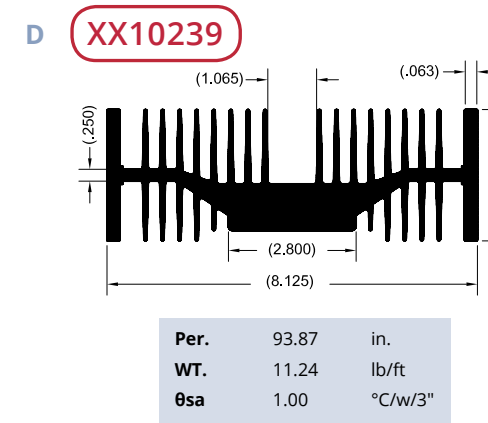
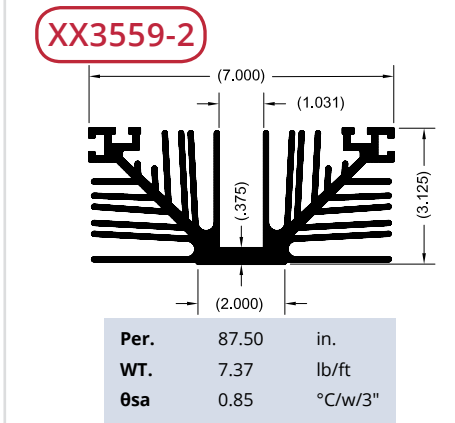
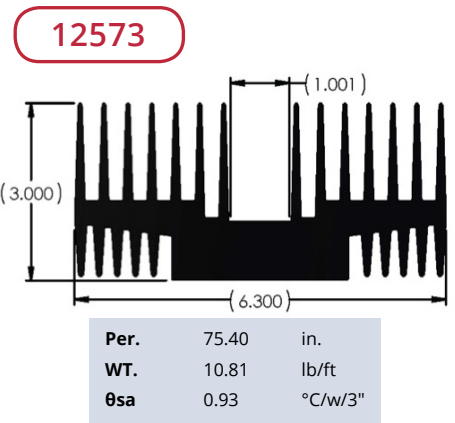
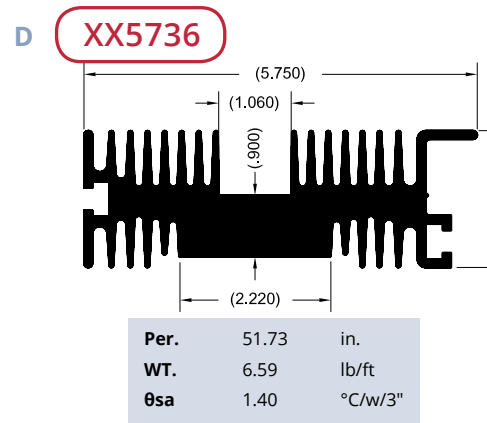
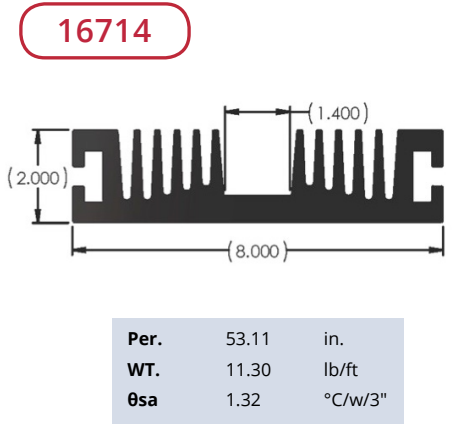
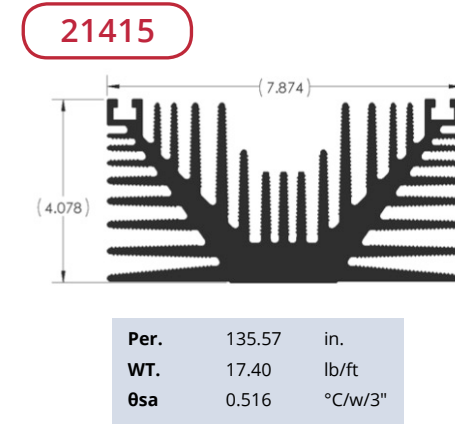
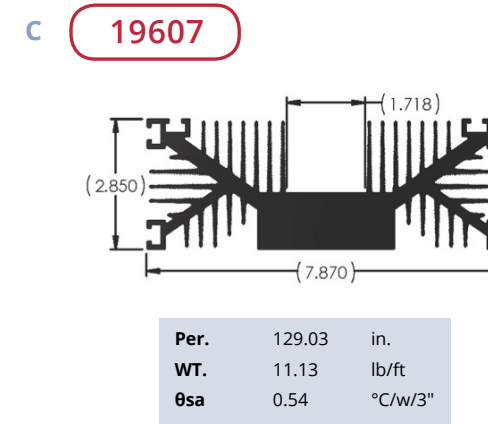
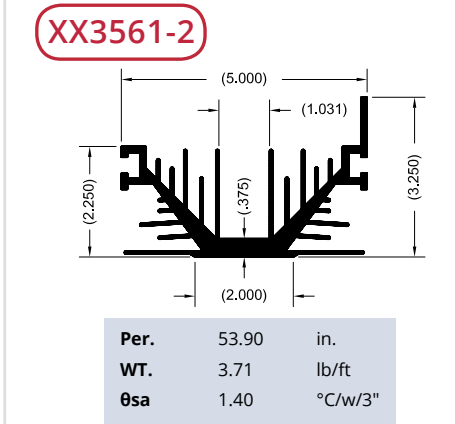
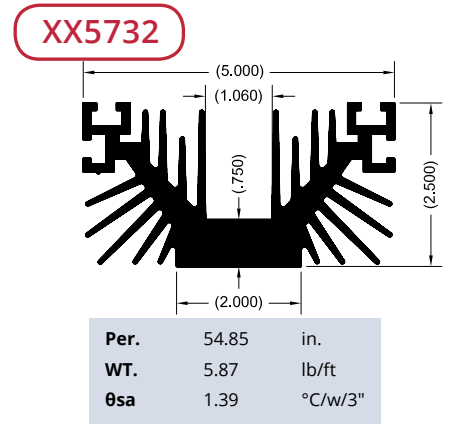
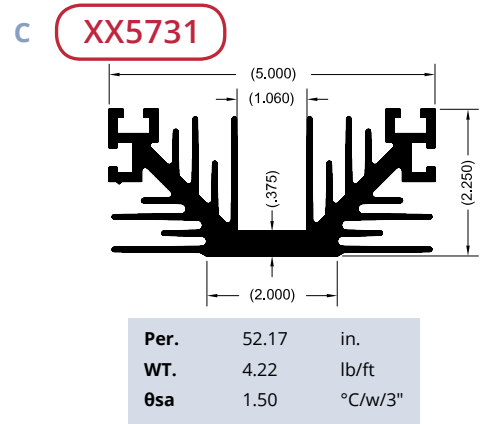
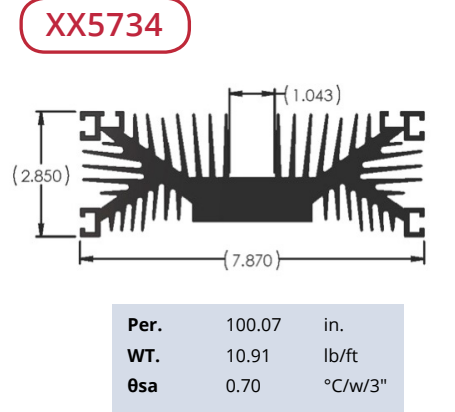
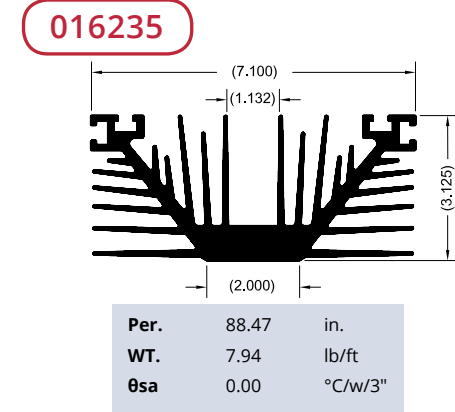
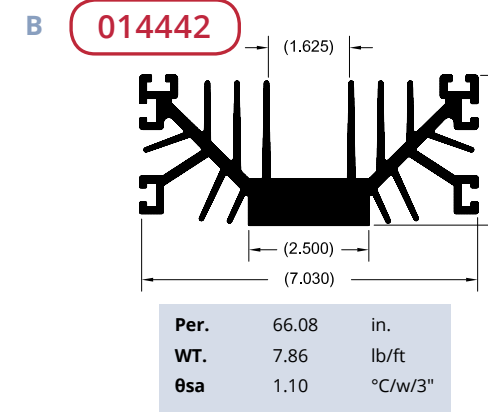
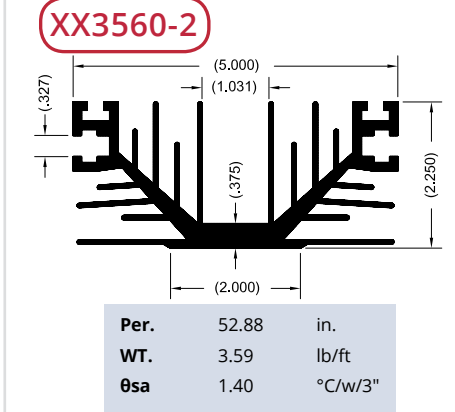
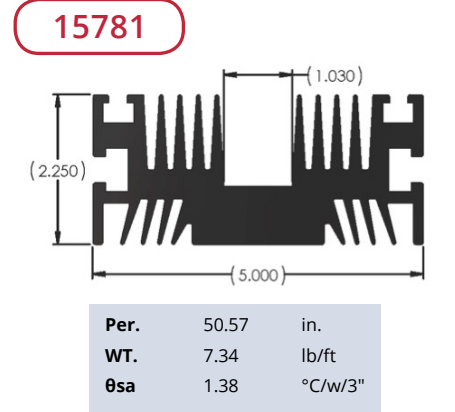
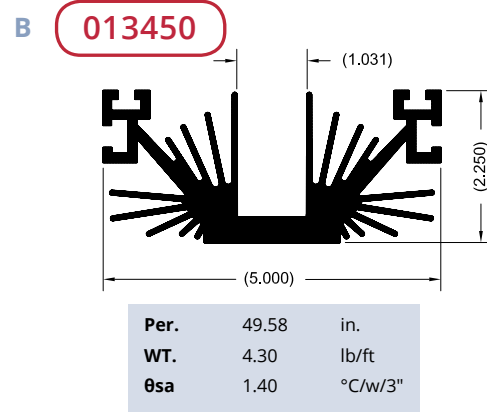
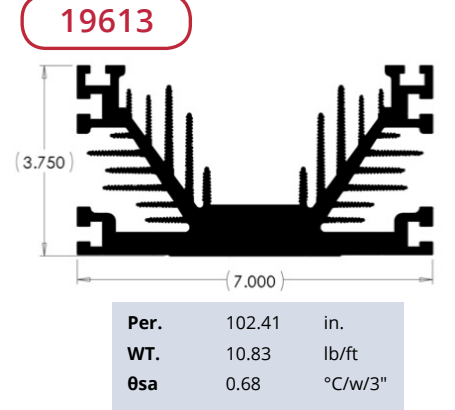
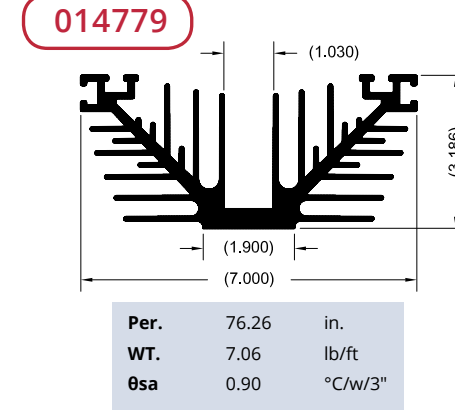
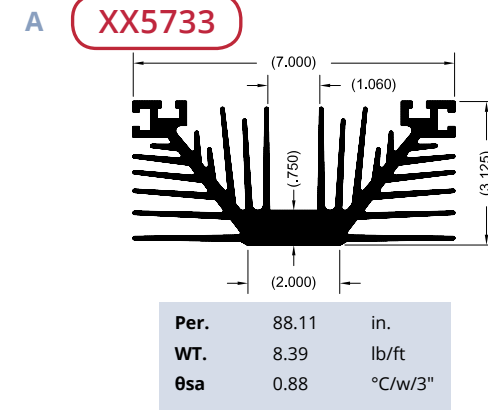
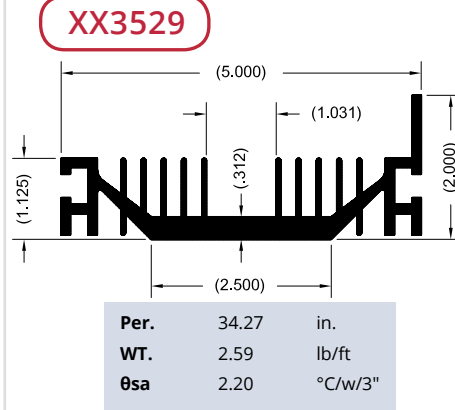
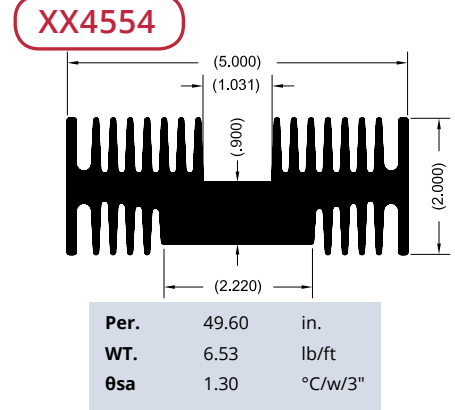
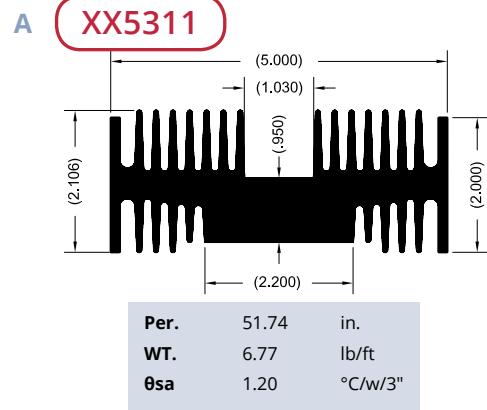
Per.	56.08	in.
WT.	3.56	lb/ft
θsa	1.40	°C/w/3"

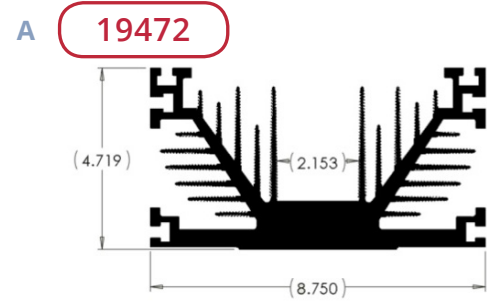


Per.	119.05	in.
WT.	9.74	lb/ft
θsa	0.59	°C/w/3"

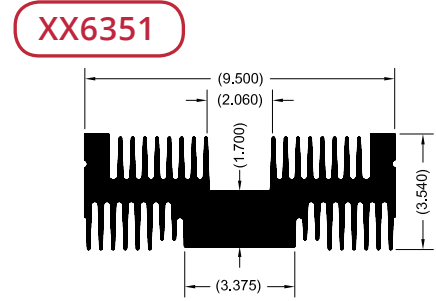




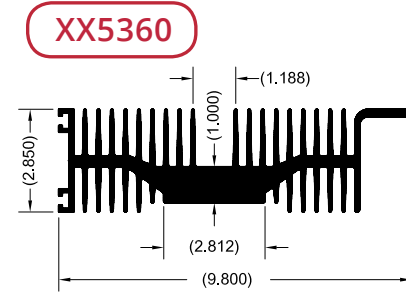




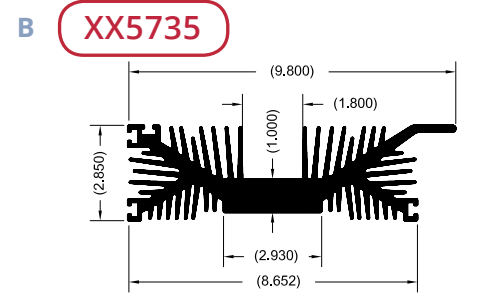
Per. 143.25 in.  
WT. 15.91 lb/ft  
θsa 0.49 °C/w/3"



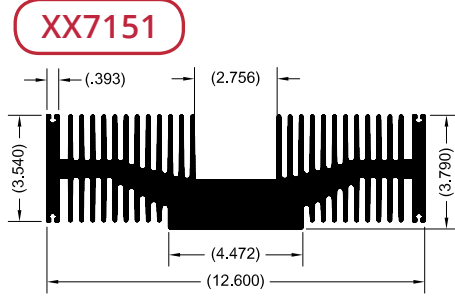
Per. 104.67 in.  
WT. 21.45 lb/ft  
θsa 0.70 °C/w/3"



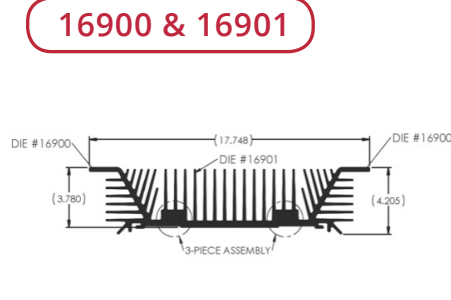
Per. 106.79 in.  
WT. 11.00 lb/ft  
θsa 0.74 °C/w/3"



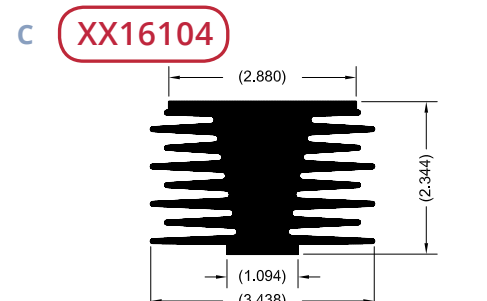
Per. 104.86 in.  
WT. 12.80 lb/ft  
θsa 0.71 °C/w/3"



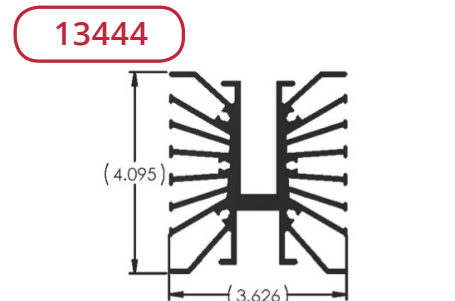
Per. 163.33 in.  
WT. 25.62 lb/ft  
θsa 0.55 °C/w/3"



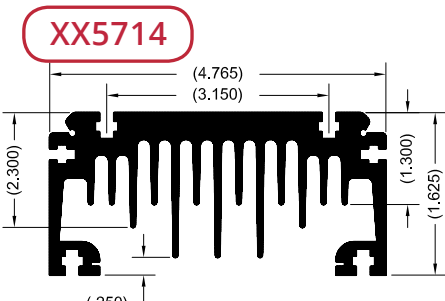
Per. 206.98 in.  
WT. 24.10 lb/ft  
θsa 0.34 °C/w/3"



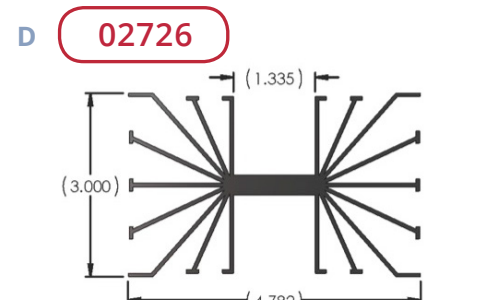
Per. 37.97 in.  
WT. 5.52 lb/ft  
θsa 2.10 °C/w/3"



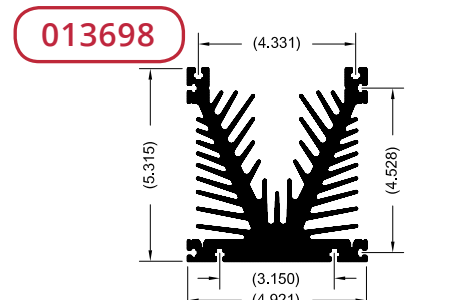
Per. 63.79 in.  
WT. 4.73 lb/ft  
θsa 1.10 °C/w/3"



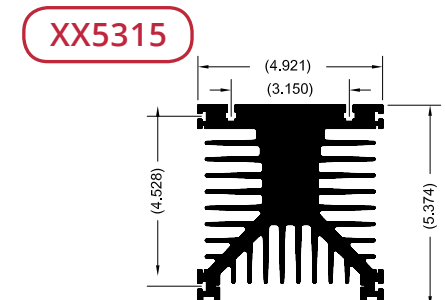
Per. 50.30 in.  
WT. 5.38 lb/ft  
θsa 1.40 °C/w/3"



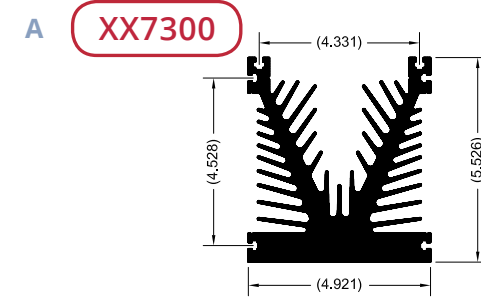
Per. 66.36 in.  
WT. 2.88 lb/ft  
θsa 1.05 °C/w/3"



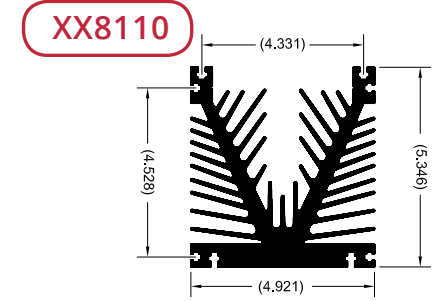
Per. 92.26 in.  
WT. 10.99 lb/ft  
θsa 0.80 °C/w/3"



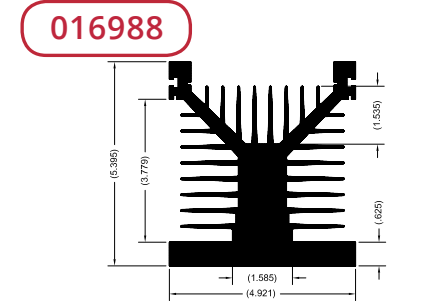
Per. 90.05 in.  
WT. 12.84 lb/ft  
θsa 0.80 °C/w/3"



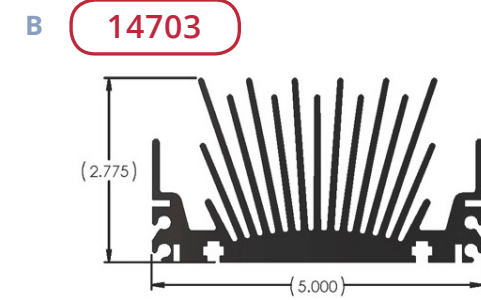
Per. 88.85 in.  
WT. 12.31 lb/ft  
θsa 0.88 °C/w/3"



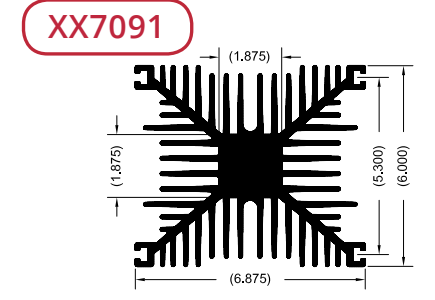
Per. 97.96 in.  
WT. 11.45 lb/ft  
θsa 0.80 °C/w/3"



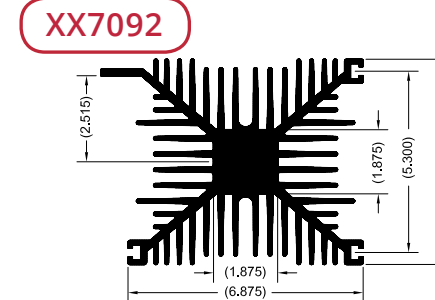
Per. 85.21 in.  
WT. 13.30 lb/ft  
θsa 0.90 °C/w/3"



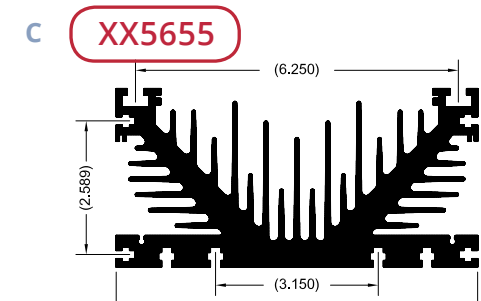
Per. 79.25 in.  
WT. 6.08 lb/ft  
θsa 0.88 °C/w/3"



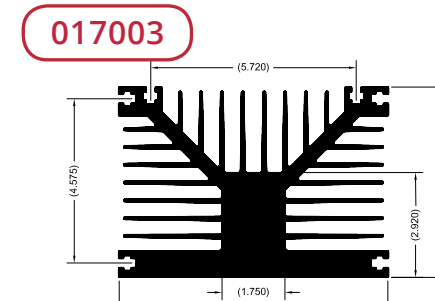
Per. 148.59 in.  
WT. 12.48 lb/ft  
θsa 0.55 °C/w/3"



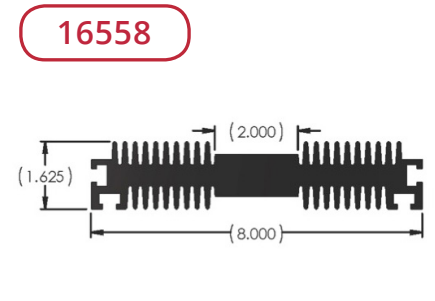
Per. 147.32 in.  
WT. 12.44 lb/ft  
θsa 0.55 °C/w/3"



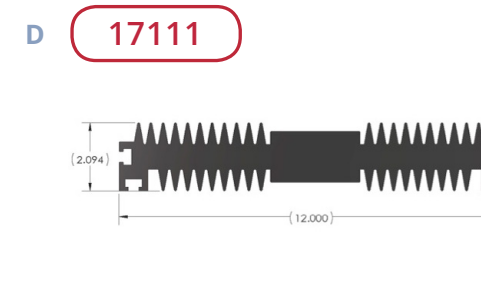
Per. 90.52 in.  
WT. 11.80 lb/ft  
θsa 0.71 °C/w/3"



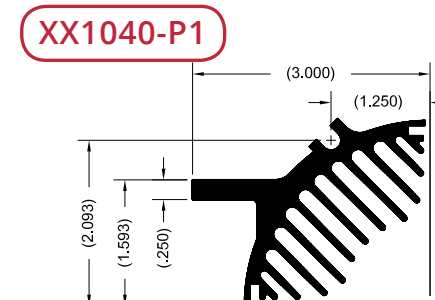
Per. 129.68 in.  
WT. 20.20 lb/ft  
θsa 0.65 °C/w/3"



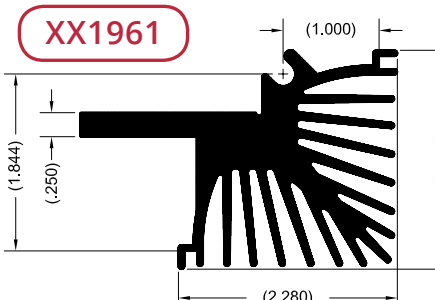
Per. 59.93 in.  
WT. 9.57 lb/ft  
θsa 1.17 °C/w/3"



Per. 76.53 in.  
WT. 20.11 lb/ft  
θsa 0.91 °C/w/3"

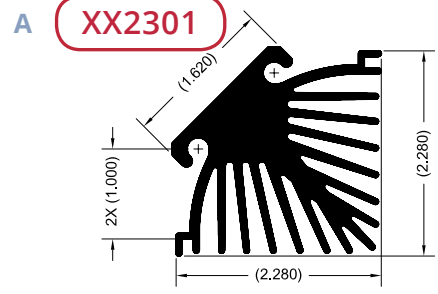


Per. 25.74 in.  
WT. 2.09 lb/ft  
θsa 2.70 °C/w/3"

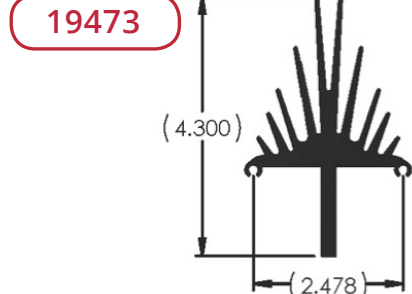


Per. 36.22 in.  
WT. 2.66 lb/ft  
θsa 2.10 °C/w/3"

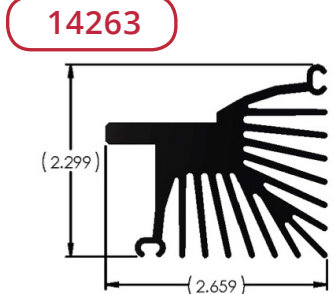




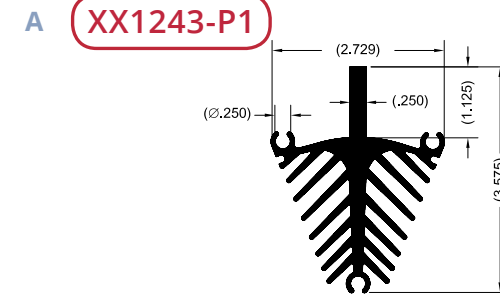
Per.	34.48	in.
WT.	2.48	lb/ft
θsa	2.10	°C/w/3"



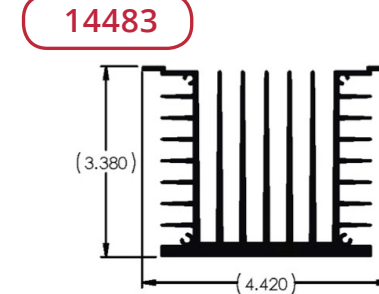
Per.	30.97	in.
WT.	2.85	lb/ft
θsa	2.26	°C/w/3"



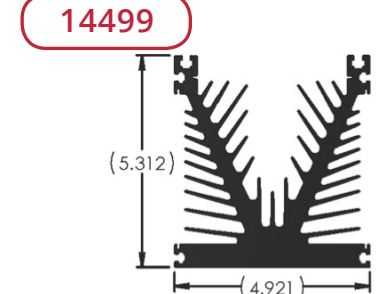
Per.	34.15	in.
WT.	2.51	lb/ft
θsa	2.05	°C/w/3"



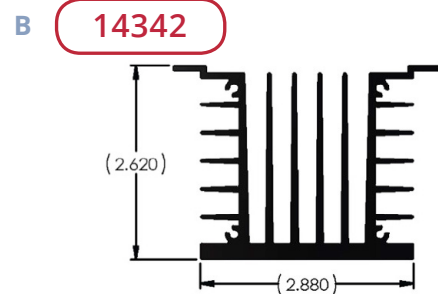
Per.	36.25	in.
WT.	2.53	lb/ft
θsa	2.10	°C/w/3"



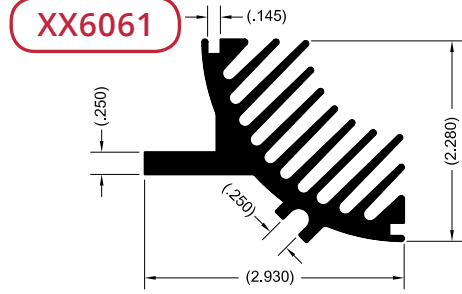
Per.	70.37	in.
WT.	4.32	lb/ft
θsa	0.99	°C/w/3"



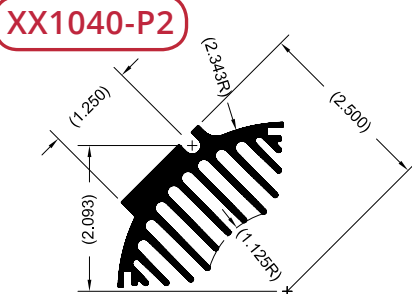
Per.	88.60	in.
WT.	11.46	lb/ft
θsa	0.79	°C/w/3"



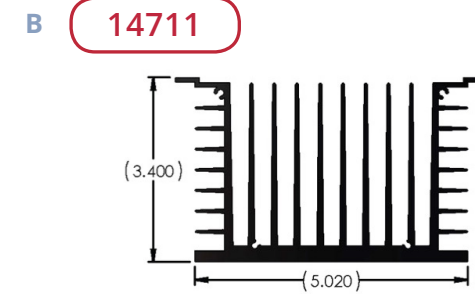
Per.	48.06	in.
WT.	2.88	lb/ft
θsa	1.45	°C/w/3"



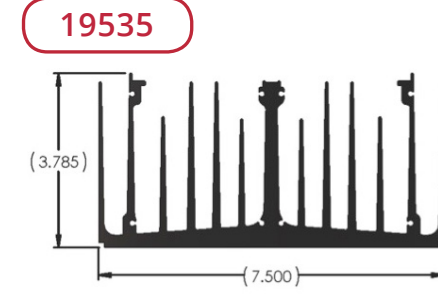
Per.	28.28	in.
WT.	2.23	lb/ft
θsa	2.00	°C/w/3"



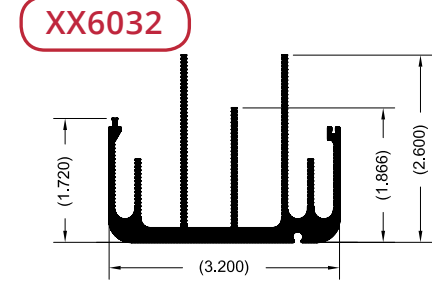
Per.	24.00	in.
WT.	1.87	lb/ft
θsa	2.90	°C/w/3"



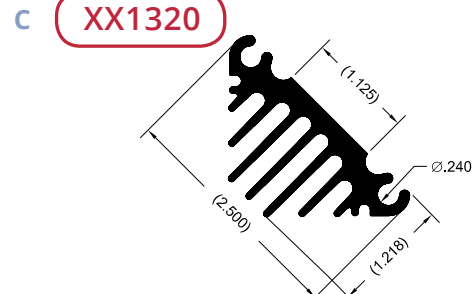
Per.	89.05	in.
WT.	5.95	lb/ft
θsa	0.79	°C/w/3"



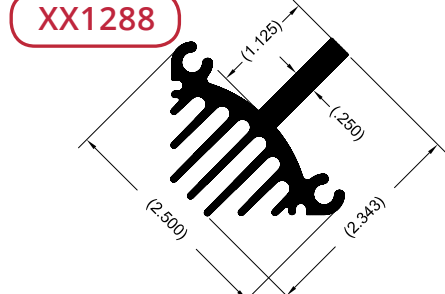
Per.	95.28	in.
WT.	9.50	lb/ft
θsa	0.73	°C/w/3"



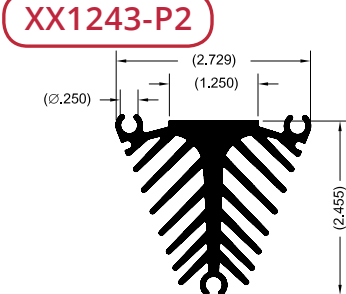
Per.	31.61	in.
WT.	1.75	lb/ft
θsa	2.02	°C/w/3"



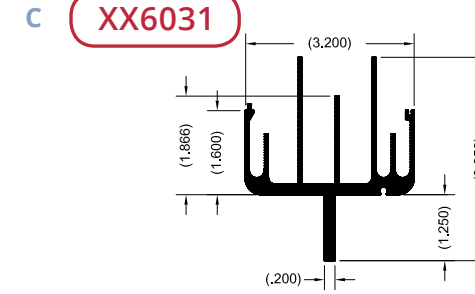
Per.	16.50	in.
WT.	1.36	lb/ft
θsa	3.90	°C/w/3"



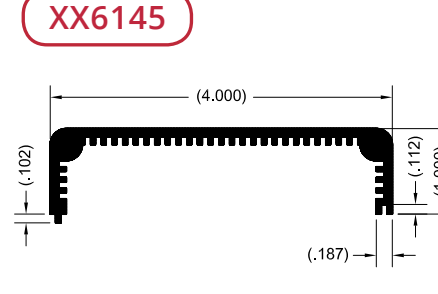
Per.	18.77	in.
WT.	1.41	lb/ft
θsa	3.90	°C/w/3"



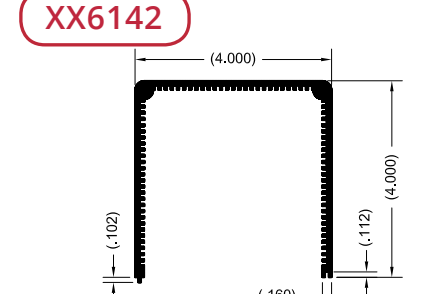
Per.	34.14	in.
WT.	2.24	lb/ft
θsa	2.20	°C/w/3"



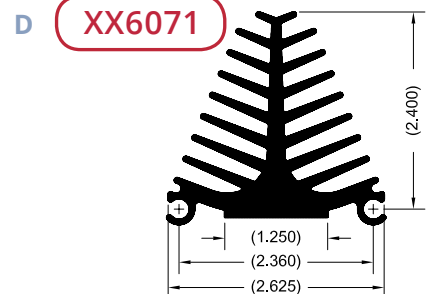
Per.	33.93	in.
WT.	2.06	lb/ft
θsa	2.20	°C/w/3"



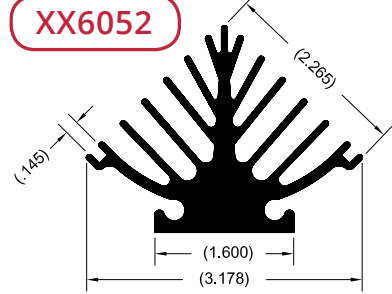
Per.	18.06	in.
WT.	1.03	lb/ft
θsa	2.10	°C/w/3"



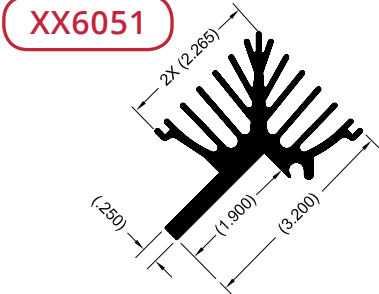
Per.	38.61	in.
WT.	2.05	lb/ft
θsa	1.80	°C/w/3"



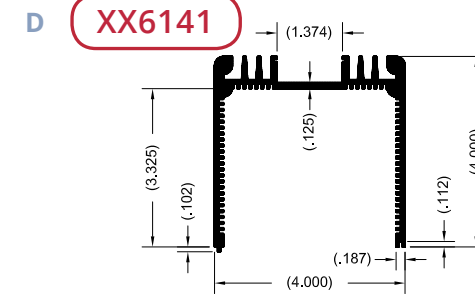
Per.	31.70	in.
WT.	2.45	lb/ft
θsa	1.80	°C/w/3"



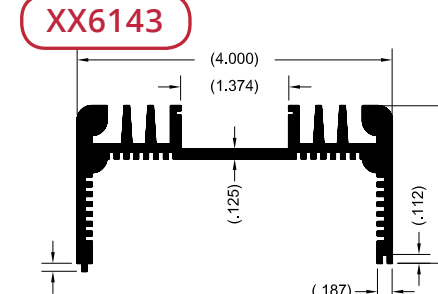
Per.	27.55	in.
WT.	2.19	lb/ft
θsa	1.90	°C/w/3"



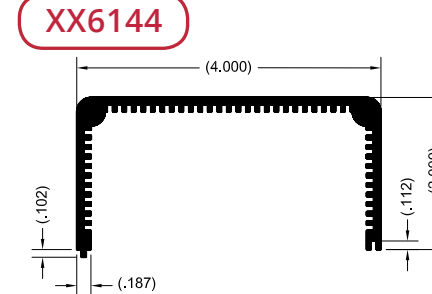
Per.	28.91	in.
WT.	2.18	lb/ft
θsa	1.90	°C/w/3"



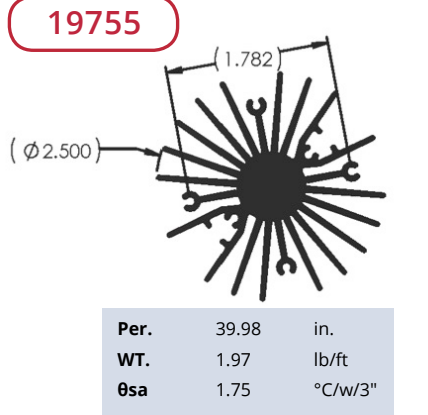
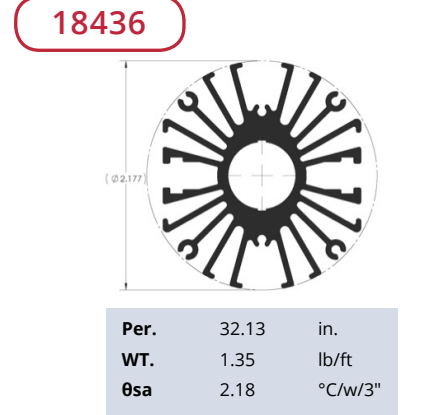
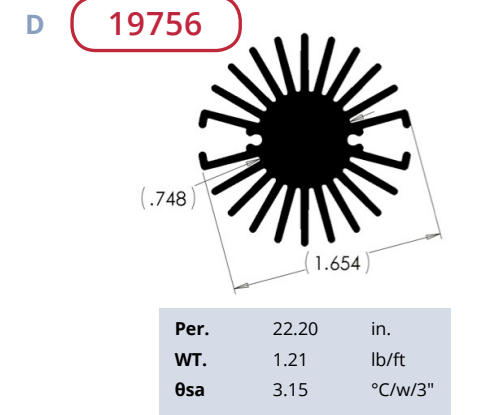
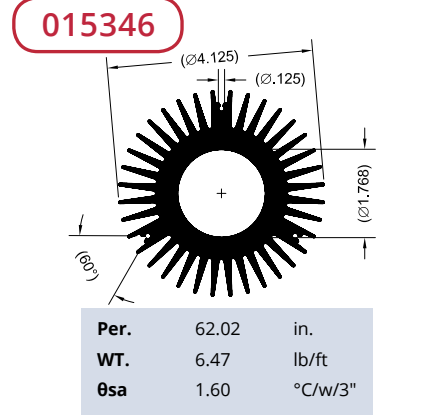
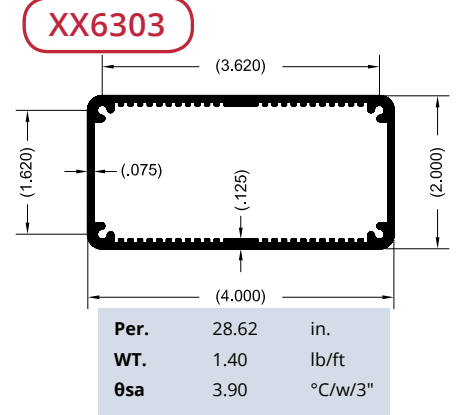
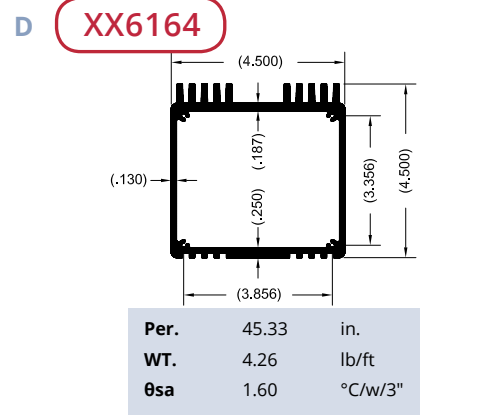
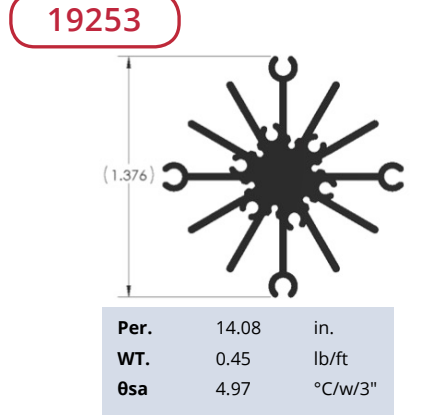
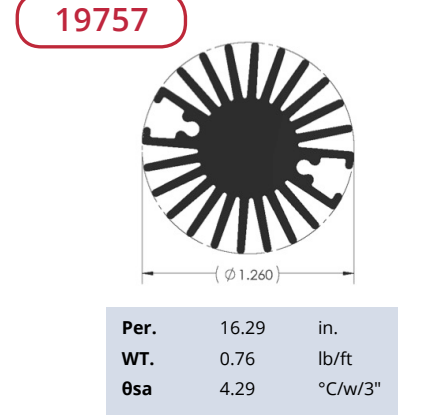
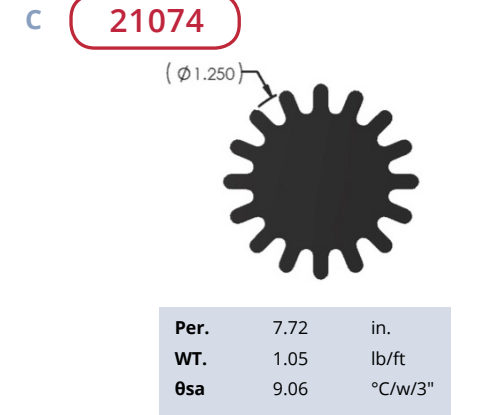
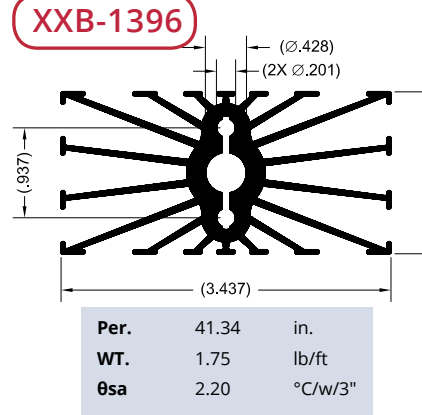
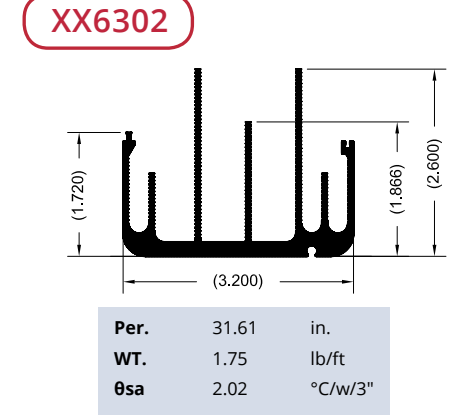
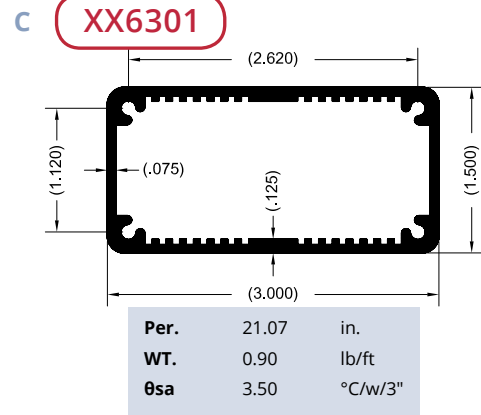
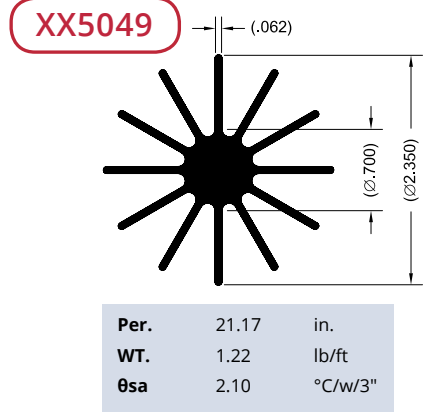
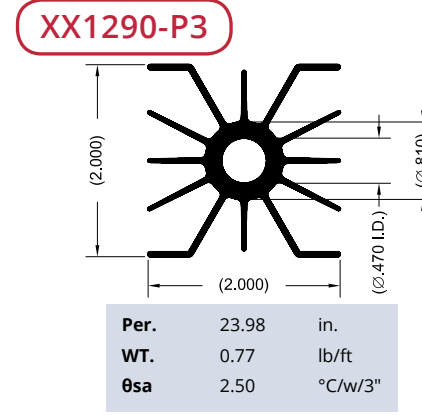
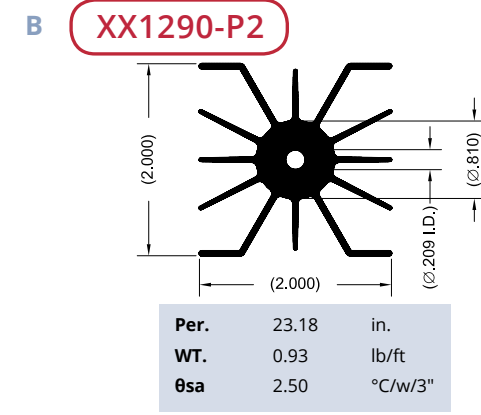
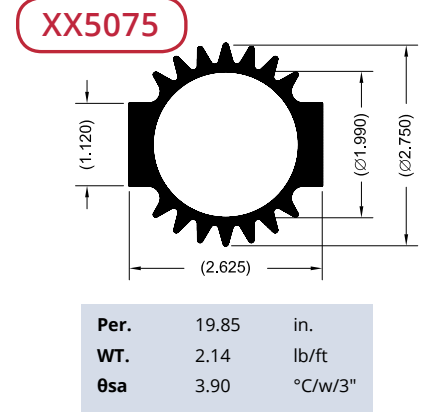
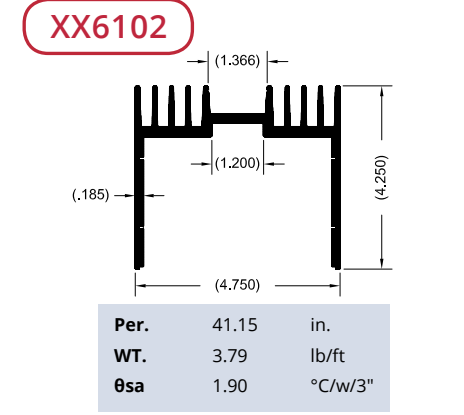
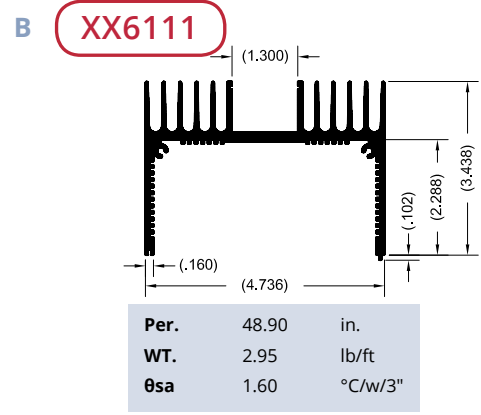
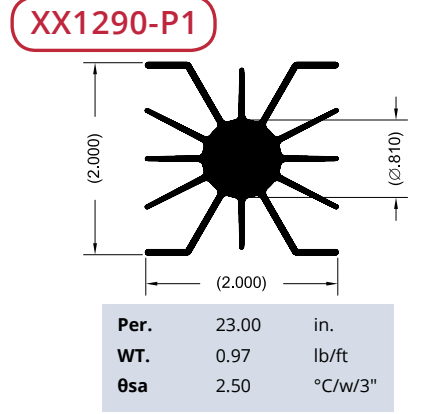
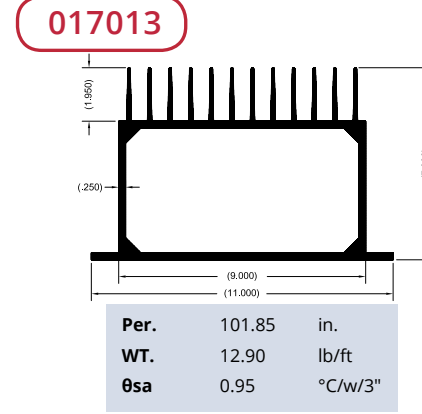
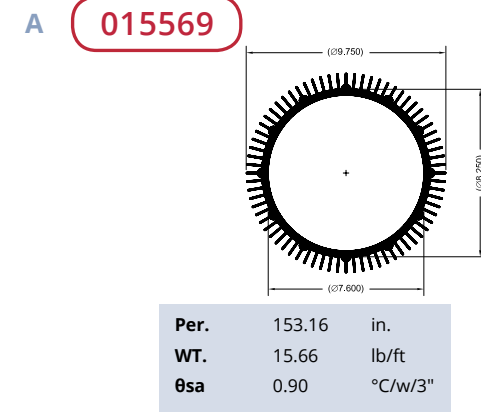
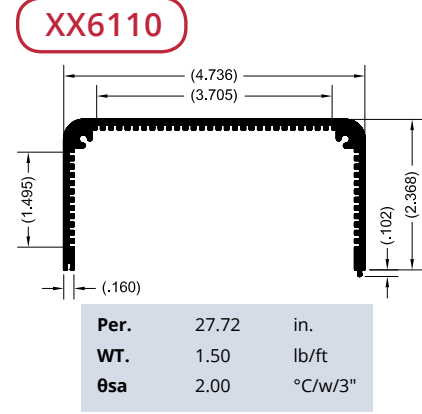
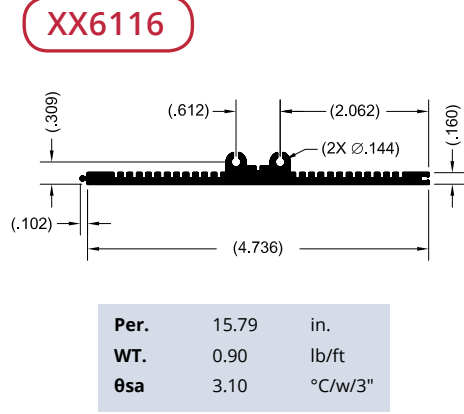
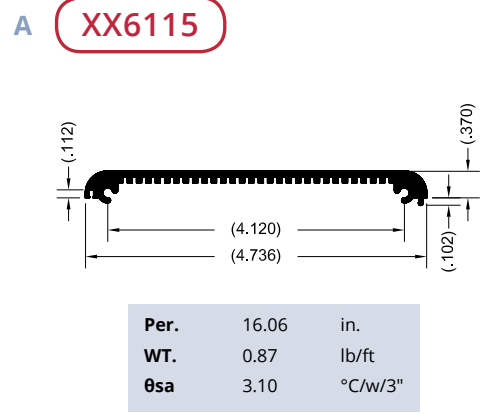
Per.	41.54	in.
WT.	2.57	lb/ft
θsa	1.70	°C/w/3"

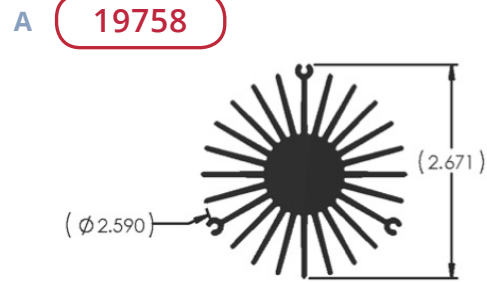


Per.	27.55	in.
WT.	1.92	lb/ft
θsa	1.90	°C/w/3"

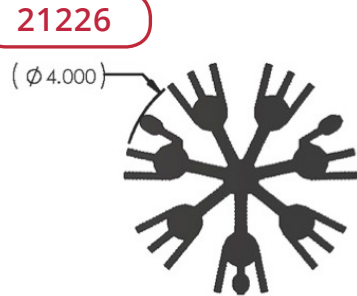


Per.	24.66	in.
WT.	1.37	lb/ft
θsa	2.00	°C/w/3"

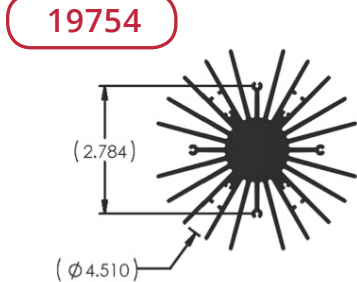




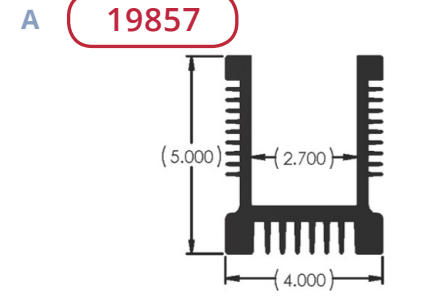
<b>Per.</b>	41.59	in.
<b>WT.</b>	2.39	lb/ft
<b>θsa</b>	1.68	°C/w/3"



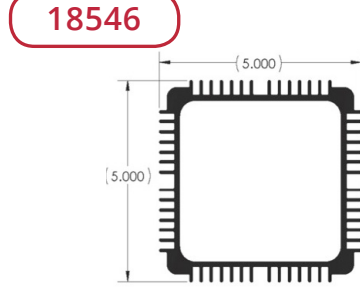
<b>Per.</b>	47.15	in.
<b>WT.</b>	5.64	lb/ft
<b>θsa</b>	1.48	°C/w/3"



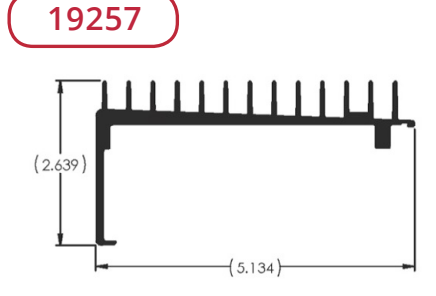
<b>Per.</b>	72.55	in.
<b>WT.</b>	5.02	lb/ft
<b>θsa</b>	0.96	°C/w/3"



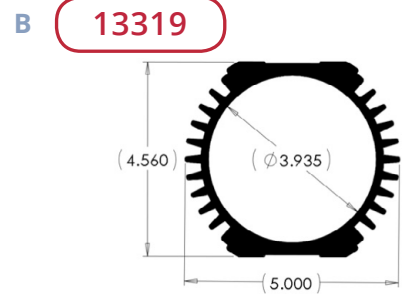
<b>Per.</b>	49.06	in.
<b>WT.</b>	7.54	lb/ft
<b>θsa</b>	1.43	°C/w/3"



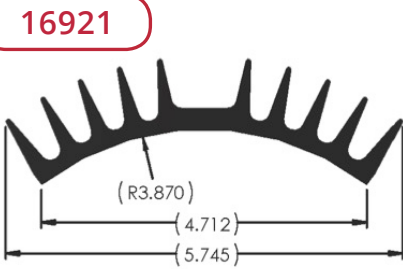
<b>Per.</b>	70.99	in.
<b>WT.</b>	4.96	lb/ft
<b>θsa</b>	0.98	°C/w/3"



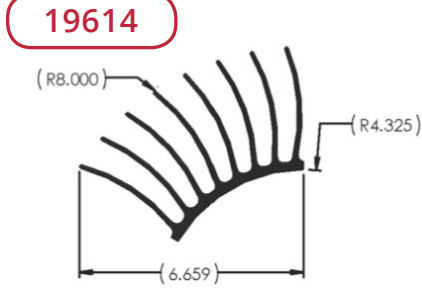
<b>Per.</b>	28.46	in.
<b>WT.</b>	2.04	lb/ft
<b>θsa</b>	2.46	°C/w/3"



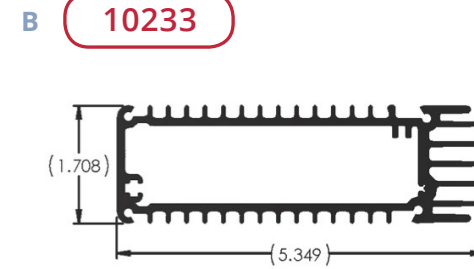
<b>Per.</b>	39.94	in.
<b>WT.</b>	5.90	lb/ft
<b>θsa</b>	1.75	°C/w/3"



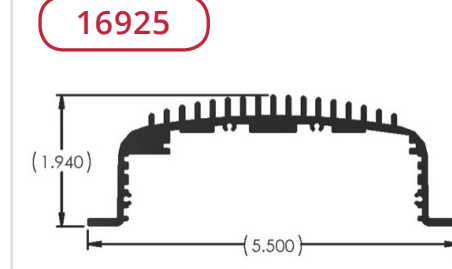
<b>Per.</b>	25.10	in.
<b>WT.</b>	2.93	lb/ft
<b>θsa</b>	2.79	°C/w/3"



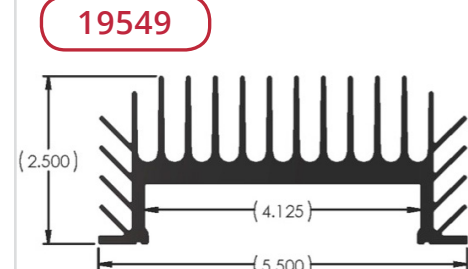
<b>Per.</b>	63.45	in.
<b>WT.</b>	6.04	lb/ft
<b>θsa</b>	1.10	°C/w/3"



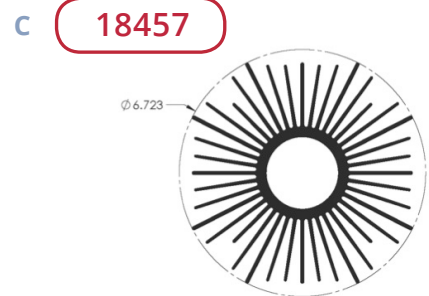
<b>Per.</b>	43.52	in.
<b>WT.</b>	2.58	lb/ft
<b>θsa</b>	1.61	°C/w/3"



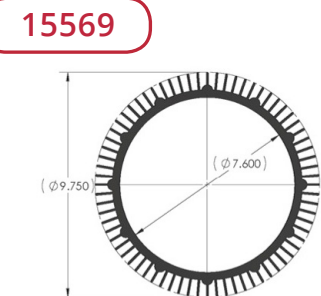
<b>Per.</b>	27.11	in.
<b>WT.</b>	1.92	lb/ft
<b>θsa</b>	2.58	°C/w/3"



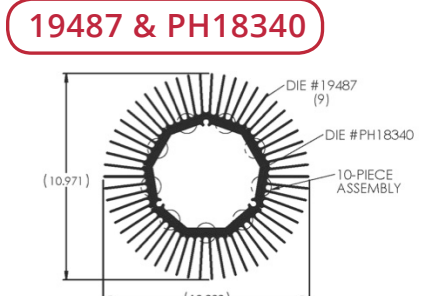
<b>Per.</b>	52.62	in.
<b>WT.</b>	4.17	lb/ft
<b>θsa</b>	1.33	°C/w/3"



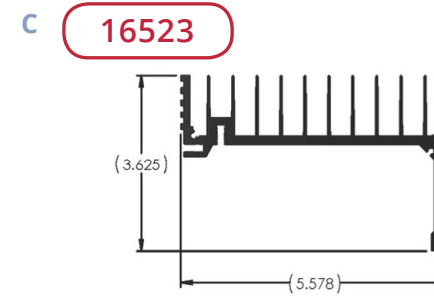
<b>Per.</b>	158.40	in.
<b>WT.</b>	9.37	lb/ft
<b>θsa</b>	0.44	°C/w/3"



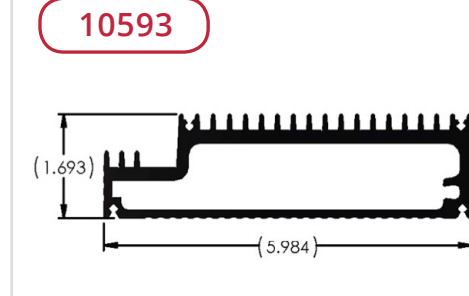
<b>Per.</b>	153.13	in.
<b>WT.</b>	15.66	lb/ft
<b>θsa</b>	0.46	°C/w/3"



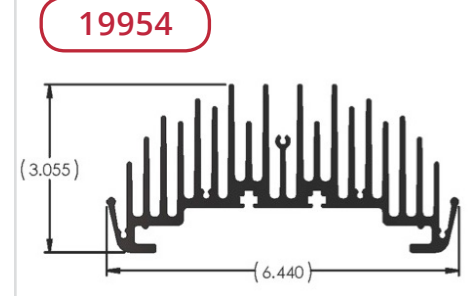
<b>Per.</b>	311.01	in.
<b>WT.</b>	25.59	lb/ft
<b>θsa</b>	0.22	°C/w/3"



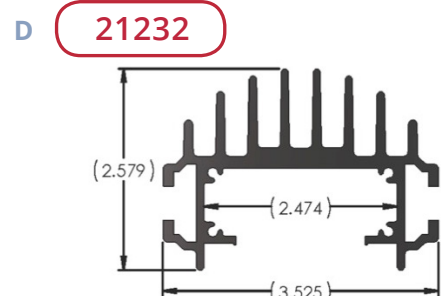
<b>Per.</b>	51.00	in.
<b>WT.</b>	3.38	lb/ft
<b>θsa</b>	1.37	°C/w/3"



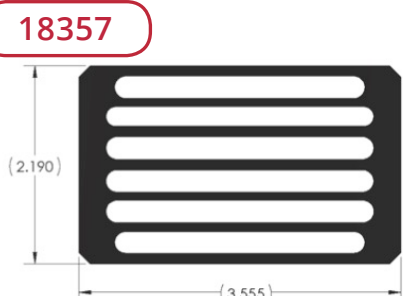
<b>Per.</b>	40.28	in.
<b>WT.</b>	3.43	lb/ft
<b>θsa</b>	1.74	°C/w/3"



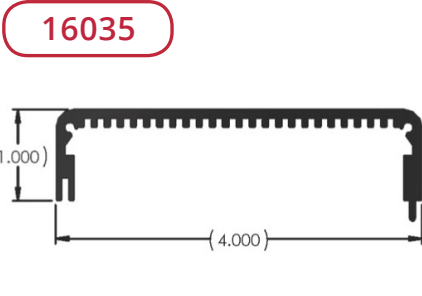
<b>Per.</b>	78.90	in.
<b>WT.</b>	5.55	lb/ft
<b>θsa</b>	0.89	°C/w/3"



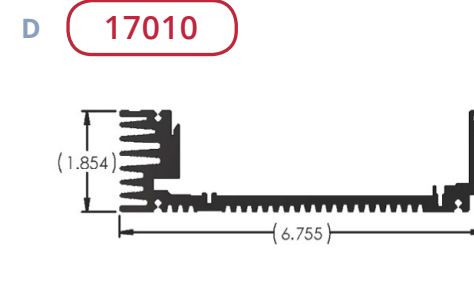
<b>Per.</b>	30.59	in.
<b>WT.</b>	2.33	lb/ft
<b>θsa</b>	2.29	°C/w/3"



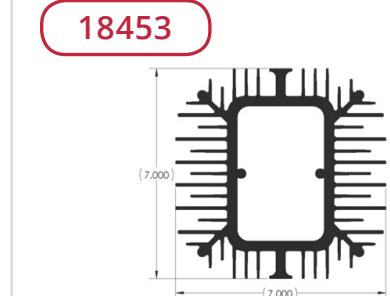
<b>Per.</b>	47.69	in.
<b>WT.</b>	4.25	lb/ft
<b>θsa</b>	1.47	°C/w/3"



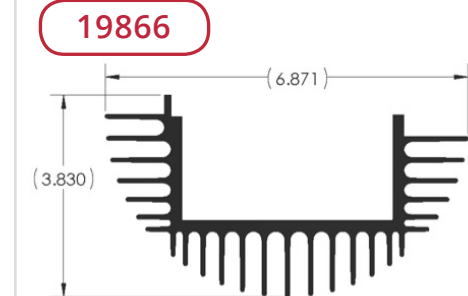
<b>Per.</b>	17.40	in.
<b>WT.</b>	1.05	lb/ft
<b>θsa</b>	4.02	°C/w/3"



<b>Per.</b>	39.79	in.
<b>WT.</b>	3.31	lb/ft
<b>θsa</b>	1.76	°C/w/3"



<b>Per.</b>	139.00	in.
<b>WT.</b>	13.95	lb/ft
<b>θsa</b>	0.50	°C/w/3"



<b>Per.</b>	61.60	in.
<b>WT.</b>	4.60	lb/ft
<b>θsa</b>	1.14	°C/w/3"

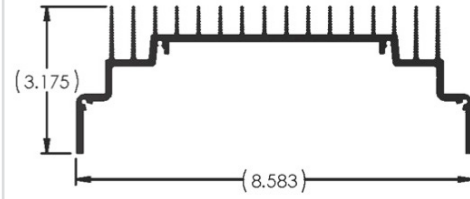
A

18395



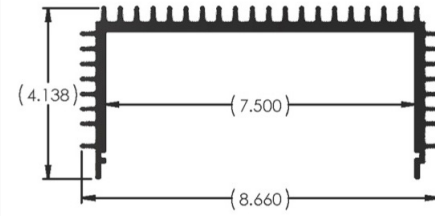
<b>Per.</b>	40.24	in.
<b>WT.</b>	2.94	lb/ft
<b>θsa</b>	1.74	°C/w/3"

16517



<b>Per.</b>	52.66	in.
<b>WT.</b>	3.22	lb/ft
<b>θsa</b>	1.33	°C/w/3"

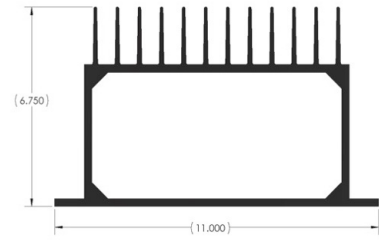
19384



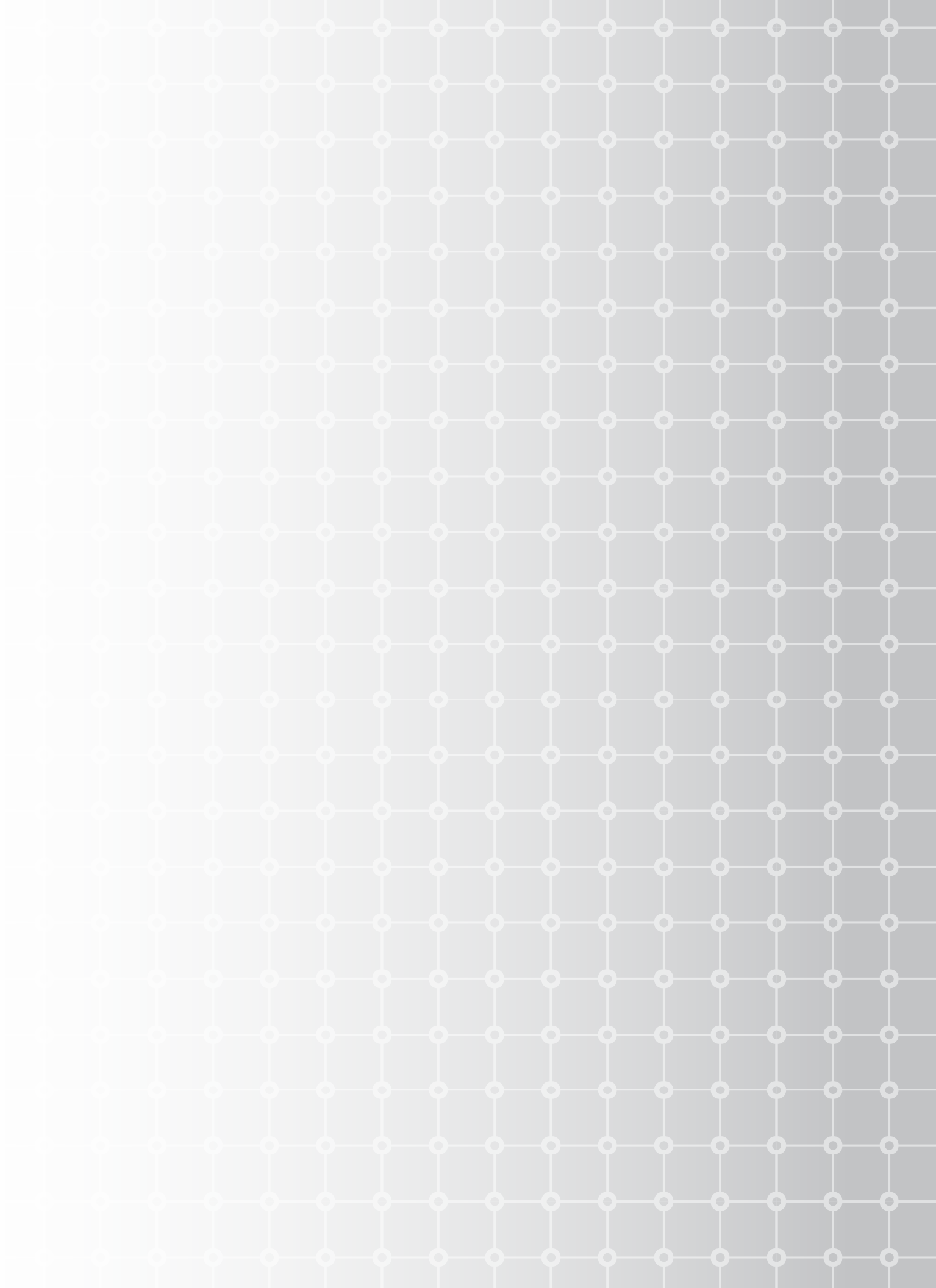
<b>Per.</b>	68.16	in.
<b>WT.</b>	5.89	lb/ft
<b>θsa</b>	1.03	°C/w/3"

B

17013



<b>Per.</b>	100.85	in.
<b>WT.</b>	12.75	lb/ft
<b>θsa</b>	0.69	°C/w/3"

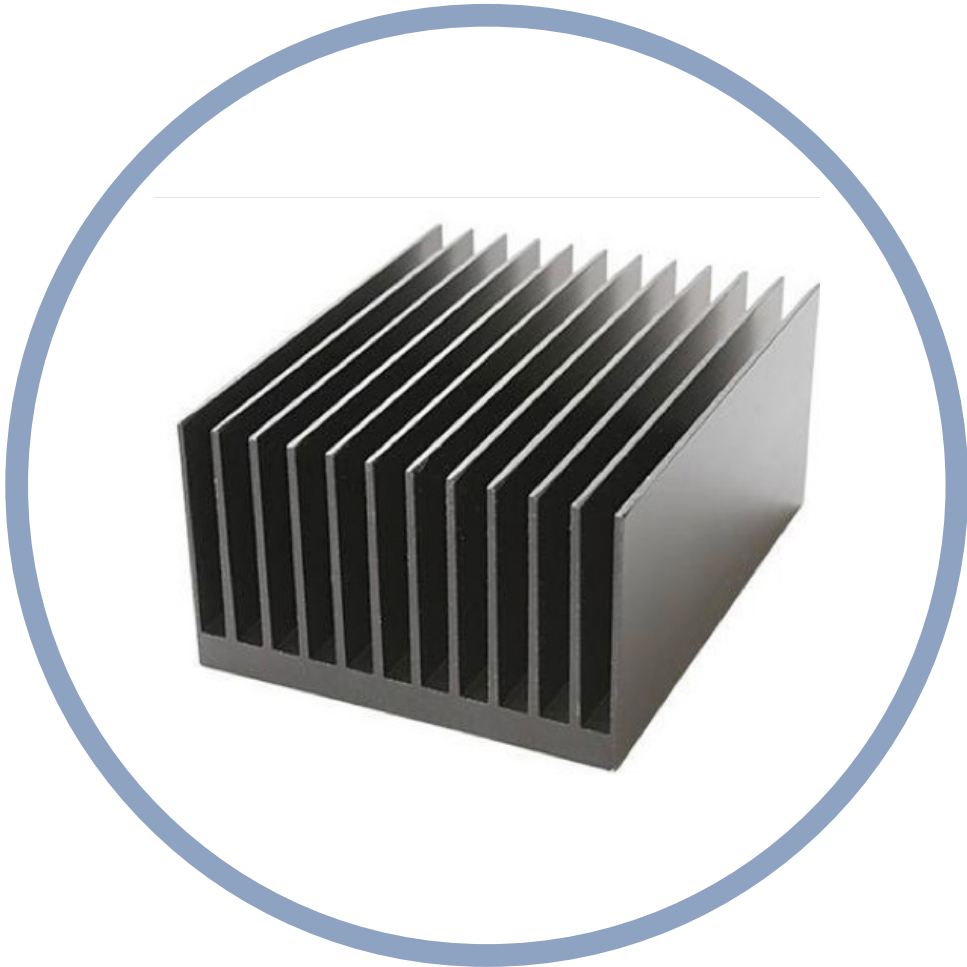


# HIGH ASPECT RATIO THERMAL EXTRUSIONS

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*12 Inch High Aspect Ratio Thermal Extrusions* ..... 280-285

*High Aspect Ratio Thermal Extrusions* ..... 286



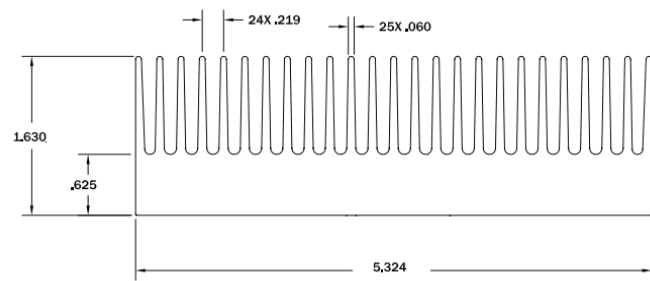
# 12 INCH HIGH ASPECT RATIO THERMAL EXTRUSIONS



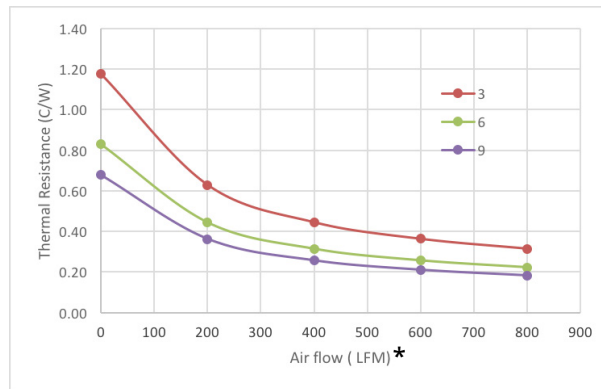
## PART NUMBER 122254

**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 19671  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Inches				
		Length	Width	Height	Avg Base Thk	Avg Fin Thk
122254	19671 Profile Cut to 12 inches	12	5.324	1.63	0.625	0.096



THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS

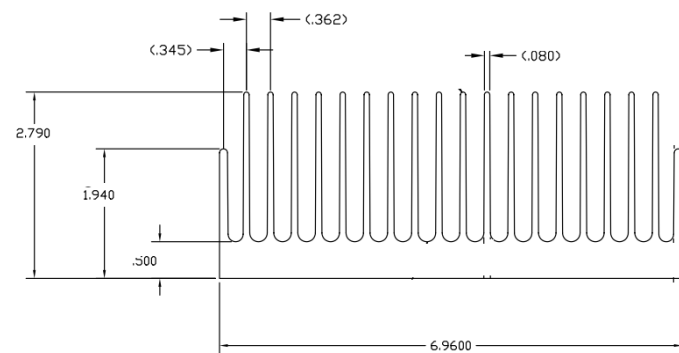


## PART NUMBER 122255

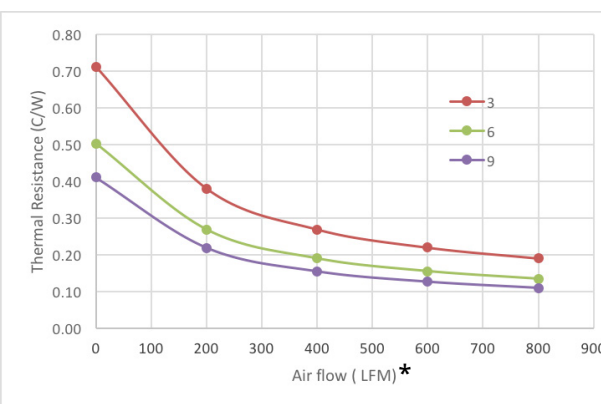


**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 13694  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Inches				
		Length	Width	Height	Avg Base Thk	Avg Fin Thk
122255	13694 Profile Cut to 12 inches	12	6.96	2.79	.05	0.1



THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS



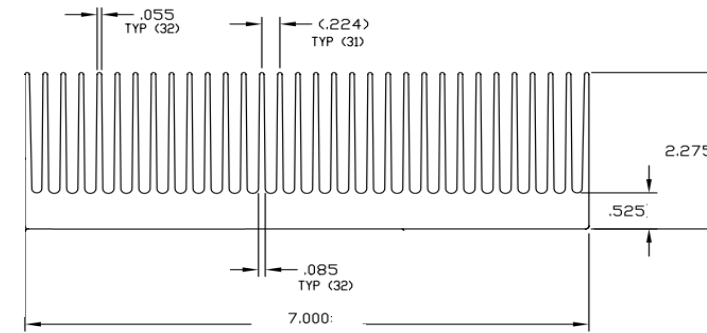
\*Thermal performance data is for reference only and may vary by application  
 \*0 LFM represents a natural convection environment with a vertical heat sink  
 \*All data is based on a fully distributed load on the base of the heat sink  
 \*All forced convection data is based on an open duct configuration



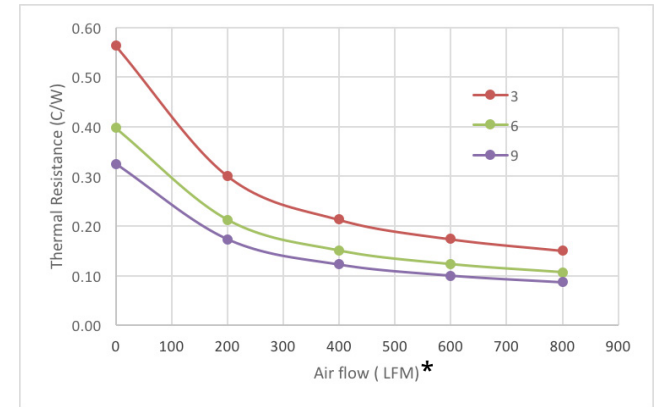
## PART NUMBER 122256

**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 15837  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Inches				
		Length	Width	Height	Avg Base Thk	Avg Fin Thk
122256	15837 Profile Cut to 12 inches	12	7	2.275	0.525	0.085



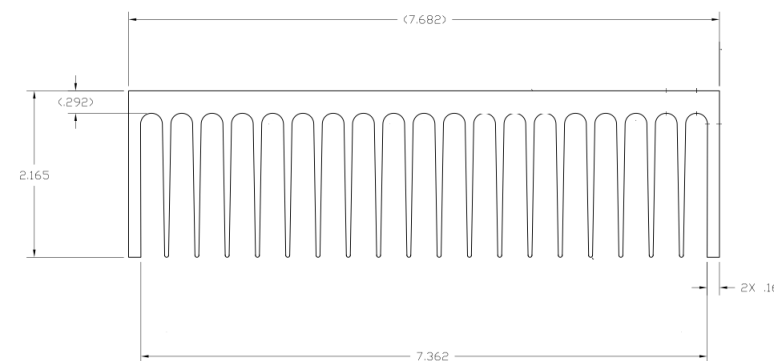
THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS



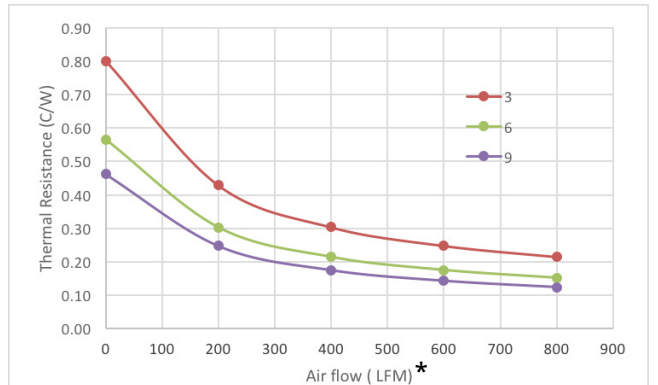
## PART NUMBER 122257

**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 19275  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Inches				
		Length	Width	Height	Avg Base Thk	Avg Fin Thk
122257	19275 Profile Cut to 12 inches	12	7.362	2.165	0.292	0.051



THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS



\*Thermal performance data is for reference only and may vary by application  
 \*0 LFM represents a natural convection environment with a vertical heat sink  
 \*All data is based on a fully distributed load on the base of the heat sink  
 \*All forced convection data is based on an open duct configuration

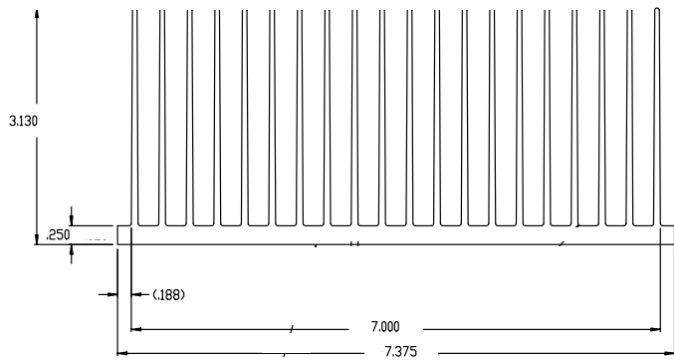
# 12 INCH HIGH ASPECT RATIO THERMAL EXTRUSIONS



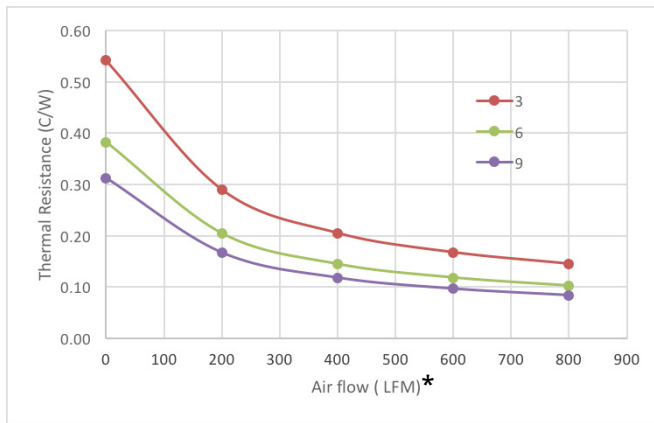
## PART NUMBER 122258

**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 15817  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Length	Inches			
			Width	Height	Avg Base Thk	Avg Fin Thk
122258	15817 Profile Cut to 12 inches	12	7.375	3.13	0.25	0.09



THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS

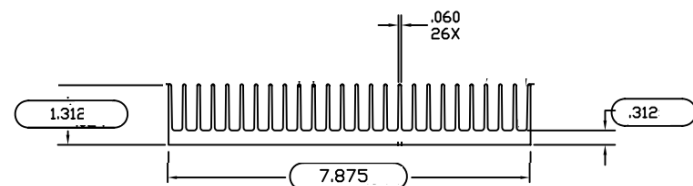


## PART NUMBER 122259

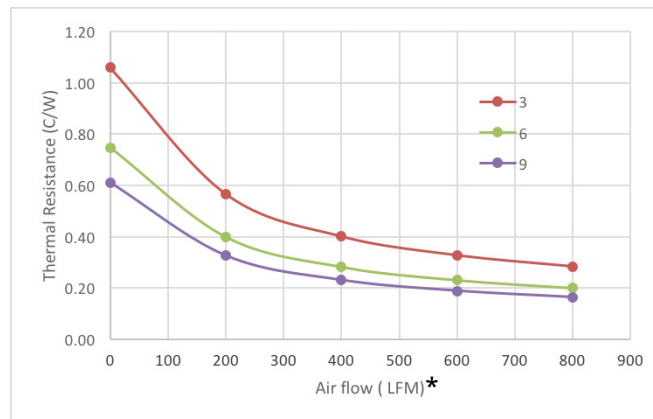


**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 16639  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Length	Inches			
			Width	Height	Avg Base Thk	Avg Fin Thk
122259	16639 Profile Cut to 12 inches	12	7.875	1.312	0.312	0.08



THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS



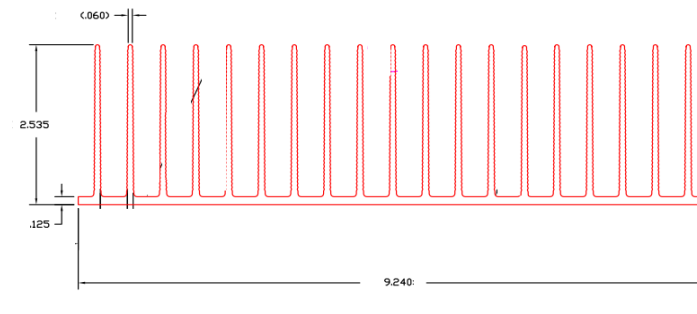
\*Thermal performance data is for reference only and may vary by application  
 \*0 LFM represents a natural convection environment with a vertical heat sink  
 \*All data is based on a fully distributed load on the base of the heat sink  
 \*All forced convection data is based on an open duct configuration



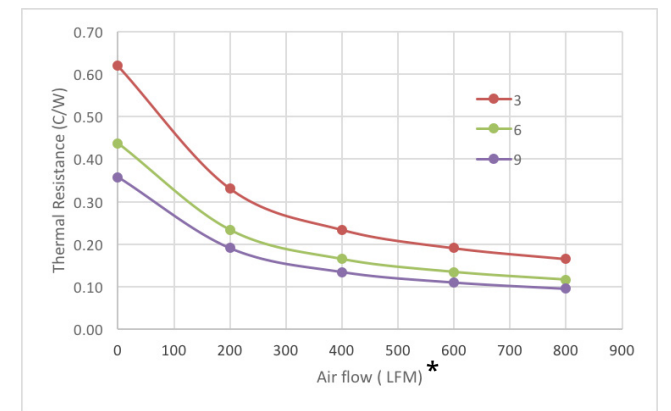
## PART NUMBER 122260

**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 16639  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Length	Inches			
			Width	Height	Avg Base Thk	Avg Fin Thk
122260	16639 Profile Cut to 12 inches	12	9.24	2.66	0.125	0.085



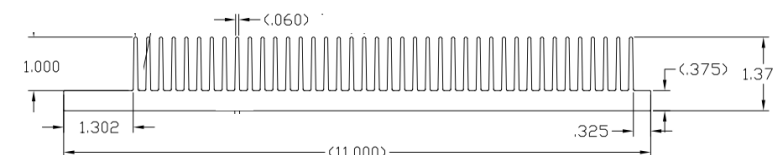
THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS



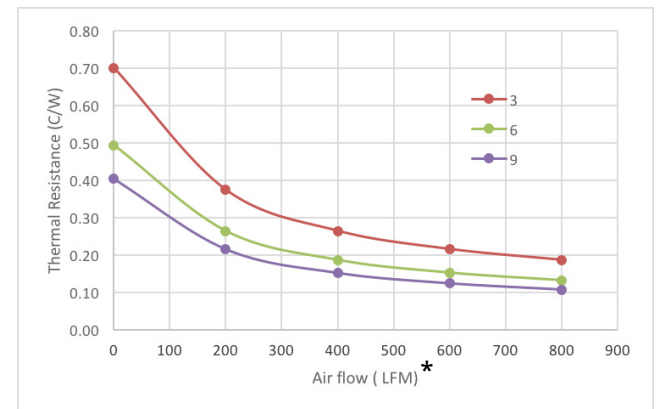
## PART NUMBER 122261

**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 19584  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Length	Inches			
			Width	Height	Avg Base Thk	Avg Fin Thk
122261	19584 Profile Cut to 12 inches	12	11	1.375	0.375	0.09



THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS



\*Thermal performance data is for reference only and may vary by application  
 \*0 LFM represents a natural convection environment with a vertical heat sink  
 \*All data is based on a fully distributed load on the base of the heat sink  
 \*All forced convection data is based on an open duct configuration

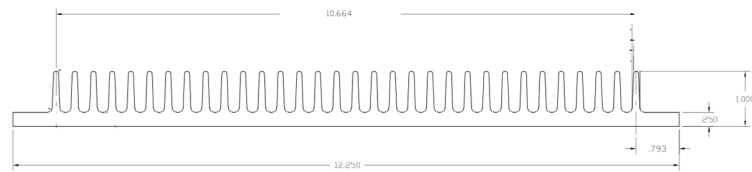
## 12 INCH HIGH ASPECT RATIO THERMAL EXTRUSIONS



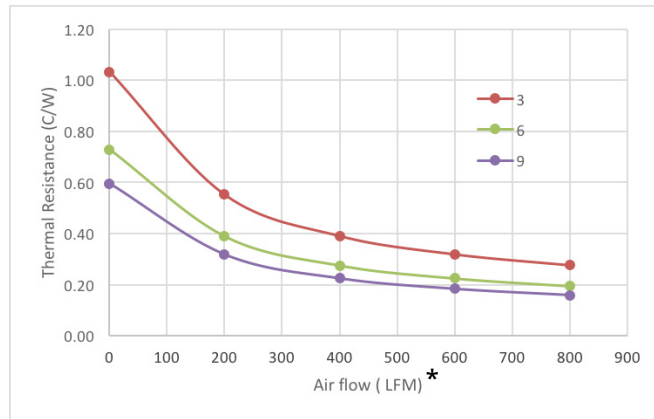
### PART NUMBER 122262

**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 19152  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Length	Inches			
			Width	Height	Avg Base Thk	Avg Fin Thk
122262	19152 Profile Cut to 12 inches	12	12.25	1	0.25	0.146



THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS

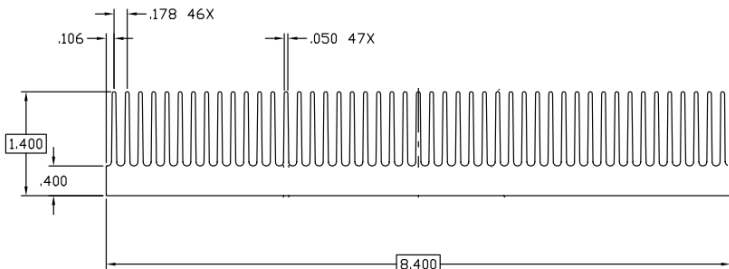


### PART NUMBER 122263

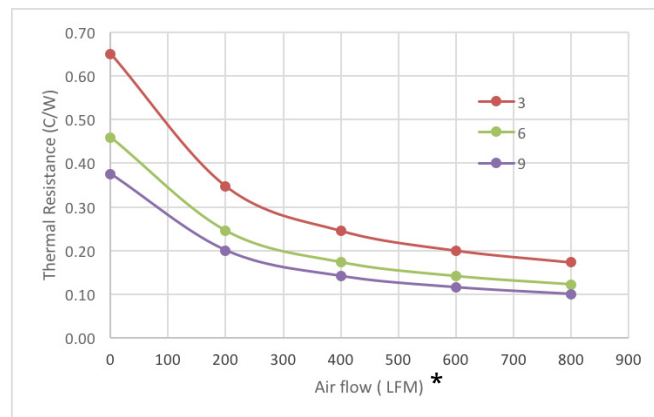


**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 16681  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Length	Inches			
			Width	Height	Avg Base Thk	Avg Fin Thk
122263	16681 Profile Cut to 12 inches	12	8.4	1.4	0.4	0.5



THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS



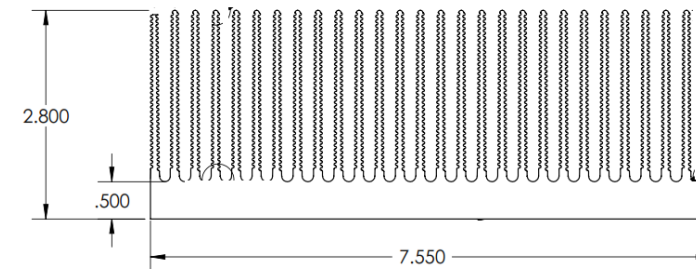
\*Thermal performance data is for reference only and may vary by application  
 \*0 LFM represents a natural convection environment with a vertical heat sink  
 \*All data is based on a fully distributed load on the base of the heat sink  
 \*All forced convection data is based on an open duct configuration



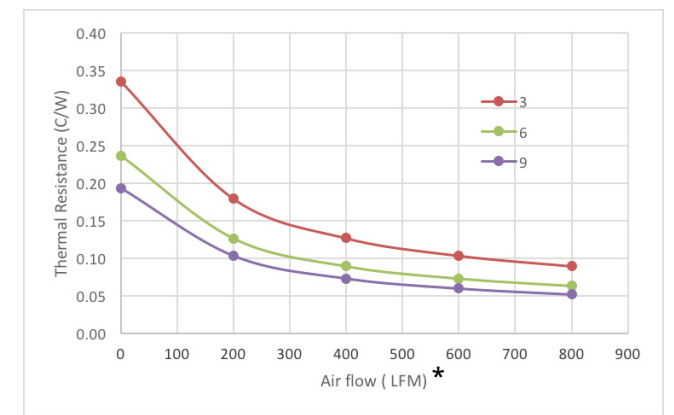
### PART NUMBER 122264

**Material:** 6063 Aluminum  
**Description:** 12 Inch Cut Length of Extrusion Profile 19832  
 Cut, Deburred, Washed  
 No Finish

Part Number	Description	Length	Inches			
			Width	Height	Avg Base Thk	Avg Fin Thk
122264	19832 Profile Cut to 12 inches	12	7.55	2.8	0.5	0.57



THERMAL RESISTANCE FOR 3", 6", 9" CUT LENGTHS



\*Thermal performance data is for reference only and may vary by application  
 \*0 LFM represents a natural convection environment with a vertical heat sink  
 \*All data is based on a fully distributed load on the base of the heat sink  
 \*All forced convection data is based on an open duct configuration

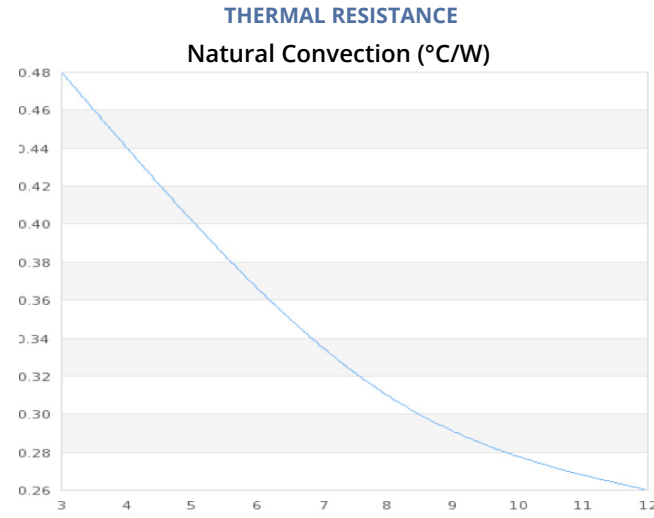
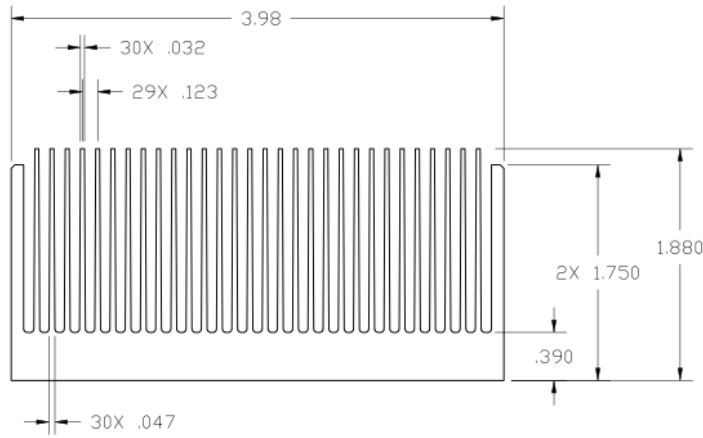


# HIGH ASPECT RATIO THERMAL EXTRUSIONS



## PART NUMBER 122547

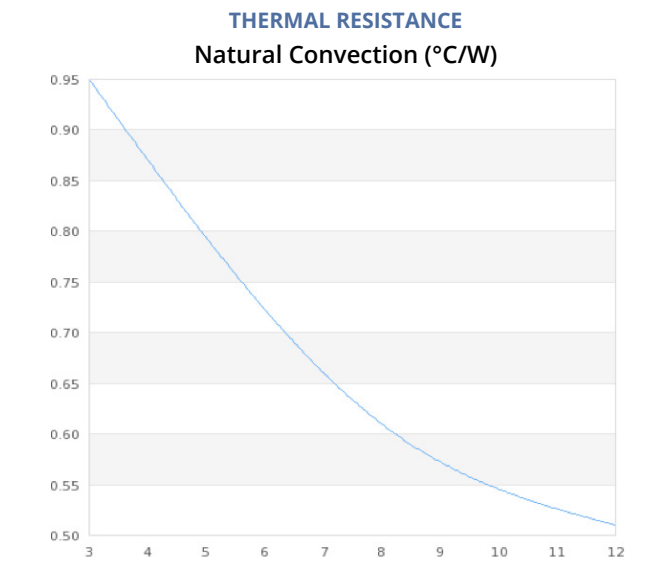
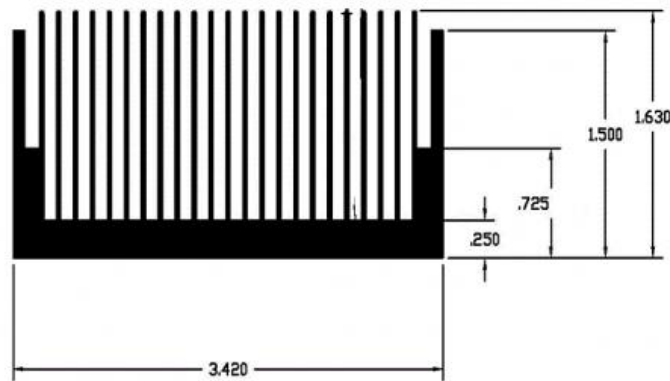
Part Number	Description	Inches						Perimeter	Weight Per Piece	Natural Convection (3 in.)
		Length	Width	Height	Avg Base Thk	Avg Fin Thk				
122547	High Aspect Heat Sink for Power Module	15.25	3.98	1.88	0.39	0.123	145	5.5	0.48	



## PART NUMBER 122551



Part Number	Description	Inches						Perimeter	Weight Per Piece	Natural Convection (3 in.)
		Length	Width	Height	Avg Base Thk	Avg Fin Thk				
122551	High Aspect Heat Sink for Power Module	12.32	3.42	1.63	0.25	0.031	73.61	2.61	0.95	



\*Thermal performance data is for reference only and may vary by application  
 \*0 LFM represents a natural convection environment with a vertical heat sink  
 \*All data is based on a fully distributed load on the base of the heat sink  
 \*All forced convection data is based on an open duct configuration







**Resin** - A term used for an organic polymer that when mixed with a curing agent crosslinks to form a thermosetting plastic.

**Resistance** - The property of a conductor that opposes the flow of current by dissipating energy as heat. In packages, it causes voltage and current loss in signal and power distribution systems.

**SCR** - Silicon controlled rectifier.

**Shrinkage** - The decrease in volume, or contraction of a material by the escape of any volatile substance, or by a chemical or physical change in the material.

**Single-in-Line (SIP)** - DIP-like package with single line of leads as opposed to two for DIP.

**Solvent Cleaner** - The process of removing soil from a substrate surface with an organic solvent. The solvent cleaning process does not alter the substrate physically or chemically.

**Specific Heat** - The ratio of thermal energy required to raise the temperature of a body 1° to the thermal energy required to raise an equal mass of water 1°.

**Storage Life** - The period of time during which a packaged adhesive can be stored under specific temperature conditions and remain suitable for use. Often called "Shelf Life."

**Surface Mount Technology (SMT)** - A method of assembling hybrid circuits and printed wiring boards, where component parts are mounted onto, rather than into, the printed wiring board, as in the mounting of components on substrates in hybrid technology.

**Tack (Green Strength)** - The property of an adhesive that enables it to form a bond of measurable strength immediately after adhesive and adherend are brought into contact under little or no pressure.

**Tape Automated Bonding (TAB)** - The process where silicon chips are joined to patterned metal or polymer tape using thermocompression bonding, and subsequently attached to a substrate or board by outer lead bonding. Intermediate processing may be carried out in strip form through operations such as testing, encapsulation, bum-in, and excising the individual packages from the tape.

**TCE** - Temperature coefficient of expansion.

**Temperature, Curing** - The temperature at which an adhesive or assembly is subject to curing.

**Temperature Cycling** - An environmental test where the film circuit is subjected to several temperature changes from a low temperature to a high temperature over a period of time.

**Thermal Conductivity** - A measure of a material's ability to conduct heat; physical constant for quantity of heat that passes through unit volume of a substance in unit of time when difference in temperature of two opposite faces is unity.

**Thermal Cycling** - A method to impose cyclical stress on an assembly of microelectronic components by alternately heating and cooling in an oven. It is used for accelerated reliability testing of assemblies.

**Thermal Expansion** - An increase in size due to an increase in temperature expressed in units of an increase in length or increase in size per degree.

**Thermal Gradient** - The plot of temperature variances across the bulk thickness of a material being heated.

**Thermal Mismatch** - Difference in thermal coefficients of expansion of materials which are bonded together.

**Thermal Resistance (°C/W)** - The opposition offered by a medium to the passage through it of thermal energy.

**Thermocouple** - The junction of two dissimilar metals which has a voltage output proportional to the difference in temperature between the hot junction and the lead wires.

**Thermoset** - Material that will undergo or has undergone a chemical reaction by the action of heat, catalyst, ultraviolet light, etc., leading to a relatively infusible state.

**Transistor Outline (TO)** - Industry standard package designation established by JEDEC of the EIA.

**Trim Die** - Die for shearing or shaving flash from a casting. Either the die is forced over the casting, or the casting is forced through the die.

**Viscosity** - A measure of the resistance of a fluid to flow or the internal friction within the body or fluid.

**Working Life** - The period of time during which a liquid resin or adhesive, after mixing with a catalyst, solvent, or other compounding ingredients, remains usable. Also known as "Pot Life".

**Zero-insertion-Force Connection (ZIF)** - A form of connector that allows the connector pins to be brought together under very low force, then wiped and pressed together during cam activation. Low insertion force is LIF.

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